

Sunday Afternoon, September 21, 2025

AVS Quantum Science Workshop

Room 208 W - Session AQS-SuA

AVS Quantum Science Workshop Oral Session (ALL-INVITED SESSION)

Moderators: Ekta Bhatia, NY CREATES, Charles R. Eddy, Jr., Office of Naval Research Global - London, David Pappas, Rigetti Computing, Andre Schleife, University of Illinois at Urbana-Champaign

3:00pm **AQS-SuA-1 Experimental Discovery of Anyons: Realizing the Power of Quantum Statistics, Michael Manfra**, Purdue University

3:30pm **AQS-SuA-3 Fault Tolerant Quantum Computation using Majorana-Based Topological Qubits, Roman Lutchyn**, Microsoft Quantum

Research in quantum computing has provided numerous new physical insights and the potential to exponentially increase computational power for solving significant problems in science and technology. The primary obstacle to building a scalable quantum computer is errors caused by decoherence. Topological quantum computing addresses this challenge by utilizing topological materials that inherently limit errors.

In this talk, I will discuss the engineering of topological superconductors that support Majorana zero-energy modes at the interface between a conventional superconductor (Aluminum) and a semiconductor with spin-orbit interaction (Indium Arsenide). I will present recent findings from the Microsoft Quantum team that indicate the emergence of topological superconductivity in proximitized semiconductor nanowires. Additionally, I will cover recent measurements of fermion parity, which represent a step towards the fusion of Majorana zero modes. Finally, I will outline a proposal for scalable quantum computing that involves topological qubits composed of superconducting islands in a Coulomb blockade regime, hosting aggregates of four or more Majorana zero modes.

4:00pm **AQS-SuA-5 Enabling the Scaling of Superconducting Quantum Devices in a 300 mm Wafer Fab, Ekta Bhatia, Zhihao Xiao, Chung Kow, Stephen Olson, Jakub Nalaskowski, John Mucci, Nicholas Pieniazek, Daniel Romero, Hyuncher Chong, Bryan Egan, Geevanie Telhu, Wenli Collison, Sandra Schujman, Kevin Musick, Thomas Murray, Aleksandra Biedron, Satyavolu Papa Rao, NY CREATES**

Progress in superconducting qubit performance over the past three decades has led researchers to focus on scalable quantum computing. To achieve scalability, the following are among the desiderata: system stability, easy input/output, high component yields, low energy use, and predictable component performance with tight distributions. These demands are even more challenging for quantum computing.

The NY CREATES team, along with our partners, has taken on the scalability challenge by seeking to implement superconducting qubits at 300 mm wafer scale, leveraging state of the art tools and processes to support the development of a Superconducting Quantum Process Design Kit (PDK). A PDK will enable democratization of qubit design and fabrication for startups, academia and national labs - but a PDK is only as good as the fidelity with which fabricated devices meet the designer's intent. Hence it is critical to develop fabrication processes that are controlled and repeatable, in tools that are equipped with *in situ* monitors for process control.

This talk will describe our efforts to develop tantalum (Ta)-based qubits at 300 mm scale. We use α -Ta as the wiring material, and atomic layer deposited tantalum nitride in the tunnel barrier of the Josephson junction. The advantages provided by state-of-the-art 300 mm tools to enable *in situ* process monitoring and control will be described using a few examples from various stages of the process flow. This talk will discuss the impact of two-level systems in material surfaces and interfaces. We have addressed them in many ways - by burying some in a crystalline silicon matrix to eliminate air exposure, and by replacing native oxides with surface treatments providing improved physical characteristics. Implementation of integrated air bridges and lumped element resonators that use high kinetic inductance elements and capacitors that use crystalline silicon as the dielectric will be discussed. The talk will conclude with a description of the circuit elements that are being developed for the PDK cell library, both as 'fixed geometry' cells, and as parameterized cells.

We thank our many partners, including Brookhaven National Lab, Pacific Northwest National Lab, AFRL-Rome, SEEQC, QCI, Tokyo Electron Ltd, Applied Materials, Cadence, Cornell University, Princeton University, Syracuse University, and Auburn University. The various projects underlying this talk are funded in part by the US Department of Defense (ME Commons), the US Department of Energy (C2QA), and NY CREATES.

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4:45pm **AQS-SuA-8 Laboratory-based Experiential Learning for Quantum Information Science, Richard S. Ross, UCLA**

INVITED

UCLA's Master of Quantum Science and Technology program has developed innovative instructional laboratory curricula that provide students with a solid foundation in quantum science. This presentation will showcase several case studies, including "Decohering Michelson" and "Chloroforming Deutsch & Jozsa," which demonstrate how theoretical quantum concepts can be effectively translated into practical laboratory implementations. These laboratory experiences cultivate critical skills—quantum state characterization, gate calibration and compilation, tomography, noise analysis, and signal processing—bridging the gap between abstract quantum theory and technical proficiencies demanded by the quantum workforce. The approach effectively complements traditional educational programs at both advanced undergraduate and early graduate levels, providing students with a unique foundation whether they enter industry or pursue further graduate studies in the field.

5:15pm **AQS-SuA-10 Invited Paper, Kasra Sardashti**, Laboratory for Physical Sciences

INVITED

5:45pm **AQS-SuA-12 Quantum Information Science at Brookhaven Lab and the Role of DOE Laboratories in National Research Priorities, Charles Black**, Brookhaven National Laboratory

INVITED

The DOE National Laboratories are a network of mission-driven research organizations that address national-scale challenges through transformative science and technology. Comprising 17 locations and over 20,000 scientists and engineers, the Labs operate major scientific facility infrastructure and lead long-term, coordinated efforts that require deep and broad scientific expertise. The DOE Labs are central to the national strategy for quantum information science (QIS). Through the National Quantum Information Science Research Centers and the broader DOE science portfolio, the Labs are strengthening the QIS ecosystem to support U.S. science leadership, economic competitiveness, and national security.

Brookhaven Lab is the lead institution for the Co-Design Center for Quantum Advantage (C2QA), a multi-institutional partnership among national labs, universities, and industry. C2QA's five-year goal is to overcome foundational limitations in quantum systems and deliver sufficient coherence and connectivity to enable scientific applications of national importance.

In this presentation, I will highlight Brookhaven Lab's contributions to C2QA, including highly productive partnerships with university groups on coherence-driven materials design, unique materials characterization using synchrotron X-rays at the National Synchrotron Light Source II, and the application of domain expertise in nuclear and high energy physics to demonstrate the potential of near-term quantum systems for solving DOE mission priority problems

6:15pm **AQS-SuA-14 Panel Discussion**,

Biomaterials Plenary

Room 209 F W - Session BP-SuA

Biomaterials Plenary Session (ALL-INVITED SESSION)

Moderators: Sapun Parekh, University of Texas at Austin, Christopher So, Naval Research Laboratory

3:00pm **BP-SuA-1 Protein Structure at Interfaces – Its Where the Action Is, Tobias Weidner**, Aarhus University, Denmark

INVITED

Proteins are the machinery of life -- understanding protein structure provides important clues about their mode of action. For this reason, more than 100,000 protein structures have been determined experimentally and are available in databases. At the same time, information about interfacial proteins is sparse. Not a single structure of an interfacial protein can be found in databases. We lack critical information about interfacial proteins to understand biomembranes, the protein control of biominerals, the health impact of artificial biomaterials and the toxicity of microplastic. In addition, for sensor or nanotechnology application, understanding protein binding to surfaces will be key. The current lack of information is, in part, explained by the experimental difficulty of determining the structure of protein within a monomolecular layer in the overwhelming presence of unbound proteins in solution near the interface. Here, sum frequency generation (SFG) spectroscopy has been developed into a surface sensitive

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tool to probe protein structure in detail. We have recently developed methods combining molecular dynamics (MD) simulations with SFG spectroscopy to follow the binding, structure and motion of interfacial proteins. As recent examples, I will discuss breakthroughs in understanding how the formation of neurotoxic aggregates of α -synuclein, the protein implicated with Parkinson's disease, is accelerated at cell membrane. Our data show that at slightly elevated concentrations, α -synuclein assumes a binding pose that promotes lateral aggregation at membrane interfaces. Interfacial effects can also be pronounced at nanoparticle interfaces – which can be important for health in view of the large amounts of plastic particles found in humans. When elucidating the toxicity of plastic particles, we find that nanoparticles affect the conformation of human proteins much more than flat surfaces, with significant consequences for the toxicity of plastics particles.

3:45pm BP-SuA-4 Platelet-Like Biomaterials for Hemostasis and Regenerative Medicine, *Ashley Brown*, North Carolina State University and UNC Chapel Hill **INVITED**

Platelets play a critical role in hemostasis and tissue repair after injury. Our group has created synthetic platelet-like-particles that mimic the fibrin binding ability of native platelets to target wound sites, augment clotting, and mechanically enhance clot structure and stability via particle mediated clot retraction. These materials can be easily modified to deliver drugs and/or used in conjunction with fibrin scaffolds for cell delivery. In this talk, I will describe the development and use of the platelet-like-particle platform for applications in trauma care and tissue regeneration.

4:45pm BP-SuA-8 Enzyme-Powered DNA Materials: Harnessing Tdt for Programmable Nanomedicine and Adaptive Assemblies, *Stefan Zauscher*, Duke University **INVITED**

Nature rarely builds without a blueprint—but the enzyme terminal deoxynucleotidyl transferase (TdT) is an exception. This unique catalyst can stitch together natural and synthetic nucleotides *without* a template, offering a molecular “3D printer” for DNA-based materials. We have transformed this capability into TdT-catalyzed enzymatic polymerization (TcEP)—a versatile, aqueous, and programmable route to DNA nanomaterials with unprecedented chemical diversity and architectural control.

With TcEP, we design aptamer-targeted DNA block copolymers that self-assemble into micelles, stably encapsulating and delivering the chemotherapeutic 5-fluorouracil. These micelles resist nuclease degradation and exhibit strikingly higher tumor cell toxicity than the free drug—demonstrating the clinical potential of enzymatically tailored nanocarriers.

Beyond free nanoparticles, TcEP lets us “grow” polynucleotide brushes directly from DNA origami nanostructures (DONs), where we can precisely dictate *when*, *where*, and *how* growth occurs. By integrating restriction enzyme triggers, these modifications become reversible. Incorporating hydrophobic, non-natural nucleotides creates surface patches that drive DONs to assemble into higher-order mesoscale architectures—opening the door to reconfigurable and adaptive biomaterials.

This work positions TcEP as more than a synthetic tool—it is a conceptual bridge between biomolecular chemistry, nanomedicine, and materials science. By merging enzyme catalysis with programmable design, we chart a new path toward stable, multifunctional, and evolvable DNA materials for next-generation therapeutic and structural applications.

Nanoscale Science and Technology Plenary Session

Room 206 A W - Session NSP-SuA

Nanoscale Science and Technology Plenary Session (ALL-INVITED SESSION)

Moderator: Nikolai Klimov, NIST

3:00pm NSP-SuA-1 Wide Bandgap III-Nitride Nanostructures: Epitaxy, Properties, and Emerging Device Applications, *Zetian Mi*, University of Michigan, Ann Arbor **INVITED**

In this talk, I will present recent advances on the molecular beam epitaxy of (ultra)wide bandgap III-nitride nanostructures and their unique optical, electronic, catalytic, piezoelectric, and ferroelectric properties. I will further discuss their emerging applications in ultraviolet optoelectronics, micro/nanoscale LEDs, high power, high frequency and high temperature electronics, and artificial photosynthesis.

3:30pm NSP-SuA-3 NSTD Graduate Award Finalists Presentations,

4:00pm NSP-SuA-5 NSTD Early Career Award Finalists Presentations,

4:45pm NSP-SuA-8 The Gas Field Ionization Source - An Overview of the Physics and the Future of this Technology, *John Notte*, Carl Zeiss **INVITED**

Beyond all reasonable expectations, the “pointy end of a needle” has spawned a remarkable collection of technologies, including the world’s highest brightness charged particle beam, the gas field ionization source (GFIS). This talk endeavors to provide a complete overview of the physics that enables and limits the performance of the GFIS technology. Additionally, this talk frames a timeline of the GFIS technology from its first realization, to commercialization, and several possible futures.

5:15pm NSP-SuA-10 Nanoscale Science and Technology Plenary Reception,

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Applied Surface Science

Room 209 B W - Session AS+BI+CA-MoM

The Power of SIMS

Moderators: Alexander Shard, National Physical Laboratory, Tanguy Terlier, Rice University

8:45am **AS+BI+CA-MoM-3 Inspection of Next Generation EUV Resists with NP-SIMS, Markus Langner, Gregrey Swieca, California State University Northridge; Won-Il Lee, Shixian Ha, Stony Brook University/Brookhaven National Laboratory; Nikhil Tiwale, Chang-Yong Nam, Brookhaven National Laboratory; Michael Eller, California State University Northridge**

The rapid advancements of the semiconductor industry demand constant innovations at every step of the microchip manufacturing process. Due to the recent jump towards extreme ultraviolet lithography (EUVL), novel approaches to photoresists are necessary, since conventional chemically amplified resists (CARs) exhibit poor EUV sensitivity and the photon density of EUV light sources is orders of magnitude lower compared to deep ultraviolet (DUV) sources. As a result of low photon density, the nature of EUVL is more stochastic, which leads to challenges in the photoresist chemistry to yield good critical dimension uniformity (CDU) and line edge roughness (LER). Hybrid resists of an organic polymer infiltrated with an inorganic metal solve the low EUV sensitivity problem while exhibiting improved etch resistance. However, it is necessary to ensure high homogeneity of the infiltration process, since the size of the infiltrated molecular moieties is comparable to the desired critical dimensions. Analytical techniques are often unable to yield analysis of the organic and inorganic components of a sample at the same time, in conjunction with high lateral resolution and can as a result not resolve inhomogeneity in the resist at a necessary spatial scale. Nano-projectile secondary ion mass spectrometry (NP-SIMS) is a mass spectrometry technique involving the stochastic bombardment of the sample using nano-projectiles separated in time and space, instead of a continuous ion beam. Each impact yields an individual mass spectrum resulting from an impact crater with 10-15nm in diameter, which allows statistical analysis of the sample and emitted secondary ions from different impacts and thus different locations. In this work we studied samples of polymethylmethacrylate (PMMA) infiltrated with InOx via vapor-phase infiltration (VPI) and investigated the uniformity of the infiltration process utilizing NP-SIMS experiments. The data suggests that one cycle of VPI yields an inhomogeneous distribution of In in PMMA, which improves with further infiltration cycles. The abundance of In species increases linearly with the number of cycles as well, indicating successful infiltration for each cycle up to four. Cluster species such as In2+, In2O+ display a non-linear increase with infiltration cycles, which leads to the hypothesis, that the amount of infiltrated indium is as desired but it aggregates in small clusters, which could affect pattern performance of the resist. This research is supported by the U.S. Department of Energy Office of Science Accelerate Initiative Award 2023-BNL-NC033-Fund.

9:00am **AS+BI+CA-MoM-4 Diffusion Study of Sodium in Hard Carbon Anode Active Materials Using a Novel in Situ ToF-SIMS Approach, Pascal Dippell, David Schaefer, Lysander Q. Wagner, Alexander Weiß, Bernd Smarsly, Marcus Rohnke, Justus Liebig University Giessen, Germany**

The incorporation, transport and storage of Na in hard carbon (HC) anodes play a crucial role in modern sodium-ion batteries (SIBs) and affect their electrochemical performance. Until now, the diffusion mechanism of Na in the HC microstructure has not been fully understood. The most prominent model, which is discussed in the literature, is the adsorption-intercalation-filling model, which includes diffusion along an interface of a pore and through the bulk of the HC. Most diffusion studies use electrochemical methods, but their evaluation is limited by overlapping processes in the cell, which prevents a complete understanding of sodium diffusion.^[1]

In this work, we developed a new in situ ToF-SIMS approach for the determination of the microscopic Na diffusion processes in HC. Therefore, we chose a well-defined HC thin film with an ultra-pure Na layer on top as model system, to obtain a precise interface between the two components. For the preparation of the HC|Na model system we connected an Na effusion cell to an ultra-high vacuum (UHV) preparation chamber, which is directly attached to the ToF-SIMS analysis chamber. This experimental setup enables a defined preparation of the HC|Na interface and, moreover, allows an accurate determination of the diffusion parameters. After a defined time, the Na diffusion into HC is stopped by cooling down the system to -130°C, and the diffusion profiles are preserved.

By SIMS depth profiling, we received complex diffusion profiles that include several transport parameters. The SIMS crater analysis was possible through the use of an implemented SPM. As a result of these depth profiles and additional finite element calculations, a separation of the different transport processes became possible. Specifically, we observed coupled Na bulk diffusion, which is a solid-state transport process, and Na pore diffusion, which occurs along an interface. The proposed diffusion model is complemented by additional experiments, which displayed the structural behavior of the HC thin films. These experiments include infiltration studies with liquid electrolytes and a tracer ion for demonstrating the accessibility of the pore system, as well as high resolution electron microscopy for imaging the structure of the HC.

References

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9:15am **AS+BI+CA-MoM-5 Investigating Ionic Motion in Memristors via Topographically Corrected ToF-SIMS, Jacob Shusterman, Oak Ridge National Laboratory, USA**

Secondary ion mass spectrometry (SIMS) is a powerful analytical technique which combines the benefits of high-resolution mass spectrometry with sub-micrometer lateral resolution to identify the spatial distribution of elements and molecules in a sample. Capable of both two- and three-dimensional (3D) analysis, SIMS enables chemical imaging of surfaces, devices, and bulk materials, proving a valuable tool for material characterization. Recent studies have successfully demonstrated applications of SIMS for the investigation of ionic motion in resistively switchable neuromorphic materials such as memristors. However, interpreting SIMS data, especially for microelectronic and nanoscale devices, can be difficult due to significant surface topography and data complexity. This makes it challenging to draw accurate conclusions regarding material composition or chemical changes (e.g. ionic motion) without addressing these features in native 3D SIMS chemical images. Here, we discuss various methods for topographical correction and reconstruction of SIMS data to study ionic mobility in memristive thin films.

Two prominent categories of data correction methods are considered including purely mathematical based post-processing techniques and multimodal approaches combining SIMS with atomic force microscopy. These methods are further applied to TaO_x/Ta memristors to reveal ionic migration associated with resistive switching. Here, lower switching currents (< 10 μA) revealed oxygen ion migration and preserved memristive behavior of the thin film device. Conversely, resistive switching with currents greater than 10 μA revealed titanium ion migration from the bottom electrode resulting in irreversible switching to a high conductive state. This research can help gain knowledge of fundamental phenomena associated with memristive behavior of materials for implementation in new generations of microelectronic devices.

This research was conducted at the Center for Nanophase Materials Sciences, which is a DOE Office of Science User Facility and using instrumentation within ORNL's Materials Characterization Core provided by UT-Battelle, LLC under Contract No. DE-AC05-00OR22725 with the U.S. Department of Energy.

9:30am **AS+BI+CA-MoM-6 Standardless, Semi-quantitative ToF-SIMS using the Full Spectrum Method (FSM), Nicolas Molina Vergara, Camille Edwards, Andrei Dolocan, Filippo Mangolini, University of Texas at Austin**

The accurate quantification of the hydrogen content in materials remains a significant analytical challenge despite its critical importance in determining material performance, stability, and functionality across numerous applications. Currently, only a limited number of techniques—such as hydrogen forward scattering (HFS) and nuclear reaction analysis (NRA)—provide accurate hydrogen quantification measurements, typically achieving relative errors between 3% and 10%. While time-of-flight secondary ion mass spectrometry (ToF-SIMS) offers excellent chemical characterization capabilities, its application for hydrogen quantification has been primarily qualitative due to matrix effect complications and the absence of appropriate relative sensitivity factors. Here, we report the first successful application of the Full Spectrum Method (FSM) for quantitative hydrogen analysis in organic polymers. Despite being documented in fewer than six publications over the past two decades, FSM represents a

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promising approach for semi-quantitative ToF-SIMS analysis by exploiting large ion clusters that incorporate numerous neutral atoms, effectively mitigating matrix effects as cluster size increases. We systematically quantified hydrogen content in a series of polymers—polypropylene (C_3H_6), polystyrene (C_8H_8), polyethylene terephthalate ($C_{10}H_{10}O_4$), and polytetrafluoroethylene (C_2F_4)—achieving a high degree of agreement with their nominal hydrogen composition and further verified by complementary measurements performed on identical samples using reflection electron energy loss spectroscopy (REELS). Our results establish a pathway for standardless, semi-quantitative ToF-SIMS analysis without requiring complementary analytical techniques, significantly enhancing the practical utility of ToF-SIMS instrumentation.

9:45am AS+BI+CA-MoM-7 AVS Medard Welch Award Talk: High Resolution Molecular Imaging by Mass Spectrometry – The OrbiSIMS Odyssey, Ian Gilmore, National Physical Laboratory, U.K. INVITED

Nuclear magnetic resonance and high-performance liquid chromatography mass spectrometry are the “gold standards” for molecular identification. However, they have limited spatial information. Conversely, techniques with high spatial resolution such as electron microscopy, have low molecular identification information. Generally, from an analytical perspective, this creates what can be termed the “Molecular Uncertainty Principle”, where the more certain we are about a molecule’s identity, the less certain we are about its localization [1]. This is a frustrating limit for measurements at the frontiers.

In 2017, NPL introduced the OrbiSIMS technology [2] with an objective to simultaneously provide molecular identification and localisation as close to this limit as possible. Since then, the number of OrbiSIMS instruments around the world has increased significantly and the community [<https://www.npl.co.uk/mass-spectrometry/orbisims/resources>] of users and range of applications has grown. Here we recount the OrbiSIMS odyssey from the original concept to the latest advances in cryo-OrbiSIMS [3,4], illustrated with examples of the applications in advanced materials [5] and life-sciences [6]. In a look to the future, the concept for a quantum detector to boost Orbitrap sensitivity by an order of magnitude will be presented [7].

References

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- [2] M K Passarelli et al., The 3D OrbiSIMS-label-free metabolic imaging with subcellular lateral resolution and high mass-resolving power, *Nature Methods*, 2017. 14 (12): p. 1175
- [3] J. Zhang et al., Cryo-OrbiSIMS for 3D molecular imaging of a bacterial biofilm in its native state”, *Anal. Chem.* 2020, 92, 13, 9008–9015.
- [4] C. L. Newell et al, Cryogenic OrbiSIMS Localizes Semi-Volatile Molecules in Biological Tissues, *Angewandte Chemie Int.* 2020, 59 (41), 18194-18200
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- [7] PCT/GB2024/050690 - Improved Spectrometer or Imaging Assembly (2024).

10:30am AS+BI+CA-MoM-10 ASSD Peter Sherwood Award Talk: In situ Detection of Proteins, Xenobiotics and Metabolomics via OrbiSIMS, David Scurr¹, University of Nottingham, UK INVITED

The application of secondary ion mass spectrometry (SIMS) to detect of proteins at surfaces and within tissue has significant potential in healthcare, medicine and medical device development. This approach offers the potential of an *in situ* analysis and does not require digestion and/or matrix application prior to analysis. The analysis of proteins has previously been limited due to fragmentation resulting in only single amino acid secondary ions, devoid of primary structural information. Here we use the OrbiSIMS technique to achieve *in situ* label and matrix-free 3D mapping of undigested proteins at surfaces. We successfully applied de novo sequencing for identification of proteins using fragments generated by the GCIB. We analysed 16 model protein films in a range of sizes from insulin (6 kDa) to fibronectin (272 kDa), achieving amino acid sequence coverages up to 53% [1]. Additionally we assigned highly specific protein ions in a monolayer biochip sample and successfully assigned diagnostic peptide

sequences from collagen, keratin and corneodesmosin within the depth profile through human skin [1].

Further analysis of native *ex vivo* human tissue also allowed the elucidation of the chemical landscape of the *stratum corneum* including subtle chemical variations within single skin strata and / or individual cells [2]. In addition to the biological analysis enabled using the OrbiSIMS, the relatively high sensitivity and chemical specificity offers the ability to detect the distribution of xenobiotic compounds delivered to skin, namely antibacterial, cosmetic and pharmaceutical agents have also been demonstrated. This includes the detection of xenobiotic chemistries delivered to human skin *in vivo* and *ex vivo* at concentrations <100 ppm [2].

In healthcare applications, the delivery of mRNA-based vaccines against SARS-CoV-2 have been clearly demonstrated in recent years [3]. This research aspires to characterise both delivery of LNPs to cells and provide insights into their metabolic impact using OrbiSIMS. Peaks related to components of the LNP were identified using reference standards and observed to have peak intensities at dosage time 4 hours. Significant changes in biological compounds were investigated to determine metabolic pathways affected using MetaboAnalyst. Over 600 endogenous metabolites have been identified, significant changes in endogenous compounds were identified including fatty acids and small metabolites, correlating with LNP uptake, indicating these mechanisms were impacted by LNP delivery.

[1]. Kotowska et al., *Nature Communications*, 11 (1), 2020

[2]. Starr et al. *PNAS*, 2022, 19 (12)

[3]. Roces et al. *Pharmaceutics* 2020, 12, 1095

11:00am AS+BI+CA-MoM-12 Delineating Spatial Cellular Complexities Using Multi-omics Approach by GCIB-SIMS, Hua Tian, University of Pittsburgh INVITED

The molecular and cellular microenvironment plays a critical role in determining biological function, multicellular organization, and cell fate. However, delineating multilevel biomolecular interactions within the same tissue or cells remains challenging due to limitations in analytical approaches and sample preparation compatibility.

To address this, we present a multimodal SIMS approach incorporating water cluster ion/ C_{60} beams and a cryogenic workflow, enabling untargeted lipidomics/metabolomics imaging (in both positive and negative modes) and targeted proteomics in near-native-state tissue at 1 μ m spatial resolution. Combined with neuron-linked computational analysis, this method reveals the biomolecular networks and metabolic states of distinct cell types.

To demonstrate the power of this approach, we imaged liver and skin tissues, integrating metabolites, lipids, and proteins within the same cells to visualize cell-type-specific metabolic variations. Our workflow captures >200 key ions (e.g., lipids and essential metabolites) and identifies diverse cell types (e.g., stem cells, lymphatic cells, immune cells, and senescent cells) in regions such as the liver portal/central vein and hair follicles.

Further computational integration aligns multiomics data with segmented cells for clustering analysis, uncovering metabolic and cellular gradients in the liver and the stem cell microenvironment of hair follicles during aging. This study establishes cryogenic Dual-SIMS as a powerful tool for single-cell multiomics imaging, revealing that metabolic and cellular organization is crucial for tissue and stem cell function.

11:30am AS+BI+CA-MoM-14 Arsenic Quantification in SiGe: Advancing Accuracy with Orbitrap™-SIMS, Alexis Franquet², IMEC Belgium; Alexander Pirkl, IONTOF GmbH, Germany; Rita Tilmann, IMEC Belgium

For over 50 years, Secondary Ion Mass Spectrometry (SIMS) has been crucial in the microelectronic industry providing precise analysis of dopants and impurities in semiconductors [1]. Initially used for blanket samples, SIMS now must analyze patterned samples due to the shift from 2D to 3D devices to continue to support effective process development and optimization in the Fab. This shift presents challenges, including measuring features smaller than the beam spot size and dealing with complex mass spectra with more and more mass interferences due to increased number of elements present in the devices. As a result, SIMS analysis has become increasingly complex, making it harder to extract precise information about bulk and layer composition, dopant quantification and layer uniformity. To meet this need of ultimate lateral resolution without sacrificing sensitivity, innovative approaches like Self-Focusing SIMS (SF-SIMS) have been developed, allowing SIMS to profile dopants and quantify bulk composition

¹ ASSD Peter Sherwood Award

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² JVST Highlighted Talk

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of multilayers stacks in very small structures [2]. This advancement is particularly crucial for modern devices that incorporate materials such as SiGe doped with As. However, measuring As in SiGe remains a significant challenge due to strong mass interference between As and GeH signals at mass 75 [3]. This challenge is even more pronounced for low-dose As implantation in small SiGe structures, where conventional SIMS instruments lack the mass resolution required for accurate quantification. In this study, we leverage the cutting-edge Orbitrap mass analyzer in the M6 Hybrid instrument to overcome these limitations. The Orbitrap enables mass resolution of more than 240000, which allows to suppress the mass interference at mass 75. We will assess the ability of the Orbitrap to accurately quantify As in SiGe samples, comparing its detection limits, dynamic range, and overall performance against other mass analyzers, including Time-of-Flight, Magnetic Sector, and Quadrupole systems. We will show how the use of calibration curves for both As and Ge quantification for As:SiGe ranging from 0 to 100 Ge at.%, allows to apply SF-SIMS (in Orbitrap) to quantify accurately As:SiGe lines of less than 20nm wide.

[1] P.K. Chu, Materials Chemistry and Physics, 38(3) (1994) 203

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11:45am AS+BI+CA-MoM-15 Evidence of Surface Localization of Hydrogen and Zirconium Hydride in Zircaloy with Time-of-Flight Secondary Ion Mass Spectroscopy (ToF-SIMS), **Edward Gillman**, Naval Nuclear Laboratory

The solid to vapor phase transition boundary of any material is separated by a surface that exists at any finite temperature. To account for the internal energy due to the surface separating the solid and the vapor phases, the energy of the system is modified by a factor proportional to the surface area. A constant of proportionality, γ , which modifies the internal energy due to a surface is referred to as the surface tension or the surface free energy. Surface stress, which is directly related to surface tension, modifies the distribution of hydrogen and zirconium hydrides near the surface in Zircaloy (Zr-2, Zr-4, Zr 2.5 wt. % Nb). Depth profiling performed with Time-of-Flight Secondary Ion Mass Spectroscopy (ToF-SIMS) was able to directly identify the surface localization of hydrogen and zirconium hydride.

Biomaterial Interfaces

Room 209 F W - Session BI1-MoM

Characterization of Biological and Biomaterials Surfaces

Moderators: Pierluigi Bilotto, TU Wien, Morgan Hawker, California State University, Fresno

8:15am BI1-MoM-1 Determine Protein Conformation and Orientation at Buried Solid/Liquid Interfaces in Situ, **Zhan Chen**, University of Michigan **INVITED**

Interfacial protein properties play important roles in many research areas and practical applications, such as biomedical materials, marine antifouling coatings, membranes for biological molecule separation, biosensors using surface immobilized enzymes, and antibody drug manufacturing and storage, etc. The properties of proteins at interfaces are determined by molecular structures of interfacial protein molecules. In this study, a nonlinear optical laser spectroscopic technique, sum frequency generation (SFG) vibrational spectroscopy, has been used to determine conformations and orientations of proteins at buried solid/liquid interfaces in situ in real time. A combined approach using molecular dynamics simulation, SFG experimental data, Hamiltonian spectra calculation, spectra matching, and isotope labeling was used for interfacial protein structure determination in this research. This method was successfully applied to study protein Gb1 adsorption to a variety of substrates, interfacial antibody – surfactant interactions, protein dimer formation at interface, membrane protein complex structure, and time-dependent protein structural change during the adsorption process.

8:45am BI1-MoM-3 Cryo-XPS Characterisation and Solution Realism for Functional Nanoparticle Analysis, **Liam Soomary**, Jonathan Counsell, Kratos Analytical Limited, UK; **David Cant**, William Lee, National Physical Laboratory, UK

A crucial part of nanoparticle engineering relies on understanding and controlling surface functionalisation. Traditionally, analysis can be performed with techniques such as Transmission Electron Cryomicroscopy

(CryoTEM) [1], however quantitative surface characterisation remains a challenging prospect.

X-ray Photoelectron Spectroscopy (XPS) has long been an exemplary technique for quantitative surface analysis, offering high sensitivity to elemental compositions and chemical states. However, its requirement for ultra-high vacuum (UHV) often compromises the relevant conditions under which most organic nanoparticle systems operate, leading to questions about their morphology and stability of their functionalised groups once the solvent environment is removed [2]. Recent developments in cryogenic XPS (Cryo-XPS) aims to bridge this gap. Through flash-freezing, liquid nanoparticles can be preserved in a close-to-native state within UHV conditions, minimising environment induced changes and enabling insights without significant structural perturbations [3].

In this talk, we discuss complementary techniques for solution-based measurements and highlight the benefits of Cryo-XPS in probing functionalised nanoparticles. Special attention is given to PEG-coated nanoparticles, which are widely used in drug delivery systems and biomaterials research. As we illustrate – through a case study of lipid nanoparticles – how sample preparation, handling and methodology can improve quantitative surface analysis of these systems.

[1] Judith Kuntsche et al., *Cryogenic transmission electron microscopy (cryo-TEM) for studying the morphology of colloidal drug delivery systems*, International Journal of Pharmaceutics, (2011), 120-137, DOI: 10.1016/j.ijpharm.2011.02.001

[2] S. Mourdikoudis et al., *Characterization techniques for nanoparticles: comparison and complementarity upon studying nanoparticle properties*, The Royal Society of Chemistry, (2018), 12871-12934, DOI: 10.1039/C8NR02278J

[3] G. Weiseenberger et al., *Understanding the invisible hands of sample preparation for cryo-EM*, Nat. Methods, (2021) 18:5, DOI: 10.1038/s41592-021-01130-6

9:00am BI1-MoM-4 GCIB-SIMS in the study of Lymphoma, **John Fletcher**, Simon Uzoni, Noora Neittaanmäki, Vasilis Chatzikyriako, Daniele Zanchin, University of Gothenburg, Sweden

The advent of gas cluster ion beams (GCIBs) for SIMS has greatly benefited the analysis of biological samples through the generation of increased intact molecular secondary ions. This has enabled detailed molecular maps to be generated in order to perform "molecular pathology", elucidating chemical changes associated with different diseases. In this study GCIB-SIMS, in this case using a 40 keV $(CO_2)_7^{+}$ ion beam on a J105 ToF-SIMS instrument (Ionoptika Ltd.) was used to map the intact lipid signals across 14 human lymph node samples representing diffuse large B-cell lymphoma (DLBCL) and control samples. DLBCL is a common and aggressive form of lymphoma resulting in a diffuse distribution of cancerous cells amongst the typical lymph cells. The analysis allowed the samples to be classified as malignant or non-malignant and also highlighted additional aggressive cancer signature in a DLBCL sample with an unusually high proliferation index. A complementary, combined k-means/image PCA approach was used to interrogate the data highlighting the pros and cons of the different approaches and potential sources for misclassification/diagnoses resulting from the heterogeneity of the DLBCL samples. Compared to other cancer samples the lipid markers associated with cancer can appear reversed as many studies have classed inflammatory responses to cancer as part of the cancer signature. In the lymph node tissue, the onset of malignant transformation is associated with a decrease in inflammatory character. While delivering new information regarding the chemistry of lymphoma the results also highlight the need for cellular precision with high chemical specificity and sensitivity, and the challenges associated with spectral/spatial classification of such complex samples and data where differently aggressive cancer samples show different signatures and pockets of different cell types, in this case histiocytes, can be shown intermediate cancer/healthy lipid profiles.

9:15am BI1-MoM-5 Optical Dynamics of Electrochemically Driven Reflectin Protein Films, **Yin-Chen Lin**, Dan Morse, Lior Sepunaru, **Michael Gordon**¹, University of California at Santa Barbara

Near- and sub-wavelength photonic structures are used by different organisms (e.g., insects, cephalopods, fish, birds) to create vivid and often dynamically-tunable colors, as well as create, manipulate, or capture light for vision, communication, crypsis, photosynthesis, and defense. This talk will highlight our work to understand and translate the biological

¹ JVST Highlighted Talk

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mechanism of reflectin, an intrinsically disordered protein found in squid skin cells that is responsible for dynamically tunable structural color, into new materials and device venues with the ultimate goal of using biological components and paradigms to create novel multi-scale structures with functional properties. Neuronally triggered-phosphorylation drives the condensation of reflectin proteins *in vivo*, resulting in osmotic dehydration of cell membrane-encapsulated layers of reflectin-loaded lamellae and low refractive index extracellular space that effectively function as a biological and tunable distributed Bragg reflector (DBR).

In close analogy to this physiological phenomenon, we demonstrate here that electrochemical reduction enables tunable and reversible control of reflectin condensation and thin film water fraction, allowing one to electrochemically tune reflectin film refractive index and thickness, just as that occurring in the squid [1]. Electrochemical correlative ellipsometry and surface plasmon resonance spectroscopy were developed to trigger and simultaneously analyze the dynamic changes in optical properties of reflectin films to further elucidate and mimic the color-changing mechanisms in squid skin. Measurements indicate that electrochemical reduction allows precise modulation of film refractive index (1.36 to 1.40) and thickness (40-100 nm). Condensation-driven, cyclical FRET emission from reflectin films is also demonstrated using electrochemical triggering as a preface to implementing reflectin as a triggerable optical medium in 1D gratings. Overall, this work opens new approaches to analyze biophysical mechanisms governing protein condensation and structural color regulation, and facilitates the design of bio-enabled functional materials and devices that bridge the biotic-abiotic gap.

[1] Y.-C. Lin, C. Yang, S. Tochikura, J.R. Uzarski, D.E. Morse, L. Sepunaru, and M.J. Gordon, *Advanced Materials* 2411005 (2025).

9:30am **BI1-MoM-6 Interaction Dynamics of *Borrelia* Surface Proteins with Fibronectin, Nuri Oncel, Kavindi Hewage, Carlos Munoz, Mehmet Ozdogan, Catherine Brissette**, University of North Dakota

Lyme disease, caused by the bacterium *Borrelia burgdorferi*, is a significant public health concern in North America, with approximately 500,000 cases reported annually in the United States. The dissemination of *B. burgdorferi* from the initial tick bite site to various tissues is facilitated by surface adhesins that bind to extracellular matrix (ECM) proteins such as fibronectin (Fn). This study investigates the binding dynamics of *B. burgdorferi* surface proteins RevA, BBK32, BmpA, OspA, and OspC to Fn using atomic force microscopy-based single-molecule force spectroscopy (AFM-SMFS). Our results demonstrate that RevA and BBK32 form strong, stable bonds with Fn, highlighting their roles as key mediators of host-cell attachment. By quantifying the rupture forces and kinetic parameters of these interactions, we provide a deeper understanding of *B. burgdorferi* adhesion mechanics and offer insights into potential therapeutic strategies targeting early bacterial attachment.

9:45am **BI1-MoM-7 Ready, Settlement, Action! Leveraging Microcomputed Tomography in Barnacle-Substrate Interactions, Brittney Mitchell, Beatriz Orihuela, Duke University; Gary Dickinson, The College of New Jersey; Daniel Rittschof, Duke University**

Barnacle fouling is a persistent challenge in marine environments, contributing to loss of performance, increased fuel costs, material degradation and substantial economic costs. Human and environmental health concerns are driving regulations and interest in transitioning away from broad biocidal antifouling towards surface-engineered materials that resist biofouling through physical and chemical modifications. Optimizing these materials requires robust, quantitative and qualitative insight into interactions between barnacles and substrates. The barnacle-material interface is dynamic whether looking down from the barnacle or up from the surface. Barnacles attack surfaces with adhesives, enzymes, metabolites, surfactants and reactive oxygen species. Surfaces leach chemicals, contaminants, catalysts and additives, many of which are biologically active orders of magnitude below engineering additions. We apply high-resolution microcomputed tomography (μ CT) to visualize and quantify intact barnacle morphologies and surface architecture in 3D macro- to microscale domains. We provide detailed evaluation of exoskeletal and adhesive plaque morphology, as well as substrate conformity or modification. Reconstructions of scans into visual media helps facilitate comparative analysis across substrate types and species. Our data show substrate-driven plasticity in barnacle plate and adhesive plaque phenotypes and evidence of substrate alteration beneath living barnacles. These findings demonstrate the utility of μ CT and 3D visualization as tools for comprehensive characterization of biofouling interactions.

Biomaterial Interfaces

Room 209 F W - Session BI2-MoM

Biomolecules and Biophysics at Interfaces

Moderators: Kenan Fears, U.S. Naval Research Laboratory, Markus Valtiner, Vienna University of Technology, Austria

10:30am **BI2-MoM-10 How Swelling Affects Microscale Wetting and Friction of Soft Interfaces, Jonathan Pham**, University of Cincinnati **INVITED**

Soft materials are found in a host of applications, from adhesives and coatings to natural and synthetic biomaterials. Many of these materials comprise a lightly crosslinked polymer network, which can also be infused with a compatible liquid (i.e., swelling). Swelling offers additional functionality, like molecular transport, lubrication, and control over mechanical properties. However, understanding the behavior of soft and swollen interfaces is an ongoing challenge. For example, when crosslinked solids are sufficiently soft, or the characteristic size scale is small, they display liquid-like characteristics like capillarity, even without an infused liquid. When the networks are swollen, the swelling liquid itself provides true liquid behavior, creating multi-phase situations that are even more complex. Here we will leverage confocal microscopy to show how combinations of solid and liquid characteristics control the wetting on soft, swollen networks. In addition to network elasticity, we demonstrate that surface tension, liquid separation, and osmotic pressure are important considerations. We expand on our findings by developing a route to visualize dynamic contact lines of a dynamic, sliding drop. In addition to wetting, we exploit a combination of confocal microscopy and colloidal probe microscopy to study the effects of swelling on microscale friction. In this situation, creasing occurs, leading to solid-like stick-slip behavior. Creasing is mitigated by swelling, which appears to be a function of the swelling ratios.

11:00am **BI2-MoM-12 Stability of Semi-Conducting Oxides Under Photocatalytic and Hydrogen Evolving Conditions, Tatjana Ott, Ruri Lee, Markus Valtiner**, Technische Universität Wien, Austria

Transparent semiconducting oxides play a critical role in fields ranging from corrosion, electrocatalysis and biocatalysis to the development of artificial leaf systems for solar fuel generation. However, their long-term stability remains a significant challenge, with photocorrosion being a major factor limiting performance. I will demonstrate how we employ an electrochemical flow cell coupled with inductively coupled plasma mass spectrometry (ICP-MS) to enable *in situ*, time-resolved monitoring of zinc release from zinc oxide (ZnO) single crystals under UV irradiation. This approach provides direct insights into the degradation pathways of ZnO , a key material in photoelectrochemical systems, including those inspired by natural photosynthesis.

We investigate the dissolution behavior of ZnO with (0001) and (1010) crystal orientations across a range of acidic and alkaline pH levels, examining potential-dependent dissolution under both oxygen and hydrogen evolution conditions. Our results highlight the significant influence of UV light and electrolyte pH on stability, closely linked to the intrinsic surface chemistry of ZnO . Notably, the polar ZnO (0001) orientation demonstrates superior stability at low potentials and under hydrogen evolution conditions. In contrast, non-polar ZnO (1010) exhibits higher dissolution rates, limiting its suitability for long-term water splitting and biocatalytic processes. It also highlights its role in corrosive processes where hydrogen can penetrate into materials leading to embrittlement.[1]

These findings underscore the critical role of surface structure and chemical stabilization in enhancing the durability of semiconducting oxides for materials stable against hydrogen permeation and next-generation energy conversion technologies. By optimizing surface design and understanding fundamental degradation mechanisms, it is possible to develop more resilient electroactive materials. I will discuss how the approach can be extended to other materials.

Reference.

[1] Dworschak et al. in *ACS Appl Mater Interfaces*, 2020 Nov 9;12(46):51530–51536. doi: 10.1021/acsami.0c15508
[https://doi.org/10.1021/acsami.0c15508]

[2] Ott et al. submitted

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11:15am BI2-MoM-13 PFAS-Protein Interactions: Effects of Perfluoroctanoate on the Structure and Function of Cytochrome C, *William Maza*, US Naval Research Laboratory

The unique chemical nature of perfluoroalkyl substances (PFAS) renders it resistant to common metabolic processes. Consequently, the resulting bioaccumulation of PFAS has been implicated in long-term health risks associated with liver, kidney, and thyroid disease, increased cholesterol (hypertension and heart disease), disruption of reproductive function, and disruption of the immune response to name a few. However, the cytotoxic effects of PFAS in human organs is still poorly understood. Recent evidence points to increased levels of reactive oxygen species (ROS) as a primary source of cytotoxicity. The cause of the observed increase in ROS has to be established. To better understand the potential disruption of cellular respiration by PFAS we examine the effect of PFAS on the structure and function of the heme-containing electron carrier cytochrome c (Cc). We observe that in the presence of perfluoroctanoate (PFOA) Cc undergoes significant structural changes up to 2mM PFOA. These PFAS-induced conformational changes include disruption of the putative MET80-heme charge transfer absorption band and increase in the Trp59 fluorescence indicating disruption of the Cc tertiary structure and at least partial exposure of the active site to water. The disruption of the heme coordination and tertiary structure of the Cc induces a significant change in the electrochemical redox potential of the active-site heme group which likely results in short circuiting its function as an electron shuttle between cytochrome C reductase and cytochrome C oxidase in the electron transfer pathway. This likely results in downstream disruption of respiratory process and buildup of ROS.

11:45am BI2-MoM-15 Influence of Surface Structural and Electronic Properties on Antibacterial Action of Nano- and Microcrystalline Fe:ZnO, *Yuri M. Strzhemechny, John H. Brannon, Dustin A. Johnson, Tiffany Y. McHenry, Devansh Kalluholematham, Texas Christian University; Rachel E. Cuth, Kutztown University; Kevin Sun, James Martin High School*

Antibacterial action of nano- and microcrystalline ZnO has been well established, although the fundamental mechanisms driving such cytotoxicity is still debated. In our recent works we suggested a model for an antibacterial action of ZnO via surface defect-mediated dissolution. To further validate our model, we perform surface/subsurface modification of hydrothermally grown ZnO nano- and microparticles in order to modulate their antibacterial efficacy. It appears that the instability of the ZnO in antibacterial assays results from the defect-rich reconstruction of polar surfaces with strong intrinsic dipole moment within the wurtzite lattice. In theory, Fe doping of ZnO may suppress this dipole and stabilize the free surface while preserving the wurtzite lattice. Importantly, iron ions are beneficial species for bacteria and thus do not change the cytotoxicity of the assay. We modify the hydrothermal synthesis protocol to obtain Fe:ZnO micro- and nanoparticles with controllable doping concentrations. We perform systematic optoelectronic and physicochemical characterization of our particles before and after their interaction with bacteria in different growth media to verify both the surface stability of our ZnO specimens and the effects on the antibacterial action.

12:00pm BI2-MoM-16 Molecular Insights into the Influence of Tail Architecture on Self-Assembly of Peptide-Polymer Amphiphile, *Sabila Kader Pinky, North Carolina State University; Benjamin Allen, Abigail Knight, University of North Carolina at Chapel Hill; Yaroslava Yingling, Merve Fedai, North Carolina State University*

Peptide-polymer amphiphiles (PPAs) combine functional peptides with a hydrophobic tail that drives self-assembly in aqueous environment. Their ability to form well-defined nanostructures with tunable physical properties makes them ideal candidates for a wide range of applications. However, predicting and tuning these features remains challenging due to the complex interplay of molecular interactions. Here, we systematically investigated the self-assembly of a random coil peptide (XTEN2)-based PPAs by varying the side chains of alkyl acrylate tail (ethyl, n-butyl, tert-butyl, hexyl, and cyclohexyl). We used all-atom molecular dynamics (AMD) simulations to examine how molecular interactions influence the formation, structure, and stability of micellar assemblies. The simulations reveal the formation of a range of core morphologies, including worm-like, perforated, spherical, and multi-core structures. Our findings indicate that the balance between tail-to-tail versus tail-to-water non-bonded interactions primarily determines the micellar morphology. Additionally, the extent of core hydration also impacts the structural stability. Furthermore, the comparison between experimentally obtained particle sizes and simulation-obtained particle sizes supports the accuracy of our computational approach in replicating real particle sizes and indicates that the models accurately

capture the size characteristics of these self-assembled structures. We anticipate that the insight from this study will collectively provide a comprehensive understanding of how molecular properties and interactions drive the self-assembly and structural diversity of PPAs, offering insights into designing nanostructures with tailored morphologies for specific applications.

CHIPS Act : Semiconductor Manufacturing Science and Technologies

Room 207 A W - Session CPS+MS-MoM

Digital Twins and Advanced Packaging for Semiconductor Manufacturing

Moderators: *Tina Kaarsberg, U.S. Department of Energy, Advanced Manufacturing Office, John Lannon, Micross*

9:00am CPS+MS-MoM-4 An Overview of Advanced Semiconductor Packaging Activities at Arizona State University, *Christopher Bailey, Hongbin Yu, Arizona State University*

Arizona State University (ASU) is engaging in all aspects of the chips act including R&D as well as Education and Workforce Development (EWD) activities. At our MacroTechnology Works (MTW) facility, which is a refurbished Motorola Fab, we are installing a 300mm Fan Out Wafer Level Packaging (FOWLP) pilot line based on the DECA M-Series process flow. In addition to this, investments in metrology, EDA, and Multi-Physics modelling have been made to support innovation for future heterogeneous integrated systems.

During this presentation, I will provide an overview of advanced packaging activities underway at ASU which includes projects in the Microelectronics Commons SWAP-Hub program as well as the NAPMP SHIELD-USA project that is pushing the envelop for fan-out wafer level packaging for new substrate technologies with an aim to achieve 0.5um line/spacing and bump pitches as low as 2um. In addition to this, the presentation will detail education and workforce development programs for advanced semiconductor packaging.

9:15am CPS+MS-MoM-5 Overview of research at the Center for Heterogeneous Integration Research in Packaging (CHIRP) Center, *Srikanth Rangarajan, Binghamton University* INVITED

The Center for Heterogeneous Integration Research in Packaging (CHIRP) is a leading research center dedicated to advancing the field of heterogeneous integration (HI) for next-generation electronic systems. This talk provides an overview of CHIRP's research activities, focusing on novel packaging technologies, materials, and designs that enable the integration of diverse components with enhanced performance and functionality. We will highlight key projects and recent advancements in areas such as chiplet-based integration, 2.5D/3D packaging, thermal management, and reliability. Furthermore, the presentation will outline CHIRP's collaborative ecosystem and its role in shaping the future of microelectronics through innovative HI solutions.

9:45am CPS+MS-MoM-7 Re-Shoring Advanced Packaging Capabilities in a Secure Environment, *John M. Lannon Jr, Rex Anderson, Micross Advanced Interconnect Technology*

The CHIPS Act has garnered a lot of attention for the re-shoring (or on-shoring) of semiconductor device manufacturing, which includes device manufacturing and downstream packaging, assembly, and test of the devices. Prior to the CHIPS Act, the DoD had been developing its own initiative to de-risk mission critical microelectronics supply chain needs, the Reshore Ecosystem for Secure Heterogeneous Advanced Packaged Electronics (RESHAPE) program. The goal of this program is to ensure the defense industrial base (DIB) has access to a secure, domestic advanced packaging, assembly, and test capability. Initial awards for the program were made late in 2023 for four technical elements: 300mm wafer bumping and 300mm wafer preparation at Micross Advanced Interconnect Technology (a post-CMOS wafer processing facility in North Carolina); Fan-out Wafer-Level Packaging (FOWLP) at the SkyWater facility in Kissimmee, Florida; and Si interposer technology through BRIDG/SkyWater collaboration at the SkyWater facility in Kissimmee, Florida. In this paper, we will provide a brief overview of the RESHAPE program, then focus on the Secure Center for Advanced Packaging Excellence (SCAPEx) project awarded to Micross, covering both current capabilities and future advanced packaging capabilities coming online over the next 12 months.

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10:00am **CPS+MS-MoM-8 ML-based Co-design of TSV and TGV Interposers for Advanced Packages, Pouria Zaghari, Sourish Sinha, Douglas Hopkins, Jong Ryu, North Carolina State University**

Copper-filled vias are essential elements in advanced 2.5D and 3D electronic packaging, facilitating reduced form factors and enhanced system performance. This study presents a numerical parametric investigation and a machine learning–driven optimization of through-silicon vias (TSVs) and through-glass vias (TGVs). The optimization targeted three primary performance metrics: copper protrusion, thermal resistance, and electrical parasitics. The coupled influences of aspect ratio (AR) and via pitch were systematically evaluated for both square and hexagonal via array configurations.

The parametric results indicate that glass substrates outperform silicon in mitigating copper protrusion (by up to 47.5%) and reducing mutual capacitance (by up to 67.6%), while TSVs exhibit superior thermal conductivity. A high AR was associated with reduced copper protrusion, whereas low pitch and hexagonal arrays enhanced thermal performance. Conversely, high pitch and low AR configurations were more effective in minimizing electrical parasitics.

For optimization, a conventional genetic algorithm (GA) was benchmarked against a novel online artificial neural network (ANN)–based approach. The ANN method achieved a 61.3% reduction in computational time relative to the GA, underscoring its suitability for high-fidelity optimization of complex electronic packaging designs.

This framework has significant potential for integration into a digital twin environment, wherein a real-time virtual replica of an electronic package can accurately reproduce its electrical, thermal, and mechanical behavior. The computational efficiency of the ANN-based approach enables rapid, high-resolution simulations necessary for real-time digital twin applications—capabilities that are impractical using traditional GA-based optimization due to prohibitive computational demands.

The significance of this work lies in its multidisciplinary co-design methodology, simultaneously accounting for electrical, thermal, and mechanical performance metrics. By leveraging a computationally efficient ANN-based optimization, the framework offers a scalable pathway toward adaptive, self-correcting electronic systems, where digital twins can be employed to predict, monitor, and proactively mitigate potential reliability risks.

10:30am **CPS+MS-MoM-10 Digital Twins and the SRC MAPT2 Chapter on Digital Twins and Applications, Robert Baseman, IBM Research Division, T.J. Watson Research Center** **INVITED**

The semiconductor industry anticipates substantial reductions in manufacturing costs and product times to market as a result of deploying digital twins throughout the design and production ecosystem. Recognizing this, the SMART USA Institute was established as part of the CHIPS Act to accelerate efforts to develop, validate, and use digital twins to improve domestic semiconductor design, manufacturing, advanced packaging, assembly, and test processes.

Here we summarize Chapter 12 of the Semiconductor Research Corporation's Microelectronics and Advanced Packaging Technologies Roadmap2 (SRC MAPT2), a collaborative effort of experts from academia, industry, and national labs. This new Chapter in MAPT2 is intended to provide a digital twin focus to the industry Roadmap, to inform the SMART USA Institute strategy and to illustrate how digital twins will support the US NSTC Strategic Plan and the National Strategy on Microelectronics Research.

Digital twins of relevance to the semiconductor industry and considered in the Chapter include twins of a vast scope: from twins of atomic scale surface chemistry processes with a characteristic time scale of picoseconds to twins of global supply chains with a characteristic timescale of years.

The Chapter characterizes the state of the art, future industry requirements, challenges to be overcome, and enabling technical directions for twins *per se*, infrastructure enabling development & deployment of twins, and applications of twins. The Chapter includes some perspectives on assessing the impact of twin deployment and concludes with some illustrations of how digital twins will support several domestic strategic initiatives.

11:00am **CPS+MS-MoM-12 Digital Twins Meet Materials Science: Real-Time AI Analysis for Advanced Manufacturing, Jeff Terry, Illinois Institute of Technology**

We have developed an artificial intelligence (AI)-driven methodology for the automated and reliable analysis of advanced materials characterization measurements, including Extended X-ray Absorption Fine Structure (EXAFS), Nanoindentation, X-ray Emission Spectroscopy (XES), and X-ray Photoelectron Spectroscopy (XPS). These techniques are critical for probing the chemical, structural, and mechanical properties of materials at the nanoscale and are commonly deployed across semiconductor fabrication lines for quality assurance, process control, and failure analysis.

At the heart of our approach is a genetic algorithm capable of extracting physically meaningful structural parameters by fitting experimental spectra to a curated set of candidate chemical configurations. Analysts provide a preliminary list of potential compounds and corresponding computational inputs, after which the algorithm iteratively refines the model to best match the observed data. This process is implemented in our open-source Python analysis framework, **Neo**, which is designed to support modular, high-throughput, and reproducible analysis pipelines.

Importantly, Neo interfaces directly with the **XPS Oasis** and **XES Oasis** databases—comprehensive, structured repositories of curated spectral reference data. These databases allow Neo to draw from a rich library of previously characterized materials and electronic structures, significantly enhancing its ability to identify subtle differences in chemical states and bonding environments. This capability is especially valuable in semiconductor production, where minor variations in composition or surface chemistry can have outsized impacts on device performance and reliability.

By embedding this AI-enabled analysis tool within production environments, manufacturers can achieve **real-time, in-line monitoring** of materials during fabrication. Moreover, by streaming these insights into **digital twin platforms**, facilities can build continuously updated virtual models of the physical production line. These models enable predictive analytics, fault detection, process optimization, and adaptive control—ultimately reducing downtime, improving yield, and enhancing materials traceability throughout the supply chain.

Nanoscale Science and Technology

Room 206 A W - Session NS1-MoM

Frontier in Nanoscale Electron, Ion, and Scanning Probe Imaging

Moderators: Marek Kolmer, Ames National Laboratory, Robertus Elberse, NIST

8:15am **NS1-MoM-1 Design, Construction, and Performance of a Dilution Refrigerator-Based Esrspm System with Cryogenic Switches, Robertus Elberse, Dengyu Yang, Sungmin Kim, Dilek Yildiz, Daniel Walkup, Steven Blankenship, Joseph Stroscio, NIST** **INVITED**

Electron Spin Resonance using a Scanning Tunneling Microscope (ESRSTM) relies on reaching cryogenic temperatures to achieve favorable thermal population distributions of quantum states. To date, most ESRSTMs operate between 300 mK and 4 K. Here, we present an ESRSTM that can operate down to 10 mK using a dilution refrigerator (DR). The design of the system is multi-modal, combining STM, AFM, electrical transport and ESR measurement capabilities. To characterize the microwave transmission, we have measured the frequency-dependent radio frequency (RF) transmission using a Josephson tunnel junction, consisting of an Al probe tip and Al (111) sample at 10 mK. Excellent transmission was observed up to 40 GHz in comparison to previous measurements in other laboratories. At the base temperature of the DR (10 mK) scanning tunneling spectroscopy can reach an energy resolution of \approx 10 μ eV, comparable to the energy broadening expected at base temperature [1]. However, when RF lines are sufficiently transmissive, as we have measured in our DR ESRSPM, the thermal noise introduced by photons originating at room temperature can cause increased broadening effects. This may reach orders of magnitude higher than broadening given by the base temperature of the DR. We will show how adding attenuators and cryogenic switches may help reduce such photonic noise and subsequently show its effect on the decoherence time of single atom qubits.

[1] J. Schwenk *et al.*, “Achieving μ eV tunneling resolution in an in-operando scanning tunneling microscopy, atomic force microscopy, and

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magnetotransport system for quantum materials research," *Rev. Sci. Instrum.*, vol. 91, no. 7, p. 071101, Jul. 2020, doi: 10.1063/5.0005320.

8:45am NS1-MoM-3 Magnetic Coupling in Graphene Nanoribbon Quantum Dots and Looking Beyond, Percy Zahl, Brookhaven National Laboratory; Alexander Sinitkii, Maman Sarker, University of Nebraska-Lincoln, USA; Peter H. Jacobse, Michael F. Crommie, University of California, Berkeley; Anshul Saxena, Walker Department of Mechanical Engineering University of Texas; Ziyi Wang, Materials Sciences Division Lawrence Berkeley National Laboratory Berkeley; Emma Berger, Department of Physics University of California, Berkeley; Narayana R. Aluru, Walker Department of Mechanical Engineering University of Texas

Carbon-based quantum dots (QDs) enable flexible manipulation of electronic behavior at the nanoscale, but controlling their magnetic properties requires atomically precise structural control. While magnetism is observed in organic molecules and graphene nanoribbons (GNRs), GNR precursors enabling bottom-up fabrication of QDs with various spin ground states have not yet been reported. Here the development of a new GNR precursor that results in magnetic QD structures embedded in semiconducting GNRs is reported.

Inserting one such molecule into the GNR backbone and graphitizing it results in a QD region hosting one unpaired electron. QDs composed of two precursor molecules exhibit nonmagnetic, anti ferromagnetic, or anti ferromagnetic ground states, depending on the structural details that determine the coupling behavior of the spins originating from each molecule.

We present on surface precisely synthesized GNR structures imaged using high-resolution atomic force microscopy (HR-AFM) together with high resolution scanning tunneling spectroscopy (STS) to identify local spin properties localized at specific sites within those carbon based structures at the atomic scale.

The synthesis of these QDs and the emergence of localized states are demonstrated through HR-AFM, scanning tunneling microscopy (STM) imaging, and spectroscopy, and the relationship between QD atomic structure and magnetic properties is uncovered. GNR QDs provide a useful platform for controlling the spin-degree of freedom in carbon-based nano structures.

Looking Beyond: Such structures are promising molecular building blocks of carbon based future devices with spin controllable or quantum computing capable elements. Challenges remain to build or move such structures from metal support onto insulating surfaces to decouple spins from the substrate and create a potentially significant long de-coherence time to be practically useful. Furthermore control and readout certainly will be challenging. First steps have been demonstrated using SPM techniques and manipulation on atomic scale. Still, instrumentation has to allow for convenient and efficient future experiments.

Reference to this work:

[1] Small 2024, 20, 2400473; DOI: 10.1002/smll.202400473

9:00am NS1-MoM-4 Direct Observation of Mg Diffusion Through Screw-type Dislocations in a GaN Device Using Atom Probe Tomography, Yimeng Chen, Michael Salmon, Xiuhong Han, EAG Laboratories

Large band gap vertical GaN power devices have been developed for high efficiency switch devices [1]. These devices incorporate p-type GaN through Mg doping in selective regions. Precise control of dopant concentration is crucial for semiconductor devices. However, interfacial diffusion or through defect migration of dopants can degrade the performance. Dopant segregation at threading dislocations inducing current leakage was reported [2].

We analyzed a GaN device removed from a USB charger, purchased from the market, that contained the NV6125 microchip for power switching control. The microchip was mechanically de-processed at EAG down to the field-effect-transistor level, exposing the source/drain region for microstructural characterization. A \sim 0.5 μ m thick lamella in cross-section was made along the gate via Focused Ion Beam (FIB) and observed using Scanning Transmission Electron Microscopy (STEM). STEM observation confirmed a layered structure composed of dielectric oxide, metal contact, p-type GaN and AlGaN layers on GaN. The GaN epi exhibits a high threading dislocation density (TDD) that we estimate to be \sim 1E9/cm 2 . Using a simple 2-beam tilting strategy in STEM, we were able to identify each dislocation as either edge, screw, or mixed type.

Precise STEM carbon-deposition was utilized to mark and target defect free regions as well as individual dislocations. Small pillars,

\sim 0.5 μ m \times 0.5 μ m \times 4 μ m, containing the marked locations from the existing STEM lamella were extracted and welded to specific grids suitable for both APT and STEM. The samples were then re-imaged and marked again in STEM. Using the STEM marks to guide further FIB machining, the pillars were further processed into needle-shaped samples suitable for atom probe tomography (APT), centered at the precise locations of the threading defects. Composition and elemental distribution, in and around dislocations, were studied using APT. In the presentation, we will compare dopant distribution in dislocation-free regions and at dislocation cores.

APT analysis confirmed approximately 100 ppm Mg dopant in the p-type GaN region. The results clearly indicate Mg diffusion along the dislocation core through the electron blocking layer, resulting in a line concentration of \sim 80 dopant atom per 100 nm inside the GaN. The study demonstrates the unique capability of site-specific analysis of defects in device structures using correlative STEM and APT analysis, providing detailed insight into the diffusion behavior of dopant in and around threading defects.

[1] T. Oka, T. Ina, Y. Ueno, J. Nishii, *Appl. Phys. Express* 2015, 8, 6.

[2] H. Sakurai, et. al., *Appl. Phys. Express* 2020, 13, 086501.

9:15am NS1-MoM-5 Focused Ion Beam Low Energy Implantation, Alex Belianinov, Michael Titze, Chris Smyth, Sandia National Laboratories; Jonathan Poplawsky, Oak Ridge National Laboratory; Barney Doyle, Sandia National Laboratories

Ion implantation is a key capability for the semiconductor industry. As devices shrink, novel materials enter the manufacturing line, and quantum technologies transition to being more mainstream, traditional implantation methods fall short in terms of energy, ion species, and positional precision. However, lowering the implantation energy while maintaining nanometer scale spot size is a technological challenge. This presentation will show an overview of techniques at Sandia National Laboratories Ion Beam Facility that allow focused ion implants 10-200 keV range for quantum relevant applications.

Additionally new developments in sub-1 keV focused ion implants into Si and 2D devices, using a focused ion beam system, validated by atom probe tomography will be shown. We illustrate that identical results for low energy ion implants can be achieved by either lowering the column voltage, or decelerating ions using bias – while maintaining good spatial resolution. Furthermore, our data reveal that standard implant modeling approaches overestimates experimental depth by a significant margin. Finally, we discuss how our results pave a way to much lower implantation energies, while maintaining high spatial resolution.

9:30am NS1-MoM-6 Silicon-Containing Poly(Phthalaldehyde) Hard Mask Materials for Simplified High-Resolution and Grayscale Patterning via Thermal Scanning Probe Lithography (t-SPL) - A NanoFrazor Use Case, Nicholas Hendricks, Emine Çağın, Heidelberg Instruments Nano AG, Switzerland

Enabled by the NanoFrazor technology, thermal scanning probe lithography (t-SPL) has established itself as a mature and reliable direct-write nanolithography technique for generating nanoscale structures [1-4]. The NanoFrazor technology offers an alternative and complementary process to conventional lithography techniques of photolithography and electron-beam lithography (EBL). With an advanced cantilever, t-SPL generates patterns by scanning an ultrasharp tip over a sample surface to induce local changes with a thermal stimulus, which allows for various modifications to the sample via removal, conversion, or addition. Along with an ultrasharp tip, the t-SPL cantilever contains other important functions such as an integrated thermal height sensor and an integrated heating element, both of which are advantageous for fabricating devices for quantum computing, nanoelectronics, and photonics.

The main thermal imaging resists used in t-SPL are poly(phthalaldehyde) (PPA) based materials that are commercially available from Allresist and Polymer Solutions. PPA is an all-organic based resist capable of direct sublimation when exposed to temperatures greater than the decomposition temperature, \sim 180°C. With such characteristics, PPA has been able to produce sub-10nm lateral dimensions while providing sub-nm vertical resolution but with limited etch selectivity in oxygen-based reactive ion etches. To overcome this, t-SPL utilizes a four-layer film stack, that includes a silicon-containing hard mask, deposited either by spin-coating or evaporation, for high-resolution patterning. To simplify the high-resolution patterning process, a two-layer film stack utilizing a spin-coatable silicon-containing PPA (Si-PPA) material, functioning both as a hard mask material and a thermal imaging resist, is assessed here. One of the advantages of

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using Si-PPA is that a simplified film stack is used (from four steps to two steps) while maintaining sub-20nm processing capabilities.

Within this presentation, the background of t-SPL will be introduced as well as the experimental results of the two-layer film stack for high-resolution patterning. Sub-40nm patterns transferred into a silicon substrate and sub-20nm features patterned into the Si-PPA film by t-SPL will be further elaborated upon. Initial results from grayscale patterning generated in Si-PPA films and etch amplifications will be discussed.

[1] S. Howell et al., *Microsystems & Nanoengineering*, 6, 21 (2020)

[2] V. Levati et al., *Adv. Mater. Technol.* 8, 2300166 (2023)

[3] L. Shani et al., *Nanotechnology*, 35, 255302 (2024)

[4] Mukherjee et al., *ACS Nano*, 19, 9327 (2025)

9:45am NS1-MoM-7 Tunable Electronic Properties Within Highly Unoccupied Electronic Bands of Graphene-SiC Heterostructures Determined by Scanning Tunneling Spectroscopy, Marek Kolmer, Umamahesh Thupakula, Shen Chen, Ames National Laboratory; Hoyeon Jeon, Oak Ridge National Laboratory; Wonhee Ko, The University of Tennessee, Knoxville; An-Ping Li, Oak Ridge National Laboratory; Michael C. Tringides, Iowa State University

Manipulation of the interlayer couplings in vertically stacked two-dimensional (2d) materials results in highly tunable electronic properties, often stemming from emerging novel electronic and topological phases. Here, we will focus on the epitaxially grown graphene (EG) on a silicon carbide (0001) surface, where thermal decomposition of the top silicon carbide layers provides a synthesis of epitaxial graphene layer(s) with exceptional uniformity and control over their structural properties, i.e., number of graphene layers. Subsequent intercalation of heteroatoms under graphene layer(s) becomes a promising strategy for the synthesis of designer 2d quantum materials. In the talk we will discuss how control over these buried graphene interfaces and metal intercalation affects the resulting electronic structure of these model systems. In particular, we will focus on the less understood interface states located within the unoccupied electronic band regime above the vacuum level. Such states, especially for energies larger than ~20 eV, are not easily accessible with most spectroscopies, while here, both the pristine and intercalated systems can be easily measured and compared. The low-temperature scanning tunneling microscope operating in the high-sample bias voltages reaching ~40 V is used to study the interaction between the interface states and high-bias resonances formed within the triangular tip-sample potential. We show the methodology of how to extract the intrinsic electronic density of states of highly unoccupied bands as a function of graphene thickness and intercalated phase from these high-bias scanning tunneling spectroscopy (STS) experiments. Due to the 2d nature of systematically studied graphene heterostructures, their high-bias STS spectra show pronounced features within this energy regime, i.e., in contrast to typical bulk, half-plane metals' spectra, which strongly depend on the interlayer couplings between the heterostructure interfaces.

Acknowledgements: This work was supported by the U.S. Department of Energy (DOE), Office of Science, Basic Energy Sciences, Materials Science and Engineering Division. M.K. and U.T. acknowledge support through a DOE Early Career Project. The research was performed as a User Project at the Center for Nanophase Materials Sciences, which is a DOE Office of Science User Facility; and at the Ames National Laboratory, which is operated for the U.S. DOE by Iowa State University under contract # DE-AC02-07CH11358.

Nanoscale Science and Technology

Room 206 A W - Session NS2-MoM

Advanced Nanomaterial for Quantum and Energy Applications

Moderators: Alex Belianinov, Sandia National Laboratory, Wonhee Ko, University of Tennessee, Knoxville

10:30am NS2-MoM-10 Fabricating Color Centers using Liquid Metal Alloy Ion Source Focused Ion Beams, Michael Titze, Sandia National Laboratories

INVITED

Color centers are interesting candidates for transmitting quantum information. However, experiments using color centers are hindered by the difficulty of fabricating color centers deterministically. Liquid metal alloy ion source based focused ion beams (FIBs) hold the potential to deterministically fabricate color centers at scale. Often the challenge lies in

having a source material that contains the ion of interest to form the color center of relevance. Example challenges include lack of wetting the filament material, evaporation of the element of interest, formation of hard to break oxides, and too little or too high viscosity of the source material, leading to a lack of formation of an emitting Taylor cone. In this talk we will discuss our current efforts in realizing a Na and Pb source. We will discuss the use of a AuSi eutectic where Na is added as an impurity that shows Na is outgassing during source fabrication. We will also present current results using a eutectic NaPb alloy, including the observation of evaporation of the source material when using standard source fabrication recipes, highlighting the need for in-situ thermometry. We will also present our work on fabricating quantum devices utilizing FIB created tin-vacancy centers in diamond and silicon vacancies in SiC showing how FIB enables the required targeting resolution for integration of color centers with quantum devices once a suitable source is fabricated.

This work was performed, in part, at the Center for Integrated Nanotechnologies, an Office of Science User Facility operated for the U.S. Department of Energy (DOE) Office of Science. Sandia National Laboratories is a multimission laboratory managed and operated by National Technology & Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International, Inc., for the U.S. DOE's National Nuclear Security Administration under contract DE-NA-0003525. The views expressed in the article do not necessarily represent the views of the U.S. DOE or the United States Government.

11:00am NS2-MoM-12 Atomic-scale Vibrational Excitations at Amorphous/Crystalline Interfaces, Kory Burns¹, University of Virginia, USA; Nooreen Qureshi, University of Virginia; Tymofii Pieshkov, Pulickel Ajayan, Rice University; Jordan Hachtel, Center for Nanophase Materials Sciences, Oak Ridge National Laboratory

Isotopically pure amorphous Boron Nitride has an extremely low nuclear cross-section (inhibiting the absorption of thermal neutrons), high thermal stability, good measurement precision, and robustness to external perturbations; making it an ideal candidate for next-generation quantum sensors. Some of the most prominent issues in understanding thermal transport in candidate materials is the difficulty in fabricating dissimilar interfaces at scale and accurately characterizing their properties. In this presentation, amorphous BN is deposited on 3 different substrates by pulsed laser deposition. Next, an aberration-corrected scanning transmission electron microscope (STEM) with a monochromator on the electron energy loss spectrometer (EELS) is used to measure phonon modes at atomic resolution at the interface between the BN film and the substrate. The epitaxial strain between BN and the substrate is measured using off axis EELS, where the bright field disc is displaced in q-space relative to the EELS aperture to collect electrons that scatter at high angles. This ensure that electrons that scatter off the nucleus are interpreted in the EEL spectrum, and not ones that scatter off the material's electron cloud. This approach ensures that we can measure a localized response from individual atoms by suppressing long-range excitations from the dielectric environment. Accordingly, we reimagine the process used to calculate the localized phonon transport at interfaces and enhance the selection criteria of thin films and substrates for quantum sensing applications. Ultimately, this work reinforces the need to study the structure-property relationship of amorphous solids and discusses their implication in novel applications, including quantum sensors and radiation-hard electronics.

11:15am NS2-MoM-13 Revealing Quantum Functionality of Topological Thin Films by *in situ* Characterization with Materials Cluster System, Wonhee Ko, University of Tennessee, Knoxville

Achieving unique quantum functionality from the nanostructures is a key to realizing novel electronic and quantum devices. Thin films of quantum materials are a promising candidate, but the quantum states in these films are highly fragile to the ambient condition and require *in situ* growth and characterization techniques. We build materials cluster system that combines *in situ* epitaxial film growth and characterization instruments, such as molecular beam epitaxy (MBE), pulsed laser deposition (PLD), angle-resolved photoemission spectroscopy (ARPES), and scanning tunneling microscopy (STM). With the materials cluster system, we grew thin films of topological insulators and observed lattice and electronic structures in atomic scale. Interestingly, we found that the step edges possess Rashba edge states with unique spin texture, which interacts with topological surface states depending on the film thickness. Moreover, the strength of Rashba interaction was tunable by functionalizing step edges

¹ JVST Highlighted Talk

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with selenium atoms. The results demonstrate that the unique quantum functionality can be exhibited by materials cluster system, which will become a foundational system to realize quantum devices with these films.

11:30am NS2-MoM-14 Atomically Precise vertical Tunnel Field Effect Transistor (vTFET) for 10X Microelectronics Energy Efficiency in a General Purpose Transistor, Desiree Salazar, Energetics Inc.; Shashank Misra, Sandia National Laboratories, USA

Atomically Precise vertical Tunnel Field Effect Transistor (vTFET) for 10X Microelectronics Energy Efficiency in a General Purpose Transistor. Desiree Salazar, S. Misra, Emilie Lozier and T. Kaarsberg

The United States Department of Energy (DOE) Advanced Materials and Manufacturing Technology Office (AMMTO) is leading a multi-organization effort to counter alarming trends in U.S. computing energy use (e.g. **LBNL 2024** [https://usdoe-my.sharepoint.com/personal/tina_kaarsberg_ee_doe_gov/Documents/lbnl-2024-united-states-data-center-energy-usage-report.pdf]) forecasts that data centers will account for 26% of US electricity use by 2028 when cryptocoin mining is included) with its initiative in energy efficiency scaling for two decades (EES2) for microelectronics. Under this initiative, DOE/AMMTO has funded a portfolio of EES2 device technology R&D projects that promise >10X energy efficiency increase by 2030. This paper will highlight the first of these projects with Sandia National Laboratories to build on atomically precise manufacturing techniques to create a vertical tunnel field effect transistor (vTFET). Updates will be provided on the successful integration of front end of line (FEOL), back end of line (BEOL) and mid-! (MEOL) manufacturing processes (especially thermal budget) to fabricate this vTFET in a CMOS compatible process. One important discovery of the research in this area is "ultradoping" which makes the abrupt doping profiles needed for efficient vTFETs far more manufacturable. This talk also will present how these Sandia results integrate with version 1.0b of the EES2 roadmap that will be issued in Summer 2025. Version 1.0a of the Roadmap is available at EES2 Roadmap Version 1.0 [https://eere-exchange.energy.gov/FileContent.aspx?FileID=f4234e29-cc0c-4a56-a510-86b616ab5535].

11:45am NS2-MoM-15 Microwave-Assisted Direct Upcycling of Lithium Ion Battery Cathodes, Clare Davis-Wheeler Chin, Sandia National Laboratories; Kirsten Jones, University of New Orleans; Boyoung Song, Bryan Wygant, Anastasia Ilgen, Sandia National Laboratories; Candace Chan, Arizona State University; C.J. Pearce, Sandia National Laboratories; Winson Kuo, John Watt, Los Alamos National Laboratory; John B. Wiley, University of New Orleans; Kevin Leung, Sandia National Laboratories
Rapid market growth of lithium ion-batteries (LIB) for electric vehicles has generated critical materials and sustainability challenges. LIB cathodes require cobalt, which is costly and primarily mined in conflict regions. In response, recent efforts focus on developing efficient, scalable methods for recycling spent LIB cathode materials. Here we report a direct-upcycling approach that exploits microwave (MW) heating for exfoliating layered cathode oxides LiCoO₂ (LCO) and LiNi_xMn_yCo_zO₂ (NMC) into nanosheets (NSs), which facilitates manipulation of Co:Ni:Mn stoichiometry and reassembly into functioning cathode materials. MW irradiation interacts directly with reaction species to promote heterogeneous heat distribution and instantaneous localized superheating, accelerating exfoliation rates and increasing conversion from bulk oxides to NSs. Our "one-pot" MW method decreases exfoliation time from 2 days (leading-edge electrochemical method) to 2 hours and is easily scaled to generate multi-gram yields. High-resolution transmission electron microscopy (HR-TEM) of MW-exfoliated LCO and NMC indicates conversion into mono- and bilayer NSs with yields >99%. LCO NSs also show increased catalytic activity over starting materials, indicating expanded use cases for recycled materials. The results of this work help establish a fundamental science foundation for sustainable scale-up and securing the LIB supply chain, which is a DOE priority.

Funding Statement

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This work was performed, in part, at the Center for Integrated Nanotechnologies, an Office of Science User Facility operated for the U.S. Department of Energy (DOE) Office of Science. Los Alamos National Laboratory, an affirmative action equal opportunity employer, is managed by Triad National Security, LLC for the U.S. Department of Energy's NNSA, under contract 89233218CNA000001

Plasma Science and Technology

Room 201 ABCD W - Session PS-MoM

Advanced Logic and EUV Patterning

Moderators: John Arnold, IBM, Angelique Raley, TEL Technology Center, America, LLC

8:15am PS-MoM-1 Current Status and Future Perspectives of Plasma-Induced Damage and its Characterization, Koji Eriguchi, Kyoto University, Japan

INVITED

Defect generation during plasma processes (plasma-induced damage, PID) is a crucial challenge in electronic device design. Various techniques, including atomic layer etching and cryogenic processing, are believed to control PID. To ensure low PID, precise characterizations and a deeper understanding of the fundamental physics behind experimental observations are indispensable. This study reports recent progress in PID characterization and discusses the fundamental aspects as future perspectives.

PID is now evaluated by electrical methods [1]. With the introduction of low-*k* films, mechanical property changes by PID have become another focus. Recently, a cyclic nanoindentation (c-NI) method [2] revealed that SiN films degrade more significantly than SiO₂ films by PID, particularly in terms of contact stiffness evolution. Mechanical property changes by PID should be considered for various applications.

Impedance spectroscopy (IS) was proposed to assess various aspects of PID in SiN and SiO₂ films [3]. An IS-based method was applied to Si and InP [4], one of the promising compound semiconductors for next-generation devices. Capacitive and conductive components were found to depend on the incident species from plasma. The IS-based method identified differences in the energy profiles of defects created in Si and InP substrates.

PID is governed by indeterministic dynamics. Molecular dynamics simulations [5] revealed that PID is formed by stochastic straggling within the sidewalls of "fin" structures. An increase in junction current (~dark current in CMOS image sensors) was experimentally confirmed using device arrays [6], highlighting the need to incorporate stochastic mechanisms in designing plasma processes for 3D and ultimately scaled devices. Recently, the stochastic aspects of PID were modeled similarly to stock price predictions, revealing Poisson statistics in defect creation and fundamental PID variation [7].

PID is inherently unavoidable. A deeper understanding and advanced characterization techniques are indispensable. This study reports mechanical property degradation and new characterization methods. Stochastic mechanisms in 3D and ultimately scaled devices have been discussed. Exploring various techniques and predictive models will be essential for future PID design.

[1] K. Eriguchi, Jpn. J. Appl. Phys. **60**, 040101 (2021).

[2] T. Goya *et al.*, J. Phys. D **57**, 475202 (2024).

[3] T. Kuyama *et al.*, IEEE IRPS, 4B.4 (2021).

[4] T. Goya *et al.*, Jpn. J. Appl. Phys. **63**, 06SP04 (2024).

[5] K. Eriguchi *et al.*, Jpn. J. Appl. Phys. **53**, 03DE02 (2014).

[6] Y. Sato *et al.*, J. Vac. Sci. Technol. B **40**, 062209 (2022).

[7] K. Eriguchi and K. Urabe, Dry Process Symp., 17 (2023).

8:45am PS-MoM-3 Direct Etching of Ru Pattern with Space Width of 10 nm and Less, Miyako Matsui, Hitachi, Ltd., Japan; Kiyohiko Sato, Makoto Miura, Kenichi Kuwahara, Hitachi High-Tech Corp., Japan

With continuous device scaling, scaling of the metal pitch is continuously required using advanced patterning technologies such as extreme ultraviolet lithography. As such scaling continues, alternative metal interconnects are required to replace Cu. Ru is a candidate for an alternative interconnect material with metal pitches of 20 nm and beyond because a Ru interconnect can have a lower effective resistance than that of a Cu interconnect at such small pitches. Ru can be etched directly, which can lead to new scaling boosters such as semi-damascene patterning. In the

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Ru etching process, roughness or other damage should be suppressed to reduce interconnect resistance.

In our previous study, we investigated the mechanism generating roughness in Ru patterns with a 32-nm pitch by using Cl₂/O₂-based plasma generated by a microwave-ECR etching system. The Ru sidewall roughness was thought to be caused by non-volatile RuO_x and RuCl_y, which were non-uniformly formed on the Ru sidewall. We found that the sidewall roughness of a Ru pattern strongly depends on the protection layers formed on the sidewall by adding passivation gas to the Cl₂/O₂-based plasma.

In this study, we investigated the etching mechanism of Ru patterns with a space width of 10 nm or less. The effect of space width on the etching performance and cross-sectional profiles of Ru patterns with a narrow space width was investigated. The space width of a Si₃N₄ mask pattern with a width of 14 nm was narrowed using an in-situ atomic-level deposition technique, which almost conformally deposited an atomic-level-thick SiO₂ layer on a Si₃N₄ mask pattern with a 32-nm pitch.

Etch stop occurred on the patterns when the space width of the mask pattern was narrower than 9 nm because the SiO₂/Si₃N₄ hard mask widened due to the redeposition of Si-containing by-products, and the redeposited by-products prevented ions from entering the space. When the ion energy was increased by applying a higher wafer bias power and the ion flux decreased by reducing the duty cycle of the wafer bias, Ru etching proceeded, but the Ru sidewall was laterally etched by radicals during the off-period of the wafer bias power. Ru sidewall protection becomes more important in preventing the lateral etching of Ru patterns with a narrow space because the ratio of radical to ion flux becomes large inside the narrow space.

We suggest adding a passivation gas to the Cl₂/O₂ plasma to form a protection layer on the sidewall of patterns with a space width of 10 nm or less. Sidewall roughness was also reduced because the Ru sidewall was protected from the etching by a uniform protection layer.

9:00am PS-MoM-4 Study of Electron-Surface Interactions for Etching of Ruthenium with Chlorine and Oxygen, Michael Hinshelwood¹, University of Maryland College Park; Hubertus Marbach, Michael Remmel, Gerson Mette, Michael Budach, Daniel Rhinow, Klaus Edinger, Carl Zeiss SMT GmbH, Germany; Gottlieb S. Oehrlein, University of Maryland College Park
Ruthenium (Ru), a material used in semiconductor manufacturing for extreme ultraviolet (EUV) photomasks, is experiencing increasing attention as a material for capping layer and as potential adsorber in high NA lithography. Ru can be etched through the formation of volatile oxides and considerable research efforts have been put into optimizing etching processes. Y. Li et al. demonstrated that Ru can be rapidly etched by combining a low-energy electron beam (EB) with a flux of O₂/Cl₂-derived neutrals emanating from a remote plasma (RP) source [1]. This etching demonstrated a synergistic effect, with the remote plasma by itself causing a low level of etching, and the combination of EB and unexcited gas resulting in growth of a non-volatile compound. Here, we build upon that work, using in-situ ellipsometry to gain understanding on how the EB affects the surface etching reaction. By breaking up the exposure steps, subjecting the Ru surface to sequential EB and RP with either Cl₂ or O₂, we have found that the EB in conjunction with Cl₂ gas induces the uptake of Cl on the Ru surface, creating a chlorinated layer. The growth rate of this layer increases with increasing electron flux and energy, suggesting that electron-induced modification of the Ru surface is the source of the observed behavior. This chlorinated layer is selectively etched by O₂ plasma-derived neutrals, which otherwise results in non-volatile RuO₂ growth on the unmodified Ru. The etch rate of this modified layer increases with layer thickness, and is boosted by electron flux, suggesting that the electrons have multiple roles in this etching system. By isolating the effects of the EB on this etch mechanism of Ru, we obtained valuable information for the development of low-damage etch processes. Ellipsometric data and models of surface processes are complemented by X-ray photoelectron spectroscopy data.

This material is based upon work supported by Carl Zeiss SMT GmbH.

[1] Y. Li et al., "Investigation of ruthenium etching induced by electron beam irradiation and O₂/Cl₂ remote plasma-based neutral fluxes: Mechanistic insights and etching model," *J. Vac. Sci. Technol. A*, vol. 43, no. 2, p. 023005, Feb. 2025, doi: 10.1116/6.0004219.

9:15am PS-MoM-5 Highly Selective Isotropic etching of SiGe over Si via Pulsed RF Power in NF₃ Plasma, Geun Young Yeom, Hong Seong Gil, Woo Chang Park, Yun Jong Jang, Sungkyunkwan University (SKKU), Republic of Korea

Highly selective isotropic dry etching of SiGe for Si is an important process for fabricating 3D-structured GAA-FETs or 3D DRAM. Si-Ge bonds, which are relatively weaker than Si-Si bonds, are more easily fluorinated by F-radicals and thus are etched as SiF₄ and GeF₄. However, because the high reactivity of fluorine radicals makes it challenging to achieve damage-free SiGe etching using F-radical-based approach, there is a growing demand for the development of more highly selective etch processes.

In this study, we employed an ICP-type remote plasma with NF₃ gas to investigate how pulsed RF power can be used to control the etch species and thereby to improve etch characteristics in isotropic SiGe etching. By applying microsecond-scale on/off cycles to the RF power, we found that the etch rate of SiGe maintained (or increased) while that of Si decreased, significantly enhancing the overall etch selectivity. Additionally, we found that lower processing temperatures significantly enhanced the etch selectivity, primarily due to differences in activation energies between Si and SiGe under pulsed plasma conditions.

9:30am PS-MoM-6 Significance of the Impacts of Metal Oxide Resists (MORs) in Plasma Etch Processes, Adam Pranda, Steven Grzeskowiak, Yusuke Yoshida, Eric Liu, TEL Technology Center, America, LLC

One of the major developments in logic scaling has been the transition from 193nm deep ultraviolet (DUV) lithography to 13.5nm extreme ultraviolet (EUV) lithography. Historically, organic or chemically amplified resists (CARs) have been used for patterning because of sufficient radiation sensitivity, resolution, and etch resistance for enabling viable manufacturing flows with DUV lithography. However, the shift to EUV lithography presents numerous problems for CARs due to the reduced absorption of EUV light that among roughness and defectivity challenges also necessitates thinner resist thickness to achieve high resolution. For etch processes utilizing EUV CARs, this requires maintaining a sufficiently high etch selectivity to successfully transfer the pattern before integrity is lost. One approach to overcoming the challenges with CARs in EUV lithography has been the development of metal oxide resists (MORs), which demonstrate improved absorption of EUV light, improved etch resistance, and reduced line edge roughness. Given the significant difference in chemical properties between CAR and MOR, it is imperative for manufacturing viability to understand how existing etch processes are impacted by a switch to MOR in the patterning stack. In this study, we used a high-density plasma reactor to etch a benchmark blanket patterning stack (Fig. 1) containing either a EUV CAR or MOR. We utilized a characterization suite including optical emission spectroscopy (OES), spectroscopic ellipsometry (SE), atomic force microscopy (AFM), and x-ray photoelectron spectroscopy (XPS) to understand the relationships between the plasma conditions (OES), the evolution of the surface chemistry of the resists (XPS), and the resulting etch behavior (SE) and surface topography (AFM). The characteristic plasma processes for a patterned stack etch interact with MOR in a different manner than with CAR, resulting in different physical and chemical impacts to the resist itself, but also via etch byproducts alter the chamber condition and the etch behavior of subsequent etch steps in the patterning stack. We also applied the findings from the blanket stack work on patterned structures to investigate the impacts on pattern fidelity, especially since there is industrial interest to implement MOR for line-space patterning at pitch sizes of 32nm and below. Identifying the underlying mechanisms that lead to differences in the overall stack etch when MOR is used compared to CAR will provide key guidance into the development of process flows that integrate MOR.

10:30am PS-MoM-10 Influence of Nitrogen on Controlling the Etch Selectivity between Tungsten Metal and Dielectric Materials, Indroneil Roy, Pingshan Luan, Jason Marion, Yusuke Yoshida, Peter Biolsi, TEL Technology Center America

Metal gate cut (MGC) last approach has many advantages over traditional poly gate cut such as increased separation length of the gate, improved composite yield, and lower parasitic leakage. In future device structures (e.g. Complementary Field Effect Transistor, CFET), the increase of gate heights along with the decrease of critical dimensions (CD) results in high trench aspect ratios (A.R., calculated by height/CD). This poses a significant etch challenge where the metal etch rate slows down and the etch profile becomes more difficult to control. Simply etching for longer may not be suitable because the hard mask, typically comprised of dielectric materials,

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will be fully consumed. Thus, a process that provides higher metal-to-dielectric selectivity is highly desirable for MGC applications. In this work, we use blanket films of tungsten (W), which is a typical metal gate material, and SiO_2 and Si_3N_4 , which are typical hard mask materials, to investigate the effect of plasma chemistry in controlling etch selectivity. Particularly, the role of N_2 in a BCl_3/N_2 plasma is explored. We found that the W: SiO_2 and W: Si_3N_4 etch selectivity is governed by the interplay between etchant Cl neutrals, and a passivation effect when N_2 is introduced in the plasma. The etch amounts of W, Si_3N_4 , and SiO_2 were evaluated using spectroscopic ellipsometry (SE). We found that the W etch amount (E.A.) increases with increasing N_2 flow whereas the dielectric E.A. decreases. However, in a low N_2 flow regime, the Si_3N_4 : SiO_2 selectivity reverses. The behavior of N_2 flow on etch selectivity was evaluated by studying the surface composition of these materials before and after etch using X-ray photoelectron spectroscopy (XPS). The effect of A.R. on etch selectivity was also investigated. The plasma composition is also monitored using optical emission spectroscopy (OES) to understand differences in relative concentration of gas phase species.

10:45am PS-MoM-11 Plasma Etch of Low-K Dielectric (SiOC, SiOCN) at Reduced Temperature, Sang-Jin Chung, University of Maryland, College Park; Pingshan Luan, Adam Pranda, Yusuke Yoshida, TEL Technology Center America; Gottlieb Oehrlein, University of Maryland, College Park

Front-end low-k dielectric (SiOC, SiOCN) are important in complementary field-effect transistors (CFET) for reducing LC delay, minimizing power consumption, and mitigating crosstalk. Future generations of CFETs will also be increasingly stacked to improve device density. Therefore, high-aspect-ratio (HAR) etch and profile defect issues must be considered, as well as the different etch rates of the dielectric/poly-Si materials which will be dependent on the precursor chemistry, substrate temperature, and plasma power.

In this work using an inductively coupled plasma chamber, we will examine SiOC and SiOCN etch both isotropically and anisotropically with varied substrate temperatures (10 °C to -60 °C), precursors, plasma power, and bias voltages. *In situ* ellipsometry will be used to monitor the real time etch behavior, and XPS will be used to probe the composition after etching.

The etch capability of the chamber at cryogenic temperatures has been successfully confirmed.¹ In this work, *in situ* ellipsometry monitoring of the surface can give us a powerful understanding of the chemical properties of the deposited FC film when etching SiOC and SiOCN material, particularly as we lower the substrate temperature when condensation might occur.

In addition to planar etch of these substrates, HAR structures will be used to simulate isotropic etch characteristics of the SiOC and SiOCN materials. A previous study using Si_3N_4 and SiO_2 -HAR structures showed significant spontaneous etch when using HFC precursors (CH_2F_2 , CHF_3 , and CF_4/H_2) whereas mostly deposition was seen with FC precursors (C_4F_8).² Our current results show that at low substrate temperature, this isotropic etch was mitigated. The etching characteristic and sidewall profiles of SiOC and SiOCN materials will be compared to SiO_2 and Si_3N_4 .

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2. Chung, S.-J., Luan, P., Park, M., Metz, A., & Oehrlein, G. S. Exploring oxide-nitride-oxide scalloping behavior with small gap structure and chemical analysis after fluorocarbon or hydrofluorocarbon plasma processing. *J. Vac. Sci. Technol. B* 41, 062201 (2023).

11:00am PS-MoM-12 Etch Characteristics of Flexible Low-k SiCOH Thin Films Under Fluorocarbon-Based Plasmas Using Inductively Coupled Plasma-Reactive Ion Etching Process, Rajib Chowdhury, Thomas Poché, SeonHee Jang, University of Louisiana at Lafayette

Flexible electronics have gained considerable attention within the microelectronics industry due to their ability to fold, twist, stretch, and conform to various surfaces. Unlike traditional Si-based electronics, flexible electronic devices are fabricated on substrates such as polymers, metal foils, and flexible glass, enabling applications in displays, wearable devices, and solar cells. However, low-temperature processing is required to produce flexible electronic components due to the low glass transition temperature of polymer substrates. Among various dielectric materials, carbon-doped silicon oxide (SiCOH) is widely used in semiconductor devices for its low dielectric constant (low- k , $k < 4.0$). Photolithography and dry etching are essential for integrating SiCOH into flexible electronics. While

the etching properties of SiCOH films on rigid Si wafers are well-studied, research on flexible SiCOH films is limited. In the dry etching process, etchants such as CF_4 , O_2 , and Ar influence the film properties, potentially affecting device performance. This study explores the effect of etching parameters on flexible SiCOH films to advance their application in flexible electronics.

Flexible low- k SiCOH films were produced onto flexible indium tin oxide-coated polyethylene naphthalate substrates by plasma-enhanced chemical vapor deposition of a tetrakis (trimethylsilyloxy)silane precursor at ambient temperature. RF plasma powers of 20 and 60 W were utilized for the deposition. An inductively coupled plasma-reactive ion etching process was performed to investigate the etching characteristics of the SiCOH films under CF_4 -based plasmas. Each etching gas chemistry was selected among CF_4 , $\text{CF}_4 + \text{O}_2$, and $\text{CF}_4 + \text{Ar}$. The physical, chemical, and electrical properties of the SiCOH films were investigated to determine the effects of etching process parameters on film's properties.

The Fourier transform infrared spectra of the pristine films identified four prominent absorption bands as CH_x stretching, $\text{Si}-\text{CH}_3$ bending, $\text{Si}-\text{O}-\text{Si}$ stretching, and $\text{Si}-(\text{CH}_3)_x$ stretching vibration modes. After etching, the peak area ratio of $\text{Si}-\text{O}-\text{Si}$ stretching mode increased, and that of $\text{Si}-(\text{CH}_3)_x$ stretching mode decreased. The high-resolution X-ray photoelectron spectroscopy scan found that the peak intensity of the C1s and Si2p peaks decreased after the etching process, and the peak center of the F1s peak shifted depending on etching chemistry. The k -values of the pristine SiCOH films deposited at 20 and 60 W were 2.46 and 2.00, respectively. Following etching, the k -values of the films at 20 W were reasonably consistent, while those at 60 W increased notably following the etching process.

11:15am PS-MoM-13 Enhancing 24nm Pitch Line / Space by DSA Rectification: A Path to Smoother Lines and Car Extension, Rémi Vallat, Lander Verstraete, Philippe Bézard, Hyo Seon Suh, Laurent Souriau, Kurt Ronse, IMEC, Belgium

The introduction of extreme ultraviolet (EUV) lithography tools has significantly accelerated the scaling of device features, driving advancements in the semiconductor industry. However, as critical dimensions (CD) continue to shrink, the impact of stochastic variability becomes even more pronounced, and the demands for precise patterning grow stricter. Traditional chemically amplified resist (CAR) materials are facing increasing challenges in meeting specifications for roughness, defectivity, and etch budget. As a result, there is a rising interest in exploring alternative resist formulation and patterning schemes, such as directed self-assembly (DSA).

DSA can mitigate the stochastic issue and push EUV patterning close the resolution limit, thanks to its resilience to small resist variation by extending the use of CAR combined with low dose exposure. For DSA, PS-*b*-PMMA low chi block copolymer is typically used down to 22nm pitch, its phase separation limit. Scaling below 22nm requires the introduction of higher Chi materials to provide a sharper interface with less fluctuations and thus better roughness. [1-3]

In this talk, the case of rectification by DSA at Pitch 24nm Line/ Space CAR patterns (P24 L/S) will be discussed (Figure 1). After introducing the DSA process flow, we will present how to minimize the Line Edge Roughness (LER) and Line Width Roughness (LWR) by optimizing the stack and the dry etch pattern transfer process. Finally, we will discuss how to further improve the roughness (both LER and LWR) at BCP level (for both PS-*b*-PMMA and HighChi) and how the improved roughness is modulated during the pattern transfer down to the layer below.

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11:30am PS-MoM-14 Dry Etch Challenges Towards the High NA EUV Lithography Patterning Era, Sara Paolillo, Stefan Decoster, Philippe Bezard, Remi Vallat, Vincent Renaud, Viktor Kampitakis, Annaelle Demaude, Laurent Souriau, Bhavishya Chowrira, Dieter Van Den Heuvel, Victor M. Blanco Carballo, Syamashree Roy, Shubhankar Das, Frederic Lazzarino, IMEC, Belgium

INVITED

Pitch scaling remains a fundamental driver of semiconductor technology advancement. To print smaller feature sizes, Extreme Ultraviolet (EUV) lithography was introduced starting from the 7 nm technology node. As we

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are approaching the scaling limits of Low Numerical Aperture (NA) EUV, High NA EUV lithography is being proposed as a solution for patterning sub-24 nm pitch structures in a single exposure step. Additionally, multi-patterning schemes are being employed to extend capabilities beyond the lithographic resolution limit. In all cases, to support this ongoing miniaturization, it is crucial to ensure the precise transfer of the photoresist patterns into underlying layers through plasma etching.

This presentation will highlight the opportunities and evolving challenges associated with dry etching at current resolutions and as we transition into the high NA era. As device features shrink, the lithography trade-off between resolution, sensitivity, and features roughness becomes increasingly challenging to balance; improving one comes at the expenses of the others. One major challenge is addressing local photoresist non-uniformities, such as height variations and residues after development, which can lead to defects (breaks or bridges) after pattern transfer. These effects become even more pronounced when using thinner resists required for High NA lithography. To mitigate these issue and improve pattern fidelity, strategies such as descum processes, enhanced etch selectivity, and novel break-healing techniques are being explored. Another key challenge related to the aforementioned trade-off is minimizing features roughness, including line roughness (LER/LWR), local CD non-uniformity (LCDU), and tip-to-tip (T2T) variability. We will discuss several methods to mitigate these effects, like directional etching, directed self-assembly, and precise tuning of etching parameters.

Beyond the challenges related to working at the limits of the lithographic process, patterning increasingly smaller features in the final stack also presents significant challenges. Achieving high selectivity, vertical profiles, minimal mask erosion, low feature roughness, and preventing line bending demands continuous advancement in both etching techniques and patterning stack design. We will discuss how the choice of materials within the stack and their properties affect patterning performance.

Finally, we will present case studies from IMEC where high NA exposure has been introduced, and we will discuss the results of pattern transfer.

12:00pm PS-MoM-16 Next Generation Interconnect Patterning of Ruthenium Using Advanced RIE Processing, Shravana Kumar Katakam, Harsimran Singh, IBM Research Division, Albany, NY; Nicholas Joy, Dayun Yan, TEL Technology Center, America, LLC, Albany, NY; Christopher Penny, Koichi Motoyama, Hosadurga Shobha, Yann Mignot, Joe Lee, IBM Research Division, Albany, NY

The demand to scale interconnects to tighter pitch is increasing substantially to match the logic scaling trend and new interconnect materials like Ruthenium (Ru) are being considered as a replacement of Copper (Cu) interconnects for 18nm Pitch (P18) and beyond. There are unique patterning challenges associated with Ru interconnects using subtractive Reactive Ion Etching (RIE). It has been reported in our previous work that Hard Mask (HM) swelling during RIE is one of the major challenges at these tighter pitches and demands an innovative RIE solution. It was demonstrated that P18 patterning was successful by implementing a multi-step etch process. However, the process margin further shrinks when the pitch is reduced to P16 and beyond and needs further improvements in the RIE process. The challenges for P16 are similar to P18 and the main issue continues to be hardmask swelling from HM re-deposition during the etching process especially for high aspect ratio lines. Furthermore, in addition to HM swelling due to tighter space CDs, Line Edge Roughness (LER) and Line Width Roughness (LWR) are additional contributing factors impacting the yield at these pitches. To this end, the RIE solution not only demands a recipe without hardmask swelling but also with reduced roughness. As a continuation of our previous work, we present here a unique RIE solution which not only has very minimal hardmask swelling but also has a significant reduction in LER compared to multi-step process. A special passivation process has been implemented for reducing the roughness in conjunction with advanced pulsing capabilities which resulted in successful patterning of Ru interconnect at P16. The effects of changes to the pulsing conditions and passivation gas addition are evaluated, and the results are discussed.

Quantum Science and Technology Mini-Symposium

Room 208 W - Session QS1-MoM

Qubit Modalities for Quantum Computing

Moderators: Ekta Bhatia, NY CREATES, Drew Rebar, Pacific Northwest National Laboratory

8:15am QS1-MoM-1 Strongly Anharmonic Gatemon Devices on Proximitized InAs 2DEG, Shukai Liu¹, University of Maryland, College Park; Arunav Bordoloi, Jacob Issokson, Ido Levy, New York University; Krasra Sardashti, University of Maryland College Park; Javad Shabani, New York University; Vladimir Manucharyan, EPFL, Switzerland

Gatemon qubits represent an all-electric variant of the conventional transmon, where local electrically gated superconductor-semiconductor hybrid Josephson junctions (JJs) are employed for qubit operations. Gatemon qubits, made of transparent super-semi Josephson junctions, typically have even weaker anharmonicity than the opaque AlOx-junction transmons. However, flux-frustrated gatemons can acquire a much stronger anharmonicity, originating from the interference of the higher-order harmonics of the supercurrent. Here, we investigate this effect of enhanced anharmonicity in split-junction gatemon devices based on a proximitized InAs quantum well. We find that anharmonicity over 100% can be routinely achieved at the half-integer flux sweet-spot without any need for electrical gating or excessive sensitivity to the offset charge noise. We verified that such “gateless gatemon” qubits can be driven with Rabi frequencies more than 100 MHz, enabling gate operations much faster than what is possible with traditional gatemons and transmons. Furthermore, by analyzing a relatively high-resolution spectroscopy of the device transitions as a function of flux, we were able to extract fine details of the current-phase relation, to which transport measurements would hardly be sensitive. The strong anharmonicity of our gateless gatemons, along with their bare-bones design, can prove to be a precious resource that transparent super-semi junctions bring to quantum information processing.

8:30am QS1-MoM-2 Quantum Keynote Lecture: Evolution of IBM Quantum Processors Towards Advantage and Quantum Error Correction, David McKay², Jerry Chow, IBM Quantum

INVITED

To achieve the ultimate goal of quantum computing – fault tolerance – we need to push performance to the limit, in particular quality and scale. IBM has been a leader in both; in 2021 we debuted the 127-qubit fixed-frequency fixed-coupling Eagle processor. The Eagle processor had unparalleled stability and coherence but was limited by crosstalk in the fixed-coupling architecture. This limitation drove the development and release of the 156 qubit Heron processor in 2023, utilizing a fixed-frequency tunable-coupling architecture. When benchmarked at scale, using error per layered gate (EPLG) at 100 qubits [1], the Heron is up to a 10x improvement over the Eagle. In this talk, I will discuss some of the technological improvements required to build these devices, expand on measuring quality at scale using EPLG [1] and Cliffordization [2], and introduce our next device scheduled for later this year, the 120 qubit Nighthawk. The Nighthawk processor is an evolution of the Heron with grid connectivity to accelerate to the era of quantum advantage [3]. Finally, I will discuss our quantum error correction roadmap based on a low-density parity-check (LDPC) code [4]. This code improves encoding rate by requiring long range checks. Implementing the required long-range couplers is the next node of our innovation roadmap and will be implemented in a future exploratory processor “Loon”.

[1] arXiv:2408.07677 [2] arXiv:2503.05943 [3] arXiv:2506.20658 [4] arXiv:2506.03094

9:15am QS1-MoM-5 Stable CNOT-Gate on Inductively-Coupled Fluxoniums with Over 99.9% Fidelity I, Wei-Ju Lin, University of Maryland College Park, Taiwan; Hyunheung Cho, University of Maryland College Park, Republic of Korea; Yingqi Chen, Louisiana State University, China; Krasra Sardashti, Laboratory for Physical Sciences; Maxim Vavilov, University of Wisconsin - Madison; Chen Wang, University of Massachusetts - Amherst; Vladimir Manucharyan, EPFL, Switzerland

In this part of the talk, we report a detailed characterization of two inductively-coupled superconducting fluxonium qubits [1] for implementing high-fidelity cross-resonance gates [2]. Our circuit is notable because it behaves very closely to the case of two transversely coupled spin-\$1/2\$ systems. In particular, the generally unwanted static ZZ-term resulting from the non-computational transitions is nearly absent, even with a strong

¹ JVST Highlighted Talk

² Quantum Keynote Lecture

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qubit-qubit hybridization. Spectroscopy of the non-computational transitions reveals a spurious $\$LC\$$ -mode arising from the combination of the coupling inductance and the capacitive links between the terminals of the two-qubit circuit. Such a mode has a minor effect on the present device, but it must be carefully considered for optimizing future multi-qubit designs.

[1] Lin, Wei-Ju, et al. "Verifying the analogy between transversely coupled spin-1/2 systems and inductively-coupled fluxoniums." *New Journal of Physics* 27.3 (2025): 033012.

[2] Lin, Wei-Ju, et al. "24 Days-Stable CNOT Gate on Fluxonium Qubits with Over 99.9% Fidelity." *PRX Quantum* 6.1 (2025): 010349.

9:30am QS1-MoM-6 Stable CNOT-Gate on Inductively-coupled Fluxoniums with over 99.9% Fidelity II, *Wei-Ju Lin, Hyunheung Cho, University of Maryland, College Park; Yinqi Chen, University of Wisconsin - Madison; Kasra Sardashti, University of Maryland, College Park; Maxim G. Vavilov, University of Wisconsin - Madison; Chen Wang, University of Massachusetts, Amherst; Vladimir E. Manucharyan, EPFL, Switzerland*

In this part of the talk, we discuss the realization of a 60 ns direct CNOT gate on two inductively-coupled fluxonium qubits over 99.9% fidelity [1]. Fluxonium qubit is a promising elementary building block for quantum information processing due to its long coherence time combined with a strong anharmonicity. In this paper, we realize a 60 ns direct CNOT-gate on two inductively-coupled fluxoniums, which behave almost exactly as a pair of transversely-coupled spin-1/2 systems [2]. The CNOT-gate fidelity, estimated using randomized benchmarking, was as high as 99.94%. Furthermore, the fidelity remains above 99.9% for 24 days without any recalibration between measurements. Compared with the 99.96% fidelity of a 60 ns identity gate, our data brings the investigation of the non-decoherence-related errors during logical operations down to $\$2 \times 10^{-4}$. The present result adds a simple and robust two-qubit gate into the still relatively small family of the "beyond three nines" gates on superconducting qubits.

[1] Lin, Wei-Ju, et al. "24 days-stable CNOT-gate on fluxonium qubits with over 99.9% fidelity." *arXiv preprint arXiv:2407.15783* (2024).

[2] Lin, Wei-Ju, et al. "Verifying the analogy between transversely coupled spin-1/2 systems and inductively-coupled fluxoniums." *arXiv preprint arXiv:2407.15450* (2024).

9:45am QS1-MoM-7 Silicon-Based Quantum Processors, *Jason Petta, University of California at Los Angeles INVITED*

Of all of the qubit modalities being investigated, semiconductor spin qubits most closely resemble conventional transistors, which can be fabricated at scale with ~ 100 billion transistors on a chip. It is therefore important to pursue long-term approaches to fault-tolerant quantum computing with spin qubits. I will give an update on recent progress, including high-fidelity multi-qubit control [1,2], long-range spin-spin coupling [3,4], and two-dimensional spin qubit arrays [5,6].

References

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- [3] F. Borjans *et al.*, *Nature* **577**, 195 (2020).
- [4] X. Zhang *et al.*, *Phys. Rev. Applied* **21**, 014019 (2024).
- [5] W. Ha *et al.*, *Nano Lett.* **22**, 1443 (2022).
- [6] E. Acuna *et al.*, *Phys. Rev. Applied* **22**, 044057 (2024).

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Quantum Science and Technology Mini-Symposium Room 208 W - Session QS2-MoM

Systems, Devices, and Manufacturing Technologies for Quantum Technology

Moderator: Aranya Goswami, Massachusetts Institute of Technology

10:30am QS2-MoM-10 Superconducting Qubits at MIT Lincoln Laboratory, *Mollie Schwartz, MIT Lincoln Laboratory INVITED*

Superconducting qubits are leading candidates in the race to build a quantum computer capable of realizing computations beyond the reach of modern supercomputers. Within this modality, the ability to robustly and

reliably fabricate high-quality, quantum-compatible circuits is critical both for fundamental research efforts and for more complex and capable quantum processors. MIT Lincoln Laboratory has worked over the course of two decades to establish, and continually expand and improve, superconducting qubit fabrication capabilities. Recently, we have piloted a superconducting foundry model to enable the US quantum research and development community to leverage the most robust and reliable of these capabilities in order to accelerate research progress. This presentation will provide an overview of superconducting qubit fabrication at MIT Lincoln Laboratory, describe its transition from 50 mm prototyping tools to 200 mm fabrication to support an expanded user base, and provide perspectives on how to support and enable the broader quantum research community as the variety and complexity of questions at the research frontier continues to expand.

11:00am QS2-MoM-12 Voltage Tunable MBE-grown Ge/SiGe Josephson Junctions for Gatemon Qubits, *Joshua Thompson, Jason Dong, Junior Langa, Laboratory for Physical Sciences; Brycelynn Bailey, University of Arkansas; Chomani Gaspe, Riis Card, Laboratory for Physical Sciences; Shiva Davari, Mariam Afrose, University of Arkansas; Thomas Hazard, Kyle Serniak, MIT Lincoln Laboratory; Kasra Sardashti, Laboratory for Physical Sciences; Hugh Churchill, University of Arkansas; Christopher Richardson, Laboratory for Physical Sciences*

Voltage tunable Josephson junctions (JJs) based on planar semiconductor quantum wells have potential to realize voltage tunable qubits fabricated at scale. Josephson junctions are fabricated from undoped Germanium quantum wells (Ge-QWs), grown by Molecular Beam Epitaxy (MBE), with carrier mobility greater than $40,000 \text{ cm}^2/\text{Vs}$ and hole density less than $1 \times 10^{12} \text{ cm}^{-2}$. These junctions use epitaxial aluminum to make transparent contact to the Ge-QW and a mesa structure that is $2.5\text{-}\mu\text{m}$ tall with only the JJ on top, minimizes microwave loss from epitaxial layers, which is critical for superconducting qubits. This presentation will demonstrate gate tunable critical currents and discuss the characterization of MBE-grown Ge JJs along with the path toward integrating these JJs into gatemon qubits.

11:15am QS2-MoM-13 Development of Ge/SiGe Semiconducting Quantum Dot Devices for Hole-Based Spin Qubits, *Giovanni Franco-Rivera, Jason Dong, University of Maryland College Park; Alan Kramer, Laboratory for Physical Sciences; Kasra Sardashti, University of Maryland College Park; Robert Butera, Laboratory for Physical Sciences*

Confining few electrons in silicon-based heterostructures via lithographically-defined, gated on-chip quantum dots (QD) enables the manipulation of the spin degree of freedom for quantum information processing. In recent years, the hole-based QDs based on strained Ge/SiGe semiconducting quantum wells have rapidly advanced as a compelling platform for spin qubits [1]. Some of the appealing features of the Ge-based spin qubits are their coherent properties achievable by solid-state all-electrical control readout enabled by their intrinsic spin-orbit interaction [2], and their prospects of scalability resulting from long-range coupling via superconducting circuits [3]. From a fabrication standpoint, two key components for the formation of the Ge-QDs is the electrical contacts to the Ge-well and the gate dielectric interface quality over the active dot area. On the aforementioned aspect, we explore the use of metallic germano-silicide contacts to the Ge quantum well due to their lower temperature requirements for the fabrication and ability to be proximitized to the quantum dot active area avoiding structural damages caused by a high fluence ion implantation. We estimate the contact resistance via low temperature transport measurements on gated transfer line method devices (TLMs) with contacts formed by platinum germano-silicides (Pt-Ge-Si). On the later aspect, the gate dielectric interface, we focus on optimizing the quality of the ALD-grown $\text{Al}_2\text{O}_3/\text{SiGe}$ interfaces. We present the results from a series of X-ray photoemission spectroscopy (XPS) measurements on the $\text{Al}_2\text{O}_3/\text{SiGe}$ and $\text{Al}_2\text{O}_3/\text{Pt-Ge-Si}$ interfaces. Our XPS data points to the presence of unwanted Ge in the dielectric interface layer presenting a medium for charge traps that contribute a significant source of charge noise in the device. Lastly, we present methods to mitigate the Ge presence in the gate stack and near the $\text{Al}_2\text{O}_3/\text{Pt-Ge-Si}$ interface.

References:

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11:30am **QS2-MoM-14** Post-processing of Josephson Junctions for Precision Tuning of Qubit Frequencies, **David P. Pappas**, **X Wang**, **Joel Howard**, **Greg Stiehl**, **Cameron Kopas**, **Stefano Poletto**, **Xian Wu**, **Mark Field**, **Nicholas Sharac**, **Christopher Eckberg**, **Hilal Cansizoglu**, **Raja Katta**, **Josh Mutus**, **Andrew Bestwick**, **Kameshwar Yadavalli**, Rigetti Computing; **Jinsu Oh**, Ames Laboratory; **Lin Zhou**, **Matthew Kramer**, Ames Laboratory **INVITED**

Thin layers of thermal aluminum oxide are the dominant material for making Josephson tunnel-junctions (JJs). These JJs are the key component for qubits in most superconducting implementations of quantum computing. It has become clear that it is necessary to address the issue of JJ homogeneity in order to more precisely tune the qubit frequencies. Work towards this using the newly developed alternating-bias assisted annealing (ABAA) technique will be discussed. ABAA illuminates a promising path towards precision tuning of qubit frequency post-processing while attaining higher coherence due to an apparent reduction in junction loss. Here, we demonstrate precision tuning of the qubits by performing ABAA at room temperature using commercially available test equipment and characterizing the impact of junction relaxation and aging on the resistance spread after tuning. A study of the structural properties of the material using transmission electron microscopy will be given with some thoughts of what the driving mechanism for ABAA is at the atomic scale.

Thin Films

Room 206 B W - Session TF1-MoM

Fundamentals of Thin Films I

Moderators: **Jeffrey Elam**, Argonne National Laboratory, **Paul Poodt**, Eindhoven University of Technology, Netherlands

8:15am **TF1-MoM-1** Reduced Oxide Epitaxy at Very High Temperatures, **Joseph Falson**, Caltech **INVITED**

In this presentation I will discuss epitaxial growth of reduced oxides at very high temperatures and low oxygen pressures, with a specific focus on binary transition metal oxides. We have stabilized a range of high quality films where in addition to injected oxygen, diffusion of anions from the substrate fuels crystal growth and promotes excellent crystallinity. I will also discuss the use of these atomically flat epitaxial layers as building blocks towards complex heterostructures constructed from dissimilar material classes.

8:45am **TF1-MoM-3** High Entropy Oxide Epitaxial Thin Films via Far-from-Equilibrium Synthesis, **Saeed S. I. Almishal**, **Matthew Furst**, **Sai Venkata Gayathri Ayyagari**, The Pennsylvania State University; **Pat Kezer**, University of Michigan, Ann Arbor; **Nasim Alem**, The Pennsylvania State University; **Christina Rost**, Virginia Tech; **John Heron**, University of Michigan, Ann Arbor; **Jon-Paul Maria**, The Pennsylvania State University

High entropy oxides (HEOs) are inherently metastable, with properties that are highly sensitive to their thermal history and formation kinetics. Pulsed laser deposition (PLD) stabilizes atomic and electronic configurations far from equilibrium, enabling the exploration of structural and electronic phases inaccessible via conventional bulk synthesis. By precisely tuning growth temperature and rate, PLD directs how materials access metastability and allocate configurational entropy, locally acquiring order within a globally disordered matrix. We exemplify this strategy by growing $MgCoNiCuZnO$ epitaxial thin films, where precise control over substrate temperature and oxygen partial pressure yields up to a 6% variation in the out-of-plane lattice parameter in pseudomorphic thin films across a 200 °C range. By slowing the growth rate or increasing film thickness fivefold, we can induce the formation of two distinct nanostructures: copper-rich nanotwists and coherent spinel nanocuboids. Incorporating additional cations (e.g., Sc, Cr) facilitates the design of vertically stacked pseudomorphic heterostructures exhibiting exceptional crystalline fidelity and sharp interfaces. Building on these insights, we demonstrate metastable functional oxides—most notably $Sr_x(Ti,Cr,Nb,Mo,W)O_3$ films—where engineered chemical disorder while maintaining structural order enhances both electron correlation and spin-orbit coupling. Our work demonstrates how entropy-assisted, far-from-equilibrium synthesis via PLD provides transformative opportunities for designing novel functional oxides, significantly expanding the landscape of crystalline materials.

9:00am **TF1-MoM-4** ALD with Alternative Co-Reactants: Which Work, Which Do Not, and Why, **Jay Swarup**¹², **Robert Mercogliano**, **James Jensen**, **Geet Chheda**, **Robert DiStasio Jr.**, **James Engstrom**, Cornell University

For a number of ALD processes, it is desirable to employ alternative co-reactants to achieve a variety of objectives, which include modifying the temperature window, optimizing the stoichiometry of the thin film, and eliminating undesirable side reactions. Concerning the latter, we have demonstrated that using *t*-BuOH in lieu of H_2O as a co-reactant in ALD with trimethyl aluminum (TMA) results in deposition of a thin film of Al_2O_3 that does not oxidize the underlying Co substrate, while use of H_2O does [1]. Here we build upon this previous work using a combination of experiments and theory to examine systematically a series of alcohols—primary, secondary and tertiary—as co-reactants with TMA for the ALD of Al_2O_3 . We compare these results to the benchmark TMA/ H_2O process and investigate the role of temperature. We have employed a quartz-crystal microbalance to monitor ALD *in situ* and in real-time, and the deposited thin films have been characterized using XPS. In parallel, we utilized density functional theory (DFT) calculations to identify key reaction intermediates and quantify the kinetics of surface reactions. At a temperature of $T = 120$ °C we find that none of the 8 alcohols examined result in steady growth of a thin film of Al_2O_3 . At a temperature of $T = 285$ °C the situation is quite different, as steady growth is observed, but only by employing tertiary alcohols as co-reactants. Steady growth does not occur with the 6 primary and secondary alcohols examined. For example, concerning structural isomers of C_4H_9OH and $C_5H_{11}OH$, *t*-BuOH and 2-methyl-2-butanol result in steady growth, while 2-butanol and 3-methyl-2-butanol do not. Our calculations using DFT verify the essential role played by the tertiary -OH groups in facilitating the reaction with the chemisorbed species formed in the TMA half-cycle. We find that the important reaction intermediate involves an interaction between an adsorbed alkoxy species with another alcohol, producing -OH(a) species. A final issue we addressed concerned the effect of intentionally introducing a small amount of H_2O into the alcohol co-reactants. We find that a mixture of *t*-BuOH and a small amount of H_2O results in steady growth at $T = 120$ °C, whereas pure *t*-BuOH did not. Similarly, a mixture of *i*-PrOH and a small amount of H_2O results in steady growth at $T = 285$ °C, whereas pure *i*-PrOH did not. Overall, our study highlights the critical roles played by alcohol order, process temperature, and the influence of small amounts of H_2O impurity on the efficacy of using alcohols as co-reactants in ALD.

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9:15am **TF1-MoM-5** Enhancing Atomic Layer Deposition Reactor Efficiency for Iridium Thin Films: Balancing Sustainability and Performance in Film Growth, **Jaron Vernal Moon**, **Timothy J. Gorey**, Los Alamos National Laboratory

Atomic layer deposition (ALD) is a useful technique that enables atomic layer-by-layer growth of conformal films, but the technique is inherently wasteful due to the conventional viscous flow of chemical precursor injection, where the flow stream results in faster film growth at the stream-sample interaction point, reducing coating conformality. This work presents a new, “hold-step” ALD reactor that greatly increases efficiency of conformal film growth while reducing chemical use for improved sustainability. This work specifically focuses on iridium and iridium oxide thin films. By delving deeper into the understanding of the iridium precursor physical properties at temperature, the ALD recipe is tuned to best promote efficient iridium film growth kinetics. By introducing a “hold-step”, the reaction zone is isolated from the vacuum pump during dosing and the pressure is held constant for a set amount of time, resulting in improved film growth as the dosing gases are permitted to diffusively permeate and chemisorb onto embedded surfaces more efficiently. Additionally, characterizing the iridium precursors using techniques such as gas chromatography and thermogravimetric analysis, the ALD reaction can be fine-tuned for effective film growth. By changing from viscous to static flow and better understanding of the precursor kinetics, the total amount of gas required per deposition cycle is substantially reduced. A hold-step reactor design will be presented and compared to traditional ALD reactor designs. For comparison, precursors quantities and the resulting film qualities will be compared. The innovative yet simple design of a hold-step reactor not only enhances film quality but also promotes sustainability by reducing waste gas usage.

¹ TFD James Harper Award Finalist

² JVST Highlighted Talk

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9:30am **TF1-MoM-6 Diffusion, Reaction and Thermodynamics of Organic Vapor Phase Infiltration to Overcome Shortcomings of Inorganic Hybridization, Brian Welch**, Technion Israel Institute of Technology, Israel; **Bratin Sengupta**, Argonne National Laboratory, USA; **Ruke Cai**, Technion Israel Institute of Technology, Israel; **Vera Rozynev**, Argonne National Laboratory, USA; **Eitan Feldman**, Rice University; **Anil Mane**, Argonne National Laboratory, USA; **Alon Grinberg Dana**, Technion Israel Institute of Technology, Israel; **Jeffrey Elam**, Argonne National Laboratory, USA; **Tamar Segal-Peretz**, Technion Israel Institute of Technology, Israel

Vapor phase infiltration (VPI) enables tailoring of polymeric materials through incorporation of inorganic components. However, the benefits of VPI (also known as sequential infiltration synthesis, SIS) – are often paired with drawbacks such as compromised mechanical stability. Furthermore, the resulting organic-inorganic bonds are often prone to degradation through hydrolysis. To overcome these limitations, we investigate all-organic VPI using step growth molecular layer deposition (MLD) chemistries as a strategy for enhancing polymer properties. We examine the reaction-diffusion kinetics and thermodynamic behavior of three aromatic step-growth polymerization reactions: polyamide, polyurea, and polyimine. Their material growth occurs via MLD at the surfaces of non-absorbing silicon and zirconia. Organic VPI occurs within the bulk of nucleophile-rich polyvinyl alcohol (PVA), but not through physical entrapment in unreactive polystyrene and poly(methyl methacrylate). Using a reaction-diffusion model, we quantify diffusion-limited polyamide and reaction-limited polyurea nucleation behavior in PVA, identifying key parameters: diffusivity, reaction rate, and Damköhler number. Unlike inorganic alumina treatment, organic modification enhances dissolution-resistance in PVA, preserving polymer integrity and resisting hydrolysis even in harsh pH 13 solutions. This study demonstrates the potential of all-organic material deposition for synthesizing novel polymers with improved durability and solvent resilience.

9:45am **TF1-MoM-7 Tailoring Ba-Based Thin Films for Security Imaging: Role of H₂O Reactivity and Al₂O₃ Supercycle Integration in ALD, Adnan Mohammad**, Chi Thang Nguyen, Nuwanthaka Jayaweera, Jacob Kupferberg, Jeffrey W. Elam, Argonne National Laboratory, USA

Microchannel plate (MCP) electron amplifiers are important components in large-area photodetectors, particularly for security-related applications such as night vision, radiation monitoring, and surveillance. Enhancing their performance and gain depends on advanced thin film coatings with high secondary electron yield (SEY). Barium-containing materials, recognized for their high SEY properties, are highly promising candidates for emissive coatings in MCPs. Atomic layer deposition (ALD) has emerged as a leading fabrication technique for such films, offering advantages in uniformity, pinhole-free morphology, and atomic-scale thickness control at low processing temperatures. However, despite ALD's potential, research on barium-thin films via this method remains under-explored. Notably, no prior work has investigated ALD-synthesized barium-based coatings in MCPs, presenting a significant opportunity to bridge this gap.

In this study, we demonstrate the thermal atomic layer deposition (ALD) of barium-containing thin films using bis(tri(isopropyl)cyclopentadienyl)barium (Ba(iPr₃cp)₂) as the barium precursor and water (H₂O) as the co-reactant. We further investigate the structural and functional impact of incorporating alumina via super-cycle deposition within the Ba(iPr₃cp)₂/H₂O process. The Ba(iPr₃cp)₂ precursor was vaporized at 175°C, and depositions were performed in a hot-wall reactor at 250°C under a pressure of ~1.2 Torr. Systematic saturation studies were conducted to optimize precursor temperature, dose time, purge duration, and co-reactant exposure. Real-time thin film growth was monitored using in-situ ellipsometry, which enabled rapid saturation analysis while providing valuable insights into surface reactions during each ALD cycle.

The barium-containing films were characterized using X-ray photoelectron spectroscopy (XPS) for chemical composition, X-ray diffraction (XRD) for crystalline structure, X-ray reflectivity (XRR) for density, and atomic force microscopy (AFM) for surface topography. Moving forward, we aim to integrate ALD-grown barium layers onto microchannel plate (MCP) substrates and systematically evaluate their resistance, gain, and temporal stability. These metrics will directly assess secondary electron yield (SEY) performance, validating the material's potential as a high-SEY coating to enhance MCP efficiency.

Thin Films

Room 206 B W - Session TF2-MoM

Characterization of Thin Films

Moderators: Joseph Falson, Caltech, John Hennessy, Jet Propulsion Laboratory (NASA/JPL)

11:00am **TF2-MoM-12 Data Science Tools to Disentangle Large Electron Diffraction Datasets of Thin Films, Matthias Young, Andreas Werbrouck, Andrew Meng, Dilan Gamachchige, Indeewari Herathlilage, Nikhila Paranamana, Xiaoqing He**, University of Missouri

Historically, the thin film community has been largely driven by process-property understanding, and we have had limited access to deep understanding of the atomic-scale structure of vapor-deposited thin films. This arises from challenges in measuring the atomic structure of these films due to (1) their amorphous, polycrystalline, and defective structures, and (2) the ultrathin film thicknesses, often with gradients in composition and structure in the x-y and z directions. Prior work has established an understanding of how the structure of vapor-deposited thin films evolves during growth using bulk measurements such as infrared spectroscopy, synchrotron diffraction, and nuclear magnetic resonance, or surface sensitive measurements such as X-ray photoelectron spectroscopy. However, these approaches struggle to provide position- or depth-dependent atomic structure information, especially at sub-nanometer length scales. In recent years, our group has employed transmission electron microscopy (TEM) diffraction to measure the atomic structure of atomic layer deposition (ALD) films with high spatial resolution across nanoscale interfaces. However, even with TEM, the presence of multiple phases and orientations that are distributed in different amounts throughout the film volume and co-located in the beam path in each diffraction image make interpretation challenging. Here, we employ a data science algorithm known as non-negative matrix factorization (NMF) to identify the unique component diffraction signals and map their locations throughout ultrathin interfacial volumes. To facilitate this on the large volume of data present from a series of 2D diffraction patterns collected over a rastered 2D measurement area during scanning TEM (4D-STEM), we report the use of QR decomposition for randomized non-negative factorization as well as feature reduction through superpixel clustering. Together the speed-ups provided by these approaches allow for the rapid processing of high volumes of TEM data, enabling component isolation and spatial mapping for several gigabytes of electron diffraction data in minutes on a laptop compared to the hours required without these acceleration approaches. This allows us to quickly distill high volumes of data down to meaningful insights with low computational overhead, promising to enable more rapid discovery and innovation in the thin film community.

11:15am **TF2-MoM-13 A Novel Approach to Study EUV and BEUV Photoresist Sensitivity through Real-time μ XPS, Peter Sun, Samuel Tenney, Chang-Yong Nam, Jerzy Sadowski**, Brookhaven National Laboratory

Extreme ultraviolet (EUV) and beyond extreme ultraviolet (BEUV) lithography can achieve sub-10 nm features in semiconductor manufacturing. These nanoscale patterns require photoresists to be highly sensitive to EUV and BEUV conditions. One of the photoresist candidates are polymethyl methacrylate (PMMA) based hybrid photoresists with vapor phase infiltrated (VPI) inorganic materials.

The sensitivity of the photoresists depends on photo absorption efficiency, secondary electron generation, and material degradation. Currently, sensitivity studies mainly focus on characterizing developed films, an approach that cannot decouple photoresist sensitivity and developer sensitivity. To isolate the photoresist sensitivity, a method to study these photoresists' in situ exposure behavior before development is needed.

This report presents a novel approach to studying photoresist sensitivity through in situ real-time low-energy electron/photoemission electron microscopy (LEEM/PEEM) and micro-spot X-ray photoelectron spectroscopy (μ XPS). In particular, we model the time-dependent chemical change and the charging behavior of the photoresists under X-ray exposures at 92 eV and 400 eV. We show the approach is reliable in determining the PMMA and its VPI hybrids' sensitivity to EUV and BEUV conditions. This approach will allow the study of a broader range of EUV and BEUV photoresist candidates and assist in next-generation photoresist and developer selection.

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Source II at Brookhaven National Laboratory under Contract No. DE-SC0012704.

11:30am **TF2-MoM-14 Stoichiometric Determination in Thin Films: A Study of BaTiO₃, Peter Dickens, Melissa Meyerson, Mark Rodriguez, Clare Davis-Wheeler, Jonathan Heile, William Wampler, Christian Harris, Brianna Klein, Sandia National Laboratories**

Thin films are essential in modern technology, providing unique properties for electronic, sensor, and optical applications. As more complex alloys and compounds are integrated onto devices, the need to effectively characterize material composition becomes increasingly important. To surmount this hurdle, many different methods are utilized throughout literature with XRF, XPS, and EDX being prime among the reported methods; however, it is common for there to be little to no discussion on the analysis, nuances, and accuracy of the technique used. These issues are further exacerbated by the common availability of black box analysis associated with each of these techniques leading to reports and conclusions based on imprecise analysis.

In this presentation we use BaTiO₃ as a case study material to compare each of the common compositional methods. We report on the determination of the Ba/Ti atomic ratio in four thin films deposited by sputter deposition under conditions to produce a range of stoichiometries. We directly compare analysis produced from X-ray Fluorescence (XRF), Rutherford Backscatter Spectroscopy (RBS), Inductively Coupled Plasma Optical Emission Spectroscopy (ICP-OES), X-ray Photoelectron Spectroscopy (XPS), and Wavelength Dispersive Spectroscopy (WDS). Discussion is focused on accuracy of each technique and nuances related to each method and the analysis.

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SAND2025-04533A

11:45am **TF2-MoM-15 Advanced Characterization of Inorganic and Organic Liners for Through Vias in Glass Packages, Meghna Narayanan, Mohan Kathaperumal, Mark Losego, Georgia Institute of Technology, USA**

Electronic packaging technology is evolving towards advanced substrates, including glass, to overcome limitations posed by traditional organic substrates. Glass packaging offers low dielectric loss, high modulus, low and tunable coefficient of thermal expansion (CTE), enhanced thermal stability, high I/O density, and reduced warpage. However, fully adopting glass packaging technology still faces several hurdles, including metal adhesion, stress management, and a full understanding of long-term reliability. The CTE mismatch between glass and copper (5 to 15 ppm/°C) leads to reliability issues such as glass and through-glass via (TGV) cracking, copper via protrusion, and delamination. We aim to address the glass and TGV cracking by introducing an organic or inorganic liner inside the TGV to act as a stress buffer, lowering the propensity for TGV electrode failure. In this study, we will describe TGV substrates coated with different liners – Parylene C, SiO₂N, SiO₃N, AZO (Aluminium-Zinc oxide), and Parylene C+AZO, obtained through different methods of deposition. The foremost step is to characterize if the liner is conformally coating the 100 µm diameter via. Conformal coating is essential to mechanical performance and even electroplating through the entire depth of the TGVs. A non-uniform liner coating will lead to an uneven Ti-Cu seed layer prior to electroplating of copper. Since the liner can be 0.1 to 5 µm thick, cross-sectioning is inadequate for post-plating liner inspection. Non-destructive methods for evaluating these coatings would also be of value to research and development, as well as in-line process monitoring. We have evaluated the effectiveness of several methods. In this work, two advanced techniques—two-photon imaging and micro-computed tomography (microCT)—are used to assess liner uniformity and measure thickness. Two-photon imaging is particularly effective for fluorescent materials like Parylene C and SiO₂N, enabling visualization and thickness measurement within TGVs. The thickness of Parylene C is measured to be 5.6 µm (expanding to 8.7 µm near the surface), and Parylene C+AZO is measured to be 1.87 µm (expanding to 2.8 µm near the surface). Although AZO and SiO₂N are fluorescent, the nanoscale thickness (< 100 nm) is challenging to measure due to the resolution of the tools. The paper will propose additional metrology tools and show preliminary attempts to measure such nanoscale thicknesses. We will also show preliminary results on plating the liner.

coated TGVs to assess their performance in mitigating crack formation upon thermal cycling.

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Applied Surface Science

Room 209 B W - Session AS-MoA

Quantitative Surface Analysis I

Moderator: Lyndi Strange, Pacific Northwest National Laboratory

1:30pm AS-MoA-1 Quantified Photoemission Using Ga Ka (9.25 keV) Hard

X-Rays Applied to Advanced Materials, Ben Spencer, Abdulrhman Alsaedi, Liam Dwyer, The University of Manchester, UK; Benjamen Reed, David Cant, Alexander Shard, National Physical Laboratory, U.K.; Michael Baker, Alex Walton, Nicholas Lockyer, Wendy Flavell, The University of Manchester, UK

INVITED

X-ray photoemission spectroscopy (XPS) sampling through the sub-surface towards the bulk requires higher X-ray photon energies generating higher Kinetic Energy photoelectrons. We detail how this is enabled in the Scienta Omicron Hard X-ray Photoelectron Spectrometer (HAXPES) laboratory instrument utilising a 9.25 keV X-ray source (Ga Ka MetalJet, Excillum) and EW4000 electron energy analyser [1-6]. Laboratory systems offer some important advantages over synchrotron X-ray sources including easier access, highly reliable source intensities, and the development of reliable quantification methodologies [7]. We demonstrate how HAXPES can extract information significantly further into the surface compared to traditional approaches, with sampling depths up to twenty times the inelastic mean free path enabled by analysis of the inelastic background [2,5], and we detail the metrology developed to ensure accurate quantification across the measurable Binding Energy range [2-6]. 9.25 keV HAXPES enables measurement of higher Binding Energy core levels, such as 1s core levels of first row transition metals (up to Cu 1s at 8.98 keV), and previously unmeasured Auger transitions. We highlight measurements of higher Binding Energy core levels for quantification and chemical state identification applied to energy materials, where deeper core levels offer enhanced relative sensitivities compared to traditional XPS [8], and including the analysis of satellite peak structures as compared to theoretical calculations. As such we demonstrate the capabilities of laboratory HAXPES with a view to future developments and applications to advanced materials research.

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2:00pm AS-MoA-3 Quantification of Bulk MoS₂ and Characterization of Mo Oxides by Cr Ka-excited HAXPES : Issues and Tentative Improvements, Olivier Renault, Nicolas Gauthier, Mario Ghostine, Roman Charvier, CEA-Leti, France; Bruno Domenichini, Université Bourgogne-France Comté, France

In this presentation, we will present HAXPES results related to Mo compounds of practical interest in device technology. Spectra of bulk MoS₂ were acquired with a Cr Ka source following a careful measurement protocol [1]. The latter includes checking for instrument stability, use of pure-element relative sensitivity factors and an improved determination of the spectrometer transmission function. The results indicate large errors in the determination of the stoichiometry depending on the selected core-lines. Preliminary results obtained on pure metallic, homogeneous Mo surfaces show potential improvements if the measured intensity takes into account inelastic losses which are important at high kinetic energies. A second part will be dedicated to sub-stoichiometric Mo oxide films with a particular attention to beam effects, the impact on the determination of the stoichiometry along with suitable protocols for accessing deeply buried interfaces.

In a second topic, we will address the case of sub-stoichiometric Mo oxide films which are photochromic materials and are prone to alterations upon X-ray irradiation, with consequences on the determination of the Mo/S ratio. We will comment on the origins of these alterations and propose solutions towards a reliable analysis, before presenting results regarding deeply buried interfaces.

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Acknowledgment : This work, carried out on the Platform for Nanocharacterisation (PFNC), was supported by the "Recherche Technologique de Base" and "France 2030 - ANR-22-PEEL-0014" programs of the French National Research Agency (ANR).

2:15pm AS-MoA-4 Routine, Integrated Ag-La HAXPES – Acquisition and Quantification, Miroslav Michlicek, Thermo Fisher Scientific, CZ, Czechia; Keith McCourt, Paul Mack, Thermo Fisher Scientific, UK

Hard X-ray photoelectron spectroscopy (HAXPES) has significantly evolved since its inception and early use in synchrotron facilities, and is nowadays readily available in lab-based instruments. Especially when used in tandem with standard Al-Ka XPS spectroscopy, the method offers deep insight into the electronic structure of materials and can help to resolve some ambiguities inherent to standard XPS. Despite its advantages, HAXPES has faced several challenges, including accurate peak quantification.

This work addresses the steps necessary to overcome these quantification challenges for Ag-La HAXPES data. We first discuss critical experimental considerations for ensuring accurate and reproducible measurements, namely the reproducibility of the monochromator crystal. We then examine the three pillars supporting the peak area quantification: relative sensitivity factors, escape depth correction and instrument transmission function. In particular, we detail our approach to estimating the instrument transmission function. The robust, factory-default estimate was acquired by global fitting of noble metals (Au, Ag, Cu) spectral datasets collected from multiple instruments. Finally, we present the combined quantification accuracy on several pure elements (i.e. from different transitions) and binary compounds with an expected stoichiometry. In conclusion, the integrated automated anode switching coupled with data quantification software, represents a significant step forward in making routine Ag-La HAXPES acquisition practical and reliable.

2:30pm AS-MoA-5 Non-Destructive Depth Profiling by Variable Energy PARXPS (VE-PARXPS), Paul Dietrich, Francesca Mirabella, Martin Breitschaff, Andreas Thißen, SPECS Surface Nano Analysis GmbH, Germany

Chemical analysis of contemporary materials frequently entails the characterization of surface and bulk compositions. EnviroMETROS LAB and FAB provide a monochromated small spot X-ray source with up to three different photon energies giving different surface and bulk sensitivities due to the variation in kinetic energy of the emitted photoelectrons. Moreover, the angle-resolving, wide-angle electron analyzer AEOLOS 150 AD-CMOS together with the software enables high sensitivity and high resolution analysis with direct non-destructive depth profiling.

Variable Energy X-ray photoelectron spectroscopy (VE-XPS) employs tunable X-ray sources, such as synchrotrons or laboratory-based monochromators, to adjust the photon energy. This adjustment enables depth profiling and enhanced sensitivity to different core-levels. By tuning the photon energy, the kinetic energy of emitted photoelectrons can be controlled, effectively changing the inelastic mean free path (IMFP). This capability allows for analysis of surface, subsurface, and bulk regions.

In parallel angle-resolved XPS (PARXPS) photoelectrons at various emission angles are collected simultaneously using a wide-angle analyzer. This method facilitates the concurrent acquisition of spectra from multiple angles, thereby enhancing the efficacy and precision of probing depth and electronic structure. PARXPS allows to create concentration depth profiles from data that was taken for different photoelectron emission angles. A parallel spectra collection of individual angle channels is possible with the AEOLOS 150 AD-CMOS analyzer, developed especially for performing PARXPS measurements.

VE-XPS allows for the adjustment of probing and information depth, while PARXPS provides angular-resolved data, enabling non-destructive depth profiling with enhanced accuracy. By varying the energy and emission angle, more detailed information can be extracted, which is crucial for materials such as layer stacks and semiconductors. The combination of tunable energy with angular resolution enables the differentiation between surface, interface, and bulk states, thereby facilitating the acquisition of comprehensive structural information. The capacity to adjust depth sensitivity minimizes the occurrence of misinterpretation arising from charging effects or contributions from deeper layers, ensuring the reliability and precision of the measurement process. The combination of VE-XPS and PARXPS, allows to obtain a much richer dataset, enabling a more precise and comprehensive understanding of material surfaces and interfaces

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2:45pm AS-MoA-6 Efficient, Non-Destructive Characterization of Buried Layer Chemistry - Introducing the Next-Generation High-Intensity Deep HAXPES Instrument, *Marcus Lundwall¹, Tamara Sloboda, Dick Allansson, Scienta Omicron, Sweden; Daniel Beaton, Scienta Omicron; Susanna Eriksson, Scienta Omicron, Sweden*

Buried interfaces in electronic devices—such as batteries, solar cells, and transistors—play a critical role in device performance. Reliable instrumentation for characterizing these interfaces is therefore essential for material development. While X-ray photoelectron spectroscopy (XPS) is a powerful technique for probing chemical states at surfaces, it cannot directly access buried interfaces without sputtering or etching, which can introduce artifacts. Hard X-ray photoelectron spectroscopy (HAXPES) offers a solution by providing increased information depth, enabling non-destructive characterization of layered structures. As a result, HAXPES has become an invaluable tool in materials research, particularly for applications involving semiconductor thin films, polymer materials, metal surfaces, and coatings.

This presentation will provide an overview of HAXPES applications, with a focus on non-destructive studies of buried interfaces in electronic devices, operando studies and oxidation processes. Additionally, we will introduce recent advancements in lab-based HAXPES systems. The latest generation features a Ga Ka 9.25 keV MetalJet microfocus HAXPES X-ray source, alongside improvements in electron detection efficiency. Compared to its predecessor, the new system offers a several-fold increase in acquisition speed while maintaining a proven probing depth of up to 50 nm. To fully leverage these enhancements, the sample handling and navigation system has been upgraded with a larger mounting area, enabling automated acquisition across a higher number of samples and measurement points. These innovations make high-end, high-energy Deep HAXPES a viable high-throughput technique beyond synchrotron facilities.

3:00pm AS-MoA-7 Quantification of the Carbon Hybridization State via C 1s XPS: Possibilities and Limitations, *Filippo Mangolini, The University of Texas at Austin; Michael Walter, Fraunhofer Institute for Mechanics of Materials IWM, Germany; J. Brandon McClimon, Robert W. Carpick, University of Pennsylvania; Michael Moseler, Fraunhofer Institute for Mechanics of Materials IWM, Germany*

The determination of the carbon hybridization state in carbon-based materials is of pivotal importance owing to the strong dependence of the physical, chemical, and mechanical properties of these materials on the carbon bonding configuration. Despite the relevance of published studies, the quantification of the hybridization state of carbon atoms by X-ray photoelectron spectroscopy (XPS) is still a surface-analytical problem owing to the challenges associated with the unambiguous identification of the characteristic binding energy values for sp^2 - and sp^3 -bonded carbon. Here, we performed density functional theory (DFT) calculations to determine the binding energy values of C 1s core electrons on the absolute energy scale for model structures of a class of carbon-based materials, namely amorphous carbon (a-C). In the case of hydrogen-free a-C, the DFT calculations indicate that the average C 1s binding energy for sp^3 -bonded carbon atoms is approximately 1 eV higher than the average binding energy of sp^2 -hybridized carbon atoms. Notably, the introduction of hydrogen in the a-C network reduces the distance between the characteristic signals of sp^3 - and sp^2 -bonded carbon due to the increased ability to screen the core hole by neighboring hydrogen atoms as compared to carbon atoms. These results, which are in qualitative agreement with experimental XPS spectra acquired on a-C materials containing different hydrogen content, highlight that the characterization of the carbon hybridization state on the basis of fitting C 1s XPS spectra with two synthetic components, one assigned to sp^2 -bonded carbon and one assigned to sp^3 -bonded carbon, is not physically accurate in the case of a-C specimens containing hydrogen. This work can assist surface scientists in the use of XPS for the accurate characterization of carbon-based material.

3:15pm AS-MoA-8 Correlative XPS and EBSD with Cluster Ion Etching for Enhanced Surface Preparation, *Simon Bacon, Helen Oppong-Mensah, Robin Simpson, Paul Mack, Tim Nunney, Thermo Fisher Scientific, UK*

Electron Backscatter Diffraction (EBSD) is a critical technique in materials science, providing detailed crystallographic information that is essential for understanding the microstructure and properties of materials. EBSD is widely used to analyse grain size, orientation, and phase identification, which are fundamental for optimising material properties and performance in various applications. The high spatial resolution and sensitivity of EBSD

make it an invaluable tool for characterising such features in metals, ceramics, semiconductors, and other advanced materials.

However, the preparation of samples for EBSD presents several challenges. Surface contamination and damage can significantly affect the quality and accuracy of EBSD data. Traditional mechanical polishing methods often introduce surface artifacts that obscure the true microstructure of the sample. Ensuring the precise alignment and correlation of data between different analytical techniques also poses difficulties and can hinder any characterisation efforts.

To address these challenges, we demonstrate a solution that integrates a correlative XPS-SEM workflow (CISA) with cluster ion beam etch sample preparation. XPS offers detailed surface chemical analysis in the form of elemental composition and chemical state information. Cluster etching provides a controlled method for cleaning and defining surfaces, which helps to minimise contamination and damage. The CISA workflow ensures accurate alignment and correlation of data between XPS and EBSD analyses. By utilising specialised sample holders and advanced software alignment routines, we can achieve precise co-location of analytical data, which improves reliability and reproducibility of the results.

In summary, the combination of XPS and EBSD is a powerful one, offering comprehensive chemical and microstructural characterisation of materials. The use of both cluster ion beam etching as an integrated sample preparation method and the CISA workflow for precise feature location and alignment, ensures high quality, reliable cross-technique data to facilitate advancements in materials science and engineering.

3:30pm AS-MoA-9 Enhanced Depth Profiling of Polymer Multi-Layer Samples Using Combined Femtosecond Laser Ablation and Cluster Ion Beams in XPS, *Robin Simpson², Thermo Fisher Scientific, UK; Charlie Chandler, Mark Baker, University of Surrey, UK; Tim Nunney, Thermo Fisher Scientific, UK*

X-ray Photoelectron Spectroscopy (XPS) is a critical technique for surface and interface analysis, providing elemental and chemical state information. Depth profiling of polymer multi-layer samples, however, presents significant challenges due to the potential for sample damage and chemical modification during the sputtering process. To address these challenges, we propose a novel approach that integrates femtosecond laser ablation with cluster ion beam sputtering for XPS depth profiling.

Femtosecond laser ablation offers precise material removal with minimal thermal damage, making it ideal for initial bulk material removal. Cluster ion beams, known for their gentle sputtering capabilities, are then employed for fine-scale depth profiling, reducing the risk of chemical alteration and maintaining the integrity of the polymer layers.

In this study, we systematically investigate the combined use of femtosecond laser ablation and cluster ion beams on polymer multi-layer samples. We calibrate the laser and ion beam parameters to optimize ablation rates, minimize surface roughness, and ensure accurate depth resolution. Our results demonstrate significant improvements in depth profiling accuracy and chemical specificity, allowing for detailed characterization of each polymer layer.

The hybrid approach enhances the depth profiling capability of XPS, providing a powerful tool for analyzing complex polymer structures. The integration of femtosecond laser ablation and cluster ion beams enables high-resolution depth profiling, offering new insights into the composition and chemical states of multi-layer polymer samples.

Our findings highlight the potential of this combined technique to advance the field of polymer analysis and other applications requiring precise depth profiling. Future work will focus on further optimization of the parameters and extending the technique to a wider range of materials.

4:00pm AS-MoA-11 Contribution of Imaging X-Ray Photoelectron Spectroscopy (Xps) to Characterize Spatial Chemical Distribution of Zno Nanoparticles in a Protective SiO₂ Matrix for Luminescence Application, *Vincent Fernandez, IMN-CNRS, France; Michel Féron, LCC-CNRS, France; Neal Fairley, CasaXPS, France; Myrtil Kahn, LCC-CNRS, France; Richard Clergereaux, LPCE-CNRS, France; Mireille Richard-Plouet, IMN-CNRS, France*

Due to their potential applications, white-light emitting materials have attracted extensive research interest. The covered fields of applications include information display, fluorescent sensors, and solid-state lighting. Among them zinc oxide with its photoluminescence characterized by two main bands: one related to excitons below 400 nm and a broad emission in the visible range could enable to obtain white light emission. In order to

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protect nanocrystalline phosphors such as ZnO nanoparticles (NPs) and keep their emission performance, a strategy is to embed them in transparent matrix. Among the possible oxides fulfilling the specification, silica was identified as a suitable candidate thanks to its chemical stability and non-toxicity.

Nanocomposite (NC) thin films are prepared by a hybrid process [1] combining injection, at low pressure, of colloidal ZnO solution, forming an aerosol, in a Plasma Enhanced Chemical Vapor Deposition (PECVD) reactor. Thus innovative thin films consisting of ZnO nanoparticles and SiO₂ using this hybrid process were deposited by injection of nanoparticles stabilized by organic ligands and dispersed in 20%vol pentane-80%vol HMDSO solution in an Ar plasma. These films were characterized by XPS and by parallel Imaging energy scan XPS [2] on a Kratos Nova optimized instrument [3]. Data were analyzed using CASAXPS 2.3.27 [4]. Zn 2p, O1s, C1s and Si 2p Core levels were measured in parallel Imaging energy scan XPS with an energy resolution of 1.12 ±0.05 eV measured on Ag 3d5/2. Data analyses show anti-correlation between the atomic concentration of Zn, associated to ZnO nanoparticles, and both the atomic percentages of Si, associated to SiO₂ Fig 1 and the atomic concentration of Carbon fig 2. Moreover the energy resolution is good enough to map separately the amount the O bound to Zn, at 530.8 eV and the O linked to Si, at 532.6 eV.

These results highlight the possibilities offered by XPS imaging, allowing us to shed light on mechanisms involved during drying of the aerosol droplets at the substrate surface.

Acknowledgments

“Measurements were performed using the IMN’s characterisation platform, PLASSMAT, Nantes, France.”

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4:15pm AS-MoA-12 Uncertainties in XPS Elemental Quantification, *Alexander Shard, Benjamen Reed, David Cant*, National Physical Laboratory, UK

X-ray photoelectron spectroscopy (XPS) is routinely employed to measure surface compositions. The standard approach to quantification treats the surface region as if it is homogeneous and applies sensitivity factors to measured peak intensities to calculate the ‘equivalent-homogeneous composition’ of the sample expressed as a mole fraction, which is usually converted to atomic percent. In this talk, we briefly summarise the main contributions to uncertainty in XPS composition measurements and provide mathematical expressions through which the uncertainty in the measured composition can be estimated and reported. Contributions to the measurement uncertainty from peak area measurement, detector linearity, sensitivity factors, spectrometer transmission and analytical practice are outlined and combined. We show that the statistical uncertainty in peak area measurement usually contributes negligibly to the accuracy of the measurement, but is the main factor that determines the precision. The best practices to improve the precision and accuracy of standard ‘equivalent-homogeneous composition’ XPS quantification are outlined.

4:30pm AS-MoA-13 Revisiting Detector Linearity and Deadtime Correction for Photoelectron Spectrometers, *Benjamen Reed, Alexander Shard*, National Physical Laboratory, U.K.

In x-ray photoelectron spectroscopy (XPS) data, the integrated area under a core level peak is proportional to the atomic fraction of that element in the sample. Therefore, confidence in the intensity scale of a photoelectron spectrometer is vital for quantitative analysis. Sample dependent factors aside, the XPS analyst must calibrate for the relative intensity response (or transmission function) of their analyzer, which is largely a result of the electrostatic lens column and is unique for each instrument. However, even before a spectrum is acquired, there must be confidence that the measured count rate of the analyzer’s detection system is correct. At high count rates, the photoelectron detector may exhibit non-linearity that significantly affects measured count rates, and therefore the peak intensities from which atomic fractions are calculated. At even higher count rates, detector saturation may occur.

So, although it is tempting to conduct XPS measurements with increased count rates (e.g. by increasing x-ray emission and using high-throughput lens modes / collimation settings) with the intent to improve signal-to-noise and reduce experiment times, this approach is stymied by the limits of the detection system itself. Awareness of this limitation of photoelectron detectors may not be universally known throughout the XPS users’ community; in a recent VAMAS interlaboratory study on XPS intensity calibration, a number of datasets on sputter-cleaned gold were submitted that exhibited evidence of detector non-linearity.

With the international standard on detector linearity (ISO 21270) due for systematic review in 2026, it seems appropriate to revisit these concepts for the benefit of the surface analysis community. We present a method for assessing the linearity and deadtime correction of photoelectron detectors based on the *spectrum ratio* method from ISO 21270 with improved data selection criteria for multi-channel detectors. We also discuss the effect of non-linearity and incorrect deadtime correction on XPS quantification.

4:45pm AS-MoA-14 Beyond the Standard Elemental Analysis of Surfaces - What more can be done with XPS?, *Donald Baer*, Pacific Northwest National Laboratory; *Merve Taner Camci*, Turkish Energy, Nuclear and Mineral Research Agency, Turkey; *David Cant*, National Physical Laboratory, UK; *Scott Chambers*, Pacific Northwest National Laboratory; *Hagai Cohen*, Weizmann Institute of Science, Israel; *Pinar Aydogan Gokturk*, Koc University, Turkey; *David J. Morgan*, Cardiff University and HarwellXPS, UK; *Andrey Shchukarev*, Umeå University, Sweden; *Peter Sherwood*, University of Washington; *Sven Tougaard*, University of Southern Denmark; *Sefik Suzer*, Bilkent University, Turkey; *John Watts*, University of Surrey, UK

Because of the importance of surfaces and interfaces in many scientific and technological areas, the use of XPS in publications has been growing exponentially. Although XPS is being used to obtain useful information about the surface composition of samples, much more information about materials and their properties can be extracted from XPS data than commonly obtained. This presentation describes some of the areas where alternative analysis methods or experimental design can obtain information about the near surface region of a sample, often information not available in other ways. Experienced XPS analysts are familiar with many of these methods, but they may not be known to new or casual XPS users and sometimes they have not been used because of an inappropriately assumed complexity. Information available includes, optical, electronic, and electrical properties, nanostructure, expanded chemical information and enhanced analysis biological materials and solid/liquid interfaces. Many of these analyses can be conducted on standard laboratory XPS systems, with either no or relatively minor system alterations. Topics discussed include i) Considerations beyond the “traditional” uniform surface layer composition calculation to obtain nanostructure of the near surface region, ii) using the Auger parameter to determine a sample property, iii) use of the D parameter to identify sp² and sp³ carbon information, iv) extracting phase and enhanced chemical information from the XPS valence band, v) using cryocooling to examine the solid/liquid interface and expand range of natural and biological samples that can be analyzed and minimize damage, and vi) Using electrical potential effects on XPS signals to extract chemically resolved electrical measurements including band alignment, electrical property information, double layer formation and charge dynamics.

Biomaterial Interfaces

Room 209 F W - Session BI1-MoA

Functional Biomaterials and Sensing

Moderators: *Sapun Parekh*, University of Texas at Austin, *Rong Yang*, Cornell University

1:30pm BI1-MoA-1 Casting Light on Exceptional Biointerfaces, *Joe Baio*, Oregon State University INVITED

Abstract: From cell membranes to sticky frog tongues, the natural world abounds with novel biointerfaces. In this talk, we will explore how these biological materials have inspired the design of new biomedical systems. Specifically, we will examine surface-driven self-assembly of biomaterials that mimic natural processes. The presentation will begin with the development of analytical methods that enable visualization of the structure and organization of biomolecules at interfaces. With these tools in hand, we will then investigate the surface phenomena that govern the intricate system muscle cells use to repair plasma membrane damage. Finally, the discussion will expand to recent experiments uncovering the structures of biomolecules that drive wet adhesive processes in nature.

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2:00pm **BI1-MoA-3 Molecular Modeling of Nucleic Acid-Based Nanomaterials**, *Elizabeth Skelly*, University of North Carolina at Charlotte; *Christina Bayard*, North Carolina State University; *Joel Jarusek*, University of Nebraska; *Benjamin Clark*, North Carolina State University; *Laura Rebollo, Yasmine Radwan, Phong Nguyen, Melanie Andrade-Muñoz*, University of North Carolina at Charlotte; *Thomas Deaton*, North Carolina State University; *Alexander Lushnikov*, University of Nebraska; *Sharonda LeBlanc*, North Carolina State University; *Alexey Krasnoslobodtsev*, University of Nebraska; *Yaroslava Yingling*, North Carolina State University; *Kirill Afonin*, University of North Carolina at Charlotte

DNA and RNA-based nanotechnology offers transformative potential for precision medicine, particularly in drug delivery and therapeutic applications, due to their inherent ability to precisely target and execute molecular functions. Nucleic Acid NanoParticles (NANPs) serve as versatile scaffolds for assembling functional nanomaterials. However, systematic understanding of how NANP design parameters, such as size, shape, sequence, composition, flexibility, and linker strands, govern their physicochemical properties and drive their self-assembly into supramolecular structures remains limited. Here, we employ multi-resolution molecular dynamics simulations, integrating all-atom (AA) and dissipative particle dynamics (DPD), to investigate how these parameters influence NANP structural, mechanical, and self-assembly characteristics. Furthermore, the integration of inorganic nanoparticles (NPs), such as quantum dots (QDs), into nucleic acid systems significantly enhances their functionality. QDs offer exceptional luminescence, photostability, and resistance to photobleaching, making them ideal biological markers. Functionalizing QDs with nucleic acids merges their superior optical properties with therapeutic functionalities. Due to the inherent limitations of experimental characterization techniques (e.g., TEM), we applied DPD simulations to elucidate mechanisms governing the formation and structural dynamics of QD-DNA condensates, providing detailed insights unattainable through experimental approaches alone. These findings advance our fundamental understanding of nucleic acid-based nanomaterials and facilitate their strategic development for next-generation biomedical applications.

2:15pm **BI1-MoA-4 Surface-Immobilized Fibronectin Conformation Drives Synovial Fluid Adsorption and Film Formation**, *Syeda Tajin Ahmed*, University of California Merced, United States Virgin Islands; *Ummay Honey, Lenka Vitkova, Diego Jaramillo Pinto, Katelyn Lunny, Warren Flores, Kaleb Cutter*, University of California Merced; *Yidan Wen, Kevin De France*, Queens University, Canada; *Roberto Andresen Eguiluz*, University of California Merced

The articular cartilage extracellular matrix (ECM) is a complex network of biomolecules that includes fibronectin (FN). FN acts as an extracellular glue, controlling the assembly of other macromolecular constituents to the ECM. However, how FN participates in the binding and retention of synovial fluid components, the natural lubricant of articulated joints, to form a wear-protecting and lubricating film has not been established. This study reports on the role of FN and its molecular conformation in mediating macromolecular assembly of synovial fluid ad-layers. FN films as precursor films on functionalized surfaces, a model of FN's articular cartilage surface, adsorbed and retained different amounts of synovial fluid (SF). FN conformational changes were induced by depositing FN at pH 7 (extended state) or at pH 4 (unfolded state) on self-assembled monolayers on gold-coated quartz crystals, followed by adsorption of diluted SF (25%) onto FN precursor films. Mass density, thin film compliance, surface morphologies, and adsorbed FN films' secondary and tertiary structures reveal pH-induced differences. FN films deposited at pH 4 were thicker, more rigid, showed a more homogeneous morphology, and had altered α -helix and β -sheet content, compared to FN films deposited at pH 7. FN precursor films deposited at pH 7 adsorbed and retained more synovial fluid than those at pH 4, revealing the importance of FN conformation at the articular cartilage surface to bind and maintain a thin lubricating and wear protective layer of synovial fluid constituents. This knowledge will enable a better understanding of the molecular regulation of articular cartilage-SF interface homeostasis and joint pathophysiology and identify molecular interactions and synergies between the articular cartilage ECM and SF to reveal the complexity of joint biotribology.

2:30pm **BI1-MoA-5 Growable Mycelial Coatings: A New Approach to Bio-Based Plastic Replacements**, *Sandro Zier, Liza White, Caitlin Howell*, University of Maine

Sustainable and compostable plastic replacements are in growing demand as we learn more about the health and environmental hazards associated with single-use plastic packaging. However, many biomaterials readily

absorb water, making them unsuitable as plastic replacements, while hydrophobic bio-derived plastic alternatives can be expensive to produce. Here, we present an alternative: large-scale coating of a fungal mycelium mixture which grows exponentially over the course of three days to create a densely packed functional surface barrier. The resulting surface is highly hydrophobic ($CA > 130^\circ$) and absorbs water to the same degree as the current accepted standard for shipping materials (water uptake $< 30 \text{ g/m}^2$ after 120s). The grown coating also shows extremely high oil resistance and can withstand bending and folding. These findings highlight a promising path toward affordable, compostable, and high-performance biomaterials that address the pressing need for sustainable plastic alternatives while maintaining functionality for real-world applications.

2:45pm **BI1-MoA-6 Nanoparticle biosensing in 3D Cell culture**, *Miriam Kael, Paul Stoddart*, Swinburne University of Technology, Australia; *Sally McArthur*¹, Deakin University, Australia

While only a limited number of assays are tailored for 3D, and some are influenced by matrix proteins like collagen, nanoparticle-based biosensors present a valuable opportunity to analyse 3D *in vitro* cultures. Investigating how the sensor influences the model during *in situ* measurements is crucial, as is understanding how the model could interfere with the sensor's design. Certain sensors that exhibit potential in 2D may not be applicable in 3D environments. Although gold nanoparticles offer benefits, their detection in a 3D context is limited by traditional darkfield techniques. On the other hand, fluorescent nanodiamonds demonstrate significant potential as probes for 3D cultures.

3:00pm **BI1-MoA-7 Peptide-Polymer Mixtures Form Tunable Biomolecular Condensate Materials**, *Tino Zhang, Sapun Parekh*, University of Texas at Austin

Liquid-liquid phase separation (LLPS) is increasingly recognized as a promising strategy for designing dynamic and functional materials for catalysis, drug delivery, and synthetic biology. Despite growing interest, the physical and chemical properties of LLPS-based materials remain poorly characterized, limiting their rational design and broader utility. Here, we introduce a minimal, peptide-based bi-component biomolecular condensate (BCs) system that offers a modular platform to construct and interrogate LLPS materials with tunable properties. We generated a library of biomolecular condensates by pairing short, rationally designed peptides with biopolymers such as nucleic acids and proteins. Systematically characterizing their internal environments using Raman microscopy, fluorescence recovery after photobleaching (FRAP), and fluorescence lifetime imaging, our results reveal that peptide sequence and stoichiometry govern critical material features such as viscosity, molecular partitioning, and local chemical structures. These results show that the understanding of LLPS material properties are complex and establish a framework for programming condensates with defined functionalities, highlighting the tunability of the chemical environment in condensates. Looking ahead, we envision applying these designer condensates as responsive microreactors or environment-responding materials, where properties can be modulated via peptide-level design.

Biomaterial Interfaces

Room 209 F W - Session BI2-MoA

Microbes and Biofilms

Moderators: *Joe Baio*, Oregon State University, *Caitlin Howell*, University of Maine

4:00pm **BI2-MoA-11 Influence of Copper on the Establishment of Marine Biofilms**, *Sara Tuck, Kenan Fears*, U.S. Naval Research Laboratory

Biofouling, the accumulation of unwanted organisms on submerged assets, is an ongoing challenge within the maritime industry and has additional repercussions on human health. Biofouling build-up increases fuel consumption, asset drag, and operational costs in addition to facilitating the transfer of environmental and pathogenic bacteria from one location to another. Conventional methods to inhibit biofouling includes the application of antifouling coatings, the most popular of which are copper based. In biological systems, copper is tightly regulated and, in an attempt to exploit this, some antifouling coatings contain up to 75% copper (I) oxide by weight. Despite these high loadings, the efficacy of these coatings is rapidly declining with the emergence and spread of copper tolerant species. Microbial communities resistant to copper have been found to

¹ JVST Highlighted Talk

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form mature biofilms on these coatings, which could be altering the interfacial properties to create more favorable conditions for the settlement of a broader biofouling community. To gain an understanding of the mechanisms responsible for the loss of antifouling performance, coated and uncoated polyvinyl chloride panels were deployed at field sites to harvest early biofilms. From these collections, we isolated, cultured, and identified bacterial species. Copper tolerance profiles were developed by re-exposing individual colonies to copper sulfate in broth microdilution assays. We also investigated copper biocide release from copper-ablative coated glass coverslips over a short time frame to better understand the copper environment that is susceptible to primary colonization.

4:15pm BI2-MoA-12 Biofouling Prevention by Constant and Alternating Potentials, *Jana Schwarze, Emily Manderfeld, Axel Rosenhahn*, Ruhr University Bochum, Germany

The application of electrochemical potentials to surfaces is an easy and direct way to alter surface charge density, the structure of the electrochemical double layer, and the presence of electrochemically activated species. We investigated how applied potentials affect the colonization of surfaces by microorganisms. Different constant potentials as well as the regular alternation between two potentials were investigated, and their influence on the attachment of the biofilm-forming microorganisms on gold-coated working electrodes and laser induced graphene was quantified in laboratory and in field experiments. In order to be able to study the attachment under dynamic conditions, different electrochemical approaches have been developed to merge dynamic assay conditions e.g. microfluidics or rotating disks with potential control by potentiostats. In addition to the effect of the applied potentials on fouling, the electrochemical processes on the working electrode were analyzed by cyclic voltammetry and correlated with chemical analysis that provided insight into the reactive oxygen species formed. The electrochemical processes that occur on the surface will be discussed in view of the observed antifouling behavior and discussed regarding the protection of structures and ships in contact with seawater and technological applications such as desalination by reverse osmosis.

4:30pm BI2-MoA-13 NO-Releasing Hybrid Material Coatings with Low Fouling Properties Against Pathogenic Bacteria, *Luciana Natascha Herbeck, Samantha Muhring-Salamone, Regina Kopecz, Axel Rosenhahn*, Ruhr-University Bochum, Germany

One serious, global issue facing human mankind is the uncontrolled accumulation and growth of organisms and organic matter onto man-made surfaces, known as biofouling.^[1] Negative outcomes attributed to freshwater biofouling comprise clogging or corrosion, the spread of pathogenic bacteria in water distribution or food processing systems, and is the root of medicinal infections.^[2-6] As the trend in coating design is moving towards sustainable and bio-friendly approaches, one strategy is to mimic nature's concepts in counteracting biofouling, e.g. by using secondary messenger molecules such as nitric oxide, which has been found to disperse biofilms and to exhibit antimicrobial effects.^[7] This property has already been utilized in research on catheters and wound healing patches.^[8,9] In this work, the secondary messenger molecule nitric oxide was integrated into a sustainable coating matrix consisting of the naturally occurring polysaccharide alginate, tetraethyl orthosilicate and an aminosilane capable to serve as an NO-acceptor/donor group. Two different nitrogen oxide species were formed in the coating after NO binding at elevated pressures and the ratio of the two species depended on the ratio of the two silane compounds. The NO-binding and release was characterized by UV-Vis spectroscopy and Griess-assays. Antifouling properties of the coatings against the freshwater bacteria *Bacillus subtilis*, *Pseudomonas fluorescens* and *Escherichia coli* were verified in dynamic attachment assays, revealing a significant reduction for NO-releasing samples compared to coatings without NO-release.

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4:45pm BI2-MoA-14 Effect of Salts on the Aggregation and Strength of Protein-Based Underwater Adhesives, *Zachary Lamberty, Chloe Skogg, US Naval Academy; Michael Wilson, Purdue University; Maryssa Beasley, Naval Research Laboratory; Abdon Vivas Tejada, Amarachi Peters, Elizabeth Yates, US Naval Academy; Christopher So*, Naval Research Laboratory

While hydrophobic underwater adhesives have often been desired for their ability to remove water from interfaces, their inherent immiscibility with water can also hinder their use. Water-based adhesive systems can lead to improved wetting, lower toxicity, and exhibit dynamic physical responses to aqueous chemistries in the environment. For protein-based adhesives, simple aqueous salts can dramatically alter the driving intra- and intermolecular forces among proteins and with surfaces. Here we investigate the effect of four main salts found in seawater, NaCl, KCl, MgCl₂, and CaCl₂ on underwater adhesives made from two agricultural byproduct proteins, bovine serum albumin (BSA) and bovine α -Lactalbumin (α La). We demonstrate that salts can significantly impact the adhesive strength of protein-based adhesives, increasing strength at moderate salt concentrations but decreasing at higher concentrations. Calorimetry and rheology experiments show that a high salt condition hastens gelation time to form weaker materials with lower adhesion, while moderate salt conditions slow protein aggregation to produce stiffer materials with higher bond strength. In general, salts that stabilized native protein structures formed stiffer gel networks but tended to decrease adhesive strength compared to salts with destabilizing effects. When combining simple salts and protein-based adhesives, we demonstrate control over nearly all attributes of adhesive curing and strength as an effective means to improve underwater adhesion.

CHIPS Act : Semiconductor Manufacturing Science and Technologies

Room 207 A W - Session CPS+MS-MoA

Semiconductor Manufacturing Workforce Development

Moderators: Erica Douglas, Sandia National Laboratories, Timothy Gessert, Gessert Consulting

1:30pm CPS+MS-MoA-1 Workforce Development in the Semiconductor Industry: A New National Approach, *Michelle Williams, Mike Glavin¹*, SEMI Foundation

INVITED

To fulfill its promise to grow to \$1 trillion as soon as 2030, the semiconductor industry will need an estimated 1 million new workers. Addressing this challenge will take a whole-of-industry, nationalized approach bolstered by significant federal and state investments. It will also require a fundamental rethinking of employer approaches to attracting, recruiting, and retaining a far broader workforce that represents the widest possible range of perspectives, backgrounds, and ideas so the industry can continue to innovate, problem solve, and thrive.

The SEMI Foundation is the workforce development arm of SEMI, the global industry association representing the microelectronics manufacturing and design supply chain with more than 3000 members worldwide. We know that accomplishing this work requires three strategies: we must illuminate and demystify the semiconductor industry for students and jobseekers; we must provide clear educational pathways into the industry; and we must provide access to hands-on training to prepare the workforce.

This keynote address will illuminate a new national approach on how to employ these strategies and weave them together to help galvanize a new generation of workers and create economic opportunity in communities proximate to semiconductor companies across the nation. Attendees will walk away with concrete and timely opportunities for their companies to engage in workforce development networks and activities to bolster their own success.

2:15pm CPS+MS-MoA-4 Bridging the Talent Gap: Advancing Workforce Development for the Manufacturing and Semiconductor Industries, *Sue Smith*, Smart Automation Certification Alliance

The rapid advancement of technology and growing global demand for semiconductor components have placed unprecedented pressure on the U.S. manufacturing sector to expand and innovate. The landscape of geopolitics along with supply chain challenges have added to the mounting pressure. However, a widening skills gap combined with a shortage of an estimated 1.9 million manufacturing workers is most threatening to the

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industry's ability to meet this demand. This presentation addresses the urgent need for robust, scalable workforce development strategies tailored specifically to manufacturing and semiconductor manufacturing. Drawing on industry input, standards, and credential development, we will explore how partnerships among industry, government, and educational institutions can catalyze talent pipelines. The session will highlight successful case studies, outline key competencies for next-generation workers, and propose an ecosystem-based approach to building a resilient, diverse, and future-ready workforce. Attendees will gain actionable insights into curriculum innovations and collaborative models that can drive sustainable growth in one of the nation's most critical sectors.

The Smart Automation Certification Alliance (SACA) collaborates with partner companies in the manufacturing sector to develop credentials in Industry 4.0 and emerging technologies based on international standards supporting the attainment of certifications and demonstrated competencies. These credentials are being used by employers, secondary and post-secondary education, and training providers in developing the workforce for current and future skills needed in the workplace.

To effectively bridge the talent gap in the manufacturing workforce, particularly in emerging technologies like semiconductors, credentials will play a key role in an ecosystem-based approach. There are industry, government, and education partnerships having success in workforce development with SACA and other industry recognized credentials. More innovation and participation in collaborative models will drive sustainable solutions to addressing the skills gaps and meeting the demands for the growth in semiconductor production and advanced manufacturing. Development of standards by and for industry assures the appropriate skills and knowledge are identified and the attainment of aligned credentials develops the talent needed.

2:30pm CPS+MS-MoA-5 Partnership of Research University and Technical College for Microelectronics and Nanomanufacturing Workforce Development, Seung-Joon Paik, Yu "Michelle" Wu, Georgia Institute of Technology; Jameel Hasan, Georgia Piedmont Technical College

A partnership has been established between the Georgia Institute of Technology, a research university with advanced nanomanufacturing facilities, and Georgia Piedmont Technical College, a technical college with regional professional education capabilities, aiming to address the nationwide demand for a workforce to build a talent pipeline for the semiconductor industry. Through this partnership, military veterans and their relatives are trained in a microelectronics and nanomanufacturing certificate program. The certificate program has achieved a completion rate of over 85% through 600+ hands-on lab hours using 20+ different pieces of equipment since 2022.

The U.S. semiconductor industry is projected to face a shortage of 53,200 engineers and technicians by 2030 due to the evolving demands of the industry according to The Semiconductor Industry Association. While many workforce development efforts are being invested to build education and training ecosystem, there are obstacles to overcome to accommodate workforce into the industry. Semiconductor fabrication or Nanomanufacturing facility has unique environments and requirements such as enclosed cleanrooms with stringent temperature, humidity and vibration, and head-to-toe covering cleanroom suit. Hands-on practices and proper training are crucial for enriching learning experiences and effectively applying job skills.

The Institute for Matter and Systems (IMS) at Georgia Institute of Technology is equipped with state-of-the-art nanofabrication machines and tools in a 28,500-square-foot space. Through the core facilities of cleanroom and material characterization, IMS offers hands-on training in lab safety, nanomanufacturing, and characterization to users. The capabilities include photolithography, thin film deposition, etch, and metrology, which are widely used techniques in high-tech nanomanufacturing industries and research facilities. Georgia Piedmont Technical College works as a hub of training opportunities for regional workforces in advanced manufacturing industries. The college engages military veterans in training programs for high-demand industries and implements education curricula and teaching methodologies in microelectronics and nanomanufacturing.

This presentation highlights a strategic partnership effort for workforce development in microelectronics and nanomanufacturing focused on veterans. Formation of partnership, modifications of curriculum, and hands-on experiences enriching students learning experience will be discussed. Key components involve successful approaches, lessons learned, and future access expansion.

2:45pm CPS+MS-MoA-6 an Accelerated Bachelor's Degree in Semiconductor Materials and Devices, Susan Farhat, Department of Chemical Engineering, Kettering University; Ronald Kumon, Daniel Ludwigsen, Uma Ramabadran, Cornel Rablau, Ronald Tackett, Demet Usanmaz, Lihua Wang, Department of Natural Sciences, Kettering University

Kettering University, a STEM-focused private university in Michigan, is gearing up to launch an Accelerated Bachelor of Science degree in Semiconductor Materials and Devices that is designed to address one of the major hurdles in bringing semiconductor manufacturing back to the United States: a shortage of skilled workers. With the current strain on the global supply chain, and the CHIPS and Science Act injecting billions of dollars into bringing semiconductor manufacturing back to the US, the demand for highly-skilled professionals with semiconductor-industry-relevant training is skyrocketing. Funding for the development of this program has been obtained through a Strategic Investment Grant from the Michigan Economic Development Corporation (MEDC) intended to bolster Michigan's technological workforce. Kettering University has also become one of the participating schools under the MEDC-supported Michigander Scholars program to bolster workforce preparation in Michigan's high-tech sectors. The skill set required for a career in the semiconductor industry is inherently interdisciplinary, and this degree program reflects this, as it has elements from physics, chemistry, and engineering. In this talk, we will present the motivation behind this degree, the plan of study itself, and the reasoning behind why it was constructed in the manner in which it was.

3:00pm CPS+MS-MoA-7 Building a Regional Education and Workforce Development Infrastructure for Semiconductor Manufacturing, Robert Geer, NY CREATES

INVITED

The large-scale federal investments aimed at reasserting U.S. leadership in the global semiconductor industry has created an urgent need for a skilled IC design and manufacturing workforce. However, a significant talent gap threatens these goals. Addressing this need requires a comprehensive approach, currently underway, to build the education and workforce development infrastructure to support the semiconductor industry.

The Semiconductor Industry Association estimates that the industry will need to add more than 100,000 jobs in the U.S. to support planned or announced projects. Revitalizing the semiconductor talent pipeline requires a holistic approach. Nearly half the chip fab workforce will enter the industry with a high school diploma, 2-yr degree or non-credentialed training (e.g. military service). The remainder will be dominated by B.S./M.S./Ph.D. engineers, computer science, and research/development professionals. Addressing the challenges of preparing such a broad talent pool requires a combined national/regional strategy to address overall career awareness and engagement, modernization of training and education programming to address key skill and knowledge gaps, and targeted initiatives to reduce the 'time-to-productivity' for new hires.

A case study of this 'national/regional' strategy will be presented focusing on the new chip fabs under construction in the northeast U.S which will require tens of thousands of highly trained technicians, engineers, and data professionals over the next decade. The coordination of national initiatives (including the new National Semiconductor Technology Center in Albany, NY, regional DoD Microelectronics Commons Hubs in the northeast U.S. and Manufacturing U.S.A. institute investments) with regional (state-wide) efforts with in-depth analysis of competency profiles for semiconductor manufacturing will be reviewed in terms of maturing the region's workforce and educational ecosystem to support chip-fab expansion. Key components involve broadening the requisite competency base across the higher education network through industry-aligned curriculum modernization, expanded access to experiential learning in leading edge facilities, expanded adoption of 'learn and earn' opportunities and coordination with national awareness campaigns. Central to this strategy is the role played by industry organizations and regional development nonprofits as a 'connective tissue' to support the overall talent pipeline.

3:30pm CPS+MS-MoA-9 Workforce Development Opportunities in a University Nanofabrication Core Facility, Megan Dernberger, Benjamin Schmidt, Christina McGahan, Sarah Ross, Sharon Weiss, Vanderbilt University

In Vanderbilt Institute of Nanoscale Science and Engineering (VINSE) at Vanderbilt University, several programs are successfully implemented to engage students, postdocs, and external users of VINSE in workforce development. Programs include workshops, an Industrial Affiliates Program (IAP), and part-time student employment. These programs are mutually beneficial to staff and users, reducing the time burden for full-time staff

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while also promoting users' technical, teaching, and leadership skills. This talk highlights lessons learned with the development of these programs.

The VINSE IAP fosters collaborative relations with industry leaders. This program allows students and faculty direct access to industry contacts for recruitment, job opportunities, and networking events. The industry members can sponsor workshops with technical trainings, interactive Q&A sessions, and content tailored to the userbase. Utilizing connections with VINSE alumni and a modest entry fee to create a low barrier to entry resulted in over 15 IAP members in the first year.

Additionally, VINSE offers staff-led short courses to the internal and external community. The one- or two-day events provide a hands-on introduction into topics and technical skills for users. Topics include microfluidic device fabrication, semiconductor device fabrication, electron microscopy, and atomic force microscopy.

Undergraduate and graduate students can be directly involved in VINSE for months to years through the VINSE Undergraduate Tech Crew and SuperUser programs respectively. Tech Crew undergraduates, ~14, assist staff with cleanroom upkeep and process development. They specialize in various tools and processes, gaining hands-on experience and exposure to a wide range of nanoscience applications. Students can join Tech Crew during an intensive 10-week summer program or the academic year. A three-level tiering system acknowledges skill and leadership development with promotions in title, pay, and responsibilities. Graduate student SuperUsers, ~5, are selected based on technical and interpersonal skills and assist with highly-used cleanroom equipment. They provide initial tool training to users and initial troubleshooting of tool issues on a subset of tools, building teaching experience and deeper tool knowledge. As an incentive, SuperUsers have increased access to VINSE staff, extra training on selected tools, and a professional development stipend.

These workforce development programs are highly successful for fostering interdisciplinary relations, increasing technical skills, and enhancing the nanoscience research community at Vanderbilt.

4:00pm CPS+MS-MoA-11 Challenges of Infusing Vacuum Technology into Two-Year Technology Programs, Elena Brewer, Erie Community College
With the recent revival of semiconductor manufacturing in the United States, the industry is challenged with the lack of a qualified technical workforce to meet the rapidly growing demand for technicians. Vacuum technology has a special place of being an enabling technology for the semiconductor industry and other industry segments. Thus, the availability of technicians prepared to work with and troubleshoot vacuum-based systems is essential for the semiconductor industry. This presentation will address the challenges encountered by SUNY Erie Community College and Normandale Community College, and present corresponding solutions to overcome these challenges. The main three challenges in teaching vacuum technology at the community college level are: lack of institutional expertise, lack of available training equipment, and lack of technician-level educational resources in vacuum technology. SUNY Erie has been tackling these challenges since 2014 when ECC's Nanotechnology AAS program was first introduced. Since then, vacuum technology has been infused into the Electrical Engineering Technology AAS program, and a standalone Vacuum Technology micro-credential was developed. Normandale Community College has been working on providing educational solutions in Vacuum Technologies even longer and offers vacuum technology training at various levels using different modes of course delivery, including interactive remote-access vacuum instruction. This presentation will highlight the educational resources developed over multiple NSF ATE grant projects that are available for community college and technical college faculty, such as: an eBook in Vacuum Technology; laboratory manual and instructor's guide to support experiential learning in Vacuum Technology; rough and high vacuum technology training equipment; and current and future professional development opportunities for community college and technical program faculty.

4:15pm CPS+MS-MoA-12 Review of AVS Educational Outreach Activities in the Context of the Chips in Science Act and its Related Workforce-Development Needs, Tim Gessert, Gessert Consulting LLC

The AVS has provided various types of education opportunities to its members and others since the mid 1960's. One important component of these activities has been public and private short courses on topics consistent with the needs of various high-technology sectors. Indeed, for many technologists, engineers, and scientists now working in these high-tech industries, their initial exposure to areas such as basic vacuum technology, vacuum-process development, and characterization, often began with an AVS Short Course. In the mid 1980's, AVS education outreach

expanded to include training high-school teachers through the AVS *Science Educators Workshop* (SEW). Through this activity, many hundreds of high-school teachers throughout the U.S. have received not only basic vacuum training, but also a working vacuum system designed for the needs of a high-school classroom. In addition to the SEW helping these teachers convey the extensive uses of vacuum processes in many industries, another goal of the SEW has always been to help "spark" student interest in considering post-secondary education (i.e., college), and possibly even toward an STEM career involving vacuum technology. Recently, and encouraged by the realities of COVID, many AVS education outreach activities now also include the option for virtual training, including virtual short courses, webinars, and You-Tube videos that can often align better with changing workplace and workforce needs. Additionally, in partnership with the American Institute of Physics (AIP), the AVS is now actively exploring how to better provide this type of education outreach to communities that have been historically underrepresented in the high-technology sectors.

In this presentation, the past ~60 years of AVS experience with educational outreach will be briefly reviewed, emphasizing how these ongoing activities and experiences might be leveraged to benefit the workforce development needs of the Chips in Science Act. It will also be discussed how, while the workforce of the future US Semiconductor Workforce will certainly require many skilled individuals with advanced academic degrees, this future workforce will continue to require many individuals with hands-on technology skills in areas such as process development/optimization and equipment operation/maintenance. Because of the long-term AVS experience with training involving all these different workforce sectors, it is believed that much of the established AVS education outreach activities can significantly benefit the activities related to the Chips in Science Act.

Nanoscale Science and Technology

Room 206 A W - Session NS-MoA

Light-Matter Interactions at the Nanoscale

Moderators: Nikolai Klimov, National Institute of Standards and Technology, Sesha Challa, NIST-Gaithersburg

2:00pm NS-MoA-3 Towards the Development of Robust Chip-Scale Photonic Thermometers, Sesha Challa, Michal Chojnacky, Kevin Douglass, Thinh Bui, Daniel Barker, Nikolai Klimov, NIST-Gaithersburg

Accurate, high-precision temperature metrology is critical for industries, defense, and healthcare. Temperature also is ranked as the second most measured physical property, following time and frequency, underscoring its role in both applied and fundamental sciences. Resistance-based temperature sensors such as standard platinum resistance thermometers (SPRTs), are the benchmark for conventional temperature metrology due to their high accuracy and widespread acceptance. However, their performance is hindered by sensitivity to environmental conditions and mechanical stress. These inherent limitations, coupled with the critical need to reduce dependence on the calibration chain, have spurred significant interest in developing alternative technologies such as photonic thermometry.

At the National Institute of Standards and Technology (NIST), we are developing an integrated photonic-based temperature sensing platform that can bypass the limitations of SPRTs and transform the way temperature is realized and disseminated. Photonic-based sensors also offer the potential to eliminate costly and disruptive recalibration processes. At the core of this sensing platform is an ultra-sensitive photonic thermometer (SPoT). It consists of an on-chip integrated silicon nanophotonic resonator. The device's optical resonance frequency shifts with temperature, enabled by the high thermo-optic coefficient of single-crystal silicon. This allows precise tracking of temperature variations with exceptional sensitivity. The performance of the SPoT device is critically influenced not only by the sensor design but also by key factors in photonic packaging, which together determine its overall sensitivity, stability, and reliability. Reproducibility in sensor performance is often compromised by fabrication variability, especially in shared nanofabrication facilities.

In this work, we address fabrication-induced variability by investigating sensor designs that are inherently tolerant to process deviations. Our study focuses on photonic crystal cavities, ring resonators, and tapered-width resonators, all fabricated under identical conditions. These structures are implemented on a commercially available 220 nm silicon-on-insulator

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platform to evaluate their robustness and suitability for reliable, reproducible photonic thermometry.

2:15pm NS-MoA-4 Spot On: Precision Photonic Thermometry System with Packaged Sensor and Modular Readout Architecture, Michal Chojnacky, National Institute of Standards and Technology (NIST)/ University of Maryland, College Park; CH. S. S. Pavan Kumar, Kevin Douglass, Thinh Bui, Nikolai Klimov, National Institute of Standards and Technology (NIST)

Photonic temperature sensors have attracted significant interest as alternatives to resistance thermometers due to their high-temperature sensitivity, robustness to electrical interference and mechanical shock, small form factor, manufacturing scalability, and compatibility with CMOS fabrication processes. Different types of sensing elements, including photonic crystal cavities, fiber Bragg gratings, and microresonators have been demonstrated, along with strategies for device packaging and characterization. Each of these photonic temperature sensors relies on a temperature-dependent shift in the device's optical resonance frequency due to a combination of thermo-optic and thermal expansion effects, which can deliver sensitivities of 10s of pm/K and resolve sub-mK level temperature changes. However, implementing these technologies in a practical thermometry platform capable of providing stable, reliable, and repeatable temperature measurements remains a challenge. In this work, we describe the development of a chip-scale, silicon microresonator-based photonic thermometer, with the goal of delivering a packaged, functional, field-deployable thermometer and the supporting photonic readout to enable its use in both calibration laboratories and demanding field environments.

The Sensitive Photonic Thermometer (SPoT) described in this presentation is based on a silicon microring resonator integrated in a photonic chip. The device is fiber-bonded and packaged in a capsule format suitable for performance testing in International Temperature Scale of 1990-defining fixed point cells and thermometric baths. We present the metrological characterization of SPoT and benchmark its performance against the state-of-the-art Standard Platinum Resistance Thermometer (SPRT). We provide an overview of different device interrogation architectures that can be used for deployable and cost-effective photonic readout of SPoT. We also outline further steps for achieving a metrology-grade SPoT platform with an absolute frequency axis suitable for replacing SPRTs in calibration laboratories.

2:30pm NS-MoA-5 Development of New Chip-Scale Photonic AC-DC Thermal Transfer Standard, Sesha Challa, Michal Chojnacky, Kevin O. Douglass, Daniel S. Barker, NIST; Stefan Cular, Howard Community College, Columbia, MD; Nikolai Klimov, NIST

One of the state-of-the-art ac-dc thermal transfer standards, such as Multijunction Thermal Converter (MJTC), relies on comparing the Joule resistive heating of an unknown ac signal to a known dc signal. The resistive temperature sensor, a thermocouple array, detects the heat generated by an electrical signal applied to the heater. Despite being accurate, MJTC reached its fundamental limitations. MJTC suffers from frequency-dependent heater impedance due to capacitive coupling between the ac current flowing through the resistive heater and the thermocouple array. Furthermore, the precision of ac-dc difference cannot be increased much further by increasing the size of the thermocouple array. To address these limitations and to reduce the ad-dc difference calibration chain, we are developing an alternative, photonics-based technology to perform ac-dc difference measurements. Our new chip-scale Photonic Thermal Transfer Standard (PTTS) device is designed to match or exceed the metrological performance of conventional thermal transfer standards, overcome the current technological barriers, and reduce the ac-dc difference calibration chain. The PTTS device, similar to the MJTC standard, detects local temperature changes from Joule heating induced by ac/dc electrical currents. However, in contrast to MJTC, the temperature sensing element in PTTS is photonics-based. Waveguide-integrated microscale photonic thermometer not only has ultra-high resolution and precision but is also immune to RF interference and does not have a capacitive coupling with the resistive heater. In this work, we demonstrate the first prototype chip-scale photonic device to perform ac-dc difference. The device exhibits a larch ac response above 100 kHz, typical of conventional MJTCs due to fixture constraints (cables, wire bonding, leads). The following generation of PTTS chips will address these limitations. At the end of the presentation, we will outline the future directions toward the development of the new photonics-based thermal transfer standard.

2:45pm NS-MoA-6 Deterministic Design of Pseudo-Randomly Distributed Nanostructures for Antireflectivity in the MWIR, Samir Paudel, Menelaos K. Poutous, University of North Carolina at Charlotte

Binary-phase subwavelength gratings (SWG) can perform as antireflective structures. Fabricating SWG for applications in the mid-wave infrared (MWIR, 3-5 μ m wavelength) can be challenging due to a substrate's optical index and hardness. For high index contrast, antireflective SWG are required to have a depth which can be of the order of a wavelength [1]. The SWG fill-factor can be numerically optimized to improve antireflective efficiency, without any conceptual insight into the SWG profile. Recent experimental results show that pseudo-randomly distributed nanostructures (PRnS) can enhance optical transmission through dielectric windows as well [2,3]. In contrast to optimization by numerical iteration techniques, we have utilized deterministic principles to design PRnS with a priori minimum-feature dimensions, and specific selection rules for off-axis transmitted intensity scatter profiles. To enhance antireflectivity, we used more than one binary phase transition within the periodic basis cell, to control the effective index value and off-axis scatter profile. We selected linear, low and high scatter PRnS patterns, with a universal critical feature size of 400 nm, to achieve optical surface transmission enhancement above Fresnel limits within the MWIR bandwidth. To ease fabrication requirements, the designs were restricted to a binary phase-depth close to $\pi/2$, and unit cell periodic dimensions between 0.8 μ m and 4 μ m. The PRnS patterns were fabricated using direct two-photon laser-writing in a negative-tone polymer film on a sapphire substrate. To verify fabrication fidelity and tolerance, the PRnS patterns were characterized using a contactless UV-laser confocal microscope. Unpolarized spectral transmission was measured at normal angle of incident using a spectrophotometer in the 2 – 5 μ m wavelength band. The measured unpolarized spectral transmission indicates that, with the same critical feature size, wide off axis scatter PRnS patterns exhibit superior antireflectivity performance compared to narrow off-axis scatter PRnS patterns. The experimental results were in good agreement with numerical rigorous coupled-wave analysis simulation predictions.

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- 2) S. Paudel, P. Gadamsetti, and M. K. Poutous "Design and fabrication of deterministic, pseudo-randomly distributed, binary phase nanostructures for reflectivity suppression", Proc. SPIE 12898 (2024).
- 3) S. Paudel and M. K. Poutous "Wide angle-of-incidence reflectivity suppression in the NIR by pseudo-randomly distributed binary phase nanostructures", Proc. SPIE 13362 (2025).

3:00pm NS-MoA-7 Plasmonic Behavior in Boron-Doped Diamond Arising from Low Energy, Intervalance Band Electronic Excitations, Souvik Bhattacharya, R. Mohan Sankaran, University of Illinois at Urbana Champaign

Diamond is well-known for its extraordinary mechanical, thermal, and optical properties. The introduction of impurity dopants can further tune and transform diamond. For example, boron, a p-type dopant, has been used to enhance electronic conductivity¹ and produce superconductivity². In recent years, a whole host of other impurity atoms in combination with vacancies have been found to create color centers with unique spin properties that have potential for quantum technologies.³

In this talk, we will discuss our recent discovery of low energy (<0.5 eV) plasmonic excitations emerging from the valence subbands as a result of boron doping of diamond.⁴ Our study was made possible by recent advancements in characterization techniques including scanning transmission electron microscopy-valence electron energy loss spectroscopy (STEM-VEELS) and near-field infrared (IR) spectroscopy. Applying these techniques to boron-doped diamond, we obtain complementary information about the material response in terms of the energy loss and absorption. A theoretical treatment based on first-principles calculations is then carried out to elucidate the fundamental band origin of the response. We show that boron doping leads to emptying of valence subbands, opening up intervalence band (IVB) transitions. Further analysis of the real dielectric component of the calculated response function reveals a resonance and zero-crossing that blue shifts with increasing carrier density, indicating the emergence of metallicity and plasmonic behavior. This mechanism is notably distinct from the collective Drude-like intraband excitations that are reported in traditional metals and other doped semiconductors. The possibility of plasmonic properties in diamond is yet another insight into this remarkable material that could be

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combined to for example, enhance the fluorescence of color centers for quantum sensing applications.

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3:15pm NS-MoA-8 Two-Layer Dual-Mode Reflective-Transmissive Polarization Converter by Stereometamaterials, *Sanchita Sarker, Mohammad Parvinnezhad Hokmabadi*, University of North Carolina at Charlotte

The ability to control light polarization is vital for applications in imaging, communications, metrology, among others. This work reports a systematic approach using supercells of periodic metamaterials to achieve enhanced polarization control. The use of supercells, with identical resonators, provides enhanced parameter flexibility, enabling facile control over the phase and polarization of scattered beams through rotation, flipping, and shifting of the resonators. In particular, we show that by changing the symmetry of the structure from reflection to inversion in a subwavelength two-layer supercell, a transmissive polarization conversion device can be transformed into a reflective counterpart, both with near-unity polarization conversion ratios. This systematic use of supercells highlights their potential for advanced polarization manipulation in electromagnetic and optical devices.

3:30pm NS-MoA-9 Near-Perfect Metamaterial Polarization Rotator for Arbitrary Linear Input States, *Sanchita Sarker, Mohammad Parvinnezhad Hokmabadi*, University of North Carolina at Charlotte

Achieving a compact, reflectionless polarization rotator that converts any input linear polarization into a prescribed linear state with high efficiency over a broad range of incidence angles remains a key challenge. We address this problem by introducing a metamaterial-based rotator composed of two C_4 -symmetric metasurfaces. Each metasurface is formed from split-ring resonators (SRRs), and a controlled in-plane twist between the layers induces the required chirality for polarization rotation. In this device, the C_4 symmetry inherently suppresses cross-polarized reflection, while balanced electric and magnetic responses eliminate co-polarized reflection through destructive interference of the backward wave. Careful tuning of the interlayer coupling between resonators enables near-unity polarization conversion efficiency when ohmic losses are neglected. The device replicates the performance of a crystalline quartz rotator while being insensitive to azimuthal alignment. Unlike natural optical activity, the rotation angle here is fully determined by geometry (e.g., interlayer twist and resonator design), independent of thickness, and can be tailored for any desired wavelength. This approach offers a compact, versatile platform for advanced imaging and polarization-control systems.

4:00pm NS-MoA-11 Direct-Write Ion Patterning of Aluminum Nitride Towards Tuning Integrated Photonics, *Bogdan Dryzhakov, Kyle Kelley*, Oak Ridge National Laboratory

Leveraging focused ion beams, this study spatially patterns point defects into wurtzite aluminum nitride (AlN), achieving defect-driven tunability of ferroelectric, optical, and thermal properties. The robust bonding and strong restoring forces of the AlN lattice help preserve long-range polar order even at ion irradiation doses up to 10^{18} ions/cm², enabling highly localized defects that act as domain nucleation sites for ferroelectric polarization reversal. Notably, ion irradiation induces stable ferroelectricity in nominally piezoelectric AlN and reduces the ferroelectric switching barrier in boron-substituted aluminum nitride (Al_{0.94}B_{0.06}N) by more than 40%. Advanced spectroscopic imaging, including photo- and cathodoluminescence, Raman spectroscopy, and thermal conductance mapping, spatially tracks evolving signatures of defect states and directly correlates them with the emergent ferroelectric functionality and significant (>10x) thermal tunability. Finally, integrating this localized defect engineering of AlN films into quantum photonic integrated circuits enables on-chip tuning of piezoelectric and nonlinear optical coefficients, demonstrating its promise as a practical method for advanced electro-optic and photonic device engineering.

4:15pm NS-MoA-12 Actively Tunable in-Plane Hyperbolicity in Excitonic Single-Walled Carbon Nanotubes, *Jason Lynch, Deep Jariwala*, University of Pennsylvania

Hyperbolicity allows for the confinement of extremely large electric fields on the nanometer scale and the control of the propagation of electromagnetic energy within it. Hyperbolic metamaterials in the visible and near infrared rely on free-carrier effects since plasmonic media were the only ones with strong enough optical responses to host negative permittivities in this energy range. As a result of using plasmonic media, hyperbolic systems lack tunability and emissivity without the implementation of an adjacent active layer. However, narrow, inorganic excitons have recently been shown to exhibit negative permittivities in several different media just above their resonant energies. Therefore, excitons promise to enable hyperbolic media that is intrinsically emissive and highly tunable. Most of these systems require low temperatures (with the exception of chiral-pure single-walled carbon nanotubes (SWCNTs) and hBN-encapsulated, exfoliated WS₂), and they typically lack in-plane optical anisotropy. Here, we study the electro-optical properties of chiral-pure, aligned SWCNTs, and we observe that SWCNTs have a hyperbolic region that is actively tunable using electrostatic doping. We first use the Lorentz oscillator model to provide insights on the requirements for excitons to exhibit negative permittivity, and what would be needed for a true epsilon-near-zero excitons. Using these insights, we find that excitonic SWCNTs must be chiral-pure and high-density to exhibit negative permittivities. Next, micro-Mueller matrix ellipsometry is used to observe actively-tunable, in-plane hyperbolicity in aligned SWCNT films. The hyperbolic window is tuned by 50 meV by injecting $\approx 10^{13}$ carriers/cm². For comparison, the Drude model predicts that the plasmon resonance would be tuned by < 1 meV in ITO at the same transition energy. Therefore, SWCNTs have a 60x improvement in hyperbolic tunability than free-carrier systems when normalized for energy. Additionally, the loss in the SWCNTs at the hyperbolic transition is found to be comparable to TiN showing that it could be implemented in similar hyperbolic systems. When combined with the ability for SWCNTs to be globally-aligned on the wafer-scale, our work demonstrates that SWCNTs has great potential as a hyperbolic medium for both emissive and active photonics.

4:30pm NS-MoA-13 Imaging Photonic Resonances within an All-Dielectric Metasurface via Photoelectron Emission Microscopy, *Andrew Kim¹, Sandia National Laboratories; Chloe Doiron, Sandia National Laboratories, USA; Fernando Vega, Purdue University, USA; Jaeyeon Yu, Alex Boehm, Joseph Klesko, Igal Brener, Raktim Sarma, Alexander Cerjan, Taisuke Ohta, Sandia National Laboratories, USA*

Dielectric nanophotonics aims to achieve precise control of light-matter interactions by confining light within subwavelength structures and manipulating the electromagnetic fields therein. Such precise control is utilized towards technological applications that include imaging, holography, and sensing, among others. Here, we use photoelectron emission microscopy (PEEM) to demonstrate near-field imaging of optical resonances within a dielectric metasurface in the ultraviolet to visible wavelength range. This approach involves far-field photonic excitation akin to the illumination conditions of photonic devices and allows for near-field imaging at a sub-optical wavelength spatial resolution. We analyze the local volumetric field variations within the meta-atoms as a function of excitation wavelength and polarization by comparing photoelectron images to finite-difference time-domain simulations. The metasurface supports two distinct resonances that occupy regions of different material thickness within the metasurface, resulting in a contrast in photoemission intensity due to the inelastic mean free path (IMFP) of the photoelectrons. The simulations replicate the intensity distribution in PEEM images by accounting for this IMFP as the two resonances shift their intensity as wavelength is varied. Through our analysis, we determine the IMFP of very low kinetic energy (<1 eV) photoelectrons to be ≈ 35 nm, which is comparable to the meta-atom height and thus highlights the PEEM sensitivity to resonances within the volume. Overall, these results demonstrate that photoelectron imaging with sub-wavelength resolution is suitable for examining light-matter interactions in volume-type (as opposed to surface) photonic modes within dielectric nanophotonic structures.

This work was supported by the US Department of Energy, Office of Science, Division of Materials Sciences and Engineering (grant BES 20-017574) and by the LDRD program at Sandia National Laboratories. This work was performed in part at the Center for Integrated Nanotechnologies,

¹ JVST Highlighted Talk

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4:45pm **PS-MoA-14 Investigation the Photocatalytic effect of RuO₂ loading on TiO₂ towards Hydrogen Evolution in Visible Light, Moses Ashie, Bishnu Bastakoti, North Carolina A&T State University**

The significant role that fossil fuels have played in energy utilization cannot be underestimated. However, owing to the non-renewable and CO₂ emission associated to its usage has paved a way for a search for a more renewable and environmentally unfriendly energy sources of which hydrogen energy identified as a potential target. A highly porous TiO₂-RuO₂ heterogenous solvothermally engineered photocatalyst revealed how varying synthesis conditions can contribute to the modification of TiO₂ towards effective photocatalytic water splitting in the visible region of the electromagnetic spectrum. Characterization techniques such as XRD, SEM, TEM, UV-Vis DRS, and electrochemical analysis revealed that TiO₂-RuO₂-20 exhibited reduced band gap, improved light absorption capability, lower electron-hole recombination rate, lower solution resistance which collectively contributed to effective photocatalytic activity. In addition, a high surface area and mesoporous nature contributed to 1794.8 mmolg⁻¹h⁻¹ of hydrogen gas. Compared to the pristine RuO₂ (21.9 mmolg⁻¹h⁻¹) and the commercially available TiO₂ (246.4 mmolg⁻¹h⁻¹), the TiO₂-RuO₂-20 sample produced a yield that is almost 81 times and 7 times respectively. This therefore proves the effectiveness of the solvothermal method and the ruthenium dioxide in modulating the photocatalytic properties of TiO₂ photocatalyst for photocatalytic water splitting in visible light.

Plasma Science and Technology

Room 201 ABCD W - Session PS-MoA

Plasma Modelling Focused on CCP

Moderators: Mingmei Wang, Lam Research Corporation, Du Zhang, TEL Technology Center America

1:30pm **PS-MoA-1 Plasma Prize 2024 Award Talk: Some Tales from Our Model Validation Adventures, Shahid Rauf, Han Luo, Peng Tian, Jun-Chieh Wang, Xingyi Shi, Tianhong Wang, Nakul Nuwal, Rupali Sahu, Kallol Bera, Jason Kenney, Applied Materials, Inc.; Manuel Schroeder, Jan Guttmann, Niklas Friedrichs, Ihor Korolov, Julian Schulze, Ruhr-University Bochum, Germany**

INVITED

Plasma modeling has emerged as a crucial tool in the design of plasma equipment within the semiconductor industry. These models are also extensively utilized for exploratory studies and to enhance the understanding of the physics underlying major plasma processing applications. Given the inherent complexity of plasmas, model validation – through testing against experimental measurements – is essential for developing credible models. We report on a multi-year, broad collaboration between our modeling and experimental teams aimed at systematically examining models for capacitively and inductively coupled plasmas. The modeling efforts have employed particle-in-cell (PIC), fluid, and hybrid models, allowing for a comparative analysis of the modeling techniques. Experimental diagnostics have included Langmuir probes, phase-resolved optical emission spectroscopy (PROES), and retarding field ion energy analyzers (RFEA). Ion energy distribution function (IEDF) measurements using the RFEA in argon (Ar) and oxygen (O₂) plasmas highlight the significance of kinetic effects in low-pressure capacitively coupled plasmas (CCP). In low-density CCPs, where the sheath thickness ranges from 5 to 10 mm, collisions distort the IEDF even at pressures as low as 2.5 Pa. Experimentally validated two-dimensional (2D) models demonstrate the impact of plasma non-uniformity on the symmetry of the ion angular distribution function (IADF). PROES and modeling have been employed to investigate multi-frequency CCPs with tailored voltage waveforms for the low-frequency (LF) component. One key finding of this combined modeling-experimental study is the role of the LF in power coupling by the high-frequency (HF) source, which affects both the spatial and temporal characteristics of plasma production. To test 2D plasma models, we have examined radio frequency (RF) hollow cathode discharges (HCD) in Ar and O₂ with several HCD geometries, RF frequencies, and pressures ranging from 5 to 100 Pa. Kinetic effects are significant across the entire pressure

range, underscoring the importance of employing kinetic or hybrid models in simulating CCPs. Our collaborative efforts are now focused on inductively coupled plasmas (ICP), with ongoing tests of models for pulsed ICPs that transition between the E, E/H, and H modes of operation. Preliminary results from ICP diagnostic and modeling work are presented.

2:00pm **PS-MoA-3 Experimental Validation of a Stability Model for Capacitively Coupled Plasmas, Omar Alsaeed, North Carolina State University; Brian Bentz, Sandia National Laboratories; Benjamin Yee, Brett Scheiner, Chenhui Qu, Meenakshi Mamanuru, Lam Research Corporation; Amanda Lietz, North Carolina State University**

Self-organization in radiofrequency plasmas is a commonly occurring phenomenon that can be detrimental to wafer-scale uniformity in semiconductor manufacturing. Recent theoretical work has proposed that thermoelectric electron energy transport within a fluid electron framework drives the onset and growth of these instabilities. A theoretical stability criterion was previously tested experimentally in inductively coupled plasmas and numerically in capacitively coupled plasmas, showing good agreement. However, the underlying driving mechanism remains unverified, with conflicting reports in the literature, and experimental validation efforts have been lacking in capacitively coupled plasmas. This work presents experimental measurements of the unstable mode wave number and growth rates in symmetric planar capacitively coupled plasmas at moderate pressures (0.1–10 Torr) in electropositive chemistries (Ar, He, N₂). Measurements were performed using laser collision-induced fluorescence (LCIF), optical emission spectroscopy (OES), and high-speed imaging. The experimental results are compared against theoretical predictions of stability as a function of gap size, gas pressure, and chemical composition, providing insights into the nature of instability in moderate-pressure radiofrequency plasma systems.

* Work funded by Lam Research Corporation, U.S. DOE Early Career Research Program Award DE-SC0025621, and by Sandia National Laboratories' Plasma Research Facility, funded by the U.S. Department of Energy Office of Fusion Energy Sciences. Sandia is managed and operated by NTESS under DOE NNSA contract DE-NA0003525.

2:15pm **PS-MoA-4 Radio-Frequency Power Pulsing of Intermediate Pressure Electronegative Capacitively Coupled Plasma, Rupali Sahu, Kallol Bera, Shahid Rauf, Applied Materials Inc.**

Plasma processing of wafers utilizes ion and radical based surface processes for high throughput, low-temperature operation. In cases where radical-surface reactions are preferred over ions, power pulsing can be utilized to control the radical-to-ion ratio. In the most basic form, RF pulsing involves switching CCP power between ON and OFF states at a certain pulse frequency. Radicals and ions are generated during the pulse ON phase. During the pulse OFF phase, ions and electrons disappear quickly while the radicals are lost more gradually. Hence, the longer the OFF time is, the higher is the cycle-averaged radical-to-ion flux ratio. A larger pulse OFF time can lead to difficulties in plasma reignition when the power is turned ON, as very few electrons are left for bulk avalanche ionization. These factors determine the stable operating regime for RF pulsing in an electropositive plasma. Plasma modeling shows stable RF pulsing operation is usually achieved at high pulsing frequency and large duty cycle, which is consistent with experimental data.

Strongly electronegative plasmas are characterized by negative ion density being much higher than that of electrons. In this study, we use plasma modeling to analyze pulsing behavior of electronegative capacitively coupled plasmas. This study has been done for He-NF₃ gas mixture at intermediate pressure (~a few Torr). The pulsing frequency and duty-cycle are varied. Modeling results show that strongly electronegative plasma exhibits some counter-intuitive results, such as stable pulsing operation being limited to low pulsing frequency and delayed ignition during pulse ON for certain process conditions. Mechanisms of power absorption in the plasma and electron generation are examined for all cases. It was seen that Penning ionization of Helium sustains electron density during the pulse OFF period, until eventually running out of the excited states of Helium. During the pulse ON phase, the power is preferentially absorbed by the charged specie with highest conductivity, which turns out to be F⁻ ions in some cases, causing a delay in plasma re-ignition. If the delay is larger than the pulse ON duration, the plasma fails to reignite, and the plasma can't be sustained. These mechanisms allow for a pulsing window which exhibits large pulse ON times and can afford to have relatively longer pulse OFF times compared to plasmas that don't have penning ionization reactions.

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2:30pm PS-MoA-5 Hybrid Kinetic-Fluid Methods of Plasma Modeling
Vladimir Kolobov, University of Alabama at Huntsville INVITED

Low-temperature plasma (LTP) is a quasi-neutral mixture of electrons, ions, and neutral species. Its highly non-equilibrium state is beneficial for numerous technological applications. Several methods of particle transport, ranging from fully kinetic to hydrodynamic, have been developed to model LTP systems. In our presentation, we will highlight some important recent advances in the field and discuss the challenges of selecting appropriate models for efficient and accurate simulations.

The disparity of scales and non-local electron kinetics are the most challenging aspects of plasma simulations [1]. The attached Figure shows the key steps in selecting suitable models for electrons in non-magnetized LTP depending on the characteristic temporal and spatial scales. Solutions of the complete Boltzmann kinetic equation by particle-based (PIC) and phase-space-grid methods remain expensive for practical engineering. The disparity of momentum and energy relaxation scales for electrons allows for reducing the phase space dimensionality using angular moments. The dominance of elastic scattering for slow electrons results in a quasi-diffusion equation for the Electron Energy Distribution Function (EEDF) in coordinate-energyspace. Small-angle scattering and continuum energy loss are suitable for fast runaway electrons. Fluid models become adequate when the spatial/temporal scales exceed the electron energy relaxation length/time. Depending on the Coulomb collision frequency, two fluid model varieties could be justified (see attached Figure description). Selecting appropriate models for electrons capturing non-local kinetic effects is poorly understood and will be the focus of our presentation.

Our presentation will show examples of hybrid kinetic-fluid simulations of AC and DC plasma sources, illustrating the importance of non-local kinetic effects. We will explain why maintaining plasma in the dynamic and stratified regimes is the most energy efficient [2]. Finally, we will review recent efforts to use Physics Informed Neural Networks (PINNs) for plasma simulations [3] and discuss perspectives for integrating machine learning algorithms for solving inverse problems in plasma science and engineering.

[1] V.I. Kolobov and R.R. Arslanbekov, Towards adaptive kinetic-fluid simulations of weakly ionized plasmas, *J. Comput. Phys.* 231 (2012) 839

[2] V. I. Kolobov and Y. B. Golubovskii, The principle of minimal power, *Plasma Sources Sci. Technol.* 31 (2022) 094003

[3] V. Kolobov and L. Schoenbaum, Development of grid-based and PINN solvers for electron kinetics in collisional non-thermal plasmas, <https://arxiv.org/abs/2412.16706>

3:00pm PS-MoA-7 Regression-based Circuit Estimation of Collisional Sheath in Moderate Pressure Capacitively Coupled Plasma, *Sathya Ganta, Abhishek Verma, Kallol Bera*, Applied Materials, Inc.

Capacitively coupled plasma chambers are widely used in the semiconductor industry for various deposition and etching applications. Many of these applications require moderate pressure (a few Torr) plasma that provides the required electron density, ion flux and sheath potential/ion energy. At these pressures, the sheath is collisional and cannot be studied by most of the existing analytical techniques that are suitable for collision-less sheaths. In this paper, we begin with the standard circuit model representing a sheath with capacitive element capturing sheath voltage to sheath displacement current relation, resistive element depicting sheath voltage to sheath ion current relation and diode element corresponding to sheath voltage to sheath electron current relation. We then added features to the sheath circuit model that captured the collisional aspects of the sheath at moderate pressure like delay in the electron and ion current responses to sheath voltage and separate resistive elements to capture ion currents at different harmonics. The parameters that define the new collisional sheath circuit model were estimated for any given set of plasma process conditions by comparing sheath voltage and electron, ion and displacement current data obtained from corresponding 1D fluid Argon gas capacitively coupled plasma (CCP) simulations. Regression-based statistics were then used to build a relationship between plasma process conditions like pressure / RF voltage / RF phase and the estimated parameters of the new collisional sheath circuit model. We then used this regression relationship, and an electromagnetic model implemented with the new collisional sheath circuit to predict electron, ion, displacement currents and sheath voltage (i.e., on-wafer ion fluxes and ion energies) for Argon gas capacitively coupled plasma over a wide process span without running the computationally intensive plasma simulations.

3:15pm PS-MoA-8 The Impact of Tailored Voltage Waveforms on Reaction Rates in Capacitively Coupled Plasma Ar/O₂ Discharges, *Syed M. Zulqarnain, Amanda M. Lietz, North Carolina State University; James Prager, Timothy Ziembra, EHT Semi*

Capacitively coupled plasmas (CCPs) are extensively employed in the selective and anisotropic etching of semiconductor materials, as well as in the deposition of thin films. Tailored voltage waveforms (TVW) offer a promising approach to manipulating plasma dynamics and controlling ion and electron energy distributions. These TVW may also provide reduced differential charging within high aspect ratio features, which can cause problematic ion deflection. In many industrial applications, RF CCPs operate with diverse mixtures of electronegative and electropositive feed gases, resulting in different species of positive and negative ions, neutral radicals, and electrons in the plasma volume. Mixtures containing oxygen (O₂) are vital for many etching processes. O₂ significantly contributes to the removal of polymer films during etching by facilitating their oxidation, which helps prevent the loss of ions in the polymer and accelerates the etching of the target material. The control of ion energy and flux is critical for optimizing these processes and offers significant advantages for controlling plasma chemistry during processing. This computational investigation delves into the plasma dynamics of argon/oxygen admixtures in a CCP biased by a triangular-shaped TVW, its impact on ionization rates, and the transport mechanisms of ions and electrons. In this study, a dual-frequency capacitively coupled argon/oxygen discharge at 5 mTorr pressure with a high-frequency (60 MHz) sinusoidal voltage waveform applied to the upper electrode and a low-frequency (400 kHz) triangular-shaped TVW bias applied to the lower electrode is simulated, using Monte-Carlo collision-based, particle-in-cell code (EDIPIC). As the O₂ concentration increases, the electronegativity of the discharge is expected to influence the distribution of positive ions and electrons and the ionization dynamics of the discharge. We explored the impact of TVW on discharge behavior, with particular emphasis on the evolution of ionization rates and electron dynamics within a single low-frequency waveform cycle. The analysis focused on the electric field reversals that may occur during the positive phase of the waveform, examining their effects on ionization rates and power deposition as O₂ concentration varies. Additionally, the study compared the variations in ionization and excitation levels in the bulk plasma between TVW and conventional sinusoidal waveforms. This study elucidates the interplay between plasma electronegativity, reactive chemistry, and tailored voltage waveforms in manipulating plasma dynamics to inform the optimization of semiconductor etching and deposition techniques.

3:30pm PS-MoA-9 Intermediate Pressure Capacitively Coupled Plasma Model Validation, *Kallol Bera, Rupali Sahu, Nakul Nuwal, Shahid Rauf, Applied Materials, Inc.*

Radio-frequency (RF) capacitively coupled plasmas (CCP) at intermediate pressure (~ a few Torr) are widely used in advanced plasma processing in the semiconductor industry. However, the plasma behavior in this pressure regime is not well characterized. Plasma modeling, validated with experimental data at these pressures, enhances the understanding of plasma behavior that is crucial for the plasma chamber design and process development. CCPs with Argon, an electropositive gas, and Oxygen, an electronegative gas, are simulated using a one-dimensional fluid-MCS hybrid plasma model at intermediate pressures and compared with experimental data. Key parameters such as electrode voltage, current, and phase, as well as electron densities, are compared and analyzed. Additionally O density measurements are compared to simulation results for Oxygen plasma. Our model includes continuity equations for charged and neutral species, drift-diffusion approximation for electron flux, momentum conservation equation for ions, energy conservation for electrons, and the Poisson equation for electric potential. The secondary electrons emitted from the surface are treated kinetically using a Monte Carlo model as they accelerate across the sheath. This kinetic secondary electron model is coupled to the fluid bulk plasma model to capture the contributions from these secondary electrons to species production and electron power deposition. A Particle-in-cell model Monte Carlo Collision (PIC-MCC) model is employed to understand the kinetic behavior, and to compare with the hybrid model. Kinetic effects are found to be significant at intermediate pressure highlighting the importance of incorporating kinetic effect at these pressures. The Druyvesteyn Electron Energy Distribution Function (EEDF) is found more appropriate than Maxwellian distribution, consistent with PIC-MCC model results. For Ar plasma, dimers are found to play a crucial role at these pressures. The surface sticking coefficient of atomic oxygen is a critical factor in determining plasma density and O density for Oxygen plasma.

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4:00pm PS-MoA-11 Modeling insights into amorphous carbon etching by SO₂/O₂ low-pressure plasma, *Dmitry Levko, Mingmei Wang, Lam Research Corporation*

In this work, we will explore the influence of the oxygen partial pressure on the amorphous carbon film etching by low-pressure SO₂/O₂ plasma for the experimental conditions of Ishikawa *et al.*, *Applied Surface Science* **645**, 158876 (2024). We will use zero and one-dimensional plasma models to develop and validate both gas-phase and surface reactions mechanisms of SO₂/O₂ plasma in contact with carbon mask. We will discuss the influence of oxygen partial pressure on the plasma parameters such as the main ion and reactive species densities, plasma potential and peak-to-peak voltage. We will also discuss the influence of oxygen on the amorphous carbon etch rate.

4:15pm PS-MoA-12 Pulsed Power Strategies for Plasma Etching of High Aspect Ratio Features Using Fluorocarbon Gas Mixture for Feature Charging Control, *Yifan Gui, Yeon Geun Yook, Chenyao Huang, Mark J. Kushner, University of Michigan*

In microfabrication, plasma etching of high aspect ratio (HAR) features with precision remains a significant challenge largely due to feature charging effects that can lead to profile distortion and etch stop. Feature charging occurs when there is an imbalance in the flux of ions and electrons to inside surfaces of features, leading to the creation of local electric fields that deflect incoming charged species and distort ion trajectories. Previous experimental and modeling studies have shown the sensitivity of feature charging on energy and angular distributions (EADs) of charged species incident onto the wafer. Potential remedies for feature charging include pulsed plasma operation, tailored bias waveforms, and the introduction of electronegative gases to suppress electron density or promote charge neutralization. These strategies aim to balance ion and electron fluxes or temporarily neutralize accumulated charge to mitigate defects within the HAR features. For example, the use of pulsed power is believed to produce a cycle of charging and discharging of the feature as the fluxes and EADs of the charged particles are modulated.

In this work, we discuss a computational investigation of pulse power strategies for controlling the fluxes of charged particles to wafers in capacitively coupled plasmas (CCPs) with the goal of mitigating feature charging. The Hybrid Plasma Equipment Model (HPEM), a modular simulator designed to address the behavior of low-pressure plasma systems, was used to investigate the evolution of incident fluxes and EADs of charged particles during pulse-on and -off periods in multi-frequency CCPs using fluorocarbon gas mixtures and mixtures amenable to cryogenic etching. The consequences of utilizing different modes of pulse operation (low frequency, high frequency, dc) and gas mixtures on the EADs and charged species flux will be discussed in relation to minimizing feature charging.

Work supported by Lam Research, Samsung Electronics and Department of Energy Office of Fusion Energy Sciences.

4:30pm PS-MoA-13 Application of a Structured Showerhead Electrode in Plasma Enhanced Chemical Vapour Deposition: Modeling and Experimental Study, *Montu Bhuva, Geoff Hassall, James Ellis, Gregory Daly, Oxford Instruments Plasma Technology, UK; Erik Wagenaars, James Dedrick, University of York, UK*

The application of a structured showerhead electrode in improving the film thickness uniformity is investigated for large diameter substrate processing using plasma enhanced chemical vapor deposition (PECVD). The fluid-kinetic simulations are carried out using the hybrid plasma equipment model (HPEM) accessed via the Quantemol Virtual Tool (QVT) interface. The modelling results are experimentally verified with the optical actinometry in Ar/O₂ plasma to capture the structured electrode effects on the radial atomic oxygen concentration. The above investigations are conducted at an intermediate pressure regime of 1-2.5 Torr in the Oxford Instruments PlasmaPro-100 PECVD test reactor. The simulation model is further applied to investigate the performance of the multi-cavity structured showerhead in SiH₄ chemistry accessed via the Quantemol Database (QDB). The simulation model indicates that the showerhead cavity rings play a vital role in controlling the radial plasma profile adjacent to the substrate. Finally, the designed structured showerheads, based on the simulations, are tested in the clean room environment for SiO₂ deposition, and the improvements in the process results are characterised against the conventional planar showerhead.

4:45pm PS-MoA-14 Kinetic and Hybrid Modeling of a Radio Frequency Hollow Cathode Discharge and Comparison with Experiments, *Nakul Nuwal, Kallol Bera, Han Luo, Xingyi Shi, Applied Materials Inc.; Shahid Rauf, Applied Materials, USA; Jan Guttmann, Applied Materials Inc.; Ihor Korolov, Julian Shulze, Ruhr Universität Bochum, Germany*

Radio frequency (RF) hollow cathode discharges (HCD) are used in various semiconductor manufacturing processes such as material etching and deposition. HCD cathodes have cavities, and the plasma forms inside these cavities under the right conditions. In the HCD, RF sheath heating as well as secondary electron acceleration can lead to plasma production. In this work, plasma simulation results for argon and oxygen HCDs are compared with plasma diagnostics measurements using non-invasive methods. These measurements include the emission spectra of plasma discharge using Phase Resolved Optical Emission Spectroscopy (PROES), which provides the spatio-temporal excitation rate of important species in the discharge. We use both kinetic and hybrid plasma models in this work to understand the plasma dynamics and elucidate with the experimental observations. The Particle-In-Cell with Monte Carlo Collisions (PIC-MCC) model includes evolution of charged particles and electrostatic field along with charged particle collisions with the neutral species using a Monte Carlo approach. The hybrid model only treats the electrons as particles and includes a fluid model for the other charged species. In both models, the charged species' densities are coupled with the Poisson's equation to calculate the electric potential, enabling a self-consistent plasma simulation. Plasma simulations are performed for different pressures, voltages, and feed gases (Ar & O₂). Our simulation results show good agreement with the spatio-temporal experimental measurements of metastable argon excited state at low pressures. With increase in voltage, the excited species is found to penetrate further into the hollow cathode slot. The modeling results also indicate that the secondary electron emission coefficient from surfaces significantly influences the plasma behavior.

5:00pm PS-MoA-15 Molecular Dynamics Analysis of Transport Properties and Gap-Filling Mechanisms in Flowable Chemical Vapor Deposition Using TEOS-Based Plasma, *Hu Li, Tokyo Electron America Inc.; Takeo Nakano, Masaaki Matsukuma, Tokyo Electron Technology Solutions Ltd., Japan; Jianping Zhao, Peter Ventzek, Tokyo Electron America Inc.*

Flowable chemical vapor deposition (Flowable CVD) is an advanced deposition technique widely used for effectively filling nanoscale structures with complex geometries using plasma-generated oligomers. This method is particularly crucial in semiconductor manufacturing and advanced memory device fabrication, especially for structures with high aspect ratios at dimensions of tens of nanometers. Conventional CVD approaches often encounter incomplete gap-filling, resulting in void formation that significantly compromises device performance. Flowable CVD addresses these challenges by employing oligomers synthesized through plasma-induced polymerization reactions, which exhibit fluid-like properties at relatively low deposition temperatures. This inherent fluidity enables superior gap-filling without the need for additional oxidation steps.

However, despite these evident advantages, the fundamental mechanisms underlying oligomer formation, fluid dynamics, and transport processes in Flowable CVD remain inadequately understood, resulting in occasional practical difficulties such as void formation. Therefore, gaining comprehensive insights into oligomer transport phenomena and deposition mechanisms is essential for optimizing Flowable CVD processes to achieve reliable, void-free film deposition.

This study addresses these critical gaps in understanding by examining the transport properties of oligomer species likely formed in tetraethoxysilane (TEOS)-based plasma environments. Molecular dynamics (MD) simulations were performed to quantitatively evaluate essential characteristics of oligomer liquids, including surface tension, viscosity, and contact angle interactions on wafer surfaces. These analyses provide valuable insights into how such physical properties affect overall gap-filling performance.

Our simulation results indicate that the viscosity of TEOS-derived oligomers increases with decreasing temperature. Furthermore, oligomers with higher molecular weights exhibited relatively lower viscosities, suggesting longer durations required for complete gap-filling. This research establishes clear correlations between oligomer transport properties and deposition efficiency, thereby contributing valuable knowledge to the fundamental mechanisms governing gap-filling and addressing related process challenges.

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5:15pm **PS-MoA-16 Validation of Fluorocarbon Containing Gas-Phase Reaction Mechanisms for Computational Modeling of Commercial Atomic Scale Processing Plasmas, Jordyn Polito, Ben Harris, Geoff Hassall, James Ellis, Oxford Instruments Plasma Technology, UK**

Semiconductor hardware companies require in-depth understanding of plasma systems to address customer support challenges and to inform hardware and process design. Robust, reliable plasma models can be used to increase understanding of plasma systems and aid in rapid solutions to industrial challenges. However, industrial-scale plasma modeling is often challenged by a lack of in-situ diagnostics to validate process-relevant plasma chemistry reaction mechanisms. In this work, the impacts of utilizing reliable plasma modeling techniques together with validated process-relevant reaction mechanisms will be considered from an industrial perspective. Here, a reaction mechanism for CF_4/O_2 is compiled and used in a 0D global plasma model to predict reactive neutral and ion densities and electron temperatures in the plasma region of an inductively coupled plasma used for reactive ion etch processes (RIE). Experimental measurements obtained in an Oxford Instruments Plasma Technology Cobra 300 reactor will be used to validate the reaction mechanism and predict operating conditions that lead to optimal process outcomes.

Quantum Science and Technology Mini-Symposium Room 208 W - Session QS1-MoA

Advanced Materials for Quantum Information Science

Moderators: Kasra Sardashti, University of Maryland College Park, David Pappas, Rigetti Computing

1:30pm **QS1-MoA-1 Superconductor-Semiconductor Epitaxy in Hyperdoped Germanium, Javad Shabani, NYU** INVITED

Introducing superconductivity into group IV elements by doping has long promised a pathway to introduce quantum functionalities into well-established semiconductor technologies. The non-equilibrium hyperdoping of group III atoms into Si or Ge has successfully shown superconductivity can be achieved, however, the origin of superconductivity has been obscured by structural disorder and dopant clustering. Here, we report the epitaxial growth of hyperdoped Ga:Ge films by molecular beam epitaxy with extreme hole concentrations 10^{21}cm^{-3} , that yield superconductivity with a critical temperature of $T_c = 3.5\text{K}$. Our findings, corroborated by first-principles calculations, suggest that the structural order of Ga dopants creates a narrow band for the emergence of superconductivity in Ge, establishing hyperdoped Ga:Ge as a low-disorder, epitaxial superconductor-semiconductor platform. This platform opens up a new path for integration of superconductivity for cryogenic and quantum applications in group IV.

2:00pm **QS1-MoA-3 Molecular Beam Epitaxy of Germanium Quantum Wells with Epitaxial Aluminum, Jason Dong, Joshua Thompson, Chomani Gaspe, Riis Card, Kasra Sardashti, Laboratory for Physical Sciences; Shiva Davari Dolatabadi, Hugh Churchill, University of Arkansas; Kyle Serniak, Thomas Hazard, MIT Lincoln Laboratory; Christopher Richardson, Laboratory for Physical Sciences**

Voltage tunable Josephson junctions (JJs) are an alternative route towards tuning the critical current of JJs in quantum circuits to enable new functionalities, and replace the current carrying flux lines and squids that are currently used. Germanium JJs implemented on float-zone silicon substrates allow for scalable integration with low-loss superconducting circuit elements, and enable a gate tunable transmon with longer coherence times. Here, Ge quantum wells (QW) with epitaxial aluminum contacts are grown by molecular beam epitaxy.

Strained Ge-QWs are grown on $\text{Si}_{0.2}\text{Ge}_{0.8}$ virtual substrates. The $\text{Si}_{0.2}\text{Ge}_{0.8}$ virtual substrates are grown with a reverse graded buffer layer on float zone silicon. Epitaxial aluminum is grown *in situ* on the Ge quantum wells to create high-transparency superconducting contacts that proximitize the underlying Ge-QWs. From low-temperature magneto-transport measurements, a 2 K mobility exceeding $45,000\text{ cm}^2/\text{Vs}$ is observed for samples with a 22-nm deep QW. The effect of growth conditions on the structural quality and low-temperature mobility will be discussed. The structural quality of the samples is investigated with X-ray diffraction, atomic force microscopy, and defect selective etching. Reverse graded buffer layers with the thickness exceeding $1.5\text{ }\mu\text{m}$ are found to be required to eliminate most structural defects. The limiting scattering mechanisms are identified from analysis of the carrier density dependence of the mobility and potential routes towards improving the mobility will be discussed.

2:15pm **QS1-MoA-4 Epitaxy of Superconducting Germanium Thin Films for Integrated Quantum Electronics, Patrick Strohbeen¹, New York University; Julian Steele, Ardesir Baktash, university of queensland, Australia; Alisa Danilenko, new york university; Axel Leblanc, Jechiel van Dijk, New York University; Yi-Hsun Chen, Lianzhou Wang, university of queensland, Australia; Salva Salmani-Rezaie, Ohio State University; Eugene Demler, ETH Zurich, Switzerland; Peter Jacobson, university of queensland, Australia; Javad Shabani, New York University**

Superconducting group IV materials are highly promising for quantum information due to the homoepitaxial alignment with the underlying substrate, reducing material disorder at the film/substrate interface. Furthermore, increasing interest in germanium systems for both spin qubits, gate-tunable superconducting qubits, and topological phases has put a spotlight on the necessity for thin film superconductors that readily interface with group IV systems. However, the hyperdoped phase is thought to require dopant incorporation above typical thermodynamical solubility limits and thus most efforts have been focused on non-equilibrium techniques. Very recent work has shown that superconductivity is observed in Ga-doped germanium system using molecular beam epitaxy. In this talk we will present an expanded study towards illuminating the atomic fine structure of superconducting germanium thin films grown via MBE. We observe that our superconducting MBE-grown films exhibit well-dispersed Ga-dopants throughout the film as substitutional defects via synchrotron-based X-ray scattering and absorption experiments. Cross-sectional electron microscopy imaging shows the homoepitaxial interface between the Ge substrate and the superconducting Ge film is well-defined, the films are of high crystalline quality, and no Ga clustering is found. Band structure calculations further suggest that the observed crystal structure induced a narrow-band state at the R-point in the Brillouin Zone, posing a new possible mechanism for the observed superconducting state.

2:30pm **QS1-MoA-5 Growth and Characterization of Thin-Film A15 Nb-Al Intermetallics for Superconducting Quantum Electronics, Joseph Falvo², University of Maryland College Park; Elizabeth Henry, Clemson University; Ashish Alexander, University of Maryland; Hussein Hijazi, Rutgers University; Ivan Lainez, University of Maryland; Leonard Feldman, Rutgers University; Kasra Sardashti, Laboratory for Physical Sciences**

As superconducting qubit technology progresses, there is an increasing demand for materials with high critical temperatures and critical magnetic fields to allow for devices to be more robust against external excitations. A15 intermetallic compounds, a family of superconductors explored in the 1950's through the 1970's, provide one potential avenue to such high critical values. In this work, we synthesize Nb₃Al, one of many A15 compounds, as a thin film by co-sputtering from elemental targets, followed by a rapid thermal annealing procedure. We confirm the realization of the desired ratio and crystal structure within our films by Rutherford backscattering (RBS) and X-ray diffractometry, respectively. For films with thickness close to 200 nm, we achieve thin films with T_c greater than 16 Kelvin and zero-temperature critical fields greater than 30 T. Additionally, we report single-photon microwave quality factors of 1.9×10^5 and estimates for kinetic inductance similar to NbN at comparable thickness.

2:45pm **QS1-MoA-6 High Purity Physical Vapor Deposition CaO Thin Films for Quantum Information Science, Jake DeChiara, Saeed Almishal, Pennsylvania State University; Jon-Paul Maria, Pennsylvania State University**

CaO has generated substantial interest in the quantum informatics community as a novel solid state QuBit host. In this work we aim to experimentally verify the existence of Schottky defects with rare earth and bismuth interstitials in a high purity CaO thin film host grown on R-plane Sapphire. We study reactive RF sputter and pulsed laser deposition techniques utilizing metallic calcium and $\text{Ca}(\text{OH})_2$ targets. X-ray fluorescence reveals that metallic calcium targets contain substantial chlorine impurities, which adversely affects CaO film growth via sputtering. We demonstrate $\text{Ca}(\text{OH})_2$ as an intriguing candidate as a calcium source for physical vapor deposition due to its availability in high (99.999%) purity and relatively low cost. We utilize a hydrothermal sintering method to attain target density above 95 % while maintaining high chemical purity. All CaO thin films grown were found to achieve single orientation in the (0 0 2) direction, as verified via X-Ray diffraction. Film thickness evaluated by X-Ray reflectivity measurements revealed a faster deposition rate from the metallic calcium target compared to the $\text{Ca}(\text{OH})_2$ target during sputter

¹ JVST Highlighted Talk

² JVST Highlighted Talk

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deposition. Deposition growth rates achieved from the $\text{Ca}(\text{OH})_2$ targets were highly linear and suggest high target stability and reliability. CaO films grown by pulsed laser deposition attained high crystallinity, relatively fast deposition rates, and single orientation. We have identified a wide range of methods in the physical vapour deposition processing space which permit further investigation into the defect structure of doped CaO thin films.

3:00pm QS1-MoA-7 Extending the Specific Resistance of AlOx Thin Films by Tuning Plasma Oxidation Time for QIS Devices, *Runze Li*, University of Maryland, College Park; *Joshua Pomeroy*, National Institute of Standards and Technology

We are extending the range of the specific resistance for our Plasma-AlOx tunnel barriers based on adjusting the oxidation time to reach $1 \text{ G}\Omega^*\text{um}^2$. Device instabilities like charge drift and loss tangent are persistent problems for QIS devices like Josephson junctions that significantly reduce the device stability or shorten the decoherence time. By using plasma oxidation and *in situ* techniques for device fabrication, we have greatly increased the stability of our AlOx tunnel junctions. We believed that generating oxygen atoms in the plasma results in higher reactivity than the oxygen molecules present in natural oxidation. Hence, a denser and less defective aluminum oxide is formed through plasma oxidation. As a result, we have observed a ≈ 50 times increase in the plasma-AlOx based Single Electron Transistors (SETs) compared to naturally oxidized AlOx based SETs (Zimmerman, 2008). We will report on the fabrication and characterization of our plasma-AlOx thin film for thickness and composition change v.s. oxidation time.

3:15pm QS1-MoA-8 Epitaxial Control of Magnetism and Superconductivity in Quantum Materials, *Matthew Brahlek*, Oak Ridge National Laboratory **INVITED**

Understanding and designing functional quantum phenomena presents significant challenges due to the complexity of integrating structurally dissimilar materials and managing intertwined factors such as valence, spin, orbital, and structural degrees of freedom. In this talk, I will highlight recent discoveries that demonstrate how novel phenomena can emerge at the interfaces of materials synthesized as high-quality thin films via molecular beam epitaxy. I will also discuss how advancements in x-ray techniques have provided new insights into the origins of these properties. These findings include emergent and tunable ferromagnetism [1], interfacially enhanced superconductivity [2-3], and the proposed emergence of altermagnetism [4]. A key takeaway is that these breakthroughs are made possible by the tight integration of material synthesis with structural and spectroscopic x-ray-based probes. This combined approach is essential for unraveling the origins of functional quantum phenomena and exploring how these exotic phases can be controlled—potentially paving the way for next-generation microelectronic devices.

- [1] M. Brahlek *et al.*, *Nano Letters*, 23, 7279-7287 (2023); 10.1021/acs.nanolett.3c01065
- [2] R. G. Moore *et al.*, *Advanced Materials*, 35, 2210940 (2023); 10.1002/adma.202210940
- [3] A.-H. Chen *et al.*, *Advanced Materials*, 202401809 (2024); 10.1002/adma.202401809
- [4] M. Chilcote *et al.*, *Advanced Functional Materials*, 2405829 (2024); 10.1002/adfm.202405829

Quantum Science and Technology Mini-Symposium

Room 208 W - Session QS2-MoA

Surface Engineering for Quantum Applications

Moderators: *Dave Pappas*, Rigetti Computing, *Drew Rebar*, Pacific Northwest National Laboratory

4:00pm QS2-MoA-11 Towards Reducing Dielectric Loss from Josephson Junctions in Superconducting Qubits, *Aranya Goswami*, Hung-Yu Tsao, Chia-Chin Tsai, *Kyle Serniak*, *Jeffrey A. Grover*, *William D. Oliver*, Massachusetts Institute of Technology

Superconducting qubits are a promising platform to build large-scale quantum computers. However, material imperfections and defects induced by various nanofabrication processes result in the formation of two-level systems (TLSs). TLSs reduce coherence times and increase temporal fluctuations, making qubits harder to operate in a system. One of the major sources of such TLSs has been observed to arise from the dielectric inside

the Josephson junctions as well as residues/surface dielectric oxide on the metal surrounding the junction. Here we study this in two parts.

First, we look at the impact of oxidation parameters on the behavior of the Al/AlOx/Al Josephson junctions. We specifically study the effects of oxidation pressure and flow during the AlOx formation on the coherence times of the qubits. Using this process, we attempt to identify oxidation conditions that improve coherence and reproducibility for wafer-scale qubit processing.

In the second part of this talk, we present a wafer-scale inorganic stencil-mask based technique to fabricate the Josephson junctions for superconducting qubits. Using this platform, we compare the effects of a resist-free vs resist-based processes on the coherence times of transmon qubits.

4:15pm QS2-MoA-12 HF Induced Degradation in High-Purity, Epitaxial Thin Film Niobium, *Haozhi Wang*, University of Maryland, College Park; *Tathagata Banerjee*, Cornell University; *Thomas Farinha*, University of Maryland, College Park; *Aubrey Hanbicki*, Laboratory for Physical Sciences; *Valla Fatemi*, Cornell University; *Benjamin Palmer*, *Christopher Richardson*, Laboratory for Physical Sciences

As a high-gap superconductor, Niobium (Nb) is a natural choice for making supercomputing qubits that can be operated at elevated temperatures. Nowadays, HF based acid cleans have become a regular processing step to remove native oxide and boost device performance. However, one impurity that severely degrades the superconducting properties of Nb is hydrogen (H). Without a protective NbOx layer, Nb can absorb H, and at a large enough H concentration, niobium hydrides (NbH) precipitate. In this talk, we present the impact of HF-based acid cleans on an ultrahigh purity single crystal Nb film grown on sapphire with $T_c = 9.23$ K, RRR = 40, and resonators with single-photon quality factors more than 10^6 . Depending on the exposure to HF-based solutions, a degradation of the both dc and rf performances are observed. Unique crystallite defects with heights of 50 nm and 3-fold symmetry, which we identify as hydrides, are also observed. The contaminated Nb material is further characterized using x-ray diffraction, x-ray photoelectron spectroscopy, and Raman spectroscopy.

4:30pm QS2-MoA-13 Reducing Losses in Transmon Qubits Using Fluorine-Based Etches, *Michael Gingras*, *Bethany Niedzielski*, *Felipe Contipelli*, *Ali Sabbah*, *Kate Azar*, *Greg Calusine*, *Cyrus Hirjibehedin*, *David Kim*, *Jeff Knecht*, *Christopher O'Connell*, *Alexander Melville*, *Hannah Stickler*, *Mollie Schwartz*, *Jonilyn Yoder*, MIT Lincoln Laboratory; *William Oliver*, MIT; *Kyle Serniak*, MIT Lincoln Laboratory

Superconducting qubits have developed from proof-of-principle single-bit demonstrations to mature deployments of many-qubit quantum processors. Reducing materials- and processing-induced decoherence in superconducting qubit circuits is critical to further the development of large-scale quantum architectures. In this talk we discuss the results of applying selective fluorine-based etches, targeting lossy silicon oxides, in close proximity to sensitive aluminum circuit elements such as Josephson Junctions, resonators and crossover tethers. These fabrication improvements can be implemented with little to no damage to existing structures. The impact that these have on transmon qubit coherence will be discussed.

This material is based upon work supported under Air Force Contract No. FA8702-15-D-0001. Any opinions, findings, conclusions or recommendations expressed in this material are those of the author(s) and do not necessarily reflect the views of the U.S. government or the U.S. Air Force.

4:45pm QS2-MoA-14 Understanding and Mitigating Coherence and Frequency Fluctuations in Superconducting Transmon Qubits, *Tanay Roy*, *Xinyuan You*, *Bektur Abdisatarov*, *Daniel Bafia*, *Mustafa Bal*, *David van Zanten*, *Alexander Romanenko*, *Anna Grassellino*, Fermi Lab

Transmon qubits are a cornerstone of superconducting quantum computing platforms. However, their frequency and coherence properties exhibit temporal fluctuations, leading to performance degradation in quantum processors over time. A common mitigation approach involves frequent recalibration, which, while effective, results in increased system downtime. Enhancing the long-term stability of transmon qubits is therefore critical for scalable and reliable quantum computing. In this study, we develop novel techniques for understanding the underlying mechanisms driving frequency and coherence fluctuations in fixed-frequency transmon qubits. We further explore strategies to mitigate these instabilities, aiming to improve overall system robustness. Our findings provide insights into optimizing superconducting quantum hardware for practical applications.

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5:00pm QS2-MoA-15 Platinum Encapsulation of Niobium and Tantalum Thin Films for Low-Loss Superconducting Qubit Interfaces, *Ananya Chattaraj*, Brookhaven National Laboratory

Superconducting qubits are fundamental components of many quantum computing platforms, yet their scalability is fundamentally limited by decoherence mechanisms arising from environmental disturbances. A critical challenge lies in mitigating dielectric losses associated with surface oxides on superconducting films, which contribute to two-level system (TLS) noise—a dominant decoherence source. Niobium (Nb) and tantalum (Ta) are key superconducting materials used in transmon qubits, but native oxide layers formed during fabrication degrade coherence times. Recent advances have pushed tantalum-based qubits to coherence times approaching 0.3 ms; however, further improvements require refined control over interfacial chemistry and oxide suppression. In this study, we explore platinum (Pt) capping layers as a materials-engineering strategy to reduce oxide formation and dielectric loss on Nb and Ta thin films. The films were deposited via optimized sputtering under oxygen-free conditions to ensure high purity and preserve superconducting properties. Initial laboratory characterization by X-ray diffraction (XRD) and X-ray photoelectron spectroscopy (XPS) confirmed phase purity and reduced oxidation. High-quality films were further analyzed with advanced synchrotron-based techniques, including grazing-incidence extended X-ray absorption fine structure (GI-EXAFS) and variable photon energy hard X-ray photoelectron spectroscopy (HAXPES). These element-specific, depth-resolved methods enabled detailed probing of the Pt/Nb and Pt/Ta interfacial structures, revealing the atomic-scale environment, oxidation states, and any potential alloying or interdiffusion effects that can influence qubit performance. Transport measurements verified that Pt encapsulation maintained the superconducting transition temperature (Tc) of Nb films near 9 K, demonstrating the Pt layer's efficacy as a protective barrier without compromising superconductivity. Comparative analyses between Pt/Nb and Pt/Ta interfaces highlighted differences in oxidation behavior and structural stability, offering critical insights for material selection and interface design in qubit fabrication. This work advances the understanding of interfacial engineering approaches in quantum device materials and provides a pathway toward scalable, low-loss superconducting qubit architectures.

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Surface Science

Room 209 CDE W - Session SS-MoA

Photo/Electrochemistry

Moderators: Rachael Farber, University of Kansas, Liney Arnadottir, Oregon State University

1:30pm SS-MoA-1 Plasmonic Catalysis: Opportunities, Challenges, and Unresolved Questions, *Suljo Linic*, University of Michigan, USA INVITED

Metallic plasmonic nanostructures have emerged as an important class of optically active materials. The initial interest in these materials was based on their nano-antenna properties where these materials concentrate electromagnetic UV-vis fields in small volumes at the surface of the nanostructure. A critical problem with using these metallic materials as nano-antennas is that they lose a significant fraction of electromagnetic energy due to the formation of energetic electron-hole (e-h) pairs in the nanostructures.

There has been a growing realization that the formation of energetic charge carriers in the nanoparticles opens avenues for a number of applications including photocatalytic chemical conversion. At the core of these applications is the need to control the rate of formation of energetic e-h pairs, the location of their formation, and their flow in the nanostructure. There has been a high degree of interest in using hybrid nanostructures containing plasmonic nanoparticles, where the plasmonic component

controls the interaction of light with the material, while the non-plasmonic component uses the resultant energetic carriers to perform a function. Examples of these materials include metal-metal, metal-semiconductor or metal-molecule hybrids. The use of these multicomponent materials introduces a number of fundamental questions related to the impact of the interface between the plasmonic and non-plasmonic component as well as the presence of the non-plasmonic material on the optical properties of the system, the flow of energy and excited charge carriers in the system.

I will discuss our work in the emerging field of hybrid plasmonic materials, focusing on the underlying physical principles that govern the flow of energy and excited charge carriers in these systems, as well as on common misconceptions and fundamental questions that deserve more attention and warrant additional studies.

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2:00pm SS-MoA-3 Effects of Electric Fields and Solvents on the Surface Chemistry of Catalysis and Electrocatalysis, *Charles T. Campbell*, University of Washington

Understanding how liquid solvents affect the adsorption energies of catalytic reaction intermediates on transition metal surfaces, compared to their better-known values in gas phase, is crucial for understanding liquid-phase catalysis and electrocatalysis. For neutral adsorbates, the dominant effect is a decrease in adsorption energy compared to the gas phase by an amount equal to the solvents' adhesion energy to the solid multiplied by the surface area of the solid (that is blocked from solvent adsorption) per mole of adsorbed reactant. However, the electric field near the surface also has a strong effect on adsorption energies. When thermal catalytic or electrocatalytic reactions occur on metal surfaces in liquid solvents like water, an electrical double layer develops near the metal surface with a large electric field which changes with reaction conditions. This electric field affects the energies of adsorbed reaction intermediates and transition states, and therefore reaction rates. I will review ultrahigh vacuum (UHV) surface science studies regarding the effects of electric fields on the energies of adsorbed catalytic reaction intermediates, and show how these can guide predictions about how changes in electric fields from the double layer affect adsorbate energies on metal surfaces in liquids, and serve as benchmarks for validating accuracy of computational studies. In UHV, the electric field felt by an adsorbate can be strongly tuned by the addition of another adsorbed species nearby. Alkali adatoms exert a very strong change in electric field near the metal surface, which changes the energies of coadsorbed catalytic reaction intermediates, their electronic character and their reaction rates, as has been studied extensively in UHV. Assuming that changes in the field have only small effects on the strength of the weak attractions between adsorbate and solvent, the change in adsorbate energy with local electric field in a liquid is the same as in UHV. This approach explains the well-known observation that the binding energy of hydrogen adatoms (H_{ad}) to many late transition metal surfaces, as probed by cyclic voltammetry in water, increases with increasing pH. This change in H_{ad} energy in turn explains pH-induced changes in thermal catalytic and electrocatalytic hydrogenation reaction rates whereby H_{ad} must add to another species.

2:15pm SS-MoA-4 In Air STM Observation of Au(111) Surface Disturbance Including Au Magic Fingers as Modified by Solvent Choice, *Nazila Hamidi, Erin Iski, Dillon Dodge, Rowan Dirks, Lauren Hornbrook*, University of Tulsa

The formation of Au magic fingers on Au(111) surfaces, a phenomenon first observed under "pristine" ultra-high vacuum (UHV) conditions, has long fascinated researchers due to its implications for nanoscale surface manipulation and quantum effects. This study explores the formation of these structures under more relevant conditions, specifically in air and at room temperature, using Scanning Tunneling Microscopy (STM). After exposing Au(111) to a 0.1 M solvent solution, three types of surface disturbances were observed, including the formation of Au magic fingers. The disturbance mechanism involved strong tip-surface interactions and the mass transport of Au atoms, influenced by the solvent choice. Various solvents, including $HClO_4$, HNO_3 , HCl , $NaOH$, CH_2O_2 , $CHCl_3$, C_6H_5N , and $C_2H_4O_2$, were tested for their effects on the surface disturbances. The

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degree of disturbance was categorized into significant & organized disturbance (SOD), significant & disorganized disturbance (SDD), and insignificant disturbance (IND).

The formation of Au magic fingers was primarily observed with solvents classified under SOD, such as HClO_4 and HNO_3 , which facilitated the diffusion of Au atoms at a rate of $9.9 \pm 1.1 \text{ nm}^2/\text{min}$. Solvents in the SDD category, like CH_2O_2 , showed a diffusion rate of $4.0 \pm 1.9 \text{ nm}^2/\text{min}$. Our findings reveal that the chemical properties of the solvent, particularly its total charge and electronegativity, play a pivotal role in modulating the surface dynamics of Au(111). The mechanism for the formation of Au magic fingers likely involved the adsorption of solvent molecules to the STM tip, which then picked up and moved Au atoms from the step edges to form nanowires. This study advances our understanding of solvent-surface interactions and demonstrates the potential for ambient STM to probe and manipulate nanostructures under practical, real-world conditions. The ability to form organized nanostructures like Au magic fingers in the air, without needing UHV or protective liquid layers opens new avenues for nanotechnology, catalysis, and surface chemistry applications. By bridging the gap between fundamental surface science and applied chemistry, this work underscores the importance of solvent choice in controlling nanoscale phenomena and paves the way for future innovations in nanomaterial design.

2:30pm SS-MoA-5 Size-Selected Pt Clusters on N-Implanted HOPG: Oxygen Reduction Reaction and the Effect of Nitrogen Anchor Sites, Lokesha Saravanan, University of Utah; Tsugunosuke Masubuchi, Keio University, Japan; Zihan Wang, University of Utah; Pavel Rublev, Yu Wei, Anastassia N. Alexandrova, University of California at Los Angeles; Scott L. Anderson, University of Utah

Platinum clusters (Pt_n) have been considered as an effective electrocatalyst for the oxygen reduction reaction (ORR), the hydrogen evolution reaction and alcohol oxidation. In this work, atomically size-selected Pt_n were deposited under soft landing conditions ($\leq 2 \text{ eV/atom}$) on indium tin oxide (ITO) and highly-oriented pyrolytic graphite (HOPG) electrodes in ultra-high vacuum, then studied electrochemically. The ORR activity exhibited strong substrate dependence, with Pt_n on HOPG showing up to a ~ 5 times increase in mass activity compared to Pt_n on ITO. However, clusters on pristine HOPG are unstable due to sintering, dissolution, and surface poisoning. To overcome the stability issue, nitrogen implantation has been employed to create anchoring sites on HOPG (N-HOPG). Pt_n deposited on N-HOPG showed improved stability against sintering and dissolution while retaining their high catalytic activity. The catalysts have been characterized by a combination of scanning tunneling microscopy (STM) and scanning transmission electron microscopy. X-ray photoelectron spectroscopy (XPS) provided direct evidence of Pt-N interactions, revealing the nitrogen species that serve as chemically active binding sites. Density functional theory (DFT) calculations were performed to simulate both the cluster-surface interaction and the impact dynamics of N/N_2 ions during implantation. These simulations suggest that ion bombardment leads to penetration and modification of surface graphite layers, promoting the formation of anchor or defect-rich sites favorable for Pt_n stabilization. These findings can provide fundamental insights into cluster stabilization mechanisms and the role of nitrogen anchoring sites on HOPG, offering a broader understanding of electrochemical transformations involving various metal clusters. I would like to acknowledge the support from the U.S. Department of Energy, Office of Science, under grant number DE-SC0020125.

2:45pm SS-MoA-6 Surface Analysis of Planetary Regolith Particles: X-Ray Photoelectron Spectroscopy Results from the Asteroid Bennu, Catherine Dukes, Lianis Reyes Rosa, Adam Woodson, Jackson Glass, Annabel Li, University of Virginia; Christopher Snead, Lindsay Keller, NASA Johnson Space Center; Michelle Thompson, Purdue University; Harold Connelly, Jr., Rowen University; Dante Lauretta, University of Arizona; OSIRIS-REx Sample Analysis Team, NASA

NASA's OSIRIS-REx mission to near-Earth primitive asteroid Bennu returned >120 grams of regolith. The rims of planetary regolith particles can exhibit a composition that is significantly different from the bulk, due either to geochemical processes on the parent body—such as interactions with aqueous environments—or to space weathering processes, including meteoritic impacts or solar wind irradiation. We investigate the surface composition of multiple Bennu particles from aggregate sample OREX-803205-0 via X-ray photoelectron spectroscopy (XPS). We compare these values with published bulk elemental abundances as well as energy-dispersive X-ray (EDS) spectroscopic measurements. XPS analyses were

performed on a PHI Versaprobe III small spot instrument; SEM/EDS measurements were made with an FEI Quanta 650 with Oxford silicon drift detector.

The near-surface compositions of the $>1 \text{ mm}$ particles we analyzed are relatively homogeneous and comparable to the bulk elemental content [1], containing Mg, Si, O, Na, Fe, S, Al, Cr, Mn, C, Cl, and F [2]. The Bennu particle surfaces exhibit lower carbon and oxygen signatures (C: 11–13.4 at-%, O: 56–60 at-%) than the Murchison meteorite surfacial concentrations (C: 16–19 at-%, O: 60–64 at-%) — presumably the result of controlled sample handling and/or indicative of space weathering [3]. The surface abundances of Na (0.6–2.8 at-%), Mg (10.1–13.4 at-%), and Si (10.1–11.9 at-%) are significantly greater for Bennu than Murchison, where $<<1$ at-% Na has been observed and Mg content is only 3–5 at-% [3]. No Ca was observed on the Bennu particle rims, which is surprising because ICP-MS bulk analysis identifies Ca at concentrations similar to Na [1]. These differences may be the result of sample inhomogeneities, but are most probably indicators of aqueous exposure.

The $<1 \text{ mm}$ Bennu regolith particles that we analyzed have surface constituents identical to those of the $>1 \text{ mm}$ particles but exhibit more compositional variation. In particular, S (to 2.1%) and Na (to 3.8%) are highly enriched on some particles. Na enrichment may have originated from salty precipitates generated by a subsurface brine within Bennu's parent body [4], such exposure can also preferentially leach elements such as calcium from particle rims [5].

Acknowledgments: This material is based upon work supported by under contract no. NNM10AA11C issued through the New Frontiers Program.

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3:00pm SS-MoA-7 X-Ray Photoelectron Spectroscopy informs on Hybrid Photoelectrode Surface Passivation and Durability, Jillian Dempsey, University of North Carolina at Chapel Hill INVITED
Integration of CO_2 reduction molecular catalysts with silicon photoelectrodes can be achieved through covalent attachment methods, such as hydrosilylation, where hydrogen-terminated silicon is reacted to form silicon-carbon bonds. These hybrid photoelectrodes use sunlight to drive the conversion of CO_2 to value added fuels and chemicals. Incomplete reaction of the atop silicon sites can leave reactive sites that are prone to corrosion and lead to the formation of defects that trap photogenerated carriers. X-ray photoelectron spectroscopy provides critical information both on the success of the catalyst attachment, as well as the extent of passivation through detection of SiO_2 growth. Further, XP spectra recorded before and after controlled potential photoelectrolysis inform on the durability of the covalently modified silicon surface and guide the development of improved hybrid photoelectrodes.

4:00pm SS-MoA-11 Investigation of the Interaction between Water Vapor and Ni Nanoparticles Supported Over Ceria, Nishan Paudyal, Erik Peterson, Yinghui Zhou, University of Wyoming; Sanjaya Senanayake, Brookhaven National Laboratory; Jing Zhou¹, University of Wyoming

Understanding the role of water vapor in the growth and sintering of ceria-supported Ni nanoparticles is important since it can provide insights into their promising activity towards reactions in which water is a key reactant. In our study, we prepared fully oxidized $\text{CeO}_2(111)$ and partially reduced $\text{CeO}_{1.75}(111)$ thin films as model catalytic supports for Ni and studied the detailed nucleation, size, and distribution of Ni nanoparticles under ultrahigh vacuum (UHV) conditions using scanning tunneling microscopy (STM) and x-ray photoelectron spectroscopy (XPS). Deposition of Ni with submonolayer coverages at 300 K produces small particles that are uniformly distributed over both oxidized and reduced ceria surfaces. The particles agglomerate into large three-dimensional features that are on average 1.0 nm high after heating to 700 K. Furthermore, the particles show a clear preferential decoration at step edges on CeO_2 due to enhanced diffusion at elevated temperatures. The Ni particle growth with heating was also observed over reduced ceria. However, due to a stronger interaction between Ni and reduced ceria with defects (e.g. oxygen vacancies/ Ce^{3+}), smaller Ni particles are formed over $\text{CeO}_{1.75}$. Exposure of water vapor to the Ni/ceria surface at 300 K can influence the sintering behavior of Ni, causing the formation of significantly flatter particles with heating compared to Ni over adsorbate-free ceria that are attributed to

¹ JVST Highlighted Talk

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unique adsorbate-metal-oxide interactions. We also conducted the experiments when water was first dosed onto ceria supports followed by subsequent Ni deposition at 300 K. Surface defects (e.g. oxygen vacancies) over reduced ceria are the active sites for water dissociation to form hydroxyl groups at 300 K. This creates fewer nucleation sites for Ni upon deposition over $\text{CeO}_{1.75}$ at room temperatures and an extensive decrease in its particle density. Predosed water over $\text{CeO}_{1.75}$ also causes significant sintering of Ni nanoparticles with subsequent heating to higher temperatures. Our experimental findings suggest distinct adsorbate-metal-oxide interactions are key to tune the properties of Ni nanoparticles over reducible $\text{CeO}_x(111)$ surfaces caused by water exposure. Such interactions are essential in consideration for further modification of Ni-based catalysts for improved reactivity and stability.

4:15pm SS-MoA-12 The Effect of Surface Reaction Intermediates on the Interaction of Solvent Molecules with Pt(111) Model Catalyst, Valeria Chesnyak, Oregon State University; Arjan Saha, Washington State University; Marcus Sharp, University of Washington; Zbynek Novotny, Pacific Northwest National Laboratory; Nida Janulaitis, Charles T. Campbell, University of Washington; Zdenek Dohnalek, Pacific Northwest National Laboratory; Linay Arnadottir, Oregon State University

The interaction energies of molecules with solvents on metal surfaces contribute to processes in heterogeneous catalysis and electrocatalysis. Such interactions are essential in catalytic biomass conversion reactions, pollution cleanup, and energy transition. The impact of solvents on the adsorption energetics of reactants, reaction intermediates, and transition states determines reaction rates and selectivity. While adsorption enthalpies of many reactants on metal surfaces in vacuum have been reported, how they change in the presence of liquids remains poorly understood.¹ Computational methods such as density functional theory (DFT) can predict adsorption energies, including coadsorption and solvation effects at the reactant-solvent-catalyst interface. However, these models require experimental benchmarks for validation, as significant discrepancies persist between calculated and experimental adsorption enthalpies. We present here results aimed to provide such benchmarks for the interaction energies between adsorbed intermediates and solvents on metal surfaces.

Single Crystal Adsorption Calorimetry (SCAC) is the only technique capable of directly measuring the molecular and dissociative enthalpies of adsorption on well-ordered single crystalline surfaces. We employ a state-of-the-art microcalorimeter, developed by the Campbell group,² to understand coadsorption-induced effects of common agents in catalysis on surfaces. Specifically, we measure the differential heats of adsorption for water and methanol coadsorbed with CO or hydrogen on clean Pt(111). On Pt(111), CO forms a $\sqrt{3} \times \sqrt{3}$ R30° structure, while molecular hydrogen dissociates to form a (1×1) hydrogen atom adlayer at cryogenic temperatures (100 K). Understanding the effects of these pre-adsorbed catalytic intermediates on the adsorption energies of the solvents provides important benchmarks for validating computational models.

References:

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4:30pm SS-MoA-13 Mechanistic Insights into C-C Bond Formation in Photoinduced and Photocatalytic Reactions on Reducible and Non-Reducible Oxide Surfaces, Aakash Gupta, University of Central Florida; Keith Blackman, Eric Segrest, Mihai Vaida, University of Central Florida

The formation of carbon-carbon (C-C) bonds is a fundamental step in numerous catalytic processes that drive the synthesis of diverse materials, including commodity chemicals, polymers, cosmetics, and pharmaceuticals. Understanding how C-C bonds are created in heterogeneous reactions at the gas-solid interface, and how this process depends on the properties of the solid surface, is essential for improving the efficiency of these reactions.

This study examines the transformation of single-carbon species into two-carbon species through the coupling of CH_3 radicals and tracks the subsequent evolution of these intermediates on various oxide surfaces. The investigation employs an experimental strategy that integrates time-of-flight mass spectrometry with pump-probe spectroscopy, along with rapid preparation of the surface with molecules.

On irreducible oxide surfaces such as silicon oxide, the reaction is initiated by a pump laser pulse at a central wavelength of 266 nm. This pulse excites

the CH_3 precursor molecules into the dissociative A-band, resulting in the formation of CH_3 and I fragments. A subsequent probe laser pulse in the ultraviolet range ionizes the reaction intermediates and final products, which are then detected and analyzed using time-of-flight mass spectrometry. Alongside bimolecular processes that yield I_2 and regenerate CH_3 , the formation of C_2H_6 can be monitored with femtosecond resolution.

On reducible metal oxide surfaces, including $\text{TiO}_2(110)$ and amorphous TiO_2 , the reaction pathway is more complex and extends over considerably longer timescales. In the case of $\text{TiO}_2(110)$, the process begins with photodissociation of adsorbed CH_3 precursor molecules. The resulting CH_3 radicals can couple on the surface to produce C_2H_6 , which subsequently undergoes photocatalytic oxidative dehydrogenation to form C_2H_5 , C_2H_4 , and H_2O . An additional reaction channel involves dehydrogenation of surface-adsorbed CH_3 radicals, leading to the generation of CH_2 species. On amorphous TiO_2 surfaces, however, C-C bond formation predominantly proceeds through dissociative adsorption of CH_3 molecules.

Such investigations provide detailed insights into C-C bond formation across a variety of surfaces and precursors, offering new opportunities to understand and control surface reactions of significant industrial and technological relevance.

4:45pm SS-MoA-14 Studying the Intermolecular Forces That Drive Magic Number Clustering, Alex Walter, S. Alex Kandel, University of Notre Dame

The intermolecular forces that drive crystallization also drive cluster formation in solution. These clusters can be measured using electrospray ionization mass spectrometry (ESI-MS) as the soft ionization technique does not break up supramolecular clustering, and the information can be used to study pathways to bulk crystallization. Clusters that appear at higher frequencies than would be expected are called magic number clusters and have highly favorable geometries, charge distributions, or energies. In a solution together, guanine and cytosine form magic number tetramers (3:1 guanine: cytosine). During MS/MS experiments, the tetramers break into guanine dimers and 1:1 guanine: cytosine clusters. This is not the expected Watson-Crick binding pattern, but rather a Hoogsteen binding pattern where the N7 purine and the C4 amino group are binding to the N3 and C4 positions of the other guanine. Replacing a guanine with a cytosine stretches this geometry. Substituting the guanines with 9-methylguanine shows the same binding pattern, as the N9 position does not participate in the Hoogsteen binding, but replacing the guanines with 6-O-methylguanine breaks this clustering entirely as the methyl group sterically blocks magic number cluster formation. This technique is applied to other systems, including melamine with cyanuric acid and adenine with thymine/uracil to learn more about magic number clustering, the intermolecular forces that drive solution assembly, and crystallization.

5:00pm SS-MoA-15 Application of XPS to Detect Low-Energy Electron (1-25 eV) Irradiation-Induced DNA Degradation, Hao Yu, University of Notre Dame; João Pereira-da-Silva, Universidade NOVA de Lisboa, Portugal; Jackson King, Thejaswini Basappa, Bo-An Chen, Pitambar Sapkota, University of Notre Dame; Filipe Ferreira da Silva, Universidade NOVA de Lisboa, Portugal; Sylwia Ptasińska, University of Notre Dame

Low-energy electrons (LEEs, typically 1–30 eV) are known to induce DNA damage through surface-localized interactions occurring within only a few nanometers of depth, primarily via dissociative electron attachment (DEA). These processes can lead to localized bond scission and chemical modifications in specific molecular components. To examine these changes, we employed X-ray Photoelectron Spectroscopy (XPS). In this study, we investigated various components of DNA irradiated with LEEs in the 1–25 eV range, using XPS to monitor energy-dependent chemical modifications.

The investigated targets included double-stranded calf thymus DNA and plasmid DNA (pUC18), as well as four nucleosides together with their corresponding nucleobases, representing eukaryotic DNA, prokaryotic DNA, and individual base components, respectively. Samples were deposited on substrates to form dry thin films for surface analysis. The films were then irradiated with LEEs for durations ranging from 30 minutes to 8 hours under ultrahigh vacuum conditions (base pressure $\sim 2 \times 10^{-10}$ mbar). XPS measurements using an Al Ka X-ray source (70–100 W), focusing on the O 1s, C 1s, N 1s, and P 2p core levels, were performed both during and after irradiation under the same UHV conditions.

At 5 and 10 eV, DNA undergoes core-excited dissociative electron attachment (DEA), and we observed selective cleavage of C–N (N-glycosidic) and C–O bonds in plasmid DNA. Damage patterns at these energies were similar, with the extent of modification increasing progressively with irradiation time. In contrast, at 1 eV, where shape-resonant DEA dominates,

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chemical modifications were minimal, consistent with the limited effectiveness of DEA at such low energies. The TE buffer remained stable under extended X-ray and LEE exposure, but appeared to enhance the yield of site-selective DNA damage under LEE irradiation. At 25 eV, LEEs promoted DNA degradation through combined ionization and DEA pathways. Analysis of calf thymus DNA showed evidence consistent with cleavage of C-O and C-N bonds and disruption of the phosphate backbone. Comparison among four nucleosides revealed that thymidine and guanosine exhibited the most pronounced spectral changes, while cytidine and adenosine were more resistant. Additionally, nucleosides were more susceptible to electron-induced damage than their corresponding nucleobases, indicating that LEEs may preferentially target sugar moieties and N-glycosidic bonds.

5:15pm SS-MoA-16 Unmasking Local Phenomena in Electrochemistry through Scanning Electrochemical Cell Microscopy, *Miguel Bernal, Dario Stacchiola*, Center for Functional Nanomaterials, BNL

Electrochemical reactions at solid-liquid interfaces are at the heart of catalysis, energy conversion, and materials durability. However, the traditional way we study them—using electrodes with macroscopic dimensions—tends to blur the picture. Averaging over large surfaces hides the fact that many processes, from the nucleation of a nanoparticle to its eventual dissolution, actually take place in a highly heterogeneous and stochastic manner at the micro- and nanoscale.

In our work, we use scanning electrochemical cell microscopy (SECCM) to confine the electrochemical reaction to tiny, micrometer- and submicrometer-sized regions of interest. This localized probing allows us to capture electrochemical “snapshots” that reveal just how variable processes such as metal nanoparticle growth and dissolution can be from one spot to the next.

By examining hundreds of such localized measurements, we can build statistical maps of activity across a surface, linking electrochemical behavior with substrate heterogeneity and particle-scale transformations. Even more insight emerges when SECCM is combined with complementary high-resolution imaging, such as in-situ electrochemical transmission electron microscopy (EC-TEM), which directly visualizes dissolution one nanoparticle at a time.

Taken together, these approaches show that electrochemical reactivity is not uniform but intrinsically local and dynamic. Understanding this hidden complexity opens new opportunities for the design of durable electrocatalysts and functional nanomaterials, where performance and stability hinge on events occurring at the level of single entities. Local electrochemical probing thus provides a powerful lens to bridge the gap between ensemble electrochemistry and the reality of nanoscale processes.

Thin Films

Room 206 B W - Session TF1-MoA

Thin Films for Energy I

Moderators: *Blake Nuwayhid*, Naval Research Laboratory, *Matthias Young*, University of Missouri

2:00pm TF1-MoA-3 Enabling Scalable Sustainable Energy Devices via Spatial Atomic Layer Deposition, *Paul Poodt*, SparkNano and Eindhoven University of Technology, Netherlands INVITED

Atomic Layer Deposition is a key enabler for next-generation energy storage and conversion technologies, offering unmatched control over film thickness and composition with excellent conformality on complex and porous surfaces. However, many applications—such as electrolysis and batteries—require high-throughput, low-cost processing, making Spatial ALD (sALD) an attractive solution.

We present recent advances in sALD for two key applications: electrocatalyst coatings for proton exchange membrane water electrolysis (PEMWE) and LiF passivation layers for Li-ion battery electrodes.

PEMWE is a leading method for green hydrogen production. Current systems rely on Ir- and Pt-based electrocatalysts, but the high cost and scarcity of these materials pose scalability challenges. ALD enables ultrathin, conformal catalyst layers with atomic-level control, allowing significant reductions in noble metal usage. We demonstrate sALD of Ir- and Pt-based materials at full PEM stack scale. These coatings achieve 10–100× lower Ir loadings than current standards while maintaining excellent stability under accelerated stress tests.

In Li-ion batteries, LiF has emerged as a promising solid-electrolyte interphase (SEI) component due to its chemical robustness and wide electrochemical stability window. Conventional ALD of LiF often requires high temperatures and undesirable sources of fluorine. We introduce a plasma-enhanced sALD process using a new lithium precursor to deposit pure, crystalline LiF at 100–200°C—compatible with Li-metal anodes and other sensitive substrates. The films exhibit high growth rates, excellent conformality, and are free of oxygen and carbon. Examples of significant improvements in capacity retention will be shown.

Finally, we address the critical role of precursor utilization efficiency in sALD. Through combined experiments and modeling, we show how process parameters—such as surface area, aspect ratio, throughput, temperature, and pressure—can be tuned to minimize precursor waste. Efficient precursor use is essential for the cost-effective and sustainable scaling of ALD in electrochemical device manufacturing.

2:30pm TF1-MoA-5 Manufacturing-Scale Powder Atomic Layer Deposition for Battery Applications, *Arrelaine Dameron*, Forge Nano Inc INVITED

Historically Atomic layer deposition (ALD) has been regarded as a lab-only process, disregarded as too expensive and an unrealistic process for commercial adoption outside of semiconductor manufacturing. However, several methods for high volume manufacturing have been developed over the last decade, making ALD on powders affordable as a material-upgrading technique. Forge Nano has patented, constructed, and demonstrated the highest throughput ALD capability in the world, unlocking new potential for lower cost integration of ALD into products. ALD is a well utilized platform technology for powders, porous particles, and high-surface area objects that has been widely demonstrated throughout the literature. Fundamentally, ALD on powders or any high surface area surface is the same as on flat surfaces -- if the chemistry is self-limiting, the precursors can be kept separate and supplied at a concentration to saturate the available surface area, the thin film growth will be controlled and uniform. In practice, the very high surface area, long diffusion pathways, and complexities of gas solids mixing bring a few additional challenges not usually encountered during lab-scale ALD.

Commercial adoption of EVs requires that we overcome consumer angst around battery range by enabling fast charge and increasing specific capacity, while also significantly decreasing cost (\$/kWh). Achieving these objectives requires higher energy density and higher charge rate operation of high-capacity cathodes and anodes. It also requires that we standup a robust supply chain for battery materials and implement process intensification to minimize manufacturing costs. The major challenge of high-capacity cathode materials paired with low-cost graphite or Si/graphite anodes is their propensity for transition metal dissolution and crossover, and gas generation, which stems from electrochemical decomposition of the electrolyte solvent at electrode-electrolyte interfaces. These degrade battery performance and increase safety risk. FN has developed ALD coatings that can improve anode and cathode materials.

This talk will highlight the benefits of nano-engineering the surface of anode and cathode materials for lithium-ion battery cell development and manufacturing considerations when scaling those solutions for battery production.

3:00pm TF1-MoA-7 Thin Film Solid-State Electrodes for Electrochemical-Mechanical Coupling Experiments, *M. Florencia Petracchi, Bhuvsmita Bhargava, Yueming Song, David Stewart, Taeho Jung*, University of Maryland, College Park; *Alec Talin*, Sandia National Laboratories; *Gary Rubloff, Paul Albertus*, University of Maryland, College Park

Measuring and studying the coupling between mechanical stresses and electrochemical responses in solid state batteries can be challenging due to the presence of several irregular interfaces, and to the non-uniform stress distributions present at them. It is essential to understand this coupling since these mechanical stresses and strains, resulting from fabrication, volume changes from ion insertion and extraction and applied operating pressures, can affect the thermodynamics, kinetics and transport mechanisms in batteries and thus impact their performance.

Our platform, which consists of thin-film electrode samples with mechanically planar interfaces in lateral configurations, and the use of a flat platen connected to a Nanoindenter, allows us to apply controlled uniaxial forces to single electrode interfaces [1]. This platform is used to directly measure the effect that applied stresses have on interfacial equilibrium potentials.

In this presentation we will introduce our platform, including the fabrication of our thin-film V_2O_5 cathodes through reactive sputtering [2] on LATP solid

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electrolyte substrates with a Lithium metal anode, our testing and characterization protocols, as well as our results showing clear coupling between applied mechanical loads and open-circuit voltage. This coupling varies with lithiation state of the sample due to changes in the partial molar volume of Lithium in the V_2O_5 . The partial molar volume of Lithium in V_2O_5 obtained from this platform falls into the range between 2.5 to 5 cm^3/mol , which is consistent with what has been observed for other intercalation materials^[3].

References:

- [1] Song, Y., Bhargava, B., Stewart, D. M., Talin, A. A., Rubloff, G. W., & Albertus, P. (2023). Electrochemical-mechanical coupling measurements. *Joule*, 7(4), 652-674.
- [2] Warecki, Z., Ferrari, V. C., Robinson, D. A., Sugar, J. D., Lee, J., Levlev, A. V., ... & Talin, A. A. (2024). Simultaneous Solid Electrolyte Deposition and Cathode Lithiation for Thin Film Batteries and Lithium Iontronic Devices. *ACS Energy Letters*, 9(5), 2065-2074.
- [3] Koerver, R., Zhang, W., De Biasi, L., Schweidler, S., Kondrakov, A. O., Kolling, S., ... & Janek, J. (2018). Chemo-mechanical expansion of lithium electrode materials-on the route to mechanically optimized all-solid-state batteries. *Energy & Environmental Science*, 11(8), 2142-2158.

3:15pm TF1-MoA-8 Mapping Lithium Diffusion in Thin-Film V_2O_5 Using Raman Spectroscopy, Daniel MacAyeal, University of Vermont; **Leopoldo Jose Tapia-Aracayo**, University of Maryland, College Park; **Spencer Caverly**, University of Maryland; **David Stewart, Gary Rubloff**, University of Maryland, College Park; **Alexander Kozen**, University of Vermont

Understanding the lateral diffusion of lithium in thin-film solid state battery (SSB) materials is critical to improving SSB performance, stability, lifespan, and architecture. Using model test structures of sputtered annealed- and unannealed- V_2O_5 /LiPON, we use Raman spectroscopy peak shifts to map Lithium concentration in V_2O_5/VO_x . We evaluate the diffusion of lithium from LiPON layers into thin-film Vanadium Oxide, measure the impact of different sputter deposition process conditions on lateral lithium diffusion into crystalline and amorphous metal oxide films. We confirm experimental results with simulations, exploring both potential-driven diffusion and Fickian diffusion as possible mechanisms for Lithium transport. Lastly, we will discuss the important implications of the lateral spacing limitations of clustered SSB devices due to lateral diffusion and propose architectural design rules based on this diffusion behavior for optimized device performance.

Thin Films

Room 206 B W - Session TF2-MoA

Thin Films for Energy II

Moderator: Alexander Kozen, University of Vermont

4:00pm TF2-MoA-11 Interface Engineering for the Highly Efficient Antimony Chalcogenides Thin Film Energy Devices, Feng Yan, Arizona State University **INVITED**

Antimony chalcogenide (Sb_2X_3 , X=S, Se, Te) thin film solar cells have garnered significant interest due to their optimal bandgap, high absorption coefficient, and earth-abundant constituent elements. Interface engineering plays a pivotal role in optimizing the performance of these solar cells, as the interfaces between different layers critically influence charge carrier dynamics. This talk focuses on systematically investigating and engineering interfaces in Sb_2X_3 -based thin film solar cells to enhance their efficiency and stability. Precise control over interface properties was achieved by employing techniques such as sputtering and chemical bath deposition (CBD). The introduction of buffer layers, passivation treatments, and surface modifications were explored to mitigate recombination losses and improve charge extraction. Advanced characterization methods including X-ray photoelectron spectroscopy (XPS), were utilized to analyze the interfacial properties and their impact on device performance. The findings highlight the critical importance of interface quality and the potential of tailored interface engineering to unlock higher efficiencies in antimony chalcogenide thin film solar cells. This work provides a pathway for further optimization and commercial viability of Sb_2X_3 solar cells, contributing to the advancement of sustainable photovoltaic and photoelectrochemical technologies.

4:30pm TF2-MoA-13 Developing R32 Barium Nickelate Thin Films for Catalysis, Ian Graham, Georgia Institute of Technology; **Kayla Chuong, Anna Österholm, Lauren Garten**, Georgia Institute of Technology, USA

The oxygen evolution reaction (OER) is the rate limiting step inhibiting the production of fuel from water.^{1,2} Barium nickelate (BNO) is a promising catalyst, due to a tunable oxygen stoichiometry without significant structural changes to the crystalline phases. Tuning oxygen stoichiometry in transition metal oxides can modulate the band structure and increase catalytic activity.³ The R32 phase of BNO is proposed to exhibit increased OER catalytic activity due to a theoretically predicted e_g orbital filling of Ni near the optimal value of 1.2 for OER.¹ However, the range of stoichiometries, and therefore Ni oxidation states, that the R32 phase of BNO can exhibit are not yet known.

Here, we stabilized the R32 phase of BNO in thin films using a $BaNi_{0.93}O_{2.68}$ target by pulsed laser deposition (PLD) on (0001) Al_2O_3 substrates. The films were deposited at a substrate setpoint temperature of 400 °C, oxygen partial pressures ranging from 0.012-0.091 mbar, and a laser fluence of 2.5 J/cm². X-ray diffraction shows that the films are solely (100) oriented and only the R32 phase is observed over this range of partial pressures. Energy dispersive X-ray spectroscopy reveals that the film stoichiometries range from $BaNi_{1.10}O_{2.26}$ to $BaNi_{1.03}O_{2.14}$. The range of stable oxygen stoichiometries is further increased by post annealing in an oxygen atmosphere beyond those available by PLD. X-ray photoelectron spectroscopy indicates the presence of Ni^{2+} , Ni^{3+} , and Ni^{4+} . Four-point probe measurements show an increase in resistivity with increasing oxygen stoichiometry; decreasing oxygen stoichiometry to $BaNi_{1.03}O_{2.14}$ resulted in a conductivity of 0.161 S/m. Then films were deposited on conductive (111) $Nb: SrTiO_3$ substrates for impedance spectroscopy, dielectric, and piezoelectric measurements. The piezoelectric response was measured using laser doppler vibrometry in an $e_{11,f}$ wafer flexure system. Impedance spectroscopy results further show the role of oxygen vacancies migration on the electronic and ionic conductivity.

References

- 1) Lee et al., *J. Am. Chem. Soc.* **2016**, 138 (10), 3541–3547.
- 2) Plevová et al., *Journal of Power Sources* **2021**, 507, 230072.
- 3) Wang et al., *ACS Catal.* **2018**, 8 (1), 364–371.

4:45pm TF2-MoA-14 Nano Layers, Tera Goals : Atomic Layer Deposition of Ruthenium for the future Hydrogen Economy, Swapnil Nalawade, Shyam Aravamudhan, Mengxin Liu, Dhananjay Kumar, North Carolina A&T State University

Atomic layer deposition (ALD) enables angstrom level control over material synthesis, making it a powerful platform for engineering catalytic thin films. In this study, we report the deposition of ultrathin Ruthenium (Ru) films on TiO_2 substrates with (100), (101) and (110) orientations via thermal ALD using organometallic precursor ($Ru(ETCP)_2$) and oxygen as co-reactant. The process yield conformal, uniform and highly crystalline as confirmed by X-ray photoelectron spectroscopy (XPS) and X-ray diffraction (XRD). XRD showed hexagonal closed packed structure and XPS confirmed the binding energy of $Ru3d_{5/2}$ is associated with $Ru^{(0)}$. Electrochemical evaluation demonstrates hydrogen and oxygen evolution reactions in 0.1 M H_2SO_4 , achieving enhanced catalytic activity for Ru on $TiO_2(110)$ which also exhibited lower charge transfer resistance in EIS plot. Tafel slopes also highlighted different kinetics for different Ru films. To understand surface chemistry and guide future refinement, first principles density functional theory (DFT) calculations will be employed to explore reaction mechanisms to unravel the energetics and rate limiting steps during growth of Ru films. DFT will help in understanding precursor-ligand decomposition, oxygen interaction and surface termination dynamics during the ALD cycle. This integrated experimental-computational approach illustrates how nanoengineered Ru films can play pivotal role in enabling next generation clean energy infrastructure to achieve terawatt scale hydrogen production.

5:00pm TF2-MoA-15 Sputter Deposition of Composite Membranes for High Performance Hydrogen Purification, Cameron Burst, Colorado School of Mines; **Thomas Fuerst**, Idaho National Laboratory; **Doug Way, Colin Wolden**, Colorado School of Mines

Ultrahigh purity hydrogen is essential in many fields including semiconductor processing, fuel cells, and fusion energy. Palladium-based foils offer high flux and perfect selectivity for hydrogen purification, but are prohibitively expensive for many applications. BCC metals like vanadium (V) and niobium (Nb) are ~600X less expensive and offer an order of magnitude greater hydrogen permeability, but require the application of a catalyst to efficiently dissociate and recombine molecular hydrogen and protect V and

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Nb from uptake of nonmetal impurities. In this work sputter deposition is used to fabricate composite membranes to unlock the full potential of BCC metal foils. Pd is a great catalyst, but will rapidly interdiffuse with BCC metals. In the first strategy we deposit a TiN interdiffusion barrier between Pd and the underlying V foil. TiN was deposited via reactive sputtering, and films with the desired (200) orientation were obtained in the metallic regime at 400 °C with the application of a 200 V bias. The permeability of thin-film TiN was determined with palladium-based sandwich structures. TiN layers up to 10 nm resulted in a minimal decrease in flux (~20%) relative to a freestanding PdCu foil, which was attributed to the interfacial resistance. Composite Pd|TiN|V|TiN|Pd membranes exhibited permeability values up to three times greater than pure palladium, exhibiting stability at 450 °C for over 100 h. However, the membranes were unstable at 500 °C, which was attributed to the instability of the thin Pd layer and loss of catalytic activity. The second strategy involved using sputter-deposited TiO₂ as a catalyst layer. It was found that anatase TiO₂ was an excellent catalyst for H₂ activation, producing composite membranes that achieved theoretical permeability at 500 °C. After 20 hours of operation these membranes begin to display a slow decline in performance. Extensive materials characterization techniques are employed to understand the underlying reasons driving performance and to further improve the stability of these composite membranes.

Vacuum Technology

Room 205 ABCD W - Session VT1-MoA

Vacuum for Fusion and Large Systems I

Moderators: Sol Omolayo, Lawrence Berkeley National Laboratory, Charles Smith, Oak Ridge National Laboratory

1:30pm **VT1-MoA-1 Advanced Roots Pumping Solutions for Demanding Applications in Fusion and Nuclear Research: The New Okta 1500 GM, Nico Völker, Pfeiffer Vacuum GmbH, Germany** INVITED

Abstract:

Fusion and nuclear research facilities impose stringent requirements on vacuum technology, including high pumping speeds, reliability, and contamination-free operation under extreme conditions. Pfeiffer Vacuum's latest addition to its high-performance Roots pump portfolio, the **Okta 1500 GM**, addresses these challenges with enhanced efficiency and flexibility tailored for scientific and industrial applications.

The Okta 1500 GM combines a robust design with an integrated magnetic coupling, ensuring absolute gas-tightness. This feature eliminates the risk of cross-contamination and significantly reduces maintenance, making the pump ideal for radioactive and toxic media handling.

This presentation will highlight key technical innovations, such as the mechanical seals and advanced thermal management, as well as application examples from recent fusion and nuclear research projects. Special emphasis will be placed on the pump's contribution to operational safety, system uptime, and reduced lifecycle costs in demanding R&D and pilot-scale environments.

2:15pm **VT1-MoA-4 SPARC Tokamak Status and Inter-Pulse Pumping Projections, Matt Fillion, Oliver Mulvany, Commonwealth Fusion Systems; Shaun Hughes, Ant Hollingsworth, Commonwealth Fusion Systems, UK; Chris Chrobak, Adam Kuang, Commonwealth Fusion Systems**

The SPARC tokamak is a compact, high-field, deuterium-tritium fueled magnetic confinement device, aimed at demonstrating net energy gain. The SPARC vacuum pumping systems (VACP) comprises three subsystems: the cryostat pumping system provides superconducting component vacuum insulation, the leak detection system provides interspace pumping of vulnerable double-walled vacuum components, and the torus pumping system integrates with the fueling system to enable plasma operations.

A significant portion of each VACP subsystem will be installed and commissioned this year as part of a major SPARC milestone. Concurrently, VACP development progresses to enable SPARC final assembly and integrated commissioning, culminating in the initial pump-down of SPARC and beginning of plasma operations.

This talk will provide an update on the SPARC vacuum pumping systems and associated challenges. Additionally, we will discuss vacuum performance on plasma operations in more detail.

2:30pm **VT1-MoA-5 ITER Roughing Pump System Within the Fuel Cycle, Ainsley Hart, Jared Tippens, Lisa Batsch-Smith, David vanderVeen, Oak Ridge National Laboratory** INVITED

The ITER Project is an international collaboration consisting of the United States, European Union, China, Russia, South Korea, Japan, and India, with the goal of demonstrating the scientific and technological feasibility of fusion energy for peaceful purposes. The ITER machine is being constructed in Cadarache, France and is a large Tokamak device.

The Roughing Pump System (RPS) design is being completed by US ITER, the United States Domestic Agency, and is vital to the fuel cycle system. The fuel cycle system includes the Pellet Injection System, RPS, and the Tokamak Exhaust Processing (TEP) System. This presentation will cover the RPS only, and its role in the fuel cycle.

The RPS is vital for regeneration of the Torus Cryopumps (TCPs), as well as other functions outside of the fuel cycle. RPS is currently being designed using first-of-a-kind, all-metal roughing pump trains composed of scroll and roots pumps to manage the gas load between the TCPs and the TEP System. Originally, a bespoke cryogenic-based system was required for regeneration, but as vacuum pumping technology has advanced the commercially available pumps now provide the opportunity for the all-metal pump trains.

The TCPs evacuate large vacuum volumes in the ITER facility. They accumulate various gas species during operations, leading to the need for regeneration at varying levels of temperature. This gas volume will then be evacuated through the Torus Cryopump Regeneration System (TCRS) Cells, consisting of 1 roots pump and 5 scroll pumps, to the TEP System for processing. There are three TCRS cells, where a roots pump is backed by 3 scrolls in parallel, which is backed by two scroll pumps in series.

The RPS system's Eumeca scroll pumps are based on the tritium compatible Normatex scroll pumps that have been evaluated with protium and deuterium at the Karlsruhe Institute of Technology [1]. Recently, the Eumeca pumps have successfully completed protium and deuterium testing at the United Kingdom Atomic Energy Authority, leading to the proposed 3-1 scroll pump configuration backing the roots pump.

This presentation will highlight the role of RPS in ITER's fuel cycle, the results of the scroll pump characterization testing, and analysis of the TCP regeneration cycle from VacTran analysis.

[1]Berndt, U., et. al (1991). Performance Characteristics of Large Scroll Pumps. *Fusion Engineering and Design*, 18, 73-77. [https://doi.org/10.1016/0920-3796\(91\)90110-C](https://doi.org/10.1016/0920-3796(91)90110-C)

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3:00pm **VT1-MoA-7 Space Simulator – Thermal-Vacuum Chambers, Juan Pablo Romero, INOVOAL Corp, Argentina** INVITED

Satellites and systems orbiting the Earth are affected by the extreme conditions of space, where vacuum and sudden thermal amplitude affect materials and hardware systems. To ensure their correct performance, in INOVOAL we are specialists in design and manufacturing Space Simulators, Thermal Vacuum Chamber systems for testing satellites and space components that validate the resistance and functionality of systems under controlled conditions prior to their launch. This equipment allows engineers to identify and correct potential failures, thus maximizing the lifespan and performance of space missions.

Vacuum System: The vacuum system includes Dry Mechanical Pump for the first stage and a turbo-molecular pump for the second stage. Optionally, the equipment is prepared to add a cryogenic pump as a third vacuum stage. Throughout the vacuum system and chamber sections, there are control points to sense the performance and allow the opening and closing of vacuum valves and the start of thermal sequences. Turbo and Cryogenic pumps are directly connected to the chamber through gate valves. Electrically operated right-angle valves are configured to control the approximate vacuum and the counter-vacuum of the turbo (and cryogenic) valves.

Mechanical Sub-System: Most of the SP vessels are based on a horizontal cylindrical design, with a cylinder central body and two semi-elliptical caps, one rear and one front as a door. The design is based on and verified according to ASME Sec. VIII Div. I standards.

Shroud: The Shroud is of the 304L stainless steel pillow plate type. The Shroud is divided into three sections: The main cylinder (located along the

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central axis of the Simulator's main vessel) and rear cover, the front cover or door, and the cold table.

INTERIOR SURFACE: The interior surface of the Shroud has an Emissivity higher than 0.9. It is internally painted with black polyurethane with thermal and optical characteristics suitable for thermo-vacuum tests. The painting is MAP PU1 or similar with equal or better characteristics. The paint is tested and certified to ensure that it does not out gas in high vacuum and thermal cycles.

EXTERIOR SURFACE: The external side of the Shroud is mirror polished with "Electropolish" or a similar process and has an emissivity rate lower than 0.15. Optional for the interior surface of the chamber: Shot peening with glass bead blasting.

3:30pm VT1-MoA-9 Alternative Method for Large Vacuum Systems Bake-Out, Freek Molkenboer, Han Veldhuis, Herman Bekman, Andrey Ushakov, Veronique De Rooij, Thom Oosterveen, Michael Dekker, Corne Rijnsen, Willem van Werkhoven, Dirk van Baarle, TNO Science and Industry, the Netherlands

Thermal bake-out is a well-known and commonly used method for removing contaminants from the inner surface of a vacuum system. However, the economic and practical scalability of this method for very large systems or systems with a high thermal mass poses quite some challenges.

The Einstein Telescope will be the largest vacuum system on Earth and will require the removal of water and hydrocarbons after installation underground. The currently foreseen method is thermal bake-out using Joule heating of the beam tube. The beam-pipes have a diameter of 1 meter, and due to the layout of the Einstein Telescope, a total of 120 kilometers of beam-pipe is needed.

In a dedicated study, TNO will investigate the technical feasibility of using plasma techniques to remove water and hydrocarbons from the inner surface of the beam tube. For this study, a dedicated setup will be designed and built to assess whether plasma-assisted cleaning can achieve the low partial pressure specifications needed for the Einstein Telescope.

During the presentation, we will discuss the considerations and realization of the setup, as well as the first validation experiments.

Vacuum Technology

Room 205 ABCD W - Session VT2-MoA

Vacuum for Fusion and Large Systems II

Moderators: Freek Molkenboer, TNO Science and Industry, the Netherlands, Marcy Stutzman, Jefferson Lab

4:00pm VT2-MoA-11 The Einstein Telescope Beam Pipe Vacuum System: The Pilot Sector, Ivo Wevers, Giuseppe Bregliozi, Paolo Chiggiato, Manjunath Dakshinamurthy, Ana Teresa Perez Fontenla, CERN, Switzerland; Purnalingam Revathi, University of Antwerp, Belgium; Carlo Scarcia, CERN, Switzerland **INVITED**

Gravitational waves were first detected in 2015 by LIGO, which has since measured several other events in collaboration with VIRGO. These groundbreaking discoveries have driven the development of next-generation gravitational wave observatories, including the Cosmic Explorer (CE) in the U.S. and the Einstein Telescope (ET) in Europe.

A key factor in enhancing detection performance is the length of the Fabry-Perot cavities, where high-power laser beams are stored in an ultrahigh vacuum. Both CE and ET require over 100 km of vacuum pipes, each approximately 1 meter in diameter. If built using the same materials and design as LIGO and VIRGO, these vacuum systems could account for an important fraction of the total budget for the new facilities. To reduce the cost impact of the vacuum system, unconventional materials, less expensive pipe manufacturing and different surface treatments were investigated.

Mild steels and ferritic stainless steels have emerged as promising, cost-efficient alternatives due to their inherently lower residual gas content. However, material selection must also consider availability, formability, weldability, strength, ductility, corrosion resistance in addition to cost. Based on these criteria, ferritic stainless steel AISI 441 (EN 1.4509) has been identified as the most suitable material for ET's beam pipe vacuum system.

To validate this approach, a 40-meter-long pilot beam pipe is being constructed at CERN. This test sector will assess the vacuum layout, material performance, vibration transmission and operational strategies

needed to achieve ultrahigh vacuum (UHV) in a dust-controlled environment at a lower cost. The results will play a crucial role in shaping the final design of the next-generation gravitational wave detectors.

4:45pm VT2-MoA-14 Comparative Water and Hydrogen Outgassing Behavior of Bare vs. Magnetite-Coated AISI 1020 Low-Carbon Steel, Aiman Al-Allaq, ODU - Jefferson Lab; Md Abdullah Al Mamun, Matthew Poelker, Jefferson Lab; Abdelmageed Elmoustafa, ODU

Building on our previous work on low-carbon steel's outgassing characteristics, this study presents a systematic comparison between bare and magnetite-coated AISI 1020 steel vacuum chambers. Room temperature pump-down curves for both chambers follow power-law behavior ($P \propto t^{-a}$) with a values near 1.1, indicating diffusion-limited desorption. The magnetite coating initially provides 5.3× lower water outgassing rates (1.88×10^{-11} vs. 9.88×10^{-11} Torr·L/s·cm²), but this advantage reverses after thermal treatment, with bare steel outperforming magnetite by 3.3× after 80°C and 1.4× after 150°C baking. More significantly, hydrogen outgassing measurements show bare steel achieving rates as low as 9.6×10^{-16} Torr·L/s·cm² compared to 2.4×10^{-14} Torr·L/s·cm² for magnetite-coated steel after intensive thermal conditioning. Comprehensive characterization through Sips isotherm modeling reveals higher binding energies for magnetite (1.12-1.24 eV) versus bare steel (0.9-0.97 eV), while Arrhenius analysis shows similar activation energies (0.33-0.68 eV). RGA measurements confirm hydrogen dominance (>99%) in the residual gas composition. These findings enhance our understanding of the fundamental outgassing mechanisms in low-carbon steel and provide quantitative data essential for vacuum system design.

5:00pm VT2-MoA-15 Panel Discussion,

5:15pm VT2-MoA-16 VTD Business Meeting,

Monday Evening, September 22, 2025

Plenary Lecture

Room Ballroom AD - Session PL-MoE

Plenary Session

Moderator: Stephanie Law, Pennsylvania State University

5:30pm PL-MoE-1 Interfaces are Everything! The Critical Role of Interface Control and Engineering for Next-Generation Quantum Technologies,

Michael Manfra, Purdue University, Microsoft Quantum Lab West Lafayette

INVITED

Tuesday Morning, September 23, 2025

Applied Surface Science

Room 209 B W - Session AS-TuM

Surface Characterization of Energy Materials

Moderators: Jodi Grzeskowiak, TEL Technology Center, America, LLC, Benjamin Reed, National Physical Laboratory, UK

8:30am AS-TuM-3 Solar Energy from a Big Picture Perspective to Nanoscale Insights via TOF-SIMS, *Steven P. Harvey*, NREL INVITED

The world is rapidly changing the way that it gets energy due to rapid price declines in new energy sources and storage within the last ten years. We will briefly discuss solar energy trends as a whole, before diving into our recent contributions to the field using time-of-flight secondary-ion mass spectrometry (TOF-SIMS) at the National Renewable Energy Laboratory to improve the performance and reliability of solar cell and battery materials, and we will present some of our work that highlights the versatility of TOF-SIMS. This work includes: 1) Multi-scale, multi-technique investigations of photovoltaic module failure including TOF-SIMS to enable insights into the root-cause mechanisms of module degradation at the nanoscale that are observed at the length scale of meters 2) Investigations into the performance and stability of hybrid perovskite solar cell devices and our work to understand measurement artifacts in this materials class when profiling.

9:00am AS-TuM-5 Introduction of Cryogenic X-Ray Photoelectron Spectroscopy for Chemical Analysis of Sensitive Battery Interfaces, *Sanzeeda Baig Shuchi¹, Yi Cui, Stacey Bent*, Stanford University

Understanding the chemical environment of pristine interfaces is a long-sought goal in electrochemistry, materials science, and surface science. One such interface, the solid electrolyte interphase (SEI) in lithium battery anodes, is described as the nanometer-thick passivation layer between the lithium anode and electrolyte formed due to electrochemical and chemical decomposition of the electrolyte. For high performing electrolytes above ~95% Coulombic efficiency, SEI is considered the key performance modulator in next-generation lithium metal batteries.

Important understanding of the SEI is achieved using X-ray photoelectron spectroscopy (XPS). However, room temperature (RT) combined with the ultra-high vacuum (UHV) conditions of standard XPS can induce major SEI evolution from reactions and volatilization during measurement. Subsequently, a technique is necessary for SEI stabilization.

Here, for the first time, we develop cryogenic (cryo)-XPS with immediate plunge freezing and demonstrate SEI preservation. We show that cryogenic conditions can halt chemical reactions and freeze UHV-volatile species. Most chemical reactions are halted due to slow reaction kinetics at cryoT. We hypothesize that the true SEI thickness can also be retained, benefiting from the lower vapor pressure of different frozen SEI species at cryoT. Indeed, we discover completely different SEI composition and a thicker pristine SEI with cryo-XPS. While cryo-XPS ensures SEI preservation over an extended period under UHV, compositions derived from RT-XPS are dominated by stable species only. We confirm the SEI thickness preservation from Li 1s high-resolution spectra of the underlying metal substrate. We carefully analyze and decouple three major effects during SEI analysis: UHV effect, reaction effect, and beam effect. UHV and reaction are found to be the major drivers for SEI compositional changes under standard RT-XPS conditions.

While RT-XPS-based chemical descriptions fail to provide performance correlations, we show that pristine SEI composition achieved by cryo-XPS enables performance correlations across diverse electrolyte chemistries. We expect our research to inspire future studies of sensitive and reactive interface characterization under cryogenic conditions to ensure pristine state preservation.

9:30am AS-TuM-7 Surface and Bulk Characterization of Organic Semiconductors Using XPS and UPS Techniques, *Jonathan Counsell, Liam Soomary*, Kratos Analytical Limited, UK; *Chris Moffitt*, Kratos Analytical Inc.

Organic semiconductors have gained significant attention in recently due to their potential for flexible, lightweight, and low-cost electronic applications. These materials, enable charge transport via delocalized electronic states, a characteristic of their π -conjugated molecular structures. Their utility includes various organic electronic devices, including Organic Thin-Film Transistors (OTFTs), Organic Light-Emitting Diodes (OLEDs), Organic Photovoltaics (OPVs), and organic diodes. The selection and performance of these materials depends on the semiconductor properties such as charge

carrier mobility, energy level alignment, and stability [1]. Among the widely studied molecules, DNTT and CuPc function as p-type semiconductors, facilitating hole transport, whereas CuF₁₆Pc serves as an n-type semiconductor, supporting electron transport. Additionally, F4TCNQ, a strong electron acceptor, is commonly employed as a molecular dopant to enhance the conductivity of p-type materials. Understanding the surface properties and chemical interactions of these molecules is crucial for optimizing device performance and stability.

We will explain the utility of a combination of experimental methods using a modern X-ray Photoelectron Spectroscopy (XPS) spectrometer (both small-area spectroscopy and 2D XP imaging) to probe the surface and bulk properties of both blanket and printed structures. This approach allows for an in-depth analysis of how organic semiconductors interact with substrates and templating/electrode layers. Additionally, we will explore the effects of deposition processes and the evolution of electrical properties as a function of depth, employing Hard X-ray Photoelectron Spectroscopy (HAXPES) and ion milling techniques. Furthermore, Ultraviolet Photoelectron Spectroscopy (UPS) will be utilized to determine the work function of these materials, a critical parameter in optimizing charge injection and transport. A methodological approach to surface characterization will also be discussed, providing insights into the interfacial properties that govern device performance.

[1] Owen A. Melville, Benoît H. Lessard, and Timothy P. Bender, ACS Applied Materials & Interfaces 2015 7 (24), 13105-13118, DOI: 10.1021/acsami.5b01718

9:45am AS-TuM-8 "XPS? Never Heard of It!" - The Consequences of Choosing Incorrect Analytical Techniques When Characterizing Problem Polymer Surfaces!, *Brian Strohmeier*, Surface Science Solutions, LLC

This presentation describes a controversy where an end user was experiencing substantial adhesion issues with splicing tape on a PET polymer film material. The end user strongly suspected that some type of surface contamination was the root cause of the poor adhesion characteristics on the PET film product. The manufacturer of the PET film used FTIR, XRF, and sessile drop contact angle/surface energy measurements to characterize the surface of the film and claimed the analytical results indicated the product was free of any detectable surface contamination. Based on their in-house analytical results, the PET film manufacturer absolved themselves of responsibility for the poor adhesion of the splicing tape to the PET film and contended that the end user's own manufacturing process was at fault.

Subsequent XPS measurements performed by a third party, at the request of the end user, indicated the presence of high amounts of PDMS silicone surface contamination on the issue PET films. In contrast, non-issue PET films produced by another manufacturer had no XPS-detectable silicone present. It is well known that even low amounts of silicone surface contamination can be detrimental to adhesion performance on polymer materials. XPS has a substantially higher surface sensitivity compared to FTIR and XRF and is the premier surface analytical technique for characterizing the chemistry of complex material surfaces and for solving challenging surface-related industrial problems. Although XPS produced overwhelming and irrefutable evidence, contrary to FTIR and XRF, as to the cause of the splicing tape adhesion problem on the issue PET films, the manufacturer of the defective material rejected the XPS analytical conclusions based on the claim that they had never heard of XPS! The way in which this contentious dispute was eventually settled will be described in this presentation. This presentation demonstrates the importance of always using a multi-technique approach for characterizing material surfaces as well as the consequences of choosing the correct technique(s) to best solve the problem at hand.

11:00am AS-TuM-13 Investigations of the Solid-Electrolyte Interface in an All-Solid-State Battery Using ToF-SIMS, *Gabriel Parker², Chanho Kim, Yaunshun Li, Guang Yang, Xiao-Ying Yu*, Oak Ridge National Laboratory, USA

All solid-state batteries are a rapidly expanding field with complex formations of both the anode and cathode materials. Solid-state lithium sulfur batteries provide increased energy storage and improved safety. In this presentation, we investigate the composition and formation of the solid electrolyte interface (SEI) for pristine and cycled sulfur-based solid-state batteries. We compare two sulfide solid state electrolyte, namely, Li₆PS₅Cl (LPSCL) and Li₁₀GeP₂S₁₂ (LGPS). The cathode material composition is LiNi_{0.8}Mn_{0.1}Co_{0.1}O₂ (NMC811). These nickel rich layered oxides provide

¹ AVS Nellie Yeoh Whetten Awardee

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² AVS Graduate Research Awardee

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contributions to energy storage and act as the active material offering high capacitance and voltage while the sulfide solid state electrolyte offers increased ionic conductivity. Time-of-flight secondary ion mass spectrometry (ToF-SIMS) was used to acquire surface spectra, depth profiles, 2D secondary electron (SE) images, and secondary ion 2D/3D images of the SEI. SIMS spectra and images were gathered using the 30 keV Bi_3^+ primary ion beam over a $500 \times 500 \mu\text{m}^2$ area for 60 scans. Depth profiles were obtained using the 2 keV Cs^+ sputter beam and 30 keV Bi_3^+ primary ion beam over a $100 \times 100 \mu\text{m}^2$ area for 250 scans. Sulfur clusters (S_x) were observed, which were attributed to the deformation of the cathode surface after cycling. The mass spectral analysis and 2D/3D results imaged the SEI with formation of sulfates, phosphates and fluorine compounds. Comparisons of the LPSCL and LGPS in spectral analysis and 2D/3D imaging illustrate that LPSCL has higher counts of SEI formation products as well as indication of bubbling on the surface. In contrast, LGPS has pitting. Our results show that ToF-SIMS can uncover the mechanistic differences in SEI formation of all solid-state batteries.

Keywords: Solid-state batteries, solid-electrolyte interface, ToF-SIMS, sulfide solid-state electrolyte, imaging.

11:15am AS-TuM-14 Study of the Solid Electrolyte Interface Formation at Hard Carbon Electrodes in Sodium-Ion Batteries, David Schaefer, Justus Liebig University Giessen, Germany; Sven Daboss, Christine Kranz, Ulm University, Germany; Marcus Rohnke, Justus Liebig University Giessen, Germany

The performance and lifetime of sodium-ion batteries (SIBs) is determined by the interplay between material properties and solid electrolyte interphase (SEI) formation and evolution. The SEI enables electrochemical cells to function reliably and protects the cell from uncontrolled degradation.^[1] It is formed primarily from electrolyte reduction products, with its main attributes targeted to be electric insulation, ionic conduction and stability against dissolution in the liquid electrolyte. Although the role of the SEI is recognized in the literature, its formation and evolution are not yet fully understood.^[2]

This study focuses on the formation process and compositional evolution of the SEI on hard carbon composite anodes. The cells contain cyclic ester-based electrolytes including the additive fluoro ethylene carbonate and sodium metal counter electrodes. Morphological, chemical and electrochemical analyses were conducted at different sodiation potentials vs. Na^+/Na (unsodiated, 1.2 V, 0.9 V, 0.6 V, 0.2 V, 0.01 V) during the first half cycle, as well as during desodiation (0.3 V, 1.3 V, 2.0 V) until the end of the first full cycle by scanning electron microscopy (SEM), time-of-flight secondary ion mass spectrometry (ToF-SIMS) and scanning electrochemical microscopy (SECM).

Starting from smooth particle surfaces in the pristine state, SEM revealed roughening during sodiation indicating SEI formation. Various visual representations of the SEI were obtained, showing a pox-, or bubble-like morphology. ToF-SIMS analysis revealed chemical differences at the surfaces between samples at different sodiation stages. An SEI consisting of the components Na_2O , NaOH , Na_2CO_3 and NaF with different compositions was observed by ToF-SIMS analyses of electrode surfaces, while oxidic components only seem to appear upon increased sodiation of the hard carbon composite electrode. Interestingly, the surface seems to have lost almost all oxidic residues after desodiation up to 2.0 V vs. Na^+/Na and regained sodium fluoride as the major residue salt component.

Information about changes in the electrochemical activity at the surfaces of the electrodes was obtained by SECM. Whereas pristine hard carbon particles are conductive and show a positive feedback signal this drastically changes upon formation of the SEI, hindering electron transport, which yields in a significant decrease in the electron transfer rate and a shift from positive to negative feedback response.

[1] J. Fondard, E. Irisarri, C. Courrèges, M. R. Palacin, A. Ponrouch, R. Dedryvère, *J. Electrochem. Soc.* **2020**, 167, 070526.

[2] J. Sun, I. E. Gunathilaka, L. A. O'Dell, P. C. Howlett, M. Forsyth, *J. Power Sources* **2023**, 554, 232298.

11:30am AS-TuM-15 Surface Sensitive Chemical Imaging of Lithium Materials for Battery Applications by Auger Electron Spectroscopy, Juergen Scherer, Physical Electronics USA; Masahiro Terashima, Kazutoshi Mamiya, Shin-ichi Iida, ULVAC-PHI, Japan

Interest in all-solid-state batteries (ASSBs) has been increasing due to their higher safety, energy density, and longer lifespan compared to conventional

lithium-ion batteries (LIBs). However, the internal resistance generated at the interface between the solid electrolyte (SE) and the electrode is a challenge for the practical use of ASSBs as it hinders fast charging and discharging. Several studies have been conducted to reduce the internal resistance through various surface modifications between the SE and cathode, which has led to a significant improvement in Li ion transport during charge and discharge. Despite the numerous studies on the SE/cathode interface of ASSBs, the mechanism behind the increase in interfacial impedance remains unclear.

In this study, we focus on lithium chemical mapping of the cross-section of the SE/cathode interface using Auger electron spectroscopy (AES). AES provides high spatial resolution information on chemical composition and state. The thickness of the anode, SE, and cathode layers in thin-film ASSBs is usually in the range of a few micrometers, making AES an ideal technique for obtaining chemical maps from solid-solid interfaces. Moreover, AES is more sensitive to changes in the lithium chemical state than X-ray photoelectron spectroscopy (XPS). However, it is well known that SEs are generally vulnerable to electron beam damage, and there are few reports on the application of AES in lithium mapping on SEIs.

We examine the electron beam damage on the surface of lithium phosphorus oxynitride (LiPON) as a model SE. The goal is to find the optimum conditions for AES lithium chemical mapping. To achieve this, the impact of electron beam damage on the LiPON surface was investigated. The results showed that the intensity of the LiPON peak was influenced by the beam energy, electron dose, and sample temperature. In conclusion, it was found that the optimal conditions for acquiring a lithium map are at room temperature using 3 keV electrons with a lower beam current.

With the optimum conditions, AES chemical mapping from the SE/cathode cross-section was conducted. Despite the challenges associated with lithium mapping using an electron beam, the study was successful in differentiating between the distributions of different chemical states of lithium in the form of LiPON and LiCoO_2 . This was achieved through optimizing the beam energy, electron dose, and sample temperature. The results provide valuable insights into the lithium chemical distributions at the SE/electrode interface and contribute to a deeper understanding of the behavior of ASSBs at this interface.

11:45am AS-TuM-16 Chemical and Elemental Analysis of Annealed Porous Transport Electrodes via X-ray Photoelectron Spectroscopy, Lonneke van Eijk, Jayson Foster, Colorado School of Mines; Lei Ding, Weitian Wang, Feng Yuan Zhang, University of Tennessee Knoxville; Adam Paxson, PlugPower; Svitlana Pylypenko, Colorado School of Mines

Optimization of proton exchange membrane water electrolyzers (PEMWs) is crucial for ensuring commercially competitive green hydrogen generation and facilitating the societal transition toward increased green hydrogen adoption. Current efforts focus on improving catalyst activity and stability by optimizing Ir oxide-based catalysts and developing alternative materials. Additionally, research aims to enhance catalyst layer (CL) structures and integrate them effectively with the titanium-based porous transport layer (PTL), which often includes a protective platinum coating. This work focuses on development of porous transport electrodes (PTEs) that integrate mixed iridium-ruthenium oxide (IrRuOx) catalysts with Pt-coated titanium PTL. The complexity of the PTEs requires a multi-technique characterization approach that combines electron microscopy methods with X-ray photoelectron spectroscopy (XPS) for surface analysis and time-of-flight secondary ion mass spectrometry (ToF-SIMS) for surface and interface characterization.

This presentation will discuss XPS analysis of porous transport electrodes (PTEs) featuring IrRuOx catalysts that were subjected to various post-treatments involving annealing in different environments. The aim is to investigate how these parameters influence the material's composition and structure, and their respective impact on electrochemical properties. Emphasis is placed on the complexities of characterizing Ir-based materials, with detailed attention to the Ir 4f, Ru 3d, and O1s spectral regions. Due to difficulty of analysis of Ir 4f spectra, various fitting methodologies for O1s spectra were evaluated. It was found that some cases require detailed fitting analysis, while in other cases, basic metrics like binding energy and full width at half maximum (FWHM) are effective in capturing trends that are directly related to catalytic activity and stability. Additionally, XPS-derived metrics were correlated with electrochemical performance using Principal Component Analysis (PCA), highlighting patterns within complex data. These results advance our understanding of XPS analysis of complex catalysts, emphasize the importance of thorough and careful analysis, and

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highlight opportunities for combining simple metrics with multivariate analysis for the development of energy materials.

12:00pm AS-TuM-17 X-Ray Photoelectron Spectroscopy Challenges: Practical Solutions to Peak Overlap in Battery Electrodes and Catalysts, Lyndi Strange¹, Pacific Northwest National Laboratory; Donald Baer, Mark Engelhard, Pacific Northwest National Lab

X-ray photoelectron spectroscopy (XPS) is crucial for analyzing battery materials and catalytic systems. Several studies have indicated that XPS analyses in the literature exhibit significant analysis flaws. One sometimes subtle but remarkably significant issue occurs when a minor peak significant component in a sample overlaps with a peak of interest and importance from an element of interest. This is particularly true with the amount of chemical state of “active” elements at lower concentration are the desired information. This talk highlights peak overlap issues that have been observed in our laboratory. We have focused attention on an often-overlooked F Auger overlap in Ni 2p spectra, relevant to battery anodes. This overlap occurs in many battery electrodes which because of the materials involved have complex photoelectron structures, including simpler elements like Li and F but also a variety of transition metals. We discuss challenges in XPS analysis of Li and nickel–manganese–cobalt (NMC) battery electrodes. Lithium analysis faces preparation challenges and peak overlap with F. New XPS users often overlook the interference of the FKLL Auger signal with the Ni 2p spectrum generated by AlK α X-rays in NMC electrodes. Simulated spectra of F and NiO demonstrate the extent of F Auger contributions to the Ni 2p signal, depending on the F/Ni atom ratio. This suggests how significant these effects are on the resultant spectra. Our analysis shows that overlap issues are significant for real electrode materials. We will also note other examples of peak interferences in quantification including the overlap of Ru 3d and C 1s in catalysts materials and how photoelectron structure from a TiO₂ support influence Pt 4f quantification for catalytic and energy conversion materials.

Spectroscopic Ellipsometry

Room 209 F W - Session EL-TuM

Spectroscopic Ellipsometry Analysis Methods

Moderators: Tino Hofmann, University of North Carolina at Charlotte, Marcel Junige, University of Colorado at Boulder

8:00am EL-TuM-1 Crystal Symmetry and Spectroscopic Ellipsometry, Gerald Jellison, Oak Ridge National Laboratory INVITED

Of the known crystals, over 90% are optically anisotropic and therefore birefringent. That is, the complex dielectric function depends on the polarization of the incident light and the orientation of the crystal. The general linear dielectric response for non-magnetic materials is expressed as a complex 3×3 symmetric tensor. This tensor can be simplified if the crystal is oriented in the laboratory reference frame, where uniaxial, orthorhombic, and monoclinic crystals require 2, 3, and 4 independent complex elements, respectively. Isotropic materials require only 1 element. Triclinic materials have no symmetry other than translation, so their dielectric tensors have 6 independent elements.

These dielectric functions are best measured by generalized or Mueller matrix ellipsometry [1]. If there is no depolarization, then the ellipsometric data can be reduced to the 2×2 reduced Jones matrix ρ where $\rho_{pp} = \rho_{pp}/\rho_{ss}$, $\rho_{sp} = \rho_{sp}/\rho_{ss}$ and $\rho_{ps} = \rho_{ps}/\rho_{ss}$. For isotropic materials, $\rho_{pp} = \tan(\psi)\exp(i\Delta)$, where ψ and Δ are the standard ellipsometric angles. The cross-polarization terms ρ_{sp} and ρ_{ps} will be non-zero if the coordinate system of the crystal does not match the coordinate system of the ellipsometer, defined by the plane of incidence. For uniaxial crystals, the cross-polarization terms will be zero if the optic axis is in or perpendicular to the plane of incidence. For orthorhombic and monoclinic crystals, the cross-polarization terms will be zero if a principal axis is perpendicular to the plane of incidence. Even when the cross-polarization terms are non-zero, there are some orientations of the crystal where ρ_{sp} and ρ_{ps} will be symmetric. If the optic axis of a uniaxial crystal is in the sample surface plane ($\Theta = 90^\circ$), then $\rho_{ps}(\phi) = -\rho_{sp}(\phi)$, $\rho_{ps}(\phi) = -\rho_{ps}(-\phi)$, and $\rho_{sp}(\phi) = -\rho_{sp}(-\phi)$, where the Euler angle ϕ is the angle of the optic axis with respect to the plane of incidence.

This talk will discuss the symmetry relationships for uniaxial, orthorhombic, and monoclinic crystals and will show spectroscopic generalized

ellipsometry data taken from several anisotropic crystals. Example crystals may include: rutile and anatase (TiO₂), ZnO, calcite and aragonite (CaCO₃), dolomite [CaMg(CO₃)₂] zinc oxide (ZnO), tin oxide (SnO₂), and paratellurite (a-TeO₂).

[1] G. E. Jellison, Jr., N. J. Podraza, and A. Shan, “Ellipsometry: dielectric functions of anisotropic crystals and symmetry,” *J. Opt. Soc. Am. A* **39**, 2225 (2022).

8:30am EL-TuM-3 Ellipsometric Reality Check: Are My Results Correct?, Maxwell Junda, Covalent Metrology

Covalent Metrology offers a large range of analytical measurement techniques (150+) and uses these to support scientists and engineers in solving demanding problems across many different industries. There is often tremendous value in combining multiple measurement techniques on a sample to obtain complementary material property information. This provides a fuller understanding of the materials of interest. However, sometimes when spectroscopic ellipsometry (SE) is used in conjunction with other metrology, the corresponding results don’t match. This often opens a Pandora’s Box of questions about the source of the mismatch and which result is “right.” Similarly, even when evaluating ellipsometry results by themselves, the widely varying needs of each application require careful handling of how SE data is modeled and results are interpreted.

As an example, one Covalent customer is fabricating waveguides. Accuracy in our measurements of dimensions and thickness of the waveguide materials is *critically important* since these waveguides are designed to operate at a specific wavelength which defines the required dimensions. Cross sectional transmission electron micrographs (TEM) are also used to measure dimensions which, with surprising frequency, differ from best-fit SE results by a nontrivial margin. As a further complication, using TEM-derived thicknesses as fixed parameters in the SE modeling results in unacceptably poor model fits. This mismatch has necessitated investigation into properties at the interfaces that are detectable by SE, but not TEM.

By contrast, another Covalent customer is using routine SE measurements for process monitoring. Here, the repeatability of SE measurements (i.e. precision) is most important to track the deposition process over time and overall accuracy of the results is secondary. This represents a completely different use-case for ellipsometry where establishing a standardized measurement and modeling methodology for detecting deviations dominates, potentially even over accurate measurement results.

Lastly, specific choices for optical modeling configurations always have tradeoffs between physical realism, sensitivity, and practical utility. Some models are developed to accommodate gross spatial nonuniformities in films on 300mm wafers, whereas others are created to detect weak absorption modes in the infrared when paired with transmittance measurements. Although all are fundamentally based on the information encoded within SE data, the optical models used to obtain final results are unavoidably context-dependent.

8:45am EL-TuM-4 Spectroscopic Ellipsometry Based on Frequency Division Multiplexing, Jongkyoon Park, KRISS, Republic of Korea

Spectroscopic ellipsometry (SE) is a widely utilized technique in optical metrology, particularly in the semiconductor industry, for its ability to measure thin-film thickness non-destructively and with sub-nanometer precision. Various types of SE have been developed, each type offering unique strengths and limitations, making the selection of an appropriate technique crucial for specific applications. Here, we experimentally and theoretically demonstrate a novel SE technique based on frequency division multiplexing (see Fig. 1), which we call Frequency Division Multiplexing Spectroscopic Ellipsometry (FDM-SE) [1,2].

FDM-SE is a variant of traditional rotating polarizer ellipsometry (RPE) in which the broadband light source is replaced with multiple discrete-wavelength intensity-modulated laser diodes (LDs) (see Fig. 2). This modification enables obtaining the optical properties of materials at multiple wavelengths simultaneously by using a spectrally integrating detector instead of a spectrometer.

In order to assess the performance of FDM-SE method, SiO₂ films on a Si wafer with different film thicknesses were measured by FDM-SE and a commercially available conventional SE instrument. We obtain a difference between the measured thicknesses with both methods of less than 5 Å on average implying that FDM-SE can be used for accurate thickness measurements. Thus, the proposed FDM-SE technique provides a novel alternative SE approach for a variety of optical metrology applications.

¹ JVST Highlighted Talk

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9:00am **EL-TuM-5 Advanced Electromagnetic Modeling Techniques for Metamaterial Platforms, Ufuk Kilic**, University of Nebraska-Lincoln, USA
INVITED

Nanostructured metamaterials play a crucial role in cutting-edge applications spanning optoelectronics, quantum information processing, and biomedical technologies [1-3]. Precise characterization of their structural and optical properties is essential for their effective integration into functional systems. The conventional spectroscopic ellipsometry (SE)-based optical characterization faces inherent limitations. SE is largely constrained to far-field analysis and relies on idealized layer-based models, making it insufficient for complex nanostructures with pronounced near-field interactions, strong nonlocal effects, and wavevector-dependent material responses.

In this talk, to overcome these challenges, we leverage the finite element modeling (FEM) based theoretical characterization, optimization, and verification technique which basically relies on the frequency dependent full-wave electromagnetic solutions of Maxwell's equation [3]. FEM provides a powerful framework for directly visualizing electromagnetic field distributions, incorporating experimental inputs from imaging techniques such as scanning electron microscopy and transmission electron microscopy, and refining optical models through spectroscopic ellipsometry-based dielectric function analysis. By enabling precise modeling of both near- and far-field interactions, as well as capturing nonlocal material responses that go beyond standard effective medium approximations, FEM pushes the boundaries of conventional characterization techniques. This deeper understanding of light-matter interactions is essential for advancing photonic, optical, and quantum materials, enabling next-generation applications.

References:

- [1] Carneiro, S. V., et al., *Materials Today Nano* 22 (2023): 100345.
- [2] Kilic, U., et al., *Advanced Optical Materials* (2024): 2302767.
- [3] Kilic, U., et al., *Nature communications* 15.1 (2024): 3757.

9:30am **EL-TuM-7 Evaluation of Scatterometry for High Aspect Ratio Deep Trench Monitoring: A Rigorous Coupled-Wave Analysis Approach, Martial Santorelli, Justine Grasland, Delphine Le Cunff, ST Microelectronics, France; Marceline Bonvalot, Laboratoire des Technologies de la Microélectronique, CNRS-LTM, France; Madec Querré, ST Microelectronics, France; Jean-Hervé Tortai, Laboratoire des Technologies de la Microélectronique, CNRS-LTM, France**

In the ongoing development of extreme miniaturization, gapfilling processes are truly challenged for High Aspect Ratio (HAR) 3D structures, whereby seam and void formation can occur. An in-depth characterization of such processes requires specific in-line, statistical, non-destructive and robust metrology solution, enabling accurate evaluation of filling quality. Optical scatterometry emerges as a promising technique, proven effective for characterizing empty HAR deep trench while lack of sensitivity has been shown when increasing depth and top film stack complexity [1], [2]. Scatterometry Mueller matrix formalism aptly describes the optical behavior of periodic grating structures. However, linking these matrix coefficients to physical properties remains challenging due to the variety of potentially impacting factors in complex HAR structures (film stack and geometry parameters). To overcome this limitation, Rigorous Coupled-Wave Analysis (RCWA) provides a powerful simulation framework that enables the interpretation of changes in matrix elements by leveraging the flexibility of parametric modeling combined with extensive computational capabilities [3].

Our study firstly focuses on characterizing HAR deep trenches prior to gapfilling (Figure 1a). We propose an RCWA-based methodology to analyze the influence of structural parameters, such as film thickness and trench dimensions, on key Mueller matrix elements (m_{12} , m_{33} and m_{34}). A Global Sensitivity Analysis (GSA) using Sobol indices isolating the impact of trench dimensions highlights the parameter effects in the infrared IR wavelength range. This sensitivity shifts to high IR wavelength range for deep trenches ($> 4 \mu\text{m}$), where the IR response becomes more influenced by trench slope (Figure 2). Subsequently, a comprehensive GSA including all input parameters enables model simplification by determining non-sensitive inputs from the top film stack. Instead of solving an inverse problem, experimental parameters have been extracted by selecting the closest matching response from a generated library. Gapfilling is then modeled by varying void size and position in the trench (Figure 1b-d). The rigorous pre/post gapfilling approach quantifies the influence of filling defects on the infrared spectrum while minimizing variability from other inputs. Our

results demonstrate that buried voids (Figure 1c) have a slight effect on the amplitude and phase of IR oscillations, whereas partial filling (open voids, Figure 1d) significantly impacts first the frequency and then the phase in the IR range. Such defects may be detectable in the infrared spectrum when appropriate signal processing techniques are applied.

Electronic Materials and Photonics

Room 207 A W - Session EM1+AP+CPS+MS+PS+QS+SM+TF-TuM

Emerging Frontiers in Quantum Materials and Devices

Moderator: Mollie Schwartz, MIT Lincoln Laboratory

8:30am **EM1+AP+CPS+MS+PS+QS+SM+TF-TuM-3 Rapid, Atomic-Scale Smoothing of GaSb(111)A Surfaces During Molecular Beam Epitaxy, James Rushing, Paul Simmonds, Tufts University**

InAs/Ga(In)Sb quantum wells (QWs) with a broken gap band alignment can behave as a quantum spin hall insulator (QSHI) with an insulating bulk and topologically protected helical edge states [1-2]. QSHIs could be a key component in spintronic and topological quantum computing applications [2-3]. Producing a topological phase transition in InAs/Ga(In)Sb QWs requires precise control of QW thickness, composition and quality, particularly at the heterointerfaces. Additionally, our calculations suggest QWs grown on (111) surfaces could provide benefits over (001) due to the higher symmetry and out-of-plane polarization effects of this surface.

While exploring the MBE growth of InAs/Ga(In)Sb QW heterostructures on GaSb(111)A, we discovered an exciting and confounding phenomenon that seems to be unique to crystal growth on III-Sb(111)A surfaces. Ga(In)Sb(111)A frequently exhibits an extremely rough morphology characterized by pyramidal peaks covering the entire surface. We show that rough III-Sb surfaces (pyramidal features $> 70\text{nm}$ in height; rms roughness $> 10\text{nm}$), can be smoothed to atomically flat surfaces ($< 3\text{nm}$ height features; $< 0.5\text{nm}$ rms roughness) in a matter of seconds by exposing them to an arsenic over-pressure. We first observed this phenomenon when rough GaInSb(111)A surfaces became atomically flat after capping with just 8nm of InAs. After reducing the thickness of this InAs layer to a single monolayer and still observing the same surface smoothing effect, we found that we could achieve almost identical results by simply exposing the rough GaSb(111)A to an arsenic flux. These results suggest that arsenic is the primary mover in these profound morphological changes. Our recent results show that the smoothing can be accomplished with As₄ or As₂, and with a wide range of arsenic beam equivalent pressures, from 5×10^{-7} to 1×10^{-5} Torr.

We will describe our efforts to gain control and understanding of this phenomenon through the modulation of arsenic exposure time, flux, and terminating III-Sb material. This powerful new MBE technique will allow us to reliably achieve smooth heterointerfaces in (111)-oriented InAs/Ga(In)Sb QWs for novel, high-quality QSHIs. More broadly, we believe that this approach will enable the growth of a wide array of III-Sb-based nanostructures on (111)A surfaces for other electronic and photonic applications.

1. Krishtopenko and Teppe. *Science Advances* 4, eaap7529 (2018)
2. Avogadri et al. *Physical Review Research* 4, L042042 (2022)
3. Du et al. *Physical Review Letters* 119, 056803 (2017)

8:45am **EM1+AP+CPS+MS+PS+QS+SM+TF-TuM-4 Benchmarking Different NbTiN Sputtering Methods for 300 mm CMOS-compatible Superconducting Digital Circuits, Adham Elshaer¹, Jean-Philippe Soulié, Daniel Perez Lozano, Gilles Delie, Ankit Pokhrel, Benjamin Huet, IMEC Belgium; Margriet J. Van Bael, KU Leuven and Imec, Belgium; Daan Buseyne, KU Leuven, Belgium; Blake Hodges, Seifallah Ibrahim, Sabine O'Neal, Imec USA; Zsolt Tökei, Imec Belgium; Anna Herr, Quentin Herr, Imec USA**

The NbTiN films presented here are CMOS-compatible and were developed for metallization purposes in superconducting digital circuits [1-5]. Those circuits use NbTiN for Josephson junctions and capacitors electrodes, as well as for wiring. Superconducting digital circuits initially relied on Nb in the early days. NbTiN is a better candidate/replacement due to its higher thermal budget and better chemical stability [1-5]. In this study, the properties of superconducting NbTiN thin films deposited using two

¹ JVST Highlighted Talk

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different sputtering methods have been compared. One method used multiple targets (MT) co-sputtering (Nb and Ti targets), while the other used a NbTi single target (ST). Benchmarking metrics used for comparison include: superconducting, electrical, as well as morphological properties. All films show a high T_c , ranging from 13.3 K to 15.1 K. Compared to MT, ST NbTiN films showed consistently lower resistivity and better sheet resistance (R_s) wafer-level uniformity (49 points wafer-map). For instance, 50 nm MT film had a R_s relative standard deviation (Stddev%) of 15.5%, while for the ST NbTiN films, R_s Stddev% showed a 2-fold improvement at 7.8%. Upon annealing of the ST NbTiN films at 650°C, the R_s uniformity further improved, reflected by a lower Stddev% at 4.5%. AFM data show similar results for MT and ST films, ~1.07 nm and 1.09 in the center and 0.73 nm and 0.71 nm at the edge of the wafers, respectively. Furthermore, XRD theta-2theta scans have been performed showing the 200 and 111 peaks for NbTiN orientations. Results show that the MT and ST films have different/signature 200/111 peak intensity ratios for the as deposited films. ST NbTiN films have a lower 200/111 peak ratio. However, after annealing at 650°C, the ST films 200/111 peak ratio increases, and surpasses that of the MT NbTiN films. This change suggests a change in the ST film disorder and grain size after annealing. The impact of the ST NbTiN film thickness on properties has also been studied. The T_c shows an increase as a function of thickness, from 9.6 K for 7 nm, to 14.3 K for 50 nm, up to 14.9 K for 200 nm films. Certainly, the ability to tune the superconducting properties of NbTiN, makes them appealing from a stack engineering perspective. Both MT and ST NbTiN properties can be tailored using deposition conditions such as: power, partial pressure and post deposition annealing [3]. However, MT NbTiN films 300 nm wafer-level R_s non-uniformity represents a limiting factor for scaling superconducting devices. Annealed NbTiN ST films on the other hand, show a 3.4-fold R_s wafer uniformity improvement while maintaining properties tunability.

9:00am **EM1+AP+CPS+MS+PS+QS+SM+TF-TuM-5** **Controlling the Properties of Epitaxially Grown Topological Semimetals, Kirstin Alberi, National Renewable Energy Laboratory** **INVITED**

Three dimensional topological semimetals (TSMs) exhibit a wide range of interesting properties, including high carrier mobility, large magnetoresistance, anomalous transport behavior, broadband optical absorption and non-linear optical responses. Epitaxial thin film synthesis offers a practical platform for manipulating composition, defects and disorder in these materials, offering a window into approaches for manipulating their properties. In this talk, I will discuss insights into the relationships between structure and composition and the resulting properties revealed through careful control of growth conditions. Focused examples include the impact of point defects and impurities on electron transport in the Dirac TSM Cd_3As_2 and the formation and behavior of domain boundaries in the Weyl TSM TaAs.

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9:30am **EM1+AP+CPS+MS+PS+QS+SM+TF-TuM-7** **Photon Down-Conversion of Yb-Doped $CsPb(Cl_{1-x}Br_x)_3$ to Low-bandgap Metal Halide Perovskites, Yutong Ren¹, Princeton University; Igal Levine, The Hebrew University of Jerusalem, Israel; Dan Oron, David Cahen, Weizmann Institute of Science, Israel; Antoine Kahn, Princeton University**

Quantum cutting represents a transformative strategy to mitigate thermalization losses that typically occur when high-energy photons are absorbed by semiconductors.^{1,2} Recent advances have extended this concept from rare-earth doped crystals to semiconductor-rare-earth hybrid systems, particularly those utilizing halide perovskite absorbers, thereby exploiting their exceptional optoelectronic properties.

In this study, we focus on Ytterbium (Yb) -doped $CsPb(Cl_{1-x}Br_x)_3$, a metal halide perovskite that absorbs visible light and exhibits intense near-infrared (NIR) photoluminescence—a clear signature of efficient quantum

cutting. Upon excitation with visible light, the doped perovskite converts the absorbed energy into two NIR photons, with the emission energy closely matching the optimized bandgap of a Sn-Pb based perovskite absorber. This spectral alignment is critical for enabling effective energy transfer between the quantum cutting layer and the absorber.

Our investigation focuses on elucidating the structural and electronic properties of the interfaces between Yb-doped $CsPb(Cl_{1-x}Br_x)_3$ and Sn-Pb based perovskite films. By employing a suite of advanced spectroscopic techniques—including ultraviolet photoelectron spectroscopy, inverse photoemission spectroscopy, time-resolved photoluminescence (tr-PL), and time-resolved surface photovoltage (tr-SPV)—we systematically examine how the quantum cutting layer, the absorber layer, and their interfacial region collectively influence energy transfer efficiency. In particular, the complementary tr-PL and tr-SPV analyses unambiguously determine the dominant interfacial charge transfer and recombination processes, and thus gain control over the interfacial charge transfer. By integrating Yb-doped $CsPb(Cl_{1-x}Br_x)_3$ with customized Sn-Pb perovskite absorbers, our approach shows promise for pushing the boundaries of conventional efficiency limits while also offering a cost-effective strategy for enhanced energy conversion.

1. Wegg, R. T. et al. Quantum cutting through downconversion in rare-earth compounds. *J. Lumin.* **87-89**, 1017–1019 (2000).
2. Kroupa, D. M. et al. Quantum-cutting ytterbium-doped $CsPb(Cl_{1-x}Br_x)_3$ perovskite thin films with photoluminescence quantum yields over 190%. *ACS Energy Lett.* **3**, 2390–2395 (2018).

9:45am EM1+AP+CPS+MS+PS+QS+SM+TF-TuM-8 Molecular Beam Epitaxy Growth of $InAs_{1-x}Bi_x$ on GaSb for Topological Insulating States, Merve Baksi, James Rushing, Xikae Xie, Avery Hanna, Larry Qui, Ekow Williams, Paul J. Simmonds, Tufts University

Incorporation of bismuth (Bi) into III-V semiconductors has attracted significant interest not only for its ability to extend infrared optoelectronic applications across a wide spectral range but also for its potential to induce topologically protected surface states, which could form the foundation for certain quantum computing technologies [1].

Motivated by the small inverted band gap that can be induced in InAs/GaSb quantum wells (QWs) [2], we propose engineering the band structure and inducing the edge states through Bi incorporation into InAs layers. This enhancement is expected to improve robustness against thermal fluctuations, making the material viable for room temperature applications as opposed to the topological HgTe/CdTe QW system with a temperature dependent band gap [3].

Theoretical studies predict that $InAs_{1-x}Bi_x$ quantum wells exhibit a topological insulating state when the Bi composition reaches $x \approx 0.15$, with an estimated inverted gap of approximately 30 meV [1]. Given these predictions, InAsBi emerges as a promising candidate for realizing two-dimensional topological insulators (2D TIs). However, achieving such high Bi incorporation remains challenging due to the significant miscibility gap and the limited solubility of Bi in III-V materials [4].

In this work, we investigate the molecular beam epitaxy (MBE) growth of InAsBi on GaSb substrates, focusing on optimizing Bi incorporation and structural quality. By leveraging MBE growth techniques, we aim to systematically control Bi incorporation and assess its impact on electronic and structural properties of InAsBi in reduced dimensions. Our findings will contribute to the advancement of III-V-based topological materials and their potential integration into future quantum devices.

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¹ JVST Highlighted Talk

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Electronic Materials and Photonics

Room 207 A W - Session EM2+AP+QS+TF-TuM

Evolution of Materials and Devices for Energy Harvesting and Conversion

Moderators: Seth King, University of Wisconsin - La Crosse, Parag Banerjee, University of Central Florida

11:00am **EM2+AP+QS+TF-TuM-13 Structural and Electronic Properties of CdSexTe_{1-x} /CdTe thin-film photovoltaic devices: Carrier Dynamics Analysis by Charge Carrier Collection Efficiency, Philip (Sanghyun) Lee, University of Kentucky; Kent Price, Morehead State University**

Polycrystalline Cadmium Telluride (CdTe) thin-film solar cells are among the most successful commercial thin-film solar technologies, achieving a record cell efficiency of nearly 23.1% and offering competitive module costs compared to silicon (Si) modules. More than 20 GW of CdTe modules have been installed worldwide. Laboratory-scale tests have even surpassed 23.1%, getting closer to the theoretical Shockley-Queisser limit of about 32%. Recent research has focused on integrating selenium (Se) into CdTe absorbers to create band grading without the use of CdS window layers. The compound CdSexTe_{1-x} has emerged as a key candidate for enhancing the short-circuit current (J_{sc}) by lowering the bandgap below 1.45 eV, which could help push short-circuit-current (J_{sc}) closer to its theoretical limits.

In this study, we fabricated CdSexTe_{1-x}/CdTe devices with vapor transport technology (VTD) and characterized the structural chemistry and electronic properties of CdSexTe_{1-x}/CdTe devices from the carrier collection dynamics perspective. The device structure is CdSeTe/CdTe absorbers on TEC-10 glass coated with fluorine-doped tin oxide (SnO₂:F), and finished with Gold back metal contact to minimize the impact of unwanted back contact Schottky barrier on carrier dynamics. The devices were treated under Cl₂ ambient at 480 °C for grain recrystallization and grain boundary passivation. Selenium (Se) diffuses deeper into the CdTe film to form CdSeTe. The device was then assessed using cross-section using Scanning Transmission Electron Microscopy (STEM) coupled with Energy dispersive X-ray analysis (STEM-EDX) in addition to evaluating device performance and characteristics. The carrier collection is measured by quantum carrier collection efficiency. The results indicate that Se uniformly diffused into CdTe grains, forming CdSeTe, which effectively lowers the bandgap energy to 1.41 eV, which is 40 mV lower than our initial calculation (1.45 eV), which increased photocurrent to 28.66 mA/cm². The Se concentration is approximately 5-7 %, incorporated into the front interface of CdSexTe_{1-x}/CdTe films. From the carrier dynamics analysis, the total loss of charge carrier collection is 19.6%, as compared to ideal charge carrier collection at the front heterojunction of CdSexTe_{1-x}/CdTe. This indicates that there is room to further improve charge carrier collection to achieve higher photocurrent and, thus, efficiency. The UV and violet light charge collection is 5.46 mA/cm², whereas the red light charge collection is 4.37 mA/cm². The most charge collection occurs at in-between wavelengths as 18.71 mA/cm².

11:15am **EM2+AP+QS+TF-TuM-14 Analysis of KNbO₃ Crystal Structure Fabricated on LiNbO₃ and LiTaO₃ Substrate for Piezoelectric Sensors and Devices Applications, LAY THITHI, Asuki Hagiwara, Ryotsuke Arai, Josai University, Japan**

Recently, small scales energy harvester with clean energy sources are in demand for various portable sensors and electronics devices [1]. Piezoelectric materials such as KNbO₃ are in focus for new type of sensors and electronic materials due to its high piezoelectric properties, high curie temperature around 450°C as well as lead free for environmental hazard compared to lead zirconate titanate PZT [2-3]. On the other hand, piezoelectric crystal such as lithium niobate (LiNbO₃) and lithium tantalate (LiTaO₃) also have been widely used in electronic and communication devices because it has high electro-optical properties as well as high curie temperature which is considered as the most important parameter for device performance [4]. In this study, well-ordered KNbO₃ film were synthesis on LiNbO₃, LiTaO₃ single crystals substrate by hydrothermal method aiming for possibility of electro-optical switching devices, energy conversion and other sensing devices.

KNbO₃ (100) and (111) structure epitaxially grown on LiNbO₃ and LiTaO₃ single crystal substrate with various reaction time and conditions. Crystal structure and film thickness were analyzed by SEM and XRD. Grains size ranging from 1-7µm and polycrystalline crystal film with thickness varies 3-10µm were obtained by single reaction. Two different substrates showed different surface morphology and crystal structure to understand lattice

matching KNbO₃ film synthesis on LiNbO₃ and LiTaO₃ which is important for piezo electric properties [5].

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[5] Xiaoyan Liu, Kazuya Terabe and Kenji Kitamura, Stability of engineered domains in ferroelectric LiNbO₃, LiTaO₃, crystals, *Phys. Scr. T129*, 103-107, 2007.

11:30am **EM2+AP+QS+TF-TuM-15 Modelling the Surface Electronic Properties of Catalytic Condenser for Programmable Reactions, Lars Grabow, Shengguang Wang, University of Houston; Kaida Liu, Ulrick Gaillard, University of Minnesota; Rohit Punyapu, Rachel Getman, Ohio State University; Matthew Neurock, University of Minnesota** INVITED

The evolution of catalyst design has progressed from structural control and optimization to dynamic electronic control of active sites for surface chemistry. This advancement enables precise tuning of active sites via potential, light, or strain applied to material surfaces. Catalytic condensers are novel devices that stabilize charge from an applied potential across a high-k dielectric film in a thin top layer of carbon with active sites on metal nanoclusters. This talk examines several computational methods to calculate charge condensation on catalytic condensers and the influence on the adsorption of atomic and molecular species.

The tested methods include direct quantum chemical cluster calculations, charged periodic calculations with homogeneous background counter charge, implicit solvation methods, localized countercharge within the vacuum region, and explicit charge transfer atoms within the vacuum region. Density functional theory (DFT) calculations were employed to evaluate these methods, providing insights into the influence of condensed charge on adsorption and assessing the accuracy and computational requirements of each approach.

The study systematically varied the charge on metal surface atoms from -1 to +1 per atom, calculating binding energies for atomic adsorbates such as H, O, N, and C, as well as the molecular adsorbate CO on ideal single crystal 3d, 4d, and 5d transition metal surfaces, namely Cu(111), Ru(0001), and Pt(111). The applicability of each method was explored by examining the range of systems that can be calculated, computational demands, accuracy of results, and potential pitfalls. Cluster calculations, periodic methods, and implicit solvation models were compared, revealing that charged periodic calculations with homogeneous background counter charge and large vacuum region provided the most practical and computationally efficient results. The study also highlights the role of electric fields versus charge, depicting the extent of polarization of adsorbates from charge density difference plots.

Overall, the choice of method remains a tradeoff between accuracy and computational expense. The findings offer general conclusions about catalytic condensers and contribute to the understanding of electronic control in catalytic surfaces, paving the way for future advancements in programmable catalyst design.

Nanoscale Science and Technology

Room 206 A W - Session NS1-TuM

AI for Material Discovery and Characterization

Moderators: Yongtao Liu, ORNL, Son Le, University of Maryland

8:00am **NS1-TuM-1 Advancing Scanning Probe Microscopy as a Tool for Nanoscale Scientific Discovery with AI, Rama Vasudevan, Ganesh Narasimha, Jawad Chowdhury, Soumendra Bagchi, Yongtao Liu, Oak Ridge National Laboratory** INVITED

Scanning probe microscopy (SPM) methods have been a mainstay of nanotechnology since their inception in the 1980s, helping to image and

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map functional properties of a wide variety of samples, ranging from ceramics to thin films to nanoparticles to biomolecules. More recently, the advent of machine learning and artificial intelligence (AI) has led to an increasing adoption of AI-based methods within core physical sciences.

In this talk, it will be shown how AI can significantly improve SPM in terms of scientific discovery, by adapting AI algorithms and tailoring them for purposes of microscopy characterization and manipulation. Traditional spectroscopic characterization in SPM is carried out in a point by point manner across a grid of points, which is highly redundant. We propose the use of curiosity-based algorithms that can adaptively sample different locations to improve exploration, and boost the robustness of generated structure-function models. The proposed algorithm is trialed on several microscopy platforms and is shown to be superior to random sampling, and is suitable for circumstances when no scalarizer function is available for optimization.

In contrast to materials characterization, where the task is generally purely one of materials prediction, material manipulation requires knowledge of how to act under different environment states, constituting a sequential decision making problem, which is usually formulated as a reinforcement learning problem. This can be solved via traditional policy-based learning methods such as policy-gradient, Q-learning, etc. Here, we show how RL-policies can be learned to manipulate ferroelectric domain structures in thin films, given a surrogate model for domain wall-SPM tip bias interactions, as well as extensions of this RL approach for atomic scale manipulations with other microscopy platforms. This research was supported by the Center for Nanophase Materials Sciences (CNMS), which is a US Department of Energy, Office of Science User Facility at Oak Ridge National Laboratory.

8:30am NS1-TuM-3 Understanding and Controlling Atomic Transformations in 2D Materials Through *in situ* STEM, Raymond Unocic¹, Caitlyn Obrego, North Carolina State University; Kevin Roccapriore, AtomQ; Ayana Ghosh, Oak Ridge National Laboratory; Maxim Ziatdinov, Pacific Northwest National Laboratory; Sergei Kalinin, University of Tennessee Knoxville; Matthew Boebinger, Oak Ridge National Laboratory, USA

The discovery and design of next-generation functional 2D materials demand an atomic-level understanding of how structure and chemistry govern performance. At the nanoscale, where materials are often only a few atomic layers thick, minute structural or chemical changes can trigger profound shifts in electronic, magnetic, optical, and catalytic properties. Unlocking control over these properties requires deep insight into the transformation mechanisms that govern atomic-scale behavior. Scanning transmission electron microscopy (STEM) has emerged as a vital tool due to high spatial resolution imaging, diffraction, and spectroscopy. Recent breakthroughs in *in situ* and *operando* STEM now allow us to go beyond static characterization, opening the door to real-time observation of structural evolution and chemical reactions under dynamic conditions. In this work, we leverage *in situ* STEM to investigate the formation pathways, reaction kinetics, and energy landscapes involved in the synthesis of novel 2D materials. Using controlled heating experiments, we directly visualize the transformation of amorphous precursors into crystalline layered structures, capturing how temperature and electron dose influence nucleation and growth mechanisms at the atomic level. Further, we demonstrate atomic engineering of 2D materials through feedback-controlled electron beam techniques to create targeted defects and nanopores with atomic precision. To deepen our mechanistic understanding, we integrate machine learning tools to analyze transformation dynamics and uncover hidden patterns in atomic-scale behavior. These insights pave the way for predictive control over material design. The presentation will conclude with a forward-looking perspective on how advanced microscopy, paired with machine learning, is redefining the limits of materials discovery - transforming our ability to design and engineer 2D functional materials.

8:45am NS1-TuM-4 Advancing Autonomous Experimentation with Human-AI Synergy and Cross-Platform Integration, Yongtao Liu, Oak Ridge National Laboratory

Advancements in artificial intelligence are rapidly transforming materials research by enabling autonomous experimentation. In this talk, I will present our recent progress in developing automated and autonomous experimentation frameworks that accelerate discovery across diverse materials systems. Our approach integrates computer vision-enabled high-throughput experimentation, AI-powered decision-making, prior

knowledge-guided exploration, and cross-platform co-optimization. By leveraging computer vision, we enable rapid, automated exploration of complex experimental parameter spaces. We further incorporate AI algorithms into experimental loops to perform real-time data analysis and decisions making. A key feature of our framework is the incorporation of expert knowledge and human oversight, enabling context-aware experimentation grounded in physical understanding. Beyond single-platform optimization, we also introduce a cross-platform strategy of autonomous experimentation that enables coordinated operation between synthesis and multimodal characterization tools. This distributed yet collaborative strategy requires no physical integration, offering an approach for autonomous research across diverse research platforms.

9:00am NS1-TuM-5 Nanovision: An Integrated Platform for Two-Dimensional Material Discovery and Device Assembly, Son Le², Jeffrey Schwartz, Laboratory for Physical Sciences; Ruihao Ni, You Zhou, University of Maryland, College Park; Karen Grutter, Aubrey Hanbicki, Adam Friedman, Laboratory for Physical Sciences

Two-dimensional (2D) materials are crucial for enabling next-generation computing, electronics, sensing, and communication technologies. Currently, most breakthroughs in 2D material research rely on atomically thin (few-layer), exfoliated crystals. Frustratingly, identifying candidate crystals typically requires tedious, time-consuming, manual processes performed by trained researchers. This bottleneck severely limits device complexity, fabrication throughput, and overall research efficiency. To address this challenge, we created an integrated hardware and software platform that rapidly and automatically images, identifies, and catalogs exfoliated 2D crystals at full-wafer scales. Our platform enables researchers to visualize and to interact with ultra-high-resolution multimodal images of 2D materials using a web-accessible interface that supports remote operations, promotes data sharing, and enhances researcher productivity. By leveraging artificial intelligence and computer vision strategies, our platform eliminates the need for researchers to engage in tedious visual identification. A working prototype of this platform has helped us to streamline our 2D materials device research while collecting user feedback for continual refinements to our workflow. Moreover, using this platform, we are compiling physical and digital libraries of exfoliated 2D materials with the goal of democratizing access to high-quality materials for researchers. In this presentation, we describe the ongoing development of the hardware, software and control interface used in this impactful materials discovery platform.

Nanoscale Science and Technology

Room 206 A W - Session NS2+2D-TuM

Multimodal Techniques in Surface and Interface Engineering at the Nanoscale

Moderator: Mausumi Mahapatra, Loyola University Chicago

9:30am NS2+2D-TuM-7 Generalized Defect Quantification of 2D Materials with Atomic Force Microscopy, Matthew Rosenberger, University of Notre Dame

INVITED

Routine defect characterization is a critical capability for understanding defect-property correlations and optimizing growth of two-dimensional (2D) materials. High throughput optical methods for defect characterization, such as Raman spectroscopy, are useful for graphene, but are insufficiently sensitive to defects in some other 2D materials, such as transition metal dichalcogenides (TMDs), particularly for defect densities of about 10^{12} cm^{-2} or less. Typical methods for directly detecting defects at the atomic scale, such as scanning transmission electron microscopy (STEM) and scanning tunneling microscopy (STM), are effective, but they are slow and often require arduous sample preparation. There is a need for 2D material defect characterization techniques that are routine, fast, and reliable. Here, we demonstrate two atomic force microscopy (AFM)-based techniques for locating and quantifying atomic-scale defects in 2D materials. First, we show that conductive AFM can locate and differentiate the same defects as STM by comparing conductive AFM and STM on the same region of a TMD crystal¹. Our work establishes conductive AFM as a higher-throughput alternative to STM for defect quantification. Second, we show that lateral force microscopy (LFM) can locate atomic-scale defects through a direct comparison of LFM with conductive AFM on a TMD crystal². Importantly, we show that LFM can locate atomic-scale defects in

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TMD monolayers on insulating substrates and in insulating 2D materials, such as hexagonal boron nitride, because LFM is a purely mechanical technique. The AFM-based methods presented here enable routine defect characterization, which will facilitate rapid investigations of defect-property relationships and speed up the development of new growth processes.

(1) Xu, K.; Holbrook, M.; Holtzman, L. N.; Pasupathy, A. N.; Barmak, K.; Hone, J. C.; Rosenberger, M. R. Validating the Use of Conductive Atomic Force Microscopy for Defect Quantification in 2D Materials. *ACS Nano* **2023**, 17 (24), 24743–24752. <https://doi.org/10.1021/acsnano.3c05056>.

(2) Yang, Y.; Xu, K.; Holtzman, L. N.; Yang, K.; Watanabe, K.; Taniguchi, T.; Hone, J.; Barmak, K.; Rosenberger, M. R. Atomic Defect Quantification by Lateral Force Microscopy. *ACS Nano* **2024**, 18 (9), 6887–6895. <https://doi.org/10.1021/acsnano.3c07405>.

11:00am NS2+2D-TuM-13 Excess Barrier Height Unlocks Andreev Reflection in Scanning Tunneling Microscopy, Petro Maksymovych, Clemson University; Wonhee Ko, University of Tennessee Knoxville; Jose Lado, Aalto University, Finland

Superconductors are currently entering a new golden age, marked by a renewed quest for higher Curie temperature, explosion of new candidate superconducting materials and emerging applications, such as topological quantum computing. However, the foundational questions—whether the material is actually superconducting and what causes superconductivity—remain as pertinent as ever. Indeed, pairing symmetry—a key property of any superconductor—can be a challenging and contested property, even for materials where superconductivity itself is unambiguous.

To this end, we introduced a new approach to detect Andreev reflection (AR) in metal-superconducting contacts of arbitrarily high resistance, most notably in scanning tunneling microscopy (STM). Fundamentally, AR allows the injection of Cooper pairs from a metal to a superconductor, producing excess conductance and a unique sensitivity to the properties of a superconducting state. However, detecting AR in traditional transport measurements requires low (ideally zero) contact resistance —limiting its application to mesoscale and contact geometries. To remove this limitation, we shifted the experimental observable from the excess conductance to the excess height of the tunneling barrier, providing a new approach to detect, probe, and quantify Andreev reflection.

In this talk, I will discuss how tunneling barrier height spectroscopy functions in superconducting junctions and present our recent computational and experimental results on AR-STM with both conventional and unconventional superconductors. The barrier height spectroscopy has a rich structure with combined sensitivity to the pairing symmetry, number of superconducting gaps and the detailed structure of the Fermi surface. Moreover, excess barrier height detects special, higher order Andreev reflection processes, that occur in proximate tunneling junctions just before the collapse of the tunneling barrier. As a result, STM can now leverage the unique power of Andreev reflection to probe superconductivity, magnetism and even topological properties from a new perspective. Research sponsored by Clemson University and US Department of Energy. SPM experiments were carried at the Center for Nanophase Materials Sciences, Oak Ridge National Laboratory, a US DOE User Facility. Song/PM, arXiv: 2411.11724; Ko/PM. *Nano Letters*, **2023** 23 (17), 8310–8318; Song/PM, *Nano Letters* **2023** 23 (7), 2822–2830; Ko/PM, *Nano Letters* **2022** 22 (10), 4042–4048

11:15am NS2+2D-TuM-14 Dynamic Evolution of Rh/Fe₃O₄(001) Catalysts Under Hydrogen Conditions, Mausumi Mahapatra, Loyola University Chicago; Marcus Sharp, Zdenek Dohnalek, Christopher Lee, Yifeng Zhu, Oliver Gutiérrez, Bruce Kay, Pacific Northwest National Laboratory

Metal/oxide interfaces are a new emerging class of catalysts owing to their unique electronic and chemical properties. In this study, we have prepared a series of model Rh/Fe₃O₄(001)catalysts that include Rh adatoms (Rh_{ad}), mixed surface layers with octahedrally-coordinated Rh (Rh_{oct}), as well as metallic Rh clusters and nanoparticles (Rh_{met}) on Fe₃O₄(001). Using X-ray photoelectron spectroscopy (XPS) and scanning tunneling microscopy (STM), we investigated the activity of such model systems towards H₂ and their stability in reducing environments. Our results show that the atomically dispersed Rh_{ad} and Rh_{oct} species do not activate H₂, which would result in the formation of surface hydroxyls on Fe₃O₄(001). In contrast, the presence of Rh_{met} in H₂ results in the formation of hydroxyls and subsequent etching of the Fe₃O₄(001) at higher temperatures (≥ 500 K) due to water formation via the Mars-van Krevelen mechanism. Additionally, such surface etching leads to the release of the Rh_{oct} from the surface

lattice and their sintering to Rh_{met}. To bridge the material gap between the model and high surface area catalysts, we perform parallel studies on powder Rh/Fe₃O₄ catalysts. The XPS characterization shows remarkable similarities between these systems. Further, our model studies provide an atomistic picture of the behavior of high surface area catalysts in the H₂ atmosphere.

11:30am NS2+2D-TuM-15 Hybrid ALD-MLD HfO_x Thin Films: The Role of Carbon for Memristive Application, Soham Shirodkar, Dushyant Narayan, Minjong Lee, Dan Le, University of Texas at Dallas; Jacob N. Rohan, Cerfe Labs, Austin; Jiyoung Kim, University of Texas at Dallas

Resistive switching (RS) memories based on transition metal oxides (TMOs) are a promising class of emerging nonvolatile memory devices for next-generation electronics. However, conventional TMO-based RS memories typically require high forming voltages (V_{form}) during initial operation, consuming excessive power. To address this issue, incorporation of metal dopant species into TMOs is proposed to lower the V_{form} [1]. For example, Hf/Zr doping in TiO₂ ReRAM has been demonstrated to increase the formation of oxygen vacancies, leading to lower forming voltages [2]. In our previous work, we have demonstrated that incorporating carbon into HfO_x films via a hybrid Atomic Layer Deposition (ALD)/Molecular Layer Deposition (MLD) process can eliminate the need for a forming process, enabling 'Born-ON' behavior during the first sweep [3,4]. However, control of carbon incorporation is challenging due to its high atmospheric reactivity. Therefore, the choice of organic precursor during the MLD can significantly influence the film's properties and ultimately the device properties.

In this work, we systematically investigate the impact of different organic precursors during ALD/MLD hybrid process using two linear-chain hydrocarbons Ethylene Glycol (EG) and Glycerol (GL) as well as an aromatic hydrocarbon Hydroquinone (HQ). These organic precursors vary in number of carbon atoms and number and position of OH groups. In this regard, we observed significant differences in growth per cycle (GPC) and carbon bonding states: HQ, being the largest molecule, exhibited the highest GPC-3.1 Å/cycle and carbon composition-45% along with higher expected C-sp² content due to its aromaticity. Whereas EG showed a low GPC-0.2 Å/cycle and less carbon incorporation-15% due to its small size and possible poisoning effects. In contrast, GL, with an additional OH group, likely mitigates these poisoning effects common to linear hydrocarbons, resulting in a GPC of 2.1 Å/cycle and 31% carbon content. Metal-Insulator-Metal devices with these films exhibit distinct 'Born-ON' behavior as well as resistive switching without electroforming, though each precursor-based film requires a different thermal budget to activate this response. This study underscores the crucial role of precursor chemistry in tailoring the properties of carbon-doped TMO memristors and offers potential pathways for improving RS device performance.

This research is supported by Cerfe Labs and Air Force Research Laboratories.

[1] H.-S. Philip Wong et al., *J Electroceram* (2017) 39:21–38

[2] Yoshio Nishi et al., *ICSSDM*, Kyoto (2012)

[3] C. A. Paz de Araujo et al., *APL Mater.* **10**, 040904 (2022)

[4] M. Lee et al., *ALD/ALE* (2024)

11:45am NS2+2D-TuM-16 Quantitative Comparative Force Spectroscopy on Molecules, Xinzhe Wang, Yale University; Percy Zahl, Brookhaven National Laboratory; Jara Trujillo Mulero, Universidad Autonoma de Madrid, Spain; Hailiang Wang, Yale University; Rubén Pérez, Universidad Autonoma de Madrid, Spain; Eric Altman, Udo Schwarz, Yale University

Understanding molecular-scale interactions at surfaces is essential for advancing catalyst design and developing efficient energy conversion processes. Here, we report ongoing efforts to improve the spatial accuracy and quantitative reliability of three-dimensional atomic force microscopy (3D-AFM) by refining data correction techniques for CO-functionalized tips. These developments allow us to minimize tip- and substrate-induced artifacts and isolate the intrinsic molecular interaction at atomic resolution.

As a testbed for this approach, we investigate cobalt phthalocyanine (CoPc) and its amino-functionalized counterpart ((NH₂)₄CoPc) adsorbed on Ag(111), both of which are of interest in CO₂ electroreduction catalysis. By identifying and removing asymmetric force contributions caused by the metallic structure of the tip, we obtain corrected force spectroscopy data that reveal equilibrium interaction distances and energies across individual molecules. Our analysis shows that NH₂ substitution alters the spatial distribution of interaction strength, decreasing equilibrium distances near

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ligand attachment points while broadly reducing interaction energy with the tip.

These experimental observations agree well with DFT-based simulations and suggest that side-group functionalization directly modulates the molecule's chemical landscape. The methodology provides a direct route toward correlating molecular structure with catalytic behavior at the single-molecule level, thereby enabling a deeper understanding of functional molecular systems on surfaces.

12:00pm NS2+2D-TuM-17 Thermal Strain-Induced Nanogap Formation in Monolayer MoS₂ during CVD Growth, *Seonha Park, Sieun Jang, Songkil Kim*, School of Mechanical Engineering, Pusan National University, Republic of Korea

Molybdenum disulfide (MoS₂) is a promising semiconducting material due to its atomic flatness and high carrier mobility. In particular, chemical vapor deposition (CVD)-grown MoS₂ has been widely explored for electronic applications owing to its high quality and scalability. However, the mismatch in thermal expansion coefficients between MoS₂ and the growth substrate induces strain in MoS₂ flakes, and the nanogap structure can be formed to release such growth-induced strain. Understanding and controlling this unique nanogap structure is of great interest, as it offers opportunities for applications such as nanogap electrodes, biosensors, and gas sensors. In this work, nanogap formation mechanisms and the factors governing gap size and morphology were systematically investigated in monolayer CVD MoS₂. To investigate the role of MoS₂-substrate interfacial bonding strength in nanogap formation, three samples with different adhesion properties with the substrate are prepared. Strain distribution analysis using photoluminescence (PL) mapping and statistical analysis of multiple SEM images revealed that interfacial bonding strength significantly affects strain relaxation behavior, where weaker bonding facilitates strain release, leading to faster crack propagation and more irregular gap paths. The crystallographic configuration also influenced propagation behavior. Asymmetric bi-crystalline flakes with misorientation angles showed a stronger tendency for cracks to follow grain boundaries due to increased mechanical instability. Additionally, the relationship between flake size and nanogap size was also investigated. In samples with moderate interfacial bonding strength, a linear increase in nanogap size was observed with increasing flake size above a critical threshold. In contrast, strongly bonded samples exhibited smaller nanogaps than the moderate bonding sample, with minimal variation in gap size regardless of flake size. These results suggest that nanogap size can be effectively controlled by tuning the interfacial bonding strength and the flake size.

Plasma Science and Technology Room 201 ABCD W - Session PS-TuM

Advanced Memory, HARC, and Cryo Etching

Moderators: Jeffrey Shearer, Jeffrey Shearer, TEL Technology Center, America, LLC, Christophe Vallee, UAlbany

8:00am PS-TuM-1 Optimizing hafro2 Film Thinning by Plasma Etching for Ferroelectric Memories, *Vincent Michaud, Christelle Boixaderas, Laurent Grenouillet, Thierry Chevolleau*, CEA-University Grenoble Alps, France
Non-volatile memories are crucial for reducing energy use in modern computing, where most energy is used for data transfer and storage. Ferroelectric Random Access Memories (FeRAMs) retain data without power, lowering energy consumption. The Hafnium-Zirconium Oxide (HZO) has promising ferroelectric properties and its integration is fully CMOS compatible but requires the deposition of a TiN top electrode before the annealing step for crystallization [1] [2]. Recent studies have shown the interest in implementing HZO film thickness lower than 10 nm to reduce voltage operation. However, for such a thickness, the annealing temperature exceeds 400°C which may hamper Back-End Of Line (BEOL) integration [3].

The main goal of this work is to implement HZO thin film with a thickness lower than 10 nm while getting ferroelectric properties for a thermal budget compatible with BEOL integration. The approach is based on the integration of an HZO thin film of 10 nm between the two TiN electrodes (bottom and top) followed by the thermal annealing step to get the ferroelectric properties at a temperature compatible with BEOL scheme. Then, the first step is to etch back the TiN top electrode down to the HZO layer and the second step consists in reducing the thickness of HZO film by plasma etching.

This work involves developing processes to remove the TiN top electrode without damaging the underlying HZO, to optimize plasma etching parameters to thin down the HZO crystallized films below 10nm, while retaining ferroelectric properties. The 10nm thick HZO films deposited by Atomic Layer Deposition (ALD) are partially etched using Inductively Coupled Plasma (ICP) with chlorine-based chemistry. Film thickness is measured by spectroscopic ellipsometry, the surface topography and roughness are analyzed by means of Atomic Force Microscopy (AFM). X-Ray Diffraction (XRD) and X-ray Photoelectron Spectroscopy (XPS) are used to study the impact of plasma etching on the film's structure and surface composition.

The removal of the top electrode is studied using plasma etching or/and wet etching to achieve a selective process to HZO without damaging. The thinning down of the HZO film is based on a parametric study of BCl_3/Cl_2 -based plasma to get an uniform etch process while preserving the crystalline phase with a low surface roughness. Quasi in-situ XPS analysis reveals surface modifications and etching mechanisms, compared to HfO₂ film thinning.

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8:15am PS-TuM-2 Investigation of Hydrogen and Nitrogen Used as Etching Chemistry or Surface Treatment for Phase-Change Random Access Memory Patterning, *Benjamin Fontaine*, STMicroelectronics, France; *Christelle Boixaderas, Jérôme Dubois*, CEA/LETI-University Grenoble Alpes, France; *Pascal Gouraud, Arnaud Rival*, STMicroelectronics, France; *Nicolas Posseme*, CEA/LETI-University Grenoble Alpes, France

Phase-change random access memories (PCRAM) have become a crucial technology for data storage, leveraging the resistive tunable properties of a germanium-antimony-tellurium alloy also known as GST. For automotive application requiring high temperature data retention, this material is enriched in germanium resulting in a Ge-rich GST, or Ge-GST [1].

GST is commonly etched using halogen chemistries in inductively coupled plasma reactors [2-3]. The HBr molecule provides a good trade-off in between fast etching and limited film modification. However, it alters the film, leading to the formation of germanium-oxides residues upon air exposure. Recent research focuses on alternative hydrogen and nitrogen-based gases for PCRAM patterning [3].

This study evaluates the effects of H₂ and N₂ plasma etching on Ge-GST films. Both gases have etch rates below 10 nm·min⁻¹ on unpatterned wafers. Atomic force microscopy (AFM) and X-ray Photoelectron Spectroscopy (XPS) reveal that the hydrogen-etched surface is smooth with limited modification, whereas the nitrogen-etched film is rough and significantly altered in stoichiometry. In-situ chemical analysis detected oxygen, fluorine and chlorine contamination after nitrogen etching. To further investigate hydrogen's influence, a specific protocol was developed. Fourier-Transform Infrared Spectroscopy (FTIR) and time-of-flight ion mass spectrometry (ToF-SIMS) indicated substantial hydrogen incorporation in the film post-H₂ etching, likely bounded to germanium and tellurium.

Subsequently, we explored an alternative method to integrate these recent chemistries into Ge-GST patterning. This approach was applied after partial etching of Ge-GST using HBr plasma, as post-etching treatment (PET). The results were consistent with those obtained using the gases as primary etchants. X-ray reflectivity (XRR) measurements showed a negligible GST consumption during both PET. AFM analysis highlighted a smooth surface with hydrogen PET and a rough surface after nitrogen PET. XPS confirmed the preservation of the material stoichiometry plus halogen removal with H₂ PET and the film alteration with N₂ PET.

Finally, hydrogen gas was implemented on memory lines as main etching and PET within the full process including dry stripping, and wet cleaning. Both solutions demonstrated promising results compared to a bromine-based reference process, as evidenced by secondary and transmission electron microscopy (SEM and TEM) coupled with energy dispersive X-ray spectroscopy (EDX).

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8:30am **PS-TuM-3 Does the Etching of Exotic Materials or the Implementation of Cryogenic Conditions Call Into Question the Fundamentals of Plasma-Surface Interaction?** *Christophe Cardinaud, Tatiana Mbouja Signe, Felipe Cemin, Hiba Beji, Nantes Université - CNRS-IMN, France; Thomas Le Pape, Nantes Université - CNRS-IMN France; Aurélie Girard, Cédric Mannequin, Nantes Université - CNRS-IMN, France*

INVITED

Since the early days of plasma etching in the 1970's, mechanisms leading to the etching of a material using a plasma environment have been the subject of numerous studies. The pioneering work of Coburn and Winters set the synergy of interaction between the reactive neutral species and the ion bombardment. In the 1990's numerical expressions of the etch rate versus reactive flux and ion flux were proposed. The most efficient system considers a Langmuir adsorption mechanism for the etchant and an ion flux stimulated desorption mechanism for the etch product. Surprisingly, this model matches experimental data in many situations, where the etching yield is observed to follow a "Langmuir-like" behaviour as function of the ion flux to neutral flux ratio. However, XPS surface analysis, TEM profile and molecular dynamics simulations clearly show that plasma-surface interaction is much more complex. Indeed ion bombardment causes damage to the material; reactive neutrals penetrate the material; so the plasma-surface interaction mechanism is far from being a single-layer process.

In order to better control etched depth, chemical and electrical defects, as well as pattern shape, dimension and surface topography, some etching processes are now moving towards atomic layer etching (ALE) and cryoetching. ALE aims to separate chemical modifications of the surface from the action of ion bombardment, thus breaking with the ion-neutral synergy strategy. Cryoetching aims to increase surface coverage of reactive species at the pattern bottom while promoting passivation mechanisms at the pattern sidewall. Nowadays, it has become a crucial technology in semiconductor manufacturing, as it allows high aspect ratio and selectivity, controllable sidewall profiles and damage in features from the micrometer to the nanometer scale. Recently, it has proved to be of great interest in ALE processes. Behind these technological advances lie several physicochemical mechanisms occurring on the uppermost atomic layers of the cooled surface. Furthermore etching of exotic materials, such as V_2O_3 , whose structure may not be as stable as "usual" dielectrics, metal or semiconductors, exhibits strong deviations from the "Langmuir-like" behaviour.

The presentation will briefly review the main findings on the fundamentals of plasma-surface interaction. The evolution of concepts in the case of ALE will also be discussed. Then the physicochemical mechanisms under cryogenic conditions will be presented, with a particular attention to the sample-cooling phase and the effect of residual gases. Finally, the strange case of V_2O_3 will be addressed.

9:00am **PS-TuM-5 Charging Dynamics During Pulsed Plasma Etching of High Aspect Ratio Features in Dielectric Materials**, *Chenyao Huang¹, Yeon Geun Yook, Yifan Gui, University of Michigan; Steven C. Shannon, North Carolina State University; Mark J. Kushner, University of Michigan*

During plasma etching of high aspect ratio (HAR) features in dielectric materials (e.g., SiO_2 , Si_3N_4 , ONO), disparities in the energy and angular distributions (EADs) between positive ions and electrons result in differential charging within the feature. The resulting electric fields within the feature can distort the trajectories of incoming ions resulting in defects and feature distortion. With the aspect ratio of features for memory and logic increasing, there are also increasing concerns of the consequences of charging. A proposed remedy for feature distortion due to charging is the use of pulsed biases. The feature is exposed to different fluxes and EADs of charged species during the on- and off-times during the pulse period. As a result, charging dynamics differ during the on- and off-periods. Net charging likely occurs during the on-portion of the pulsed period when ion energies are high. Discharging likely occurs during the off-portion of the period when ion energies are low, including attracting negatively charged particles into the feature.

In this work we discuss results from a computational investigation of the charging dynamics during pulsed plasma etching of HAR dielectric structures using a 3D voxel-based model, the Monte Carlo Feature Profile

Model (MCFPM). MCFPM receives fluxes and EADs of incoming species toward the wafer from a model for plasma properties at the reactor scale, the Hybrid Plasma Equipment Model (HEPM). The MCFPM launches and tracks pseudo-particles representing neutral and charged fluxes towards the surface, and simulates the evolution of the feature and the charging process. The MCFPM includes newly developed algorithms for secondary electron emission processes for electrons and ions. Charging dynamics during pulsed plasma etching of HAR vias will be discussed for fluorocarbon and cryogenic etching of SiO_2 and ONO stacks in multi-frequency capacitively coupled plasmas.

This work was supported by the Department of Energy Office of Fusion Energy Sciences (DE-SC0024545), Samsung Electronics and Lam Research.

9:15am **PS-TuM-6 Controlled Cryogenic Silicon Etching Using Pulse-Modulated Platen RF Power**, *Zhitian Shi, Nikhil Tiwale, Ming Lu, Chang-Yong Nam, Brookhaven National Laboratory*

Precise control of sidewall profiles and etch anisotropy is critical for high-resolution silicon nanofabrication ¹. In cryogenic reactive ion etching, the interplay of ion flux, radical density, and sheath voltage governs both material removal and sidewall passivation ². Fluorine-based radicals form volatile SiF_x species, while oxygen species stabilize sidewalls via SiO_xF_y passivation layers ³. Platen RF delivery can be pulse-blanked above a threshold, adjusting the duty cycle and influencing etch rate and lateral etching ⁴. Understanding these plasma-surface interactions is essential for transferring nanoscale patterns with high fidelity.

We investigated pulse-blanked RF on cryogenic silicon etching using a 400 nm ZEP hardmask patterned via electron beam lithography (JOEL JBX-6300FS, 500 nm lines, 1 μm pitch, 50% duty cycle). Samples diced from 4-inch wafers were mounted on carrier wafers with Fomblin oil at -100 °C. Etch conditions were constant: chamber pressure 15 mTorr, ICP 2000 W, Platen RF 15 W. Three RF delivery schemes were compared: pulstran 50% duty cycle, sinusoidal-triggered blanking (threshold 4 V, ~70% on-time), and continuous RF (100% on).

Cross-sectional SEM (Figure 1) shows pulsed blanking yields the highest etch rate, with 50% duty cycle increasing ~27% versus unmodulated RF. Sinusoidal-triggered blanking increases ~16%, lower than pulsed, but reduces lateral etching and improves sidewall uniformity. These results indicate that duty-cycle-controlled RF blanking effectively balances etch rate and profile control in cryogenic silicon processing.

Future work will explore the effect of duty cycle, modulating frequency, and phase matching on etch outcomes, and integrate in-situ plasma diagnostics to correlate ion energy distribution with material removal. This approach provides a pathway toward reproducible, high-fidelity nanoscale pattern transfer, enabling advanced semiconductor, photonic, and quantum device fabrication.

Acknowledgment

This research was funded by the Laboratory Directed Research and Development (LDRD) at Brookhaven National Laboratory. The research was in part supported by the Technology Innovation Program (RS-2023-00234159) funded by the Ministry of Trade, Industry & Energy (MOTIE) of the Republic of Korea (no. 1415187652).

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9:30am **PS-TuM-7 Etching Properties of Maskless Oxide/Nitride/Oxide/Nitride (ONON) Stacks with $C_4H_2F_6$ -based Gas**, *Jong Woo Hong, Nam Il Cho, Geun Young Yeom, Sungkyunkwan University (SKKU), Republic of Korea*

The Oxide/Nitride/Oxide/Nitride (ONON; $SiO_x/SiN_x/SiO_x/SiN_x$) stacked structure is commonly used in the 3D vertical architecture of semiconductor memory cells. In the etching of metal contact area of the ONON structure (that is, staircase etching), photoresist (PR) is patterned and repeatedly trimmed over the ONON structure after etching one of the ON layers to form the 3D cells. This layer-by-layer etch process is time-consuming. As a result, a two-step etch method, which involves maskless etching of an ONON stack followed by etching one ON layer at a time with PR trimming, has been adopted using gases such as C_4F_8 or C_4F_6 . However,

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this two-step approach leads to less ideal etch profiles in the maskless ONON stack in addition to high global warming potentials of C_4F_8 and C_4F_6 gases.

In this study, the etch behavior of maskless ONON stack features using $C_4H_2F_6$ -based gas, which has a lower global warming potential, has been explored and examined its impact on etch characteristics such as etch rate, etch profile, critical dimension (CD) changes, and etch selectivity between SiO_x and SiN_x . The results showed that $C_4H_2F_6$ -based gas achieved the highest etch rates of ONON stack compared to C_4F_6 and C_4F_8 , with an etch selectivity of approximately 1:1 between SiO_x and SiN_x , due to the hydrogen content in the gas. Furthermore, the horizontal CD change was smaller when using $C_4H_2F_6$ compared to C_xF_x -based gases. A thicker carbon-based polymer layer on the sidewall by the etching with $C_4H_2F_6$ also played a crucial role in preserving the top edge shape of the etched maskless ONON stack.

9:45am PS-TuM-8 Aspect Ratio Resolved Mass Spectrometry for Sticking Probability of Neutral Species in High Aspect Ratio Hole, *Takumi Kurushima, Takayoshi Tsutsumi, Makoto Sekine, Masaru Hori, Kenji Ishikawa*, Nagoya University, Japan

The demand for microfabrication technology has been increasing as semiconductor devices become three-dimensional (3D) structures. In particular, plasma etching processes for 3D structure are required with high aspect ratio holes and without their shape abnormalities. Simulation-based studies are actively uncovering particle transport and reactions inside the holes, which are difficult to measure them. However, in particle behavior, the sticking probability of radicals on sidewalls is often set based on the number of unpaired electrons, resulting in an approximate value and making it an imprecise parameter. We have developed a novel measurement method to quantitatively determine the sticking probability of neutral species.

The measurements were performed using the appearance mass spectrometry of a quadrupole mass spectrometer (QMS). By varying the aspect ratio of the orifice at the QMS entrance, radicals passed through orifices with different aspect ratios. The fitting results of the experimental and Monte Carlo simulation data lead to a sticking probability. This method is named Aspect Ratio Resolved Mass Spectrometry (ARMS).

From these results, the sticking probabilities of CF , CF_2 , CF_3 , and C_2F_4 were estimated. The ARMS can evaluate the sticking probabilities of neutral species with different mass numbers, contributing to more accurate particle models in simulation-based research.

11:00am PS-TuM-13 Twisting and Profile Distortion in High-Aspect Ratio Etching Processes, *Prem Panneerchelvam*, KLA Corporation; *Jin Xie*, KLA Corporation, China; *Chad Huard, Mark Smith*, KLA Corporation

In recent years, the channel hole etching process in 3D NAND manufacturing has experienced significant evolution. Traditionally reliant on conventional high temperature etching processes with fluorocarbon-based chemistries in pulsed plasmas, the industry has progressively adopted various generations of cryogenic etching to meet the demanding requirements of high aspect ratio structures. The primary challenge in these processes is to preserve the spatial uniformity of the etched profiles despite the extreme aspect ratios involved.

In conventional processes, achieving critical dimension (CD) uniformity was the major focus; however, as the industry transitioned to cryogenic etching, new challenges emerged. Notably, two critical phenomena—twisting and profile distortion—now dominate process variability. Twisting refers to the stochastic deviation of the etching pattern from its intended trajectory, while profile distortion describes the transformation of ideally circular mask openings into non-circular, often triangular, shapes during the etching process.

To elucidate the origins and evolution of these phenomena, we employ ProETCH®, a feature-scale Monte Carlo profile simulator. This tool enables a detailed study of high aspect ratio etch dynamics, offering insights into how stochastic variations lead to twisting and how process conditions contribute to profile distortion. By identifying process windows and parameter adjustments—including changes to plasma properties (IEADs)—this work aims to reduce these effects and improve the overall performance of the etching process.

11:15am PS-TuM-14 Detection of Etch Products during the SiN_x Etching in a HF Plasma with *In Situ* Mass Spectrometry, *Xue Wang¹, Md Tanzid Hossain*, Colorado School of Mines; *Prabhat Kumar, Thorsten Lill, Harmeet Singh, Mingmei Wang, Taner Ozel*, Lam Research Corporation; *Sumit Agarwal¹*, Colorado School of Mines

We have identified the primary etch products formed during etching of SiN_x with an HF plasma using *in situ* mass spectrometry. As etch products are formed, they can dissociate in the plasma, making direct detection of these species difficult. Due to this complexity, mass spectrometry has been primarily used to detect etch products generated during exposure of the surface to neutrals and ion beams. In other cases, the etch products are detected with a quadrupole mass spectrometer (QMS) downstream of the plasma etcher. While beam studies have provided insight into the basic etch mechanism, the etch products formed in a plasma environment can be different. If the etch products are measured downstream, these species may not represent those that are directly released from the film's surface.

In this work, we identify several etch products during the SiN_x etching in HF plasma using an in-house-built sampling setup for a QMS. As shown in Fig. 1, the QMS housing consists of two stages of differential pumping, and gas phase species were sampled by a skimmer cone positioned ~ 0.5 cm from surface being etched in the plasma. At an HF pressure of 10 mTorr, this distance is on the order of the mean free path. Additionally, we alternate between self-bias and applied radio-frequency bias at 4 MHz to isolate species that originate directly from the surface. All these designs ensure minimal interaction of etch products with the plasma and other surfaces in the chamber. From the time-resolved mass spectra for SiF_x^+ ($x = 1, 2, 3, 4$) ions during both self-biased and applied-biased etching, we confirmed that SiF_4 is the main etch product. Other fluorosilanes, SiH_xF_{4-x} , were also identified as etch products and the relative ratio of SiF_4 to other fluorosilanes increased with the bias voltage (see Fig. 2). Specifically, we observed that the fraction of SiF_4 increased faster than $SiHF_3$ when a bias was applied, and $SiHF_2$ decreased when switching from the self-bias to the applied-bias condition. This suggests that the reaction pathways change with increasing ion energy during SiN_x etching. Further measurements on N-related etch products indicated that NH_2F is likely an etch product as the QMS signal intensity for NF^+ and NHF^+ increased during etching (see Fig. 3 a, b). Furthermore, the threshold energy for dissociative ionization of NH_2F to NF^+ was ~ 14.8 eV, which is consistent with the value in the literature (see Fig. 3 c). We confirmed that NF_3 was not a major etch product since we did not detect NF_2^+ and NF_3^+ ions. Finally, the detection of NH_3 remains challenging, primarily due to interference from H_2O adsorbed on the chamber walls.

11:30am PS-TuM-15 Ion-Enhanced Synergistic Reactions in Cryogenic Plasma Etching with HF-Contained Gases, *Shih-Nan Hsiao, Yusuke Imai, Sekine Makoto*, Nagoya University, Japan; *Ryutaro Suda, Yuki Iijima, Yoshihide Kihara*, Tokyo Electron Miyagi Limited, Japan; *Masaru Hori*, Nagoya University, Japan

For over half a century, reactive ion etching (RIE) has served as a cornerstone of the semiconductor industry, driving the mass production of countless wafers daily. Its success lies in the ingenious interplay between reactive chemical gases and energized ions, a synergy that has revolutionized modern technology. However, as device architectures evolve, conventional RIE struggles to keep pace with the demands of intricate 3D structures featuring tiny dimensions and high aspect ratios. This growing complexity undermines the efficiency of its once-reliable synergistic reactions, resulting in a marked decline in throughput and posing significant challenges to modern fabrication processes. Recently, cryogenic plasma etching containing hydrogen fluoride (HF)-contained species has been reported to address these issues, due to its unique synergistic reactions between ion, surface physisorption species, and material surface [1-3]. To understand the role of ions in synergistic reactions in cryogenic HF plasma, the dependences of bias voltage on etching characteristics and surface structure of the SiO_2 with HF-contained plasmas were investigated. The feeding gas, including CF_4/H_2 and HF, was introduced through a showerhead distributor in the top electrode. *In situ* monitoring techniques, including spectroscopic ellipsometry and attenuated total reflectance Fourier transformation infrared spectroscopy (ATR-FTIR), were used to analyze the surface structure and etching characteristics. The substrate temperature (T_s) was controlled from 20 to -60 °C by circulating a coolant through the bottom electrode. As detailed in the supplemental document, the co-adsorption of HF and H_2O on a cooled substrate introduces a wet-like HF etching mechanism for SiO_2 , characterized by an almost zero activation

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barrier when utilizing pure HF plasma. Interestingly, the etch rate demonstrates an exponential dependence on peak-to-peak bias voltage, deviating sharply from the typical linear relationship observed in conventional chemical-ion sputtering. In the CF_4/H_2 system, fluorocarbon deposition imposes a significantly higher energy threshold for etching. However, a similar trend between etch rate and bias voltage emerges within the high bias voltage regime, further highlighting the complex dynamics of this process.

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11:45am PS-TuM-16 Mechanistic Insights Into Cryogenic Plasma Etching of SiO_2 : Temperature, Power and Surface Reaction Dynamics, Yeon Geun Yook, University of Michigan; *Hyunjae Lee, Sang Ki Nam, Mechatronics Research, Samsung Electronics Co, Republic of Korea; Mark J. Kushner, University of Michigan*

In semiconductor manufacturing, overcoming the limitations of high aspect ratio (HAR) plasma etching is critical for continuous scaling of 3D devices. Aspect ratio dependent etching (ARDE) is the slowing of etch rate in as the process proceeds and aspect ratio (AR) increases. Cryogenic etching (CE), cooling the substrate to temperatures as low as -100 C, is emerging as a promising approach for achieving high etch rates and vertical profiles which are less sensitive to ARDE. CE etching of SiO_2 is typically performed in capacitively coupled plasmas (CCPs) whose gas mixtures contain or produce HF. The formation of H_2O through the reaction between HF and SiO_2 , and its subsequent condensation, is thought to act as a catalyst which enhances the etch rate. In conventional dielectric etching at ambient temperatures in CCPs, carbon-fluorine reactions dominate the etch process through formation of polymer passivation. The fundamental reaction mechanism responsible for the improved performance of CE has not been clearly defined.

This presentation discusses results from a computational investigation of surface reaction dynamics during the cryogenic plasma etching of SiO_2 , employing the Hybrid Plasma Equipment Model (HPEM) and the Monte Carlo Feature Profile Model (MCFPM). Simulations were conducted for dual-frequency CCP reactors using $\text{CF}_4/\text{H}_2/\text{Ar}$ gas mixtures. The temperature-dependent mechanistic differences between cryogenic and room temperature etching were analyzed through parametric analysis of adsorption probability, etch yield, specular reflection of scattering of high energy particles from surfaces, surface diffusion, redeposition, implantation, and condensation. Process parameters including source power (plasma and precursor density) and bias power (ion energy) were also investigated. When compared to conventional dielectric plasma etching, CE increases etch rates by factors of 2-3 with a minimum of bowing or tapering. We found that within estimated ranges of uncertainty, when varying these parameters no single process is uniquely responsible for the improved performance of CE. The improved performance requires synergistic improvements in several key parameters.

This work was supported by Samsung Electronics.

12:00pm PS-TuM-17 Ammonium Fluorosilicate Salt Layer Dynamics during Etching of SiN_x in a HF Plasma and Strategies for Controlling SiN_x to SiO_2 Etch Selectivity, Md Tanzid Hossain, Xue Wang, Colorado School of Mines; Prabhat Kumar, Thorsten Lill, Harmeet Singh, LAM Research; Mingmei Wang, Lam Research; Taner Ozel, LAM Research; Sumit Agarwal, Colorado School of Mines

During SiN_x etching with HF plasma, ammonium fluorosilicate (AFS) forms as a transient byproduct, significantly influencing the etch behavior. While AFS formation during SiN_x etching has been known for several decades, the underlying mechanism for its formation and removal remains unclear. In this study, we have used *in situ* attenuated total reflection Fourier-transform infrared (ATR-FTIR) spectroscopy to study the changes in the chemical boning on the SiN_x surface during reactive ion etching, along with the AFS formation and removal dynamics (Fig. 1). The steady state accumulation of AFS on the SiN_x surface is determined by AFS formation from the etch products and AFS decomposition due to ion bombardment. Prior to etching, the plasma-deposited SiN_x film's surface is terminated with $\text{Si}-\text{NH}_x$ ($x = 1, 2$) bonds, and the neutrals in the HF plasma readily react with these species to form AFS, which is apparent from the increase in absorbance for the NH_4^+ bending and stretching modes at $\sim 1430 \text{ cm}^{-1}$ and $\sim 3000\text{--}3300 \text{ cm}^{-1}$, respectively, in Fig. 1. The etch rate of SiN_x is high during the onset of etching due to the abundance of accessible reaction sites. As etching continues, an AFS layer forms, and the etch process likely becomes

diffusion-limited as HF, H, and F neutrals have to diffuse through AFS to react with the underlying SiN_x film. Therefore, after the initial burst of AFS formation on the H-terminated SiN_x surface, the process becomes a dynamic competition between ongoing AFS synthesis and removal. On the other hand, on the SiO_2 surface, as expected, there is no AFS residue observed on the surface due to the absence of N in the plasma or in the film. However, the etch rate for SiO_2 is approximately $\sim 3\text{--}4$ times lower than that for SiN_x under nominally similar conditions. For applications such as etching of alternating stacks of SiO_2 and SiN_x for the fabrication of 3-D NAND memory devices, it is desirable to etch SiN_x and SiO_2 at approximately the same rate. Our initial hypothesis is that AFS formation accelerates the etching of SiN_x compared to SiO_2 . Therefore, to promote the etching of SiO_2 we nitrided the surface with an NH_3 plasma to create surface $\text{Si}-\text{NH}_x$ ($x = 1, 2$) species (see Fig. 2a). Subsequent HF plasma exposure revealed AFS formation on the SiO_2 surface (Fig. 2b), but it lowered the SiO_2 etch rate compared to the untreated surface. Therefore, to accelerate the etch rate of SiO_2 in a HF plasma, we will explore other process parameters including the average ion energy during etching and surface nitridation, effect of diluents in the gas phase, and the substrate temperature.

Quantum Science and Technology Mini-Symposium Room 208 W - Session QS1-TuM

Quantum Simulations and Quantum-Inspired Technologies

Moderator: Andre Schleife, University of Illinois at Urbana-Champaign

8:00am QS1-TuM-1 Investigating Processing Spaces of Epitaxially Grown Nitride Materials with Quantum and Conventional Supervised Learning, Andrew Messecar¹, Western Michigan University; Kevin Vallejo, Idaho National Laboratory; Steven Durbin, University of Hawai'i at Mānoa; Brelon May, Idaho National Laboratory; Robert Makin, Western Michigan University

The experimental design of material synthesis occurs within highly complex processing spaces defined by multiple design parameters. Traditional identification of optimal values for each design term often involves an iterative, costly, Edisonian trial-and-error strategy for experiment design. Therefore, there is great interest in leveraging machine learning-based approaches to enhance and expedite the strategic design of materials and their synthesis pathways. Here, information describing plasma-assisted molecular beam epitaxy (PAMBE) growth trials of transition metal and group-III nitrides have been organized into distinct, composition-specific data sets. For each synthesis record, the complete recipe of experiment design parameters (substrate temperature, element source conditions, growth duration, etc.) are associated with binary numerical labels representing sample crystallinity and surface morphology as determined via *in-situ* reflection high-energy electron diffraction (RHEED) patterns. A Bragg-Williams measure of lattice ordering (S^2) is also investigated as an additional, continuous figure of merit pertaining to atomic-scale disorder. Quantum and classical machine learning algorithms – including linear models, neural systems, tree-based algorithms, and quantum support vector machines – are fit to the data to investigate which growth parameters have the most statistically significant influence over each material property of interest. When predicting the occurrence of monocrystalline PAMBE-grown GaN sample surfaces, supervised learning techniques incorporating quantum computation display notable generalization advantage when compared to classical machine learning approaches. The class-conditional probabilities of obtaining single crystalline, atomically-flat thin film crystals – as well as the degree of lattice ordering measured by S^2 – are forecasted across broad ranges of possible PAMBE operating parameter combinations. These predictions are compared to experimental best practices as well as the results described in published literature detailing the PAMBE synthesis of these materials. The improved generalization performance displayed by the quantum-aware models when predicting GaN crystallinity implies a potential advantage gained via quantum computational studies of synthesis–property relationships in other material systems.

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¹ AVS Dorothy M. and Earl S. Hoffman Scholarship Recipient

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8:15am **QS1-TuM-2 Quantum Simulation of Spin-Current Autocorrelation Function**, *Yi-Ting Lee*, University of Illinois at Urbana Champaign; *Bibek Pokharel*, IBM, T.J. Watson Research Center; *Arnab Banerjee*, Purdue University; *Andre Schleife*, University of Illinois at Urbana-Champaign; *Jeffrey Cohn*, IBM Almaden Research Center

Understanding spin dynamics has long intrigued physicists, as it plays a vital role in revealing the characteristics of quantum magnets, with potential applications in spintronic devices and spin qubits. Evaluating the dynamical properties of large spin systems is often challenging for classical computers due to the exponential growth in memory requirements. Since Hamiltonian dynamics can be efficiently simulated using quantum circuits, the evaluation of time-dependent properties has generated significant interest within the quantum computing community.

While time-dependent magnetization and the one-time dynamical structure factor have been simulated on quantum computers before, there has been no simulation of the spin-current autocorrelation function (ACF). The one-time spin-current ACF can be used to identify the diffusion behavior of spin systems and is directly related to their coherence properties and device performance. In this research, we first consider the spin-1/2 XXZ Heisenberg model as it serves as the framework for studying magnetic interaction.

Here, we introduce a simple yet efficient direct measurement scheme for evaluating the one-time spin-current ACF. Unlike the standard Hadamard test, our method eliminates the need for control gates with ancilla qubits and reduces the number of required circuits by a factor of N, where N is the number of qubits. We demonstrate the circuit design and measurement protocol and validate it through a quantum experiment on the *ibm_marrakesh* hardware. In the 20-qubit experiment with the Néel state, we achieve excellent agreement with the numerical results for both the real and imaginary parts, highlighting the effectiveness of our method. Moreover, we present a design for measuring the two-time spin-current ACF and demonstrate good agreement between statevector-simulated results and numerical results, further showcasing the utility of our approach. Furthermore, our method can be potentially extended to measure any ACF, benefiting the study of spin dynamics.

This work is supported by Taiwan UIUC scholarship, and we acknowledge support by the IBM Illinois Discovery Accelerator Institute and the IBM Externship Program. This work made use of the Illinois Campus Cluster, a computing resource that is operated by the Illinois Campus Cluster Program in conjunction with the National Center for Supercomputing Applications and which is supported by funds from UIUC. The research at IBM and Purdue is supported by National Quantum Initiative Science Research Centers, Quantum Science Center, managed by ORNL for the US-DOE.

8:30am **QS1-TuM-3 Quantum Information Processing Stack: From Bottom to Top and Back**, *Sophia Economou*, *Karunya Shirali*, Virginia Tech **INVITED**
Quantum processors have become quite large and sophisticated machines over the last several years, with many tech companies racing to develop the first quantum computer of practical utility. While the progress has been impressive, quantum processors still face significant hurdles such as short coherence times and high error rates. They are not yet able to compete with classical information processing technologies in solving problems of practical interest. I will discuss my group's contributions across the quantum information processing stack, from the control of quantum hardware to quantum algorithm development and back.

9:15am **QS1-TuM-6 Quantum-Enhanced Communication Network Routing in Cyber-Physical Power Systems**, *Shuyang Ma*, *Yan Li*, Penn State University

Communication networks in cyber-physical power systems play a vital role in ensuring reliable information exchange, enabling real-time monitoring, control, and coordination of distributed energy resources. However, ensuring real-time responsiveness while meeting strict Quality of Service (QoS) constraints, such as low latency and high reliability, introduces significant challenges. A central problem is the constrained shortest path (CSP), which seeks to minimize communication costs across the grid while adhering to a maximum delay threshold. This NP-hard problem becomes computationally infeasible for large-scale networks using conventional approaches. To tackle this, we propose a novel method that transforms the CSP problem into a Quadratic Unconstrained Binary Optimization (QUBO) model, subsequently mapped to an Ising Hamiltonian. This reformulation enables the use of the Quantum Approximate Optimization Algorithm (QAOA), a hybrid quantum-classical technique that exploits quantum parallelism to efficiently approximate optimal routing solutions. Our approach offers reduced computational complexity and improved

scalability compared to traditional methods. Through numerical simulations, we demonstrate that this QAOA based strategy successfully identifies cost-effective paths that satisfy QoS requirements, underscoring its potential to revolutionize network optimization in power grids as quantum computing advances.

9:30am **QS1-TuM-7 Floquet-ADAPT-VQE: A Quantum Algorithm to Simulate Non-Equilibrium Physics in Periodically Driven Systems**, *Abhishek Kumar*, *Karunya Shirali*, *Nicholas J. Mayhall*, *Sophia E. Economou*, *Edwin Barnes*, Virginia Tech

Non-equilibrium many-body quantum systems exhibit many fascinating phenomena absent in equilibrium systems, but simulating them on classical computers is challenging. We propose a hybrid quantum-classical algorithm, Floquet-ADAPT-VQE, to simulate the non-equilibrium physics of periodically driven quantum systems. We utilize the Floquet-Hilbert space, a composition of auxiliary and physical spaces, to transform the Hamiltonian into a time-independent form. We define a cost function based on the square of the shifted extended Floquet Hamiltonian and show how to prepare Floquet eigenstates using Floquet-ADAPT-VQE. We also obtain a suitable auxiliary initial state whose squared Floquet energy is independent of the number of auxiliary qubits as well as the driving frequency, which leads to better convergence with fewer ADAPT iterations. Additionally, we provide a framework to calculate the time-dependent expectation value of observables in the Floquet state with fixed-depth quantum circuit. We demonstrate our algorithm by performing numerical simulations on a periodically driven XYZ model with a magnetic field. We also explore potential applications of our algorithm for studying various non-equilibrium phenomena in periodically driven systems.

Quantum Science and Technology Mini-Symposium

Room 208 W - Session QS2-TuM

Quantum Foundries, Educational Initiatives, Sensing and Metrology

Moderators: *Ekta Bhatia*, NY CREATES, *Haozhi Wang*, University of Maryland College Park

11:00am **QS2-TuM-13 NIST on a Chip, Quantum-Based Sensors for Metrology in the Quantum Era**, *Jay Hendricks*, National Institute of Standards and Technology (NIST) **INVITED**

The re-definition of the SI units enables new ways to realize fundamental units. Quantum-based metrology systems, however exciting, do raise new challenges and several important questions: Can these new realizations enable the size and scale of the realization to be miniaturized to the point where it can be imbedded into everyday products? What will be the role of metrology institutes in the new ecosystem of metrology and measurement? This talk will begin to explore these important philosophical questions. The technical core of the talk will be a deeper dive into research on measurement methods for pressure, the Fixed Length Optical Cavity (FLOC) and for vacuum the Cold Atom Vacuum Standard (CAVS). What is exciting about many of these new measurement approaches is that they are both primary (relying on fundamental physics), are quantum-based and use photons for the measurement readout which is key for taking advantage of the fast-growing field of photonics.

11:30am **QS2-TuM-15 RF Imaging of Sub-Surface Defects in Si(100) with an STM Tip-Induced Quantum Dot**, *Jonathan Marbey*, *Michael Dreyer*, *Matthew Brooks*, University of Maryland; *Omadillo Abdurazakov*, *Yun-Pil Shim*, University of Texas at El Paso; *Robert Butera*, Laboratory for Physical Sciences (LPS)

We present radio frequency (RF) reflectometry measurements that have been combined into a millikelvin scanning tunneling microscope (mK-STM). This technique is realized through a relatively straight forward integration of an LC tank circuit into the STM tip-plate. For semi-conductor samples, application of a voltage bias gives rise to tip-induced band bending which leads to the formation of an induced quantum dot that can be scanned across the sample surface. This measurement geometry provides a unique detection method, as variations in the energy of a state confined to the tip-induced quantum dot due to the local environment leads small changes in quantum capacitance. These capacitance variations can be effectively sensed via RF reflectometry of the tunnel junction provided the tank circuit has a sufficient quality factor Q. In particular, we find strong phase contrast in the presence of resonant tunnel coupling between the induced dot and sub-surface defect states. As a demonstration of this capability, we present experimental results on highly phosphorus doped (10^{19} cm^{-3}) Si(100). 1-D

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voltage dependent spectroscopy measurements in the vicinity of defects reveal ring-like structures in the reflected phase that can be effectively modeled by an asymmetric double-dot detuning picture. This technique ultimately aims to emulate read-out geometries relevant to modern quantum dot devices.

11:45am QS2-TuM-16 Pushing the Boundaries of Coherence in Superconducting Quantum Systems at the SQMS Center for Computing, Sensing, and Metrology, *Tanay Roy*, Fermi Lab INVITED

This talk will highlight recent advances at the SQMS Center in understanding and mitigating decoherence in superconducting quantum systems, focusing on both transmon qubits and 3D superconducting cavities. I will present results from systematic studies of materials and devices, aimed at identifying key sources of loss: including two-level systems (TLS), quasiparticles, and other noise mechanisms. These studies span microwave loss characterization in materials such as niobium, tantalum, aluminum, and their native oxides, as well as substrate losses in silicon and sapphire. Using both qubits and cavities, we disentangle subsystem contributions to loss and develop a hierarchy of mitigation strategies. Through these efforts, we have achieved transmon coherence times exceeding one millisecond. I will also present investigations into quasiparticle dynamics, including bursts observed in qubits located above ground and in the Gran Sasso underground laboratory. Additional studies explore temperature dependence to distinguish between TLS and quasiparticle losses, and reveal that applying a magnetic field can reduce temporal T1 fluctuations in transmons.

Building on these results, we demonstrate a record-coherence two-cell cavity-qudit system with coherence times exceeding 20 milliseconds. By leveraging sideband interactions and error-resilient protocols—including measurement-based correction and post-selection, we achieve high-fidelity quantum state control. This includes preparation of Fock states up to $N = 20$ with fidelities over 95%, and two-mode entanglement with coherence-limited fidelities reaching 99.9% after post-selection. These achievements position the SQMS platform as a powerful foundation for scalable quantum information processing and high-dimensional qudit encodings. Finally, I will discuss how these ultra-coherent systems are being deployed in emerging quantum sensing applications, including dark matter searches and gravitational wave detection.

Surface Science

Room 209 CDE W - Session SS+2D-TuM

Complex Phenomena on Surfaces

Moderators: **Te-Yu Chien**, University of Wyoming, **Bo-Hong Liu**, National Synchrotron Radiation Research Center

8:00am SS+2D-TuM-1 Atomically Precise Synthesis and Characterization of Defect Structures in Graphene, *An-Ping Li*, Oak Ridge National Laboratory INVITED

Atomically precise engineering of defects and interfaces in graphene, along with a detailed understanding of its structure-dependent electronic properties, is essential for the advancement of graphene-based quantum electronic applications. Here we present recent progress in the controlled synthesis and atomic-resolution characterization of defect structures in graphitic nanomaterials. The first approach involves bottom-up synthesis of graphitic nanostructures using on-surface chemical reactions using rationally designed molecular precursors. Particularly, graphene nanoribbons (GNRs) are obtained on a non-metallic substrate, showing entangled magnetic states that are decoupled from the substrate. The multistep thermally triggered transformations rely on highly selective and sequential activations of C-Br, C-F bonds, followed by cyclodehydrogenation. Scanning tunneling microscopy and spectroscopy (STM/S) are used to monitor the formation of intermediates and GNRs, revealing a weak interaction between GNRs and the substrate. The second approach employs a top-down strategy to introduce oxygen (O) substitutions into epitaxial graphene grown on SiC. Techniques including ion implantation and STM tip-assisted manipulation are used to create sp^2 -hybridized O dopants and control its configuration. A combination of chemical-bond-resolved non-contact atomic force microscopy (ncAFM) and STM is used to investigate the structural and electronic properties of the O-related defects. The STM/S measurements, supported by DFT calculations, indicate that the sp^2 -hybridized O dopant hosts a characteristic π -orbital electronic state below the Dirac point. Tuning the Fermi level with electric field may achieve single-electron occupancy of these atomically defined

centers. Such control opens the door to the realization of long coherence electron-spin qubits, providing pathway toward graphene-based quantum technologies.

The research was conducted at the Center for Nanophase Materials Sciences (CNMS), a US Department of Energy User Facility.

8:30am SS+2D-TuM-3 Fabrication of Graphene Nanoribbons/Organic Molecules Interface, *A.M. Shashika D. Wijerathna*, Markus Zirnheld, Old Dominion University; He Zhao, Central South University, China; Rockwell Li, Old Dominion University; Pingshan Wang, Central South University and Guangzhou University, China; Yiming Li, Central South University, China; Yuan Zhang, Old Dominion University

Graphene derivative materials are great superlubricant candidates that can be potentially utilized in molecular devices. Therefore, it is essential to understand the mechanical property at the interface that is formed by organic molecules and graphene derivatives materials. In this study, we fabricated an interface formed by organic molecules with armchair graphene nanoribbons and studied its mechanical properties.

15-carbon-wide armchair graphene nanoribbons (15-AGNRs) were synthesized on Au(111) substrate in a bottom-up approach with dibromo-p-pentaphenyl (DBPPP) as precursor molecules. Precursor molecules, DBPPP exhibit two different self-assembly patterns on Au(111) substrate, forming rectangular domains and hexagonal domains. Both self-assembly structures can be successfully transformed into 15-AGNRs through polymerization at 370 K and, subsequently, cyclodehydrogenation at 470 K. 30-GNRs were also observed in some cases.

Subsequently, pentacene molecules, a linear polycyclic aromatic hydrocarbon consisting of five linearly-fused benzene (C_6H_6) rings, were deposited onto the AGNRs to form the interface pentacene/AGNRs. Pentacene molecules exhibited a preference for adsorption on the Au(111) substrate than the graphene nanoribbons. Therefore, they first fill in gapping areas formed in between graphene nanoribbons, and once the metallic surface sites are fully occupied, they adsorb onto the ribbons. Pentacene is adsorbed on AGNRs in different orientations, which include nearly transverse, oblique, and nearly axial. Among these, the most energetically favorable and stable orientation is nearly transverse, where the pentacene molecular long axis is approximately 93° clockwise relative to the GNR axis. Notably, external mechanical energy facilitated the movement of pentacene molecules along the GNRs, suggesting low molecular-scale friction. These findings provide critical insights into the adsorption behavior of pentacene on AGNRs and mechanical properties of the interface, which is essential for advancing their applications in organic electronics.

This work is conducted with a low-temperature (~ 77 K), ultra-high vacuum (10^{-10} mbar) scanning tunneling microscopy (LT-UHV-STM).

Keywords: Armchair Graphene Nanoribbons, Pentacene, Friction at Molecular Interface, Adsorption Orientation, Scanning Tunneling Microscope

8:45am SS+2D-TuM-4 Visualizing the Products of Scattering at Surfaces: Hot Transient Motion of N on Ru(0001) and Coverage Dependent Mobility and Placement of O on Moiré Graphene, *Joshua Wagner^{1,2}*, Steven Sibener, University of Chicago

Diffusion of atomic species is a pivotal process in surface chemistry for topics ranging from catalysis to material stability. This presentation focuses on two types of atomic mobility: the nonthermalized “hot” atomic motion of N atoms following dissociative chemisorption of N_2 and the highly correlated coverage-dependent diffusion of oxygen atoms on moiré patterned graphene. Overall, results provide spatially rich and atomically resolved insight to on-surface dynamics and illustrate a new direction in the study of interfacial reaction dynamics where outcomes such as site-specific reactivity and non-thermalized diffusion can be examined using incident kinetic energy and angle of incidence as reaction control parameters.

Ruthenium based materials serve as more energy efficient catalysts for the dissociative chemisorption of N_2 , the rate limiting step of ammonia synthesis via the Haber-Bosch process. Despite the global importance of this chemical process, open questions remain concerning the dissipation of energy following dissociation. Answering these questions may inform catalyst design and will enrich our understanding of fundamental surface dynamics.

¹ AVS Dorothy M. and Earl S. Hoffman Awardee

² SSD Morton S. Traum Award Finalist

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To probe the energy dissipation pathways of N_2 dissociation on Ru(0001), tight control of the energy and angle of incident N_2 is achieved *via* supersonic molecular beam fluxes of N_2 molecules. An in-line and *in situ* scanning tunneling microscope (STM) provides atomic-scale visualization of surface products. Analysis of the spatial distributions of N adatoms from the same molecule as a function of incident energy and angle provides insight to the energy dissipation pathways such as energy transfer to phonons and electron hole-pair excitations following dissociative chemisorption.

Exchanging a resistively heated pinhole nozzle for an RF plasma source, the molecular beam can also deliver supersonic ground state atomic oxygen. The site-specificity of atomic oxygen binding on the graphene-Ru(0001) moiré lattice is shown here to be coverage dependent. Furthermore, the stability of oxygen species on epitaxial graphene varies with the number of proximal O atoms as shown by STM imaging. Effects of multiparticle interactions appear in pair-distribution functions, oxygen binding distributions on the moiré lattice, and the diffusivity of O atoms. Comparison of monolayer versus bilayer graphene additionally demonstrates the role that spin-flipping dynamics play in the adsorption of $\text{O}^{(\text{3P})}$ on graphitic surfaces. Overall, results provide insight to the stability of moiré-patterned two-dimensional materials which show promise as platforms for next-generation quantum materials and catalysts.

9:00am SS+2D-TuM-5 Oxygen Diffusion Dynamics on a Rh(111)/(322) Multifaceted Surface, Alexis Gonzalez, Elizabeth Serna-Sanchez, Maxwell Gillum, Stephanie Danahey, Dan Killelea, Loyola University Chicago

The diffusion of oxygen on multifaceted Rhodium (Rh) crystals is of significant interest due to the importance of Rh in heterogeneously catalyzed reactions, such as surface-facilitated oxidation reactions. In this study, we investigate the diffusion dynamics and oxygen species on these two surfaces using temperature-programmed desorption (TPD) and low-energy electron diffraction (LEED) techniques. Despite the structural differences between the (111) and (322) facets, our experiments reveal that the oxygen species on both surfaces are similar, with oxygen existing on the surface as atomic oxygen shortly after adsorption. TPD experiments show that oxygen desorption occurs at comparable temperatures on both surfaces, indicating similar binding energies for oxygen species on each facet. However, LEED shows that there may be different structures forming on either side of the crystal and the orientation of oxygen species are dissimilar. These findings suggest that the oxygen species formed on both (111) and (322) surfaces are essentially the same even though the two surfaces have different atomic arrangements. This observation highlights the importance of other factors, such as surface defects and temperature, in governing the oxygen diffusion process. The study provides information on how surface structure influences the diffusion behavior of oxygen on Rh crystals and emphasizes the need for considering both surface morphology and adsorption characteristics in the design of catalytic materials.

9:15am SS+2D-TuM-6 CO Adsorption on Gr/Ni(111) Single Point Defects, Francesco Armillotta¹, EPFL, Switzerland

Single atom catalysis (SAC) has attracted great interest due to its potential high selectivity, reduced material consumption, and activity. However, a detailed atomistic insight into the active sites and reaction details is still limited, which is fundamental for the understanding and engineering of SAC. We show that even simple molecular adsorption and desorption can reveal non-trivial aspects that affect, for example, the overall sticking probability. We study the CO chemisorption on a model single atom catalyst, where single Co and Ni atoms are adsorbed (or stabilized) in graphene (Gr) vacancies during graphene growth by chemical vapor deposition (CVD) on a Ni single crystal.^{1,2} The study is carried out using a custom designed high-resolution Thermal Desorption Spectroscopy (TDS) instrument in combination with a Variable Temperature STM. In particular, the TDS instrument allows for the study of active sites with a very low surface coverage, of the order of 10^{-3} monolayers. We provide a thorough characterization of the active sites for CO adsorption on Gr (Fig. 1a).^{3,5} In particular, the identification of Ni and Co in Gr di- and tri-vacancies, the dependence on the azimuthal Gr orientation, and an unreported CO chemisorbed state on pristine Gr. We show that the nature of the single point defect can have a huge impact on the CO adsorption probability, accounting for differences up to a factor of 10^4 . We explain the existence of very different main adsorption channels, such as a reverse spillover (Fig. 1b) and activated adsorption *via* a precursor state (Fig. 1c), both known for extended surfaces but never reported for single atoms.^{4,5} The well-defined

geometries allow for direct and reliable comparison with *ab initio* simulations, revealing important thermodynamic and kinetic aspects.

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(4) Armillotta, F.; Naderasli, P.; Chesnyak, V.; Brune, H., *J. Phys. Chem. C* **2025**, *129* (10), 4915–4922

(5) Armillotta, F.; Naderasli, P.; Chesnyak, V.; Panighel, M.; Carnevali, V.; Africh, C.; Peressi, M.; Brune, H. Carbon monoxide adsorption on intrinsically defected graphene on nickel *in preparation*

9:30am SS+2D-TuM-7 Spin and Transport in Graphene Nanostructures with π -Magnetism, Thomas Frederiksen, Donostia International Physics Center (DIPC), Spain

INVITED

The emergence of π -magnetism in open-shell graphene nanostructures—long anticipated from theoretical models—has seen remarkable experimental breakthroughs in recent years, driven by advances in on-surface synthesis and scanning probe techniques. These developments have enabled the realization and manipulation of localized spin states with atomic precision, opening new opportunities in spin-dependent phenomena at the nanoscale. In this talk, I will highlight recent progress in understanding and engineering π -magnetism in graphene nanostructures through three complementary theoretical perspectives. First, I will discuss theoretical efforts to interpret scanning tunneling microscopy (STM) experiments that probe spin-resolved phenomena in atomically precise nanographenes. Second, I will present theoretical results on hyperfine interactions in π -magnetic nanographenes, where significant and anisotropic couplings suggest promising avenues for detection via techniques such as ESR-STM and for studying coherent nuclear dynamics. Finally, I will introduce a proposal for a spin-polarizing electron beam splitter based on crossed graphene nanoribbons, showing how such structures could serve as building blocks for spintronics and quantum interference devices. Together, these directions underscore the potential of graphene nanostructures for both fundamental quantum science and future quantum technologies.

11:00am SS+2D-TuM-13 Simultaneous Electron Spectroscopy and X-Ray Scattering on Model Ceria Catalysts, Baran Eren, Weizmann Institute of Science, Israel

INVITED

Heterogeneous catalysis is a timely and critical research field in basic and applied energy sciences, due to its potential to provide solutions to global environmental issues. However, there is still a lack of a profound understanding of the molecular and structural processes at the interfaces between solids and reactant gases. A detailed understanding of the correlation between the chemistry, structure, and function in these materials requires a multimodal investigation. Over the past few years, scientists at the Advanced Light Source, the Berkeley synchrotron facility, have developed a unique setup attached to an X-ray beamline where chemically-sensitive ambient pressure X-ray photoelectron spectroscopy (APXPS) and structure-sensitive grazing incidence X-ray scattering (GIKS) experiments can be performed simultaneously. Here, we showcase that this tool can provide mechanistic insights that are unparalleled in the literature.

This novel approach allows us to probe the changing surface and bulk chemistry, and surface and bulk structure of the model ceria catalysts in the presence of H_2 and CO_2 gases. In addition to the method itself, the electron density, surface chemistry, and roughness trends observed in ceria during the reaction will be discussed in this talk. Access to such a variety of data from working catalysts in a single experiment can have far-reaching implications, because changes in surface roughness, ability to store hydrogen in the bulk in various forms, and the chemical state of the surface, which all depend on the reactive environment, can directly affect the catalyst performance.

¹ JVST Highlighted Talk

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11:30am SS+2D-TuM-15 Vibrational Spectroscopic Identification of Carbon Absorbed Beneath the Metal Surface, *Santosh K. Singh¹, Volkan Cinar, Sylvia T. Ceyer*, Massachusetts Institute of Technology

Carbon dissolved in transition metals, also known as subsurface or bulk carbon, plays a critically important role in many technological processes. Subsurface carbon atoms have been recognized as essential for the catalytic growth of carbon nanotubes, graphene synthesis, and operation of direct carbon fuel cells. Despite the recognition of carbon bound beneath the surface of a metal as a crucial species in many chemical and catalytic processes, it has not been identified spectroscopically using methods that do not destroy the sample. We report the first vibrational spectroscopic identification of bulk carbon in a Au-Ni(111) surface alloy by high-resolution electron energy loss spectroscopy (HREELS) and its unambiguous synthesis via collision-induced absorption (CIA). The vibrational modes of carbon embedded beneath the surface alloy are shown to be distinguishable from surface-bound carbon based on their intensity dependence on the incident electron energy. Three distinct peak features, centered around 690, 500, and 380 cm⁻¹, are assigned to modes of subsurface carbon atoms that are located at octahedral sites and triangular misfit dislocation loops of the second layer of Au/Ni surface alloy. Additional confirmation of these assignments come from their appearance after CIA experiments, in which surface bound carbon atoms are hammered into the bulk by collisions with energetic gas phase Xe atoms, accompanied by a decreased intensity of the surface carbon mode at 540 cm⁻¹. This work reports for the first time a new method to spectroscopically identify interstitial carbon below the surface of a solid metal and a non-thermal method to synthesize it.

11:45am SS+2D-TuM-16 Pt-Sn Catalysts for Selective Hydrogenation of Furfural, *Donna Chen, Sharfa Farzandh*, University of South Carolina; *Wenrui Chai, Katherine Mader, Graeme Henkelman*, University of Texas at Austin; *Mengxiong Qiao*, University of South Carolina

The production of high value chemicals from biomass is an attractive option for reducing economic dependence on fossil fuels, and the development of new catalysts for selective transformation of highly functionalized biomass derivatives has become an important area of research. For example, furfural is a platform chemical derived from biomass reforming, and catalysts are needed for the desired selective hydrogenation of furfural to furfuryl alcohol, which is a high-value chemical used in adhesives, resins, and coatings. In this work, model Pt-Sn surface alloy catalysts were prepared in ultrahigh vacuum (UHV) by vapor-depositing Sn on Pt(111) and annealing to various temperatures. Specifically, a $\sqrt{3}x\sqrt{3}$ -R30 low energy electron diffraction pattern was observed after annealing one monolayer of Sn on Pt(111) to 800 K, while a p(2x2) pattern was observed after annealing to 1000 K. Low energy ion scattering studies confirmed that these two ordered overlayers have compositions roughly corresponding to Pt₂Sn and Pt₃Sn, respectively. Furfural hydrogenation was studied in a microreactor coupled directly to the UHV chamber under reaction conditions of 0.1% furfural/balance H₂ at 160 °C. On Pt(111), conversion was low (~5%), with THF and furan as the main products and no furfuryl alcohol produced. However, on the p(2x2) surface, the desired furfuryl alcohol product was formed with ~70% selectivity, and conversion was ten times higher than on Pt(111). Furfuryl alcohol was also observed on the $\sqrt{3}x\sqrt{3}$ -R30 alloy surface, but the yield was only 25% of that on the p(2x2) surface. Furthermore, furfuryl alcohol production was even lower on annealed Pt-Sn surfaces with lower Sn coverages or unannealed surfaces with the same coverage. Density functional theory and minimum energy pathway calculations showed that in the first hydrogenation step, hydrogenation at the carbonyl oxygen is both kinetically and thermodynamically favored on the Pt, Pt₃Sn, and Pt₂Sn surfaces. In the second step, hydrogenation at the C-OH carbon has a low energy barrier (0.3 eV) on the Pt₃Sn surface but is not favorable on Pt(111) or Pt₂Sn (≥ 0.8 eV). These differences are explained by a combination of electronic effects that decrease the binding energy of hydrogen on the Pt-Sn alloy surface and adsorption geometries. Furfural hydrogenation was also studied on bimetallic Pt-Sn clusters supported on TiO₂(110), but these surfaces were always rich in Sn and not active for furfuryl alcohol formation.

12:00pm SS+2D-TuM-17 Bimodal Sputter Depletion of Adsorbed Na from Granular, Regolith-Like, Olivine Targets, *Adam Woodson, Cassandre Morel, Noah Jäggi, Catherine Dukes*, University of Virginia

Regolith roughness is expected to modulate the sputter flux of surface atoms into the exospheres of airless bodies such as Mercury. Studies have shown that roughness—from the nanometer scale upward—promotes redeposition and diminishes total sputtering yields. Experiments involving

irradiation of minerals and single-element powders demonstrate yield reductions anywhere from 15% to 70% as compared to smooth targets, but the grain size dependence of this effect has not been adequately parameterized. Understanding this mechanism is therefore of critical importance for quantifying desorption and sputter ejection and for predicting the relative contributions of release processes from planetary surfaces.

We measured the sputter depletion of adsorbed Na from polished natural olivine and from synthetic granular forsterite targets with narrow grain size distributions from 45 μ m up to 520 μ m. Na vapor was deposited onto each target in an ultrahigh vacuum system and then irradiated at either 15° or 60° incidence (from global surface normal) to prescribed fluence steps using 4 keV He⁺ ions. All experimental steps were carried out at room temperature (~300 K). After each fluence step an XPS spectrum was acquired and used to quantify the remaining Na surface concentration. Depletion cross sections were then extracted from the concentration vs. fluence data for each target, and sputtering simulations were conducted using SDTrimSP to recreate experimental observations and corroborate target surface structure and stoichiometry.

For the polished targets, Na concentrations exhibited single-exponential decay with increasing fluence, and depletion at 60° incidence outpaced that at 15° as expected from theory. Conversely, for all granular samples the Na concentrations exhibited at least double-exponential decay and depletion occurred more quickly at 15°. We propose that this reflects faster removal of Na that is directly exposed to the incident ion flux, convolved with slower removal of shadowed Na by—primarily—reflected incident ions. We found that the shadowed sodium was sputtered away 10–100 times more slowly than the exposed Na, with a transition from single-exponential to double-exponential decay at some threshold between nanoscale roughness (polished targets) and microscale roughness. These results may help to explain, for example, why current models underestimate the persistence of Na density enhancements in Mercury's dayside exosphere, as observed by the MESSENGER spacecraft's UltraViolet and Visible Spectrometer.

Thin Films

Room 206 B W - Session TF1+EM-TuM

Thin Films for Energy III

Moderator: Feng Yan, Arizona State University

8:15am TF1+EM-TuM-2 ALD NASICON/TiO₂ Nanocomposite Electrode with Electrochemical Phase Control for High Energy and Power Density Selectivity, *Daniela R. Fontecha, Sangbok Lee*, University of Maryland, College Park; *Alexander C. Kozen*, University of Vermont; *Gary W. Rubloff, Keith E. Gregorczyk*, University of Maryland, College Park

Advancements in ionic devices for energy applications (e.g., solid-state micro-batteries and ionic capacitors) require significant development of compatible materials and fabrication processes to enable high performance conduction and storage of ions. Atomic layer deposition (ALD) is uniquely positioned to utilize device fabrication strategies compatible with CMOS-processing due to its high conformality, that enables on-chip deposition of energy storage devices. Development of fast Li-ion conducting ALD films with coinciding electronic conductivity can help push the boundaries of energy and power delivery in microelectronics.

Although amorphous ALD metal phosphates have been well studied as Li-ion conductors for thin film batteries, there is a gap in the materials exploration space with regards to fast-ion-conducting crystalline phases. This work focuses on the Li-Ti-P-O metal phosphate materials system inspired by the fast ion conducting NASICON structure. Li₂Ti₂(PO₄)₃ (LTP) has been previously developed as a bulk solid electrolyte with Li-ion conductivities up to 10⁻⁵ S/cm. In addition to the fast ionic conductivity achieved by the NASICON crystalline structure, this phase is also capable of accepting additional Li-ions into its structure if there exists an external electron conduction pathway to perform the redox reaction.

In this work, an ALD process for the Li-Ti-P-O materials system is developed into a nanocomposite that contains NASICON LTP grains and anatase TiO₂ grains embedded in an amorphous matrix with post-process annealing at 650 °C for 8.5 minutes. The TiO₂ provides a source of electron conduction (2.2 x 10⁻⁷ S/cm) and the NASICON-type LTP provides a source of fast Li-ion conduction (9.3 x 10⁻⁷ S/cm). This ALD nanocomposite electrode was studied electrochemically in a two-electrode beaker cell vs Li⁺/Li. The NASICON phase is reversible between 1.6 – 3.5 V and the TiO₂ anatase grains provide additional Li-ion storage capacity up to 257 mAh/g at 1C and

¹ JVST Highlighted Talk

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71% retention at 20 C. When the cell is cycled to 0.5 V vs Li⁺/Li, the NASICON phase is not reversible but the pseudocapacitance gained from the amorphous matrix increases the stable capacity to 1305 mAh/g at 1C and 61% retention at 20C. These two stable voltage windows show the versatility in applications for microelectronics possible with this ALD materials system that can leverage the high capacity of the amorphous matrix (microbatteries) or the fast kinetics of the NASICON-type phase (pseudocapacitors).

8:30am TF1+EM-TuM-3 Laser Raster Pattern Control for Uniform Deposition of Hybrid Organic-Inorganic Perovskites via RIR-MAPLE, **Joshua Ayeni**, Adrienne Stiff-Roberts, Duke University

Achieving uniform, scalable hybrid organic-inorganic perovskite (HOIP) deposition remains a key challenge, especially for pulsed laser deposition (PLD) systems [1]. Resonant infrared matrix-assisted pulsed laser evaporation (RIR-MAPLE), a variant of PLD, offers gentle deposition of complex, multi-component materials with excellent stoichiometric and structural integrity [2-3]. However, it is difficult to ensure consistent film thickness and spatial uniformity due to a limited understanding of how laser raster patterns (LRP) impact plume dynamics and film growth mechanisms. Despite its crucial role, the impact of LRP on the quality of films deposited by RIR-MAPLE remains underexplored.

This study aims to address these challenges by investigating the impact of LRP on film thickness, spatial uniformity, and optoelectronic properties of (PEA)₂PbI₄ thin films, paving the way for scalable industrial applications. (PEA)₂PbI₄, a two-dimensional hybrid perovskite known for its exceptional stability and tunable optoelectronic properties, holds promise for applications in light-emitting diodes, solar cells, and photodetectors [4].

Thin films were deposited under high vacuum conditions ($\sim 10^{-5}$ Torr) with five distinct raster patterns (A-E), each varying in mirror positions and rastering speeds to control material distribution. Film thickness and uniformity were measured by profilometry and scanning electron microscopy (SEM), revealing that LRP notably affects deposition outcomes. Patterns A and B produced the thickest films (305-385 nm) with lower radial thickness variations. Markedly, pattern B shows a moderate variation, offering a trade-off between film thickness and spatial uniformity. However, patterns D and E show greater non-uniformity, and C exhibits the largest spatial variation. These results show that variations in LRP greatly affect deposition rates and morphology, highlighting the need for systematic pattern optimization. The study emphasizes the role of plume overlap and local energy dispersion in controlling growth dynamics during deposition.

To enable predictive control over film properties, a simulation-based model is being developed to characterize the behavior of the plume generated under different LRP conditions. Characterizations such as XRD, XPS, PL, UV-Vis, and electrical measurements will be conducted to assess film properties and performance. By relating deposition conditions to intrinsic material properties, this study lays the foundation for scaling RIR-MAPLE to meet industrial demands for hybrid perovskite-based technologies.

This work is supported by the National Science Foundation under Grant No. NSF CMMI-2227551.

8:45am TF1+EM-TuM-4 Role of Thermodynamics for Low-temperature Processing of Perovskite Chalcogenides: A Combined Approach of Density Functional Theory and Experiment, **Ramji Velayutham**, Susmita Jana, Kumar Shwetabh, Birabar Ranjit Kumar Nanda, Surendra Anantharaman, Indian Institute of Technology Madras, India

Semiconductors for optoelectronic devices are an ever growing topic of research for achieving cost-effective, solution-processable, and scalable techniques for applications in energy harvesting and generation. Compared to III-V semiconductors, metal halide perovskites have revolutionized photovoltaic and light emitting technologies as they meet most of the requirements mentioned above. Perovskites with ABX₃ structure where A-site can be organic or inorganic(MA, FA, Cs), B-site is inorganic, typically Sn or Pb, and X site can be halides (Cl, Br, I). Bandgap tuning by varying the composition and low-temperature synthesis are advantages of halide perovskites^{1,2}. However, the chemical stability and presence of lead are major roadblocks for commercialization of these devices. On the other hand, perovskite chalcogenides with chalcogens provide enhanced stability compared to halide perovskites. The high-temperature phase formation and phase separation in these chalcogenide systems have gained significant attention for developing low-temperature processing of materials³. Lowering the processing temperatures down to 350 °C has been achieved but not sufficient to develop flexible devices⁴.

In this study, we have explored the possibility of synthesizing the perovskite chalcogenides at lower temperature compared to the literature reports. Using density functional theory, we investigate the thermodynamics of phase formation of perovskite chalcogenides, which are dictated by the configuration entropy and chemical potentials. These results are further verified by synthesizing the exact stoichiometric composition using the chemical vapour deposition technique. X-ray diffraction studies to unravel the phase formation at low-temperature will be presented. We will correlate the absorption and emission spectra from the experimental results with the DFT studies. Further, exciton dynamics at low-temperature from the perovskite chalcogenides will be discussed. We believe that our results will pave the way for introducing perovskite chalcogenides in flexible devices.

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3. C. Wang, R. Nie, Y. Dai, H. Tai, B. Zhu, L. Zhao, Y. Wu, W. Guo, S. Il Seok. Energy Environ. Sci. 17, 1368-1386 (2024).
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9:00am TF1+EM-TuM-5 Alloyed SnO₂-Nb₂O₅ ALD Films for Energy Applications, **Daniel Macayea, Ian Christiansen, William Rekas, Madison Cooney, Elijah Burlinson, Yubin Han, Alexander Kozen**, University of Vermont

Perovskite solar cells are a promising alternative to silicon-based solar cells, however their current lifetimes and durability prohibit their commercial viability. One approach is to utilize ALD SnO₂ as a dual electron transport layer (ETL) and passivation layer applied using Atomic layer deposition (ALD). ALD is a method ubiquitous in the semiconductor industry for growing thin film materials with atomic scale precision. Sequential alternating pulses of metalorganic and oxidation precursors are delivered to a reaction chamber and react to grow a film on the surface of a substrate. Using the metalorganic precursors TDMA-Sn and Nb(OEt)₅, and the oxidation precursors H₂O and O₃, we produced and characterized alloyed thin films of SnO₂ and Nb₂O₅. We will discuss how temperature and oxidation precursor selection impacts growth behavior, optical, and electrical properties of alloyed SnO₂-Nb₂O₅ thin films, and analyze phase evolution during alloyed film annealing through TTT diagrams. Lastly, we will examine the effect the alloyed SnO₂ and Nb₂O₅ films have on perovskite solar cell performance by evaluating the open circuit potential, quantum efficiency, and degradation behavior.

9:15am TF1+EM-TuM-6 Femtosecond Laser Ablation (fs-LA) XPS Depth Profiling of Lead Halide Perovskite Thin Film Solar Cells for Space Applications, **Charlie Chandler**¹, University of Surrey, UK; Dhilan Devadasan, Simon Bacon, Thermo Fisher Scientific, UK; Jae Yun, University of Surrey, UK; Hongjae Shim, University of New South Wales, Australia; Helen Park, Korea Research Institute of Chemical Technology (KRICT), Republic of Korea; Tim Nunney, Thermo Fisher Scientific, UK; Mark Baker, University of Surrey, UK

Perovskites are an exciting field of photovoltaic devices which can be used as solar cell materials for space applications. These devices have shown significant improvements over the last decade in both efficiency and stability. The stability of these devices within the deployed environment is a key area of interest. X-ray photoelectron spectroscopy (XPS) depth profiling of different spin-coated formamidinium lead iodide (CH₃N₂PbI₃) based perovskite thin film solar cells, both pristine and following space environmental testing, have been performed. Depth profiling has been carried out using traditional monatomic and gas cluster ion beam (GCIB) bombardment and compared to profiles recorded using femtosecond laser ablation (fs-LA). A femtosecond laser with a 1030 nm peak wavelength and a pulse duration of 160 fs was employed. The monatomic and cluster ion sputtering depth profiles exhibited chemical damage due to preferential sputtering of C, N and I. Pb⁰ was also observed in the Pb 4f spectrum as a preferential sputtering artefact. fs-LA XPS depth profiles fully retained the true chemical composition of the 500 nm thick perovskite layer [1]. Following different exposures to proton irradiation, fs-LA XPS depth profiling enabled changes in the perovskite chemical composition as a function of depth to be identified and correlated with solar cell performance. An additional propane-1,3-diammonium iodide (PDAI₂) surface treatment following perovskite deposition was shown to reduce the extent of ion beam damage due to self-healing.

¹ JVST Highlighted Talk

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[1] C.W. Chandler et al., *Surface and Interface Analysis* 57 (2025) 246–252

9:30am **TF1+EM-TuM-7 Ambient Degradation Mechanism in Halide Perovskite $\text{Cs}_2\text{AgBiCl}_6$ Revealed by ATR-FTIR, Pulkita Jain¹, Seda Sarp, Eray Aydil, New York University**

Halide perovskites, such as CsPbX_3 , are promising for optoelectronics but face challenges due to lead toxicity. Among these alternatives, $\text{Cs}_2\text{AgBiCl}_6$ has gained attention for its favorable optical properties and potential applications in light-emitting devices. In one potential application, $\text{Cs}_2\text{AgBiCl}_6$ is doped with YbCl_3 , a well-known luminescence that enables downconversion and quantum cutting—a process where one ultraviolet photon generates two near-infrared photons. In this energy transfer mechanism, the perovskite host absorbs blue photons and transfers the energy to Yb ions, which then relax (${}^2\text{F}_{5/2} \rightarrow {}^2\text{F}_{7/2}$) and emit near-infrared photons (1.25 eV). In our previous work, we demonstrated that phase-pure $\text{Cs}_2\text{AgBiCl}_6$ thin films required excess BiCl_3 during synthesis to prevent the formation of impurity phases. Using this optimized composition, our Yb -doped films achieved a photoluminescence quantum yield (PLQY) of 50%, attributed to downconversion. However, PLQY decayed to 30% within one week of exposure to ambient conditions. Hypothesizing that this degradation is a surface-related phenomenon, we implemented a surface passivation strategy on both the top and bottom surfaces of the films. This approach resulted in a remarkable increase in PLQY to 75%, which remained stable for over six months. We conducted a time-dependent ATR-FTIR study to investigate further the underlying mechanisms of PLQY decay in non-passivated films. Our findings revealed that water molecules adsorb onto the film surface upon exposure to air, reacting with excess BiCl_3 to form BiOCl and HCl . Concurrently, CO_2 is adsorbed, forming carbonic acid, which is facilitated by the presence of HCl . We observed an infrared absorption peak at $\sim 1440 \text{ cm}^{-1}$ in the FTIR spectrum, attributed to carbonate species, which emerged over time, reinforcing our hypothesis regarding surface reactions. To understand the role of excess BiCl_3 , we deposited film with a stoichiometric amount of BiCl_3 on the ATR crystal and analyzed its FTIR spectrum. The results indicated that while carbonate formed, its intensity was significantly lower and did not change appreciably over time. Additionally, we examined passivated films on the ATR crystal, which exhibited similar behavior, suggesting that the observed carbonate formation is due to the presence of BiCl_3 and the formation of HCl upon its reaction with water vapor. This finding elucidates why PLQY remains stable in passivated films: the passivant protects the bulk from the ambient gases. These insights into the degradation mechanisms of Yb -doped $\text{Cs}_2\text{AgBiCl}_6$ thin films highlight the importance of surface passivation in enhancing long-term stability and performance.

9:45am **TF1+EM-TuM-8 High Rate Low Temperature Processing of Cu-chalcopyrite Semiconductors for Solar Cell Applications, Thomas Lepetit, Institut des matériaux de Nantes Jean Rouxel, France; Nicolas Barreau, Institut des Matériaux de Nantes Jean Rouxel, France; Sylvain Marsillac, Deewakar Poudel, Old Dominion University; Thamer Alaoui, Leo Choubrac, Ludovic Arzel, Université de Nantes, France; Fabien Pineau, CNRS Photovoltaics, France; Angus Rockett, Colorado School of Mines, US**

This talk describes a method to recrystallize Cu-chalcopyrite semiconductors during processing resulting in a greatly accelerated deposition process while retaining high material quality. While a number of flux materials were tested, AgBr was found to produce rapid recrystallization and greatly improved material properties in finished solar cells. Maximum process temperatures for $\text{Cu}(\text{In},\text{Ga})\text{Se}_2$ below 450°C with up to a 4x increase in deposition rate were demonstrated. Recent results have extended this work to ultrathin absorber (480 nm) deposited on transparent indium tin oxide back contacts. Related semi-transparent devices have achieved ~12% efficiency, providing the best device performances obtained to date for such thickness.

Thin Films

Room 206 B W - Session TF2-TuM

VSHOP I - Porous Framework Materials & Membranes

Moderators: Siamak Nejati, University of Nebraska-Lincoln, Junjie Zhao, Zhejiang University

11:00am **TF2-TuM-13 Synthesis of Electrically Conductive Metal-Organic Framework Thin Films, Sarah Park, Pohang University of Science and Technology (POSTECH), Republic of Korea**

INVITED

Conducting metal-organic frameworks (MOFs) present a compelling prospect for the development of high-performance electronic devices, ranging from electrocatalysts and chemiresistive sensors to supercapacitors. Although MOFs typically exhibit low electrical conductivity due to flat bands determined by highly localized organic states and weak hybridization with inorganic units, significant advances have been made in engineering their electrical properties. Specifically, through precise control of symmetry and energy overlap, highly ordered infinite charge transport pathways in conducting MOF platforms have been established. Nevertheless, for practical device integration, a critical challenge lies in processing these materials into functional thin films. This presentation introduces two distinct approaches for synthesizing conductive two-dimensional MOF thin films: a single-step, all-vapor-phase chemical vapor deposition process, and a solution-processable synthetic approach.

11:30am **TF2-TuM-15 Selective Breathing Behavior in Thin Films of Microporous Coordination Polymers, Greg Szulczewski, Hallie Matherne, The University of Alabama**

Thin films in a family of pillared, microporous coordination polymers with the general formula $\text{M}_2(\text{BDC})_2\text{DABCO}$, where M is Ni^{2+} , Cu^{2+} and Zn^{2+} , BDC is benzendicarboxylic acid and DABCO is 1,4-diazabicyclo[2.2.2]octane, were made by a hot vapor synthesis technique. The thin films were characterized by x-ray diffraction, vibrational spectroscopy and scanning electron microscopy. The films were activated by heating under high vacuum and adsorption/desorption isotherms were measured for several volatile organic alcohols. The shape of the isotherms strongly depend on the metal ion of the coordination polymer and the alcohol. In thin films of $\text{Ni}_2(\text{BDC})_2\text{DABCO}$, methanol adsorption isotherms exhibit a characteristic S-shape that is attributed to lattice expansion or breathing above a critical pressure. Upon removal of methanol from the thin film, the lattice relaxes back to the original structure. The breathing phenomena is attributed to the formation of a network of hydrogen bonds between the methanol molecules and BDC ligand.

11:45am **TF2-TuM-16 Atomic Layer Deposition for Pore Engineering in Covalent Organic Framework Thin Films for Enhanced Membrane Gas Separation, Zhiwen Chen, Junjie Zhao, Zhejiang University, China**

Covalent organic frameworks (COFs) are crystalline networks with ordered pores, large surface area and versatile topologies. Developing pore engineering strategies to fine tune the internal functionality and dimension of COF pores could offer proper pore size and affinity towards small gas molecules, which is crucial for applying COFs to membrane gas separation. Here, we report a pore engineering approach for COFs using atomic layer deposition (ALD). We prepared thin films of an imine-based COF (TPB-DHTA) on porous alumina supports via interfacial synthesis. We found that the amount of ZnO deposited into the COF pores can be precisely controlled by varying ALD cycles. Consequently, the original pore size (1.4 nm) was reduced to 1.05 nm, 0.85 nm, and even below 0.6 nm, leading to an improved the diffusion selectivity of H_2/CO_2 through the COF membranes from 93.9 to 278.6 after ALD modification. Moreover, the Zn-O moieties grown into the COF pores were found to shield the CO_2 -philic ketoenamine groups, which substantially reduced the CO_2 solubility in the COF membrane by 262%. Accordingly, the simultaneously increased diffusion selectivity and sorption selectivity for H_2/CO_2 led to a 430% improvement of permselectivity for membrane separation, demonstrating the efficacy of our strategy for pore engineering in COFs.

12:00pm **TF2-TuM-17 Synthesizing Hydrophilic Membranes for PFAS Removal via Molecular Layer Deposition, Joelle V. Scott, Mathangi Venkatesh, Jocelyne Booth, David S. Bergsman, University of Washington**

As the global water crisis continues to worsen, the increased need for access to clean water drives the need for better water treatment technologies, such as through the removal of per- and polyfluoroalkyl substances (PFAS). PFAS are a group of toxic compounds that do not biodegrade due to their strong carbon-fluorine backbone. Common PFAS removal methods include absorption and ion exchange resins, but these

¹ AVS Graduate Research Awardee

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require expensive and energy-intensive regeneration steps. A more efficient removal technology is membrane separation, which has been shown to be effective at removing PFAS from water. Short-chain PFAS are harder to remove than long-chain PFAS due to their decreased size and increased reliance on end group interactions. Due to the reduced hydrophobicity of PFAS as their carbon chain length decreases, increasing the hydrophilicity of the membrane selective layer may increase the rejection of both long- and short-chain PFAS by reducing hydrophobic interactions between the membrane and the PFAS compounds. However, interfacial polymerization, a traditional membrane synthetic approach, relies on identifying two monomers that can be dissolved in different solvents that are immiscible. The thickness of the resulting membrane also cannot be independently controlled, as it is defined by the monomer diffusion length into the counter solvent. In this work, we use molecular layer deposition (MLD) to synthesize thin film composite membranes with the aim to vary hydrophilicity. This approach avoids the issue of identifying appropriate solvents, allowing for a wider range of selective layer chemistries as well as independent control over film thickness. To demonstrate the effectiveness of this technique for controlling membrane properties, polymers based on polyurea, polyamide, and polyester were explored, measuring hydrophilicity and ability to remove long- and short-chain PFAS. Film composition is confirmed using FTIR and XPS. These are correlated with pure water permeability, salt rejection, and PFAS rejection to determine the impact of monomer chemistry.

Vacuum Technology

Room 205 ABCD W - Session VT1-TuM

Measurement, Simulations and Accelerator Vacuum Systems

Moderators: Jacob Ricker, NIST, Julia Scherschligt, National Institute of Standards and Technology

8:00am VT1-TuM-1 ORNL Second Target Station (STS) Vacuum System, Austin Chaires, Oak Ridge National Laboratory, USA **INVITED**

The STS is a \$2 Billion, Department of Energy project to be constructed at the ORNL Spallation Neutron Source (SNS). The STS will provide wholly new capabilities for the study of a broad range of materials with neutron scattering and support thousands of users from the physical, materials, and applied sciences industries. The science capabilities provided by the instrument suite at the STS will complement those of the two existing DOE Office of Science neutron scattering user facilities at ORNL, the First Accelerator Station (FTS) of the SNS and the High Flux Isotope Reactor (HFIR). The STS will deliver the highest peak brightness of cold neutrons in the world, which together with advances in neutron optics, instrumentation, and detectors, will ensure US leadership in neutron scattering for decades to come.

The STS Accelerator Systems group is responsible for the design, fabrication, installation, and testing of all hardware necessary to transport the 700 kW, 15 Hz proton beam to a rotating tungsten target, to create 22 beams of moderate neutrons.

The Ring to Target Beam Transport Beamline vacuum system branches off the existing RTBT's vacuum system and stretches ~230 meters until it ends at the STS's proton beam window (PBW) to the target. The RTST vacuum volume is essentially an 8" diameter cylinder from beginning to end and mostly located concentrically about the beam axis. It is also pocketed with additional spaces at crosses and instrument & shielding housings. The RTST is divided into 7 isolatable sections using all-metal gate valves. All sections contain: magnet vacuum chambers (VC), drift VC adaptors, bellows, beam instrumentation VC, pumps, Pirani gauges (TCG), cold-cathode gauges (CCG), a pumpdown access location, an RGA, and various other valves. Additionally, several large detector vessels and a core vessel are in early design and require systems to obtain low to high vacuum. Positive pressure gas distribution and vacuum analysis capabilities are also required for these systems.

This talk will also offer a cursory glance at the following additional vacuum systems:

- Proton Beam Window Inflatable Seal and Interstitial Space Vacuum Systems
- Cryogenic Moderator Vacuum Systems
- Neutron Guide Beamlines and In-Bunker Vacuum System

8:30am VT1-TuM-3 Robotic Assembly of SRF Cavity Pair, Adam Duzik, Roger Ruber, Jefferson Laboratory

Superconducting Radio Frequency (SRF) cavities for particle accelerators require tight tolerances, ultrahigh vacuum, and strict cleanliness during assembly. As in the semiconductor industry, defects such as particles and residues are deleterious to performance, possibly rendering a cavity unfit for use. This problem is addressed primarily through cleanroom assembly during sensitive steps and rigorous chemical processing to prevent and remove such defects. Human workers are often the largest source of contamination, even with proper gowing and practices. The semiconductor industry has long integrated robots in cleanroom operation, but this has not occurred for SRF cavity production; SRF cavities, unlike wafers, are complex shapes, require more hands-on mechanical assembly, and are low-volume production items.

At Jefferson Laboratory, a co-operative robot (cobot) has been setup to overcome these problems. Cobots are safe for use alongside human workers and can integrate new tools such as a 3D camera part detection and gripper for item manipulation. Therefore, cobots represent a promising avenue for reducing particulate generated during a variety of assembly tasks. A mockup of a cavity pair and coupler was setup and the cobot programmed to automatically pick up the coupler and place on the mating cavity flange. Particle counting methods were setup to measure human vs cobot assembly particulate generation inside a cavity mockup. Other potential uses will be discussed for further improving SRF cavity assembly steps, where a cobot can replace or assist a human operator, and what potential gains are expected.

8:45am VT1-TuM-4 Emergency Vacuum Repairs in an Aging Accelerator: Case Studies and Lessons Learned, Marcy Stutzman, Jefferson Lab

Jefferson Lab operates the CEBAF electron accelerator at energies to 12 GeV for the Department of Energy Nuclear Physics program. The CEBAF injector beamline was designed and built in the early 1990s. Although many of the vacuum components have been upgraded and replaced, many unique, original components are still installed and operating daily. Over the past 3 years, several vacuum leaks have occurred in ageing components leading to emergency repairs on a tight timeline. These include an edge welded bellows and RF power ceramic feedthrough, both of which had been in use for at least 25 years. The nature of these vacuum component failures will be discussed, along with the difficulties in repair due to the age and availability of parts, lessons learned, and what steps are being taken to minimize similar failures going forward.

9:00am VT1-TuM-5 Commissioning and Early Operations of the APS-Upgrade Storage Ring Vacuum System, Jason Carter, Argonne National Laboratory, USA **INVITED**

The Advanced Photon Source's (APS) upgraded storage ring was brought online and began commissioning in April 2024. APS was rebuilt with a new 1100-meter length storage ring vacuum system, a complex assembly of over 2500 custom vacuum components. In 2024 and 2025 APS-U has successfully commissioned the vacuum system to reach the designed pressure levels and allowing the machine to reach key performance parameters and for the facility to provide reliable beam to the users. This presentation will share results and analysis of the vacuum system commissioning along with lessons learned from the installation and operations phases.

9:30am VT1-TuM-7 Design and Construction of a Vacuum End Station for Ion Irradiation in Magnetic Field Environments at the Tennessee Ion Beam Materials Laboratory, Henry Osborne, University of Tennessee Knoxville; Kendall Trellue, University of New Mexico; Miguel Crespillo, University of Tennessee Knoxville; Eric Lang, University of New Mexico; Khalid Hattar, University of Tennessee Knoxville

As nuclear fusion reactors progress closer to becoming a reality, it is important to understand how materials that compose the heart of such reactors behave under the coupled extreme environments. Such intense temperatures, displacement damage, and magnetic field can have a significant impact on the thermal, mechanical, and radiation stability of most candidate alloys. It is essential to have this fundamental understanding for the development of physics-based models, however, this has been under studied due to lack of experimental capabilities. This presentation will detail the design and construction of a custom ion accelerator end station that will permit such experiments at the Tennessee Ion Beam Materials Laboratory (TIBML). This end station design will be compatible with either the MV tandem accelerator already at TIBML or the 300 kV implanter that is soon to arrive. The high vacuum design incorporated for this end station should permit vacuum pressures between 1×10^{-5} Pa and 1×10^{-6} Pa and easy transfers between beamlines. In addition,

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the end station achieves a maximum magnetic field strength of 1.44 Tesla by inserting the sample from the loading portion of the end station through the gate valve into the center of the large switching magnet of the ion accelerator using a 914 mm long linear translator. The exact magnetic field will be measured via hall probe at the sample location during the experiment. It similarly achieves cryogenic temperatures through liquid nitrogen cooling conducted to the sample via copper braids. Due to the extreme conditions created by the cryogenic, magnetic, and radiation environments, several precautions had to be taken in the design, material selection, and development of this end station. Initial results of this new end station design to study the microstructural evolution of materials will be presented. Finally, this presentation will highlight the varied and future potential fusion energy-related experiments that will be made possible through the utilization of this end station. The development of this magnetic end station at TIBML will allow the fusion materials community to better understand coupled extreme environments.

9:45am VT1-TuM-8 Assembly, Conditioning and Installation of ALS-U Accumulator Ring Vacuum System, Sol Omolayo, Lawrence Berkeley Lab, University of California, Berkeley; Thomas Gaucher, Raul Mascote, Lawrence Berkeley Lab

The Accumulator Ring (AR) vacuum system for the upgraded Advance Light Source (ALS-U) features over 320 vacuum chambers connected in series to form the 182m circumference of the AR. Majority of the vacuum chambers are either made from 316 stainless steel or Copper alloys and 25% of the chambers are Non-evaporable Getter NEG coated. The scope of assembly, conditioning and installation of AR vacuum system includes receipt inspection and testing, modular pre-assembly, vacuum bakeout, integration into magnet systems, pre-alignment, installation and in-situ NEG activation. 108 modules were assembled and installed over a 2 year period. An average pressure of 5e-10Torr was achieved after installation. The AR will soon begin beam commissioning. The AR is designed to ultimately circulate 50mA of electron beam as part of the injection system to support the soon-to-be upgraded ALS storage ring.

Vacuum Technology

Room 205 ABCD W - Session VT2-TuM

Measurement, Simulations and Accelerator Vacuum Systems

Moderators: Gerardo Brucker, MKS Instruments, Inc., Yev Lushtak, Lawrence Berkeley Lab

11:00am VT2-TuM-13 Enabling Vacuum Process Monitoring with Time-of-Flight Spectroscopy, Marco John, Klaus Bergner, Sebastian Hüttl, Kristian Kirsch, Andreas Trützschler, VACOM Vakuum Komponenten & Messtechnik GmbH, Germany

The increasing complexity of industrial vacuum processes requires broader and deeper knowledge of the vacuum itself. A crucial aspect for increasing quality demands is the necessity of in-situ monitoring and control of pressure and residual gas composition within vacuum processes. A consequence of advanced process control is the reduction of production errors, prevention of failures or major damage in combination with increased operating time. Traditional monitoring devices like hot cathodes or quadrupole mass spectrometers are both only able to measure either pressure or residual gas composition. Therefore, these devices are only conditionally suited for complete process control of vacuum processes. With our novel wide-range vacuum monitor NOVION®, which combines the well-known technology of time-of-flight spectroscopy with our patented ion trap, industrially available pressure and gas analysis is possible at the same time.

In this talk we present the fundamental principles of the novel vacuum monitor and explain the compact combination of well-known time-of-flight spectroscopy with our own patented ion trap. Within different application cases we discuss advantages and limits of this technology and demonstrate with one single device wide range gas analysis, simultaneous measurement of total and partial pressures, leak detection for Helium and detection of air leaks. With these combined capabilities the novel vacuum monitor is able to quickly capture the complete pressure and gas composition measurement at various stages of the vacuum process chain. In addition, we demonstrate a special signal enhancement method to improve the resolution in the near signal-to-noise range.

11:15am VT2-TuM-14 Update on Fixed Length Optical Cavity (FLOC) Pressure Calibration Standard for Calibration of Military and Commercial Aircraft, Jacob Ricker, Kevin Douglass, Thinh Bui, Jay Hendricks, Jay H. (Fed) <jay.hendricks@nist.gov>, NIST

NIST has constructed several Fixed Length Optical Cavity (FLOC) pressure standards based on gas refractivity and shown that they are effective at measuring absolute pressure [1]. The US Air Force has recently funded development of these standards for the support of their Air Data Calibration Systems. These Air Data Systems provide calibration for altimeters and air speed indicators and traceability of these sensors is crucial for all operational military and commercial aircraft. NIST has been constructing a new portable FLOC constructed of an Invar material. This presentation will describe the assembly and testing of a new lower cost/robust/portable calibration system capable of calibrating gas pressure sensors over the entire range of 1 Pa to 10 MPa. The testing includes pressure performance and system stability.

References:

[1] <https://doi.org/10.1016/j.measen.2021.100286>.

11:30am VT2-TuM-15 Single-Laser Optical Pressure Measurements to Support Air Data Calibration, Kevin Douglass, Thinh Bui, Jacob Ricker, Jay Hendricks, National Institute of Standards & Technology

NIST is currently constructing a portable robust Fixed Length Optical Cavity (FLOC) pressure standard to be optimized for the calibration of aircraft altimeters, rate of climb indicators, and air speed indicators while also extending the operating pressure range close to 10 MPa. To reduce cost and help simplify the operation of the system we have tested an optical approach that only uses a single laser locked to the reference cavity with a portion of that light being modulated to generate a sideband which is locked to the sample cavity. The tradeoffs and advantages of this technique will be discussed.

11:45am VT2-TuM-16 Radiometric Force Due to Accommodation Coefficient of Gas-Surface Interaction, Felix Sharipov, Universidade Federal do Paraná, Physics Department, Brazil; Benjamin Schafer, Harvard University

The radiometric force arises when a body heated non-uniformly by some radiation is immersed in a gas at a low pressure. This phenomenon results from gas-surface interactions, which are characterized by the accommodation coefficients. In turn, these coefficients depend on the gas species and surface properties such as roughness and chemical composition. When the accommodation coefficients are not constant over the body surface, the radiometric phenomenon arises when the body is a different temperature than the surrounding gas, even if the body temperature is uniform. In the present study, we calculate the force exerted on a thin membrane with different accommodation coefficients on its top and bottom surfaces. The membrane temperature is assumed to be higher than that of the surrounding gas. The direct simulation Monte Carlo method is used to span a wide range of the Knudsen number including the free-molecular, transitional, and viscous flow regimes. The force reaches its maximum value when the mean-free-path is close to the membrane diameter. Thus, if the membrane diameter is about 1 cm, then the force is maximum at the pressure about 1 Pa. We show that perforations in the membrane increase the radiometric force for higher pressures. The obtained results allow to optimize the membrane geometrical parameters to reach significant radiometric force. Analysis shows that the radiometric force caused by the accommodation coefficient difference can levitate a lightweight membrane that is a few centimeters wide in near-space conditions.

12:00pm VT2-TuM-17 Thermal Transpiration: Beyond Takaishi and Sensui, Robert Berg, National Institute of Standards and Technology (NIST)

Thermal transpiration, also known as the thermomolecular effect, applies when a pressure gauge at temperature T_2 is used to measure the pressure of a gas held at temperature T_1 . Examples include gas thermometry (say $T_1 = 10$ K) and temperature-controlled gauges (say $T_2 = 318$ K). When the temperature difference is large and the gas mean free path is comparable to the diameter of the tube connecting the two volumes, thermal transpiration can make the pressure ratio P_1/P_2 much less than 1.

Thermal transpiration has been described by physically motivated empirical functions, physics-based numerical models, and a physics-based analytical model. The most common empirical function is that of Takaishi and Sensui (T-S) [1]. Numerical models are rarely used because they rely on details of

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geometry and surface accommodation that restrict the model's use to a specific scenario.

There is only one physics-based analytical model, the “dusty gas” model [2], which employs the concept of a gas composed of infinitely heavy “dust” molecules. The dust molecules scatter the ordinary gas molecules, so that the flow in the connecting tube has a viscous component and an opposing rarified-gas component. The dusty gas model was used during the 1960s and 1970s to describe experimental measurements, most notably by Malinauskas and co-workers. Despite that success, it has not been widely used because the model’s core equation requires a numerical solution.

The dusty gas model is superior to the T-S empirical function. The T-S function assumes perfect surface accommodation, while the dusty-gas model does not. Also, the T-S function has three free parameters of obscure meaning, and fitting those parameters to experimental data can hide an error in the data. In contrast, the dusty gas model has only two free parameters with clear physical meaning. The first parameter accounts for imperfect accommodation, and the second accounts for an error in the ratio λ/d , where λ is the mean free path and d is the tube diameter. A re-analysis of literature data found good agreement with the dusty gas model.

1. T. Takaishi, Y. Sensui, *Trans. Faraday Soc.* **59**, 2503-2514 (1963).
2. A.P. Malinauskas, J.W. Gooch, B.K. Annis, R.E. Fuson, *J. Chem. Phys.* **53**, 1317-1324 (1970).

Tuesday Morning Break, September 23, 2025

Exhibitor Technology Spotlight Sessions

Room Hall A - Session EW-TuMB

Exhibitor Technology Spotlight Session I

Moderator: Christopher Moffitt, Kratos Analytical Inc

10:15am **EW-TuMB-2 New Developments for Surface Analysis from Thermo Fisher Scientific**, *Tim Nunney, Robin Simpson, Paul Mack, Simon Bacon, Dhilan Devadasan*, Thermo Fisher Scientific, UK; *Charlie Chandler, Mark Baker*, University of Surrey, UK

In this presentation we will showcase the latest innovations in instrumentation for surface and materials analysis from Thermo Fisher Scientific, including a new instrument for improving capabilities for XPS depth profiling.

10:30am **EW-TuMB-3 Enviro Standard Analytical Tools: New Developments and Applications**, *Francesca Mirabella, Stefan Böttcher, Paul Dietrich, Andreas Thißen*, SPECS Surface Nano Analysis GmbH, Germany

This presentation will focus on recent advancements and applications of our comprehensive surface analytical instrumentation the Enviro Standard Analytical Tools, with a particular emphasis on X-ray Photoelectron Spectroscopy (XPS) and Hard X-ray Photoelectron Spectroscopy (HAXPES). These techniques offer powerful insights into chemical composition, electronic structure, and buried interfaces. These tools have been integrated with additional modalities such as Scanning Electron Microscopy (SEM), Scanning Auger Microscopy (SAM), Ultraviolet Photoelectron Spectroscopy (UPS), and Inverse Photoemission Spectroscopy (IPES), enabling multi-faceted characterization from surface to subsurface to address complex analytical challenges. The talk will include a discussion of innovations in instrumentation and recent applications.

10:45am **EW-TuMB-4 Small Lab-Size Cryogen-Free Low Temperature SPM with Magnetic Field**, *Juergen Koeble*, Scienta Omicron GmbH, Germany; *Andrew Yost*, Scienta Omicron Inc

The rising price of liquid helium increasingly and significantly adds to operational costs for low temperature SPM research. Recent advances in cryogenic technologies coupled with improvements in cooling power, temperature stability, and vibrational properties allow for integration into highly sensitive instruments such as scanning probe microscopes. Following scientific demands for nano-scale scanning probe microscopy, e.g. low temperature, optical and magnetic analysis, RF signaling, lowest drift, and signal-to-noise, we have developed a modular cryogen-free low temperature scanning probe microscope for STM and AFM in ultra-high vacuum. The new **ARCTIC** SPM represents the latest innovation in ultra-low-temperature scanning probe microscopy.

Built on our newly developed **ARCTIC** closed-cycle cooling platform, it combines cutting-edge technology with user-friendly operation. With the **ARCTIC** SPM LAB, you benefit from unattended, continuous cooling, eliminating the complexities of handling extreme temperatures while delivering virtually unlimited measurement time with stability traditionally only associated with liquid helium cryostat-based SPMs. The **ARCTIC** SPM also provides long-term stable low temperature operation of a dry superconducting magnet, and this new highly compact scanning probe microscope offers easy optical access for advanced optical experiments even in the presence of a high magnetic field.

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Exhibitor Technology Spotlight Sessions

Room Hall A - Session EW-TuL

Exhibitor Technology Spotlight Session II

Moderator: Christopher Moffitt, Kratos Analytical Inc

12:30pm EW-TuL-2 RHK Technology: 37 Years of Continuous SPM Innovation, **Adam Kollin**, RHK Technology, Inc.

RHK Technology was founded in 1981 to develop new research tools for the Surface Science research community. The first product introduced was a High Resolution Electron Energy Loss Spectrometer (HREELS) followed by a Digital Temperature Controller for Temperature Programmed Desorption (TPD) measurements. RHK introduced its first Scanning Probe Microscope control system in 1988. In the following 37 years, RHK has developed a wide range of cutting-edge Scanning Probe Microscopes focused on UHV and cryogenic environments. The company is located in Troy Michigan and has delivered over 1500 SPM systems to over 40 countries around the world.

Adam Kollin, the founder and CEO of RHK Technology will discuss the latest advances from RHK including their new tenth generation SPM control system, the R10. Further advances in their cryo-free SPM system will be highlighted such as new Lumin-SLT that features a 70% light collection efficiency for Cathodoluminescence (CL) Photoluminescence (PL), STM Light Emission (STM-LE) as well as Raman spectroscopy studies. Upcoming capabilities will also be discussed.

12:45pm EW-TuL-3 Kratos Axis Supra+ -- Automated Laboratory XPS Analysis, **Chris Moffitt**, Kratos Analytical Inc.

As demand for surface analysis increases across materials systems, the automation of modern instrumentation provides broader access to more robust analyses, over larger sample sets, with advanced approaches. The Kratos Axis Supra+ multi-technique XPS system incorporates automated sample handling with automated analysis of XPS, UPS, depth profiling and others, including higher energy Ag-La generated, quantitative HAXPES, for increased depth analysis and clarification of chemical state.

The Axis Supra+ is uncompromised in its ability to analyze the wide range of new advanced materials, including operando surface analysis measurement of battery materials while biasing or flowing current and heating. The multi-contact stage in the Axis Supra⁺ spectrometer accommodates the specialized holders for the operando analysis, supplying 4 electrical contacts to be used for these analyses, while still accepting all the standard sample platens for high throughput analysis. An inert sample transfer version of these multi-contact holders has also been developed, which allows the sample to be loaded onto the platen and electrical connections made in a glove box, and then loaded into the spectrometer without exposure to atmosphere. Cryo-cooling of battery and other materials has been shown to minimize degradation and chemical bonding damage that can be caused by x-ray exposure at room temperature, and Kratos offers new sample holder options that allow cooling of sample to cryogenic temperatures to mitigate chemical changes during XPS measurement, as well as measure biological samples after fast freezing onto a pre-cooled sample holder.

The Axis Supra+ allows more samples to be analyzed with the full capabilities of the highest-performing XPS instrument, without intervention. Once samples are physically loaded, analyses are submitted through the computer interface, utilizing multiple cameras for location identification, which can be done remotely. This same principle follows for utilizing the HAXPES mono source, so that analysis by standard Al-Ka monochromatic x-rays can be automatically followed by analysis with the higher energy Ag-La monochromatic source and the results automatically processed and quantified using new Data Dependent Acquisition software features. Additional analytical techniques, such as Ag-La HAXPES, ISS, UPS, AES, REELS and IPES are all possible on the Supra⁺, and additional sample preparation chambers can be easily added, such as a station for deposition or the high-pressure, high-temperature gas reaction cell for catalysis experiments and measurement.

1:00pm EW-TuL-4 Physical Electronics Spotlight Session: Driving Discoveries Through Surface Analysis: Innovative Technologies for Thin Film Characterization, **Amy Ferryman**, Physical Electronics

Physical Electronics (PHI) offers the world's most complete portfolio of powerful surface analysis instruments, including X-ray photoelectron spectroscopy (XPS), Auger electron spectroscopy (AES) and secondary ion mass spectrometry (SIMS). Our innovative technologies provide unique tools to solve challenging problems, accelerating development and discovery of advanced materials and products. This presentation will

highlight recent developments in methodologies for thin film characterization utilizing our automated PHI *Genesis* multi-technique XPS platform in combination with our powerful, next generation *StrataPHI* software package, a tool designed to calculate the thickness and structure of advanced multilayer thin film structures using spectral and angle-dependent XPS (ADXPS) and hard X-ray photoelectron spectroscopy (HAXPES) data.

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2D Materials

Room 205 ABCD W - Session 2D-TuA

2D Materials: Theory and Applications

Moderator: Kai Xiao, Oak Ridge National Laboratory

5:15pm **2D-TuA-13 Theoretical Study of van der Waals epitaxy of Biayer Silicene on III-Sb substrates, Kumar Vishal, Hong Huang, yan zhuang, wright state university**

Research development of integrated silicon photonics in the mid-infrared (MIR) range has gained considerable momentum over the past decades, driven by its vital applications in biochemical sensing, medicine, and even astronomy communications. However, progress has been hampered by the limitation by the energy bandgap and optical transparency in conventional material. Very recently, it has been reported that 2D bilayer silicon (BLSi) demonstrates unique optical properties across the MIR spectrum. By adjusting the strain, the optical absorptions can be tuned in a wide range of wavelength from 1.5 -11.5 mm. However, experimentally the maximum in-plane strain achieved is ~7% in a lattice-matching epitaxial silicon. Remote- and Van der Waals epitaxy methods can break the lattice-mismatch constraint to obtain single crystal 2D materials, but with an insufficient in-plane strain preserved in the 2D films.

In this work, motivated by the recent achievement of dative epitaxy of single crystalline Cr₅Te₈ on WSe₂ enduring a ~16% lattice mismatch, we conducted a theoretical study based on density function theory (DFT). Our aim is to explore the feasibility of growing BLSi on two III-Sb substrates: GaSb and AlSb. These substrates were chosen due to their ability to provide sufficient in-plane strain (11.92% and 12.23% respectively) to assure energy bandgap opening in BLSi. The generalized gradient approximation (GGA) and the strongly constrained and appropriately normed (SCAN) meta-generalized gradient approximation (meta-GGA) have been employed in the computation to analyze the chemical bond formation and to optimize the energetically favorable atomic structures. Our findings suggest that Van der Waals epitaxy of BLSi on both of the III-Sb substrates is viable when the substrate's surfaces are terminated with the metallic atoms. By forming the dative bonds between the BLSi and the III-Sb substrates, substantial in-plane strain in BLSi can be preserved, leading to a low buckled BLSi with an opened energy bandgaps.

5:30pm **2D-TuA-14 Tuning Bandgap in Nanoporous Graphene through Molecular Design, Mamun Sarker, Alexander Sinitskii, University of Nebraska - Lincoln**

Molecular design is a powerful tool for growing graphene nanostructures with atomic precision, enabling control over their electronic and physical properties. Precisely tuning these properties is essential for advancing the next generation of graphene-based 2D electronic devices. In this presentation, I will discuss the on-surface synthesis of novel nanoporous graphene (NPG) materials, whose electronic bandgaps can be tuned from semiconducting to nearly metallic through rational molecular design. These NPGs were synthesized using custom-designed polyaromatic precursors deposited on Au(111) and thermally activated under ultra-high vacuum via surface-assisted chemical reactions. Scanning tunneling microscopy (STM) reveals the structural integrity and periodicity of nanoporous networks. Scanning tunneling spectroscopy (STS), in combination with density functional theory (DFT), shows that strategic modifications in the pore size, topology, and connectivity can reduce the bandgap to as low as 0.05 eV, approaching metallic behavior. This work not only demonstrates the feasibility of tailoring graphene's electronic structure with sub-nanometer precision but also establishes a versatile platform for engineering low-bandgap 2D materials.

5:45pm **2D-TuA-15 How Transparent Is Graphene? An Analytical Model for Remote Epitaxy, Jason Kawasaki, University of Wisconsin Madison**

We propose an analytical model for the remote bonding potential of the substrate ϕ_{remote} that permeates through graphene during remote epitaxy. Our model, based on a Morse interatomic potential, includes the attenuation due to (1) the increased separation between film and substrate and (2) free carrier screening from graphene. Compared with previous slab density functional theory calculations, which use the electrostatic potential as a proxy for bonding, our analytical model provides a more direct description of bonding, explicitly includes screening (which is often ignored), and is based on simple, interpretable, and well benchmarked parameters. We show that the magnitude of $\phi_{\text{remote}}(z)$ for typical semiconductor and oxide substrates is few meV or smaller, similar to the van der Waals potential of graphene. This suggests that the potential of graphene, plus the interference between the

remote substrate and graphene potentials, must be considered when interpreting experiments on remote epitaxy. We use our model to interpret previous experiments from the remote epitaxy and related literature. True remote effects are often obscured by defect-seeded nucleation, e.g. pinhole epitaxy, that mimics the macroscopic behavior of idealized remote epitaxy. Our model also points to tests, based on tunable screening and spatial extent of the substrate potential, that may increase the strength of the remote potential towards the more idealized picture.

Applied Surface Science

Room 209 B W - Session AS-TuA

Theory and Data

Moderators: Steve Consiglio, Tokyo Electron, Jeffrey Terry, Illinois Institute of Technology

2:45pm **AS-TuA-3 Artificial Intelligence Algorithms for Materials Characterization Analysis, Min Long, Boise State University INVITED**

The analysis of materials characterization techniques is complex and has typically been carried out by highly experienced/trained personnel, requiring significant human effort to extract and interpret meaningful physicochemical insights. This paradigm will be severely challenged by modern and next-generation instruments with high data collection rates, which are orders of magnitude faster than the data can be analyzed using current resources. This problem can even cause reproducibility challenges, one of the major issues affecting the scientific community, due to improper analysis of large and growing data sets. Artificial intelligence (AI) models informed by domain knowledge provide opportunities to address these challenges. We explored AI algorithms and selected a number of them to develop an AI-based spectral analysis framework, Neo, enabling automatic analysis of data from various types of measurements with high accuracy, performance, and reproducibility. The algorithms we adopted include genetic algorithms, differential evolution, and neuroevolution algorithms that can search for optima of physical and chemical properties of materials that lead to high-quality fits of the experimental spectra. A human analyst can first suggest a set of initial parameters potentially present in the sample, used as theoretical standards, and pass it to the framework. The framework will then evaluate those temporary solutions using fitness functions, adjust them by searching for improved solutions in the large multidimensional parameter space of combinations of these materials, until it can determine the set of structural parameters that best reproduce the experimental data. The framework integrates domain knowledge by not only finding the best mathematical description of the data but also the most physically and chemically meaningful results to improve the interpretability of models. The framework and its specialized sub-packages have been applied to various spectroscopy measurements, such as extended X-ray absorption fine structure (EXAFS), nanoindentation load-displacement curve, X-ray emission spectroscopy (XES). We are also planning to extend this framework to other measurements like X-ray photoelectron spectroscopy (XPS). Our results have shown that our methods can successfully provide refined structures in simple molecules, bulk crystals, and from an operando lithium-ion battery with much less human intervention in comparison with conventional methods.

3:15pm **AS-TuA-5 Fourier Denoising of XPS Data: An Algorithm for Automating the Identification of the Cutoff of the Gauss-Hermite Filter in Reciprocal Space and Feature Identification in XPS Spectra, Alvaro J. Lizarbe, Matthew R. Linford, Kristopher S. Wright, Garrett Lewis, Brigham Young University; David E. Aspnes, North Carolina State University; David J. Morgan, Cardiff University, UK; Mark Isaacs, University College London; Jeff Terry, Illinois Institute of Technology; Stanislav Průša, Brno University of Technology**

Introduction

Especially in X-ray Photoelectron Spectroscopy (XPS), large amounts of data and information are collected in its various modes that include imaging, depth profiling, stability, and operando studies. We recently published a paper¹ introducing Fourier analysis with a Gauss-Hermite filter function as a way to denoise X-ray Photoelectron Spectroscopy (XPS) data. While we always advocate for high quality data to be collected, Fourier analysis offers ways to improve collected data when the best possible signal-to-noise ratios cannot be obtained. Imperfect data are commonly obtained in sample damage studies due to changes in the sample, when elemental concentrations or low, when weak photoemission cross sections (seen in HAXPES) exist, when large numbers of spectra are collected in imaging

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studies, or when there is limited instrument time available. In such cases, Fourier analysis offers a mathematical approach to reduce noise and enhance signal quality, making it a valuable tool for XPS data analysis. We recommend that the original and smoothed data always be shown together. The Gauss-Hermite filter is a type of low-pass filter that applies a gradual, sigmoidal cutoff to low and high frequencies, allowing for a smooth transition between noise and signal. Currently, the position of this cutoff is adjusted manually by the analyst.

Work to be Presented.

The user must select the cutoff for the Gauss-Hermite filter we use to Fourier denoise XPS data. While the approximate location for this cutoff is generally clear from the shape of the Fourier coefficients in reciprocal space, it would be advantageous to be able to automate this process. In this talk, we describe an algorithm that successfully identifies the cutoff for the Gauss-Hermite filter, which should make this general approach to data denoising more widely applicable. This cutoff is based on statistical analyses of the fits. As a useful expansion to this capability, we show how this general approach can be applied when a high-order polynomial is used to fit carbon Auger data for D-parameter calculations.²

(1) Lizarbe, A. J.; Wright, K. S.; Lewis, G.; Murray, G.; Austin, D. E.; Terry, J.; Aspnes, D. E.; Linford, M. R. The case for denoising/smoothing X-ray photoelectron spectroscopy data by Fourier analysis. *J. Vac. Sci. Technol. A* **2025**, 43 (3). DOI: 10.1116/6.0004167

(2) Fairley, G. Compagnini, V. Scardaci, J. Baltrus, A. Roberts, A. Barlow, P. Cumpson and J. Baltrusaitis, *Surf. Interface Anal.* 55 (3), 165 (2023).

4:00pm AS-TuA-8 Fourier Denoising of XPS Data: Application of the Gauss-Hermite Filter Function to Carbon Auger D-Parameter, HAXPES, and LEIS data, and an Improved Algorithm for Reducing End-Point and Slope Discontinuity Artifacts, Matthew R. Linford, Alvaro J. Lizarbe, Kristopher S. Wright, Garrett Lewis, Brigham Young University; David E. Aspnes, North Carolina State University; David J. Morgan, Cardiff University, UK; Mark Isaacs, University College London, UK; Jeff Terry, Illinois Institute of Technology; Stanislav Průša, Brno University of Technology, Czechia

A general trend in surface and material characterization is the collection of larger amounts of data and information. In X-ray photoelectron spectroscopy (XPS), large numbers of spectra are often collected in imaging, depth profiling, damage, and operando studies. These large quantities of data present challenges to the analyst who always has limited time for data analysis. Accordingly, mathematical tools for XPS data analysis should become more relevant and important, not less. We recently presented the case for the Fourier denoising of XPS data (Lizarbe, A. J.; Wright, K. S.; Lewis, G.; Murray, G.; Austin, D. E.; Terry, J.; Aspnes, D. E.; Linford, M. R. *J. Vac. Sci. Technol. A* **2025**, 43 (3)). The highest quality data should be collected whenever possible, and mathematical ‘tricks’ aren’t, in general, a viable way to clean up extremely poor data. However, it’s not always possible to collect data with the best possible signal-to-noise ratios. Imperfect data are often collected, when an element or chemical state of an element is present at a very low concentration, when cross section for photoemission is low, like in HAXPES, when many spectra must be collected in a short period of time, as in imaging studies, or when instrument time is simply expensive. For these reasons, noise removal from adequate data has a place in XPS data analysis. We showed that the traditional Savitzky-Golay and Boxcar smooths are lacking in their ability to successfully remove noise from data. These deficiencies, when observed in reciprocal space, demonstrate that these common smooths don’t fully remove noise (high frequencies) from XPS data. A better approach to XPS data smoothing is with the Gauss-Hermite filter, which is applied in reciprocal space and has a sigmoidal shape. Below a user-selected cutoff, it preserves all the low-frequency information in a spectrum (low-index Fourier coefficients, signal), while removing high-frequency information.

In this talk, we describe an extension of these approaches to calculating the carbon Auger D-parameter and to smoothing HAXPES data. In addition, we show Fourier smoothing of data from a different technique: low-energy ion scattering (LEIS) data. LEIS spectra can present a challenge to data analysis because of their high sputter backgrounds at low energies. Finally, because numerical artifacts are introduced by Fourier denoising when there are end-point or slope discontinuities in the data, we show an improved algorithm for Fourier denoising via the Gauss-Hermite filter. This approach uses an improved function over what is currently in the software, which substantially reduces the current slope discontinuity in the current procedure.

4:15pm AS-TuA-9 Identification of Materials from TOF SIMS Spectra via Machine Learning, Lev Gelb¹, Amy Walker, University of Texas at Dallas

We present progress towards analysis of TOF SIMS data using machine learning (ML) methods. We posit that TOF SIMS is not more widely used because the data is complex and hard to interpret without expert knowledge, and investigate how machine learning might help. We primarily train models on simulated “big” data sets constructed by combining and modifying experimental spectra, with a focus on neural-network (NN) architectures.

Two applications are considered: identification of (presumed) homogeneous samples (which could be even a single pixel in a TOF SIMS image), and separation of multicomponent mixtures. In both cases, the sample consists of compound(s) which appear in some reference library, which is the basis for training. Complicating factors include statistical noise, background, calibration errors, and the likely case that the reference spectra were not taken under exactly the same conditions (primary ion, ion energy, instrument manufacturer, etc.) as the data to be analyzed.

In the first application, we focus on the extent to which improved spectral resolution helps (or hinders) analysis, the effect of reference library size on model performance, the effects of background counts and contamination by other species, and ways to have the model indicate that the sample is *not* described in the library. The NN approach is also compared with more straightforward spectral overlap-based methods and alternative machine-learning algorithms.

In the second application, the sample is assumed to consist of at least two components contained in the reference library. In addition to the complicating factors already mentioned, the presence of matrix effects can significantly complicate automated analysis. As in the first application, NN model performance is quantified and compared with overlap-based methods.

4:30pm AS-TuA-10 Benefits of a Modern File Format for ToF-SIMS Imaging, Alex Henderson, University of Manchester, UK

INVITED

ToF-SIMS data is typically acquired into the proprietary file format of the instrument vendor. The vendor’s software has visualisation tools and data analysis routines that are tuned to that format, and that can be sufficient for the end-user. But what if we want to do something the vendor has yet to implement? What about those machine-learning or deep-learning AI methods we read about? Can we share our data with our collaborators? Can we publish it openly, as mandated by most academic funding providers?

Most vendors offer one or two data export options. Sometimes these are only suitable for single spectra, or images of pre-selected ions. Often the file format is something thought up by the vendor, or can be missing important metadata.

For SIMS there are only a limited number of open file formats, each with their limitations. Examples include ISO 14976 (the “VAMAS format”) for spectra and maps, and imzML, originally developed for MALDI, for hyperspectral imaging. Each of these has issues with the size of files generated by modern instrumentation, or modalities such as image depth profiling.

In this presentation we will explore formats from other ‘big data’ domains such as climate science and astronomy, to see whether these can be adapted to our data. In the course of this, we will explore peak detection, data compression, out-of-core data access, visualisation, and machine learning.

We will also present open questions regarding metadata and invite the community to be involved in the process of developing a common format suitable for our requirements.

¹ JVST Highlighted Talk

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5:00pm AS-TuA-12 Template Matching Approach for Automated Determination of Crystal Phase and Orientation of Grains in 4D-STEM Precession Electron Diffraction Data for Hafnium Zirconium Oxide Ferroelectric Thin Films, *Alain Diebold*, CNSE, University at Albany, SUNY; *Colin Ophus*, Stanford University; *Amir Kordjazi*, University of Southern Maine; *Steven Consiglio*, TEL Technology Center, America, LLC; *Sarah Lombardo*, *Dina Triyoso*, *Kandabara Tapily*, TEL Technology Center, America, LLC, USA; *Ana Mian*, TESCAN GROUP, Inc.; *Nithin BVI Shankar*, TESCAN GROUP, a.s., Czechia; *Tomáš Morávek*, TESCAN GROUP, a.s.; *Narendraraj Chandran*, TESCAN GROUP, a.s, Czechia; *Robert Stroud*, TESCAN GROUP, Inc.; *Gert Leusink*, TEL Technology Center, America, LLC

Hafnium and zirconium oxide based thin films deposited by atomic layer deposition (ALD) are used as dielectric layers in advanced semiconductor devices. These films can also be stabilized in a ferroelectric phase for applications in memory, logic, and synaptic devices. ALD typically produces small-grained polycrystalline films containing a mixture of ferroelectric and non-ferroelectric phases with varying crystallographic orientations. Routine characterization of these films is critical for the research, development, and manufacturing of next-generation devices. While X-ray diffraction (XRD) is widely used for phase identification, it is limited to large-area, unpatterned thin films. Electron microscopy-based methods, in contrast, enable site-specific characterization within device structures, where local phase distributions may differ from blanket film samples.

This presentation discusses automated analysis of four-dimensional scanning transmission electron microscopy (4D-STEM) precession electron diffraction (PED) datasets for hafnium zirconium oxide (HZO) thin films in TiN/HZO/TiN capacitor structures. STEM lamellae are often thicker than the average HZO grain size, resulting in dynamical diffraction contributions from multiple grains at many probe positions. Additionally, distinguishing between HZO crystal phases is challenging due to small differences in lattice parameters and the potential presence of multiple orthorhombic polymorphs, making automated phase mapping particularly difficult. PED offers advantages over nanobeam electron diffraction (NBED) for phase and orientation analysis, and we find that PED is necessary for reliable automated template matching in HZO diffraction data.

Although automated phase and orientation mapping of HZO films using 4D-STEM has been previously demonstrated, a detailed assessment of different analysis methods has been lacking. Here, we compare results from a commercial software package (NanoMEGAS ASTAR) with an open-source framework (py4DSTEM). Correlation between automated phase maps and electrical verification of ferroelectricity confirms the identification of the non-centrosymmetric orthorhombic space group 29 phase of HZO.

Biomaterial Interfaces

Room Hall A, Booth 222 - Session BI-TuA

The Future of Biointerface Science

Moderator: *Tobias Weidner*, Aarhus University, Denmark

2:15pm BI-TuA-1 Quantifying Bacterial Adsorption at Biointerfaces Using Impedance Spectroscopy: A Key Step in Biofilm Formation, *Yunxing Li*, *Dipankar Koley*, Oregon State University

Bacterial adsorption is the first and important stage in the formation of biofilm on biointerfaces. A comprehensive understanding of this early stage of biofilm development helps us better control biofilm formation and evaluate the biointerfacial properties of various materials. To address the challenge of detecting subtle changes with this unstable bacterial adsorption in real time, here we developed a highly sensitive, flexible microsensor based on impedance spectroscopy to detect and quantify bacterial adsorption on different material surfaces using our innovative PEDOT coated electrode. These highly sensitive impedance electrodes gave a linear response to the amount of GFP-*E. coli* adsorbed. Furthermore, impedance-based methods enable monitoring of the kinetics of bacterial adsorption in real time. Utilizing this sensor, we observed stronger GFP-*E. coli* adhesion to positively charged glass than to regular glass. Additionally, we applied this sensor to metal ion-releasing resin composites to study how divalent metal ions (Zn^{2+}) control bacterial adsorption on these biointerfaces. It not only allows for real-time quantification of bacterial adsorption, but more powerfully, it is capable of distinguishing between different material biointerface, which offers valuable potential for biointerface characterization.

2:30pm BI-TuA-2 Scalable and Biocompatible Polymer Dome Arrays for Oil-Free High-Resolution Live-Cell Imaging, *Kwang-Won Park*, *Sophie Liu*, *Wenjing Tang*, *Rong Yang*, Cornell University

High-resolution imaging of biological targets near the surface of glass coverslips conventionally requires immersion oil to match refractive indices and achieve optimal optical performance. However, this approach presents several limitations, including incompatibility with surface-sensitive cell types, potential cytotoxicity from oil infiltration into cell media, handling difficulties due to viscosity, and inapplicability with dry lenses. To address these challenges, we present a novel imaging platform based on polymer dome arrays (PDAs), nanoscale plano-convex polymer lenses fabricated via Condensed Droplet Polymerization (CDP), offering a scalable and biocompatible alternative to traditional oil-based systems. CDP enables rapid, vapor-phase production of PDAs with tunable sizes, radii of curvature, and surface densities directly on coverslips. The refractive index of the polymer material ($n \sim 1.5$) closely matches that of glass, eliminates immersion oil while enhancing diffraction-limited resolution. PDAs exhibited mechanical stability and optical precision during repeated imaging and confirmed biocompatibility with sensitive cell lines. To further enhance cell adhesion and minimize cytotoxic response, we applied conformal ultrathin polymer coatings atop the PDAs using initiated Chemical Vapor Deposition (iCVD) following CDP. These coatings significantly improved cell-substrate interactions while maintaining structural integrity and optical clarity over extended duration. This platform supports stable, long-term cell culture, allowing for real-time, high-resolution imaging at the single-cell level without reliance on immersion oil or advanced optical instrumentation. The combination of robust fabrication, superior biocompatibility, and optical performance positions this system as a versatile tool for live-cell imaging, mechanobiology, and high-throughput drug screening, where customizable, non-toxic substrates are essential.

2:45pm BI-TuA-3 Development and Characterization of Decellularized Seaweed Scaffolds for Tissue Engineering, *Gobinath Chithiravelu*, *Marion J. Jones*, *Ivana Hernandez de Estrada*, *Yadvendra Singh*, *Harish Subbaraman*, *Binata Joddar*, Oregon State University

In this study, the marine red seaweed *Devaleraea mollis* (commonly known as dulse) was investigated as a green, sustainable, and animal-free scaffold alternative, owing to its extracellular matrix (ECM) mimicking properties. A decellularization-recellularization approach was employed to develop cellulose-based scaffolds capable of supporting human cardiomyocyte growth. Native dulse samples were cleaned, dried, and decellularized using a combination of SDS (3, 5,7,10,12,15%), Triton X-100 (2%), and NaOCl (0.2%) in varying concentrations and time-dependent treatments. The resulting scaffolds were comprehensively characterized using light microscopy, scanning electron microscopy (SEM), Fourier-transform infrared spectroscopy (FTIR), and Raman spectroscopy to identify the conditions that best preserved the fibrous, honeycombed architecture and cellulose-rich content of the native tissue. Among the treated scaffolds, those processed with 10%, 12%, and 15% SDS concentrations demonstrated the most favorable outcomes. These selected scaffolds were then subjected to swelling analysis to evaluate biodegradation behavior, followed by in vitro cell culture to assess biocompatibility all tested scaffolds demonstrated excellent compatibility with human cardiomyocytes, maintaining high cell viability over at least one week of in vitro culture, as confirmed by immunohistochemistry, quantitative cell analysis, and SEM imaging. Notably, SEM revealed over 50% surface coverage by cells on the scaffold by day six, indicating robust cell attachment and proliferation. Collectively, these findings highlight seaweed-derived cellulose as a highly promising, biocompatible, and eco-friendly biomaterial posing itself a novel interface for diverse biomedical applications, including scaffolds for cultivated meat production and innovations in sustainable tissue engineering.

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Spectroscopic Ellipsometry

Room 209 F W - Session EL1-TuA

Spectroscopic Ellipsometry Material Applications

Moderators: David Aspnes, North Carolina State University, Ron Synowicki, J. A. Woollam Co., Inc.

2:15pm EL1-TuA-1 Optical Properties of Chromogenic Thiazolothiazole-embedded Polymers, *Nuren Shuchi, Dustin Louisos, Glenn D. Boreman, Tyler Adams, Michael G. Walter, University of North Carolina at Charlotte; Tino Hofmann, New Jersey Institute of Technology* INVITED

The growing demand for advanced optical technologies capable of dynamic manipulation of spectral properties through external stimuli has spurred significant interest in chromogenic materials with tunable optical properties. Chromogenic materials that exhibit reversible changes in their optical properties in response to optical stimuli are called photochromic materials [1,2]. These materials have been demonstrated to play a significant role in facilitating the development of tunable infrared metasurfaces by leveraging their light-induced changes in optical properties [3]. The development of photochromic materials that exhibit strong and reversible changes in their optical properties in the infrared and visible spectral regions could offer an alternative approach to achieving tunable ir/vis metasurfaces, potentially with advantages in terms of cost, fabrication, or power consumption. Viologens represent an important class of photochromic materials [4]. Their properties can be enhanced by incorporating a thiazolo[5,4-d]thiazole (TTz) fused, conjugated bridge, an approach that has gained growing interest due to its strong fluorescence, solution-processability, and reversible photochromic transitions. Notably, dipyridinium thiazolo[5,4-d]thiazole viologens exhibit high-contrast, rapid, and reversible photochromic changes when integrated into a polymer matrix. Upon exposure to radiation with energy exceeding 2.8 eV, they undergo a color transition from light yellow (TTz²⁺) to purple (TTz⁺) and then to blue (TTz⁰) due to two distinct photoinduced single-electron reductions [5]. In this presentation, we report on a parameterized dielectric function of photochromic dipyridinium thiazolo[5,4-d]thiazole embedded in polymer obtained from a quantitative analysis of the polarization-sensitive optical response in the visible and infrared spectral ranges. In addition to discussing the photochromically-induced changes to the optical response we will report on recent results on the infrared imaging contrast obtained for this material as well as interesting temporal responses observed upon photoexcitation. **References:** [1] J. Crano and R.J. Guglielmetti, *Organic Photochromic and Thermochromic Compounds* Vol. 1 (New York, NY: Kluwer Academic Publishers., 1999). [2] H. Konaka, *et al.*, *Inorg. Chem.* **42**, 1928-1934 (2003). [3] S. Bang, *et al.*, *Micromachines* **9**, 560 (2018). [4] Z. Guo, *et al.*, *Adv. Opt. Mater.* **12**, 2401791 (2024). [5] T.J. Adams, *et al.*, *ACS Appl. Opt. Mater.* **2**, 704-713 (2024).

2:45pm EL1-TuA-3 Dielectric Function of Atomic Layer Deposition Grown VO₂ Determined by Spectroscopic Ellipsometry, *Dustin Louisos, Nuren Shuchi, Glenn Boreman, University of North Carolina at Charlotte; Tino Hofmann, New Jersey Institute of Technology*

VO₂ is a transition metal oxide that experiences a temperature driven metal insulator transition at 68 °C [1,2], which makes it a promising material for tunable optical and electronic devices [3,4]. Accurate knowledge of its optical constants is critical for design and modeling of devices, however, reported optical constants vary widely depending on deposition method, annealing recipe, and film quality. In this work, the optical properties of VO₂ thin films grown by atomic layer deposition are investigated using spectroscopic ellipsometry in the visible and infrared spectral range.

VO₂ films with a nominal thickness of 35 nm were grown on c-plane sapphire substrates using atomic layer deposition [5]. Atomic layer deposition was followed by a post-deposition thermal annealing step for 30 minutes at 400 °C. Spectroscopic ellipsometry measurements were performed from 0.045 to 5.9 eV using the J.A. Woollam IR-VASE and RC2. Spectroscopic ellipsometry measurements were taken on the as-deposited amorphous VO_x, annealed VO₂ at room temperature, and annealed VO₂ at 100 °C.

A single-model dielectric function was developed to describe the dielectric function over the entire spectral range. The oscillator model for the as-deposited sample is a sum of four Gaussian oscillators [6] and one Tauc-Lorentz oscillator [7]. The oscillator model for the as-deposited VO_x sample was used to determine the oxygen content, x, using a technique given by [8]. The oxygen content was found to be approximately 2, which has the proper stoichiometry needed to anneal to VO₂. For the annealed sample, the model uses a sum of Lorentz and two Tauc-Lorentz with a Drude term

[9] added for the metallic state. For the sample measured in this work, we find a resistivity of 5.71 10⁻⁴ Ohm·cm which is significantly lower than the resistivity found for films deposited by magnetron sputtering [10] and other atomic layer deposition approaches [11] reported recently.

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3:00pm EL1-TuA-4 Temporal Properties of Photochromic Thiazolothiazole-Embedded Polymer Films, *Nuren Shuchi, Tyler Adams, Naz Tumpa, Dustin Louisos, Glenn Boreman, Michael Walter, University of North Carolina at Charlotte; Tino Hofmann, New Jersey Institute of Technology*

Organic photochromic polymers, whose photo-chemical and optical properties can be altered through optical stimulation, are found in diverse applications ranging from tinted lenses and smart windows to memory devices, actuators, tunable filters, and holographic gratings [1-4]. Recently, extended viologens containing the thiazolo[5,4-d]thiazole (TTz) backbone are increasingly attracting interest due to their strong fluorescence, solution-processability and reversible photochromic transition [5]. Especially, dipyridinium thiazolo[5,4-d]thiazole viologen exhibits high-contrast, fast, and reversible photochromic changes. When exposed to radiation with an energy larger than 3.1 eV, it transitions from light yellow (TTz²⁺) to purple (TTz⁺) to blue (TTz⁰) state due to two distinct, photo-induced single electron reductions [5]. The complex dielectric function of a non-photochromic TTz derivative and a photochromic TTz-embedded polymer has been determined previously in the visible and near-infrared spectral range using spectroscopic ellipsometry [6-7].

In this presentation, we will discuss the dynamic optical properties of photochromic thiazolothiazole-embedded polymer films. Attenuated total reflectance ellipsometry was used in order to isolate surfaces exposed to oxygen-rich and oxygen-deficient environments. This facilitates the spatial separation of surface regions based on oxygen exposure and the distinction between surface and bulk contributions to the overall optical response.

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3:15pm EL1-TuA-5 Determination of optical properties of ultrathin silane films coated on Silicon substrate by means of Immersion Ellipsometry, *Samira Jafari, Brigham Young University; Blaine Johs, Film Sense LLC; Matthew Linford, Brigham Young University*

This study investigates the optical properties of ultrathin silane films deposited on silicon substrates using Immersion Ellipsometry (IE). IE is a very sensitive optical technique and can determine the refractive index (n) of very thin films (< 5 nm) by analyzing ellipsometric data acquired in both air and liquid ambients (water, n=1). The immersion approach enhances the accuracy of very thin film characterization, by decorrelating the film thickness and optical constants. A series of silanes, including chloro octadecyl silane, chloro decyl silane, (heptadecafluoro-1,1,2,2-tetrahydrodecyl) silane, and other silanes were studied, revealing distinct optical characteristics attributable to their varying chemical compositions. Notably, a correlation between refractive index and electronegativity was observed, where lower electronegativity resulted in a lower refractive index, given the film thickness approximation to the molecular length. This demonstrates SIE's ability to decouple optical constants from film thickness in ultrathin films, enabling accurate determination of optical parameters. To complement the optical analysis, X-ray photoelectron spectroscopy (XPS)

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was used to characterize the chemical composition and bonding states of the deposited silanes, while contact angle goniometry provided insights into the films' surface wettability. This comprehensive approach highlights IE's efficacy in characterizing transparent ultrathin films and underscores its potential for improving control over silane-based coatings in microelectronics, biomedical devices, and optical applications.

Spectroscopic Ellipsometry

Room 209 F W - Session EL2-TuA

Spectroscopic Ellipsometry Novel Methodologies

Moderators: Ufuk Kilic, University of Nebraska - Lincoln, Mathias Schubert, University of Nebraska - Lincoln

4:00pm EL2-TuA-8 In Situ Spectroscopic Ellipsometry Studies of Selective Thermal Dry Etching, *Marcel Junige, Steven M. George*, University of Colorado Boulder **INVITED**

Thermal dry etching uses gas-phase reactants in a vacuum and physicochemical reactions based on thermal activation, providing isotropic material removal for lateral patterning without line of sight. Thermal dry etching covers atomic layer etching (ALE) and spontaneous etching. ALE is defined by self-limiting reactions, separated by purge steps. These half-reactions modify and sequentially volatilize a thin film surface, thereby removing material digitally one ultra-thin layer per cycle. Conversely, spontaneous etching is characterized by a sustained reaction of a thin film surface with one etchant only, thereby removing a targeted material with a continuous etch rate.

This invited talk reviews exemplary studies of thermal ALE and spontaneous etching, utilizing *in situ* spectroscopic ellipsometry (iSE) to reveal thickness changes, self-limiting behavior, synergy between half-reactions, and selectivity between different materials. An iSE instrument (J.A. Woollam Co.) acquired ellipsometric spectra for 5 s at the end of reactant purge steps. Interference enhancement enabled thickness precision of $\pm 0.01 \text{ \AA}$.

Al_2O_3 thermal ALE using sequential hydrogen fluoride (HF)/trimethylaluminum (TMA) exposures exhibited a linear etch per cycle (EPC) at 275°C . After initial fluorination, consecutive HF exposures gave virtually no Al_2O_3 thickness loss. This self-limiting behavior corresponded to ideal ALE synergy because all material removal resulted solely from a favorable interaction of the HF/TMA sequence and no etching occurred by either HF or TMA alone. SiO_2 thermal ALE using sequential TMA/HF exposures likewise exhibited a linear EPC at 275°C . Consecutive HF exposures displayed negligible SiO_2 thickness loss, especially after eliminating H_2O during the fluorination step. This self-limiting behavior revealed near-ideal synergy for SiO_2 ALE.

SiN_x thermal ALE using sequential TMA/HF exposures discovered no ALE synergy because consecutive exposures of HF alone caused predominant SiN_x spontaneous etching. This difference between near-ideal versus no ALE synergy obtained great inherent selectivity between major SiN_x versus minor SiO_2 spontaneous etching using anhydrous HF vapor at 275°C . Using anhydrous HF at temperatures $>150^\circ\text{C}$ also discovered facile spontaneous etching of single-crystalline, poly-crystalline, and amorphous Si films with high selectivity compared to SiO_2 retention.

In contrast, co-adsorbing polar molecules with anhydrous HF had a drastic effect. Co-dosing NH_3 +HF at 275°C obtained exceptional selectivity for rapid SiO_2 versus negligible SiN_x spontaneous etching. Similarly, co-adsorbing dimethylamine with HF at 200°C enabled substantial SiO_2 spontaneous etching.

4:30pm EL2-TuA-10 Artificial Intelligence for Ellipsometric Analysis of Liquid Mixtures Using Multi-Bounce ATR-FTIR, *Jeremy VanDerslice, J.A. Woollam Co.; Alyssa Mock, Madison Coleman, Mar Diehl, Madison Meaney, Tyler Adams*, Weber State University

Artificial intelligence is emerging as a valuable tool in optical metrology, offering a new avenue for data interpretation in model-based techniques like ellipsometry. Optical models used to describe thin films traditionally measured by ellipsometers often require careful initialization or involve significant computational cost. In these cases, AI methods can assist by providing initial parameter estimates or, in some applications, by replacing the physical model entirely. One such application benefiting from the combination of ellipsometry and predictive data interpretation is the concentration analysis of liquid mixtures using Fourier-transform infrared (FT-IR) ellipsometry in a multi-bounce prism configured for attenuated total reflection (ATR) measurements. In this approach, neural networks learn the

nonlinear relationships between ellipsometric measurements and analyte concentrations in these mixtures. This capability is particularly relevant in industries relying on optical techniques for liquid analysis. In the wine and beverage industry, for example, concentrations of ethanol, sugars, phenolic compounds, organic acids, and other analytes are commonly measured using reflection or transmission intensity. While the existing intensity-based methods offer non-destructive analysis, they generally exhibit lower sensitivity to absorption features specific to each analyte compared to polarization-based measurements, which suggests a reduced sensitivity threshold compared to ellipsometry. The use of predictive neural networks, in combination with ellipsometry, enables enhanced determination of analyte concentrations within a liquid mixture without requiring prior expertise in ellipsometry.

4:45pm EL2-TuA-11 Stimulated Brillouin Scattering for Semiconductor Metrology, *Matthew Sartin, Deric Session, Robin Mair, Michael Kotelyanskii, Manjusha Mehendale, George Antonelli*, Onto Innovation

Picosecond laser ultrasonics has been used as an in-line semiconductor metrology for opaque film thickness for almost 30 years. In transparent or opaque or semi-transparent material systems, a stimulated Brillouin scattering feature is present. It has been used in the semiconductor industry to map the in-wafer uniformity of the sound velocity and thus elastic modulus in both insulators and semiconductors. Although the underlying physics are well documented in the literature, the details of signal generation in different geometries at different wavelengths are often overlooked or misinterpreted. We shall present an analytical model and measurements at 1030/1060 nm using a dual frequency comb configuration on a metal film (W and TaN) on silicon substrate both from the metal and silicon side. This material system is instructive in demonstrating the difference in the underlying physics and opportunities.

5:00pm EL2-TuA-12 Laser Ellipsometry: A Half Century Old New Technique, *Alexander Ruder, Deric Session, Marieke Ordway, Fei Shen, Michael Kotelyanskii, Manjusha Mehendale, G. Andrew Antonelli*, Onto Innovation

Laser sources played an important role in the introduction of ellipsometry to the semiconductor industry. This method was largely displaced by spectroscopic methods. Over the past five years, there has been a resurgence of interest in laser ellipsometry particularly for high precision measurements of ultra-thin dielectric films. Advances in laser, phase modulation, optical-design, and electronic instrumentation enable significant improvement in precision and stability relative to previous generations. The industrial requirements and operating principle for an exemplar of this new class of systems will be reviewed. Examples of measurements on thin films including high-k gate dielectrics shall be provided.

Electronic Materials and Photonics

Room 207 A W - Session EM1+CPS+MS+PS+SM+TF-TuA

Advances in Materials and Processes for Devices and Interconnects (FEOL and BEOL)

Moderators: Moon Kim, University of Texas at Dallas, Philip Lee, University of Kentucky

2:15pm EM1+CPS+MS+PS+SM+TF-TuA-1 Carborane-Based Blocking Layers and Plasma Removal Strategies for Area Selective Deposition in Semiconductor Patterning, *Raja Sekhar Bale*, University of Missouri-Kansas City; *Rupak Thapa*, University of Missouri-Kansas City; *Vamseedhara Vemuri, Nicholas Strandwitz*, Lehigh University; *Anthony Caruso, Michelle Paquette*, University of Missouri-Kansas City

Advancing semiconductor scaling to the 2 nm and angstrom-level nodes requires patterning methods that move beyond the resolution, alignment, and cost limits of conventional top-down approaches. Area-selective deposition (ASD) provides a complementary bottom-up strategy, enabling growth only where desired to reduce process steps, minimize defects, and/or improve integration in back-end-of-line (BEOL) fabrication. This work investigates the use of carborane self-assembled monolayers (SAMs) as blocking layers for ASD. Carborane SAMs are thermally stable, mechanically robust, and chemically tunable, making them strong candidates for selective surface modification in semiconductor patterning. Their role is to define surfaces where deposition should be inhibited, while remaining compatible with BEOL conditions. To explore their processing compatibility, the blocking ability of carborane SAMs toward ALD dielectric oxides was studied alongside plasma-based removal. Using CF_4/O_2 and

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$\text{C}_4\text{F}_8/\text{O}_2/\text{Ar}$ chemistries, we carried out blanket plasma etching of carborane SAMs. This presentation will highlight results on carborane SAM formation, blocking behavior, and plasma response, demonstrating their potential as scalable materials for atomic-scale patterning in next-generation semiconductor manufacturing and their compatibility with advanced BEOL integration.

2:30pm EM1+CPS+MS+PS+SM+TF-TuA-2 Ferroelectricity in Atomic Layer Deposited Wurtzite Zinc Magnesium Oxide $\text{Zn}_{1-x}\text{Mg}_x\text{O}$, Benjamin Aronson, University of Virginia; *Kyle Kelley*, Oak Ridge National Laboratory; *Ece Gunay*, Carnegie Mellon University; *Ian Mercer*, Penn State University; *Bogdan Dryzhakov*, Oak Ridge National Laboratory; *Susan Trolier-McKinstry*, *Jon-Paul Maria*, Penn State University; *Elizabeth Dickey*, Carnegie Mellon University; *Jon Ihlefeld*, University of Virginia

Ferroelectric wurtzites have garnered interest in the scientific community since first reported in 2019. $\text{Zn}_{1-x}\text{Mg}_x\text{O}$ has shown promise due its low coercive field (2–3 MV/cm) relative to other wurtzites, integrability on flexible polymer substrates, and complementary metal–oxide–semiconductor (CMOS) and back-end-of-line (BEOL) compatible deposition temperatures as low as room temperature. However, the majority of ferroelectric wurtzite thin films – including $\text{Zn}_{1-x}\text{Mg}_x\text{O}$ – have been fabricated using physical vapor deposition (PVD) techniques, which features largely directional growth. Due to the use of high aspect ratio structures in non-volatile memory devices, the ability to conformally deposit ferroelectric wurtzites will contribute to BEOL integration. Atomic layer deposition (ALD) presents an opportunity to overcome this outstanding challenge due to its sequential, self-limiting growth. In this work, $\text{Zn}_{1-x}\text{Mg}_x\text{O}$ thin films with compositions between $x = 0$ and $x = 0.58$ were grown on platinized silicon substrates using plasma-enhanced atomic layer deposition. Films were characterized using X-ray diffraction (XRD), transmission electron microscopy (TEM), and piezoresponse force microscopy (PFM). All films deposited featured a singular out-of-plane *c*-axis textured wurtzite structure. The *c/a* ratio decrease with increasing Mg content indicates the increasing structural distortion. Film structure and structural distortions were further reinforced and visualized via TEM. PFM amplitude and phase hysteresis loops demonstrated polarization reversal in the $x = 0.46$ and $x = 0.58$ films. Ultimately, this finding presents opportunities to further mature the $\text{Zn}_{1-x}\text{Mg}_x\text{O}$ processing space in which ferroelectric switching is possible, as well as explore ALD of other ferroelectric wurtzites.

2:45pm EM1+CPS+MS+PS+SM+TF-TuA-3 Harnessing Nitrogen-Rich Interfaces in AlN Ferroelectrics, Ian Mercer¹, Erdem Ozdemir, Chloe Skidmore, Benjamin Debastiani, Kazuki Okamoto, Penn State University; Sebastian Calderon, Elizabeth Dickey, Carnegie Mellon University; Susan Trolier-McKinstry, Jon-Paul Maria, Penn State University

The importance of interface preparation in the nitride semiconductor and thin film community has long been recognized as critical in controlling nucleation and properties. These AlN ferroelectrics are an enticing pathway toward integrated energy-efficient robust non-volatile memory, displaying CMOS chemical compatibility, large polarizations, and BEOL processing. Although this has not been fully realized in the relatively recent nitride wurtzite ferroelectric community, current convention stems from strictly polar systems like GaN and AlN. However, there is a clear opportunity in engineering electrode interfaces in these systems to aid in film nucleation, reduced leakage, and extended fatigue lifetimes. In this work, we discuss the influence of surface nitridation on a variety of relevant substrates prior to film deposition to enhance film texture and electrical properties. Adding the surface nitridation leads to a discussion on whether nitrogen-rich interfaces can compensate for nitrogen vacancies that migrate to electrode interfaces during cycling. By depositing top and bottom metal nitride electrodes, we investigate the benefits in the electrical properties versus metallic electrodes. Reactive RF magnetron sputtering is employed to co-sputter AlN ferroelectrics. X-ray diffraction (XRD) is used to display *c*-axis texture, while hysteresis (PE), leakage (PUND), and fatigue measurements are used to characterize the electrical properties. Etching/SEM is also used to display partial switching, exploiting the *n*-polar fast etch in KOH solutions, which helps visualize the effects of nitrogen-rich interfaces. Furthermore, this study reinforces the functionality of interface engineering in AlN ferroelectrics at both the top and bottom electrode interfaces. The importance of this work is that all films in this class may benefit from nitrogen-rich interfaces.

3:00pm EM1+CPS+MS+PS+SM+TF-TuA-4 Selective Etching of GaN Over AlGaN and Monitoring via Optical Emission Spectroscopy, Michael Thomas, Patrick Wellenius, Spyridon Pavlidis, North Carolina State University

Achieving etch selectivity between GaN and AlGaN is critical for the repeatable fabrication of enhancement-mode AlGaN/GaN High Electron Mobility Transistors (HEMTs). The selectivity can be tuned by varying the O_2 content in a Cl_2 -based etch. In this work, we explore the etch process parameter space that affects selectivity and explore how *in-situ* optical emission spectroscopy (OES) can be used as an indicator of chamber and plasma conditions over time.

Two epitaxial structures on sapphire were used. The first is a thin film of GaN (control). The second is a device-relevant AlGaN/GaN heterojunction with a GaN cap layer. Following photolithography, samples of each type were etched simultaneously in an Oxford Instruments Plasmapro 100 Cobra inductively coupled plasma (ICP) to eliminate run-to-run variation from the selectivity determination. The total etch time was varied by gas composition to keep the HEMT sample etch depth within the AlGaN front barrier. Etch step heights were measured via atomic force microscopy (AFM) in an Oxford Instruments Asylum Research MFP-3D Origin AFM. Using an OceanOptics USB4000 Spectrometer, OES signals were collected with 1 s integration every 60 s during chamber cleaning and conditioning, and every 30 s during the final etches for each composition.

During initial experiments, the chamber pressure, ICP power, and table RF power were all kept constant at 15 mTorr, 500 W, and 25 W, respectively. The total gas flow was kept constant at 50 sccm, and Cl_2 was further kept constant at 35 sccm. The remaining 15 sccm were split between O_2 and Ar, with three tests being done at 0/15, 2/13, and 4/11 sccm of O_2/Ar respectively. An initial peak selectivity of 3.45:1 was measured with 2 sccm O_2 . The OES signal confirms O_2 emission brightness changes as expected with flow rate. To further improve the selectivity, we will report on the etch characteristics across a wider parameter space, including varying the Cl_2 content of the plasma, the total gas flow rate, the chamber pressure, ICP power and substrate size. Moreover, we explore how the OES's utility can be leveraged to assess the effectiveness of pre-etch chamber conditioning to improve both selectivity and repeatability. The results of this study are expected to boost the yield and performance of AlGaN/GaN HEMTs.

This technology was primarily supported by the Microelectronics Commons Program, a DoD initiative, under award number N00164-23-9-G059.

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Room 207 A W - Session EM2+AIML+AP+CPS+MS+SM-TuA

Advances in AI and Machine Learning within the Semiconducting Industry

Moderator: Erica Douglas, Sandia National Laboratories

4:00pm EM2+AIML+AP+CPS+MS+SM-TuA-8 Improved Design-of-Experiments and Process Modeling with Generative AI, Somilkumar Rathi, Muthiah Annamalai, Panmo LLC

Small volume semiconductor, photonic and materials manufacturing largely uses One-Factor at-a-time (OFAT) to discover process window instead Design of Experiments (DOE). We demonstrate, *Panmo Confab*, a Generative AI based DOE and process-flow-design platform to accelerate process window discovery. Large volume semiconductor, photonic and materials automation tools have relied on statistical process control (SPC), design of experiments (DOE) and yield modeling techniques which are fairly manual and depend on specialized tools and deep knowledge [1,2] when such tools are not used we get a sub-optimal outcomes for process development teams through using one-factor at a time (OFAT). In this article we report, and demonstrate, *Panmo Confab* a Generative AI based process flow tracking and design of experiments platform to accelerate flow designs and generating DOEs. Previously our tool was used without Generative AI, features to show improvement in process discovery for plasmonic nanocavity fabrication [4]. The unique innovation of our tool is to use the emerging technology of large language models (LLM), like BERT or ChatGPT [5,6] and science of causality [3] to enable generation of process flows with a description. Our tool is presented in both on-premises and Software-as-a-Service (SaaS) formats.

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¹ JVST Highlighted Talk

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4:15pm EM2+AIML+AP+CPS+MS+SM-TuA-9 Foundation Models in Semiconductor R&D: A Study on Segment Anything, *Fei Zhou*, Sandisk Corporation

Quantitative analysis of scanning and tunneling electron images is crucial in semiconductor manufacturing, particularly for defect detection, process margin checking, and morphology quantification. Traditional AI/ML approaches, such as using recurrent neural networks, require large labeled datasets and extensive transfer learning to generalize across different imaging conditions. Developing a usable AI tool for proof-of-concept demonstrations demands significant engineering effort and GPU resources, making these methods costly and time-consuming. These challenges are especially pronounced in semiconductor R&D, where fast turnaround, high accuracy, and efficient use of engineering resources are essential.

The Segment Anything Model (SAM) introduces a novel training free segmentation approach, eliminating the need for task-specific retraining while providing robust and efficient segmentation across diverse semiconductor imaging requirements. This paper explores SAM's application in semiconductor image analysis, demonstrating its ability to segment complex nanoscale features without prior dataset exposure. We assess SAM's performance in automated defect detection, where challenges such as varying defect morphology, background noise, and process-induced variations exist. With appropriate prompting and post-processing techniques, SAM adapts to different imaging conditions, offering a rapid, low-cost, and high-accuracy solution.

Additionally, we examine SAM's limitations, particularly in scenarios where the region of interest is small and contains limited useful pixel data. By employing image enhancement techniques, we demonstrate how SAM can effectively segment defects even in low-information conditions. Furthermore, we explore how integrating grounding techniques with SAM can expedite segmentation post-processing, further improving efficiency in real-world applications.

Our case studies show that SAM significantly reduces resource overhead and enables semiconductor image analysis automation, achieving saving of >100 engineering hours and >20 GPU hours per project. Its foundation model architecture allows it to generalize across different defect types, backgrounds, and imaging techniques without additional data labeling or fine-tuning. These findings suggest that integrating SAM into semiconductor workflows enhances efficiency, lowers costs, and accelerates R&D decision-making by providing a scalable and cost-effective solution for high-precision image segmentation. This study highlights the transformative potential of foundation models in semiconductor engineering, paving the way for broader adoption of AI-driven automation across the industry.

Nanoscale Science and Technology

Room 206 A W - Session NS-TuA

Advanced Nanoscale Materials & Device Technologies

Moderators: Andrew Mannix, Standford University, Taisuke Ohta, Sandia National Laboratories

2:15pm NS-TuA-1 Engineering at the Limits of the Nanoscale, *Farnaz Niroui*, Massachusetts Institute of Technology INVITED

Next-generation devices for computing, sensing, and information processing leverage the unique properties of emerging low-dimensional materials. However, integrating these materials into functional nanosystems is challenged by their incompatibility with conventional fabrication techniques. To unlock their full potential, new heterogeneous integration platforms are essential. By combining top-down fabrication with the precision of bottom-up processes, we present strategies that overcome these limitations, enabling precise and deterministic integration of low-dimensional materials with down to sub-10 nm resolution. Through these strategies, we have developed new device platforms for energy-efficient

computing, enhanced sensing, and quantum photonic technologies, which will be discussed in this talk.

2:45pm NS-TuA-3 Theoretical Insights into Ethylene Hydroformylation on Transition Metal Heterogeneous Catalysts, *Shyam Kattel*, University of Central Florida; Sourav Ghoshal, Florida A&M University

Traditional hydroformylation, an important oxo-synthesis route, is an industrial process to produce aldehydes by the reaction of synthesis gas, a mixture of CO(g) and H₂(g), with alkenes. Currently, hydroformylation represents one of the largest homogeneously catalyzed reactions in industry and is carried out using Rh and/or Co-based transition metal complexes as a catalyst. However, the homogeneous nature of this reaction leads to difficulties in catalyst separation and recovery, active metal losses, metal species contamination in aldehydes, and corrosivity of catalytic solutions. The design of heterogeneous catalytic systems without sacrificing the activity and selectivity will avoid the drawbacks associated with homogeneous catalysts and be highly useful. However, a fundamental understanding of reaction mechanisms and key steps/descriptors that control the activity and selectivity of alkene hydroformylation on heterogeneous catalytic systems is limited.

Herein first-principles density functional theory (DFT) calculations were carried out to compute reaction energetics and kinetics of ethylene hydroformylation to C₃ Oxygenates on (111) surface and small nanoparticles/clusters of eight face center cubic transition metals Cu, Ni, Rh, Pd, Ag, Pt, Ir, and Au. Our DFT and microkinetic simulations revealed that the metal surface model failed to capture the experimentally reported activity/selectivity trends, whereas the nanocluster model demonstrated excellent agreement with experimental results. The Rh nanoparticle showed a lower activation energy (0.87 eV) for the *CO and *C₂H₅ coupling reaction, a key reaction step for C-C coupling in hydroformylation reaction. Under experimental reaction conditions (~473 K, 1 atm), the results from microkinetic simulations illustrate that the selectivity of Rh nanoparticle for the formation of C₂H₅CHO (a C-C coupling product) is highest among all the metals studied in the present study for a temperature range of 450-900K. Thus, our results from DFT and microkinetic simulations provide atomistic insight into the reaction pathways of ethylene hydroformylation to C₂H₅CHO on transition metal catalysts and identify sites that promote the C-C coupling, a key reaction step in hydroformylation reaction. Finally, this work highlights the critical role of nanoparticle size and structure in tuning the selectivity of ethylene hydroformylation to a desired product.

3:00pm NS-TuA-4 Van Der Waals 3D Assembly of 2D Nanomaterials for Scalable Electronics, *Joohoon Kang*, Yonsei University, Korea

Two-dimensional (2D) nanomaterials have been received a great attention as potential building blocks for use in fundamental elements of (opto)electronic applications due to their diverse and remarkable electronic and optical properties. However, such fundamental demonstrations cannot be directly applied to practical applications because of scalable synthesis of high-quality nanomaterials and their proper assembly. In this presentation, I will demonstrate wafer-scale van der Waals assembly of 2D materials, which are exfoliated via a molecular intercalation-assisted electrochemical exfoliation method. The resulting materials with distinct electronic properties including metal, semiconductor, and insulator, can be assembled into various (opto)electronic devices such as transistors, diodes, logic gates, and photodetectors. Also, such solution-based approach further enables inkjet printing-based device fabrications without a conventional lithography.

3:15pm NS-TuA-5 Impact of External Screening on the Valence and Core-Level Photoelectron Spectra of One-Layer WS₂, *Alex Boehm, Chris Smyth, Andrew Rakyoung Kim, Don Bethke, Tzu-Ming Lu, Jose Fonseca Vega, Jeremy Robinson, Taisuke Ohta*, Sandia National Laboratories, USA

In a well-screened environment, transition metal dichalcogenides (TMDs) rearrange their charge carriers to screen the added charges, and reduce the electronic band gap. Consequently, when interfaced with dissimilar materials, a sheet of TMD would change its band gap adapted to its local external screening environment. Similarly, a well-screened environment stabilizes photo-holes or core-holes created in the photoemission process and, in turn, boosts the kinetic energy of photoelectrons resulting in the apparent smaller binding energy. Complication arises when determining the electronic band alignment of TMDs using photoelectron spectroscopy since the screening influences the material property of interest as well as its assessment approach concurrently. Using a sample that contains areas of suspended and gold-supported one-layer WS₂, we show how the electronic states of WS₂ under the contrasting effective or ineffective external screening environment align at the built-in junction. The photoelectron

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spectra point to the breakdown of rigid shifts between the valence states and core-levels with the core-levels shifting more than twice as much as the valence states. Additionally, effectively-screened WS₂ displays a valence state with a substantially larger photoemission linewidth than ineffectively-screened suspended WS₂. Altogether, our result provides key insights into how the local variation of the external screening environment creates essentially a heterojunction within a layer of WS₂.

The work was supported by the Laboratory Directed Research and Development program at Sandia National Laboratories and Base Programs and the Nanoscience Institute at the Naval Research Laboratory via the Office of Naval Research. A.R.K. acknowledges support from the U.S. Department of Energy, Office of Science, Division of Materials Sciences and Engineering (grant BES 20-017574). Samples were fabricated, in part, at the Center for Integrated Nanotechnologies, an Office of Science User Facility operated for the US Department of Energy, Office of Science. Sandia National Laboratories is a multi-mission laboratory managed and operated by National Technology and Engineering Solutions of Sandia, LLC., a wholly-owned subsidiary of Honeywell International, Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA0003525. Any subjective views or opinions that might be expressed in the paper do not necessarily represent the views of the U.S. Department of Energy or the United States Government.

4:00pm NS-TuA-8 III-Nitride Ferroelectrics for Low-Power Computing Devices, *Deep Jariwala*, University of Pennsylvania

Since the demise of Dennard scaling, modern computer has largely relied on architectural innovations such as multi-core processors and GPUs vs CPUs to address the evolving needs of computing paradigm. This above problem has been exacerbated since computing has largely evolved from arithmetic centric to data centric in the age of billions of interconnected devices and artificial intelligence. Thus, dense and reliable data storage combined with fast and high bandwidth access in novel memory devices has become the frontier for research in modern computing hardware. In this regard there have been several advancements across a variety of technologies in the past three decades. Ferroelectric materials and devices are among the forefront of these technologies due to their low-power and fast switching abilities but suffer from integration challenges.

Therefore, in this talk, I will try to make the case of how novel III-nitride materials might present interesting avenues to overcome some of the above limitations being faced by Silicon hardware. I will start by presenting our ongoing and recent work on integration of 2D chalcogenide semiconductors emerging wurtzite structure ferroelectric nitride materials namely aluminium scandium nitride (AlScN). First, I will present on Ferroelectric Field Effect Transistors (FE-FETs) made from 2D materials when integrated with AlScN and make the case for 2D semiconductors in this application. I will then show our most recent results on scaling 2D/AlScN FE-FETs, achieving ultra-high carrier and current densities in ferroelectrically gated MoS₂ and also demonstrate negative-capacitance FETs by engineering the AlScN/dielectric/2D interface. Then, I will switch gears to introduce the ferroelectric diode (FeD) memory device and demonstrate multi-bit operation as well as compute in memory (CIM) using FeD devices made from AlScN.

4:15pm NS-TuA-9 Chemical and Mechanical Modification of 2D Semiconductors for Electronic Devices, *Andrew Mannix*, Stanford University

Layered van der Waals materials, composed of discrete, atom-thin sheets, enable the deterministic assembly of heterostructures and precise placement of dopants and defects, offering a powerful route to tailor electronic and quantum properties. However, achieving scalable synthesis, controlled electronic interfaces, and low defect density remain major challenges for technological applications. This talk will highlight recent advances in overcoming these materials science barriers to enable next-generation (opto)electronic and quantum technologies based on 2D semiconductors and their heterostructures.

To accelerate chemically-tailored synthesis and compositional tuning of transition metal dichalcogenides (TMDCs) like WS₂ and WSe₂, we developed a hybrid metal-organic chemical vapor deposition process. Using solution-phase deposition of metal salt precursors and vapor-phase chalcogen delivery, this method provides high quality growth with precise doping, alloying, and growth chemistry modification [1]. Confined-space growth using this method enabled the selective formation of ferroelectric 3R-phase TMDC films on dielectrics [2], opening new possibilities for ferroelectric

semiconductor devices and nonlinear optics.

Interfacing 2D semiconductors with electrodes remains a key challenge. We found that mechanical strain from top contacts, such as Ni on WS₂, can significantly enhance device performance—an often-overlooked effect [3]. For p-type WSe₂ transistors, we show that chloroform intercalation doping is a clean, reliable, and stable method to improve contact quality, even at low temperatures. These advances provide critical pathways toward scalable 2D semiconductor technologies.

[1] Z. Zhang, L. Hoang, et al., *ACS Nano* **18**, 25414 (2024).

[2] Z. Zhang, et al., *Nano Letters*, **24**, 12775 (2024).

[3] L. Hoang, et al., *Nano Letters*, **24**, 12768 (2024).

4:30pm NS-TuA-10 Fabrication of Si Nanopillars Using Pmma Resist, *Kareena Guness*, Zachary Kranefeld, T. Pan Menasuta, Basil. F Vanderbie, Thomas. E Vandervelde, Tufts University

Poly-methyl methacrylate (PMMA) is the most commonly used e-beam resist. While it is cost effective, easily available, and offers the highest resolution among any polymeric resist, PMMA suffers from poor dry-etch resistance. For that reason, other resists like HSQ and ZEP are typically preferred. In this work, we report the fabrication of silicon nanopillars using PMMA, emphasizing on the process optimizations, particularly in reactive ion etch (RIE) chemistry, required to overcome key roadblocks. Electron beam lithography was used to write patterns in PMMA positive tone resist. To transfer the patterns to the substrate and achieve nanopillars of high-aspect ratios with smooth sides, RIE was employed with SF₆ and O₂. The hard mask was removed by soaking the wafer in remover-*pg* for several hours. The fabrication processes were characterized by Atomic Force Microscopy (AFM) and Scanning Electron Microscopy (SEM).

4:45pm NS-TuA-11 Nanoplastics Pillar Arrays for Chemical Sorption Assays, *Sandra Gutierrez Razo*, Andrew Madison, Craig Copeland, Danuta Liberda-Matyja, John Pettibone, Daron Westly, Samuel Stavis, NIST

Nanoplastics chemical sorption is of great interest and concern. Because of their scale, nanoplastic particles are difficult to detect and quantify. Many approaches involve optical microscopy and microspectroscopy, so we are fabricating pillar arrays on silicon wafers to produce novel nanoplastic standards. We spin coat low-density polyethylene (LDPE) films that are less than 100 nm thick. We then pattern the thin films using electron-beam lithography and oxygen etch. Control over pillar size, shape, and position enables useful calibrations. The arrays can also be used as substrates to study the sorption of chemicals onto LDPE. We begin with two fluorescent chemicals, rhodamine B, a common fluorophore, and and 4,4'-diamino-2,2'-stilbene disulfonic acid (DSD), an optical brightener added to laundry detergent. Further study of the correlation of fluorescence intensity and pillar volume will elucidate interactions of nanoplastic particles and chemical sorbents of environmental concern and technological interest.

The figure in the supplemental document shows LDPE films and pillars. (a-b, left) OPTIR spectra showing three absorption peaks consistent with LDPE at 2919, 2850, and 1456 cm⁻¹ indicating that the composition does not change after patterning with electron-beam lithography and etching. (a, right) Optical micrograph showing nucleation sites and spherulite boundaries in an LDPE film before nanofabrication. (b, right) Optical micrograph showing features after patterning. (c) Atomic force micrograph showing pillars of similar height of approximately 76 nm and diameters varying from approximately 1000 nm to 100 nm, before chemical sorption. (d) Fluorescence micrograph of LDPE pillars after soaking in a rhodamine B solution. (e) Fluorescence micrograph of LDPE pillars after soaking in DSD solution. For both (c) and (d), the peak wavelength of fluorescence excitation is approximately 550 nm, and fluorescence emission is collected through a long-pass filter above 590 nm.

5:00pm NS-TuA-12 Optimizing Nanocrystalline WO₃ Thin Films: The Role of Oxygen, Thickness, and Pressure in Highly Selective and Responsive NO Gas Sensing, *Somdatta Singh*, Indian Institute of Technology Roorkee, India; Ravikant Adalati, University of Mons, Belgium; Prachi Gurawal, Raman Devi, Radhika Jain, Davinder Kaur, Ramesh Chandra, Indian Institute of Technology Roorkee, India

WO₃ thin films have been deposited using the room temperature (RT) sputtered DC magnetron sputtering approach on n-type (100) silicon substrates at various O₂/Ar gas ratios, thicknesses, and pressure variations for NO gas detection. The structural characteristics of the film were examined using X-ray diffraction (XRD). X-ray photoelectron spectroscopy (XPS) confirms that all monoclinic-phase WO₃ thin films contain oxygen vacancies. The FESEM study revealed a nanocrystalline structure with a

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granular, porous morphology. This study discusses how the WO_3 thin film's stoichiometry affects the NO gas sensing capability. The sub-stoichiometric WO_3 thin film-based sensor improved performance in terms of high stability, selectivity, and fast response/recovery time. The sensor response (R_g/R_0) was approximately 52.53 for a 100 ppm NO concentration at 275°C, with a fast response time of about 26 sec and a recovery time of about 19 sec. WO_3 thin-film-based NO gas sensing has been evaluated across a range of operating temperatures (50–325°C) and gas concentrations (1–100 ppm), observing a change in sensor response. Additionally, the NO gas-detecting mechanism on WO_3 's surface has been discussed. These results demonstrate the potential for creating high-performance, cost-effective gas sensors based on room-temperature sputtered nanocrystalline WO_3 thin films.

Keywords: WO_3 ; Thin films; Sputtering; Metal oxide; NO sensor.

5:15pm NS-TuA-13 Effects of Anode Distance on Field Emitter Array Performance in Simulation, *Youngjin Shin, Kenneth Chap, Ellie Bultena, Akintunde Akinwande*, Massachusetts Institute of Technology

We present our exploration into channel electric field redistributions of field emitter arrays (FEAs) by simulating the electrostatics at various anode-to-emitter distances, L_{AE} . Silicon FEAs are cold cathode electron sources that have shown promise for high-power applications such as power switches. One of the limiting factors of FEAs as a power switch is its relatively low efficiency at lower voltages. Some of the factors that contribute to an FEA's efficiency are the on-voltage ($V_{ON}=25\text{V}-30\text{V}$), operating anode-to-emitter voltage (V_{AE}), and the gate leakage current. Typically, to achieve a higher efficiency (>99%), FEAs are utilized in high-voltage applications that require >10kV bias on the anode to maximize the ratio between V_{AE} and V_{ON} [1]. However, there are challenges in operating FEAs at high-voltages due to large amounts of leakage current when driving higher current densities. In prior works, it has been implied that electrons emitted at a non-vertical emission angle are collected by the gate electrode, increasing the leakage current [2]. L_{AE} has mainly been studied for its effects on space charge but have not yet discussed its impact on reducing the gate leakage current when the device is in saturation, improving the output power efficiency. In this study, we conduct electrostatic simulations in COMSOL to demonstrate how decreasing L_{AE} influences channel field redistribution to reduce leakage current at the gate aperture with flat and cusp anode geometries.

Our simulations show that changes in L_{AE} result in distinct local electric field distribution patterns along the gate aperture; at smaller L_{AE} , the electric field is mostly vertical, whereas at large L_{AE} , the non-uniform field has higher horizontal electric field components away from the center of the gate aperture. Fig.1 and Fig.2 show the electric field distributions across the gate apertures for a 3x3 FEA at $V_{AE}=200\text{V}$, $V_{GE}=40\text{V}$, and $L_{AE}=2\text{mm}$, 5mm, and 30mm for a flat and cusp anode, respectively. The field distribution at 30mm indicates that it is likely that a smaller proportion of electrons from the emitter are collected at the anode compared to the 2mm and 5mm configuration due to the electric field being almost entirely vertical across the entire gate aperture. The cusp anode shows the most dramatic difference between 2mm and 5mm, likely owing to its focused tip shape. Our results indicate that reducing L_{AE} increases the vertical electric field, encouraging the emitted electrons have a vertical trajectory towards the anode, preventing its collection at the gate. Future work will focus on experimental validation of these findings and analyzing how to prevent breakdown at $L_{AE}<5\text{mm}$.

5:30pm NS-TuA-14 GaN Nanoscale Vacuum-Channel Transistors, *Huu Nguyen, Keshab Sapkota, George Wang*, Sandia National Laboratories

Field-emission-based nanoscale vacuum-channel transistors (NVCTs) can combine the robustness of vacuum devices with state-of-the-art lithography techniques enabling low operating power, on-chip integrability, energy efficiency, and high-performance stability in extreme environments such as high temperatures and high radiation. By scaling device channels to be below the electron's mean-free path in air, the NVCTs can be operate in air while maintaining the ballistic electron transport characteristic of vacuum. Here, we report experimental and modeling results of top-down fabricated, single emitter gallium nitride (GaN) lateral NVCTs. We used electron beam lithography along with dry and wet etching to fabricate GaN NVCTs with device channel lengths less than 300 nm. The devices exhibited stable high field-emission current up to 10 μA , with tuning on/off ratio greater than 10^4 . Significant current leakage to the gates was observed, necessitating careful design of the device geometry to maximize gate response while minimizing leakage current. Finite-element (COMSOL) modeling showed significant gate leakage with preferential collection of the field emitted electrons by gate electrodes. In addition, the simulation

showed electric field manipulation at the gate electrode tips by applied voltage potential at collector electrode and vice versa. This induced large gate current tuning via the collector voltage. This study elucidates the operation of field emission based lateral gated devices and provides important understanding in the design and operation of these new class of devices. *Sandia National Laboratories is managed and operated by NTESS under DOE NNSA contract DE-NA0003525. This work was performed, in part, at the Center for Integrated Nanotechnologies, a U.S. Department of Energy, Office of Basic Energy Sciences user facility. This paper describes objective technical results and analysis. Any subjective views or opinions that might be expressed in the paper do not necessarily represent the views of the U.S. Department of Energy or the United States Government.*

Plasma Science and Technology

Room 201 ABCD W - Session PS1-TuA

Plasmas in Advanced Packaging

Moderators: Catherine Labelle, Intel Corporation, Eric Miller, IBM

2:15pm PS1-TuA-1 Critical Plasma Processing Steps for Fusion and Hybrid Bonding Applications, *James Papana*, Tokyo Electron Corporate Innovation Division / Tokyo Electron Kyushu, Ltd., Japan; *Scott Lefevre, Jeffrey Shearer*, TEL Technology Center America; *Michiko Nakaya*, Tokyo Electron Corporate Innovation Division, Japan; *Yousuke Mine, Yutaka Yamasaki*, Tokyo Electron Kyushu, Ltd., Japan; *Takayuki Ishii*, Tokyo Electron Kyushu, Ltd, Japan; *Christopher Netzband*, TEL Technology Center America; *Yuji Mimura*, Tokyo Electron Kyushu, Ltd., Japan; *Chikashi Aoyagi*, Tokyo Electron Ltd., Japan; *Ilseok Son, Angelique Raley, Sitaram Arkalgud*, TEL Technology Center America

INVITED

Die-to-wafer (D2W) and wafer-to-wafer (W2W) hybrid and fusion bonding are integral to advanced packaging applications. Prior to bonding, for both D2W and W2W approaches, surface preparation is performed to facilitate the bonding process. Surface preparation consists of plasma activation and wet cleaning and hydration process steps. These steps are critical to obtain good interface quality and in turn high yield bonding that is void-free with high bond strength. Plasma surface activation is typically a relatively short, low power process. Nonetheless, the plasma source hardware and process conditions must be optimized to provide sufficient activation without roughening the dielectric layer (fusion and hybrid bonding) or sputtering and/or heavily oxidizing the bond pad Cu (hybrid bonding).

D2W bonding is required for chiplet heterogenous integration, and also offers the potential for yield improvement by the use of known good die for high bandwidth memory (HBM) and CMOS image sensor (CIS) applications. For D2W bonding, singulated die are bonded directly onto the target wafers. However, the quality of the die singulation process directly impacts the bonding yield. Defectivity levels for traditional saw dicing are too high for high volume D2W manufacturing. As such, advanced singulation techniques, such as plasma dicing are an essential part of the D2W ecosystem. For plasma dicing, there are two approaches, referred to as dice before grind (DBG) and dice after grind (DAG). For DBG, the etching process is performed before wafer thinning. The etching process trenches or grooves the full thickness wafers, and the dies are then singulated during the backgrind thinning process. For DAG, the etching process directly singulates or dices the thinned wafer, landing on a carrier. Consequently, the DBG and DAG have different process requirements and integration challenges.

In this paper, an overview of the fundamental mechanisms, chamber hardware factors, key process parameters, and process integration considerations for surface activation and plasma dicing steps will be presented. In addition, implementation of surface activation plasma for onto bonding cluster tools will be discussed.

2:45pm PS1-TuA-3 Plasma processing opportunities in the era of Chiplet and Advanced Packaging for AI application, *Fee Li Lie, Shravana Kumar Katakam, Yann Mignot, Eric Perfecto*, IBM Research Division, Albany, NY

INVITED

The evolution of artificial intelligence (AI) and machine learning (ML) technologies has exponentially accelerated the computing and memory power needed to train AI systems. This leads to larger and larger System on Chip (SoC) dies, some of which are hitting the lithography reticle limit or experiencing area-driven reduction of die yield. There is an additional need for very high bandwidth between processors and large arrays of memory. One emerging solution is to disaggregate large SoC dies into chiplets and re-connect them using advanced packaging techniques. Interconnection

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between chiplets can occur directly on the package substrate ("2D"), on an interposer ("2.xD"), through stacking of multiple chiplets ("3D"), or potentially a combination of these different technologies depending on application requirements. Die to die interconnect bandwidth and latency are key and we can broadly categorize these connections as lateral or vertical. Lateral interconnection is usually achieved through dual damascene Cu wiring in hard dielectric or plated-up Cu wiring in organic dielectric. Vertical interconnection is usually achieved by using "through" vias, namely Through Silicon Via (TSV), Through Dielectric Via (TDV), or Through Mold Via (TMV), in conjunction with fine pitch micro bump or Hybrid bonding for die to die joining. In this talk, we will discuss plasma processing opportunities in the era of Chiplet and Advanced Packaging, with emphasis on 3D integration with active Si interposers. We will introduce an overview of plasma processes typically used in 3D integration, and then review scope of needed improvements for some of the critical processes such as TSV RIE, Si thinning, and TSV reveal. Finally, emerging plasma applications for hybrid bonding such as plasma dicing will be introduced.

Plasma Science and Technology Room 201 ABCD W - Session PS2-TuA

Sustainability and Plasmas

Moderators: Phillippe Bezard, IMEC Belgium, Sara Paolillo, IMEC Belgium

4:00pm PS2-TuA-8 Fluorinated Gases in Plasma Etch: Challenges, Accomplishments, and Opportunities, David Speed, GlobalFoundries INVITED

Plasma etch and chamber clean processes are a primary source of CO₂-e emissions from semiconductor manufacturing processes. Net zero emissions and F-gas phase-out goals bring challenges that require multifaceted solutions, many of which have been the subject of industry efforts for over 30 years. This presentation surveys the principal challenges, accomplishments, and opportunities for achieving reduced CO₂-e emissions from plasma etch processes. Topics to be addressed will include etch process optimization, alternative low-GWP gases, enhanced abatement processes, gas capture and recovery, design integration strategies, and digital twin approaches.

4:30pm PS2-TuA-10 Kinetic Study of Microwave-Powered, Atmospheric-Pressure Hydrogen Plasma Reduction of Iron Oxide, Daniel Ellis¹, Vivek Pachchigar, Jazline Rebollar, University of Illinois Urbana-Champaign; Nabil Abuyazid, Lam Research Corporation; Necip Üner, Middle East Technical University, Turkey; Ivan Shchelkanov, Starfire Industries, LLC; Brian Jurczyk, Starfire Industries; Jessica Krogstad, Mohan Sankaran, University of Illinois Urbana-Champaign

The reduction of iron ore is a key step in steel production. There has been growing interest in applying plasmas to overcome thermodynamic and kinetic limitations with molecular hydrogen as a feedstock. Microwave excitation is of particular interest because of the potential to energy efficiently generate reactive plasma species. Previous studies have been carried out at low (vacuum) pressure or at high temperatures where the contribution of plasma species to the reduction process were not clear.

Here, we studied an atmospheric-pressure, microwave-powered hydrogen plasma for iron oxide reduction. By using a solid-state amplifier to generate the microwave power and a coaxial geometry to transmit the radiation and excite the gas, a plasma jet free from any surface is produced which can be used to treat a material downstream at low temperatures (<~400 °C). Using this setup, we treated thin films of iron oxide (hematite) powder to minimize diffusional resistance. The extent of reduction at various process conditions was evaluated by mass loss measurements and X-ray diffraction. The reduction was correlated with plasma properties by optical emission spectroscopy (OES). In particular, the density of hydrogen radicals in the plasma volume was obtained by actinometry and the transport of hydrogen radicals to the iron oxide surface was estimated by a one-dimensional diffusion-advection-recombination model. The surface temperature of the film was obtained by optical infrared pyrometry. All together, we were able to isolate the role of a plasma-activated species, the hydrogen radical, and demonstrate its capability for low-temperature reduction. In addition, a kinetic analysis was performed to obtain an apparent activation energy of ~50 kJ/mol, compared to purely thermal reduction of 92 kJ/mol.

4:45pm PS2-TuA-11 Transient Assisted Processing (Tap): A Novel Scalable Plasma Processing Approach for Precision Etching and Sustainability in Semiconductor Manufacturing, Atefeh Fathzadeh, KU Leuven and Imec, Belgium; Philippe Bezard, IMEC, Belgium; Stefan De Gendt, KU Leuven and Imec, Belgium

New device architectures and computing paradigms require patterning a wide variety of materials with sub-nanometric precision and pattern fidelity, introducing new challenges. For instance, remaining Ga residues after patterning InGaZnO₄ channels cause higher gate leakage in 2T0C DRAM cells¹ or profile imperfections of NbTiN lead to higher power consumption and variations in critical current in Superconducting Quantum Computing (SQC)². Among existing methods, Atomic Layer Etching (ALE) offers excellent precision; however, its high gas consumption and low throughput limit its practicality to ultra-thin layer (≤10 nm) applications. These challenges, coupled with environmental concerns of dry etching, have driven interest in developing more sustainable etching approaches.

Transient-Assisted Processing (TAP) provides a breakthrough solution³. TAP is a cyclic process based on reactant transients caused by interrupted gas injection after a short, sustained flow. The dosage, gas injection, and plasma ignition timings ensure an optimal ion-to-neutral ratio and control species formation (Fig1), enhancing process control, pattern fidelity and preserving surface composition. By exploiting the outgassing phenomenon, TAP significantly reduces gas consumption, including environmentally harmful gases, compared to ALE and Reactive Ion Etching (RIE). TAP has also proven effective in precisely cleaning damage-sensitive materials and enabling in situ hard-mask deposition^{4,5}.

This presentation demonstrates TAP's advantages in versatility, scalability, and precision over RIE and ALE for various materials and applications (Fig 2). TAP's sustainability benefits are demonstrated on CMOS BEOL stacks at 24 nm pitch. Additionally, patterning NbTiN/HfZrO/NbTiN capacitors and NbTiN interconnects for SQC at 28 nm pitch showcases TAP's superior pattern control. TAP also provides highly precise control over the etch rate of compound materials, as illustrated by the patterning of IGZO at a 28 nm pitch for 2T0C-based DRAM. The study is also supported by plasma diagnostics, highlighting the underlying plasma mechanisms.

Compatible with as many materials as conventional etching, TAP not only provides better patterning performance and significantly lower consumption of harmful gases, but also achieves precision close to ALE, at a much higher throughput. This makes TAP a more sustainable and higher-performing solution for both current and future applications.

Plasma Science and Technology Room 201 ABCD W - Session PS3-TuA

Plasma Science Late Breaking Oral Session

Moderators: Phillippe Bezard, IMEC Belgium, Sara Paolillo, IMEC Belgium

5:00pm PS3-TuA-12 Atomic Layer Etching of Silicon in Continuous Flow, Pulsed Bias Power Plasmas, Vincent Donnelly, Jeremy Mettler, Qinzhen Hao, Mahmoud A. I. Elgarhy, Dept .of Chem. and Biomolec. Eng, University of Houston; Heejung Kim, Semiconductor R&D Center, Samsung Electronics Co., Ltd., Republic of Korea; Sang Ki Nam, Mechatronics Research, Samsung Electronics Co., Ltd., Republic of Korea; Song-Yung Kang, Semiconductor R&D Center, Samsung Electronics Co., Ltd., Republic of Korea

Atomic layer etching (ALE) provides superior control of etching rate uniformity, but is unacceptably slow for many applications when compared to conventional etching processes. In plasma-assisted ALE required for anisotropic etching, one cycle starts with exposing the substrate to a reactive gas such as Cl₂ for Si or fluorocarbon species for SiO₂, forming an adsorbed layer. The reactive gas flow is turned off and the reactor is purged of this species, usually with an inert carrier gas such as Ar. A plasma is ignited in the inert gas and a substrate bias results in energetic ion bombardment to remove a product layer. The problem with this approach is that the purge step needs to be long enough to reduce the reactive gas to a low enough layer such that no further chemisorption occurs during the ion bombardment step. Otherwise, the self-limiting nature of ALE is compromised. Even with the highest purge gas flow rates, it is difficult to reduce this purge time to less than one second, due at least in part to uptake and release of reactive gases from the chamber walls. Here we take a different approach to plasma ALE. With a constant inductively-coupled plasma (ICP) power, a continuous flow of reactant gas (Cl₂) was maintained in a continuous high flow of Ar carrier gas. Etching occurred during periodic substrate bias power periods (-75 DC self-bias voltage) of 0.2s to 0.5s.

¹ JVST Highlighted Talk

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Between non-ALE continuous etching at too high a Cl₂ partial pressure, and a rate approaching physical sputtering at too low a Cl₂ partial pressure, an “ALE window” was found at low Cl₂ partial pressures where the chlorination rate during 1s periods with no bias power formed a SiCl_x layer that was sputtered away during the substrate bias period at a rate that was faster than the rate at which the surface could re-chlorinate. Under these conditions, an etching rate of ~0.2nm/cycle, or about 1 monolayer of Si was achieved. Optical emission spectroscopy and a simple Langmuir-Hinshelwood model were used to monitor SiCl desorption during the ALE cycles and provided further insights into the etching mechanism. This work was supported in part by Samsung Electronics (project code IO240308-09220-01).

5:15pm PS3-TuA-13 Correlation of Optical Emission Spectroscopy Line Ratios with Deposition Rate and Refractive Index of Silicon Nitride Films in Plasma Enhanced Chemical Vapor Deposition, Youngju Ko, Hyeonjin Choi, Jinmyeong Kim, Sungkyunkwan University (SKKU), Republic of Korea; Namgun Kim, Samsung Electronics Co., Republic of Korea; Heeyeop Chae, Sungkyunkwan University (SKKU), Republic of Korea

Optical emission spectroscopy (OES) is common non-invasive method for monitoring plasma in semiconductor manufacturing and analyzes emitted light without disturbing the plasma. Quantitative understanding of plasma states from OES peak intensities is still challenging. In this work, the deposition rate and refractive index of silicon nitride (SiN_x) deposited using trisilylamine (TSA), NH₃ and N₂ gas were predicted using OES analysis in plasma enhanced chemical vapor deposition (PECVD). The four dominant peaks of 337 nm (N₂ second positive system), 391.2 nm (N₂⁺ first negative system), 656 nm (H_α Balmer line), and 486 nm (H_β Balmer line) were selected, and the correlation between the deposition rate and intensity ratios of I_{N₂⁺}/I_{N₂} and I_{H_α}/I_{H_β} was investigated. The I_{N₂⁺}/I_{N₂} was found to be strongly correlated with the deposition rate with coefficient of determination (R²) of 0.85 and mean absolute percentage error (MAPE) of 3.66%. This strong correlation is attributed to the fact that the ratio represents the variation of electron temperature, which increases molecular dissociation and ionization in plasma. However, the refractive index was poorly correlated with the I_{N₂⁺}/I_{N₂} and I_{H_α}/I_{H_β} line ratios, and the intensity ratios of I_{NH}/I_{N₂} and I_{SiH}/I_{N₂} were suggested from 336 nm (NH), 414.2 nm (SiH), and 337 nm (N₂) peaks as indicators representing the relative radical density of NH and SiH radicals. These line ratios were derived because they have similar overlap of excitation cross sections with electron energy distribution function (EEDF) in typical inductively coupled plasmas (ICP). The derived I_{SiH}/I_{NH} ratio showed a strong correlation with the refractive index, as the atomic composition of N and Si in the film is directly influenced by NH and SiH radicals in plasmas. The refractive index with I_{NH}/I_{N₂} and I_{SiH}/I_{N₂} line ratios showed high accuracy with R² of 0.95 and MAPE of 0.27%. This work demonstrated that the OES intensity ratio proposed as I_{N₂⁺}/I_{N₂} and I_{SiH}/I_{NH} can effectively predict deposition rate and refractive index in SiNx PECVD.

5:30pm PS3-TuA-14 Particle-in-Cell Simulations of Low Pressure Magnetized Plasma, Taaresh Taneja, Applied Materials Inc.; Shahid Rauf, Applied Materials, Inc.; Prashant Kothnur, Applied Materials Inc.

Low pressure magnetized plasmas (e.g., magnetrons) are widely used for metal deposition in the semiconductor industry. This study focuses on kinetic phenomena important in these plasma discharges. In particular, the generation and propagation of waves of electron and ion densities are studied. One-dimensional Particle-In-Cell (PIC) simulations with Monte Carlo Collisions (MCC) of argon plasma are used for this investigation. The simulations were conducted across a range of pressures (1–10 mTorr), ion masses (10 amu – 160 amu), and external magnetic field strengths (peak ranging from 200 G to 400 G) to explore the influence of these parameters on the plasma dynamics. The plasma was confined between a cathode and an anode, with a magnetic field applied perpendicular to the simulation axis that exponentially reduces from the cathode to the anode.

Distinct wave-like structures were observed propagating from the anode towards the cathode under various conditions. These waves exhibited clear dependence on the magnetic field strength and ion mass, suggesting a magnetically driven mechanism. Detailed analysis of the wave frequency and phase velocity revealed characteristics consistent with ion cyclotron waves, including their scaling with the ion cyclotron frequency and propagation behavior in magnetized plasmas. However, these ion and electron density waves are not found to be in perfect resonance with the ion cyclotron mode. The frequency was found to also scale inversely with the square root of the ion mass, suggesting ion acoustic wave contribution. Moreover, the wave amplitude was found to rise in the direction of

propagation, suggesting a non-linear, oscillation growing mechanism. This change in amplitude was much more pronounced at higher pressures, such as 10 mTorr.

The identification and analysis of these waves provide insight into ion transport and energy redistribution in magnetized low-pressure discharges, which are critical to optimizing sputtering efficiency and uniformity in physical vapor deposition processes. The results demonstrate the capability of PIC-MCC simulations to capture kinetic and magnetic field-induced transport effects that are often very crudely approximated in fluid models. These findings contribute to a deeper understanding of plasma behavior in magnetron systems and may inform the design of more efficient and controlled deposition environments.

5:45pm PS3-TuA-15 Effect of Nitrogen Addition on Electron Density and Uniformity Enhancement in Oxygen Plasma, Yeongjae Jeong, Chin-Wook Chung, Hanyang University, Korea

In oxygen plasmas, the formation of negative ions leads to a reduction in electron density at the discharge center and degrades the overall discharge uniformity. This study investigates the effects of adding small amounts of nitrogen to oxygen discharges, focusing on changes in electron density and spatial uniformity. Experiments were carried out in a 13.56 MHz inductively coupled plasma at 200 mTorr under varying nitrogen admixture ratios. The electron energy probability function (EEPF) was measured radially using an RF-compensated Langmuir probe. The results show that the addition of nitrogen increases the central electron density by up to 42% and improves discharge uniformity. This phenomenon is attributed to vibrational excitation of nitrogen molecules, which acts as a competing energy loss channel for low-energy electrons, thereby suppressing the formation of negative oxygen ions and reducing electron loss. In this study, we define a parameter termed electron retention efficiency to quantify this effect and analyze its correlation with electron density enhancement. The results indicate that higher electron retention efficiency leads to a more significant increase in electron density, demonstrating that minor nitrogen addition can be an effective method to control electron density and uniformity in oxygen plasmas.

Quantum Science and Technology Mini-Symposium Room 208 W - Session QS1-TuA

Interdisciplinary Quantum Applications

Moderators: Yi-Ting Lee, University of Illinois at Urbana Champaign, Kasra Sardashti, University of Maryland College Park

2:15pm QS1-TuA-1 A Study of Superconducting Behavior in Ruthenium Thin Films, Bernardo Langa Jr., University of Maryland; Brooke Henry, Clemson University; Ivan Lainez, University of Maryland; Richard Haight, IBM; Kasra Sardashti, University of Maryland

Ruthenium (Ru) is a promising candidate for next-generation electronic interconnects due to its low resistivity, small mean free path, and superior electromigration reliability at nanometer scales. In addition, Ru exhibits resistance to oxidation, low diffusivity, and most importantly, superconductivity below 1 K. These qualities make Ru an attractive material for superconducting qubits where its stability may help mitigate two-level system defects. Here, we investigate the superconducting behavior of Ru thin films (11.9–108.5 nm thick), observing transition temperatures from 657.9 mK to 557 mK. A weak thickness dependence appears in the thinnest films, followed by a conventional inverse thickness dependence in thicker films. Magnetotransport studies reveal type-II superconductivity in the dirty limit ($\xi > l$), with coherence lengths ranging from 13.5 nm to 27 nm. Finally, oxidation resistance studies confirm minimal RuO_x growth after seven weeks of air exposure. Our findings provide key insights for integrating Ru into superconducting electronic devices and explore its potential in advancing scalable, high-coherence quantum devices.

2:30pm QS1-TuA-2 Realizing Epitaxial Trilayer Josephson Junctions Grown with Molecular Beam Epitaxy, Colin Myers, University of Maryland, College Park; Kasra Sardashti, Laboratory for Physical Sciences; Christopher Richardson, Laboratory for Physical Sciences, College Park

The Al/AlO_x/Al Josephson Junction (JJ) remains the primary choice for superconducting qubit design. Reducing the potential loss mechanisms and two-level systems (TLS) in these junctions is a major priority for quantum computation and design. Hence, many alternatives to the traditional JJ are being explored, with NbTiN posing as a possible substitute for aluminum. Alloyed NbTiN possesses a T_c near 17 K, allowing for far higher operating temperatures compared to aluminum. Utilizing plasma-assisted molecular

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beam epitaxy (PAMBE), we grow epitaxial trilayer stacks of NbTiN/AlN/NbTiN, where AlN serves as the insulating barrier layer of the JJ. This allows for an oxygen-free system, in addition to employing the precise thickness and compositional control associated with traditional MBE growth. Assembling a JJ from this trilayer architecture now presents unique patterning and lithography challenges. We present a novel approach to JJ design and fabrication, as well as epitaxial NbTiN as an emergent material for quantum information science.

2:45pm QS1-TuA-3 Enabling Quantum Information Science with DNA-Templated Quantum Materials, Xin Luo¹, Jeffrey Gorman, Mark Bathe, Massachusetts Institute of Technology

Quantum information science is limited by the lack of materials that enable precise, rational control over quantum photonic, excitonic, and spin states and other properties of the quantum materials. While DNA nanotechnology offers in principle such control via spatial templating of chromophores, quantum dots, and molecular spin centers with nanometer-scale precision, this capability requires interfacing with silicon-based 2D devices to enable quantum information science with translational impact on devices. Toward this end, we previously demonstrated that programmable DNA templates can position quantum materials such as colloidal quantum dots and rods with nanometer-scale precision for integration with photonic devices through top-down electron beam lithography [1]. Here, we apply this approach to fabricate photonic cavities to control single-photon emissive properties and photonic waveguides for photonic quantum circuits. We additionally demonstrate pathways towards controlling molecular spins and excitons with DNA templates for quantum information science and technology. This scalable approach to templating quantum materials opens new applications to quantum sensing, networking, and simulation, with potential impact on secure communications, medical diagnostics, computing, and beyond.

[1] Luo, X. et al. DNA origami directed nanometer-scale integration of colloidal quantum emitters with silicon photonics. *bioRxiv*, doi: 10.1101/2025.01.23.634416 (2025).

3:00pm QS1-TuA-4 Enhanced Readout Contrast of V2 Ensembles in 4H-SiC Through Resonant Optical Excitation, Infiter Tathifif, University of Maryland College Park; Charity Burgess, Brenda VanMil, Army Research Laboratory; Samuel G. Carter, Laboratory for Physical Sciences

Favorable optical and spin properties of the V2 silicon vacancy defect in 4H-SiC have made it a promising candidate for quantum technologies. For quantum sensing with defect spins, the contrast in optically-detected magnetic resonance (ODMR) is an important metric, which tends to be rather low (<1%) for V2 ensembles using off-resonant laser excitation. To improve contrast, we resonantly excite the V2 ensembles at low temperatures and compare our findings with off-resonant excitation. Our measurements show a ~90 times improvement for ODMR contrast over the off-resonant case for fairly low resonant excitation. We hypothesize that for a particular wavelength, the resonant laser excites a subset of defects within the ensemble and drives only one of the spin-selective optical transitions for each defect. This leads to a strong spin polarization, contributing to the high readout contrast. To test our hypothesis and further characterize the behavior, we examine the dependence of the contrast on the laser linewidth and the sample temperature. Modulating the resonant laser linewidth up to 1 GHz, corresponding to the splitting of the two optical transitions, results in the contrast decreasing by 50%. As the temperature is increased to 60 K, the contrast decreases and reaches the off-resonant value, presumably due to linewidth broadening. Although the PL signal is 50 times weaker than the off-resonant excitation due to the participation of the defect sub-ensemble, the sensing figure of merit (FoM) is 10 times higher, making the resonant approach still the best choice for sensing at low temperatures. Due to the high readout contrast and reduced laser power requirements, we plan to utilize this resonant technique for wide-field magnetic imaging of quantum materials and devices at low temperatures.

3:15pm QS1-TuA-5 Enhancement of Superconductivity in Cryogenically Grown Ultra Thin Al Films, Teun van Schijndel, Yu Wu, Wilson Yáñez-Parreño, Tawshia Chowdhury, Christopher Palmstrom, University of California at Santa Barbara

Superconductivity in thin films can deviate significantly from bulk behavior, especially as dimensionality and disorder come into play. This is particularly true for aluminum, where critical temperature (T_c) and film morphology are highly sensitive to thickness and growth conditions. Here, we present an *in-*

situ scanning tunneling microscopy (STM) study, performed at 78 K, of Al thin films grown on atomically clean Si(111) substrates by molecular beam epitaxy at cryogenic temperatures down to 6 K. The morphology is characterized across a wide range of coverages, from sub-monolayer up to 20 monolayers (ML). Cryogenic growth results in oriented hexagonal islands that begin to coalesce into a continuous film around 5 ML, with a typical roughness of a few monolayers. This roughness is constant up to 20 ML. Upon annealing to room temperature, the surface becomes nearly atomically smooth, though grain boundaries remain visible in STM. In contrast, room temperature growth produces significantly rougher films with large, disconnected islands of varying shape and orientation. We also investigated the superconducting properties of cryogenically grown films after exposure to atmospheric conditions, as required for ex-situ transport measurements. To stabilize the films, we used different post-growth treatments, including low temperature capping, cold oxidation, and room temperature oxidation. The films show critical temperatures approaching 3 K, which is significantly above the bulk value of 1.2 K.

Quantum Science and Technology Mini-Symposium

Room 208 W - Session QS2-TuA

Scalable Fabrication for Quantum Technology

Moderators: Ekta Bhatia, NY CREATES, Bernardo Langa, Jr., University of Maryland

4:00pm QS2-TuA-8 Sandia's Approach to Scalable Single Defect Center Creation using Focused Ion Beam Implantation, Edward Bielejec, Sandia National Laboratories

INVITED

We will present an overview of Sandia's Ion Beam Laboratory (IBL) and its ongoing efforts to develop focused ion implantation capability using a range of accelerators to create scalable defect centers in wide bandgap materials. This presentation will cover three main topics:

(1) Novel liquid metal alloy ion source development (LMAIS) where we will concentrate on the development of LMAIS for our two mass filtered Focused Ion Beam (FIB) systems, the A&D nanoplanner (A&D FIB100NI) and the Raith Velion, both of which combine high spatial resolution with CAD based patterning to enable the formation of arbitrary patterned implantation in a wide range of substrates.

(2) In-situ counting and in-situ photoluminescence (PL) to enable single defect center creation in wide bandgap materials such as diamond and silicon carbide. Using in-situ counting we demonstrate a seven-fold improvement on the expected ion implantation error over timed implantation. Using in-situ PL we enable real-time error correction on the formation of low yield optically active defect centers. The combination of counting and PL is a promising pathway towards deterministic formation of these defect centers.

(3) The development of ultra-low energy (<<1 keV) focused ion implantation capability based on a biased sample holder configuration. This enables ultra-low energy implantation while maintaining an expected implantation resolution of between 100-300 nm.

It is the combination of these three topics that fundamentally enables the IBL approach to scalable single defect creation using FIB implantation.

Sandia National Laboratories is a multimission laboratory managed and operated by National Technology & Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA0003525.

4:30pm QS2-TuA-10 Scalable Single-Erbium Ion Qubits in Silicon Carbide for Integrated Photonics in the Telecom Band, Spyros Galis, Alexander Kaloyerous, University at Albany-SUNY

Advancing quantum photonics and communications requires scalable optical quantum devices compatible with chip-scale device integration and higher temperature operation (≥ 77 K) for integration into photonic integrated circuits (PICs). Highly integrable silicon carbide (SiC) has emerged as a promising PIC platform, offering ideal material and optical properties for classical and quantum photonics. In parallel, scalable material platforms doped with erbium (Er^{3+}), which has an optical transition in the telecom range at ~ 1532 nm, can enable a plethora of exciting photonic and quantum technologies operating in the telecom C-band. Toward this, telecom single-photon emitters (SPEs) and qubits based on single ions in semiconductors are essential for quantum PICs (qPICs), yet scaling them beyond the lab remains challenging due to material constraints, stringent

¹ JVST Highlighted Talk

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fabrication and temperature requirements, and random emitter placement, complicating PIC integration.

Our approach utilizes a novel, scalable nanofabrication scheme to address these challenges, enabling the creation of SiC nanowires (NWs) and hollow nanopillars (HNPs). This approach facilitates the following key-enabling innovations: 1) the precise (<5 nm) placement of Er^{3+} ions in these nanostructures via advanced nanofabrication and implantation engineering and 2) an enhanced effective excitation cross-section ($\sim 6 \times 10^{-18} \text{ cm}^2$). By leveraging these innovations, we have successfully isolated and characterized single and few-erbium ions in SiC NWs and HNPs at temperatures of ≥ 77 K—otherwise unattainable in bulk materials. Furthermore, through nanofabrication engineering and the minimization of implantation-induced defects, we have demonstrated single-photon Er^{3+} emission with a narrow optical linewidth of 90 MHz and single- Er^{3+} -ion qubit control, performed by Rabi oscillations in the optical domain and at temperatures of ≥ 77 K, in HNP SiC structures. Pertinent results will be presented, which, to our knowledge, represent the first experimental demonstrations of solid-state SPEs and single-ion qubits based on isolated Er^{3+} , highlighting our platform's viability for higher-temperature operation. We also concisely discuss opportunities for realizing Er-based SiC quantum integrated devices with improved performance and functionality, aiming to achieve practical qPIC devices for quantum and nanophotonic applications at telecom wavelengths.

4:45pm QS2-TuA-11 Scalable, Precise, and Reliable Positioning of Colour Centres for Quantum Computing and Simulation, Mark Mills, Gianfranco Aresta, Kristian Stockbridge, Kate McHardy, Paul Blenkinsopp, Ionoptika Ltd., UK

Quantum computing has the potential to revolutionize many aspects of modern technology and colour centres in diamond are a well suited system to be used as quantum simulators, quantum sensors and quantum networking interfaces. NitrogenVacancy (NV) centres are the most extensively studied due to their ground-state spin's long coherence times at room temperature. Next to NV centres, also group-IV colour centres in diamond offer a promising platform for quantum networks and started gathering interest as an alternatives, with the TinVacancy (SnV) centres standing out among group-IV defects due to their optimal spin-orbit coupling.

The technological challenges related to the fabrication of quantum devices based on these systems are related to the reliable and precise positioning of N and Sn atoms into the diamond matrix and the subsequent post implantation process such as thermal annealing and the scalability of the whole process.

In 2024 Ionoptika Ltd started a joint development project, partially funded by Innovate UK, in partnership with Surrey University, Fraunhofer Institute for Applied Solid State Physics IAF and XeedQ GmbH, bringing together a Focussed Ion Beam (FIB) System company, experienced FIB users and materials research Institutes with a quantum computing company. The aim of this project is to define a process for Scalable, Precise, And Reliable positioning of colour centres (NV and SnV) for Quantum computing and simulation.

We will be reporting on the engineering of a novel ion-beam column based on the well-established Ionoptika's Q-One platform for ion implantation. This single novel column will allow for use of both Liquid Metal Alloy Ion Source and Plasma Source. It will be equipped with an automated source adjustment system and ion beam autotuning. Parallel studies are being carried out with existing Q-One systems at Surrey University in collaboration with the other partners, Fraunhofer IAF and XeedQ, within this project, and we will report on these. We will also report on colour centres formation results obtained by other research institutes by using the Q-One ion implanter.

5:00pm QS2-TuA-12 Integration of Atomic Precision Solid State Quantum Hardware with energy efficient circuit, architecture and algorithm co-design for Energy Efficiency Scaling, Tina Kaarsberg, Department of Energy; Sadasivan Shankar, SLAC National Accelerator Laboratory; Scott Lockledge, Tiptek

It is auspicious that this abstract is being submitted on April 14—World Quantum Day—a date that includes the first three digits of Planck's constant, which is a fundamental constant in quantum physics. The United States Department of Energy (DOE) Advanced Materials and Manufacturing Technology Office (AMMTO) multi-organization initiative to reduce computational energy use with energy efficiency scaling for two decades (EES2) will likely rely in part on advances in quantum computing—including

quantum hardware to reach its ultimate 1000X energy efficiency goal. Under this initiative, DOE/AMMTO has funded analysis identifying new breakthrough approaches to energy efficient computing. For example, in Summer 2023, a SLAC analysis showed that using quantum algorithms for quantum mechanical calculations could use as little as one thousandth the energy of the same calculation on a classical computer. AMMTO also supports quantum hardware, for example in 2024, it announced two SBIR grants for qubit manufacturing development of 3D atomically precise (AP) qubits made using hydrogen depassivation lithography. Such AP qubits have inherently lower error rates than macro-sized qubits. This paper will highlight co-design integration of such AP solid-state quantum hardware with quantum software. The co-design will include innovations in circuit, architecture and algorithm for a wide range quantum calculations that could enable DOE to reach its 1000X energy efficiency goal

5:15pm QS2-TuA-13 Measurement of Dielectric Loss in Piezoelectric Materials for Hybrid Quantum Systems, Ivan Lainez, University of Maryland College Park; Richard Mattish, Clemson University; Bernardo Langa, Jr., University of Maryland College Park; Maggie Marte, Deepak Sapkota, Clemson University; Christopher Rouleau, Jong Keum, Oak Ridge National Laboratory; Ashish Alexander, Laboratory for Physical Sciences; Kasra Sardashti, University of Maryland College Park

An approach has been emerging to create hybrid quantum devices by combining quantum devices realized in distinct physical systems and therefore combining their advantages. In particular, piezo-acoustic cavities are of particular interest as they are capable of direct coupling of systems operating in the microwave regime to systems operating at the acoustic regime via acoustic modes through piezoelectric modulation. However, creating a piezo-acoustic cavity requires on-chip integration of physically disparate piezoelectric and superconducting materials while maintaining a coherent behavior at microwave frequencies and milliKelvin (mK) temperatures. The extent of dielectric loss in the piezoelectric elements within the cavities has not been well studied. Here, we study the dielectric loss in epitaxial heterostructures of barium titanate (BTO), Strontium titanate (STO), and Lanthanum nickel oxide (LNO)-on-silicon as promising platforms for piezo-acoustic cavities. We use a 6-resonator superconducting coplanar waveguide design as a pilot device to measure microwave losses at mK temperatures. By changing the thickness of various layers within the BTO/Si, STO/Si, and LNO/Si heterostructures, including the buffer layers (e.g., YSZ, CeO₂), we determine the loss contributions for each oxide layer. Microwave transmission for each chip is measured at 30 mK-2 K with powers ranging from -60 to -120 dBm. The transmission spectra are then analyzed to extract the actual resonant frequency, quality factors (internal vs. external), and effective dielectric constant for each chip.

**Advanced Surface Engineering
Room 205 ABCD W - Session SE-TuA**

Smart Coatings and Responsive Surfaces: Engineering for Tomorrow

Moderator: Filippo Mangolini, The University of Texas at Austin

4:00pm SE-TuA-8 Spatial Configurations in Magnetron Sputtering: A Comprehensive Review, Esteban Broitman, Rickmer Kose, SENTYS Inc.; Sven Kelling, SENTYS, Inc.

Magnetron sputtering stands at the forefront of thin-film deposition, with its efficacy intimately tied to how magnetron sources and substrates are arranged in space. In this review, we distill experimental results from across the literature into three core configurational categories: sputter-up versus sputter-down magnetron orientations, planar versus confocal magnetron arrays, and on-axis versus off-axis substrate alignments.

For each configuration, we explore how geometry shapes plasma confinement, steers the angular distribution of sputtered atoms, and dictates film characteristics—density, residual stress, microstructural evolution, and step coverage. By correlating specific geometric features with these critical film properties, we introduce a decision framework that guides researchers in selecting the optimal magnetron arrangement to achieve a targeted material performance.

To illustrate practical implementation, we showcase contemporary deposition chambers and magnetron source designs engineered for rapid, tool-free adjustment of magnetron-substrate geometry, empowering users to fine-tune film growth *in situ*.

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4:15pm SE-TuA-9 Wide-Bandgap Hybrid Metamaterials: Theory guided Advanced Surface Engineering for UV active Photonic Properties, *Ufuk Kilic*¹², *Shawn Wimer, Matthew Hilfiker, Raymond Smith, University of Nebraska-Lincoln; Christos Argyropoulos, The Pennsylvania State University; Eva Schubert, Mathias Schubert, University of Nebraska-Lincoln*

Metamaterials (MMs) -the artificially engineered surface structures with subwavelength scale features- are at the forefront of optoelectronic, quantum, and biomedical advancements [1-4]. Despite the critical importance, their effective operation in the ultraviolet (UV) spectral range by using wide-bandgap materials (WBGM) for aforementioned advancements is seldom discussed in the literature [1]. WBGMs provide exceptional transparency, high stability, corrosion resistance, and UV-active optical responses. These properties enable strong UV-active light-matter interactions, making them ideal for robust, tunable MMs in advanced photonic and quantum applications.

In this study, our methodology is framed over a theory-guided approach for fabricating and optimizing MM platforms from ultra-wide bandgap Zirconia (ZrO_2). While the finite element modeling provides insights on light-matter interaction at nanoscale [2-4], Monte Carlo ballistic simulation method unravels the particle flux dynamics and the structure growth process [5]. Utilizing electron beam assisted glancing angle deposition technique, that is particularly known for its capacity to produce various 3D morphologies over wafer-scale area, and free of masks [2-4], we fabricated highly ordered nano-columnar, and nano-helical MM platforms. Using Mueller Matrix generalized spectroscopic ellipsometry technique, we optically investigated the fabricated MM platforms within the spectral range covers near-IR (0.64 eV) to vacuum-UV (9.5 eV) and found that they exhibit strong optical anisotropies including circular dichroism and birefringence.

Here, we also present and discuss the subsequent depositions of dielectric (ZrO_2) and metallic (silver/Ag) materials leading to hybrid plasmonic MMs with a multiple number of subsegments that achieve enhanced and spectrally controlled optical anisotropies active in visible to UV spectral range. Performing complementary scanning electron microscopy, transmission electron microscopy, and energy-dispersive X-ray spectroscopy, we extracted the integrity, crystallinity, and stoichiometry of the fabricated MM platforms. This work advances photonic and quantum device design by integrating material fabrication, theoretical modeling, and experimental characterization, demonstrating how wide-bandgap ZrO_2 combined with plasmonic metals enables tunable MMs for high-power systems, UV photonic circuits, and chiral sensors.

[1]Duncan, M. A.,et al.,*ACS Appl.Mater.Interfaces*,14(50),55745-55752,(2022)

[2]Kilic, U.,et al.,*Adv.Funct.Mater.*31.20:2010329,(2021)

[3]Kilic, U.,et al.,*Adv.Opt.Mat.*2302767,(2024)

[4]Kilic, U.,et al.,*Nat.Comm.*15.1:3757,(2024)

[5]Wimer, S.,et al.,*Vacuum*,(under review 2025)

4:30pm SE-TuA-10 On the Energy Efficiency of Sputtering of Elemental Targets by Inert Gas Ions Ne, Ar, Kr, and Xe, *Ivan Petrov*, University of Illinois at Urbana Champaign; *Michal Fečík, Stanislav Mráz, Jochen Schneider, RWTH Aachen University, Germany*

Environmentally responsible surface engineering has emerged as an important topic in academic and industrial research. A recent review article¹ provides an extensive overview of sustainability aspects of physical vapor deposition (PVD) processes, focusing on magnetron sputtering and cathodic arc deposition. The authors point out that “energy and mass balances are an important sustainability-relevant aspect, constituting tremendous untapped potential for the surface engineering community”. Sputtering by particle bombardment produces energetic species which contribute to low-temperature growth of high-quality coatings and films. A large portion of the incoming energy is, however, converted to heat in the targets. Therefore, it is of interest to optimize the energy and the mass of the inert gas to make sputtering more energy efficient. Here we attempt to quantify the fraction of the incoming energy which is transferred to the sputtered atoms for elemental targets as a function of ion energy for four inert gases, Ne, Ar, Kr, and Xe. Previously, Carter et al² introduced the term erosion efficiency, $\eta^{\text{er}} = U\text{Y}(E)/E$, where U is the sublimation energy of the metal target. This definition includes the potential energy required to remove the atom from the surface but does not consider the kinetic energy of the sputtered atoms. Petrov et al³, using the Yamamura et al⁴ expression

for the sputtering yield $\text{Y}(E)$, showed that the maximum value of the erosion efficiency, $\eta^{\text{er}}_{\text{max}}$, exhibit periodic fluctuations as a function of the atomic number of the target Z_2 in the interval 0.4-4%. Here we extend this approach to calculate the sputtering energy efficiency $\eta^{\text{sp}} = (U+E_{\text{av}})\text{Y}(E)/E$, where E_{av} is the average kinetic energy of the sputtered atoms, estimated using the Thompson formula. Values of $\eta^{\text{sp}}_{\text{max}}$ are approximately factor of x4 higher in the range of 2-16%. Ar delivers close to optimal total energy efficiency for targets with atomic number $Z_2 < 50$, while for heavier targets Kr yields higher total efficiencies from approximately 20% to 80%, and Xe from 20% - 110%. The sputtering energy efficiency η^{sp} exhibits maximum values at ion energies approximately factor of 2 higher than the values for $\eta^{\text{er}}_{\text{max}}$. The ion energy interval within which $\eta^{\text{sp}} > 0.8 \eta^{\text{sp}}_{\text{max}}$ for most targets is 100-1500 eV.

1. M. Hans, J.M. Schneider, A. Matthews, C. Mitterer, *Surf. Coat. Technol.* **494**(2024)131486
2. G. Carter, M.J. Nobes and D.G. Armour, *Vacuum* **32**(1982)509
3. I. Petrov, V. Orlinov, S. Grudeva, *Bulg. J. Phys.* **18**(1991)215
4. Y. Yamamura, N. Matsunami, N. Itoh, *Rad. Eff.* **71**(1983)65

Surface Science

Room 209 CDE W - Session SS-TuA

Heterogeneous Catalysis I

Moderators: *Zbynek Novotny, Paul Scherrer Institute, Switzerland, Dario Stacchiola, Brookhaven National Laboratory*

2:15pm SS-TuA-1 Interstellar Catalysis - a Route to Molecular Complexity in Space, *Liv Hornekaer*, Aarhus University, Denmark INVITED

Interstellar molecular clouds, the regions where new stars and planetary systems form, are home to surprisingly complex chemistry. In spite of the very low temperatures and pressures characterizing these clouds more, than 330 different molecules have so far been detected. Nanoscale interstellar dust grains and polycyclic aromatic hydrocarbons are expected to play a dominant role as catalysts for the low temperature reactions resulting in the formation of these molecules. Their catalytic effect is not only ascribed to a lowering of reaction barriers, but also to their role in dissipating the energy released in the reaction. In some cases, the “catalysts” are even seen to increase the reaction barriers, while still enabling the reaction to proceed by providing energy dissipation pathways. The last 20 years have seen major advancements in our understanding of interstellar reactions, specifically with regards to simple molecules, however, the degree of chemical complexity attainable via such reactions is still under exploration. Recently it was shown that the simplest amino acid, glycine, can form under interstellar conditions. In this case a non-diffusive reaction mechanism was proposed. A more detailed quantum dynamical understanding of low temperature solid state radical-radical reactions could provide the answer to the question of whether the molecular building blocks of life – amino acids, DNA bases, sugars and fatty acids – can form in interstellar space, even before the formation of stars and planets. To answer this question, we recreate interstellar conditions in the laboratory and employ the full toolbox of surface science to study heterogenous catalytic reactions on interstellar dust grain analogue surfaces. As an example scanning tunneling microscopy measurements allows us to directly image low temperature ice cluster formation, as well as low temperature reaction products with single molecule detection efficiency.

2:45pm SS-TuA-3 Kinetics and Dynamics of CO Oxidation on Rhodium Surfaces, *Dan Killelea*, Loyola University Chicago

The ability to obtain velocity distributions of molecules desorbing from surfaces with both high temporal precision and angular resolution provide newfound insight into both the kinetics and the dynamics of the CO oxidation reaction and subsurface emergence.

I will discuss our observations of CO oxidation by co-adsorbed and adsorbed oxygen on Rh(111) and how the velocity distribution shifts in comparison to the thermally-dominated desorption pathways found for surface-adsorbed oxygen. In addition, the role of systematic defects will be covered for both the oxidation reaction and surface oxidation. I will discuss these observations and their potential impacts in oxidation reactions in heterogeneously catalyzed reactions over transition metal surfaces.

¹ ASED Young Investigator Award Finalist

² ASED Rising Star

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3:00pm SS-TuA-4 **The Effects of Alkane Structure, Cluster Size, and Cluster Composition on Activity of Pt_n and Pt_nGe_m Catalysts for Cracking and Dehydrogenation, Autumn Fuchs**, Scott Anderson, University of Utah; Avital Isakov, Anastassia Alexandrova, University of California at Berkeley

The high temperature dehydrogenation, cracking, and coking chemistry of n-butane and isobutane, catalyzed by sub-nanometer Pt_n/alumina and Pt_nGe_m/alumina catalysts will be presented. The mechanisms are explored by temperature programmed desorption (TPD) experiments with size-selected clusters deposited on alumina supports, and detailed DFT calculations. The calculations probe cluster geometric and electronic structures, including the effects of both Ge and carbon addition, and examine binding and activation of the C4 alkanes and alkenes. N-Butane is observed to dehydrogenate efficiently on Pt catalysts with and without Ge. For pure Pt_n, there is some coking initially, but the coking decays over time and the dehydrogenation activity increases slightly, i.e., coking is self-limiting and does not deactivate Pt_n for n-butane dehydrogenation. With Ge present, there is essentially no coking for n-butane, even in the initial reaction. In contrast, isobutane on pure Pt_n/alumina catalysts simply cokes with hydrogen evolved, with no significant alkene or diene products. Ge addition to the Pt_n does suppress coking for isobutane, resulting in C₄H₆ product formation, but only for the Pt_n-based catalyst (Pt_nGe_m/alumina). In addition, we find that both 2- and isobutane coke badly on Pt_n/alumina, deactivating the catalysts, and that coking is suppressed by Ge addition. This work was supported by the Air Force Office of Scientific Research (AFOSR FA9550-19-1-0261).

3:15pm SS-TuA-5 **Oxygen Passivation of Au Capped Niobium, Van Do, Helena Lew-Kiedrowska, Sarah Willson, University of Chicago; Chi Wang, National Cheng Kung University (NCKU), Taiwan; Steven Sibener, University of Chicago**

Nb is the highest temperature elemental superconductor; however, its application in particle accelerators and quantum computers is limited by growth of native surface Nb oxides. Au capping layers have been shown to prevent deleterious Nb oxide growth but Au morphology, kinetics, and degree of passivation at various coverages on Nb have not been fully investigated. This work characterizes the physical deposition and oxygen contamination of sub-ML to 10 ML Au coverages on Nb(100). We analyze the physical features and chemical states of the surface using Scanning Tunneling Microscopy, X-ray and UV Photoelectron Spectroscopy, and Auger Electron Spectroscopy. Preliminary results show that a post-deposition anneal as low as 350 C causes Au island formation at Sub-ML to 1 ML coverages, substantially exposing Nb to oxidation. Thus, understanding the effects of temperature and coverage on Au formation will be critical for revealing the optimal method to passivate Nb.

4:00pm SS-TuA-8 **Achieving Effective Catalysis by Transient Heating Using Mechanocatalysis and Pulsed Joule Heating, David Sholl, Zili Wu, ORNL; Carsten Sievers, Georgia Institute of Technology; Liangbing Hu, Yale University** INVITED

Transient heating can be a powerful approach to control the selectivity of catalytic reaction networks, especially for endothermic reactions where undesirable species can be formed under steady state conditions. Mechanocatalysis and pulsed Joule heating are two approaches where surface temperature changes of 500-1000 K can be achieved on millisecond timescales. This talk will discuss how a combination of experiments and computational simulations have been used to understand the reaction conditions that are accessible with these unconventional heating methods. Examples will include the use of computational modeling to probe temperature inhomogeneities in realistic models of carbon fiber supports during pulsed Joule heating and the use of single impact experiments and simulations to quantify heat delivery and chemical reactivity during mechanochemical depolymerization.

4:30pm SS-TuA-10 **Unraveling the Desorption Dynamics of Cyclic Hydrocarbons on Fe₃O₄(001): Insights from Temperature-Programmed Desorption, Moritz Eder¹, TU Wien, Austria; Federico Loi, J. Heyrovsky Institute of Physical Chemistry, Czechia; Nail Barama, Faith Lewis, Margareta Wagner, TU Wien, Austria; Štefan Vajda, J. Heyrovsky Institute of Physical Chemistry, Czechia; Jiří Pavelec, Gareth Parkinson, TU Wien, Austria**

We investigate cyclic hydrocarbons — cyclohexane, cyclohexene, and benzene — on the magnetite Fe₃O₄(001) surface by means of temperature-programmed desorption (TPD), infrared reflection absorption spectroscopy (IRAS), and x-ray photoelectron spectroscopy (XPS). Through a detailed

analysis of the TPD profiles, we uncover distinct interaction mechanisms between these molecules and the Fe₃O₄(001) surface, shedding light on the role of molecular structure and surface chemistry. Despite the structural similarities, the adsorption energies and desorption orders and hence the interaction with the surface are different for each molecule. Furthermore, the desorption behavior differs from other surfaces previously investigated in the literature.^{1,2} The results provide a deeper understanding of the substrate-surface interactions, with implications for catalytic applications, such as hydrocarbon upgrading, and the design of oxide-supported catalysts for energy and chemical industries.

[1] Smith, R. S., & Kay, B. D. (2018). Desorption kinetics of benzene and cyclohexane from a graphene surface. *J. Phys. Chem. B*, 122(2), 587-594.

[2] Chen, L., Zhang, S., Persaud, R. R., Smith, R. S., Kay, B. D., Dixon, D., & Dohnalek, Z. (2019). Understanding the binding of aromatic hydrocarbons on rutile TiO₂(110). *J. Phys. Chem. C*, 123(27), 16766-16777.

4:45pm SS-TuA-11 **Investigating the Stability and Reactivity of Subsurface Oxygen in Ag(111) Using Lattice-Gas Models, DFT, and Monte Carlo Simulations, Carson Mize, Lonnie Crosby, Bright Daniel, Sharani Roy, University of Tennessee Knoxville**

First-row atoms, such as hydrogen, carbon, and oxygen, not only adsorb on the surface of a solid but are small enough to diffuse into the near-surface or subsurface region. The percolation of adsorbates through the surface raises many fundamental questions, such as what conditions promote subsurface adsorption? Does the same adsorbate have different chemical properties in the subsurface compared to the surface? How do subsurface adsorbates influence chemical reactions on surfaces? To address these questions, we extended the theoretical framework of lattice-gas models to describe both coverage-dependent surface and subsurface adsorption in crystalline solids. Using this framework, we developed an all-site DFT-parameterized lattice-gas model for O/Ag(111) and integrated it with Monte Carlo simulations to calculate the thermodynamic distributions of atomic oxygen on the surface and in the subsurface of Ag(111). The results show that subsurface adsorption becomes thermodynamically favorable for oxygen coverages exceeding 0.375 ML. Furthermore, we applied the simulations to construct the first ab initio phase diagram of O/Ag(111) that shows the pressure and temperature ranges within which subsurface oxygen coexists with surface oxygen on Ag(111). Our results indicate that subsurface oxygen is present under the industrial conditions used for the catalytic partial oxidation of olefins on silver nanoparticles. Finally, we computed the reaction pathway for the conversion of ethylene to ethylene oxide on Ag(111) using DFT and found significant changes to the reaction barriers with increased oxygen coverage and the presence of subsurface oxygen.

5:00pm SS-TuA-12 **Size and Proximity Dependent Electronic Metal-Support Interactions on Cu/TiO₂(110), Lindsey Penland, H. H. Hirushan, N. Dissanayake, Rachael Farber, University of Kansas**

Electronic metal-support interactions (EMSI) are often cited as an origin of enhanced selectivity and efficiency of oxide-supported metal nanoparticle catalysts. While it is understood that tuning the oxide support defect density and metal nanoparticle size impacts the EMSI, it is unclear how such structural modifications attenuate the electronic landscape of the catalyst at the atomic scale. In this work, rutile TiO₂(110) was used as a strong Lewis acid oxide support to determine the spatially resolved electronic consequences of Cu nano-particle size on EMSI. Using a combination of scanning tunneling microscopy (STM) and scanning tunneling spectroscopy (STS), the TiO₂(110) (1×1), (1×2), (1×3), and (2×2) surface reconstructions were characterized to reveal the relationship between the coordination number of Ti and the observed local density of states (LDOS). Following this characterization, sub-monolayer quantities of Cu were deposited on TiO₂(110) and annealed to either 100 °C, 300 °C, or 500 °C to promote Cu diffusion and aggregation. STS taken atop the Cu particles showed the emergence of electronic states within the bandgap of TiO₂(110). The intensity and position of these electronic states were strongly dependent on the size of the Cu particle. STS collected at the Cu/TiO₂(110) interface showed unique LDOS when compared to the LDOS of the Cu particle and the TiO₂(110), suggesting an attenuation of the electronic structure at the Cu/TiO₂(110) interface. This attenuation of the LDOS extended beyond the immediate Cu/TiO₂(110) interface, with the distance of attenuation related to the size of the Cu particle. These results highlight the real-space, heterogeneous electronic landscape of oxide-supported metal nanoparticle systems which may have significant implications for overall reactivity and selectivity.

¹ JVST Highlighted Talk

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5:15pm **SS-TuA-13** Steering Pt Cluster Dimensionality via Morphology and Surface Oxidation State of CeO₂(111) Thin Films, **Johanna Reich, Mina Soltanmohammadi**, Technical University of Munich, Germany; **Vedran Vonk**, Deutsches Elektronen-Synchrotron (DESY), Germany; **Sebastian Kaiser, Ueli Heiz**, Technical University of Munich, Germany; **Andreas Stierle**, Deutsches Elektronen-Synchrotron (DESY), University of Hamburg, Germany; **Friedrich Esch, Barbara A. J. Lechner**, Technical University of Munich, Germany

Ceria has recently returned into the focus of research thanks to the possibility to reversibly form and redisperse supported, catalytically active Pt clusters by controlling its morphology and redox state. In the present work, we systematically synthesize CeO₂(111) thin films to tune these parameters independently and investigate their influence on size-selected Pt₂₀ cluster dimensionality and sintering behavior. First, we present recipes for atomically flat islands and closed CeO₂(111) films with a thickness up to 18 monolayers (ML), grown on Rh(111), and characterize them by means of scanning tunneling microscopy (STM), X-ray photoelectron spectroscopy (XPS), X-ray diffraction (XRD) and low-energy electron diffraction (LEED). Remarkably, XRD and LEED show an epitaxially grown, crystalline, and relaxed film with cube-on-cube alignment. Bulk or exclusive surface reduction is achieved by ultra-high vacuum (UHV) annealing or room temperature (RT) CH₃OH dosing and annealing cycles, respectively. The methanol procedure forms oxygen vacancies only in the surface, without reducing the deeper layers of the film or introducing roughening. When deposited on a fully oxidized (Figure 1 (a,d)) versus a surface-reduced (Figure 1 (b,e)) support, Pt₂₀ clusters show a strikingly different temperature-dependent dimensionality and sintering behavior. From STM images, we extract detailed cluster height distributions and coverages (Figure 1 (c,f)) and find that Ostwald ripening already sets in around 600 K on both, oxidized and reduced supports, without any indication for cluster diffusion and coalescence. Notably, at these temperatures, we obtain flat 2D clusters on the reduced support and 3D clusters on the oxidized support, where the atom detachment during sintering leads to the intermediate formation of Pt²⁺ species, in line with the redispersed single atoms at step edges observed in the literature [1-3].

References

- [1] M. Farnesi Camellone, F. Dvořák, M. Vorokhta, A. Tovt, I. Khalakhan, V. Johánek, T. Skála, I. Matolínová, S. Fabris, J. Mysliveček, Adatom and Nanoparticle Dynamics on Single-Atom Catalyst Substrates, *ACS Catal.* 12 (2022) 4859–4871.
- [2] F. Dvořák, M.F. Camellone, A. Tovt, N.D. Tran, F.R. Negreiros, M. Vorokhta, T. Skála, I. Matolínová, J. Mysliveček, V. Matolín, S. Fabris, Creating single-atom Pt-ceria catalysts by surface step decoration, *Nat. Commun.* 7 (2016).
- [3] F. Maurer, J. Jelic, J. Wang, A. Gänzler, P. Dolcet, C. Wöll, Y. Wang, F. Studt, M. Casapu, J.D. Grunwaldt, Tracking the formation, fate and consequence for catalytic activity of Pt single sites on CeO₂, *Nat. Catal.* 3 (2020) 824–833.

Thin Films

Room 206 B W - Session TF-TuA

VSHOP II - Infiltration Synthesis of Hybrid Materials

Moderators: **Jolien Dendooven**, Ghent University, Belgium, **Mark Losego**, Georgia Institute of Technology

2:15pm **TF-TuA-1 Ruthenium Tetroxide as a Versatile and Selective Precursor for Sequential Infiltration Synthesis of Ru and RuO₂**, **Nithin Poonkottil, Matthias Minjaeuw, Brent Van Neste**, Ghent University, Belgium; **Eduardo Solano**, ALBA Synchrotron, Spain; **Arbresha Muriqi**, Tyndall National Institute, University College Cork, Ireland; **Matthias Filez**, Ghent University, Belgium; **Michael Nolan**, Tyndall National Institute, University College Cork, Ireland; **Christophe Detavernier, Jolien Dendooven**, Ghent University, Belgium

INVITED

This presentation explores the use of ruthenium tetroxide (RuO₄) as a powerful and versatile precursor for atomic layer deposition (ALD) and sequential infiltration synthesis (SIS) of Ru-containing materials. Due to its strong oxidizing character, RuO₄ exhibits unique surface reactivity compared to conventional metalorganic precursors. It readily reacts with oxidizable surfaces and polymers, while showing negligible interaction with already oxidized materials [1]. This inherent chemical selectivity is particularly advantageous for nanopatterning applications, such as area-selective ALD and selective vapor-phase infiltration.

ALD or SIS of metallic Ru is achieved by alternating RuO₄ and H₂ at low temperatures, optimally around 100°C, enabling efficient reduction reaction without decomposition of the RuO₄ precursor, which occurs above 125°C. Replacing H₂ with a milder reducing agent like methanol results in the deposition or infiltration of RuO₂ instead of metallic Ru [2]. Furthermore, alternating RuO₄ with metalorganic precursors enables growth of ternary ruthenates [3]. For example, a RuO₄-trimethylaluminum (TMA) process yields an aluminum ruthenate with a 1:1 Al:Ru ratio.

RuO₄ has long been used in liquid-phase staining of (block co)polymers to enhance contrast in electron microscopy. We demonstrate that its selective reactivity is preserved in the vapor phase: RuO₄ reacts with polystyrene (PS) but not with poly(methyl methacrylate) (PMMA) [4]. This selectivity enables targeted SIS within PS-b-PMMA templates. Alternating RuO₄ and H₂ exposures in such templates, followed by plasma removal of the polymer, yields well-defined Ru nanostructures. Similarly, RuO₂ nanopatterns are obtained using RuO₄/methanol chemistry in the same template.

Mechanistic insights were obtained using *in situ* FTIR and DFT calculations, revealing that RuO₄ preferentially oxidizes the aromatic CH and C=C bonds in PS, while PMMA remains unaffected. Grazing-incidence wide-angle X-ray scattering (GIWAXS) confirmed the formation of crystalline Ru in the infiltrated PS domains. Microscopy and synchrotron-based X-ray analysis further corroborated the morphological fidelity of the Ru and RuO₂ nanostructures to the original PS template, as well as the evolution of contrast with increasing SIS cycles.

1. M. M. Minjaeu et al. *Chem. Mater.* 2019, 31, 1491–1499.
2. N. Poonkottil et al. *Chem. Mater.* 2022, 34, 8946–8958.
3. M. M. Minjaeu et al. *Dalton Trans.*, 2022, 51, 10721–10727.
4. N. Poonkottil et al. *Chem. Mater.* 2022, 34, 10347–10360.

2:45pm **TF-TuA-3 Extrinsic Cation Incorporation in the Magic Size Indium Sulfide Cluster via Vapor Phase Infiltration**, **Kihoon Kim, Taylor Harville, Donghyeon Kang, Nuwanthaka Jayaweera, Karen Mulfort, Jeffrey Elam, Cong Liu, Alex Martinson**, Argonne National Laboratory

The intentional introduction of impurities into a material is essential for controlling the properties of semiconductor materials from the bulk to the nanoscale. Here, we report the extrinsic cation incorporation into molecular-level semiconductor clusters via vapor phase infiltration synthesis. Exposure of magic-size In₆S₆(CH₃)₆ clusters to a conventional volatile organometallic precursor, i.e., dimethyl cadmium, induces the substitutional incorporation of Cd, modifying their optical properties. The extent of cation incorporation can be controlled by adjusting the exposure cycle, reaction temperature, and precursor dosage. Unlike conventional cation incorporation processes, this phenomenon is limited to specific organometallic precursors. The underlying reaction mechanisms are further investigated using density functional theory.

3:00pm **TF-TuA-4 Vapor Phase Infiltration of VOCl₃ into P3HT: The Interplay of Doping, Dedoping, and Hybridization**, **Li Zhang¹², Shawn Gregory, Mark Losego**, Georgia Institute of Technology

Vapor phase infiltration (VPI) of metal halide precursors has been shown effective in the doping of conjugated polymers. Previous publications have found that the conductivity follows a predictable pattern with metal halide exposure time: an initial increase followed by an eventual decrease. The conductivity initially increases due to doping that increases the number of charge carriers. The eventual decrease has been attributed to an increase in the number of scattering sites created by the infiltrated metal oxide clusters. Herein, we explore VPI of the conjugated polymer poly(3-hexylthiophene-2,5-diyl) (P3HT) with VOCl₃ + H₂O to modify the conductivity and optical absorbances. Conductivity initially increases with VOCl₃ exposure time, peaks around 20 mins to 1 h, and eventually begins to decrease. UV-Vis and XPS measurements at varying hold times confirm that the increased conductivity is due to an increase in the number of charge carriers, as expected. However, at extended exposure times of > 1 h, UV-Vis measurements show an increase in the pi-pi* absorbance and decreasing polaronic absorbance, indicating a decrease in the concentration of charge carriers, not just an increase in the concentration of scattering sites. Furthermore, EDX measurements show a plateauing of the vanadium concentration in the films at ~1 h, meaning no further scattering sites should be created. *In situ* conductivity and *in situ* UV-Vis spectroscopy measurements during VPI confirm decreasing conductivity and charge carrier concentrations during the VOCl₃ exposure step. From these observations, we postulate that as exposure time increases, VOCl₃ can no

¹ AVS Dorothy M. and Earl S. Hoffman Scholarship Recipient

² TFD James Harper Award Finalist

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longer diffuse into the bulk of the film, causing the thermal de-doping rate to exceed the VPI doping rate. This hypothesis is depicted in the attached Figure 1, where between t_2 and t_3 the effects of thermal dedoping take place starting at the bottom of the film. XPS of the films shows relatively constant doping concentration on the surface regardless of exposure time, but through careful experimentation, we have been able to use XPS to observe a decrease in dopant concentration at the film/substrate interface at times > 1 h, consistent with this proposed bulk de-doping mechanism. Additionally, tests including a vacuum hold step inserted after a 1 h VOCl_3 exposure show decreasing conductivity with increasing vacuum hold times, showing that thermal dedoping can occur under vacuum and at the operating temperatures used for this specific process. This work shows the importance of thermal de-doping in designing conductivity of VPI doped conjugated polymer films.

3:15pm TF-TuA-5 Approaches to Elucidate the Chemical Mechanisms of Atomic Layer Infiltration Processes and Final Hybrid Structures, *Mark Losego*, Georgia Tech

Further advancing the fundamental understanding of atomic layer infiltration (ALI) processes (also known as vapor phase infiltration, VPI, and sequential infiltration synthesis, SIS) is essential to advancing process development, chemical design, material properties, and application spaces. Fundamentals include both the thermodynamics and kinetics of the process as well as the chemical mechanisms of reaction and inorganic cluster development. Over the past few years, our group has focused on elucidating the latter for several systems, and this talk will discuss what we have learned about approaches to take to understand chemical mechanisms of ALI processes and the physicochemical structure of ALI hybrid materials. An interesting case is the dramatic difference in reaction mechanism between trimethylaluminum and titanium tetrachloride with ester groups in, for example, PMMA. While the TMA reacts directly with and consumes the carbonyl to form a M-O bond, TiCl_4 attacks the ether oxygen to form its M-O bond, cleaving the alkyl group and leaving the carbonyl unreacted. These differences elucidate approaches to do purely additive or additive and subtractive chemistry during ALI, opening new application spaces. Moreover, it appears that the bound $-\text{TiCl}_3$ moiety remains reactive toward the polymer, forming multiple cross-links which reduces the residual hydroxide concentration (making it less hydrophilic) and increases the connectivity of the polymer. To understand the structural development of the inorganic clusters requires clarifying the oxidation state, coordination number, and chemical state, (e.g., fraction of oxide versus hydroxide). This approach usually requires multiple spectroscopies, whose selection may be limited by the spectroscopic activity or absorption edge of the metal center. A set of deductive processes – applying the constraints of charge state and coordination number – can then be used to develop a model structure and test against additional spectroscopic evidence or to compare with simulated spectra. Often, spectroscopies that provide next-nearest neighbor and beyond information can help to further elucidate and verify these proposed structures.

4:00pm TF-TuA-8 Functionalization of Polymer Membranes for Water Treatment using Chemical Vapors, *Jeffrey Elam, Seth Darling, Anil Mane, Rajesh Pathak, Bratin Sengupta, Rahul Shevate, Vepa Rozyyev*, Argonne National Laboratory INVITED

Polymer membranes are used extensively in water purification to filter and remove particulate and molecular contaminants. Ideally, these membranes should exhibit high permeance, selectivity, and fouling resistance, but these attributes are rarely achieved simultaneously. One approach to improve membrane performance is to modify the polymer using reactive chemical vapors to impart the desired physicochemical properties. In this presentation, I will describe recent work at Argonne using atomic layer deposition (ALD), sequential infiltration synthesis (SIS), and vapor-phase grafting to modify polymer membranes used for ultra- and nano-filtration in water treatment. These techniques rely on self-limiting chemical reactions between gaseous precursors and a solid surface to grow material in an atomically controlled fashion. We have used ALD to produce ultrathin and conformal inorganic layers allowing the membrane pore size and pore wall composition to be precisely tuned, SIS for the bulk modification of polymers by creating an organic-inorganic hybrid material, and vapor-phase grafting of small molecules to achieve additional control over the membrane surface properties. We have also developed methods to accelerate the nucleation and growth of metal oxide layers on polymers to create superhydrophilic, anti-fouling surfaces using only a few ALD cycles. Our studies employ a suite of in-situ and in-operando measurements to elucidate the surface chemistry for these processes and extensive ex-situ

characterization and testing to understand the effects of chemical vapor treatment on polymers and how they impact membrane performance.

4:30pm TF-TuA-10 Resolving Surface Effects and Bulk Properties for VPI-Modified Polymers, *Seancarlos Gonzalez, Yuri Choe, Joelle Scott, Agni Biswal, Cecilia Osburn, David Bergsman*, University of Washington

When applying vapor phase synthetic techniques to a porous substrate like a polymer, sometimes there is not a clear delineation between vapor phase infiltration (VPI) and atomic layer deposition (ALD). In ALD, while the objective is often to deposit onto a surface, some diffusion into the subsurface layer is expected. In contrast, VPI can also cause the formation of a surface layer in addition to the components infiltrated throughout the bulk substrate. In some cases, such as for materials for membrane separations, this distinction can have a pronounced impact on device performance. However, the potential presence of a surface layer can complicate material characterization by making it unclear which properties are attributable to the bulk versus the surface.

In this work, we highlight the challenges associated with characterizing the differences between surface and bulk growth in VPI, using an example system based on the infiltration of inorganic and organic reactants into acrylonitrile butadiene styrene (ABS) substrates. First, ABS is infiltrated with diethyl zinc (DEZ) and water to form zinc oxide. It is then infiltrated with 2-methylimidazole (2-HmIM), which can react with zinc oxide to form a metal-organic framework (MOF) known as ZIF-8. Select samples were then exposed to water, which can etch away surface ZIF-8, and then compared against non-etched samples. Successful reactant infiltration was confirmed using secondary ion mass spectrometry (SIMS) to measure reactant infiltration depth, along with thermogravimetric analysis (TGA) to measure reactant loading. Substrates were then examined using x-ray diffraction (XRD) to determine ZIF-8 crystallinity and scanning electron microscopy (SEM) to measure surface morphology, with samples compared with and without surface etching. Results suggest that confinement within the polymer matrix may serve to restrict the crystallization of MOF particles, as opposed to surface deposition where crystallization can proceed unhindered. This distinction can be challenging to characterize due to the limitations of many characterization techniques, and suggests that careful consideration must be given to surface phenomenon, even when using bulk modification techniques like VPI.

4:45pm TF-TuA-11 Fundamental Studies of the Sorption, Diffusion, and Reaction Processes of Direct Vapor Phase Infiltration of Diethylzinc into PMMA for Hybrid Material Synthesis, *Typher Yom, Mark Losego*, Georgia Institute of Technology, USA

Vapor phase infiltration (VPI) is a process that is capable of creating hybrid organic-inorganic materials by allowing a precursor to diffuse a vapor phase inorganic material into a polymer matrix. Doing so can evenly distribute the material throughout the matrix due to the self-limiting nature of the precursor's reaction with functional groups on the polymer. Infiltration of ZnO into polymers is of interest because of ZnO 's electrical semi-conductivity, UV absorption, piezoelectricity, and photoluminescence. One hybrid material of interest is zinc oxide mixed with polymethyl methacrylate (PMMA), which is created by the infiltration of diethylzinc (DEZ) into PMMA. In most prior studies, the seeding of ZnO infiltration by first infiltrating with aluminum oxide (via trimethylaluminum) was used because the sorption of DEZ appeared to be low. Here, we use quartz crystal microbalance (QCM) to directly study the sorption and diffusion processes of DEZ in PMMA without a seed cycle. Based on these measurements, we find that DEZ does infiltrate into PMMA at elevated temperatures ($> 100^\circ\text{C}$). At 100°C and below, the added mass from 36 hours of DEZ infiltration is about 25% or less than that of the polymer. On the other hand, at 110°C and higher, the added mass from 36 hours of DEZ infiltration is at or above about 300% of the mass of the polymer. Additionally, the DEZ does stay inside the PMMA even with long purge times, which would normally remove weakly bound species. This talk will present the sorption rates and diffusion rates for DEZ into PMMA over a range of temperatures from 70°C to 130°C . This information will be used to further elucidate the mechanisms of this infiltration process and to what extent ZnO -polymer hybrids can be directly synthesized via vapor phase infiltration.

5:00pm TF-TuA-12 Impact of Vapor Phase Infiltration on the Mechanical and Chemical Properties of Polyethersulfone Membranes, *Yuri Choe, Alyssa Hicks*, University of Washington; *David Bergsman*, University of Washington

Vapor phase infiltration (VPI), also known as sequential infiltration synthesis (SIS), is an emerging technique for embedding inorganic materials into polymers using vapor-phase reactants, thereby tuning polymer properties.

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This technique has the potential to be useful in applications like membrane separations, where improved polymer properties, such as resistance to organic solvents, thermal stability, and selectivity, can substantially reduce processing costs. However, the infiltration of inorganic fillers can reduce polymer ductility, which can inhibit their use. Therefore, understanding the impact of VPI on polymer mechanical and chemical stability is critical for the rational design of robust membranes.

In this work, polyethersulfone membranes—often used as support layer—were treated with trimethylaluminum and water to introduce aluminum oxide via VPI. Exposure duration and process cycles were then modulated to control infiltration depth and inorganic loading, respectively, before measuring mechanical properties through burst pressure testing and dynamic mechanical analysis. Results showed that membranes were less resistant to pressure and more brittle when shallower infiltration depths and higher inorganic loadings were used. These trends were found to agree with theoretical models, such as the rule of mixtures and Gibson-Ashby formulations, which predict that the distribution of alumina would mitigate the loss of ductility. Additionally, the chemical stability of VPI-treated membranes in organic solvents and their separation performance were compared against the alumina infiltration depth, suggesting tradeoffs between chemical and mechanical stability in VPI-modified polymer membranes.

extraction as a problem domain where vacuum expertise is essential. The goal is to highlight the scale of the opportunity, the centrality of vacuum in making it possible, and the need for collaboration between the space resource and vacuum science communities to advance solutions.

Vacuum Technology

Room 205 ABCD W - Session VT-TuA

Novel Vacuum Methods and Application

Moderators: Freek Molkenboer, TNO Science and Industry, the Netherlands, Alan Van Drie, TAE Technologies

2:15pm VT-TuA-1 Advanced UHV Sealing Solutions with HELICOFLEX® TEXEAL®, Ryan Widejka, Technetics Group - An Enpro Company INVITED
As a leader in high-performance sealing for demanding environments, Technetics Group is consistently pushing the boundaries of Ultra High Vacuum (UHV) sealing technology. This presentation focuses on the development and application of HELICOFLEX® TEXEAL®, a patented texturized technology integrated into metallic seals, designed to lower the required seating load and enhance UHV performance. By applying TEXEAL® technology to its HELICOFLEX® metal seals, Technetics has achieved a significant reduction in clamping load while maintaining superior sealing integrity, even under extreme conditions. The HELICOFLEX® TEXEAL® solution minimizes the contact area without reducing the seal track width, promoting optimal conformity to flange roughness. This approach eliminates the need for softer sealing materials by selecting materials with better thermomechanical properties. Comparative test data indicate that the texturized seal exhibits lower linear loads (lbs/inch) and improved sealing rates compared to non-texturized and traditional seals. Additional benefits include improved reusability, lower sensitivity to surface defects, and minimal requirement for flange redesign, resulting in increased equipment uptime and simplified assembly processes. These innovations render the HELICOFLEX® TEXEAL® ideal for applications in semiconductor manufacturing, accelerator and fusion research, and other areas that demand ultra-high vacuum stability and reliability. This discussion will detail design principles, test methodologies, and performance metrics associated with HELICOFLEX® TEXEAL®, while outlining manufacturing capabilities and real-world applications. The session aims to provide UHV professionals with novel insights into reducing hardware stresses and operational costs, thereby advancing the state-of-the-art in UHV sealing technologies—a critical component in today's increasingly demanding vacuum systems.

3:00pm VT-TuA-4 Helium-3 and the Lunar Vacuum: Framing a \$17 Trillion Opportunity, Chris Salvino, Lunar Helium-3 Mining, LLC

Helium-3, implanted into lunar regolith by the solar wind, represents a resource with transformative potential: a \$17 trillion annual market spanning future nuclear fusion and quantum computing applications. Unlike terrestrial mining, any attempt to recover helium-3 and other volatiles must operate entirely within the hard vacuum of the lunar surface. There is no atmosphere for heat transfer, no fluid dynamics to aid separation, and abrasive dust complicates all surface interactions. These realities mean that lunar resource recovery is not simply a mining challenge, but fundamentally a vacuum science and engineering problem. Approaches to heating, capturing, and storing gases must be compatible with an environment where vacuum is not a laboratory condition but the baseline operating medium. This presentation will frame helium-3

Wednesday Morning, September 24, 2025

Atomic Scale Processing Mini-Symposium

Room 206 A W - Session AP+PS+TF-WeM

Thermal and Plasma-Enhanced Atomic Layer Deposition

Moderator: Austin Minnich, California Institute of Technology

8:00am AP+PS+TF-WeM-1 High-Temperature Thermal ALD of SiO₂ Using Chlorosilane and Aminosilane Precursors: A Comparative Study, *Okhyeon Kim, Tanzia Chowdhury, Changgyu Kim, Hye-Lee Kim, Sejong University, Republic of Korea; Jae-Seok An, Jung Woo Park, Hansol Chemical Co., Ltd., Republic of Korea; Won-Jun Lee, Sejong University, Republic of Korea*

As the number of layers in three-dimensional vertical NAND memory devices continues to increase, the conformal deposition of high-quality SiO₂ films in high-aspect-ratio (HAR) structures at high temperatures becomes increasingly critical. Atomic layer deposition (ALD) is the ideal technology for this application, offering atomic-level thickness control and excellent conformality. However, most existing studies on SiO₂ ALD have focused on low-temperature plasma-enhanced ALD processes, which are inadequate for producing high-quality films in HAR structures. In contrast, high-temperature thermal ALD of SiO₂ films remains underexplored. In this work, we investigated high-temperature (>600 °C) thermal ALD of SiO₂ using chlorosilane and aminosilane as Si precursors and compared the performance of silicon precursors. Density functional theory (DFT) calculations were first performed to evaluate the precursors based on their thermal stability. Next, the maximum ALD temperature was determined experimentally based on self-limiting behavior and confirmed by step coverage analysis in HAR patterns. Film composition and impurity levels were analyzed by X-ray photoelectron spectroscopy and dynamic secondary ion mass spectroscopy. Stoichiometric SiO₂ films were deposited using both chlorosilane and aminosilane precursors, but pure ALD processes were possible at higher temperatures with chlorosilane precursors due to their better thermal stability. Chlorosilane precursors also resulted in lower impurity levels in the film due to their simpler molecular structures, which is consistent with the better electrical properties and wet etch resistance observed. This study combines theoretical and experimental results to provide a basis for advancing high-temperature thermal ALD processes of SiO₂ and related materials.

8:15am AP+PS+TF-WeM-2 Catalyzed Molecular Layer Deposition of Methylene-Bridged Silicon Oxycarbide and the Effect of Annealing on Molecular Structure and Electrical Properties, *Man Hou Vong, Seoyeon Kim, Michael Dickey, Gregory Parsons, North Carolina State University*

Silicon oxycarbide (SiOC-H) is a low-k dielectric material capable of minimizing parasitic capacitance between interconnects, thereby lowering the signal delay. As feature nodes in integrated circuits continue to shrink, deposition processes that offer precise control over film thickness and conformity are increasingly critical. Molecular layer deposition (MLD), a vapor deposition technique that deposits molecular layers via self-limiting surface reactions driven by sequential reactant exposure, offers a promising route to meet these demands. Previous studies have demonstrated the feasibility of MLD for methylene-bridged (Si-CH₂-Si) SiOC-H using bis(trichlorosilyl)methane (BTCSM) as the precursor and water as the oxidant at moderate temperatures (< 100°C). However, the reported growth rate was limited despite the high reactant exposure. We hypothesize that the limited growth arises from the inefficient direct reaction between the Si-Cl on BTCSM and the Si-OH on the substrate surface. Herein, we introduce a catalyst to overcome the growth limitation in SiOC-H MLD using BTCSM and water. The results show that incorporating catalyst in MLD of SiOC-H at 50°C increases the growth rate by more than ten times under identical reactant exposure. Furthermore, upon annealing at temperatures from 250°C to 550°C, the Si-CH₂-Si bridges undergo a transformation into terminal methyl groups (Si-CH₃) via reaction with adjacent Si-OH groups. This transformation increases steric hinderance within the film compared to methylene bridges, reducing the film density and ultimately lowering the permittivity of the films. Overall, the findings in this work provide insights into the role of the catalyst in SiOC-H MLD and highlight its potential for enhancing deposition efficiency for scalable manufacturing in advanced microelectronics fabrication.

8:30am AP+PS+TF-WeM-3 The Effect of Precursor Choice and Process Temperature on the Properties of ALD Films, *Theodosia Gougousi, Nimarta Chowdhary, UMBC*

Precursor choice and process temperature play a critical role in determining the properties of thin films deposited by Atomic Layer Deposition (ALD). In this study, we examine the impact of deposition temperature on the properties of ALD metal oxide films grown using amide-based precursors:

tetrakis dimethyl amino titanium (TDMAT) and tetrakis dimethyl amino hafnium (TDMAHf) with water as the oxidizer.

We observe distinct differences between the two precursors. For the Ti process, we find a significant influence of temperature on phase formation and nitrogen incorporation into the films. Films deposited at 100°C crystallize in the anatase phase after inert annealing, while those deposited between 150–300°C transition to the rutile phase. At 350°C, films exhibit mixed phases that vary with thickness. Additionally, films deposited at temperatures above 200°C incorporate oxynitride bonding, significantly affecting both their linear and nonlinear optical properties and electrical conductivity. These variations are most pronounced between 200 and 275°C, a temperature range commonly considered within the "ALD window" for this process.

In contrast, for the Hf process, we do not observe any nitrogen incorporation in the films even at 400°C and the optical and electrical properties of the films are consistent across deposition temperatures. Our findings reveal previously unreported reaction pathways that significantly influence the optical and insulating properties of TiO₂ ALD films. Furthermore, we highlight significant differences in the behavior of precursors from the same family emphasizing that extrapolating properties from one materials system to another can be misleading.

This study provides significant insights into the temperature-dependent behavior of ALD-grown TiO₂ and HfO₂ films, highlighting previously unreported reaction pathways. These findings offer valuable guidance for optimizing film properties in optoelectronic applications and underscore the importance of precise precursor selection in ALD processes.

8:45am AP+PS+TF-WeM-4 Microwave Enhanced Atomic Layer Deposition (MW-ALD) of HfO₂, *Jessica Haglund, John Conley Jr., Oregon State University*

Though beneficial for many applications, the low temperatures typical of ALD can result in residual impurities from unreacted precursors. This can lead to degraded electrical, physical, and optical properties. To improve film quality, post deposition annealing (PDA) can be used. However, the high temperatures necessary for PDAs can exceed thermal budgets, especially in back end of line processing. It has been demonstrated that *post-deposition* microwave annealing can improve film quality and result in lower process temperature.¹ An alternate way to improve film quality is energy enhanced ALD (EE-ALD), in which energy is added during the ALD cycles. Previously, *in-situ* rapid thermal anneal, plasma, and UV treatments have been added to ALD cycles to drive impurities from films during deposition.²⁻⁶ We have recently introduced *in-situ* microwave enhanced ALD (MW-ALD) using Al₂O₃.⁸ Here we discuss low temperature MW-ALD of HfO₂.

A custom MKS microwave generator and helical antenna were integrated into a Picosun R200. HfO₂ was deposited at 150 °C using 100 TEMA-Hf/N₂/H₂O/N₂ ALD cycles of 1/120/0.2/120 sec. A 30 s 400 W microwave (MW) pulse (without plasma generation) was used during either the TEMA-Hf or the H₂O purge. Film thickness and refractive index were analyzed using a mapping Film Sense FS-1 ellipsometer. MW pulses during the H₂O purge had minimal impact on film thickness and refractive index. However, the same MW pulse during the TEMA-Hf purge resulted in a ~50% increase in thickness and an increase in refractive index. This is consistent with our work on MW-ALD of Al₂O₃ which found an increase in film quality when the pulse was applied during the TMA pulse as compared to the water pulse.⁸ Additional electrical data will be presented as well as results for depositions at 250 °C.

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9:00am AP+PS+TF-WeM-5 In Situ Studies of Ald Hf_{0.5}Zr_{0.5}O₂ by Spectroscopic Ellipsometry and Reflection Absorption Infrared Spectroscopy, *Stijn van der Heijden, Alex Neefs, Erwin Kessels, Bart Macco, Eindhoven University of Technology, Netherlands*

Ferroelectric Hf_{0.5}Zr_{0.5}O₂ (HZO) is widely recognized as a leading material for next-generation non-volatile memory technologies, offering excellent

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scalability and seamless integration with CMOS processing. We have developed an atomic layer deposition (ALD) process for HZO using metalorganic precursors—HfCp(NMe₂)₃ and ZrCp(NMe₂)₃—in combination with ozone as the oxygen source. This process enables controlled deposition with precise Hf:Zr stoichiometry and uniform film growth under optimized conditions.

In situ spectroscopic ellipsometry (SE) on an Oxford Instruments FlexAL was used extensively during process development to monitor film growth in real time and to extract growth-per-cycle data. Additionally, full TiN/HZO/TiN capacitor stacks were fabricated in a single ALD sequence within the same reactor, allowing us to track film evolution throughout the stack formation. This provided detailed insight into the nucleation behavior and the formation of interfacial layers.

To gain a deeper understanding of the surface chemistry, we employed *in situ* reflection absorption infrared spectroscopy (RAIRS) using a home-built reactor. The RAIRS analysis revealed that formate groups, generated during the ozone pulse, act as active surface sites for precursor adsorption in both the HfCp(NMe₂)₃ and ZrCp(NMe₂)₃ processes.

Finally, we correlate the findings from SE and RAIRS with the electrical performance of the TiN/HZO/TiN capacitors, offering an integrated view of how surface chemistry and film nucleation influence ferroelectric behavior.

9:15am AP+PS+TF-WeM-6 Thermal Stability of HfO₂ by Incorporating Al₂O₃ in a MIM Capacitor by 200 mm Batch-ALD, Partha Mukhopadhyay, Tokyo Electron America; Ivan Fletcher, Zuriel Caribe, Anton deVilliers, Jim Fulford, Tokyo Electron America, USA

This work investigates the thermal stability of HfO₂-Al₂O₃ laminated high-k dielectrics deposited by the high-volume batch atomic layer deposition (ALD) method. At higher crystallization temperatures HfO₂ converts from amorphous to polycrystalline and induces nonuniformity in film thickness. The incorporation of Al₂O₃ into the HfO₂ film forms an HfAlO alloy which presents excellent thermal stability compared to pure HfO₂ when annealed at 650°C. Cross-sectional TEM, SIMS and XPS profiles demonstrate the interfacial reaction of these ultra-thin layers where the core-level energy states, Hf4f and Al2p peaks showed a shift to higher binding energy from those of pure HfO₂ upon Al₂O₃ incorporation (Fig. S2). It is mainly because the Al covalence changes the bonding characteristics and HfO₂ becomes more ionic, therefore, the dissociation of the alloyed film is effectively suppressed compared to a pure HfO₂ film, indicating an enhanced thermal stability of HfAlO. The fabricated MIM capacitor of low Al-content Hf_{0.69}Al_{0.31}O alloy exhibits a higher capacitance density (C_pD) of 12.46 fF/μm², ~29% better than HfO₂ and dielectric constant of κ >22 than HfO₂. The present research indicates a small amount of Al (0.31) incorporation in HfO₂ extends its quantization temperature due to stabilizing its crystal phase by reducing oxygen vacancies and traps. It remarkably improved electrical characteristics under thermal stress compared to broken-down HfO₂ capacitors under annealing (Fig. S3). While a higher Al content Hf_{0.44}Al_{0.56}O alloy shows excellent thermal stability while possessing 68% higher κ than an Al₂O₃ capacitor. It also demonstrated the highest breakdown voltage (E_{BV}) of 8 MV/cm and low leakage among the samples. After annealing the degradation of E_{BV} of the HfO₂ capacitor is nearly 94% while the HfAl_{0.31}O capacitor faces only 19% (Fig S4). These thin multilayer alloys show excellent relative capacitance variation over the voltage with high C_pD, κ -value, low leakage of 10 nA/cm²@3MV/cm, suitable for higher thermal budget BEOL, and interposer process integration for various high bandwidth RF and low-cost memory applications with smaller chip area.

9:30am AP+PS+TF-WeM-7 Highly Crystalline ZrO₂ Films under 2 nm by Atomic Layer Modulation, Wonjoong Kim, Incheon National University, Republic of Korea; Ngoc Le Trinh, Incheon National University, Viet Nam; Bonwook Gu, incheon National University, Republic of Korea; Byungha Kwak, Ajou University, Republic of Korea; Hyunmi Kim, Hyeongkeun Kim, Korea Electronics Technology Institute, Republic of Korea; Youngho Kang, incheon National University, Republic of Korea; Il kwon Oh, ajou University, Republic of Korea; Han-Bo-Ram Lee, Incheon National University, Republic of Korea

As the dimensions of silicon-based devices continue to shrink, achieving both high capacitance and low leakage current becomes increasingly challenging. In particular, the corresponding reduction in thin film thickness makes it difficult to preserve critical physical properties, including crystallinity, thermal stability, and electrical performance. In this work, we investigated yttrium-doped zirconium oxide (YZO) thin films fabricated using atomic layer modulation (ALM), a technique based on atomic layer deposition (ALD). In the ALM process, the surface is sequentially exposed to two precursors with an intervening purging step between each exposure,

followed by a reaction with a counter-reactant, resulting in the growth of the YZO film within a single atomic layer. The ratio of Y to Zr in the ALM film is determined by the steric hindrance and chemical reactivity of the precursors with the surface. To design and interpret the experimental process, two theoretical approaches—density functional theory (DFT) and Monte Carlo (MC) simulations—were employed to examine the precursor interactions and their impact on film composition. In ALM films, Y atoms are located closer to Zr atoms, leading to the formation of Y–O–Zr bonds in both the lateral and vertical directions within several atomic layers. Consequently, the ALM film requires a lower energy barrier for diffusion to form the YZO crystalline phase, which enhances film density and improves crystallinity. As a result, YZO films deposited via the ALM process exhibit approximately 250 times lower leakage current density compared to the conventional YZO films fabricated using the ALD under a thickness of 2 nm. This key finding highlights that YZO films prepared by ALM achieve both an increased dielectric constant and reduced leakage current density at low thicknesses, demonstrating their potential as promising materials for future silicon device applications.

9:45am AP+PS+TF-WeM-8 Influence of Molecular Structure on Ruthenium Deposition: An *in Situ* Study Using Simultaneous Spectroscopic Ellipsometry and Quadrupole Mass Spectrometry, Terrick McNealy-James, University of Central Florida; Xin Kang, University of Florida, Gainesville; Luis Tomar, University of Central Florida; Johnathon Johnson, University of Florida, Gainesville; Novia Berriel, Taylor Currie, Titel Jurca, University of Central Florida; Lisa McElwee-White, University of Florida, Gainesville; Parag Banerjee, University of Central Florida

Ruthenium (Ru) with its low bulk resistivity and high work function has emerged as a promising metal for future interconnect technology. Numerous Ru complexes with different ligands have been studied to refine chemical vapor deposition (CVD) and atomic layer deposition (ALD) processes and improve film structure, property and performance. These include molecules such as, bis(cyclopentadienyl)ruthenium [RuCp₂]₃, tris(2,2,6,6-tetramethyl-3,5-heptanedionato)-ruthenium [Ru(thd)₃] and η^4 -2,3-dimethylbutadiene ruthenium tricarbonyl [Ru(DMBD)(CO)₃].¹⁻³

Here we investigate the ALD process characteristics of Ru thin films from (η^4 -diene)Ru(CO)₃ complexes and resulting film properties. Three molecules are chosen i) η^4 -isoprene ruthenium tricarbonyl, ii) (η^4 -1,3-butadiene)ruthenium tricarbonyl and iii) (η^4 -1,3-cyclohexadiene)ruthenium tricarbonyl; with the rationale of studying the effect of changes to the ligand motif on the film growth characteristics and resulting properties. Furthermore, by employing simultaneous *in situ* spectroscopic ellipsometry (SE) and quadrupole mass spectrometry (QMS), we disambiguate the physical growth mechanisms and chemical reactions occurring at the substrate surface. The resulting Ru film properties are analyzed *ex situ* using x-ray photoelectron spectroscopy (XPS), x-ray diffraction (XRD) and four-point probe resistivity measurements.

Our *in situ* SE measurements show that, in all cases, deposition occurs for temperatures \geq 160 °C. No self-saturation in growth behavior is observed. This aligns with QMS data which suggests that all Ru complexes undergo spontaneous dissociation reaction on the substrate surface. The water half-reaction plays no relevant role in promoting deposition. XPS and XRD analyses reveal that all films consist of a Ru/RuO_x mixture in line with high film resistivity. These results highlight the limited role of ligands in controlling the ALD / CVD film growth characteristics of diene-Ru(CO)₃ complexes with H₂O as a co-reactant.

11:00am AP+PS+TF-WeM-13 Study on the Thermal Decomposition Behavior of Mo(CO)₆ as a Precursor for Mo-ALD, Soken Obara, Souga Nagai, Jun Yamaguchi, Noboru Sato, Naoki Tamaoki, Atsuhiko Tsukune, Yukihiro Shimogaki, The University of Tokyo, Japan

As miniaturization advances in state-of-the-art semiconductor devices, interconnect resistance becomes increasingly problematic. Atomic layer deposition (ALD) of molybdenum (Mo) is gaining attention as a potential next-generation interconnect technology to replace conventional Cu and W. Although Mo precursors such as MoCl₅ and MoO₂Cl₂ are commonly used, they present significant drawbacks, including the need for high processing temperatures (\sim 600 °C) and the presence of halogens. In this study, we investigated the thermal decomposition and adsorption behavior of Mo(CO)₆, a halogen-free precursor capable of deposition at lower temperatures, to evaluate its suitability for Mo-ALD.

Using an ALD system equipped with a bubbling delivery mechanism, we deposited Mo films on Si substrates with 100 nm thermal oxide at temperatures ranging from 130 to 175 °C, using Mo(CO)₆ and NH₃ as precursor and reactant, respectively. Figure 1 shows the ALD process

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sequence and growth-per-cycle (GPC) as a function of temperature, revealing a steep increase in GPC above 150 °C. As shown in Fig. 2, the precursor pulse time dependence at 145 °C deviates from the ideal ALD self-limiting behavior, indicating a CVD-like growth mechanism.

To investigate the thermal decomposition characteristics of Mo(CO)₆, film deposition cycles were performed at 175 °C using only Mo(CO)₆ and purge gas, without NH₃. As shown in Fig. 3, film formation was observed with a 4-second purge, diminished with an 8-second purge, and disappeared completely with a 14-second purge. This suggests that physisorbed species were gradually removed by purge, thereby suppressing film formation. To determine whether chemisorbed species remained on the surface, a subsequent ALD process with NH₃ was performed after an 8-second purge. As shown in Fig. 4, Mo film growth was observed in the downstream region, suggesting that chemisorption persisted even after the longer purge duration.

Step coverage results are shown in Fig. 5. Under ALD conditions at 145 °C and 175 °C with a 4-second purge, step coverage was 100% and 91%, respectively. However, under the 175 °C condition with an 8-second purge, the step coverage exceeded 165%, indicating thicker deposition at the bottom. This result is attributed to residual physisorbed species accumulating at the feature bottom, leading to enhanced local film growth. These findings demonstrate that bottom-up filling can be achieved by tuning the purge time of the precursor.

11:15am AP+PS+TF-WeM-14 Nucleation Enhancement and Growth Modification in Co-ALD via Pd activation, Yubin Deng, The University of Tokyo, Japan, China; Souga Nagai, Jun Yamaguchi, Yuhei Otaka, Noboru Sato, Naoki Tamaoki, Atsuhiro Tsukune, Yukihiro Shimogaki, The University of Tokyo, Japan

With the continued downscaling of ULSI technologies to the 3 nm node, Cu interconnects demand increasingly thinner liner/barrier layers that can ensure reliable performance under aggressive miniaturization. Previous studies have demonstrated that 1-nm-thick Co(W) films exhibit excellent Cu diffusion barrier properties [1]. However, the critical challenge remains achieving ultrathin, continuous films with precise thickness control. In this context, ALD is considered the most promising technique, offering conformal and selective growth suitable for high-aspect-ratio structures. Importantly, fabricating thinner films via ALD requires higher nucleation densities, which can be promoted by Pd activation. The catalytic properties of Pd enhance precursor adsorption and subsequent surface reactions, thereby improving nucleation. In this study, we systematically investigated the impact of Pd activation on the nucleation behavior and morphological evolution of ALD-Co films.

All samples were prepared on Si substrates with a 300-nm-thick thermally grown SiO₂ layer and were cleaned using ethanol and APM. Two Pd activation methods were employed. The conventional wet method involved immersion in a colloidal Sn/Pd solution (0.6 mM PdCl₂, 30 mM SnCl₂, 0.35 M HCl) at 40 °C for 5 min (Fig. 1), followed by a 3 min rinse in 1 M HCl to remove residual Pd and byproducts, and subsequent drying. Alternatively, Pd activation was performed using ALD (Fig. 2) at 200 °C for 400 cycles, employing palladium(II) hexafluoroacetylacetone (Pd(hfac)₂) as the precursor and aqueous formalin (HCHO) as the reducing agent, with N₂ as the carrier and purge gas. Following Pd activation, Co films were deposited via ALD at 150 °C for 500 cycles (Fig. 3), using dicobalt hexacarbonyl tert-butylacetylene (CCTBA) and H₂ as the precursor and reactant, respectively.

In the wet method, Pd loading was controlled by varying solution concentration and activation time. While in Pd-ALD, it was precisely adjusted by tuning the precursor pulse count per cycle (supply time). As shown in Fig. 4(a), the wet method failed to deposit sufficient Pd on thermal SiO₂, even with extended activation (50 min) and highly concentrated solutions (20×). In contrast, Pd-ALD enabled fine control over the Pd amount, as shown in Fig. 4(b). Figure 5 presents the effects of Pd loading on Co nucleation and morphology. Increased Pd loading resulted in smaller and denser Co nuclei (~9 nm, ~1.1 × 10¹² cm⁻²) and enhanced Co deposition. To achieve uniform 1 nm-thick Co films, further optimization of the Pd-ALD process is necessary to reach the target nucleation density (~10¹⁴ cm⁻²).

References

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11:30am AP+PS+TF-WeM-15 Process-Structure-Properties of Atomic Layer Deposited Niobium Nitride and Evolution of Strain with Plasma Chemistry, Neeraj Nepal, Joseph Prestigiacomo, Maria G Sales, Peter M Litwin, Vikrant J Gokhale, Virginia D Wheeler, Naval Research Laboratory
Niobium nitride (NbN) has exceptional physical, chemical, and electrical properties that can be utilized in a range of applications such as gate metal, superconducting qubits and detectors (T_c ~9-17 K [1]), RF antennas, resonators, and Cu interconnect diffusion barriers. For all these applications, a low temperature growth process with wafer scale uniformity, conformality, and subatomic thickness control is highly desirable. Atomic layer deposition (ALD) provides a path towards integration of NbN at lower temperatures with control over the desired properties. Most reported thin plasma-enhanced ALD (PEALD) NbN films [2-3] to date are either amorphous or polycrystalline. In this talk, we report on highly oriented single phase, PEALD NbN (111) films and discuss the evolution of strain with plasma chemistry.

ALD NbN films were deposited on resistive Si and c-sapphire in a Veeco Fiji Gen2 ALD reactor using (t-butylimido)tris(diethylamido)niobium(V) (TBTDEN) and N₂/H₂ plasma precursors. Similar to previous reports [2], TBTDEN required a boost to enable growth. Growth windows and film morphological, structural, and electrical properties were optimized for TBTDEN temperature (80-100°C), TBTDEN boost (1-2s), TBTDEN pulse (1.5-2.0s), plasma pulse (20-30s), H₂/N₂ ratio (1.5-12.5), and temperature (150-400 °C). Optimum growth parameters (TBTDEN = 100°C, TBTDEN boost = 1.5s, TBTDEN pulse = 2s, and H₂/N₂ = 60/20sccm) yielded an ALD window from 250-300°C with a growth rate (GR) of ~ 0.5A/cy. While GR was almost constant for N₂ ≥ 20 sccm, room temperature resistivity (ρ_{RT}) increased linearly with N₂ flow. High-resolution XRD scans show 1st and 2nd order (111) NbN peaks. Lattice constants obtained from XRD show that strain changes from compressive to tensile with increasing N₂ flow, in which an N₂ flow of 20 sccm provided an almost strain-free film. The compressively strained 12.6 nm thick film at 5 sccm N₂ resulted in lower ρ_{RT} (~139 μΩcm) and superconducting critical temperature (T_c ~12.26K). Measured T_c is similar or higher than reported T_c (12.10K) of 15nm thick ALD NbN films [3]. For an optimized 30nm thick film, carbon is below the XPS detection limit, RMS surface roughness is 0.52nm, and rocking curve FWHM is 0.69°, which is narrower than previously reported for 30 nm thick films [3]. T_c on all those films were also measured to establish process-structure-property relationships, and results will be discussed in the context of use in quantum and high temperature contact applications.

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11:45am AP+PS+TF-WeM-16 Thin Film Property Modification via Electric Field-Modulated Atomic Layer Deposition, Jessica Jones¹, Shi Li, Francisco Lagunas Vargas, Zachary Hood, Argonne National Laboratory

Thin, conformal film growth via atomic layer deposition (ALD) is broadly used in microelectronics, photovoltaics, and other industries. Enhanced thin film properties are required to advance device performance. Electric fields affect gas phase molecules, and adsorption behavior, but have not been extensively investigated for direction of thin properties. Static electric fields are generated and maintained *in situ* inside an ALD reactor resulting in modification of crystallinity and chemical composition. Thicknesses were determined via spectroscopic ellipsometry, uniformity was investigated by atomic force microscopy, crystallinity by x-ray diffraction and (scanning) transmission electron microscopy (S)TEM, and chemical composition by x-ray photoelectron spectroscopy. These systems are computationally investigated to probe the mechanism by which the ALD processes are enhanced.

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¹ JVST Highlighted Talk

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12:00pm AP+PS+TF-WeM-17 Thin Conductive Cu Films by In-Situ Plasma

Post-Reduction of Atomic Layer Deposited CuO, Maria Sales, Neeraj Nepal, Peter Litwin, David Boris, Scott Walton, Virginia Wheeler, Naval Research Laboratory

Interconnect applications in microelectronics has helped spur the need to develop robust and scalable atomic layer deposition (ALD) processes for copper (Cu). For this application space, the unique advantage of ALD is being able to conformally coat via structures with high aspect ratios due to the self-saturating nature and precise thickness control. Reported ALD recipes for pure Cu typically rely on reactions between a metal-organic Cu precursor and either a thermal or plasma reducing reactant. However, these conventional ALD Cu processes have very low growth rates. Like other metal ALD recipes, ALD Cu typically requires thicknesses of at least 20-40 nm to achieve a fully coalesced, conductive film. Thus, limiting these process in applications where ultrathin highly conductive layers are required.

In this work, we report on an alternative way to obtain conductive Cu thin films by combining CuO with a higher growth rate and faster coalescence with an in-situ plasma reduction. Initially, copper (II) oxide, or CuO, is deposited by PEALD at a substrate temperature of 150 °C, using copper(I)-N,N'-di-sec-butylacetamidinate ($[\text{Cu}(\text{Bu-AMD})_2]$) and Ar/O₂ plasma as precursors. The growth rate for this CuO recipe is 0.3 Å/cycle, which is higher than what is obtained for pure Cu using the same precursor (0.1 Å/cycle). Grown CuO films have a low concentration of incorporated ligands and a smooth surface morphology. Following a fixed number of CuO ALD cycles, the CuO film is then exposed to in-situ reducing Ar/H₂ plasma pulses. To characterize the resulting films, spectroscopic ellipsometry (SE), X-ray photoelectron spectroscopy (XPS), atomic force microscopy (AFM), and contactless sheet resistance measurements were performed.

Various parameters during the Ar/H₂ reducing plasma, such as total exposure time, pulse lengths, and number of reducing plasma cycles, were investigated and effect on key properties of the resultant Cu film, such as chemistry, morphology, and resistivity will be discussed. Additionally, we report on utilizing supercycles of CuO ALD and reducing plasma pulses to grow thicker (30 nm) Cu films with low resistivity. To date, our most optimal CuO-then-post-reduction procedure yielded a 30 nm Cu film with a root mean square (RMS) roughness of 3.3-3.5 nm and a resistivity of 3.8 $\mu\Omega$ cm, which is only a factor of 2 greater than for bulk Cu.

Applied Surface Science

Room 209 B W - Session AS-WeM

Quantitative Surface Analysis II

Moderators: Hong Piao, FUJIFILM Electronic Materials USA., Inc., Samantha Rosenberg, Kairos Power

8:00am **AS-WeM-1 Using X-ray Photoelectron Spectroscopy to Determine Iron Oxidation State in Metamorphic Fe-Ti-oxides, Adirondack Mts, New York, Jennifer Mann, David Valley, Kateryna Artyushkova, Physical Electronics; William Nachlas, John Valley, Department of Geoscience, University of Wisconsin**

This presentation explores the application of X-ray Photoelectron Spectroscopy (XPS) for analyzing geological samples, specifically a rock sample from the Adirondack Mountains, N.Y. [1] The Adirondacks are notable due to their complex history and high-temperature metamorphic mineral compositions. These rocks represent the roots of an ancient mountain belt that have been exposed by uplift and erosion. The central Adirondack Highlands were metamorphosed, 1090 to 1020 million years ago, at pressures of ~0.8 GPa (depths of ~25 km) and temperatures up to 850 °C, transforming the mineral-chemistry of many of the rocks. [2-3] The unique geochemistry provides an interesting test case for applying XPS analysis to this metamorphic transformation.

Of particular interest to geochemists is the ability to determine the Fe²⁺/Fe³⁺ ratio in ilmenite and magnetite that can be used to infer peak-metamorphic temperatures. Traditional techniques like electron microprobe analysis have limitations in accurately differentiating these oxidation states. XPS, with its capability for detailed chemical state analysis, offers a promising complementary technique. However, Fe oxides are notoriously difficult to separate when multiple species are present, due to peak overlaps and changes in relative intensities of the satellite structure. [4] A library of Fe²⁺/Fe³⁺ results for quantitative analysis is important for successful identification. In addition to a polished Adirondack rock sample, multiple hematite, magnetite, and ilmenite standards were measured. This

library will be used to determine the oxidation states of iron within the rock's mineral phases.

The PHI Genesis has unique XPS capabilities in that it scans a focused (< 5 μm) X-ray beam across the sample surface. Using a combination of an optical image and PHI's unique scanning X-ray imaging capability, areas of interest on the petrographic thin section can be found quickly. The PHI scanning microprobe enables XPS analysis exclusively from ilmenite or magnetite sections of the rock. The Fe 2p_{3/2}, Fe 3p, O 1s and valence band spectra from each of these two areas will be analyzed, by comparing relative intensities and binding energies of the peaks and satellite structures when present.

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8:15am **AS-WeM-2 Detection of Low Levels of Oxygen in Reactive Materials by X-Ray Photoelectron Spectroscopy (XPS), Jeff Shallenberger, Robert Hengstebeck, Pennsylvania State University; Gilbert Rayner Jr, Kurt J. Lesker**

Accurate detection of low levels of elements such as carbon and oxygen by ion beam sputtering techniques is complicated because those elements (as well as hydrogen) are the primary constituents of the residual gas molecules present in ultrahigh vacuum systems. In this paper we determine the minimum exposure of titanium to the vacuum is only 0.1 Langmuir (1 L = 10^{-6} Torr-sec) before detectable levels of adsorbed oxygen artificially raise the measured concentration. Despite this limited analytical window oxygen detection limits of 0.3-0.4 atom% can be achieved by x-ray photoelectron spectroscopy. We apply similar approaches to aluminum nitride and titanium nitride thin films grown by atomic layer deposition techniques to show best practices for detecting low levels of carbon and oxygen. A linear relationship between exposure and oxygen adsorption at exposures <4 L was observed for all materials studied.

8:30am **AS-WeM-3 Low Energy Ion Scattering Analysis of GC/IrO_x /SiO₂ Catalyst Layer Structures, Philipp Brüner, Thomas Grehl, IONTOF GmbH, Germany; Rens Kamphorst, Katherine Encalada-Flores, Ruud Kortlever, Ruud van Ommen, Delft University of Technology, Netherlands**

Although atomic layer deposition (ALD) offers a precise method for growing ultra-thin coatings with sub-nm control due to its self-limiting nature, characterizing these films remains challenging for surface analytical techniques. This difficulty is particularly pronounced for ultra-thin films consisting of only a few atomic layers or even sub-monolayers, as most analytical methods lack sufficient surface sensitivity and often yield averaged information that includes both the deposited film and the underlying substrate.

In this study, we apply low-energy ion scattering (LEIS) to analyze SiO₂ films grown via ALD on an electrodeposited IrO_x catalyst layer on glassy carbon (GC). LEIS records the energy spectrum of noble gas ions (He, Ne, Ar) scattered from the sample surface, where the elemental peaks correspond to the composition of the outermost atomic layer, enabling quantitative analysis [1]. This extreme surface sensitivity of just a single atomic layer combined with sensitive and quantitative elemental composition analysis is unique to LEIS, making it particularly valuable for investigating ultra-thin films. Additionally, signals from sub-surface scattering provide insights into sample composition and layer thickness up to 10 nm, depending on the material.

By leveraging both top atomic layer sensitivity and thickness information, we demonstrate how to quantify the surface coverage of SiO₂ films, detect surface impurities with high sensitivity, and assess the growth mode of the films. While ALD is often expected to produce films in a well-controlled layer-by-layer fashion [2], our results on these specific samples indicate varying degrees of island growth, where some regions of the substrate develop multilayer films early in the deposition process, while others remain largely uncoated. SiO₂ films grown using different ALD processes are presented, showing the differences in film formation depending on the growth conditions clearly picked up by LEIS.

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8:45am AS-WeM-4 Characterizing Oxide Phase Formation in Niobium-Based Superconducting Devices for NASA Astrophysics Missions, Femi Akinrinola¹, Vikum Dewasurendra, Seth Woodwyk, Aidan Sheppard, Matthew Johnson, Mikel Holcomb, West Virginia University, USA
In NASA astrophysics missions, extremely sensitive detectors are required to capture faint signals from distant astronomical sources, particularly in the far-infrared to microwave regions of the spectrum. Emerging technologies such as microwave kinetic inductance detectors (MKID) and transition-edge sensors (TES) offer exceptional temperature resolution, yet their performance can be strongly influenced by the formation of unwanted oxide phases or other chemical changes during device fabrication. To address these issues, our research focuses on characterizing niobium (Nb)-based superconducting devices to identify and analyze the oxide phases forming on their surfaces. By integrating multiple material characterization techniques, we aim to understand how these oxide layers evolve and influence device performance. We utilize X-ray absorption spectroscopy (XAS) at synchrotron light sources to probe the near-surface region of the devices at nanometer-scale depths, providing detailed insights into the chemical states and electronic structure of niobium oxides. Our XAS analysis reveals the presence of multiple niobium oxide phases, including potentially metastable forms, which may play a critical role in degrading the superconducting properties of these detectors. X-ray photoemission spectroscopy (XPS) provides complementary support for these results. These findings help us correlate fabrication processes with the evolution of surface oxides, contributing to NASA's broader goal of optimizing detector performance for future space-based missions. This research is ongoing, and current efforts are focused on refining spectral fitting models, generating high-quality reference spectra for less stable Nb oxide phases, and enhancing the accuracy of phase quantification to better inform device design and fabrication protocols. We acknowledge support from NASA 80NSSC22M0173 and NSF 2417349.

9:00am AS-WeM-5 Challenges in Next Generation Semiconductor Devices: Insights by Tof-Sims, Rita Tilmann, Alexis Franquet, Paul van der Heide, IMEC Belgium **INVITED**

The semiconductor landscape is advancing, fuelled by evolvements such as the recently enacted European Union's Chips Act, promoting sustainability, and addressing the growing demand for higher performance in electrical devices. As the electrical industry increasingly prioritizes device miniaturization, there is a concurrent necessity for improved resolution metrology.

There is a marked expansion in the variety of applied materials that extend beyond traditional silicon leading to the integration of nanoscaled materials such as carbon nanotubes (CNTs) and two-dimensional (2D) materials like graphene and transition metal dichalcogenides (TMDs), as well as organic and DNA-based electronics. This wide diversity at the nanoscale underscores the urgent need for advanced metrology techniques tailored to semiconductor device design.

Time-of-Flight Secondary Ion Mass Spectrometry (TOF-SIMS) has emerged as a leading solution for addressing these metrology requirements. It offers the capability to analyze the composition and distribution of organic and inorganic materials at the nanoscale with exceptional precision. However, as the demands of semiconductor technology evolve, further improvements in TOF-SIMS methodologies are essential. Innovations such as the Self-Focusing SIMS (SF-SIMS) principle [1] and alternative erosion beam options, like oxygen gas cluster ion beams (O_2 GCIB), represent promising advancements. These enhancements can significantly improve the depth resolution and lateral precision of analyses for thin layered semiconductor stacked and patterned structures.

In this contribution examples of the new generation cFET analyses with TOF-SIMS including the beforementioned O_2 GCIB cluster in comparison to monoatomic O_2 and Cs beams is presented, finding the best compromise for increased depth resolution and sensitivity. In addition, the SF-SIMS principle is applied to enable quantification of Ge and dopants in SiGe layers.

As the industry moves forward, the focus on improving TOF-SIMS and related technologies will be vital enabling researchers and manufacturers to better characterize the increasingly complex nanoscaled materials and structures integral to next-generation semiconductor devices.

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9:30am AS-WeM-7 XPS Investigation of Argon Monoatomic and Gas Cluster Ion Beam Etching of 4H SiC, Ryan Raad, Christian Doppler Laboratory for Sustainable Silicon Carbide Technology, Institute of Sensor and Actuator Systems, TU Wien, Austria; Markus Sauer, Analytical Instrumentation Center, TU Wien, Austria; Georg Pfusterschmid, Christian Doppler Laboratory for Sustainable Silicon Carbide Technology, Institute of Sensor and Actuator Systems, TU Wien, Austria; Ulrich Schmid, Institute of Sensor and Actuator Systems, TU Wien, Austria

Depth profiling is commonly used in spectroscopic analyses, but it can significantly alter the chemical stoichiometry and crystalline structure due to ion-matter interactions, such as mixing, cascade collision, amorphization, or diffusion^{1,2}. In compound materials like SiC, preferential etching worsens the overall situation, which can yield misleading analyses. The gas cluster ion beam (GCIB) technique has emerged as a promising solution, notably known for its low-damage irradiation³. However, sputtering parameters must be carefully tuned as even with this technique, destructive effects on inorganic materials were demonstrated⁴. Therefore, understanding the surface modification of innovative semiconductors such as 4H SiC is crucial to minimizing sputtering artifacts and ensuring accurate device analysis.

We investigated the sputter-etching behavior of Argon monoatomic and GCIB on the Si-face of monocrystalline 4H SiC samples. The surfaces were analyzed with XPS after 15 minutes of in-situ sputtering with Ar^{+}_n GCIB, followed by a 1-minute aggressive Ar^+ etching (4 kV, 1.9 μ A) to magnify the contrast. Figures 1 and 2 show that increasing the energy and size of the cluster drastically changes the surface composition. As illustrated in Figure 1, for 2.5 kV 10 nA (blue) and 5 kV 20 nA (green), the oxygen signal undergoes a significant reduction only after switching to aggressive etching. We can assume that for a transferred energy of up to 3.8 eV/atom with a cluster of 1300 atoms, both the silicon oxycarbide (SiCxOy in violet at 101 eV on the Si 2p) and the 4H-SiC remain intact, while the adventitious carbon is sputtered away. However, when the impact energy is further increased

(10 kV 30 nA), the oxide is etched within the first 5 minutes (see Fig. 1) and the Si 2p detailed spectrum (see Fig. 2) broadens towards lower binding energy (Si-Si in red at 99.4 eV on the Si 2p). This reduction in the oxidation state of the silicon may suggest preferential etching of the oxide, as evidenced by a decrease in its FWHM value from 1.74 eV to 1.23 eV.

Acknowledgements

The financial support from the Christian Doppler Research Laboratory for Sustainable Silicon Carbide Technology is gratefully acknowledged, as well as the training and access to XPS from the Electrochemical Surface and Interface Analysis Cluster of TU Wien.

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11:00am AS-WeM-13 In situ and quasi-in situ characterization techniques for atomic-scale process development in device fabrication: focus on Area Selective Deposition process, Christophe Vallée, University at Albany-SUNY; Marceline Bonvalot, Grenoble Alpes University, France; Remy Gassilloud, CEA-Leti, France; Cedric Mannequin, University of Nantes, France; David Muñoz-Rojas, Grenoble Alpes University, France **INVITED**

In the recent years, innovative processes have enabled scaling nodes through the integration of new materials and new architectures at the nm scale. 3D NAND based on multi-layering needs highly selective process. The enhancement of DRAM from 1Y-1Z needs high aspect ratio processes. Sub 3nm logic development will need precision patterning process. Most of these requirements cannot be met without the use of atomically controlled processes. Hence, the latest generation of transistors need to integrate

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dozens of atomic layer deposition (ALD) steps and a few atomic layer etching (ALE) steps. The next generations will certainly include selective deposition steps with the use of an area selective deposition (ASD) process. An ASD process is designed to selectively deposit material only on a surface named growth area, with no deposition on a targeted surface named non-growth area. This process can be carried out using chemical deposition processes, the most popular of which is ALD. It can also be coupled with an ALE etching process to form an ASD process by super-cycling of deposition and etch. Inhibitors can also be used to block the growth on the non-growth area. The processes described below require a perfect understanding and control of the interactions between molecules/radicals and surface chemical groups. This highlights the need for *in situ* and quasi-*in situ* techniques. In this presentation, we will address the methods most widely used to date. Then we'll look ahead to HVM applications, discussing current needs in metrology, not only for process monitoring, understanding and control, but also for better measurement of process-induced defects and yields.

11:30am AS-WeM-15 Combining ISS, XPS and ion sputtering to discriminate Si-contamination from Si present in the stack of reticles for extreme ultraviolet (EUV) lithography, Véronique de Rooij-Lohmann, Shriparna Mukherjee, Kleopatra Papamichou, TNO, the Netherlands Organisation for Applied Scientific Research, Netherlands

EUV lithography scanners are extremely complex machines. The heart of the machine is formed by the optical system, which consists of a series of mirrors and reticle. To avoid loss of throughput and imaging performance, these need to remain free of contamination. In spite of great effort though, contamination is hard to avoid completely, as a result of the aggressive environment in combination with the plethora of components in the EUV lithography system.

Si – being ubiquitous in the semiconductor industry – is an element of particular interest to EUV-related optics life-time research. XPS analysis of Si-contamination on optical samples (e.g. reticles and mirrors) is hindered though by the presence of Si in the sample stack. Because reference data from known clean samples is usually unavailable, the discrimination between Si as contaminant and Si as sample constituent relies on assumptions. Therefore, to advance this aspect of reticle metrology, we intentionally contaminated samples with Si, then investigated and compared several approaches to distinguish between Si on the surface and Si in the stack.

The metrology includes methods based on depth-resolved information from AR-XPS and HAXPES, Ion Scattering Spectroscopy as extremely surface-selective analysis method, and removal of the Si-contamination via mild etching with monatomic He⁺, monatomic Ar⁺, and Ar₁₀₀₀⁺ cluster ions. The suitability of these methods are first tested on model Ru- and absorber samples without Si in the stack. The most promising approaches are then applied to EUV reticles.

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11:45am AS-WeM-16 Using X-Ray Induced Auger Electron Spectroscopy Transitions to Explore the Surface Reactivity of Semi-Conductors, Kirène Gaffar, Anna Gagliardi, Antonin Frappreau, Arnaud Etcheberry, Muriel Bouttemy, Solène Béchu, CNRS, ILV, France

With the exception of the modified Auger parameter, X-ray induced Auger electron (X-AES) transitions remain underexploited to date. Indeed, they can provide a powerful insight for the chemistry evolution of semiconductors (oxidation degree, chemical environment, atomic composition), as the classic photopeaks used in XPS. However, a direct interpretation (spectral signature, energy position) is not always straightforward or evident, requiring further data processing using specific decomposition procedures to take into account the complexity inherent in the shapes of these peaks.

The present work explores the decomposition of X-AES transitions by using two different methods of decomposition, the non-linear least square (NLLS) [1] and the linear least square (LLS) [2] methods. These are combined with principal component analysis and vectorial method [3]. The NLLS method requires multiple peaks to simulate the decomposition, which increases the

potential for human error. However, minor adjustments can be performed with respect to position or FWHM values. In contrast, the LLS method employs a single envelope per chemical environment, which limits the decomposition error but excludes any small adjustments.

Following the implementation of different decomposition processes on Auger lines, three different applications of X-AES lines are presented. The first application involves the quantification of nitrogen in GaN material by XPS (performed with an Al Ka source), where the N 1s signal is overlaid with the Ga L_{2,3}M_{4,5}M_{4,5} Auger line.[4] The second application is related to the kinetic aspect of the oxides formation of a solar absorber (Cu(In,Ga)Se₂-CIGS- material). In order to explore similar depth probed (with an Al Ka source), Auger transitions and XPS photopeaks with similar escape depths are coupled for each CIGS element. This coupling method is also employed to study the surface reactivity of CdTe materials when exposed to air, with a specific input on the decomposition of Cd M_{4,5}N_{4,5}N_{4,5} X-Auger lines.

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Chemical Analysis and Imaging at Interfaces

Room 205 ABCD W - Session CA+AS+SS-WeM

Chemical Analysis and Imaging at Interfaces Oral Session

Moderators: Gabriel Parker, Oak Ridge National Laboratory, Xiao-Ying Yu, Oak Ridge National Laboratory, USA

8:00am CA+AS+SS-WeM-1 Heterogeneous Chemistry at Liquid-Vapor Interfaces Investigated by X-Ray Photoelectron Spectroscopy, Hendrik Bluhm, Fritz Haber Institute of the Max Planck Society, Germany **INVITED**
Aqueous solution-vapor interfaces govern important phenomena in the environment and atmosphere, including the uptake and release of trace gases by aerosols and CO₂ sequestration by the oceans. A detailed understanding of these processes requires the investigation of liquid-vapor interfaces with chemical sensitivity and interface specificity. [1] This talk will discuss opportunities and challenges for investigations of liquid-vapor interfaces using X-ray photoelectron spectroscopy and describe recent experiments that have focused on the propensity of certain ions and the role of surfactants at the liquid-vapor interface.[2-4] The talk will also discuss the utilization of photoelectron angular distributions for the investigation of the depth of solvation of surfactants at the interface. [5-7]

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8:30am CA+AS+SS-WeM-3 Probing Chemical and Catalytic Interfaces Using Operando Soft X-Ray Spectroscopy, Jinghua Guo, Lawrence Berkeley National Laboratory **INVITED**

Synchrotron based X-ray spectroscopic techniques offer unique characterization of energy, catalysis and chemical process in regards to the functionality, complexity of material architecture and chemistry. In the operando soft X-ray spectroscopy study of interfacial phenomena, it has been found that the microstructure and composition of materials as well as the microstructure evolution process have a great influence on performances in a variety of fields, such as the energy conversion and energy storage materials in the chemical and catalytic processes. This presentation will show how to best use the X-ray spectroscopy characterization techniques, including X-ray absorption spectroscopy (XAS) and resonant inelastic X-ray scattering (RIXS) to investigate the real interfacial reaction mechanism during the operation. The experimental results show how operando soft X-ray spectra uncover the phase conversion, chemical and structure change of solid/liquid and solid/gas interfaces in real time, thus further enhance the understanding of real reaction mechanism.

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9:00am **CA+AS+SS-WeM-5 Capturing Electrical Double Layer in Action with Xps on a Graphene Coplanar Capacitor with an Ionic Liquid, Sefik Suzer**, Bilkent University, Chemistry Department, Ankara, Turkey

Time-dependent XPS data is recorded for capturing the dynamics of the Electrical Double Layer formation on electrified two Multilayered-Graphene electrodes, configured as a coplanar-capacitor, having an ionic liquid as the electrolyte. The device is subjected to 2 V biasing cycle changing its polarity every hour, while iteratively recording the O1s peak representing the anion with 0.5 s steps. Variations in the O1s peak's binding energy position on the electrified electrode report directly the electrical potential of the IL medium, which suddenly jumps to the opposite polarization, if the electrode is grounded. The peak eventually returns to its equilibrium position with a relatively long time constant. The complementing action is also captured on the drain electrode, which exhibits mirrored but oppositely polarized temporal variations. Grounding the electrode allows separating the fast electronic components from those slow ionic ones, which is the key process introduced in this work, which is vital for better understanding of the function of the numerous components of the devices investigated. Experimental details will be given, these novel findings will be discussed and their implications for understanding the mechanism of the EDL formation will be presented.

9:15am **CA+AS+SS-WeM-6 Studying Tungsten and Alloys as Candidate Plasma Facing Material Using ToF-SIMS, Xiao-Ying Yu, Gabriel Parker, Tobias Misicko, Yan-Ru Lin, Oak Ridge National Laboratory; Tanguy Terlier, Rice University; Yutai Katoh, Oak Ridge National Laboratory**

Plasma facing materials (PFMs) are important in realizing fusion power. Tungsten (W) and alloys are considered primary candidates of PFMs due to their high melting points, high thermal conductivities, good neutron irradiation resistance, fast diffusion of hydrogen, low retention, and sputtering behaviors. However, technical challenges remain in adopting W and alloys as PFMs. In this presentation, we will share recent study cases of W and alloys using advanced microanalysis and chemical imaging, primarily time-of-flight secondary ion mass spectrometry (ToF-SIMS). SIMS is a powerful imaging mass spectrometry tool, and it can be used to reveal surface composition with high sensitivity or probe the material layer-by-layer and reveal spatial distributions in two-dimension or three-dimension. Due to parallel data acquisition, full spectral information consisting of elements, isotopes, and molecule permitted in the duty cycle is available in SIMS' chemical mapping. We will present a few case studies of potential PFMs using SIMS. First, High Flux Isotope Reactor (HFIR) irradiated single crystal tungsten (SCW) specimens from the FRONTIER collaboration campaigns were selected for spectral analysis and depth profiling. SCW coupons were subjected to shielded and unshielded neutron irradiation in HFIR. Prior to ToF-SIMS analysis, specimens were prepared using focused ion beam (FIB). To assure reliable peak identification and assignment, we performed analysis of pristine single crystal tungsten as a control. Mass spectra reconstructed from depth profiling show a variety of transmutation products in unshielded W, such as Rhenium, Osmium, and Tantalum. In contrast, not as many transmutation products were detected in the shielded irradiated W spectra. Second, W alloys were studied to verify the trace doping quantity of Boron (B) using the high mass sensitivity of SIMS spectroscopy, and measurements were verified using Raman. Depth profiling was used to verify the distribution of B within the W matrix. Third, we show that depth profiling with high spatial resolution can be used to map the grain boundaries in W alloys and assist the development of new materials and validate the engineering process. These recent studies provide results of the structural and compositional changes in W and alloys as potential PFMs, showing that SIMS can be a useful tool on elucidating alloy property changes and supporting material development for sustainable fusion in the future.

11:00am **CA+AS+SS-WeM-13 ToF-SIMS Acquisition Multiplexing - Concept, Applications, and Data Analysis, Henrik Arlinghaus, 1) ION-TOF GmbH, Germany; 2) Institut für Hygiene, WWU, Germany; Alexander Pirl, Derk Rading, Julia Zabel, Ewald Niehuis, ION-TOF GmbH, Germany** **INVITED**

Time of Flight Secondary Ion Mass Spectrometry (ToF-SIMS) is a versatile technique for 2D and 3D analysis of surfaces. During the acquisition process, secondary ions are desorbed from the sample using one or more primary ion beams. These secondary ions are used to acquire a full mass spectrum at each voxel. Typically, a single acquisition mode is used when acquiring data, optimized for one specific potential aspect of the (unknown) sample. This becomes problematic when the number of acquisitions is constrained by the amount of sample available or the instrument time available. In the acquisition multiplexing approach, multiple acquisition modes, each of which is optimized for a specific performance aspect, are

utilized during the acquisition process, resulting in multiple co-located datasets. Each of these acquired datasets may be analyzed individually in the traditional manner, or via algorithmic techniques such as Multivariate Statistical Analysis (MVSA) or Machine Learning (ML). Additionally, by taking advantage of the dataset's co-location property, it is possible to analyze all of the acquired data at once, finding aspects of the sample which span the data spectrally, spatially, and across acquisition modes.

We have applied this approach to vary numerous performance parameters of ToF-SIMS instruments, such as the primary ion beam current, the primary ion species, the focus of the beam, etc. Subsequently, analysis routines optimized for the parameter that was varied were applied to the datasets to make full use of the resulting data. One example is acquiring datasets using different primary ion beam currents, and then generating a High Dynamic Range (HDR) like dataset. High primary ion currents result in intense peaks which may saturate the detector signal. At the same time, low intensity signals are noisy at low primary ion currents. Another parameter which we varied is whether to optimize the primary beam for high mass resolution (and lower spatial resolution), or high spatial resolution (and lower mass resolution). This results in two datasets with fully complementary information. These may then be analyzed using machine learning based image fusion to generate a single high mass high spatial resolution dataset.

11:30am **CA+AS+SS-WeM-15 Diamond Surface Analysis for Electronics and Quantum Applications, Alastair Stacey, Princeton Plasma Physics Laboratory** **INVITED**

Characterising and controlling surface electronic and quantum states is an almost ubiquitous challenge for electronic and quantum technologies. The diamond material system is a particular example, where bulk states can be created with extreme purity but surface states, chemical and physical, are not yet well controlled or even understood.

In this presentation I will detail our efforts to analyse the diamond surface, with a variety of vacuum science techniques and theoretical analyses, and reveal some of the chemical challenges being faced in passivating and functionalizing this surface. I will show evidence that these surfaces remain significantly disruptive for quantum devices and present recent efforts in the development of high performance hydrogen terminated diamond transistors. Finally, I will forecast the remaining challenges and next steps for improving the surface science of this important quantum electronic material.

12:00pm **CA+AS+SS-WeM-17 ToF-SIMS Spectral Analysis Using Python, Tobias Misicko¹, Louisiana Tech University and Oak Ridge National Laboratory; Nan Jiang, Xinghang Zhang, Yexiang Xue, Purdue University; Xiao-Ying Yu, Oak Ridge National Laboratory**

Time-of-Flight Secondary Ion Mass Spectrometry (ToF-SIMS) is a powerful surface analysis technique that enables spatially resolved chemical characterization of materials with high mass resolution and accuracy. However, analyzing ToF-SIMS data remains challenging due to the high dimensionality and large size of datasets resulting from parallel data acquisition. Previous efforts have largely depended on manual interpretation and the analyst's prior experience to apply dimensionality reduction techniques for material composition analysis. This process demands substantial human supervision and is hindered by the lack of open-source datasets and comprehensive, end-to-end code implementations for multivariate analysis pipelines, particularly for principal component analysis (PCA) and non-negative matrix factorization (NMF). In this work, we integrate both established and emerging methods tailored for ToF-SIMS spectral analysis, delivering an open-source, Python-based framework for intelligent mass spectral analysis to the ToF-SIMS research community. We demonstrate the application of PCA and NMF for spectral analysis and benchmark their performance using a quality-assured SIMS dataset.

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Electronic Materials and Photonics

Room 207 A W - Session EM1+AP+CA+CPS+MS+TF-WeM

Advances in Wide Bandgap Materials and Devices

Moderator: Erin Cleveland, Laboratory of Physical Sciences

8:00am EM1+AP+CA+CPS+MS+TF-WeM-1 Progress in Wide and Ultra-Wide Bandgap Semiconductors – Energy Implications, *John Muth*, North Carolina State University **INVITED**

The progress in developing wide bandgap semiconductors from idea to commercial products over the past 30 years is one of the great successes of interdisciplinary research between materials, science, physics and electrical engineering. Presently, we are experiencing another step change in the performance of semiconductor devices as ultra-wide bandgap materials (Diamond, Aluminum Nitride, Gallium Oxide) overcome fundamental issues like wafer size, the ability to control conductivity with doping in controlled ways and techniques like wafer bonding become more widely used and high voltage device demonstrations are being made. Similarly, SiC and Gallium Nitride wide bandgap devices are leveraging more mature fabrication technologies including deep ion implantation, sophisticated etching techniques, and high k dielectrics to enable non-planar device geometries, that lower the on resistances and provide increased breakdown voltages. The use of emerging alloys like AlScN offer higher performance higher frequency transistors as well as an addition route to integrate ferroelectric materials with CMOS. Innovations in photonic devices should not be left out with microLEDs for displays and chip to chip communications and increased ability to make low loss visible photonic integrated circuits as well as narrow linewidth lasers for quantum. The goal of this presentation will be to put these advances into context comparing the advances in the different materials and their potential for energy savings for a variety of systems including Artificial Intelligence, Data Centers, and computing and systems where size, weight, power efficiency and reliability matter including ships, planes and satellites.

8:30am EM1+AP+CA+CPS+MS+TF-WeM-3 Limitations and Effects of Heavy Metal Doping in GaN, *J. Pierce Fix*, Montana State University; *Kevin Vallejo*, Idaho National Laboratory; *Nicholas Borys*, Montana State University; *Brelon May*, Idaho National Laboratory

The doping of third-party elements is the backbone of the microelectronics industry, as it allows delicate control of electron/hole concentration, but it can also be used to imbue a host matrix with unique magnetic or optical properties. Wurtzite gallium nitride is a widely studied large bandgap semiconductor. There are reports of doping GaN with numerous elements, with some being extensively employed in commercial applications. However, there are still a few elements which remain completely unexplored. This work investigates the doping limits and effects of select transition metals, lanthanoids, and actinoids in GaN. The structural, electronic, and optical properties of these first-of-a-kind combinations are presented. Embedding single crystal wide bandgap materials with additional functionality will provide building blocks for new multifunctional hybrid systems for novel sensors, quantum science, or meta-multiferroics. Leveraging the non-centrosymmetric piezoelectric host matrix and atomic-level control of dopant species could allow for active tuning of proximity and correlated phenomena, potentially opening the door for applications of actinide elements beyond nuclear fuels.

8:45am EM1+AP+CA+CPS+MS+TF-WeM-4 Using Raman Spectroscopy to Characterize Stress and Strain in SiC, *Michelle Sestak*, HORIBA

Raman spectroscopy is a useful, non-destructive tool for measuring stress and strain in materials like silicon carbide (SiC). In this study, we use Raman spectroscopy to analyze stress and strain in three types of SiC samples: as-cut, diamond-lapped, and after chemical mechanical polishing (CMP). By examining shifts in the Raman peak positions, we identify differences in residual stress caused by each processing step. The as-cut samples show high stress due to mechanical damage, while diamond-lapped samples show partial stress relief. The CMP-treated samples exhibit the lowest stress levels, indicating effective surface relaxation. These results demonstrate how Raman spectroscopy can be used to monitor and compare the effects of different surface preparation techniques on stress in SiC materials.

9:00am EM1+AP+CA+CPS+MS+TF-WeM-5 Nanoscale GaN Vacuum Electron Devices, *George Wang*, Keshab Sapkota, Huu Nguyen, Gyorgy Vizkelethy, Sandia National Laboratories

On-chip vacuum electron devices that operate by cold field emission have the potential to combine advantages of traditional vacuum electron devices

(e.g. vacuum tubes), such as robustness in harsh environments and high frequency operation, together with those of modern solid-state devices, such as size and energy efficiency. By shrinking the vacuum or “air” channel to nanoscale dimensions well below the electron mean free path in air, such devices can operate at ambient pressures while maintaining the physical advantages of ballistic vacuum transport. Here, we present lateral gallium nitride (GaN) semiconductor nanogap field emission diodes and transistors that exhibit ultra-low turn-on voltage, high field-emission current, and that operate in air. The fabrication of these nanoscale devices is enabled by a two-step top-down etching approach allowing for the necessary sidewall verticality and surface smoothness. We present experimental and modeling results on the field emission characteristics of these devices at various nanogap sizes and operating pressures. Initial results showing the potential of these devices for radiation-hardened, photodetection and high-temperature applications will be presented. These results provide critical new insights into the behavior of this new class of devices and point to future challenges and opportunities. *Sandia National Laboratories is managed and operated by NTSS under DOE NNSA contract DE-NA0003525*

9:15am EM1+AP+CA+CPS+MS+TF-WeM-6 Combining CVD of Graphene and SiC for Efficient Layer Transfer, *Daniel Pennachio*, Jenifer Hajzus, Rachael Myers-Ward, US Naval Research Laboratory

Remote epitaxy (RE) is a thin film growth technique that incorporates a release layer into the material stack, allowing for transfer of the deposited material with minimal defects [1]. Transferred 2D two-dimensional (2D) material, such as graphene, is commonly used for a release layer, but the transfer step can degrade the film and increase process complexity. To avoid this, we examine *in situ* graphitic carbon growth on SiC substrates before subsequent SiC epitaxy in the same chemical vapor deposition (CVD) RE process. RE SiC and subsequent SiC epilayer transfer is desired since isolated SiC membranes are excellent for quantum photonics and SiC substrate reuse can provide significant cost savings. Despite these benefits, the high-temperature hydrogen-containing CVD environment can damage graphene, making RE difficult under standard SiC growth conditions [2].

This study established growth windows for *in situ* graphene via propane-based hot wall CVD. This propane-based graphene growth enables an efficient transition to subsequent SiC deposition using established SiC growth conditions since it shares a similar hydrogen ambient to standard SiC CVD. Growing at 1620 °C in 20 slm H₂ with 20 sccm propane flow produced predominantly monolayer (ML) graphene films on on-axis 6H-SiC(0001) substrates with minimal defects found in Raman spectral maps. Films grown on 4° off-axis 4H-SiC(0001) substrates were multilayer (6 ML) graphitic carbon despite experiencing the same conditions as the on-axis substrates. This optimized graphene growth condition was used for subsequent RE attempts to study the effect of SiC precursor dose, C/Si ratio, and growth rate on epilayer crystallinity and graphene barrier damage. SiC crystalline quality appeared correlated to growth rate, with lower growth rates producing smoother films with fewer polype type inclusions. Single-crystalline, polype type-pure SiC epilayers were achieved on 4° off-axis CVD graphene/4H-SiC(0001). Effects of initial SiC growth parameters on the graphitic carbon release layer were explored via cross-sectional transmission electron microscopy (TEM) and attempts at epilayer transfer. Some growth interfaces exhibited non-uniform multilayer graphitic carbon, motivating further study of this growth system to improve boundary uniformity and SiC epilayer quality.

[1] Kim, Y., Cruz, S., Lee, K. et al. *Nature* 544, 340–343 (2017).

[2] Pennachio, D. J., Hajzus, J. R., & Myers-Ward, R. L. *JVST B*, 43(2). (2025).

9:30am EM1+AP+CA+CPS+MS+TF-WeM-7 Multiscale Modeling of Self-heating Effects in AlGaN/GaN High Electron Mobility Transistors (HEMT), *Jerry Comanescu*, National Institute of Standards and Technology; *Albert Davydov*, NIST-Gaithersburg; *Michael Shur*, Theiss Research, Inc.; *Tyler Gervasio*, Behrang Hamadani, *Michael Lloyd*, NIST-Gaithersburg

AlGaN/GaN based High Electron Mobility Transistors have emerged as state-of-the-art devices in power and RF electronics because of the outstanding electronic properties of the AlGaN/GaN heterostructure. The large breakdown field of GaN (3.3 MV/cm, 11 times higher than silicon) enables HEMT operation in the kV-range while the high mobility of the two-dimensional electron gas at the AlGaN/GaN interface ensures that HEMTs have a very low on-resistance. In addition, the wide bandgap of GaN makes HEMT devices particularly suitable for high-temperature, high-power, and high-current operations. However, unlike silicon-based devices, the performance of current GaN based devices falls significantly shorter than what is expected based on the outstanding properties of GaN material. This

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gap in performance is even larger when HEMT devices experience self-heating under high-power operation regime, which strongly affects the device lifetime and reliability. Therefore, understanding the high-temperature operation and the self-heating effect is critical for improving the device design. We report on self-heating effect in AlGaN/GaN HEMTs. We interpret our measurement results using a new compact CAD self-heating model. The model is based on the Unified Charge Control Model (UCCM) and is in excellent agreement with the measured data. Our results allow for the identification of the material properties and device parameters primarily responsible for the temperature dependencies of the device characteristics. The measured temperature dependencies also reveal non-ideal effects related to charge trapping, including threshold voltage instability and current-voltage characteristic hysteresis. The model accounts for the temperature distribution inside the HEMT devices (e.g., distribution of temperature along the channel) which are evaluated by a combination of TCAD simulations, heat transfer finite element simulations, and experiments performed on commercial HEMT devices. The developed compact self-heating model augments TCAD simulations for the Device Technology Co-Optimization approach by linking the AlGaN/GaN HEMT performance and design optimization to material and interface properties.

9:45am EM1+AP+CA+CPS+MS+TF-WeM-8 Atomic Layer Deposition of High-k Oxide Layers on Aluminum Gallium Nitride: Insight from Time-Resolved Synchrotron Studies, Nishant Patel, Shreemoyee Chakraborty, Lund University, Sweden; Byeongchan So, Lund University, Sweden; Minho Kim, Alexis Papamichail, Linkoping University, Sweden; Rosemary Jones, Max IV Laboratory, Sweden; Erik Lind, Vanya Darakchieva, Rainer Timm, Lund University, Sweden

Gallium nitride (GaN) and aluminum gallium nitride (AlGaN) are the materials of choice for enabling power electronic devices with superior energy efficiency and very high switching frequency. Such devices are based on metal-oxide-semiconductor (MOS) stacks, where downscaling and leakage control require gate insulators with high dielectric constant, so-called high-k oxides, such as HfO₂. However, device performance and especially switching frequencies are often limited by the low quality of the (Al)GaN/high-k interface. Atomic layer deposition (ALD) is typically used for the synthesis of ultrathin, conformal high-k layers, where the choice of oxide material, ALD parameters, and pre-ALD cleaning methods strongly influence film and interface quality. Many important details about the physics and chemistry of the interface formation still remain unknown. Furthermore, until now all efforts to explore the high-k oxide film formation are based on *ex situ* approaches, meaning that film deposition and characterization of the resulting interface occur in separate steps.

Here, we will present a first time-resolved investigation of the ALD reactions of HfO₂ on (Al)GaN. We have used synchrotron-based ambient-pressure X-ray photoelectron spectroscopy (AP-XPS) and implemented the ALD process in the AP-XPS setup at the MAX IV synchrotron facility. Thus, we succeeded in mapping surface chemistry and electronic properties *in situ* during subsequent ALD half-cycles, which consisted of the deposition of tetrakisdimethylamido-hafnium (TDMA-Hf) and water. We observed a rather inefficient first ALD cycle, compared to other semiconductor ALD reactions, which improved with increasing aluminum content. Thickness and chemical composition of the resulting Hf-oxide film varied significantly if the order of the precursors was changed (TDMA-Hf first or water first). Both observations are against the established ligand-exchange ALD model and highlight the importance of in-depth studies for improving the quality of high-k layers on (Al)GaN.

In addition, we have used XPS to systematically investigate the electronic properties and chemical composition of the interface between different (Al)GaN substrates and HfO₂ or Al₂O₃ high-k oxide films, for different ALD temperatures, where Al₂O₃ layers typically resulted in a more stoichiometric oxide film. The choice of pre-ALD cleaning methods was also found to be of importance, which can enhance ALD efficiency but also result in significant interface contamination. We will discuss how our structural results can be easily implemented to improve device performance.

Electronic Materials and Photonics

Room 207 A W - Session EM2+CA+CPS+MS+SE+TF-WeM

Processing Ultra-Wide Band Gap Ga₂O₃

Moderator: Daniel Pennachio, Naval Research Laboratory

11:00am EM2+CA+CPS+MS+SE+TF-WeM-13 Ga₂O₃ Polymorphs: Epitaxial Film Growth, Characterization and Contacts, Lisa Porter, Jingyu Tang, Kunyao Jiang, Robert Davis, Posen Tseng, Rachel Kurchin, Carnegie Mellon University; Luke Lyle, Penn State Applied Research Labs; Carlo Schettini Mejia, Carnegie Mellon University

INVITED

The last decade has shown a dramatic increase in research on gallium oxide (Ga₂O₃) as an ultra-wide bandgap semiconductor for electronics that can operate in extreme conditions, such as high power, high temperature and radiation exposure. This presentation will focus on unique and intriguing characteristics associated with two processes that are necessary to produce Ga₂O₃-based devices: the growth of epitaxial films and the formation of ohmic and Schottky contacts. Whereas β -Ga₂O₃ is the thermodynamically stable phase, the other, metastable, phases of Ga₂O₃ can be produced as epitaxial films in either mixed-phase or pure-phase form. Our results, along with those in the literature, indicate that the phase content and other film properties strongly depend on the growth method (e.g., MOCVD, HVPE, mist CVD, etc.) and other conditions during film growth, such as precursor chemistry, flow rates, temperature, and substrate material / orientation. Our group has also conducted comprehensive studies of ohmic and Schottky contacts to β -Ga₂O₃. For reasons that are not well understood, only a few metals have been demonstrated as practical ohmic contacts to Ga₂O₃. Whereas Ti/Au contacts annealed at 400–500 °C are widely used, Cr/Au contacts annealed in a comparable temperature range also form ohmic contacts to Ga₂O₃. Controlled studies of several different elemental-metal Schottky contacts show that their electrical behavior highly depends on the particular Ga₂O₃ surface on which they're deposited; observed behavior ranges from Fermi-level pinning on the (-201) surface to near-ideal Schottky-Mott behavior on the (100) surface. Examples of the phenomena outlined above will be summarized and presented using results from high-resolution transmission electron microscopy, x-ray diffraction, and electrical measurements.

11:30am EM2+CA+CPS+MS+SE+TF-WeM-15 Compensating Interfacial Parasitic Si Channels in β -Ga₂O₃ Thin Films Via Fe δ -doping, Prescott Evans, Brenton Noesges, Jian Li, Mark Gordan, Daram Ramdin, Shin Mou, Adam Neal, Thaddeus Asel, Air Force Research Laboratory, USA

β -Ga₂O₃ is a promising material for high power applications given an ultra-wide bandgap and predicted high break down field. One challenge with β -Ga₂O₃ for lateral device architectures is the presence of undesired Si between epitaxial thin film and substrate which creates a parasitic conduction channel. This channel limits performance and can prevent device modulation. Attempts to remove this interfacial layer using etch methods have proven mostly successful. However, in plasma-assisted oxide molecular beam epitaxy (PAMBE), conventional removal efforts appear unsuccessful. Our results show interfacial Si can reaccumulate at clean β -Ga₂O₃ surfaces from various Si sources inside the MBE tool such as the Si doping effusion cell. Hence, careful growth steps must be considered to avoid Si reaccumulating onto clean β -Ga₂O₃ surfaces in PAMBE. This work presents an alternative to mitigate the influence of this Si parasitic conduction channel via Fe delta doping at the interface. We demonstrate how a thin Fe layer at the interface can compensate interfacial Si and create an interface without excess free charge. The growth methodology presented involves multiple steps to avoid Fe diffusion from the interface. We first deposit the Fe followed by a low temperature (LT) undoped buffer before depositing an Si doped channel layer at higher deposition temperatures. The LT buffer helps minimize Fe surface riding and diffusion while the increased substrate temperature during the Si doped channel improves surface roughness. Secondary ion mass spectrometry (SIMS) results show Fe only resides at the interface between substrate and LT buffer layer with Fe concentration in the LT buffer and Si doped channel below the noise floor of the instrument. Furthermore, SIMS shows a smooth transition in Si concentration from the LT buffer into the intentionally Si-doped channel region avoiding any spikes between the two layers, indicating high degree of controlled doping localization. Initial capacitance-voltage (C-V) measurements on samples with the Fe compensation show no spike in carrier concentration near the substrate interface indicating Fe is fully compensating interfacial Si. These results demonstrate a potential method to mitigate parasitic Si conduction channels in β -Ga₂O₃. However, time-dependent C-V results show there is some capacitance transients when the sample is fully depleted. While Fe

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seems initially promising other compensating acceptors such as N or Mg need to be explored given this observation of capacitance transients in Fe-doped structures. Overall mitigating this parasitic interface will help improve yield and performance uniformity in fabricated devices.

11:45am EM2+CA+CPS+MS+SE+TF-WeM-16 Investigating Metal Gate-Driven Interfacial Reactions in ALD-Grown Al_2O_3 on $\beta\text{-Ga}_2\text{O}_3$, Joy Roy, Adam A. Gruszecki, The University of Texas at Dallas; Khushabu S. Agarwal, Paolo La Torraca, Karim Cherkaoui, Paul K. Hurley, Tyndall National Institute, University College Cork, Ireland; Chadwin D. Young, Robert M. Wallace, University of Texas at Dallas

$\beta\text{-Ga}_2\text{O}_3$ is a leading candidate semiconductor for next generation power electronics with the potential to outperform GaN and SiC owing to its high breakdown strength paired with low power losses.¹ Integrating a robust gate dielectric and stable oxide interface is critical in leveraging these properties of $\beta\text{-Ga}_2\text{O}_3$.² However, this cannot be achieved without also considering the gate electrodes' reactivity and their influence on oxide properties. This work explores interfacial reactions—particularly those associated with oxygen scavenging—and the resulting variations in gate oxide performance induced by Ni and Ti gate metals in Al_2O_3 on bulk (001) $\beta\text{-Ga}_2\text{O}_3$ substrates.

Interface reactions were analyzed via *in situ* X-ray photoelectron spectroscopy (XPS) in an ultrahigh vacuum (UHV) cluster system. $\beta\text{-Ga}_2\text{O}_3$ samples were scanned as-loaded, after atomic layer deposition (ALD) of ~ 2 nm Al_2O_3 , and a third time following UHV electron beam deposition of Ni or Ti (~ 1 nm) to assess changes in interface chemistries. Additional chemical states in Ga_2O_3 were below the XPS detection limit after oxide and metal deposition. However, an AlO_x (sub stoichiometric) state appeared in Al core levels ($2p$ or $2s$) after introducing Ti. This, along with a TiO_x state in Ti $2p$, may imply oxygen scavenging from Al_2O_3 . While both metals reacted with surface organic residues from metal-organic precursors, Ti exhibits more carbide formation at the gate/dielectric interface. Additionally, MOSCAPs were fabricated with ~ 12 nm Al_2O_3 and 10/100 nm of either Ni/Au or Ti/Au as the gate metal for I-V and C-V characterization. Ni/Au devices showed lower frequency dispersion and over two orders of magnitude lower gate leakage in accumulation than Ti/Au samples, consistent with the XPS findings. Dielectric breakdown strength will be further studied to explore electrical stability of the oxides.

In conclusion, a fundamental understanding of gate metals' influence on interface properties is essential for precisely predicting device behavior in power electronics.

This work was supported by the National Science Foundation (Grant ECCS 2154535) at the University of Texas at Dallas and by Research Ireland (Grant 12/US/3755) at Tyndall National Institute through the US-Ireland R&D Partnership. (Corresponding author: Robert M. Wallace.)

¹ S. J. Pearton, F. Ren, M. Tadjer, and J. Kim. *J. Appl. Phys.* **124**, 220901 (2018).

² C. V. Prasad, and Y.S. Rim, *Mater. Today Phys.* **27**, 100777 (2022).

Plasma Science and Technology

Room 201 ABCD W - Session PS-WeM

Plasma Catalysis and Surface Interactions

Moderator: Sumit Agarwal, Colorado School of Mines, USA

8:00am PS-WeM-1 The Impact of Plasma Enhancement Gasses on Hydrogen Superpermeation Through Palladium Alloy Metal Foil Pumps, Caroline Hufnagel, Vitor Camacho, Colorado School of Mines; Thomas Fuerst, Idaho National Laboratory; Doug Way, Colin Wolden, Colorado School of Mines

The fusion reaction between the hydrogen isotopes deuterium and tritium is the most likely path to enabling fusion energy. The efficient processing of the tritium is critical to the plant operation for fusion energy systems. Metal foil pumps (MFPs) are the leading technology for direct internal recycling (DIR) of hydrogen isotopes from the plasma exhaust in future fusion plants. MFPs rely on the concept of superpermeation, where H atoms generated by a plasma directly absorb into the metal foil, rapidly diffuse, and desorb downstream. To date, studies of superpermeation have predominantly employed pure hydrogen. In practice the plasma exhaust may contain significant levels of plasma enhancement gasses (PEGs, i.e. Ar, Ne, Kr). These inert gasses have metastable states that can enhance plasma density and stability. In this work, we systematically study the impact of PEG addition on the hydrogen superpermeation performance of PdCu and PdAg MFPs

operated at low temperature (< 200 °C). In the case of argon, flux enhancements of up to 60% relative to pure H_2 plasma were observed, with the optimal concentration range being 5-10 % Ar. Performance correlated with the optical emission of the atomic H, and benefits were more appreciable on PdAg than PdCu. Beyond 15% addition plasma enhancement benefits were offset by dilution. Interestingly, the level of permeation enhancement improved with increasing DIR fraction, and potential reasons for this phenomenon are discussed.

Depending on programming this may be a better fit in PS8: Sustainability and Plasmas

8:15am PS-WeM-2 The Impact of Contaminants on Superpermeation Through Palladium Alloy Metal Foil Pumps, Chao Li, Marathon Fusion; Caroline Hufnagel, Colorado School of Mines; Thomas Fuerst, Idaho National Laboratory; Vitor Camacho, Doug Way, Colin Wolden, Colorado School of Mines

The fusion reaction between the hydrogen isotopes deuterium and tritium is the most likely path to enabling fusion energy. The efficient processing of the tritium is critical to the plant operation for fusion energy systems. Metal foil pumps (MFPs) are the leading technology for direct internal recycling (DIR) of hydrogen isotopes from the plasma exhaust in future fusion plants. MFPs rely on the concept of superpermeation, where H atoms generated by a plasma directly absorb into the metal foil, rapidly diffuse, and desorb downstream. To date, studies of superpermeation have predominantly employed pure hydrogen. Though undesired, inevitably MFPs will be exposed to unintentional contaminants such as carbon and oxygen, with consequences for long term durability. In this work, a combination of surface analytical techniques (Auger, XPS) and superpermeation experiments were employed to understand the impact of common contaminants. The critical nature of clean surfaces is first demonstrated through compression experiments using asymmetrically prepared PdCu MFPs. Contamination degrades performance, inhibiting both absorption of superthermal hydrogen on the feed surface and recombinative desorption on the permeate surface, with the latter being more detrimental. Next, sputter-cleaned MFPs were placed in a chamber that had been pre-contaminated with carbon. Upon plasma ignition, the superpermeation rate initially increased before rapidly declining to zero. The initial increase suggests that very small (submonolayer) contamination levels are perhaps beneficial, but would be difficult to control. O_2 plasma exposure could largely restore the performance of carbon-contaminated PdAg MFPs, but proved detrimental to PdCu. Surface analysis techniques are employed to understand the differences between the two alloys.

9:00am PS-WeM-5 in Situ/Operando Diagnostics of Liquids and Catalysts in Contact with Plasmas, Kasidapa Polprasarn, Dihya Sadi, Laboratoire de Physique des Plasmas (CNRS, Ecole Polytechnique, Institut Polytechnique de Paris, Sorbonne Université), France; Darwin Kurniawan, Department of Chemical Engineering, National Taiwan University of Science and Technology, Taiwan; Thomas Orriére, Institut PPRIME (CNRS, Université de Poitiers, ISAE-ENSMA), France; Pankaj Pareek, Faculty of Mathematics, Physics, and Informatics, Comenius University, Slovakia; Francesca Caielli, Karthik Thyagajaran, Institut PPRIME (CNRS, Université de Poitiers, ISAE-ENSMA), France; Mario Janda, Faculty of Mathematics, Physics, and Informatics, Comenius University, Slovakia; Wei-Hung Chiang, Department of Chemical Engineering, National Taiwan University of Science and Technology, Taiwan; Olivier Guaitella, David Pai, Laboratoire de Physique des Plasmas (CNRS, Ecole Polytechnique, Institut Polytechnique de Paris, Sorbonne Université), France

INVITED

Plasma interactions with liquids and solids are at the core of plasma electrochemistry (PEC) and plasma-assisted catalysis (PAC), respectively. To address the need for direct measurements in the plasma-liquid and plasma-catalyst interfacial regions, respectively, we employ an *in situ/operando* approach using multiple diagnostic techniques to study a range of physical and chemical properties at plasma interfaces. The centerpiece of this platform is *in situ/operando* spontaneous Raman microspectroscopy. For a PEC batch reactor in pure water, this technique revealed that the concentrations of aqueous H_2O_2 and NO_3^- at a depth of a few tens of microns from the plasma-liquid interface are greater than in the bulk liquid [1]. We have also successfully performed *in situ/operando* Raman on an electrospray reactor [2]. Here, we will present two case studies of changes to Raman spectra observable only in the presence of plasma. First, for PEC in air plasma-water systems at atmospheric pressure, we will focus on the spectral profile of the -OH stretch band of water and of probe molecules such as NO_3^- . Analysis of -OH stretch indicates that the plasma disrupts the

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hydrogen bonding network of water. To assist in pinpointing the cause, we will examine the broadening of the N-O symmetric stretch mode (ν_1) of NO_3^- at less than 20 μm depth from the plasma-liquid interface. Second, we will present a study of a PAC reactor consisting of a low- to medium-pressure CO_2 plasma in contact with CeO_2 as a catalyst [3]. Tracking of the first- and second-order optical phonons of CeO_2 , as well as O-O bonds in superoxides, yields information on thermal effects and oxygen vacancy formation. Besides Raman spectroscopy, additional *in situ/operando* diagnostics have been employed when monitoring the synthesis of graphene quantum dots by PEC reactors [4]. We tracked their production via photoluminescence (PL) and UV-VIS absorption spectroscopies. Both the PL and absorption signals achieve their peak intensity not at the interface but at a depth of several millimeters. This aligns with liquid flow field measurements by particle image velocimetry, which indicate the presence of a low-velocity zone at this depth.

References

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- [3] C. A. Garcia-Soto, E. Baratte, T. Silva, V. Guerra, V. I. Parvulescu, and O. Guaitella, *Plasma Chemistry and Plasma Processing* **1** (2023).
- [4] D. Kurniawan, F. Caielli, K. Thyagarajan, K. K. Ostrikov, W.-H. Chiang, and D. Z. Pai, *Nanoscale* **16**, 15104 (2024).

9:30am PS-WeM-7 Catalytic Deconstruction Product Tunability Through Atmospheric Air Plasma Pre-Treatment, Aunic Goodin¹, North Carolina State University; Tridip Das, California Institute of Technology; Shashwata Chakraborty, Sujoy Bepari, Debasish Kuila, North Carolina Agricultural and Technical State University; William Goddard, California Institute of Technology; Steven Shannon, North Carolina State University

The large amount of waste plastic produced is becoming a more prominent concern, as production of single use plastic continues to increase. Catalytic deconstruction is viewed as one potential method for deconstruction of waste plastics into usable material. In this work, we use an atmospheric pressure air plasma to pre-treat polypropylene, to better facilitate reaction with the catalyst. It has been found that this pre-treatment can tune the products of the catalytic deconstruction to change the distribution of products as needed.

Plasma treatment is performed in a sealed vial with a rubber septum cap. A steel hypodermic needle is used to both deliver synthetic air and apply a high voltage in a pin-to-cup configuration. The grounding cup is made up of a copper pipe soldered to a copper plate. The vial is placed the copper "cup" with the whole assembly surrounded with a 3D printed holder to prevent arcing from the high voltage to ground. A second hypodermic needle is then used to allow air to escape. Treatments range from 15-120 minutes at 30-40 kV (6-34 W), a frequency of 450 Hz, and a flow rate of 0-400 SCCM.

The catalyst used was a ZSM-5/SBA-15 composite catalyst, with the ZSM-5 added into the SBA-15 structure during its production. This was reacted with an equal ratio of catalyst to plastic at 400 °C with a constant flow of 1.5 SCCM of N_2 . This treatment was continued until products were no longer detected using gas chromatography mass spectrometry (GC/MS).

The best total conversion of 94% was observed with a 30 kV treatment for 30 minutes, at a flow rate of 110 SCCM, with a major product of propene (66%). The major product, as well as overall product distribution can be changed by performing the plasma treatment under different voltage, time, and flow rate.

Molecular dynamics simulations have shown the mechanism of the plastic degradation in plastic to be due to a reaction with ozone. Ozone measurements were taken to investigate different conditions. The plasma and product plastics will be further investigated through MALDI-TOF and OES measurements to better understand the conditions needed to produce specific products. The mechanism can then be better illuminated to understand how this could be applied to catalytic deconstructions with different scaled up or different plasma systems.

Through variations in plasma pre-treatment, catalytic deconstruction can be tuned to produce different product distributions. While this cannot shift the total distribution of products, it could increase the viability of catalytic deconstruction despite market fluctuations.

This material is based upon work supported by U.S. Department of Energy (DOE) no. DE-EE0009945.

11:00am PS-WeM-13 Gas-Phase Plasma Synthesis as a Method for Producing Nanomaterials with Special Properties, Hartmut Wiggers, University of Duisburg-Essen, Germany INVITED

Gas phase synthesis has been an established process for the production of functional nanoparticles for decades. The manufacturing processes used are dominated by flame processes, whereby mostly oxide materials are produced. However, with the increasing use and storage of renewable energies for industrial processes, there is a growing need for new types of materials that can often no longer be produced using flame-based processes alone. Gas-phase plasma synthesis offers new possibilities here, as an essential prerequisite of flame processes – the use of a reactive gas mixture consisting of fuel and oxidizer – is not required, which opens up access to oxide-free materials in particular. At the same time, plasma processes can be operated over a wide pressure and temperature range, which can be used for setting specific temperature-time profiles.

Microwave and ICP plasma processes are particularly suitable for the production of high-purity materials in technically relevant quantities, as the coupling of energy into the gas phase process is contactless. Using the example of selected materials based on carbon (especially few-layer graphene, FLG) and silicon, it is shown how specific materials for applications in the field of energy conversion and storage as well as for catalysis can be produced using plasma processes. Starting from the first steps of nanoparticle formation, possibilities are shown to further develop the synthesis up to the production of functional composite materials as well as single-atom catalysts.

11:30am PS-WeM-15 Interaction of Etching Plasmas with Polyurea Films deposited by Molecular Layer Deposition for Surface and Sidewall Passivation, Wallis Scholl, Colorado School of Mines; Thorsten Lill, Mingmei Wang, Wenyu Zhang, Harmeet Singh, Lam Research Corporation; Sumit Agarwal, Colorado School of Mines INVITED

Molecular layer deposition (MLD) is a vapor-phase process of alternating surface reactions which can be used to grow organic and hybrid organic-inorganic films. MLD films have several potential applications in semiconductor processing, including as conformal coatings or as a protective layer during plasma etching. However, the use of MLD in practical applications is hindered by the complexity of the growth mechanism. Some bifunctional molecules will react to the film surface with both of their functional groups, thereby consuming reactive sites and lowering the growth per cycle (GPC). Molecules can also be added to the film through physisorption to the growth surface, which adds new reactive sites to the film. Further, we have found that different MLD precursors can have different rates of double reaction and physisorption. Molecule chain length, flexibility, and hydrogen bonding must be carefully considered when selecting an MLD chemistry, as they all affect the film growth. The physisorption contribution to film growth can also be promoted by lowering the deposition temperature, which results in an increase in GPC. However, films with a high degree of physisorbed material can be unstable, as this weakly physisorbed material can later diffuse out.

In this work, toluene diisocyanate (TDIC) and ethylene diamine (ED) were used as precursors for MLD of polyurea, which was grown on top of a SiO_2 starting surface. The films were then exposed to a HF plasma to evaluate their interactions with reactive plasma. During initial HF exposure, only the MLD film was etched, while the underlying SiO_2 was protected. As plasma exposure continued, eventually removal of the MLD film stopped and the SiO_2 was selectively etched. The length of the SiO_2 etch delay was found to be highly dependent on the morphology of the MLD film; films with a higher degree of interconnectivity were better able to prevent F from diffusing through the film to access the SiO_2 . For example, depositing at a higher deposition temperature, which reduces physisorption into the film, resulted in a higher etch resistance. Ion bombardment was also found to increase film interconnectivity, thereby preventing SiO_2 etch. Additionally, we deposited MLD films on high aspect-ratio (HAR) trenches to evaluate the film conformality. While the analogous process of atomic layer deposition (ALD) requires very high doses to provide necessary diffusive flow into the trench, we found that during MLD of polyurea, films are deposited conformally using the saturation doses for a flat surface. We've attributed this to film reconstruction during MLD, which includes migration of physisorbed molecules through the film.

¹ JVST Highlighted Talk

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12:00pm PS-WeM-17 Characterization and Operation of a 2-D Plasma Reactor for Methane Pyrolysis, *Huseyin Ozturk, Andac Yagiz Kaya, Necip Berker Uner*, Middle East Technical University, Turkey

Methane pyrolysis is breaking the C-H bonds of methane in an O₂-free atmosphere. This process can synthesize H₂ directly from natural resources along with solid carbon with no carbon dioxide emissions. Using an atmospheric plasma for methane pyrolysis is attractive since the process is fully electrified, is completely intermittent with very rapid turn-on/off times and requires no consumables. However, the number of plasma reactors demonstrated for methane pyrolysis is very limited, and the application of chemical reaction engineering fundamentals to the design and operation of these reactors is currently absent in literature.

This talk focuses on the design and characterization of a unique, 2-dimensional, gliding arc (GA) plasma reactor for conducting methane pyrolysis at atmospheric pressure to produce carbon black and hydrogen. The GA is a *warm* plasma, and it combines high-temperature thermal conversion with non-equilibrium electron-impact chemistry. The reactor flow was confined to be unidirectional such that nearly all the gas was put in contact with the GA, thereby increasing flow utilization in the reactor, as verified by computational fluid dynamics. This resulted in improvements on the experimentally measured residence time distribution, and GA formation was visually and electrically analyzed in the confined flow geometry under direct-current excitation. Temperature measurements and heat transfer modeling indicated that the thermal efficiency of the reactor can be made to be as high as 50%, meaning that half of the electrical energy was converted to heating the gas, whereas the rest was dissipated into the ambient through the reactor body. This presentation will elaborate on CH₄ conversion, as well as continuous collection and ex-situ characterization of the carbon product, primarily through Raman and FTIR spectroscopy. The effect of using argon in the mixture and the influence on reactor materials to CH₄ conversion and H₂ selectivity will also be presented.

Advanced Surface Engineering Room 209 F W - Session SE-WeM

Advanced Surface Treatments for Enhanced Material Performance

Moderator: Diana Berman, University of North Texas

8:00am SE-WeM-1 Tools for High-Throughput Autonomous Materials Discovery and Development for the Surface Engineer, *Christopher Muratore*, University of Dayton INVITED

The talk highlights automated experimental tools enabling synthesis and characterization of hundreds of samples per day. This approach, where experimentation is much faster than simulation has the potential to flip the traditional 'order of operations' for materials discovery where experiment feeds model during initial iterations. One high-throughput format relies on scanning lasers with broad ranges of power, scan rates, and focal positions to induce physical and chemical transformations within materials. Laser heating parameters may be set to approximate quasi-equilibrium heating as in a furnace, or induce extreme heating and cooling rates, thereby broadening the range of accessible compositions and crystal structures dictated by kinetics of both chemical reactions and crystallization. Deposition tools, such as our magnetron sputtering system outfitted with 36 different source materials may also be used to create a broad range of compositions on the sample surface. Once a combinatorial sample with a desired range compositions and laser illumination conditions is processed, it can be manually or autonomously subjected to the combination of high-throughput characterization tools required for evaluation of the properties specified by the user. Autonomous systems enable users to specify a desired property and the system iterates processing and characterization data to 'make decisions' about optimization of conditions to realize the user-specified input. For example, an automated Raman spectroscopy system enables rapid collection of key data points (grain size, defect density, thickness, etc.) for technologically important optical, electronic, and energy materials. Some specific case studies include fundamental kinetics studies showing migration-limited crystallization kinetics amorphous materials can be directly observed. Pre-cursor materials for downstream processing can be converted directly into reaction intermediates with the appropriate non-equilibrium laser energy input to reduce process activation energy and process temperature required for high-quality materials. For photocatalysis materials rapid, non-equilibrium

process conditions were identified demonstrating optimized performance with mixtures of phases.

8:30am SE-WeM-3 Hydrophobic and Hydrophilic Metallic Coatings: Their Sputter Depositions and Applications, *Jinn P. Chu*, National Taiwan University of Science and Technology, Taiwan

The talk will cover two types of metallic coatings with extreme properties: hydrophobicity and hydrophilicity.

First, an introduction to a low-friction hydrophobic metallic glass (MG) coating and its applications will be provided. This amorphous multicomponent coating, fabricated via sputter deposition, exhibits typical glass characteristics, such as a glass transition temperature upon heating. The MG coating has been successfully applied in various fields, including medical tools. This non-stick MG coating is intended to replace easily peeled-off teflon coatings, such as polytetrafluoroethylene (PTFE).

On the other hand, for the superhydrophilic coating, a 316 stainless steel layer is sputtered onto various substrates, resulting in a water contact angle of approximately 10 degrees on the coated surface. This coating also demonstrates antifouling and underwater superoleophobic properties, making it advantageous for use in separation membranes for oil/water emulsions. Moreover, it has proven highly effective in enhancing electrochemical responses in electrodes used for electrochemical sensors and supercapacitors.

8:45am SE-WeM-4 Surface Engineering of Organic Nm-Thick PEDOT:PSS Films for Enhanced Electrical Conductivity, *Aaron DiFilippo*, Virginia Tech; *Amrita Chakraborty*, Virginia Tech, United States Minor Outlying Islands (the); *Marius Orlowski*, Virginia Tech

We report on enhancing the electrical conductivity of Poly(3,4-ethylenedioxythiophene) Polystyrene Sulfonate (PEDOT:PSS) using various surface engineering methods, including acid treatment, topical doping with Cu and Ag nanoparticles, multilayer PEDOT:PSS deposition, and graphene incorporation. Our investigations reveal that optimizing multilayer deposition combined with nitric acid surface treatment yields superior results compared to alternative methods involving metal nanoparticles and graphene. This approach not only significantly enhances conductivity but also offers improved stability, reduced errors, and cost-effectiveness. Key optimization parameters, such as spinning speed, etchant concentration, and etching time, were identified as critical to achieving these outcomes. From all acids tested, nitric acid-treated multilayer PEDOT:PSS demonstrated a remarkable reduction in sheet resistance, from 1 MΩ/sq to 7 Ω/sq, corresponding to an increase in electrical conductivity from 0.18 S/cm to 15,699 S/cm—an improvement of over 10⁵ times. Topical doping with Cu and Ag nanoparticles (30-90 nm) also improved conductivity, though less effectively than nitric acid treatment. Notably, Cu nanoparticles were as effective as Ag in topical doping, unlike bulk doping, where Cu oxidizes in aqueous solutions. This makes topical doping a versatile and cost-effective alternative, particularly for applications requiring surface metal nanoparticles, such as conductive dendrites for resistive RAM.

While each method individually enhanced conductivity, combining them did not yield significant additional improvements. The optimized nitric acid treatment, involving nine PEDOT:PSS layers, achieved the highest conductivity enhancement. However, acid-treated PEDOT:PSS exhibits a modest, self-limiting degradation in conductivity over time, stabilizing after a few days. This behavior suggests that while the initial enhancement is substantial, long-term stability requires further investigation. The study underscores the importance of optimization parameters and highlights the potential of these methods for advancing PEDOT:PSS-based technologies in flexible electronics, energy devices, and beyond. The surfaces have been characterized with Atomic Force Microscopy (AFM)X-ray diffraction (XRD), and optical microscopy in terms of surface roughness and surface composition. We also address film aging to mitigate reliability issues induced by ambient conditions.

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9:00am **SE-WeM-5 Atomic Oxygen-Resistant Metal Oxide Coatings for Space Operations in Low-Earth Orbit, Joslin S. Prasanna¹², Javier Meza-Arroyo, Minglei Sun, Chase Hazboun, Department of Materials Science and Engineering, University of Texas at Dallas; Fernando Quintero-Borbon, Centro de Investigación en Materiales Avanzados S.C. (CIMAV), Unidad Monterrey, Mexico; William Vandenberghe, Julia Hsu, Robert M. Wallace, Rafik Addou, Department of Materials Science and Engineering, University of Texas at Dallas**

Space operations in low-earth orbit (LEO) are hindered by the effect of atomic oxygen (AO) on spacecraft [1]. Coatings on spacecraft suffer loss of material due to erosion from attack by AO, thereby increasing drag and causing vehicles to drift from their operational orbit. Consequently, frequent thrust maneuvers are required to correct this position, consuming fuel, and ultimately limiting the duration of service. This raises the need to develop low-drag coatings for spacecraft that are resistant to AO and extend the life of space missions. Atomic-layer deposition (ALD) is an effective technique to deposit extremely conformal coatings of high quality and free from pinholes [2]. It also gives exceptional control over thickness down to the angstrom scale. Solution synthesis performed by the sol-gel method can scale the deposition process to deposit thicker films over larger areas.

In this work, we investigated the use of metal oxides (Al_2O_3 and TiO_2) deposited by ALD and sol-gel techniques as AO-resistant, low-drag coatings to protect conventionally used materials like Kapton and other polymers. SiO_2 and Kapton films were also studied alongside the metal oxide films for reference. Two different ALD recipes were tested for growing TiO_2 , and one recipe for Al_2O_3 . The films were characterized, both as deposited and after O_2 plasma exposure, by X-ray photoelectron spectroscopy (XPS) for chemical analysis, ellipsometry for thickness measurement, and atomic force microscopy (AFM) for surface roughness measurement. This investigation is further assisted by theoretical modeling of drag using experimentally determined surface structures. The drag simulations will be used to identify the key parameters influencing drag performance. Our study showed that Al_2O_3 deposited by ALD and sol-gel techniques displayed excellent resistance to O_2 plasma. The TiO_2 films showed more degradation but still far outperformed the Kapton and SiO_2 reference films, proving to be promising materials for AO-resistant coatings in LEO.

This work is supported by DARPA Materials Investigation for Novel Operations in Space (MINOS).

[1] S.W. Samwel et al., Space Res. J., 7(1), 1-13, (2014)

[2] T.K. Minton et al., Appl. Mater. Interfaces, 2(9), 2515-2520, (2010)

9:15am **SE-WeM-6 Reducing Tribological Run-in Through Morphology Control: A Dual-Layer Approach for Improved Environmental Insensitivity and Tribological Performance, Steven Larson, Alex Mings, Tomas Babuska, Ping Lu, Jon Vogel, Michael Dugger, John Curry, Sandia National Laboratories**

Molybdenum disulfide (MoS_2)-based composite coatings are widely utilized in the aerospace and defense industries to reduce friction, prevent galling, and enhance wear resistance. These coatings are often grown as composites with various metals (Ni, Ti, Al, Pb, Au, WSe) and nonmetals (Sb_2O_3 , PbO , C). A commonly used composition incorporates antimony oxide (Sb_2O_3) and gold (Au) into the MoS_2 matrix to promote increased density and improve wear life by amorphization. However, these additions significantly compromise the aging resistance of MoS_2 , resulting in increased friction during both run-in and dwell-time phases.

In this presentation, we demonstrate a dual-layer MoS_2 sputtered coating designed to mitigate the effects of oxidation during long-term storage and short-term exposure to highly oxidizing environments, effectively transforming the traditionally water-sensitive MoS_2 into an environmentally insensitive coating. In addition to enhancing oxidation resistance, these structures facilitate a reduction in run-in friction, reducing initial cycle friction to near run-in levels (zero run-in coatings). We correlate deposition parameters with plasma probe measurements (retarding field energy analyzer), thin film material properties (density, crystallinity, hardness, modulus, and stoichiometry), and tribological performance (friction, run-in behavior, and wear rate) of the films. The resulting thin film stacks reduce initial friction after aging by nearly 300%, exhibiting negligible transient friction behavior (run-in) while maintain ultra-low wear rates.

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9:30am **SE-WeM-7 Optimizing Low-temperature MAX-phase Ti_2AlN Synthesis in Reactive TiAIN Multi-layer Thin Films, Moses Nnaji³, David Tavakoli, Georgia Institute of Technology, USA; Dale Hitchcock, Savannah River National Laboratory; Eric Vogel, Georgia Institute of Technology, USA**

$\text{M}_{n+1}\text{AX}_n$ phases are a class of layered nanolaminates where M represents a transition metal, A represents a group 12-16 element, and X represents carbon or nitrogen. These $\text{M}_{n+1}\text{AX}_n$ phases, or “MAX-phases”, often boast a novel combination of metal and ceramic properties, including thermal and electrical conductivity, machinability, thermal shock resistance, and high-temperature integrity. Consequently, MAX-phase thin films have attracted interest for use in high-temperature protective coatings, Ohmic contacts, and low friction systems. However, the high temperatures ($>700^\circ\text{C}$) needed to form their complex crystal structures serve as a persistent bottleneck for meaningful adoption of MAX-phase coatings on sensitive substrates. Reducing the substrate temperature needed to form MAX-phase films is necessary to improve their viability in select applications, and thus improve the performance of said applications.

Magnetron sputtering is a common technique for MAX-phase thin film synthesis, and MAX-phase synthesis via low-temperature sputtering of reactive multi-layers and subsequent high-temperature annealing has also been reported. In this context, reactive multi-layers are thin film structures which can exploit exothermic reactions as a form of stored chemical energy. These reactions are not spontaneous at low substrate temperatures, but become favorable at higher temperatures and provide additional energy to the film. This phenomenon effectively results in phase transitions at decreased substrate temperatures. Thus, tailoring the thin film deposition process to yield multi-layers with high reactivity may help in forming MAX-phases at desirably low temperatures.

MAX-phase synthesis via reactive multi-layers is established, but work explicitly addressing the impact of the reactive multi-layer mechanism and phase composition on MAX-phase formation temperature is limited. Thus, comparing the behavior of composite multi-layers with different reactivities (e.g., containing constituent materials with different free energies and enthalpy) can provide insight towards minimizing the annealing temperature needed for MAX-phase synthesis. In this work, various techniques, including *in-situ* X-ray diffraction and differential scanning calorimetry, will be used to extensively characterize the evolution of MAX-phase Ti_2AlN as a function of annealing temperature in sputtered composite Ti-Al-N films. *In-situ* analysis of Ti/AlN, TiN/TiAl, and single-layer TiAlN thin film morphologies will aid optimization of processes that yield Ti_2AlN films at especially low temperatures.

9:45am **SE-WeM-8 Design of 2D Material-Based Coatings for Superlubricity in Sliding and Rolling Contacts, Diana Berman, Ali Macknojia, Aditya Ayyagari, University of North Texas**

Friction and wear-related failures remain the greatest problems in today's moving mechanical components, from microelectromechanical devices to automotive assemblies and to biological systems. The critical need to reduce and eliminate the tribological failures constitutes the necessity for continuous search of novel materials and lubrication solutions. In this presentation, we demonstrate an experimental pathway to yield superlubricity in rolling-sliding contact conditions using MXene-based solid-lubricant materials. The material's compression and inter-layer shearing result in material reconstruction to pose superlubricity. High-resolution transmission electron microscopy analysis, complemented by multi-scan Raman spectroscopy showed the formation of a robust amorphous tribolayer. This demonstration is expected to not only advance the applied aspects in the development of oil-free solid lubricants but also push the boundaries of fundamental understanding of materials' structure-property relations across physical states.

11:00am **SE-WeM-13 Physics of Sample Charging During X-Ray Photoelectron Spectroscopy: Insights from Experiments with Thin Film Insulators, Grzegorz (Greg) Greczynski, Linköping University, Sweden**

INVITED

Sample charging during X-ray photoelectron spectroscopy (XPS) measurements of poorly conducting samples is a widely recognized concern that seriously complicates analysis of chemical bonding. The high complexity owing to many instrument- and sample-determined variables

¹ ASEd Rising Star

² JVST Highlighted Talk

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involved in the process is likely responsible for the fact that no comprehensive theory of charging exists. The present study aims to describe the development of charging for the case of thin insulating films supported on conducting substrates. Such systems are particularly well suited for studies of charging phenomena as they provide unique opportunity to separate effects that operate on different length scales and allow to investigate the role of charge supplied from the bottom contact. Two inherently insulating oxides, SiO_2 and WO_3 , with the thickness varying by more than three orders of magnitude (from 1 to 5000 nm) are chosen to serve as model systems for insulators with respectively low and high X-ray-induced conductivity. The key role of low-energy secondary electrons (SE), X-ray penetration depth, sample work function, and the insulator SE yield in the development of surface charging is demonstrated. Based on these findings, a conceptual model is presented to serve as a starting point for the interpretation and discussion of charging phenomena in specific cases. Although the study is based on thin films the conclusions give insights into critical factors that govern charging phenomena in any other types of insulating samples.

11:30am SE-WeM-15 Femtosecond Laser Ablation (fs-LA) XPS Depth Profiling for Surface Engineering. *Mark Baker, Charlie Chandler, University of Surrey, U.K.; Simon Bacon, Dhilan Devadasan, Thermo Fisher Scientific, UK; Oliver Parlour, Steve Hinder, University of Surrey, U.K.; Tim Nunney, Richard White, Thermo Fisher Scientific, UK*

For corrosion and wear resistance applications, XPS depth profiling is the most widely used analytical technique for chemical analysis of thin films, coatings and other surface treatments. The technique also provides important chemical information on corrosion and wear products, important in understanding degradation mechanisms. Traditional XPS sputter depth profiling has its advantages, such as good depth resolution, but leads to incorrect chemical compositions and chemical state information being recorded in the profile for many materials, due to ion beam induced damage. Sputtering is also a relatively slow process and the profiling depth is limited to approximately 5 μm for practical purposes. A new approach has recently been developed in which XPS depth profiles are generated through femtosecond laser ablation (fs-LA) rather than sputtering. This new methodology avoids chemical damage and has the ability to profile to much greater depths (many 10s microns) due to the effective instantaneous ablation process and the ability to easily vary the amount of material removed per pulse through changing the laser energy [1]. Using a 1030 nm wavelength, 160 fs pulsed laser, fs-LA XPS depth profiles will be shown for: (i) single and multi-layer thin films, coatings and other surface engineering processes employed to enhance corrosion and wear resistance; (ii) oxidised/corroded surfaces, demonstrating the capabilities of this new technique for surface engineering applications.

[1] M.A.Baker et al, *Applied Surface Science* **654** (2024) 159405

11:45am SE-WeM-16 In Situ SEM Study of Graphene Rheotaxy: Growth on Molten Metals. *Kristýna Bukvišová, CEITEC; Thermo Fisher Scientific, Czechia; Radek Kalousek, Brno University of Technology, Czechia; Jakub Zlámal, CEITEC; BUT, Czechia; Marek Patočka, BUT, Czechia; Suneel Kodambaka, Virginia Tech; Jakub Planer, CEITEC, Czechia; Vojtěch Mahel, Thermo Fisher Scientific; BUT, Czechia; Daniel Citterberg, CEITEC, Czechia; Libor Novák, Thermo Fisher Scientific, Czechia; Tomáš Šikola, Miroslav Kolíbal, CEITEC; BUT, Czechia*

Rheotaxy -- growth of crystalline layers on liquid substrates -- has been used to grow spatially-periodic self-assembled domains of graphene on molten metals such as Cu [1]. While earlier studies of graphene rheotaxy have identified the optimal growth parameters required for the growth of highly ordered domains, the mechanisms leading to self-assembly are not well understood [2,3]. Here, we present *in situ* scanning electron microscopy (SEM) studies of graphene growth via chemical vapor deposition of ethylene on molten Cu and Au surfaces at temperatures T between 1073 K and 1390 K.

The graphene layers are grown on solid and molten Cu ($T_{\text{m,Cu}} = 1357$ K) in an ultrahigh vacuum (UHV) SEM and on solid and molten Au ($T_{\text{m,Au}} = 1336$ K) in an environmental SEM equipped with a microReactor [4]. We observe *in situ* the nucleation and growth of graphene domains, changes in their shapes and sizes as a function of deposition time, ethylene pressure, and the metal composition (Au or Cu), its state (solid or liquid), and temperature. From *ex situ* Raman spectroscopy data, we confirm that the as-deposited layers are graphene. Using *in situ* high-temperature atomic force microscopy (AFM) operated at ~ 1300 K, we measure the surface curvature of graphene. *In situ* SEM images acquired during the deposition of graphene reveal that graphene domains oscillate and self-assemble. We

follow the dynamics of graphene domains on molten metal surfaces, measure amplitudes of domain fluctuations, and quantitatively determine the rate-limiting mechanisms controlling the graphene growth on solid and liquid Au and Cu surfaces. From the data, in combination with density functional theory (DFT) calculations and continuum modeling, we show that the graphene domain oscillations lead to self-assembly and are due to Casimir-like effect of surface undulations of the liquid metal [5].

References:

- [1] Geng, D. et al. PNAS 2012, 109, 7992-7996.
- [2] Tsakonas, C.; Dimitropoulos, M.; Manikas, A. C.; Galiotis, C. *Nanoscale* 2021, 13, 3346-3373.
- [3] Jankowski M. et al., *ACS Nano* 2021, 15, 9638-9648.
- [4] Novák, L., Wandrol, P., Vesseur J. R. *Microsc. Microanal.* 2020, 26 (S2), 1144-1145.
- [5] Bukvišová, K. et al. arXiv:2503.04327.

12:00pm SE-WeM-17 Optical Metasurfaces in Iridium for High-Temperature Applications. *Zachary Kranefeld¹, T. Pan Menasuta, Kareena Guness, Kevin Grossklaus, Thomas Vandervelde, Tufts University*

Optical metasurfaces are gaining attention as a new technology because they can perform the tasks of several traditional optical elements simultaneously, while at a fraction of the size and weight. Their performance is dictated by the sub-wavelength structured surface, which also makes them extremely sensitive to morphology changes after fabrication. Oxidation and plastic deformation (edge rounding) are two dominant types of surface changes that occur in high-temperature environments, which limits optical metasurfaces from being a useful technology for those applications. We have pioneered a method of fabricating an optical metasurface into iridium films. Iridium is a refractory metal which is stable in these types of environments. The lack of reactivity, extremely high melting temperature, and high hardness are what makes iridium the best choice for the application. However, these features also present major challenges for lithographic pattern transfer at the nano-scale. The optical metasurface fabricated in our work was a selective emitter in the MWIR for a thermophotovoltaic system. The design process and all of the fabrication techniques we attempted are described, as well as the characterization of the final device.

Surface Science

Room 209 CDE W - Session SS-WeM

On Surface Reactions

Moderators: *Nathan Guisinger, Argonne National Laboratory, USA, Yuan Zhang, Old Dominion University*

8:00am SS-WeM-1 Surface and Interface Induced Properties of Low-dimensional Materials: First Principle Simulations. *Shixuan Du, Institute of Physics, Chinese Academy of Sciences, China* **INVITED**

Two-dimensional (2D) materials, with their atomic-scale thickness and dangling bonds free surfaces, provide a unique platform for precisely modulating material properties via surface or heterointerface engineering. These approaches not only enhance existing properties but also induces novel emergent phenomena. In this report, I will talk about the chemical reactions happened on surfaces and the corresponding activation enhanced by the adsorption of the precursor molecules at specific site. Second, the coupling of multiple order parameters in 2D monolayers and bilayers will be discussed. The coupling allows for the manipulation of properties such as spin polarization, electronic band topology, and valley polarization. Finally, I will talk about the construction of electride-metal heterostructure and its application in ammonia synthesis.

References:

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- [3] Zhang Y.-F.; Guo H. et al. *Adv. Funct. Mater.* 2024, 34, 2410240.
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¹ ASED Rising Star

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8:30am **SS-WeM-3 In situ XPS Study of Pt-Grafted g-C₃N₄ as a Water-Splitting Photocatalyst**, *Yu-Bin Huang*, National Synchrotron Radiation Research Center, Taiwan; *Ying-Huang Lai*, Department of Chemistry, Tunghai University, Taiwan; *Bo-Hong Liu¹*, National Synchrotron Radiation Research Center, Taiwan

The generation of hydrogen through solar-light-driven water splitting has acquired significant research interest, owing to the abundant availability of water as a raw material and the virtually limitless energy provided by sunlight. Graphitic carbon nitride (g-C₃N₄) has emerged as a promising catalyst due to its cost-effectiveness and eco-friendly characteristics.¹ When metal atoms are grafted onto g-C₃N₄, the chemical properties of the resulting metal/g-C₃N₄ composite can be optimized to enhance catalytic performance. Among various analogs, the single-atom Pt / g-C₃N₄ composite demonstrates exceptional catalytic reactivity.² This enhanced performance can be attributed to the metal-to-ligand charge transfer, which shifts the absorption spectrum toward the solar energy maximum. Additionally, the isolated Pt atom serves as a redox active site, significantly improving reaction kinetics.

In this presentation, we report an Ambient Pressure X-ray Photoelectron Spectroscopy (APXPS) investigation of Pt-grafted g-C₃N₄ under the conditions of photocatalytic water splitting. The binding energy shifts observed upon exposure to solar light provide insights into the charge transfer dynamics between the Pt and the g-C₃N₄. Furthermore, the presence of water vapor during illumination induces changes in Pt, C, and N spectra, suggesting the existence of surface adsorbates and/or surface reaction intermediates. The work function shift of the catalyst is monitored through gas phase peaks under the reaction condition. These findings deepen our fundamental understanding of the mechanisms underlying g-C₃N₄-based water-splitting catalysts at the atomic level, providing valuable guidance for the development of g-C₃N₄-based photocatalytic systems.

References:

1. Zheng, Y.; Lin, L.; Wang, B.; Wang, X., Graphitic carbon nitride polymers toward sustainable photoredox catalysis. *Angewandte Chemie International Edition* **2015**, *54* (44), 12868-12884.
2. Kuang, P.; Wang, Y.; Zhu, B.; Xia, F.; Tung, C. W.; Wu, J.; Chen, H. M.; Yu, J., Pt single atoms supported on N-doped mesoporous hollow carbon spheres with enhanced electrocatalytic H₂-evolution activity. *Advanced Materials* **2021**, *33* (18), 2008599.

8:45am **SS-WeM-4 Hydrogen-Induced Surface Chemistry of Copper Boride on Cu(111)**, *Jennifer Sanchez*, Kevin Sutherland, University of Texas at San Antonio; *Abdullah Al-Mahboob*, Brookhaven National Laboratory; *Fang Xu*, University of Texas at San Antonio; *Dario Stacchiola*, Brookhaven National Laboratory

A new type of 2D boron-based materials has potential applications in a variety of fields including energy, devices, and catalysis. However, the material needs to be physically stabilized by a single crystal substrate and is chemically unstable. When Cu(111) is used as the substrate, there is a debate on whether borophene or copper boride is formed. In this work, we present results to identify the chemical identity of the boron-formed layer on Cu(111) and further study the reduction by atomic hydrogen as a strategy to stabilize the formed 2D boron materials. Scanning tunneling microscopy (STM) and low-energy electron diffraction (LEED) resolve the surface structure. *In-situ* X-ray photoelectron spectroscopy (XPS) identifies Cu-B bonding, and low-energy electron microscopy intensity-voltage (LEEM-IV) measurements reveal the work-function shift, indicating strong evidence of copper boride formation. We find that the copper boride surface readily reacts with atomic hydrogen, suggesting new opportunities to influence surface chemistry and explore catalytic functionality.

9:00am **SS-WeM-5 DFT Study of Transition-Metal Doping in Ni(OH)₂/NiOOH Catalysts for Enhanced Urea Oxidation**, *Qiu Jin*, *Matteo Garcia-Ortiz*, School of Chemical, Biological, and Environmental Engineering, Oregon State University; *Liney Árnadóttir²*, School of Chemical, Biological, and Environmental Engineering, Oregon State University. Physical and Computational Sciences Directorate, Institute for Integrated Catalysis, Pacific Northwest National Laboratory

Urea is commonly found in agricultural runoff and wastewater, where it can disrupt nutrient cycles and harm aquatic ecosystems. Urea is also a promising sustainable energy source for fuel cells and hydrogen generation through electrochemical urea oxidation (UOR). Identifying suitable catalyst

material for UOR is challenging due to a complex six-electron transfer mechanism, with high overpotential, and competition with the oxygen evolution reaction (OER). Here we use density functional theory (DFT) calculations to investigate how five metal dopants (Mn, Fe, Co, Cu, Zn) influence UOR activity on basal-plane sites of β -NiOOH, the phase transition from β -Ni(OH)₂ to catalytically active β -NiOOH, and the UOR-OER selectivity.

We show that doping β -Ni(OH)₂ accelerates surface dehydrogenation, facilitating its transformation into the active β -NiOOH phase. Mn and Fe doping also enhances dehydrogenation and reduces the Gibbs free energy of UOR, promoting reaction efficiency. On the other hand, Cu doping reduces UOR activity and has little effect on the phase transition. Additionally, Mn increases the OER limiting potential, benefiting the competition between UOR and OER while Cu lowers the OER overpotential, reducing the potential window of higher UOR activity. These insights elucidate the interplay between dopants, phase stability, and reaction selectivity, advancing the design of high-performance catalysts for urea-rich wastewater treatment and energy conversion technologies.

9:15am **SS-WeM-6 Visualizing Self-Metalation Mediated Cyclodehydrogenation of a Nonplanar Tetrabenzoporphyrin Molecule by Tip-Enhanced Raman Spectroscopy**, *Soumyajit Rajak³*, *Nan Jiang*, University of Illinois, Chicago

Opto-electronic properties of functional molecular materials are controlled by local nanostructures constructed by the molecular arrangements at the nanoscale and their local chemical environment. Metal surface-supported physicochemical transformations facilitate the tuning of structural and electronic properties of functional materials. To obtain a higher degree of control over the reaction outcome, submolecular scale characterization of the chemical intermediates and their local environment is required. Determining the real-space surface adsorbed configurations of molecules is challenging using ensemble-averaged surface science techniques. Again, probing the effect of the local environment of chemical species is challenging because the spatial resolution of conventional optical spectroscopic techniques is limited by the diffraction limit of light. Coupling light with plasmonic nano-objects creates highly localized surface plasmons (LSPs), which allows us to break the diffraction limit. Herein we explore tetraphenyl-tetrabenzoporphyrin molecules as one of the most widely studied model molecules in organic optoelectronics for modern-age electronic device applications and catalysis. We present a combined topographical and chemical analysis of different surface-adsorbed configurations and surface-sensitive arrangements of a tetrabenzoporphyrin molecule and their chemical reactivity on a metal surface using angstrom-scale resolution scanning tunneling microscopy (STM) and ultra-high vacuum tip-enhanced Raman spectroscopy (UHV-TERS). Low temperature (77K) scanning tunneling microscopic images and localized surface plasmon resonance enhanced Raman signals reveal different adsorbate configurations of molecular entities and their thermal reaction products with a fundamental view of adsorbate-substrate binding interactions. The atomic scale insights obtained into the local environment enable precise control over the fabrication of molecules with tailored optoelectronic properties.

9:30am **SS-WeM-7 Band Engineering Low Energy States in 1D and 2D Carbon Nanomaterials**, *Felix Fischer*, UC Berkeley INVITED

Our research focuses on the rational design, deterministic assembly, and detailed investigation of the physical phenomena emerging from quantum confinement effects in carbon nanomaterials. We pursue a highly integrated multidisciplinary program, founded on synthetic bottom-up approaches toward functional materials with precisely defined structure. We control their assembly into hierarchically ordered architectures and evaluate inherent physical properties using modern scanning probe techniques cross multiple length, time, and energy scales.

Here we describe two new classes of low-dimensional carbon nanomaterials: The first represents a dual-square carbon-oxide lattice featuring a Dirac nodal-line semimetal (DNLSM) band structure. Orbital engineering guided by Wannier function analysis guided the design of a d4mm symmetric tetraoxa[8]circulene (TOC) covalent-organic framework linked through cyclobutadiene groups. A second example describes the realization of phase frustration induced flat bands in a diatomic Kagome lattice. The chemical stabilization of the energetically unfavorable open-shell high-spin ground state of aza-[3]triaugnulene within the lattice of a COF

¹ JVST Highlighted Talk

² JVST Highlighted Talk

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³ SSD Morton S. Traum Award Finalist

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forms the basis for a degenerate set of molecular orbitals that give rise to hopping frustrated topological flat bands near the Fermi level.

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[1] Liu, F.; Yan, Y.; Tang, W.; Qie, B.; Chen, J.; Wang, Z.; Louie, S. G.; Fischer F. R. Orbital Engineering Band Degeneracy in a Dual-Square Carbon-Oxide Framework, **2025**, *under review*.

[2] Yan, Y.; Liu, F.; Tang, W.; Qie, B.; Louie, S. G.; Fischer F. R. Engineering Phase-Frustration Induced Flat Bands in an Aza-Triangulene Covalent Organic Kagome Lattice, **2025**, *under review*.

11:00am **SS-WeM-13 On-Surface Synthesis and Single-Molecule Manipulation for the Atomically Precise Fabrication of Carbon Nanomaterials**, *J. Michael Gottfried*, University of Marburg, Germany **INVITED**

Recent advancements of on-surface synthesis techniques enable the fabrication and precise characterization of carbon-based nanomaterials with atomic-scale accuracy. These materials often exhibit novel (opto-)electronic and magnetic properties, which are partly derived from the inherent characteristics of the precursor molecules and partly emerge from the unique structures formed during synthesis. Therefore, on-surface synthesis presents a highly versatile alternative to conventional solution-phase chemistry, leading to novel products not obtainable by conventional chemical methods. Specifically, the quest for nonbenzenoid sp^2 carbon allotropes has stimulated substantial research efforts because of their predicted unique mechanical, (opto-)electronic, and transport properties. However, synthesis of these carbon networks remains challenging due to the lack of reliable protocols for generating nonhexagonal rings. We have developed various on-surface synthesis strategies by which polymer chains are linked to form nonbenzenoid carbon networks. In this way, we synthesized biphenylene network, a carbon allotrope with 4-6-8-membered rings, which is metallic already at very small dimensions, and other carbon networks. [1]

An especially rigorous protocol for the prototyping of new materials is the direct manipulation of atoms and molecules with the tip of a low-temperature scanning tunneling microscope. Here, we used this method to fabricated tridecacene (13ac) and pentadecacene (15ac), the longest acenes achieved to date, via multistep single-molecule manipulation. [2,3] Acenes are another important class of carbon materials with potential for use in organic electronics. We find antiferromagnetic open-shell ground state electron configurations for both acenes. Notably, 15ac shows a low-bias spin-excitation feature, indicating a singlet-triplet gap of around 124 meV. Investigation of 15ac complexes with up to 6 gold atoms suggest considerable multiradical contributions to the electronic ground state of 15ac. [3] Furthermore, doping with heteroatoms alters the electronic and magnetic properties of carbon-based nanomaterials. We present a variety of nitrogen-containing carbon nanostructures including planar and curved cycloarenes as well as N-doped graphene nanoribbons.

- [1] Q.T. Fan, L-H. Yan et al., J.M. Gottfried, *Science* 372, 852-856 (2021).
- [2] Z.L. Ruan et al., J.M. Gottfried, *J. Am. Chem. Soc.* 146, 3700-3709 (2024).
- [3] Z.L. Ruan et al., J.M. Gottfried, *J. Am. Chem. Soc.* 147, 4862-4870 (2025).

11:30am **SS-WeM-15 Impact of Subsurface Oxygen on CO Oxidation over Rhodium Surfaces**, *Arved Dorst*, University of Göttingen, Germany; *Maxwell Gillum*, *Daniel Killelea*, Loyola University Chicago; *Tim Schäfer*, University of Göttingen, Germany

Rhodium surfaces play a crucial role in heterogeneous catalysis, driving extensive research on their reactivity. In particular, CO oxidation is of great interest, where different oxygen species at the surface can influence catalytic activity. Under certain conditions, rhodium can also host subsurface oxygen species, further affecting reaction dynamics. In this work, we combine molecular beam surface scattering, ion imaging, and ultra-high vacuum techniques to investigate the impact of subsurface oxygen on CO oxidation on single-crystal Rh surfaces. When oxidizing CO at the (2 × 1)-O adlayer without subsurface oxygen, we observe hyperthermal velocity distributions of desorbing CO₂, indicating significant energy release along the translational coordinate directly from the transition state. In contrast, the presence of subsurface oxygen results in thermal velocity distributions, suggesting the formation of a temporarily trapped chemisorption state, which becomes energetically favorable in the presence of subsurface oxygen.

12:00pm **SS-WeM-17 Beyond Optimization: Exploring Novelty Discovery in Autonomous Experiment**, *Ralph Bulanadi*, *Jawad Chowdhury*, Oak Ridge National Laboratory; *Hiroshi Funakubo*, Institute of Science Tokyo, Japan; *Maxim Ziatdinov*, Pacific Northwest National Laboratory; *Rama Vasudevan*, Oak Ridge National Laboratory; *Arpan Biswas*, University of Tennessee, Knoxville; *Yongtao Liu*, Oak Ridge National Laboratory

Autonomous experiments (AEs) are transforming how scientific research is conducted by integrating artificial intelligence with automated experimental platforms. Current AEs primarily focus on the optimization of a predefined target; while accelerating this goal, such an approach limits the discovery of unexpected or unknown physical phenomena. Here, we introduce a novel framework, INS2ANE (Integrated Novelty Score–Strategic Autonomous Non-Smooth Exploration), to enhance the discovery of novel phenomena in autonomous experimentation. Our method integrates two key components: (1) a novelty scoring system that evaluates the uniqueness of experimental results, and (2) a strategic sampling mechanism that promotes exploration of under-sampled regions even if they appear less promising by conventional criteria. We validate this approach on a pre-acquired dataset with a known ground truth comprising of image–spectral pairs. We further implement the process on autonomous scanning probe microscopy experiments. INS2ANE significantly increases the diversity of explored phenomena in comparison to conventional optimization routines, enhancing the likelihood of discovering previously unobserved phenomena. These results demonstrate the potential for AE to enhance the depth of scientific discovery; in combination with the efficiency provided by AEs, this approach promises to accelerate scientific research by simultaneously navigating complex experimental spaces to uncover new phenomena.

Thin Films

Room 206 B W - Session TF1-WeM

VSHOP III - Initiated Chemical Vapor Deposition

Moderators: *Kwang-Won Park*, Cornell University, *Stefan Schröder*, Kiel University, Germany

8:00am **TF1-WeM-1 Enzyme Microenvironment Engineering via Initiated Chemical Vapor Deposition**, *Yifan Cheng*, Virginia Tech **INVITED**

Enzymes enable efficient bioprocessing but often lose activity and stability under process-relevant stressors (e.g., low pH, elevated temperature). Complementary to enzyme-centric strategies such as directed evolution, we engineer the microenvironment of immobilized enzymes to shield them from harsh bulk conditions. Using initiated chemical vapor deposition (iCVD)—an all-dry, low-temperature polymerization—we fabricate conformal polycationic films on supports and subsequently immobilize lactase (β -galactosidase). These iCVD films act as proton-buffering layers that modulate the local pH at the enzyme–solution interface, enabling lactose hydrolysis in acid whey. iCVD offers nanoscale control over film thickness and functionality, compatibility with porous substrates (e.g., membranes), and solvent-free processing advantageous for sensitive biomolecules. By tuning cationic composition, we achieve local pH increases of up to 2 units (100-fold reduction in $[H^+]$) and preserve lactase activity under acidic conditions. Immobilization strategy—random versus site-directed—significantly influences the enzyme’s kinetic parameters, and we track the evolution of these parameters over multiple use cycles. This microenvironment-engineering approach provides a general route to stabilize diverse biocatalysts without enzyme-specific re-engineering, linking active-site performance to thin-film and interface control.

8:30am **TF1-WeM-3 Engineering Protonation Depth and Charge Density in Polymers for Ph-Responsive Immobilized Lactase Catalysis**, *Huida Duan*, *Junxing Chen*, *Wei Sun*, *Yifan Cheng*, Virginia Tech

Polycationic polymer coatings with tunable physicochemical properties have emerged as promising platforms for enzyme immobilization in challenging environments such as low pH. However, how polymer thickness and charge density affect local protonation behavior and enzyme activity remains poorly understood. Here, we investigate the effect of polymer thickness and polycationic monomer composition on the protonation behavior and catalytic performance of immobilized β -galactosidase (LacZ). Copolymer films of glycidyl methacrylate (GMA), providing enzyme immobilization sites, and 2-(dimethylamino)ethyl methacrylate (DMAEMA), imparting protonation-dependent positive charges, were synthesized via initiated chemical vapor deposition (iCVD). Their chemical structures were confirmed by Fourier transform infrared spectroscopy (FTIR). Protonation depth was assessed by analyzing the intensity ratios of N–H bending to C=O

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stretching vibrations after acid treatment, while enzyme activity was evaluated under both neutral (pH 7) and acidic (pH 4) conditions using both random and site-directed immobilization strategies. FTIR results revealed that protonation was limited to a finite depth of ~255nm, with thinner films (<200nm) achieving complete protonation. Enzyme activity at pH 4 was retained only when protonated polycationic layers were present, and plateaued once protonation depth was saturated. Polymers with higher DMAEMA content (65%) outperformed those with lower content (25%), with activity increases up to 83%. Site-directed immobilization consistently preserved higher activity than random conjugation. These findings highlight the critical role of interfacial proton buffering in enabling biocatalysis under acidic conditions and provide design principles for functional polymer-enzyme interfaces in harsh environments.

8:45am TF1-WeM-4 Recent Advances in the Understanding of Spontaneous Orientation Polarization in Polymer Thin Films Deposited by Initiated Chemical Vapor Deposition (iCVD), Stefan Schröder, Torge Hartig, Thomas Strunkus, Tayebeh Ameri, Franz Faupel, Kiel University, Germany

A recent study demonstrated the formation of a spontaneous orientation polarization effect in polymer thin films deposited via initiated chemical vapor deposition (iCVD). It enables the integration of permanent, high-precision electric fields into electronic devices. However, the understanding of the exact mechanism and dependence on the reaction kinetics is still at an early stage. This work reports on new insights on the polarization process based on theoretical and experimental results. The enhanced understanding enables improved control over the resulting surface potential of the polymer films and discovery of new monomers based on electric dipole moment calculations. Furthermore, a few examples of potential applications will be given.

9:00am TF1-WeM-5 Surface Roughness Control in Vapor-Deposited Nanocoatings for Bio-Adhesion Mitigation, Jessie Yu Mao, Chengqian Huang, Mengfan Zhu, Oklahoma State University INVITED

Superhydrophobic surfaces offer effective resistance against the adhesion of biomolecules like bacteria and proteins. This property holds promise for their application in medical devices, aiming to mitigate complications such as infections and thrombosis. Hierarchical roughness plays a pivotal role in enhancing superhydrophobicity by providing multiple scales of surface features, which collectively contribute to increased water repellency and reduced adhesion of biomolecules. Traditional fabrication of topographical roughness requires specific substrates or solvent-based processing, which could raise concerns regarding biotoxicity. We constructed topographical roughness using an initiated chemical vapor deposition (iCVD) method that is applicable independent of substrate material and geometry. We studied how the processing parameters affect the formed surface topography and the bio-adhesion properties. In addition, surfaces with hierarchical roughness were created by varying the vapor deposition parameters *in situ*. The hierarchically roughened surface demonstrated superhydrophobicity, with more than 80% reduction in the adhered bacteria and a 98.8% decrease in the surface fibrin clotting, as compared with the homogeneously rough surface. This iCVD technique presents a novel avenue for attaining superhydrophobicity on medical devices to reduce device-related adverse events.

9:30am TF1-WeM-7 Precision Synthesis of Polymeric Materials Using Initiated Chemical Vapor Deposition (iCVD) for Cyber Manufacturing, Rong Yang, Cornell University

Initiated Chemical Vapor Deposition (iCVD) is emerging as a powerful technique for the precision synthesis of polymeric materials. New advances in iCVD-based precision polymerization span the synthesis of shaped particles, strategies to suppress side reactions, and achieving emergent properties, all of which are enabled by engineering non-covalent interactions. This talk highlights one example in which engineering monomer absorption into liquid templates enables the integration of artificial intelligence (AI) for the precision manufacturing of polymeric particles with programmable size, shape, and chemistry. We engineer non-covalent interactions between monomers and mesogens to control monomer partition into a liquid crystal (LC) film, thereby enabling LC-templated continuous polymerization. By tuning the relative strengths of non-covalent cohesive force versus elastic force afforded by the LC template, we guide the synthesis pathway along a variety of trajectories that lead to tailored polymer morphology. In addition, the LC templates are self-reporting, which both guide and optically report on the evolution of the morphology of polymeric particles during continuous polymerization. We perform real-time analysis of the optical outputs using AI, enabling on-

the-fly feedback and selection of synthesis conditions to achieve targeted polymer morphology. This capability, combined with the automated and scalable CVD technology, points to a new paradigm of cyber manufacturing for polymeric materials.

9:45am TF1-WeM-8 PFAS-free Initiators for iCVD, Torge Hartig, Hannes Nehls, Tim Pogoda, Joschka Paulsen, Julia Piehl, Thomas Strunkus, Franz Faupel, Kiel University, Germany; Tayebeh Ameri, Kiel University, Germany, Iran (Islamic Republic of); Stefan Schröder, Kiel University, Germany

Initiated Chemical Vapor Deposition (iCVD) is an all-dry method for the solvent-free deposition of ultra-thin conformal polymer coatings. In recent years a large library of more than 100 monomers in iCVD has been established representing an extraordinary toolbox while research on initiators has played a smaller role. TBPO (di-tert butyl peroxide) as the standard initiator in iCVD works generally well in all processes. While the deposition rates of TBPO are no problem in academia, faster rates are often required in industrial application. Hence, a focus on new initiators could open the doors to new process kinetics. Previously fluorocarbon initiators have been used for increased deposition rates. With the recent development of possible PFAS bans and fluorocarbon impact on reactor usage, new high-rate initiators are required for the iCVD process. Within this study the impact of the chemical structure of peroxides, including hydroperoxides, is explored, leading to drastically faster deposition rates.

Thin Films

Room 206 B W - Session TF2-WeM

VSHOP IV - Oxidative Chemical Vapor Deposition & Molecular Layer Deposition

Moderator: David S. Bergman, University of Washington

11:00am TF2-WeM-13 Ozone-Initiated Oxidative Chemical Vapor Deposition of PEDOT Coatings on 2D and 3D Substrates, Blake Nuwayhid¹, Travis Novak, Jeffrey Long, Debra Rolison, U.S. Naval Research Laboratory
Vapor-phase routes to organic conducting polymers offer many advantages over more commonly studied solution-phase methods. Conductive polymers often require functionalization to be soluble in an appropriate solvent, and techniques such as spin-coating or drop-casting are generally only suitable for relatively flat substrates. Oxidative chemical vapor deposition (oCVD) is an alternative that allows for control of coatings over complex 3D substrates. Poly(3,4-ethylene dioxythiophene) (PEDOT) is the most widely studied oCVD-fabricated polymer, in which all previous reports used undesirable oxidants such as iron chloride (FeCl₃), vanadium oxytrichloride (VOCl₃), or antimony pentachloride (SbCl₅). The FeCl₃ is a low-vapor-pressure solid, whereas, VOCl₃ and SbCl₅ are highly corrosive liquid precursors. These inorganic oxidative initiators necessitate post-deposition treatments to remove inorganic byproducts from the resulting polymer film. We demonstrate a new approach to oCVD PEDOT using O₃ as the oxidation source, resulting in a totally dry and cleaner deposition process than that obtained from the aforementioned oxidants. We deposit PEDOT in a custom-built oCVD reactor in a temperature range of 40–100 °C, in which the process shows monomer adsorption-limited behavior with growth rates decreasing from 1.2 nm/min at 40 °C to 0.24 nm/min at 100 °C for a process pressure of 400 mTorr. We further explore the deposition kinetics and chemical composition as a function of temperature, pressure, and O₃ concentration. We find that films deposited at <100 °C are not crosslinked, but a gentle thermal annealing at 100 °C in an Ar atmosphere induces polymer crosslinking as determined by spectroscopic ellipsometry. Compositional analysis using XPS and FTIR show that the as-deposited films are over-oxidized, possessing S=O bonds in the thiophene chain. We further characterize the thermoelectric and electrochemical properties of the O₃-deposited PEDOT and introduce additives to boost electronic conductivity.

11:15am TF2-WeM-14 Oxidative Chemical Vapor Deposition of Nanometer-Scale Polyaniline on Si/Cobalt Phthalocyanine (CoPc) Photocathodes for Enhanced Stability and CO/H₂ Selectivity during Photoelectrochemical CO₂ Reduction, Hyuenwoo Yang, Yuchen Liu, Seoyeon Kim, Hannah Margavio, North Carolina State University; Carrie Donley, University of North Carolina at Chapel Hill; Hwan Oh, Brookhaven National Laboratory; Renato Sampaio, University of North Carolina at Chapel Hill; Gregory Parsons, North Carolina State University
Photoelectrochemical CO₂ reduction (CO₂RR) to value-added products offers a promising route for carbon utilization, yet photocathode stability

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and selectivity remain critical challenges. We present a Si/CoPc/Polyaniline (PANI) photocathode, integrating a p-type Si substrate with cobalt phthalocyanine – carbon nanotube (CoPc-CNT) and a ~10 nm oxidative chemical vapor deposition (oCVD) PANI overlayer, achieving exceptional durability and CO selectivity. The oCVD process enables precise PANI thickness control, optimizing stability without sacrificing catalytic access. At -0.4 V vs RHE in CO₂-saturated 0.1 M KHCO₃ under 1 sun illumination, Si/CoPc/PANI sustains current density for 24 hours, with faradaic efficiency for CO (FE_{CO}) exceeding 88%, far surpassing unprotected Si/CoPc's ~20-minute lifespan due to CoPc detachment. Across -0.4 to -0.8 V, Si/CoPc/PANI maintains stability for 3 hours, retaining FE_{CO} at 89% at -0.8 V. Comparative tests reveal thicker PANI layers (20 nm, 45 nm) reduce current density and fail within 24 hours, highlighting 10 nm as optimal.

UV-vis spectropscopy, x-ray photoelectron spectroscopy (XPS), Raman spectroscopy and Fourier transform infrared spectroscopy (FTIR) characterize oCVD PANI overlayer on Si/CoPc photoelectrode. This synergy of oCVD PANI and CoPc yields a robust photocathode, advancing CO₂RR toward practical applications by addressing stability bottlenecks, with implications for scalable, vacuum-deposited protective layers in energy conversion systems.

11:30am TF2-WeM-15 Temperature Effects in Oxidative Molecular Layer Deposition (oMLD) of Polypyrrole, Mahya Mehregan, Shima Mehregan, Andrew Reinhard, Matthew Maschmann, University of Missouri-Columbia; Matthias Young, University of Missouri, Columbia

Polypyrrole (PPy) is a conjugated polymer with moderate electrical conductivity (~100 S·cm⁻¹) and high theoretical charge storage capacity of 411 mAh/g, making it of interest for electrochemical applications including supercapacitors, batteries, and sensors. Using solution-phase synthesis, the maximum charge storage capacity observed for PPy has been limited to ~140 mAh/g. In recent work, the use of oxidative molecular layer deposition (oMLD) to form PPy was found to enhance the charge storage capacity to >300 mAh/g, but the origins of this effect are not fully understood. In this work, we examine how the deposition temperature used for oMLD over the range of 100–150°C influences the PPy growth chemistry, final polymer structure, and electrochemical properties. We employ *in situ* quartz crystal microbalance (QCM) during oMLD deposition to understand how growth temperature affects the growth mechanism. We also employ *ex situ* differential scanning calorimetry (DSC), scanning electron microscopy (SEM), X-ray photoelectron spectroscopy (XPS), and atomic force microscopy (AFM) to validate the insights from QCM, and measure how the deposition temperature influences polymer structure and morphology. We identify that lower deposition temperatures produce higher amounts of surface sorbed MoCl_x during growth, leading to faster film nucleation and higher MoCl_x residue in the final films. We find that deposition below the glass transition temperature introduces microstructure differences, while deposition above the glass transition temperature produces uniform films. We also report high-energy synchrotron X-ray Diffraction (HE-XRD) of PPy formed at 150°C and compare against electrodeposited PPy. Together, these studies establish a deeper understanding of the process/structure/property relationships for PPy formed by oMLD, informing its use for electrochemical applications.

11:45am TF2-WeM-16 Oxidative Molecular Layer Deposition of Polythiourea for Nitrate Sensing, Shima Mehregan¹, Mahya Mehregan, University of Missouri; Erick Gutierrez Monje, Matthias Young, University of Missouri

Low-cost nitrate sensors are critical to enable efficient use of agricultural nutrients and reduce environmental impact from nutrient runoff. In previous work, we established a new strategy to fabricate low-cost nitrate sensors based on differences in ion transport kinetics through ion-selective membranes. However, to be successful, these membrane layers must be formed with highly reproducible thickness and composition, which is not straightforward with wet-chemical polymer synthesis. In this study, we examine the use of polythiourea (PTU) films formed by oxidative molecular layer deposition (oMLD) of thiourea (TU) and molybdenum pentachloride (MoCl₅) as nitrate-selective membrane layers. oMLD provides precise control over PTU membrane thickness, composition, and morphology through sequential surface reactions, providing more reproducible sensors and overcoming the limitations of wet chemical membrane synthesis. We employ *in situ* quartz crystal microbalance (QCM) studies during alternating exposures of TU and MoCl₅ to understand the oMLD growth mechanism. We characterize the chemical structure of oMLD PTU using Raman

Spectroscopy and X-ray Photoelectron Spectroscopy (XPS) and the microstructure using Scanning Electron Microscopy (SEM). We then report the fabrication of PTU-based thin-film nitrate sensors and apply nonequilibrium anion detection to evaluate their sensitivity in the presence of different anions, including chloride, nitrate, and phosphate. We find that PTU membrane layers are highly selective toward nitrate, and improve nitrate selectivity over chloride relative to commercially available electrochemical nitrate sensors, with high reproducibility among devices. This work establishes oMLD PTU as a viable membrane material for low-cost nitrate sensors.

12:00pm TF2-WeM-17 Polyurea Molecular Layer Deposition Using Low Melting Point Precursors for Use in Biosensor Design, Jay Werner, Seancarlos Gonzalez, David S. Bergsman, University of Washington

In biosensor design, biomolecules are often chemically bound to the sensor as part of the detection mechanism. As a result, surface functionalization is a critical part of biosensor design to mediate the connection between the analyte and the detector. Silane-based self-assembled monolayers (SAMs) are commonly used for this purpose, however, because of the sub-nanometer thickness of a true monolayer and the propensity of silanes to form unstable multilayer structures, it can be challenging to create and verify a SAM. Molecular layer deposition (MLD) is a promising tool which may be able to take the place of SAMs in some surface functionalization applications where a stable multilayered film would be acceptable. MLD is a vapor phase deposition process that uses a sequence of organic precursors that react via highly energetic reactions in a self-limiting way. These properties allow for the repeatable, stepwise, and conformal deposition of thin films, even in high aspect ratio features. In this work, we present a polyurea MLD chemistry based on low melting point 2,4-toluene diisocyanate (TDIC) and ethylene diamine (ED) to form a polyurea thin film at room temperature. Previous polyurea MLD processes have used high melting point 1,4-phenylene diisocyanate (PDIC) as an aromatic isocyanate precursor, often requiring heat to achieve sufficient vapor pressure. This heat can complicate the deposition process and reduce precursor lifespan. In contrast, TDIC is a liquid at room temperature and is cheaper and more widely available than PDIC. In addition to characterizing this process' growth behavior and composition, we assess the zeta potential, water contact angle, and primary amine availability for crosslinking chemistry. We also assess how these properties are affected by UV-ozone (UVO) etching treatments, which may be used to improve wettability in biosensor design.

¹ TFD James Harper Award Finalist

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2D Materials

Room 208 W - Session 2D+EM+NS+QS+SS+TF-WeA

2D Materials: Synthesis and Processing

Moderator: Tiancong Zhu, Purdue University

2:15pm 2D+EM+NS+QS+SS+TF-WeA-1 Process Discovery for Quantum Materials, *Stephan Hofmann*, University of Cambridge, UK **INVITED**

Effective heterogeneous integration of low-dimensional nanomaterials in applications ranging from quantum electronics to biomedical devices requires a detailed understanding of different formation and interfacing reactions and the ability to synergize these processes. Process development largely still follows an Edisonian trial-and-error approach, blind and constraint by conventional reactors. This is not only wasteful and frustratingly slow, but hinders scientific breakthroughs in crystal growth and innovation in new deposition technology. This talk will focus on our cross-correlative, high-throughput operando approaches and combinatorial close-space sublimation (CSS) based process design to accelerate process discovery. We show operando spectroscopic imaging ellipsometry and scanning electron microscopy with machine-learning assisted analysis and parameter space exploration for salt-assisted WS₂ layer CVD and TMD oxidation phenomena, and how direct kinetic process data can open data driven approaches to advance the required understanding of underpinning mechanisms.[1] We show that CSS is a highly promising alternative to conventional powder-furnace chemical vapour deposition, offering superior efficiency, precise structural control, scalability, and adaptable process designs. As part of processability and stability assessment, we also explore oxidation kinetics of TMD materials, [2] aided by atomistic modelling using machine-learned force fields.[3]

[1] Yang et al., Chem. Mat. 37, 989 (2025)

[2] Sahota et al., ACS Appl. Nano Mat., asap (2025)

[3] Gsanyi et al., arXiv:2401.00096, 2023

2:45pm 2D+EM+NS+QS+SS+TF-WeA-3 Selective Area Epitaxy of van der Waals Materials, *Ryan Trice¹*, *Stephanie Law*, Penn State University

Two-dimensional (2D) van der Waals (vdW) materials are interesting for a variety of applications, ranging from optoelectronics and photocatalysis to energy storage and topological devices. However, vdW materials synthesized using common techniques like chemical or physical vapor deposition often have a high density of growth-related defects, including grain boundaries, twin defects, pyramidal growth, and spiral defects. While pyramidal growth can be minimized through higher growth temperatures, grain boundaries, twin defects, and spiral defects are much harder to overcome. For many applications, especially in electronics and optics, these defects lead to non-radiative recombination, electron scattering, and other undesirable effects. Furthermore, the fabrication of 2D materials into quantum dots (QDs) through bottom-up methods faces problems with precise location placement and polydispersity in the QDs' diameters. This makes the QDs difficult to characterize and is not ideal for most quantum computing and optical setups. Top-down nanofabrication approaches fix this issue but often cause significant damage to the surfaces or edges of the materials. To address these issues, we used molecular beam epitaxy (MBE) combined with selective area epitaxy (SAE) to grow Bi₂Se₃ thin films. SAE is a technique in which thin films nucleate and grow in defined areas on a wafer. This is done using a patterned mask where growth conditions are selected such that the film will only nucleate on the substrate.

In this talk, we will describe SAE growth of Bi₂Se₃ on Al₂O₃ (0001) and Si (111) substrates using an atomic layer deposition SiO₂ mask. Etching of the SiO₂ mask was done with a wet chemical etch, resulting in micron-scale holes of various shapes and sizes. The processed substrates were then loaded into an MBE chamber for the growth of the Bi₂Se₃ film. First, we will discuss the effects of different substrate temperatures on the selective growth of the Bi₂Se₃ thin films. Second, we will discuss the geometric influence of variously shaped patterns on the crystal quality of the selectively grown films. Third, we will look at the effect and viability of nano-scale patterns for selective growth of vdW materials. Further studies will focus on using different materials for the substrate and mask. This approach could allow us to grow wafer-scale, defect-free 2D vdW QDs at specified areas on the wafer, thereby increasing the scalability and applicability of these materials to real-world challenges.

3:00pm 2D+EM+NS+QS+SS+TF-WeA-4 Precision Synthesis and Conversion of 2D Materials by Pulsed Laser Deposition with *In Situ* Diagnostics, *Daniel T. Yimam²*, *Sumner B. Harris*, Oak Ridge National Laboratory, USA; *Austin Houston*, University of Tennessee Knoxville; *Ivan Vlassiouk*, Oak Ridge National Laboratory, USA; *Alexander Puretzky*, Oak Ridge National Laboratory; *Gerd Duscher*, University of Tennessee Knoxville; *Kai Xiao*, Oak Ridge National Laboratory, USA; *David B. Geohegan*, University of Tennessee Knoxville

Over the past few decades, 2D monolayers and heterostructures have become central to nanoscience, offering promising applications in electronics, sensing, and future computing. In addition to their exciting functional properties, significant progress has been made in their bottom-up synthesis and subsequent processing. Techniques such as encapsulation, doping, and implantation in atomically thin 2D materials are crucial to transitioning them from fundamental research to scalable, real-world applications, while enabling the emergence of novel properties. However, the ultrathin nature that makes 2D materials attractive also poses substantial challenges for traditional plasma-based processing methods. To fully harness the potential, it is essential to develop reliable processing techniques that offer precise control and reproducibility.

Pulsed laser deposition (PLD) is a promising non-equilibrium method that allows precise control over the kinetic energy (KE) of ablated species. In this work, we investigate plasma plume interactions with 2D materials using *in situ* plasma diagnostics and optical characterization tools. We demonstrate that a deep understanding and control of plasma plume dynamics enables new approaches for 2D material engineering, including the formation of Janus monolayers, metal atom implantation, and encapsulation with minimal damage. Our approach allows for low temperature substitution and implantation of foreign atoms, such as chalcogens and metals, facilitating the selective synthesis of Janus monolayers and alloys. These findings highlight the potential of PLD to drive the practical advancements in 2D materials for microelectronics and quantum information science.

This work was supported by the U.S. DOE, Office of Science, Materials Sciences and Engineering Division and the Center for Nanophase Materials Sciences, which is a DOE Office of Science User Facility.

Keywords: Pulsed laser deposition, chalcogenide substitution, 2D materials, implantation, *in situ* diagnostics.

3:15pm 2D+EM+NS+QS+SS+TF-WeA-5 AVS Peter Mark Memorial Award Talk: Exploiting Thin Film Phase Diagrams for Synthesizing 2D Transition Metal Dichalcogenides, *Nicholas R. Glavin*, Air Force Research Laboratory **INVITED**

Synthesis of 2D transition metal dichalcogenides for specific applications in electronics, optoelectronic, and advanced coatings remains a critical bottleneck for many industrial applications. In this talk, we will highlight leveraging thin film phase diagrams to rapidly explore the vast parameter space in synthesizing these novel materials. This technique uses laser processing to locally modify regions within the film and coupled with high throughput characterization, rapidly assesses material state and quality for next generation sensors, optical coatings, and low power electronics.

4:15pm 2D+EM+NS+QS+SS+TF-WeA-9 Designer van der Waals Materials for Quantum Optical Emission, *Shengxi Huang*, *Wenjing Wu*, Rice University **INVITED**

Designer van der Waals (vdW) materials offers enormous opportunities to tune material properties for various applications. Isolated, optically-active defects generated in vdW materials could lead to single photon emission. 2D vdW materials as host materials for single photon emission hold various advantages, such as high optical extraction efficiency from the atomically-thin layered materials, and readiness to integrate with on-chip photonic and electronic devices. However, single photon emission from 2D vdW materials typically suffers from low purity and lack of controllability, due to the sensitivity of these atomically-thin materials to external dielectric environments, surface defects and adsorbents, and strains and wrinkles introduced during material processing. This talk introduces our recent efforts to improve the single photon purity and controllability in vdW materials. We developed novel defect structures that can overcome several current issues, and explored their electronic structure and tunability in optical emission. Through a combination of approaches, including strain engineering, heterostacking, employing optical selection rules for excitation and detection, optimization of material synthesis and handling, we were able to achieve high purity (> 98%) for single photons emitted from 2D

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transition metal dichalcogenides (TMDs) at cryogenic temperature and in hBN at room temperature. This work provides deep insights into the electronic, spin, and valley properties of TMDs and hBN. It also paves the way towards the application of 2D vdW materials for quantum optical applications. The materials engineering approaches developed here can be applied to the optimization of other optical and quantum materials.

4:45pm **2D+EM+NS+QS+SS+TF-WeA-11** **Macroscopic Tin Monochalcogenide Van Der Waals Ferroics: Growth, Domain Structures, Curie Temperatures and Lateral Heterostructures,** *Eli Sutter, Peter Sutter, University of Nebraska - Lincoln*

2D and layered van der Waals crystals present opportunities for creating new families of ferroics with switchable electric polarization, elastic strain, or magnetic order at thicknesses down to the single-layer limit. Synthesis, however, typically leads to small crystals with sizes ranging from below 100 nm (e.g., for SnTe ferroelectrics) to a few μm (e.g., for SnSe ferroelectrics). The limited size and proximity to edges affects the ferroelectric and ferroelastic domain patterns, restricts the experimental methods available to probe emerging properties, and severely limits the ability to fabricate complex device architectures required for accessing functionalities in van der Waals ferroelectrics.

Here, we report the realization of in-plane ferroelectric few-layer crystals of the monochalcogenides tin(II) sulfide and selenide (SnS, SnSe) whose linear dimensions exceed the current state of the art by up to one order of magnitude. Such large crystals allow the investigation of ferroic domain patterns that are unaffected by edges and finite size effects. Analysis of the abundant stripe domains by electron microscopy and nanobeam electron diffraction shows two distinct domain types, twin domains separated by positively charged walls with alternating head-to-head and tail-to-tail polarization as well as not previously observed purely rotational domains connected by neutral domain walls with head-to-tail dipoles. Access to large ultrathin crystals allowed determining the Curie temperatures of few-layer SnSe¹ and SnS van der Waals ferroelectrics.

Finally, we demonstrate the integration of the ultrathin ferroelectric SnSe and SnS into lateral heterostructures.² A two-step process produces crystals comprising an SnSe core laterally joined to an SnS edge-band, as confirmed by Raman spectroscopy, electron microscopy imaging, and diffraction. The ability of the lateral interface to direct excited carriers, probed by cathodoluminescence, shows electron transfer over 560 nm diffusion length from the SnS edge-band. The ferroelectric heterostructures adopt two domain configurations, with domains either constrained to the SnSe core or propagating across the entire SnSe-SnS flakes.

The combined results demonstrate industrial scale in-plane ferroelectrics as well as multifunctional van der Waals heterostructures, presenting extraordinary opportunities for manipulating ferroelectric domain patterns and carrier flow.

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(2) Sutter, E.; Ghimire, P.; Sutter, P. *ACS Nano* **2024**, *18* (44), 30829–30837. DOI: 10.1021/acsnano.4c11341.

5:00pm **2D+EM+NS+QS+SS+TF-WeA-12** **Machine Learning Analysis of Molecular Beam Epitaxy Growth Conditions,** *Mingyu Yu, Ryan Trice, Isaiah Moses, Wesley Reinhart, Stephanie Law, Penn State University*

Machine learning models hold the potential to explore parameter space autonomously, quickly establish process-performance relationships, and diagnose material synthesis in real time. This reduces reliance on manual intervention in parameter space exploration, enabling more precise and efficient mechanistic control. For molecular beam epitaxy (MBE), despite its breakthroughs in materials synthesis, its stringent growth conditions and complex epitaxial mechanisms make the process of optimizing growth process time-consuming and expensive. Therefore, leveraging machine learning to develop autonomous MBE growth platforms presents a highly promising prospect. Our study on the multi-modal machine learning-guided MBE synthesis is based on a comprehensive high-quality dataset of GaSe thin films grown on GaAs (111)B substrates. GaSe is an emerging two-dimensional semiconductor material with intriguing properties, including thickness-tunable bandgaps, nonlinear optical behaviors, and intrinsic p-type conductivity. Moreover, as a representative member of the van der Waals (vdW) chalcogenide semiconductor family, insights gained from studying GaSe can be extended to other vdW chalcogenides. In this work, we aim to leverage machine learning to analyze the relationships between

growth conditions (Ga flux, Se:Ga flux ratio, and substrate temperature) and the resulting sample quality, as well as the correlations among various characterization results including *in situ* RHEED patterns and *ex situ* x-ray diffraction rocking curve full-width at half maximum (FWHM) and atomic force microscopy (AFM) root mean square (RMS) roughness. Unsupervised learning on RHEED patterns reveals a well-defined boundary between high- and low-quality samples, capturing physically meaningful features. Mutual information analysis shows a strong correlation between RHEED embeddings and rocking curve FWHM, while the correlation with AFM RMS roughness is weak. Among key growth conditions, growth rate most strongly influences FWHM, whereas the Se:Ga flux ratio primarily affects RMS roughness and the RHEED embeddings. Supervised learning models trained to predict FWHM and RMS roughness demonstrate moderate accuracy, with significant improvement achieved by incorporating RHEED embeddings. Furthermore, anomaly detection via residual analysis in supervised learning aligns well with unsupervised classification from RHEED, reinforcing the reliability of the predictive models. This study establishes a data-driven framework for machine learning-assisted MBE, paving the way for real-time process control and accelerated optimization of thin-film synthesis.

5:15pm **2D+EM+NS+QS+SS+TF-WeA-13** **Promoting Crystallographic Alignment in SnSe Thin Films using Step Edges on MgO by MBE,** *Jonathan Chin, Marshall Frye, Joshua Wahl, Kayla Chuong, Georgia Institute of Technology; Mengyi Wang, Derrick Liu, Pennsylvania State University; Mingyu Yu, University of Delaware; Qihua Zhang, Nadire Nayir, Adri van Duin, Maria Hilde, Stephanie Law, Pennsylvania State University; Lauren Garten, Georgia Institute of Technology*

SnSe is a van der Waals material that can be scaled down to two dimensions,¹ making it a promising candidate for nanoelectronics such as field effect transistors (FETs).² SnSe in the orthorhombic *Pnma* structure exhibits significant electrical anisotropy where the carrier mobility is 45% higher along the [010] direction than the [001] direction in plane,³ making it necessary to control the in-plane alignment of 2D films for integration into electronic devices. SnSe has been shown to form planar coverage on (100) MgO,⁴ with which it has a 1.4% and 5.5% lattice mismatch along the [010] and [001] directions, respectively. However, despite the distinct axial lattice matches, *in-situ* reflective high-energy electron diffraction (RHEED) shows no preferential SnSe film alignment for films deposited on uncleaved MgO. Therefore, to promote orientation control, we cleaved and annealed the MgO substrates to produce step edges along the surface to increase the local surface energy, thereby encouraging atomic adsorption and alignment. SnSe thin films were then deposited from individual Sn and Se effusion cells via molecular beam epitaxy (MBE) onto the prepared MgO substrates heated to 280 °C for 1–5 minutes with a 1.35:1.00 Se:Sn flux ratio at a 0.083 Å/s growth rate to track the nucleation and growth of SnSe grains. The phase of the SnSe films was confirmed by Raman spectroscopy, exhibiting the characteristic A_g^2 , B_{3g} , A_g^3 , and A_g^4 phonon modes.⁵ *In-situ* RHEED confirmed the in-plane alignment along the [010] and [001] by RHEED relative to the [100] substrate, matching theory projections made using reactive force field (ReaxFF) simulations. Additionally, atomic force microscopy (AFM) shows SnSe grains nucleating at step edges on MgO, while scanning transmission electron microscopy (STEM) reveals how the aligned SnSe grains propagate laterally off step edges, maintaining crystallographic alignment throughout the film layer. Overall, our results demonstrate that SnSe grains preferentially nucleate along the step edges produced parallel to the [100] edge of the MgO substrates. The alignment of a 2D vdW film facilitated by step edge formation demonstrates how to achieve orientated depositions of similar anisotropic vdW films on a substrate of choice, ultimately facilitating the manufacture of 2D nanoscale electronic devices.

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3.Zhou, M. *et al. J. Mater. Chem.* **5**, 1247–1254 (2017).

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5.Wu, P. *et al. New J. Phys.* **22**, 083083 (2020).

5:30pm **2D+EM+NS+QS+SS+TF-WeA-14** **Synthesis of Millimeter-Scale Single-Crystal α -MoO₃ Nanosheets on Sapphire,** *Ryan Spangler, Pennsylvania State University; Thiago Arnaud, Joshua Caldwell, Vanderbilt University; Jon-Paul Maria, Pennsylvania State University*
 α -MoO₃ is a van der Waals layered semiconductor with biaxial anisotropy that has recently gained interest as an emerging 2D material with a wide band gap (~3 eV), large work function, and high permittivity. Additionally, α -

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MoO_3 exhibits extreme anisotropy of the dielectric function, enabling in-plane and out-of-plane elliptic or even hyperbolic behavior at various wavelengths. Therefore, $\alpha\text{-MoO}_3$ also possesses great potential for nanophotonics through the low-loss and directional propagation of hyperbolic phonon polaritons, which result from the interaction of light with lattice vibrations in highly anisotropic polar materials. However, the lack of single-crystal thin film growth techniques limits further advancement of $\alpha\text{-MoO}_3$. In this work, we describe a process for the growth of ultra-large, thin, and atomically smooth single crystals of $\alpha\text{-MoO}_3$ directly on α -plane sapphire using an alkali-assisted physical vapor transport method. Important parameters necessary for high-quality growth to be discussed include substrate selection, alkali-to- MoO_3 ratio, and substrate temperature. The growth proceeds through a vapor-liquid-solid (VLS) mechanism enabled by the formation and liquefaction of low-melting point alkali molybdate phases. This growth mode greatly enhances lateral expansion to several millimeters and thicknesses ranging from hundreds of nm down to <5 nm. This is far thinner and more expansive than crystals grown without alkali metal additives, which can exceed several micrometers in thickness while being limited to a few tens of micrometers in lateral dimensions. The thin alkali-assisted sheets exhibit clean step-flow growth without grain boundaries over mm-scale areas as revealed by atomic force microscopy and polarized optical microscopy. Raman spectroscopy and X-ray diffraction indicate the high crystalline quality of the $\alpha\text{-MoO}_3$ films rivaling that of accessible bulk crystals. We will also investigate the propagation of hyperbolic phonon polaritons using scanning near-field optical microscopy (SNOM) to compare hyperbolic phonon polariton lifetimes to values obtained from exfoliated bulk crystals. We find that this growth technique is suitable for exfoliation-free large-scale single-crystal $\alpha\text{-MoO}_3$ for nanophotonics and other applications.

5:45pm **2D+EM+NS+QS+SS+TF-WeA-15** **Studying the Impacts of Growth Temperature and Seeding Promoters on the Structural and Optoelectronic Properties of ReS_2 Grown by CVD**, *Elycia Wright, Kedar Johnson, Amari Gayle, Robin Rousseau, M.K. Indika Senevirathna, Michael D. Williams, Clark Atlanta University*

Rhenium disulfide (ReS_2) is a fascinating member of the transition metal dichalcogenide (TMD) family, which has recently gained significant attention due to its distinct distorted octahedral 1T crystal structure characterized by triclinic symmetry. This distinctive structure shows that ReS_2 holds remarkable properties, including anisotropic electronic, optical, and mechanical characteristics. Unlike other TMDs such as MoS_2 , MoSe_2 , WS_2 , and WSe_2 , ReS_2 possesses a band structure that remains consistent regardless of the layer thickness. Due to weak interlayer coupling, it maintains a direct band gap in its bulk and monolayer forms. This unique characteristic makes ReS_2 particularly promising for applications in highly responsive photodetectors. To maximize the potential of ReS_2 for optoelectronic applications, it is essential to address the challenges associated with its anisotropic growth, distorted structure, and weak interlayer interactions. The anisotropic nature of ReS_2 can lead to variations in growth rates in different directions, resulting in multidomain structures that complicate the production of single-crystal ReS_2 on a large scale.

In this study, we will synthesize ReS_2 by chemical vapor deposition (CVD) at various temperatures and utilize seeding promoters to facilitate the growth of single crystals with continuous layers. We will employ advanced techniques such as confocal microscopy, Raman spectroscopy, and photoluminescence spectroscopy to systematically investigate how the growth temperature and seeding promoters affect the structural and optoelectronic properties of ReS_2 .

6:00pm **2D+EM+NS+QS+SS+TF-WeA-16** **Growth and Characterization of InSe Thin Films on $\text{GaAs}(111)\text{B}$ and $\text{Si}(111)$** , *Maria Hilse, Penn State University*

Urgent societal and environmental needs have sparked searches for high-mobility 2D materials with sizeable bandgap and decent stability under ambient conditions for use in ultra-low power, ultra-high performance field effect transistors. With a carrier mobility exceeding $1000 \text{ cm}^2/\text{Vs}$, small electron effective mass, flat electronic band dispersions, excellent optoelectronic, possible ferroelectric properties and a close-to-ideal solar spectrum matched bulk bandgap of 1.26 eV , InSe shows high potential for future use in electronics. Due to the layered nature, and the many members of different polytypes in the InSe materials family, intriguing confinement phenomena and exotic electron-hole coupling mechanisms tunable by the number of single layers add to the potential wealth of properties in InSe.

In this study, InSe thin films were grown by MBE on $\text{GaAs}(111)\text{B}$ and $\text{Si}(111)$. The presence of many InSe phases required a systematic mapping of the growth parameters to identify conditions for single-phase, single-polytype, and single-crystal growth. Through structural characterization in- and ex-situ using reflection high-energy electron and X-ray diffraction, growth conditions for solely gamma-phase, crystalline InSe films were found. Although the structural properties of the films presented nearly unchanged over a small window of growth conditions, the film morphology was seen to sensitively depend on the Se:In flux ratio. Raman spectroscopy confirmed the phase and polytype assignment deduced from large-area structural characterization.

Microstructure analysis, however, revealed a high degree of structural defects in the films. Nano-scale domains of varying single layer stacking sequences, high-angle rotational domains as well as single layers of unusual bonding configuration resulting in a novel InSe polymorph were found in the films. The total number of defects and the general locations of the new polymorph varied in films across GaAs and Si . The highest structural homogeneity was found for InSe films grown on Si .

Density functional theory calculations for a representative selection of the experimentally observed defects confirmed that most defects, including the novel polymorph have formation energies at or below the thermal budget of the MBE synthesis process. Although the bandgaps of all InSe polytypes and polymorphs possess comparable values, large differences were found in their relative offsets. Due to the random distribution of polytypes and polymorphs in the film, our study suggests a high degree of electronic disorder in these films. Electrical transport showed a variable-range hopping-like behavior supporting the hypothesis of electronic disorder.

Atomic Scale Processing Mini-Symposium

Room 206 A W - Session AP+PS+TF-WeA

Thermal and Plasma enhanced Atomic Layer Etching

Moderators: **Eric Joseph, IBM T.J. Watson Research Center, Greg Parsons, North Carolina State University**

2:15pm **AP+PS+TF-WeA-1** **Selectivity During Spontaneous Dry Thermal Etching of Si-Based Materials by Hydrogen Fluoride**, *Marcel Junige, Micah Duffield, Steven George, University of Colorado at Boulder*

Spontaneous dry thermal etching involves reaction of a thin film surface with a gaseous etchant leading to material removal with a constant etch rate. Spontaneous dry thermal etching can often be involved as a competitive process during thermal atomic layer etching (ALE). Selectivity can occur during spontaneous dry thermal etching with hydrogen fluoride (HF) because HF can form different etch species, F^- or HF_2^- , that etch with material specificity. For example, F^- can etch SiN_x and HF_2^- can etch SiO_2 . The nature of the active HF etch species can be controlled by the HF environment. HF alone yields F^- etch species. HF together with a polar co-adsorbate can yield HF_2^- etch species.

The talk will discuss four examples of HF selectivity: SiN_x etch vs SiO_2 non-etch; Si etch vs Si_3N_4 , SiCOH and SiO_2 non-etch; Si etch vs Si non-etch with co-adsorbed H_2O ; and SiO_2 non-etch vs SiO_2 etch with co-adsorbed NH_3 or $(\text{CH}_3)_2\text{NH}$ (dimethylamine). The experiments were conducted using *in situ* spectroscopic ellipsometry to monitor the film thicknesses during time to obtain etch rates. Additional quadrupole mass spectrometry (QMS) analysis was able to monitor the presence or absence of etch products during the experiments for Si etch vs Si non-etch with co-adsorbed H_2O .

Selective SiN_x etch vs SiO_2 non-etch was observed for HF etching at 275°C . Etch selectivity was measured for HF pressures from 0.5 to 9.0 Torr. SiN_x : SiO_2 etch selectivity approached a maximum of $150 : 1$ at 9.0 Torr. These results are consistent with F^- as the active etch species that yields SiN_x etching. Si etch vs Si_3N_4 , SiCOH and SiO_2 non-etch was also demonstrated for HF etching at 275°C and an HF pressure of 3 Torr. Crystalline Si etched at 23 \AA/min . In comparison, Si_3N_4 , SiCOH and SiO_2 etched at much smaller rates of 0.03 , 0.11 and 0.01 \AA/min , respectively. Much higher Si etch rates were observed at higher HF pressures at 275°C . The Si etch rate increased to 240 \AA/min at an HF pressure of 9 Torr.

Si etch vs Si non-etch with co-adsorbed H_2O illustrated the influence of polar co-adsorbed species on the etching. QMS experiments revealed that Si was etched by HF at a pressure of 1 Torr with a temperature threshold at $\sim 150^\circ\text{C}$. In contrast, co-dosing H_2O at a pressure of 1 Torr eliminated Si etching. These results suggest that F^- is the active etch species for Si etching. QMS experiments also identified the volatile etch products as H_2 and SiF_4 . SiO_2 non-etch vs SiO_2 etch with co-adsorbed NH_3 or $(\text{CH}_3)_2\text{NH}$ also

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supported the idea that polar co-adsorbates convert the HF active species to HF_2^- . Without polar co-adsorbates, F^- species do not etch SiO_2 . With polar co-adsorbates, HF_2^- species can etch SiO_2 .

2:30pm AP+PS+TF-WeA-2 ZrO₂ Thermal Atomic Layer Etching Using HF for Fluorination and TiCl₄ for Ligand Exchange: Effect of Processing Parameters, *Chen Li, Troy Coleran, University of Colorado Boulder; Beomseok Kim, Hanjin Lim, Samsung Electronics Co., Republic of Korea; Steven George, University of Colorado Boulder*

ZrO_2 thermal atomic layer etching (ALE) can be performed using sequential surface modification and volatile release reactions. HF fluorinates the ZrO_2 surface to form a ZrF_4 layer. TiCl_4 then undergoes ligand-exchange and volatilizes the ZrF_4 layer. In this study, the etch rate of ZrO_2 ALE was evaluated as a function of various processing parameters such as pressure, temperature and exposure time. The initial ZrO_2 films were grown by atomic layer deposition (ALD) using tetrakis(diethylamino) zirconium and H_2O . The processing parameters during ZrO_2 thermal ALE were examined using various techniques including quartz crystal microbalance (QCM), x-ray reflectivity (XRR), atomic force microscopy (AFM) and quadrupole mass spectrometry (QMS). In situ QCM experiments examined ZrO_2 ALE at HF pressures from 0.1 to 0.9 Torr with fixed TiCl_4 pressure and at TiCl_4 pressures from 0.2 to 2 Torr with fixed HF pressure. The mass of the ZrO_2 film decreased linearly with number of ALE cycles. The higher HF and TiCl_4 pressures led to higher ZrO_2 etch rates. However, self-limiting behavior was observed at both low and high HF and TiCl_4 pressures. The ZrO_2 etching rates were also observed to increase at higher temperatures. These results illustrate that self-limiting reactions can occur over a range of reactant pressures and temperatures. At higher reactant pressures, the QCM analysis measured mass change per cycle (MCPC) values that varied from -49.4 to $-118.6 \text{ ng}/(\text{cm}^2 \text{ cycle})$ at 200 and 300°C , respectively. These MCPCs correspond to ZrO_2 etch rates from 0.87 to $2.09 \text{ \AA}/\text{cycle}$ at 200 and 300°C , respectively. XRR measurements also confirmed the linear removal of ZrO_2 versus number of ALE cycles and the etch rates. AFM measurements also studied the roughness of crystalline ZrO_2 films after ALE. These crystalline films contained a mixture of monoclinic and tetragonal phases. The surface roughness increased with number of ALE cycles. However, higher precursor pressures at high temperatures produced a lower roughness increase. In addition, QMS analysis revealed the volatile etch products during the sequential HF and TiCl_4 exposures on ZrO_2 at 200 , 250 and 300°C . The signal intensity of the etch products increased at higher temperatures. H_2O was monitored during the HF exposure when HF fluorinates ZrO_2 to produce ZrF_4 . ZrCl_4 was observed as the etch product and TiFCl_3 was detected as the ligand-exchange product during the TiCl_4 exposure. These products confirm the ligand-exchange reaction between TiCl_4 and ZrF_4 . This project was supported by Samsung Electronics Co., Ltd (IO230707-06660-01).

2:45pm AP+PS+TF-WeA-3 SiO₂ Etching by HF in a Liquid-Like H₂O Layer in a Vacuum Environment, *Samantha Rau¹, Micah Duffield, University of Colorado at Boulder; Antonio Rotondaro, Hanna Paddubrouskaya, Kate Abel, Tokyo Electron America, Inc.; Steven George, University of Colorado at Boulder*

Adsorbed H_2O layers may be employed for etching by a liquid layer in a vacuum environment. Liquid-like H_2O layers can form at H_2O pressures around 10 Torr and temperatures around room temperature. Etchants may then be dissolved in the liquid-like H_2O layers. These conditions allow many etching processes that are conducted in wet aqueous solutions to be extended to liquid-like H_2O layers in vacuum.

This study focused on SiO_2 etching by HF in a liquid-like H_2O layer in vacuum. The experiments were conducted in a warm-wall vacuum chamber designed with a sample stage that allowed for H_2O liquid layer formation only on the cooled stage. The thickness of SiO_2 films was measured using *in situ* spectroscopic ellipsometry as the SiO_2 films were exposed to various H_2O and HF pressures at different substrate temperatures. Studies were conducted at H_2O pressures from 5 to 30 Torr, HF pressures from 2 to 6 Torr, exposures time from 2 to 20 s, and temperatures from 18.1 to 30.4°C . The SiO_2 films etched readily under these conditions.

The SiO_2 etch rate increased versus HF pressure. Figure 1 shows that as the HF pressure was increased from 2 to 6 Torr, at 30.4°C with a H_2O pressure of 15 Torr and exposure time of 5 s, the SiO_2 etch rate increased from $\sim 14 \text{ \AA}/\text{exposure}$ to $\sim 3315 \text{ \AA}/\text{exposure}$, respectively. The SiO_2 etching also increased versus H_2O pressure. Figure 2 shows that as the H_2O pressure was increased from 10 to 30 Torr, at 30.4°C with a HF pressure of 3.5 Torr and

exposure time of 5 s, the SiO_2 etch rate increased from $\sim 10 \text{ \AA}/\text{exposure}$ to $\sim 105 \text{ \AA}/\text{exposure}$, respectively. The dramatic variation in SiO_2 etch rates suggests that the thickness and composition of the liquid-like layer may be changing rapidly with HF and H_2O pressure.

The SiO_2 etch rate also increased versus exposure time. As the exposure time increased from 2 to 20 s, at 30.4°C with a H_2O pressure of 10 Torr and HF pressure of 3.5 Torr, the SiO_2 etch rate increased from $\sim 6 \text{ \AA}/\text{exposure}$ to $\sim 150 \text{ \AA}/\text{exposure}$, respectively. The SiO_2 etch rate was also inversely dependent on sample temperature. Experiments were conducted at temperatures of 30.4°C , 27.2°C , and 18.1°C with a H_2O pressure of 15 Torr, HF pressure of 3.5 Torr, and exposure time of 5 s. These studies yielded SiO_2 etch rates of $\sim 33 \text{ \AA}/\text{exposure}$, $\sim 1564 \text{ \AA}/\text{exposure}$, and $\sim 3456 \text{ \AA}/\text{exposure}$, respectively. The large increase of the SiO_2 etch rate is attributed to the thicker liquid-like layer at lower temperatures. The thicker liquid-like layer may be able to more easily solvate the HF reactants and SiO_2 etch products.

3:00pm AP+PS+TF-WeA-4 Wet-Like Atomic Layer Etching of WCN by Applying the Leidenfrost Effect to Obtain Floating Nanomist-Assisted Vapor Etching, *Thi-Thuy-Nga Nguyen, Nagoya University, Japan; Kazunori Shinoda, Kenji Maeda, Kenetsu Yokogawa, Masaru Izawa, Hitachi High-Tech Corp., Japan; Kenji Ishikawa, Masaru Hori, Nagoya University, Japan*

Semiconductor devices have been miniaturized to the nanometer scale. Work function metals, made from various metals like TiAlC, TiC, TiN, and WCN, are used in field effect transistor gate stacks. Precise control of isotropic and selective atomic layer etching (ALE) of thin metal gate materials in 3D nanostructures is crucial for the next-generation logic semiconductor devices. This requires minimizing damage from sputter effects in plasma ALE, high temperatures in thermal ALE, and pattern collapse in wet ALE. In our previous study, we developed a wet-like plasma etching method for a ternary metal carbide TiAlC [1]. This technique combines the advantages of wet etching (high isotropy and selectivity) and dry etching (high controllability). By using high-density vapor plasma at medium pressures, we generated a rich radical source of reactive species to significantly increase the reaction rate with the sample surface. This opens an avenue for developing our new dry ALE method, named wet-like ALE.

Here we have demonstrated the wet-like ALE for WCN material by sequentially exposing it to a rich radical source of O_2 plasma for surface oxidation at a relatively low temperature of less than 40°C and removal of the modified layer (WO_3) by dissolving it in a highly volatile nanomist flow. The proposed nanomist phase is a mist-vapor phase with properties between the mist liquid and vapor phases, maintaining the wet properties of the liquid phase at a minimal mist size for nanodevice applications. At the Leidenfrost point, the nanomist floats on its own stable vapor cushion film over the whole sample surface [2]. By using the Leidenfrost effect, the modified layer can be dissolved in a stable vapor film existing under the floating nanomist or in a floating nanomist-assisted vapor. The nanomists were generated from liquids by our originally developed non-contact atomizer at room temperature. The high removal rate of the modified layer (WO_3) was obtained at a temperature higher than 130°C that is considered as the Leidenfrost point of the nanomist produced from the aqueous liquid mixture, in which the WCN surface is supposed to be etched by the floating nanomist-assisted vapor at medium pressures. Self-limiting oxidation and removal of WCN by nanomist were achieved in both steps of the wet-like ALE cycle.

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We would like to thank Dr. Yoshihide Yamaguchi (Hitachi, Ltd., Japan) and Mr. KuangDa Sun (Nagoya University) for the previous discussions about Leidenfrost effect and mist generation, respectively.

[1] T.T.N. Nguyen *et al.*, *Sci. Rep.* **12**, 20394 (2022).

[2] B.S. Gottfried *et al.*, *Int. J. Heat Mass Transf.* **9**, 1167-1187 (1966).

3:15pm AP+PS+TF-WeA-5 Thermal Atomic Layer Etching of Hafnium-Zirconium Oxide (HZO) Using Organofluorides for Fluorination, *Aziz Abdulagatov, Jonathan Partridge, University of Colorado at Boulder; Matthew Surman, ASM Microchemistry Ltd., Finland; Steven George, University of Colorado at Boulder*

Thermal atomic layer etching (ALE) of various materials has previously been achieved using sequential fluorination and ligand exchange reactions where HF has been used as the fluorination source. In this work, organofluorides were employed as an alternative to HF. The thermal ALE of $\text{Hf}_{0.5}\text{Zr}_{0.5}\text{O}_2$ (HZO) was demonstrated using various organofluorides. The organofluorides were N,N-Diethyl-1,1,2,3,3-hexafluoropropylamine (Ishikawa's reagent (IR)), 1,1,2,2-tetrafluoroethylidemethylamine (TFEDMA) and diethylaminosulfur

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trifluoride (DAST). IR, TFEDMA and DAST are common deoxyfluorination reagents.

HZO ALE was demonstrated using organofluoride exposure in combination with ozone (O_3) and boron trichloride (BCl_3) exposures. Ozone was used to remove carbon residue resulting from organofluoride adsorption. BCl_3 was employed for ligand exchange with the fluorinated surface to form volatile Hf and Zr chlorides and BCl_xF_y products. BCl_3 can also undergo conversion with HZO.

In situ spectroscopic ellipsometry (SE) observed the linear decrease of HZO film thickness. Under similar reaction conditions at 270 °C, crystalline HZO films with a thickness of 10 nm displayed etch rates of 0.1, 0.2, and 0.5 Å/cycle, using IR, TFEDMA, and DAST, respectively. Etching amorphous HZO using IR yielded higher etch rates of 0.6 Å/cycle at 270 °C. The IR, O_3 and BCl_3 surface reactions were also determined to be self-limiting.

Quadrupole mass spectrometry (QMS) was also utilized to study the IR- O_3 - BCl_3 etch process on crystalline ZrO_2 powder at 270°C. During IR exposure, organic fragments and HF were detected indicating that HF is produced in situ by IR at 270 °C. During O_3 exposure, combustion products were observed from the oxidation of organic residuals left from IR exposures. During BCl_3 exposure, Hf and Zr chloride products, as well as BCl_xF_y products, were produced by the ligand-exchange reactions. Concurrently, boroxine ring ($B_3O_3Cl_3$) fragments were monitored and indicated the conversion of HZO to B_2O_3 .

3:30pm AP+PS+TF-WeA-6 Selective Atomic Layer Etching of SiO_2 over Si_3N_4 via TMA Surface modification and SF6 Remote Plasma, Jieun Kim, Min Kyun Sohn, Sun Kyu Jung, Min-A Park, Jin Ha Kim, Jaeseoung Park, Subin Heo, Sang-Hoon Kim, Jeong Woo Park, Seong Hyun Lee, Dongwoo Suh, Electronics and Telecommunications Research Institute, Republic of Korea
Precise etch selectivity between SiO_2 and Si_3N_4 is critical in advanced semiconductor fabrication processes, especially for applications such as spacer patterning in Gate-All-Around Field-Effect Transistors (GAAFETs) and multilayer structuring in 3D NAND devices. While selective etching of Si_3N_4 over SiO_2 has been widely studied using plasma chemistries such as $SF_6/H_2/Ar/He$, NF_3/O_2 , and $CF_4/O_2/N_2$ gas mixtures,¹⁻³ achieving atomic-scale precision in the reverse case —preferentially etching SiO_2 over Si_3N_4 —remains challenging.

In this work, we present an atomic layer etching (ALE) approach that enables highly selective etching of SiO_2 over Si_3N_4 through surface chemical engineering. The process sequence comprises four steps — trimethylaluminum (TMA) surface modification, Ar purge, SF₆ remote plasma exposure, and Ar purge—performed at 300 °C, 5 Torr, with an SF₆ flow rate of 50 sccm.

Under standard SF₆ plasma conditions, Si_3N_4 is typically etched more rapidly than SiO_2 due to the greater susceptibility of Si-N bonds to fluorine radicals. However, we found that incorporating a TMA surface modification step effectively inverts this trend. Chemical interactions at the surface are believed to yield Al-O-Si linkages on SiO_2 and Al-N-Si on Si_3N_4 , leading to distinct reactivities during subsequent F-radical exposure. The Al-O-Si sites promote the formation of volatile AlF₃ and SiF₄, whereas Al-N-Si structures exhibit much lower fluorine reactivity.

This chemistry-driven mechanism enabled a marked difference in etch per cycle EPC, with SiO_2 reaching 0.49 Å/cycle and Si_3N_4 reaching 0.05 Å/cycle, resulting in a selectivity close to 10:1. Whereas conventional atomic layer plasma etching using $CH_2F_2/O_2/N_2$ gas mixtures achieves selectivity through physical passivation or polymer deposition—often leading to surface damage or limited thickness control—our method, based on surface chemical modification and remote plasma exposure, enables damage-free etching and precise, layer-by-layer thickness control by decoupling chemical reactivity from ion bombardment. These findings suggest that surface modification-based selectivity tuning can serve as a viable strategy for precision etching in next-generation logic and memory device integration.

Reference

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4:15pm AP+PS+TF-WeA-9 Mitigating Redeposition in Directional Atomic Layer Etching of Lithium Niobate Using HBr Plasma, Ivy Chen, Caltech; Frank Greer, Jet Propulsion Laboratory (NASA/JPL); Austin Minnich, Caltech
Lithium niobate ($LiNbO_3$, LN) is a ferroelectric crystal of interest for integrated photonics owing to its large second-order optical nonlinearity and the ability to impart periodic poling via an external electric field. However, on-chip device performance based on thin-film lithium niobate (TFLN) is presently limited by propagation losses arising from surface roughness and corrugations. Atomic layer etching (ALE) could potentially smooth these features and thereby increase photonic performance. Previously, our group has reported the first isotropic ALE processes for lithium niobate. Here, we report a directional ALE process for x-cut MgO-doped LN using an HBr-containing plasma. At 0 degrees Celsius we report an 85% synergy ALE recipe with etch rate of 1.1 nm/cycle and surface roughening. At 200 degrees Celsius we report a reduced synergy at 30%, with an etch rate of 1.24 nm/cycle and no evidence of surface roughening. We also compare the surface roughness result of the HBr containing process with a chlorine-only process. Our ALE process could be to fabricate waveguide structures with nanometer precision without surface roughening or redeposition, thereby increasing the performance of TFLN nanophotonic devices and enabling new integrated photonic device capabilities.

4:30pm AP+PS+TF-WeA-10 Atomic Layer Etching of Sputter-Deposited AlN Thin Films in Cl2-Ar Plasmas, Iurii Nesterenko¹, Silicon Austria Labs GmbH, Austria; Jon Farr, Applied Materials, Inc.; Steffen Harzenetter, Applied Materials, Inc., Germany; Dmytro Solonenko, Benjamin Kalas, Thang Dao, Silicon Austria Labs GmbH, Austria; Julian Schulze, Ruhr University Bochum, Germany; Nikolai Andrianov, Silicon Austria Labs GmbH, Austria

Aluminum nitride (AlN) is a widely used material in micro- and nanoelectronics, particularly in photonics and MEMS devices. However, one of the critical challenges in the fabrication of AlN-based devices is achieving precise nanoscale etching while maintaining smooth surfaces and well-defined etch profiles. Atomic Layer Etching (ALE) is a promising approach to the above-mentioned problems, which are particularly crucial in photonic applications, where surface roughness and deviations in profile angles can result in optical losses and inefficient mode confinement.

This study investigates the ALE of AlN thin films deposited via sputter deposition on an 8-inch wafer. The wafer was diced into 2×2 cm coupons, which were then attached to a SiO_2 thermal oxide carrier wafer. The experiments were performed in an Applied Materials™ Centura™ DTM Chamber using Cl₂ and Ar gases for the modification (Cl step) and ion bombardment (Ar step) steps, respectively. The thickness of the AlN thin films was measured via spectroscopic ellipsometry (Semilab SE-2000). Also, the ion energy distribution function (IEDF) was analyzed using an ion energy analyzer (Impedance Quantum).

The feasibility of ALE for sputter-deposited AlN thin films was successfully demonstrated. The etch per cycle (EPC) was found to be approximately a single monolayer of the wurtzite AlN crystal structure (Fig.1). The ALE energy window was determined by analyzing the IEDFs in the Ar step, revealing the energy range of around 75 eV, which is consistent with the previously reported data in the literature [1]. Furthermore, measurements of the AlN sputtering threshold under Ar bombardment (Fig. 1) indicated minimal sputtering contributions, suggesting that the synergy of the process could approach 100%. Further investigations will be conducted to quantify this synergy more accurately. Moreover, it was determined that the process is linear, e.g. the EPC is constant against the number of cycles (Fig.2). The AlN RMS roughness after processing within the ALE energy window is around 570pm (Fig.3), which is lower than the original material roughness of 3nm.

Future work will also focus on optimizing the process by minimizing the duration of the Ar, Cl, and purge steps. The optimization of the Cl step will be complemented by X-ray Photoelectron Spectroscopy (XPS) to gain deeper insights into the surface chlorination mechanism.

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¹ JVST Highlighted Talk

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4:45pm AP+PS+TF-WeA-11 Sub-Surface TiO₂ Atomic Layer Etching (ALE)

Through W Films, *Hannah Margavio, Gregory Parsons*, North Carolina State University

The growing complexity of microelectronic architectures requires the development of novel atomic-scale fabrication techniques. Traditional semiconductor processing relies on separate deposition and etching steps. For example, a common fabrication technique known as etch-replacement deposition proceeds with W atomic layer deposition (ALD) and TiO₂ chemical vapor etching (CVE) occurring locally via SiH₄ and WF₆ exposure, yielding a W film thickness roughly equal to the removed TiO₂ film. In the etch replacement process, WF₆ converts TiO₂ into an intermediate solid phase, TiWO_xF_y, which becomes volatile upon further WF₆ exposure. Alternatively, TiWO_xF_y can be reduced by SiH₄, resulting in a W-rich film.

In this work, we address the need for advanced and unique processing for more complex metal nanostructures using atomic layer etching (ALE). We demonstrate the fabrication of intricate metal architectures via sub-surface etching of TiO₂ by controlling WF₆, MoF₆, and BCl₃ etching conditions after W ALD. First, 30 W ALD cycles were deposited on TiO₂/Si line patterns resulting in ~20 nm of W deposition on TiO₂. Following deposition, the film stack was exposed to 10, 80, and 150 WF₆ individual doses. After WF₆ exposure, it was found the W layer remained and the underlying TiO₂ layer was etched away as a function of CVE cycles, creating an air gap between the patterned TiO₂ lines and the W layer. We will show when additional WF₆ doses were exposed to the film stack, the air gap spacing increased. Similarly, MoF₆ doses after W ALD initiated sub-surface TiO₂ CVE. With MoF₆, we were able to elucidate the sub-surface etching mechanism via STEM EDS mapping; we observed metal fluoride diffused through the W film to react with the underlying TiO₂, while etch products diffused out. Compared to WF₆ and MoF₆ driven CVE, ALE using sequential WF₆ and BCl₃ doses accelerated etching and allowed greater control of TiO₂ removal. By integrating W ALD and TiO₂ ALE with sequential WF₆ and BCl₃ cycles on patterned TiO₂ structures, unique film stacks with tunable, uniform air gaps were fabricated.

5:00pm AP+PS+TF-WeA-12 Pulsed Plasma Strategies for High-Precision Pseudo-Atomic Layer Etching, *Maryam Khaji*, University of Michigan; *Qinzhen Hao, Mahmoud A. I. Elgarhy, Jeremy Mettler*, University of Houston; *Hyunjae Lee, Sang Ki Nam*, Mechatronics Research, Samsung Electronics Co, Republic of Korea; *Vincent Donnelly*, University of Houston; *Mark J. Kushner*, University of Michigan

Conventional plasma-based atomic layer etching (ALE) involves two self-limiting steps: passivation, where radicals (e.g., Cl) passivate the top layer of the substrate (e.g., silicon) to form SiCl_x; and etching, where the passivated layer is selectively removed by an ion-rich flux with its energy tuned to etch only the passivated material [1]. In spite of its high precision, ALE is time-consuming due to the need to evacuate the chamber between steps and so is challenged to incorporate into high volume manufacturing (HVM). Strategies are needed to maintain the precision of ALE while increasing its processing speed.

In this work, we report on a computational investigation of strategies to achieve rapid and precise Pseudo-Atomic Layer Etching (P-ALE) processes. This investigation is conducted for an inductively coupled plasma (ICP) reactor with RF or dc power applied to the substrate using Ar/Cl₂ mixtures for Si etching. Reactor scale plasma properties are addressed using the Hybrid Plasma Equipment Model (HPEM). Feature profile evolution is evaluated using the Monte Carlo Feature Profile Model (MCFPM) [2].

We will discuss strategies for P-ALE whose goal is to maintain the dual-process (passivation-etching) of conventional ALE while using a single gas mixture. These strategies use combinations of pulsed source (ICP) and bias powers, and electrode biasing, that produce a passivation phase where ion energies are low, and that appears to be ion starved; followed by rapid etch phase where additional passivation is low, and that appears to be neutral starved. To achieve these ends, plasma potential and dc bias must be carefully managed. Comparisons are made to experimental data.

This work was supported by Samsung Electronics and the Department of Energy Office of Fusion Energy Sciences.

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5:15pm AP+PS+TF-WeA-13 Development of Atomic Layer Etching Process

Dedicated to Diamond Electronic Devices, *Marine Régnier*, Univ. Grenoble Alpes, CNRS, Grenoble INP, Institut Néel; Institute of Applied Physics, University of Tsukuba; Japanese-French Laboratory for Semiconductor Physics and Technology J-FAST, CNRS, Univ. Grenoble Alpes, University of Tsukuba, France; *Aboulaye Traoré*, LSPM, CNRS, Université Sorbonne Paris Nord, France; *Marceline Bonvalot*, Univ. Grenoble Alpes, CNRS, Grenoble INP, LTM; Japanese-French Laboratory for Semiconductor Physics and Technology J-FAST, CNRS, Univ. Grenoble Alpes, University of Tsukuba, France; *Etienne Gheeraert*, Univ. Grenoble Alpes, CNRS, Grenoble INP, Institut Néel; Institute of Applied Physics, University of Tsukuba; Japanese-French Laboratory for Semiconductor Physics and Technology J-FAST, CNRS, Univ. Grenoble Alpes, University of Tsukuba, France

Diamond power devices, such as Schottky diodes and MOSFETs are currently being intensively investigated for possible application in power electronics and require dedicated fabrication processes to achieve adequate operating performances. Conventional etching techniques often lead to defects, surface roughness and sub-surface damages, which can significantly degrade carrier mobility and breakdown voltage of power devices. Thus, it becomes essential to develop diamond etching processes minimizing induced defects. Atomic layer etching (ALE) is a very soft etching technique involving two successive self-limiting and independent reactions. The first self-limiting reaction involves modifying the surface of a material by forming an ultra-thin reactive surface layer, while the second self-limiting reaction consists in the sputtering of the modified layer while keeping the underlayer intact. The repetition of these two reactions allows the removal of a layer of materials with a defect-free etched surfaces and sub-surfaces at atomic-scale precision. The first report of ALE of diamond dates back to 1988 [1], however, since then, no further studies have been reported.

In this work, the ALE process optimization of (100) diamond is presented. The ALE process is achieved by first modifying the surface and then using a soft plasma to induce the selective removal of this modified surface. Experiments have been performed in a standard inductively coupled plasma reactive ion etching equipment with in-situ plasma monitoring by optical emission spectroscopy. They have been characterized as a function of the etching rate per cycle (EPC) estimated from diamond etched depth after 100 ALE cycles. The impact of the incident ionic bombardment kinetic energy during the 2nd ALE reaction has been evaluated from the dc self-bias voltage (V_{DC}). Results show a clear plateau of approximately 5 V (Fig. 1), called ALE window, demonstrating the self-limiting effect of the etching process within one ALE cycle. The etching rate is of 7.1 Å per cycle, corresponding to the removal of two (100) diamond monolayers per cycle. Finally, synergy factor has been calculated. Synergy measures the effect of combining the two ALE steps. Separately, 100 cycles of step 1 then 100 cycles of step 2 leads to an etching rate of 4.0 Å per cycle. But 100 cycles of (1+2) steps lead to 7.1 Å per cycle, i.e. a synergy of 43%. This again demonstrate the effectiveness of the ALE process.

All these results will be presented in detail and discussed in the light of literature data.

References

[1] M.N. Yoder, Atomic Layer Etching, US4756794A, 1988.

5:30pm AP+PS+TF-WeA-14 Atomic Layer Etching for Vertical Trench Control and Electrical Optimization in HDLK Materials, *Sanghyun Lee, Keun Hee Bai*, Samsung Electronics, Republic of Korea

As device scaling continues, it becomes increasingly challenging to enhance device performance. In order to improve device performance, reducing resistance and capacitance in the BEOL (Back-End of Line) is especially important. Among various methods, minimizing damage to low-k dielectric materials during patterning processes has become a key challenge in BEOL integration. In this work, we suggest using Atomic Layer Etching (ALE) to overcome this problem, along with the selection of suitable low-k materials. ALE enhances controllability over surface reactions and profile formation by utilizing low ion energy, which enables the achievement of vertical profiles while simultaneously minimizing Plasma-Induced Damage (PID). The proposed ALE process utilizes a fluorocarbon-based surface modification step (C₄F₈), followed by a low-energy O₂ plasma step for selective carbon removal. This cyclic approach enables atomic-scale material removal with minimal physical damage, significantly reducing ion bombardment effects. To evaluate the effect of ALE on different low-k materials, we tested various High-Density Low-k (HDLK) samples with differences in k-value, modulus, and carbon composition. As a result, both low-k damage and vertical trench profile integrity were substantially

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improved, with smoother sidewalls and better verticality observed. The process performance was evaluated through detailed compositional analysis (XPS, EDX), PID characterization, and electrical measurements. The results confirmed that the proposed ALE method effectively reduced damage to low-k materials while enhancing profile control. Consequently, it demonstrates strong potential as a next-generation patterning solution for advanced BEOL integration.

5:45pm AP+PS+TF-WeA-15 Mechanisms of Atomic Layer Etching of Ni₃Al, Owen Watkins, Taylor G. Smith, University of California, Los Angeles; Jean-François de Marneffe, IMEC, Belgium; Jane P. Chang, University of California, Los Angeles

New metals and alloys are being investigated as potential replacements to TaBN in the absorber layer of extreme ultraviolet (EUV) lithography masks. Among potential candidates, Ni₃Al is particularly promising because it has both a high extinction coefficient and an index of refraction close to 1. A major hurdle in integration is anisotropically etching Ni₃Al selective to Ru, the 2-3 nm capping layer underneath the Ni₃Al absorber, with previously developed reactive ion etch and oxygen plasma-based atomic layer etch (ALE) having selectivities of 0.4 and 0.6, respectively. Better selectivity could be obtained through an ALE process based on cycles of nitrogen plasma, which does not spontaneously form volatile Ru compounds.

In this work, a Ni₃Al ALE process using nitrogen plasma, formic acid vapor, and Ar⁺ ion beam sputtering is investigated. The three step ALE process was shown to etch blanket Ni₃Al films at a rate of 1.0 nm/cycle. The self-limiting nature of the ALE process was examined by varying the duration of the nitridation, FA vapor, and Ar⁺ ion beam steps one at a time and measuring the resulting etch rate per cycle after 10 ALE cycles. These experiments showed that increasing the low energy Ar⁺ ion beam served only to remove residual formate from the surface prior to starting the subsequent ALE cycle and was not responsible for etching the Ni₃Al. The anisotropy of the Ni₃Al ALE process was examined using specially prepared samples of Ni₃Al deposited over patterned Si which had an initial sidewall Ni₃Al thickness of 17 nm. Scanning electron microscopy (SEM) showed that 30 ALE cycles redeposited material on the feature sidewalls, increasing the sidewall thickness to 34 nm at the bottom of the patterned feature and 21 nm near the top. The etch mechanism, particularly the volatile Al product, was investigated by comparing the etch rates of Ni, Ni₃Al, NiAl, and Al films. Ni etched at a rate of 1.3 nm/cycle¹ and Ni₃Al at a rate of 1.0 nm/cycle, while NiAl and Al were not etched by this ALE process. Because films with high Al content did not etch, Ni clearly plays a role in the removal of Al. Possible volatile etch products of Al therefore include a dimeric complex containing both a Ni and Al atom, or trimethylaluminum from Al reacting with CH₃ formed by Ni-catalyzed hydrogenation of formic acid. Finally, the etch rate of blanket Ru films was determined to be 0.5 nm/cycle, demonstrating a 2:1 selectivity between Ni₃Al and Ru—a major advance toward integration of Ni₃Al in EUV masks.

¹T.G. Smith, A.M. Ali, J.F. de Marneffe, J.P. Chang, *JVSTA* **42**, 022602 (2024).

6:00pm AP+PS+TF-WeA-16 In-situ Comparative Analysis of Surface Reactions During Isotropic Atomic Layer Etching of TiC under Various Plasma Chemistries and Infrared Heating, Kazunori Shinoda, Hitachi High-Tech Corporation, Japan; Thi-Thuy-Nga Nguyen, Nagoya University, Japan; Dai Ishikawa, Kenetsu Yokogawa, Masaru Izawa, Hitachi High-Tech Corporation, Japan; Kenji Ishikawa, Masaru Hori, Nagoya University, Japan

As integration density increases, field-effect transistors (FETs) have evolved from two-dimensional planar structures to three-dimensional FinFETs, with gate-all-around (GAA) structures now emerging at advanced technology nodes. To enable continued scaling, complementary FETs (CFETs) are being investigated as the next step beyond GAA. This structural progression has intensified interest in isotropic atomic layer etching (ALE), which offers atomic-level dimensional control critical for fabricating advanced three-dimensional semiconductor structures. In response to this demand, a thermal-cyclic ALE process has been developed, incorporating cyclic plasma exposure and infrared (IR) heating for surface modification and layer removal. A 300-mm dry chemical removal (DCR) tool was engineered to implement this process. Using this system, selective isotropic ALE has been demonstrated for materials including Si₃N₄, SiO₂, TiN, W, and Co. This study presents a comparative analysis of surface atomic-layer reactions during TiC ALE using various fluorocarbon-based plasma chemistries. In-situ X-ray photoelectron spectroscopy (XPS) was employed to characterize surface chemical bonding states, while in-situ spectroscopic ellipsometry was used to monitor etching performance during cyclic processing. The experimental setup comprised a radical irradiation chamber and an XPS analysis chamber, connected via a high-vacuum transfer system to preserve surface integrity.

Exposure to radicals generated from fluorocarbon-based gas mixtures resulted in the formation of surface-modified layers containing Ti-F bonds. Exposure to radicals generated from nitrogen-containing fluorocarbon-based gases led to the appearance of N-H bonds, with a binding energy centered at 402 eV. This reaction pathway is analogous to that observed in TiN ALE, where the surface-modified layer was tentatively identified as containing ammonium salt-based species. These layers were effectively removed by IR heating. Repetitive cycles of plasma exposure and IR heating produced a linear increase in TiC etching depth with cycle count. The etch per cycle (EPC) varied with plasma chemistry, typically ranging from 0.9 to 1.4 nm/cycle under optimized conditions. Saturation behavior with respect to radical exposure time confirmed the self-limiting nature of the process. Throughout the ALE cycles, the etched TiC surfaces remained smooth.

Chemical Analysis and Imaging at Interfaces

Room 205 ABCD W - Session CA-WeA

Advances in Experimental and Theoretical Insights Into Material Interfaces

Moderators: Jiyuong Son, Oak Ridge National Laboratory, Samuel Tenney, Brookhaven National Laboratory

2:15pm CA-WeA-1 Exploring Technologically Relevant Interfaces with Advanced Spectroscopy and Surface Techniques: Chemical Analysis Under Reaction Conditions Meets 2-D Electron Gas Materials, Patrick Lömker, Daniel Beaton, Andrew Yost, Timo Wätjen, Scienta Omicron

Unraveling reaction paths and identifying rate limiting steps are essential ingredients in furthering the understanding of catalytic reactions and to enable rational design thereof. Reactions that are at the heart of society – think fertilizer, plastics, pharmaceuticals and fuels – and are undergoing a paradigm shift due to climate concerns. While X-ray photoelectron spectroscopy with direct sample access is well established in the pressure regimes up to the tens of milibars, utilizing hard X-rays excites electrons with a long inelastic mean free path (IMFP) and thus enables studies at radically higher pressures, often required to investigate reactions in real conditions. Ambient Pressure X-ray Photoelectron Spectroscopy (APXPS, often also AP-XPS) enables the study of catalytic reactions under *operando* conditions. This technique, typically available both in laboratory and synchrotron settings, is adapted to reveal the workings in the 10s of mbar regime where many reactions can be studied, however especially solar cell materials and photocatalysis are moving into the spotlight here. By utilizing hard X-rays and advancing the technique further (the bar pressure regime can be accessed, while still accessing surface and near-surface chemical information. In this presentation, an overview of AP- and BAR-XPS studies is given where we detail the catalysis of reduction for thermal CO (Fischer-Tropsch), nitrogen(Haber-Bosch) and electrochemical CO₂ (closing the cycle). The BAR-XPS studies have been demonstrated at up to 2.5 bar, excitation energies of up to 9.8 keV, and more than eight years of continuous, reliable performance. Its innovative inlet geometry and the intense photon flux from PETRA III have been key to these advances. But with the advent of 4th generation synchrotron facilities, BAR-XPS-type instruments will be well positioned to fully exploit these capabilities, making high-pressure AP-XPS experiments more routine and widely accessible. In this presentation I will share with you results obtained on *operando* studies of Haber-Bosch and Fischer-Tropsch synthesis reactions at up to 1 bar, exemplifying the kind of real-world chemical systems that BAR-XPS is built to explore. Further, the growing demands on electronics in view of energy use, efficiency and processing speed make it necessary to study *operando* surfaces of 2-dimensional electron gas materials in view of GaN integration on Si. KEYWORDS HAXPES, XPS, catalysis, *operando*, AP-XPS, high-pressure, BAR-XPS, STM, 2DEG, GaN

2:30pm CA-WeA-2 Optimizing in situ liquid ToF-SIMS using SALVI and IONTOF M5-NCS, Jiyuong Son, Anton Levlev, Jacob Shusterman, Xiao-Ying Yu, Oak Ridge National Laboratory

In situ time-of-flight secondary ion mass spectroscopy (ToF-SIMS) was enabled to study liquids using a vacuum compatible microfluidics device. This approach has brought a wider range of sample analysis capabilities in vacuum instrumentation, specifically applications in interfaces involving the condense liquid phase. The successful operation of *in situ* ToF-SIMS also has been presented previously using an IONTOF V instrument. We establish *in situ* liquid ToF-SIMS using the IONTOF M5-NCS instrument at the Oak Ridge National Laboratory (ORNL). Several parameters in the instrument setting (i.e., Primary beam current, voltage, pulse mode) were modified to

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optimize signal intensity and obtain more effective data collection in a wide mass range. A systematic study was performed including LMIG aperture, tip material of primary gun, primary beam current, voltage, and microfluidic device condition. If just following the procedure for the IONTOF V instrument, *in situ* liquid SIMS data suffered from low secondary ion intensity and only a narrow mass range was available for spectral and image collection. To acquire higher secondary ion counts, one procedure is not possible to "fit for all" for different ToF-SIMS instruments. In this work, we will present findings of *in situ* liquid ToF-SIMS optimization using the IONTOF M50NCS platform located in the center for nanophasic materials science (CNMS) at ORNL. We demonstrated higher mass resolution in liquid SIMS spectral acquisition using the LIMG buncher voltage mode. Higher total secondary ion counts per sec (~40k ions / sec) with altering single pulse width of the LMIG primary beam was also achieved. The optimized *in situ* liquid SIMS procedure will be used to study complex interface chemistry in the future.

2:45pm CA-WeA-3 First Principles-Based Defect Engineering to Enhance Layered Ni-rich Cathode Performance, Sumaiyatul Ahsan, Faisal M. Alamgir, Georgia Institute of Technology, USA

We present a strategy to enhance the capacity retention of Ni-rich cathodes by modifying the electronic structure via an oxygen-vacant surface layer. Rather than addressing external factors that result in surface coatings for protection against electrolytic attack, we emphasize that intrinsic issues with electronic structure can also contribute to degradation, making materials more vulnerable in the first place. Our DFT calculations show that introducing oxygen vacancies (OV) in LiNiO₂ stabilizes reactive Ni²⁺ ions and reduces the overlap between O2p and Ni3d orbitals. To validate our predictions, we examined NMC811 (LiNi_{0.8}Mn_{0.1}Co_{0.1}O₂), known for its high initial capacity but tendency for capacity loss. An *in-situ* annealing XRD reveals the optimal temperature range for surface OV formation while retaining the layered bulk structure. Then, a one-step thermal treatment was employed to create a core-shell structure with 6.9% surface OV, resulting in a 9.4% improvement in capacity retention over 100 cycles at 1C compared to the unmodified sample. Scanning Transmission Electron Microscopy (STEM) visualized the vacancies and edge defects, and we implemented a quality control framework using XPS, tabletop XRD, and lab-scale h-XAS for efficient measurement of cation disorder, OV concentration, and bulk homogeneity. Our study on LNO and NMC811 demonstrates that employing OV to tune the electronic structure provides a universal solution for capacity fading in Ni-rich cathodes.

3:00pm CA-WeA-4 Infrared Nanoscopy of Electron-Beam Modified Metal Organic Frameworks, Samuel Tenney, Brookhaven National Laboratory; Andrea Kraetz, Johns Hopkins University; Prerna Prerna, Ilja Siepmann, University of Minnesota; Michael Tsapatsis, Johns Hopkins University

Metal organic frameworks (MOFs) are a class of porous materials that are promising for applications in many areas including gas separations and sorptions. Some MOFs, such as ZIF-L, can be chemically modified by exposure to an electron-beam to tailor their properties. This chemical modification by electron-beam exposure is known to modify their solubility among other properties. The modified MOFs have been characterized with nanoscale infrared techniques, namely photothermal infrared (PTIR) or AFM-IR and optical-photothermal infrared (O-PTIR), to understand the chemical changes that happen and the possible application of these materials towards gas separation. The results show a two-step process in the chemical modification of the MOFs with increasing electron-beam exposure.

3:15pm CA-WeA-5 Probing the Electronic-Ionic-Mechanical Coupling at Solid-Electrolyte/Electrode Interfaces, Yue Qi, Brown University INVITED

Electrochemical interfaces are critical components of energy conversion and storage devices. In solid-state batteries, the electrode/electrolyte interfaces must enable fast charge transfer reactions while maintaining physical contact throughout cycling. To probe the highly coupled electrochemical, mechanical, and physical responses and their evolution at these interfaces, multiscale modeling and multimodal characterization must work hand in hand.

At well-contacted interfaces, we draw an analogy to electron transport at metal/semiconductor interfaces and develop a density functional theory (DFT)-informed band-alignment model for intrinsic ionic resistance. This model incorporates DFT-computed electronic and point defect properties of the contacting phases to predict space-charge layer formation, potential drop, and electrostatic dipole at the electrode/solid-electrolyte interface. It is essential for interpreting *in operando* Kelvin probe force microscopy (KPFM) measurements of local potential profiles across interfaces of solid-

state batteries—especially considering the dependence on lithium concentration and applied electric potential. To further probe band bending at buried interfaces, depth-resolved cathodoluminescence spectroscopy (DRCLS) is being developed to enable non-destructive characterizations.

Extrinsic interface resistance arises from changes in the contact area, which naturally decreases during Li stripping at Li/solid electrolyte interfaces. To capture the governing mechanisms across multiple length and time scales—including interface interactions, vacancy hopping, and plastic deformation, we integrated DFT simulations, kinetic Monte Carlo (KMC) methods, and continuum finite element modeling (FEM). By assuming the self-affine nature of multiscale contacts, we predicted the steady-state contact area as a function of stripping current density, interface wettability, and stack pressure. These predictions are supported by high-spatial-resolution *operando* scanning electron microscopy.

Together, these modeling advances are being integrated into a comprehensive framework to guide the design and development of next-generation all-solid-state batteries and electrochemical random-access memory (ECRAM) devices.

Electronic Materials and Photonics

Room 207 A W - Session EM1+AP+CPS+MS+PS+SM+TF-WeA

Materials and Devices in Emerging Memories

Moderators: M. David Henry, Sandia National Labs, Philip Lee, University of Kentucky

2:15pm EM1+AP+CPS+MS+PS+SM+TF-WeA-1 Impact of Precursor Purge Time on the Performance of Ferroelectric Hf0.5Zr0.5O2 Prepared by Plasma-Enhanced Atomic Layer Deposition, Yong Kyu Choi, Benjamin Aronson, Megan Lenox, Liron Shvilberg, University of Virginia, USA; Chuanzhen Zhou, North Carolina State University; Kristina Holsgrave, Queen's University Belfast, UK; Amit Kumar, Queen's University Belfast, UK; Andrea Watson, Stephen J. McDonnell, Jon F. Ihlefeld, University of Virginia, USA

Hafnium oxide (HfO₂) shows significant potential for non-volatile memory and energy harvesting applications. However, its monoclinic phase lacks polarization, making it unsuitable for ferroelectric applications. Introducing ZrO₂ into HfO₂ (HZO) helps stabilize a ferroelectric phase. Atomic layer deposition (ALD) is the most widely used film processing technique, offering excellent thickness control, conformability, and relatively low processing temperature. Previous research has explored the impact of various metal precursors, oxidizer precursors, and process temperatures on the ferroelectric properties of HZO. One common observation is that the metal precursor purge time has a large effect on the resulting film phase and performance. However, no clear mechanism has been identified to explain this effect. In this presentation, we will discuss how HZO thin film properties change when the metal precursor purge time varies during plasma-enhanced ALD. Reducing the metal precursor purge time from 90 s to 3 s induced a transition from ferroelectric to antiferroelectric properties with double polarization hysteresis loops, higher endurance and polarization stability, and slightly increased in relatively permittivity. Infrared spectroscopy measurements (FTIR-ATR) confirmed that the antiferroelectric properties are due to the antipolar orthorhombic o-I phase, which is consistent with observations from HRTEM and DPC-STEM. The films deposited with shorter purge times showed carbon impurities as identified by ToF-SIMS analysis. This suggests that residual chemical ligands from incomplete precursor removal during the ALD process, in part, stabilizes the antipolar o-I phase. These results show that phase stability in fluorite oxides is influenced by impurities beyond intentional substituents and that stable antiferroelectric responses can be achieved without deliberately altering the material composition, such as adjusting the Hf:Zr ratio to control phase formation.

2:30pm EM1+AP+CPS+MS+PS+SM+TF-WeA-2 Effect of Atomic Layer Annealing Duration on Phase Stabilization of Hafnium Zirconium Oxide Thin Films, Nicolas Lam, University of Virginia; Gerald Beiger, John Barber, Virginia Tech; Megan Lenox, Liron Shvilberg, University of Virginia; Christina Rost, Virginia Tech; Jon Ihlefeld, University of Virginia

Significant research has gone into understanding the stabilizing mechanisms and properties of ferroelectric hafnia. This is largely due to its ability to display ferroelectricity in size scales below 10 nm, incorporation in already existing mass production infrastructure, and complementary metal oxide semiconductor compatibility. Today, hafnium zirconium oxide (HZO) is

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the most studied hafnia alloy due to its low processing temperature. However, the widespread implementation of HZO as a memory material is hindered by a variety of challenges, such as wake-up, imprint, and retention. A major issue is the inability to make phase pure ferroelectric HZO, a metastable non-centrosymmetric polar orthorhombic structure. Commonly cited impurity phases include the metastable tetragonal, antipolar orthorhombic, and equilibrium monoclinic phases. Previous work using the atomic layer annealing (ALA) technique has shown enhanced crystallinity and remanent polarization in pristine HZO films, circumventing significant formation of the antiferroelectric and tetragonal phases. In this work, thin films of HZO were grown using the ALA technique with various ALA treatment durations, ranging from 0 s up to 59 s. Following a deposition of a metal oxide layer using plasma-enhanced atomic layer deposition, the surface of the film was subjected to additional argon plasma. After synthesis and a post-metallization anneal to form the metastable phase, various structural and electrical measurement techniques were used to characterize the films. Grazing-incidence X-ray diffraction shows no formation of the equilibrium monoclinic phase; Fourier transform infrared spectroscopy shows increasing ferroelectric phase concentration with ALA time. Polarization hysteresis measurements show an increasing hysteretic response with ALA time as compared to an antiferroelectric reference sample. Positive up negative down measurements quantified the relative amount of wake-up. The reference devices displayed a 200% increase in remanent polarization while the ALA samples displayed an 8% relative increase with the longest treatment time. The results suggest that ALA can modify the local environment of the deposited films, such that the phase fraction of the ferroelectric phase and the amount of wake-up can be tuned. This results in devices that exhibit minimal to no wake-up. This work furthers the understanding of the effect that ALA has on the resultant film's properties.

2:45pm **EM1+AP+CPS+MS+PS+SM+TF-WeA-3 Understanding Time-Dependent Imprint in Hafnium Zirconium Oxide Based Ferroelectric Tunnel Junctions, Megan Lenox, University of Virginia, USA; Samantha Jaszewski, Sandia National Laboratories; Jon Ihlefeld, University of Virginia, USA; M. David Henry, Sandia National Laboratories, USA**

While research into understanding the performance-materials property relationship of hafnium zirconium oxide (HZO) based devices has been accelerated in the past decade, their integration into microelectronic products is challenged by their endurance and imprint behavior. Imprint, or a shift in the coercive field following polarization with an initial applied field, lowers HZO remanent polarization (P_r) along the imprint direction, impacting the current transport mechanisms and reducing the overall performance stability when studied in ferroelectric non-volatile memory applications. In these devices, imprint has been hypothesized to result from charge carrier migration at the electrode interface, increasing the charge needed for polarization switching. However, the mechanisms responsible for imprint in ferroelectric tunnel junctions (FTJ) is not understood. To study FTJ imprint phenomena, 7 nm $\text{Hf}_{0.7}\text{Zr}_{0.3}\text{O}_2$ devices with NbN and Nb as the top and bottom electrode, respectively, were fabricated. Polarization-electric field measurements were performed every 2^n seconds, showing a $+V_c$ shift with time.

Resistance measurements, using a pulsing scheme composed of a $\pm V_{\text{max}}$ write pulse followed by fifty 0.4 V read pulses at various pulse widths taken every 2^n seconds, showed a drift in the ratio of high and low resistance states, and an overall reduction in the binary state memory window with increasing time, characteristic of imprint. Further, these results highlight imprint impacts on multi-state polarization switching used in neuromorphic memory applications. To investigate imprint mechanisms, pulsed hysteresis measurements taken in 0.1 V intervals followed by a reset pulse at $\pm V_{\text{max}}$ showed an 18.1x change in the resistance ratio between the high and low resistance states. However, a similar pulsed hysteresis measurement without the reset pulse had a 11.4x resistance ratio. These results support the generation of time-dependent imprint-free HZO-based FTJs by utilizing selective pulsing schemes, promoting their use in next-generation microelectronics.

Sandia National Laboratories is a multimission laboratory managed and operated by National Technology and Engineering Solutions of Sandia LLC, a wholly owned subsidiary of Honeywell International Inc. for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA0003525. This work is supported by the Center for 3D Ferroelectric Microelectronic Manufacturing (3DFeM2), an Energy Frontier Research Center funded by the U.S. Department of Energy, Office of Science, Office of Basic Energy Sciences Energy Frontier Research Centers program under Award Number DE-SC0021118.

3:00pm **EM1+AP+CPS+MS+PS+SM+TF-WeA-4 Disentangling Gamma-Ray Radiation Effects and Time-Dependent Imprint on Ferroelectric Hafnium Zirconium Oxide-Based Devices, Samantha Jaszewski, Sandia National Laboratories; Megan Lenox, Jon Ihlefeld, University of Virginia; M. David Henry, Sandia National Laboratories**

Ferroelectric hafnium oxide (HfO_2) enables technological developments in microelectronics, such as the scaling of ferroelectric random-access memory (FeRAM) and new devices like ferroelectric field-effect transistors (FeFETs) and ferroelectric tunnel junctions (FTJs) that were not previously possible with conventional ferroelectrics. This is due to the material's compatibility with silicon and its ability to exhibit a ferroelectric response in films as thin as 1 nm. Understanding the interaction between radiation and ferroelectric HfO_2 -based devices is necessary before these devices can be utilized in radiation-hostile environments. In the literature, it has been reported that gamma-ray radiation can result in a shift of the coercive voltage of ferroelectric HfO_2 -based devices, impacting the memory window and, thus, the reliability of these devices. However, ferroelectric HfO_2 -based capacitors have also been shown to exhibit a time-dependent imprint effect in which the coercive voltage shifts over time as a result of the depolarization field in the film, which drives charge redistribution in the ferroelectric layer. As such, it can be challenging to disentangle the effects of gamma-ray radiation and the time-dependent imprint shift when evaluating the performance of these devices.

In this work, ferroelectric hafnium zirconium oxide (HZO) capacitors and ferroelectric tunnel junctions (FTJs) are subjected to 1 and 5 Mrad doses of gamma-ray radiation under grounded and biased conditions. X-ray diffraction and Fourier-transform infrared spectroscopy measurements demonstrate that gamma-ray radiation does not result in phase transformations, further confirmed by capacitance-voltage measurements, which show that the relative permittivity of the HZO capacitors does not change after radiation. Polarization-electric field measurements show shifts in the coercive field after radiation. However, it will be shown that these coercive voltage shifts are due to time-dependent imprint in the material rather than the effects of gamma-ray radiation. This work demonstrates that the structural and electrical properties of ferroelectric HZO-based capacitors and FTJs are not affected by gamma-ray radiation up to doses of 5 Mrad. It also underscores the importance of careful measurement procedures and analysis when evaluating radiation effects in this material.

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Electronic Materials and Photonics

Room 207 A W - Session EM2+AP+NS+TF-WeA

Advances in Materials and Devices for Energy Storage

Moderators: Claire Davis-Wheeler Chin, Sandia National Lab; Alexander Kozen, University of Vermont

3:15pm **EM2+AP+NS+TF-WeA-5 In-Situ Characterisation of Solid Electrolyte Interphase Formation on Lithium Metal for Energy Storage, Anthony Somers, Deakin University, Australia**

The Solid Electrolyte Interphase (SEI) is a complex passivating layer that forms on the anode in the early stages of battery cycling. Ideally this layer should protect the anode from degradation while allowing the ions of interest to freely move through with high efficiency. To ensure long cycle life this layer also needs to be stable over hundreds of charge/discharge cycles. For the safe and successful operation of promising new battery technologies, such as lithium metal, information on how electrolyte composition effects the SEI is needed.

Most analysis of the SEI is ex-situ, making it difficult to identify the processes occurring during the initial formation phase. While there are a range of in-situ and operando techniques that have been used to investigate SEI formation, there is often a lack of cross-checking between techniques to confirm findings or determine all processes involved.

In this work a range of in-situ, operando and ex-situ techniques have been used to identify the mechanisms of SEI formation in relation to cycling performance for lithium metal batteries with ionic liquid containing electrolytes. To achieve this, techniques able to detect early subtle changes at the electrode, such as electrolyte rearrangement and organic adsorption, as well as the final reactions that lead to the formation of inorganic, passive

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layers have been used. Measurements such as operando FTIR spectra, in-situ differential capacitance and electrochemical quartz crystal microbalance and ex-situ XPS are used to form this more complete picture of the processes involved in SEI formation.

3:30pm EM2+AP+NS+TF-WeA-6 Intercalation of Polyacrylonitrile Nanoparticles in Ti₃C₂T_x MXene Layers for Improved Supercapacitance, Shanna Marie Alonso, Bishnu Bastakoti, North Carolina A&T State University

We report the intercalation of polyacrylonitrile nanoparticles in Ti₃C₂T_x MXene layers through simple sonication. The use of polyacrylonitrile, which was synthesized via radical polymerization, offered dual benefits: (1) It increased the interlayer spacing of MXene, thereby exposing more surface area and enhancing ion transport channels during charge and discharge cycles, and (2) Integrating MXene with polyacrylonitrile enables the creation of a composite with conductive properties, following percolation principle. X-ray diffraction analysis showed an increase in the c-lattice parameter, indicative of the interlayer spacing, from 22.31 Å for the pristine MXene to 37.73 Å for the MXene-polyacrylonitrile composite. The intercalated polyacrylonitrile nanoparticles facilitated the delamination by weakening the interlayer interactions, especially during sonication. Electrochemical assessments revealed significant improvement in the properties of the MXene-polyacrylonitrile composite compared to the pristine MXene. The assembled asymmetric device achieved a good specific capacitance of 32.1 F/g, an energy density of 11.42 Wh/kg, and 82.2% capacitance retention after 10,000 cycles, highlighting the practical potential of the MXene-polyacrylonitrile composite.

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Room 207 A W - Session EM3+TF-WeA

Materials and Devices for Advanced Photonics and Plasmonics

Moderator: Erin Cleveland, Laboratory of Physical Sciences

4:15pm EM3+TF-WeA-9 Writable and Spectrally Tunable Cadmium Oxide Plasmonics via Gallium-Ion Implantation, Maxwell Tolchin¹, The Pennsylvania State University; Bhaveshkumar Kamaliya, McMaster University, Canada; Angela Cleri, The Pennsylvania State University; Youngji Kim, Vanderbilt University; Morvarid Ghorbani, McMaster University, Canada; Anton levlev, Center for Nanophase Materials Sciences, Oak Ridge National Laboratory; Nabil Bassim, McMaster University, Canadian Centre for Electron Microscopy, Canada; Joshua D. Caldwell, Vanderbilt University, Sensorium Technological Laboratories; Jon-Paul Maria, The Pennsylvania State University

Ion beam engineering is a promising field to advance plasmonic and nanophotonic technologies. At high (1s to 10s MeV) and low (10s to 100s keV) ion beam energies, semiconductor chemistries can be modified and constructed into spatially and spectrally coherent devices. A direct beneficiary to ion beam engineering is cadmium oxide (CdO) thin film plasmonics. High-throughput CdO thin films grown by high-power impulse magnetron sputtering (HiPIMS) have an intrinsic affinity for oxygen vacancy formation. Thereby, achieving carrier concentrations of 1.6 to 3.5 × 10¹⁹ cm⁻³ while maintaining mobilities of 235 to 290 cm²V⁻¹s⁻¹. By the carrier concentration to plasma frequency relation using Drude formalism, spectral ranges can span the mid-wave infrared (MWIR) spectrum. This is evident by reactively co-sputtering HiPIMS CdO with extrinsic dopants (i.e., Y, In, F) to extend carrier concentrations and mobilities to 5 × 10²⁰ cm⁻³ and 470 cm²V⁻¹s⁻¹, respectively. These capabilities realize CdO as a highly programmable, low-loss material system with a chemical bandwidth to sustain high crystallinity and structural resilience. Herein, and enabled by the chemical flexibility of CdO and need for localized and wavelength-tunable plasmonics, 30 keV gallium-ion (Ga⁺) implantation is employed. Using a focused ion beam scanning electron microscope (FIB-SEM), thermally activated Ga⁺ implants facilitate shallow, donor-doped CdO at ion doses ranging from 1 × 10¹⁴ to 1 × 10¹⁶ ions/cm². Beam tilting techniques and iterative thermal activation conditions achieve site-specific and spectrally defined architectures. Microscopy and spectrometry support high-homogeneity Ga⁺ distribution and characteristic morphology in CdO. Near- and far-field spectroscopy show observable changes to phonon and

plasmon resonances affiliated with Ga-doping behavior. An innovative beam-stitching process affords larger pattern designs to demonstrate Hall Effect transport properties of 1.3 × 10²⁰ cm⁻³ and 372 cm²V⁻¹s⁻¹. In summary, spectral tunability by Ga⁺ implantation is on-par with optoelectronic properties seen in extrinsically doped-CdO thin films with an added dimensionality of spatially-controlled dopant writability. And, this work acknowledges the reliability of ion implantation doping for next generation plasmonics and nanophotonics by ion beam engineering.

4:45pm EM3+TF-WeA-11 Nano-Plasmonics for Hybrid, Far IR Photodetection: Simulation and Fabrication, Basil Vanderlei, Samuel Fedorka, Charles Dickerson, John McElearney, Tufts University; Corey Shemelya, Government; Thomas Vandervelde, Tufts University

Far infrared avalanche photodetectors are typically cryogenically cooled to negate thermally excited carriers from being generated in the absorption region which limits potential applications. To remove the need for cryogenic equipment a possible option is the removal of the absorption region and replacement with plasmonic nano-antennas and direct carrier injection. In this work we explore novel methods, materials, and geometries to promote direct injection and anisotropic progression of carriers into the avalanche region of a III-V PIN diode. Our proposed designs were verified by simulation with CST Microwave Studio for electromagnetics and COMSOL Multiphysics for carrier dynamics. Additionally, we have developed a unique fabrication plan for both the multi-axis junction and plasmonic resonator, as well as structures resonant in the RF regime for the purposes of a feasibility study.

Magnetic Interfaces and Nanostructures

Room 209 F W - Session MI+2D-WeA

Magnetic Interfaces and Nanostructures Oral Session

Moderators: Valeria Lauter, Oak Ridge National Laboratory, Hendrik Ohldag, Lawrence Berkeley National Laboratory

2:15pm MI+2D-WeA-1 Probing Heterogeneity in 2D van der Waals Materials via Cryogenic STEM, Miaofang Chi, Joy Chao, Haoyang Ni, Oak Ridge National Laboratory

INVITED

Quantum materials exhibit unique phenomena and functionalities that extend beyond classical physics. The use of 2D sheets and the construction of hetero- and moiré structures have emerged as promising approaches to inducing exotic quantum effects. However, studying these materials via cryogenic scanning transmission electron microscopy (STEM) and electron energy loss spectroscopy (EELS) has traditionally been limited by stage instability. Recent advancements in stage design by manufacturers now provide new opportunities for this research. In this talk, I will present our ongoing studies using atomic-scale cryogenic STEM and monochromated EELS to investigate the coupling between lattice and electronic structures in several representative 2D van der Waals materials relevant to magnetic storage and spintronic applications. One key example is the discovery of layer-number-dependent phase transitions in CrCl₃ during cooling. Another is the impact of defects and secondary phases on the magnetic structure evolution of Fe_{5-x}GeTe₂ (FGT-512). Additionally, we have mapped local excitons in moiré-structured MoTe₂. These studies demonstrate that the electronic and magnetic properties of 2D materials can be tuned by controlling the layer number or engineering moiré structures. They also highlight the power of combining high-resolution cryogenic STEM imaging and spectroscopy to advance the understanding of quantum materials.[1]

[1] This work was supported by the U.S. Department of Energy, Office of Science, Basic Energy Sciences, Materials Sciences, and Engineering Division and was performed at the Center for Nanophase Materials Sciences at ORNL.

2:45pm MI+2D-WeA-3 Examining the influence of magnetic and electron beam probes on the topologically-protected edge states of 2D Bi₂Te₃ Nanoplates, Timothy Carlson², Swathi Kadaba, Wake Forest University; Gabriel Marcus, Quocherent; Motahareh Mirhosseini, David Carroll, Wake Forest University

In this work well defined, stoichiometric two-dimensional (2D) nanoplates of the topological insulator, Bi₂Te₃, were imaged using magnetic force microscopy (MFM), atomic force microscopy (AFM), and high resolution transmission electron microscopy (HRTEM) including techniques such as electron energy loss spectroscopy (EELS) and cross sectional TEM. Nanoplates with a diameter range of 0.5 to 1.5μm and ~6-15nm thick were supported on highly order pyrolytic graphite (HOPG) for the scanning

¹ JVST Highlighted Talk

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² JVST Highlighted Talk

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probes and ultra thin, lacy TEM grids for the electron probes imaging and spectroscopy. In the case for the MFM experiments, the relative strength of the edge-fields were characterized by adjusting the lift heights resulting in a unique relationship between the magnetic probe and the nanoplates under observation. For the EELS experiments, the data was collected on the edges of the nanoplates and signatures indicative of edge channels was observed. We suggest in both cases time-reversal symmetry breaking in the Bi₂Te₃ nanoplate from the field of the magnetic cantilever and the high electron flux from the electron beam. These symmetry breaking interactions are believed to produce induced, topologically protected currents. The addition of an applied DC bias to the tip enabled the controlled filling of Landau levels by lowering or raising the fermi level. Previous studies suggest Bi₂Te₃ nanoplates of similar proportions to lie within the 3D topological insulator family and therefore harbor 2D surface states, however, based on the nature of the contrast seen in the MFM, electron energy loss spectroscopy (EELS), and our synthesis method we argue these nanoplates fall within the 2D topological insulator family. These studies reveal the existence of persistent currents in our 2D Bi₂Te₃ system at room temperature and point to MFM and EELS as powerful tools for probing such topologically protected quantum spin hall states.

3:00pm MI+2D-WeA-4 Surface of Topological Weyl Semimetal PtBi_{1.6}, Zheng Gai, Oak Ridge National Laboratory; Dejia Kong, Department of Chemistry, University of Virginia, Charlottesville, VA 22903; Rongying Jin, University of South Carolina, Columbia, SC 29208

PtBi_{2-x} (specifically PtBi_{1.6}) is a noncentrosymmetric Weyl semimetal that hosts topologically protected surface states, making it a fascinating platform for exploring exotic surface and bulk phenomena. The material naturally cleaves to reveal two distinct surface terminations: a buckled Bi1 surface with 3m symmetry, and a flat Bi2 surface with m symmetry. PtBi_{1.6} also exhibits giant magnetoresistance, surface superconductivity, and evidence of robust quasiparticle interference patterns, making it a compelling candidate for applications in spintronics, quantum sensing, and topological quantum computing. However, several key questions remain open. One major challenge is understanding the role of surface states in transport phenomena—particularly whether they contribute to the large magnetoresistance observed at low temperatures. Our scanning tunneling microscopy (STM) studies reveal the presence of both Bi1 and Bi2 terminations upon cleaving, consistent with prior surface-sensitive spectroscopic studies. Detailed quasiparticle interference (QPI) analyses highlight contrasting behaviors on the two surface types, suggesting that the electronic structure and scattering mechanisms are highly termination-dependent. Additionally, we examine the impact of atomic-scale defects on the surface states, providing insight into their stability and resilience. These findings deepen our understanding of surface-bulk interplay in noncentrosymmetric topological systems and underscore the importance of surface engineering in future device applications.

The STM work of this research was conducted at the Center for Nanophase Materials Sciences, ORNL, which is a DOE Office of Science User Facility.

3:15pm MI+2D-WeA-5 Visualizing Electronic and Magnetic Structure at Nanoscale for Spintronics, Jyoti Katooch, Carnegie Mellon University, USA
INVITED

Topological semimetals, such as WTe₂ and TaIrTe₄, have strong spin-orbit coupling, non-trivial band dispersion, and bulk and surface spin polarized states. A combination of intrinsic spin Hall effect and surface state driven efficient and unconventional spin current generation can be obtained in these systems for manipulating the magnetic order. However, the comprehensive understanding of electronic structure, which is directly responsible for charge to spin conversion, of these systems at mesoscopic scale remains critical missing. I will discuss our results on probing spatially resolved electronic structure of atomically thin layers of WTe₂ and TaIrTe₄ using nanoARPES. Moreover, recently, we reported the first experimental realization of field-free deterministic magnetic switching of a perpendicularly polarized van der Waals (vdW) magnet employing spin current with out-of-plane spin polarization in layered WTe₂. We will discuss our efforts to utilize the photoemission electron microscopy (PEEM) paired with x-ray magnetic circular dichroism (XMCD) to obtain a spatially resolved view on the underlaying mechanism of this magnetic switching behavior. Finally, I will discuss our experiments aimed at nanoscale imaging of magnetic structure of atomically thin films of a vdW antiferromagnet, i.e., CrSBr. Layered magnetic systems display highly intriguing properties, such as thickness-dependent magnetic ground state, electric field tunability, enhancement of interlayer AFM exchange coupling in the ultra-thin limit, and tunable magnon-magnon coupling, to name a few. We will report on

experiments wherein we employ PEEM paired surface-sensitive XMCD/XMCD to perform layer-dependent domain imaging in mesoscopic sized samples of CrSBr. We will discuss detailed thickness, temperature, and externally applied magnetic field-dependent magnetic domain imaging of atomically thin samples of CrSBr.

4:15pm MI+2D-WeA-9 Layered Systems for Spintronics and Quantum Sensing of Spin Dynamics, Simran Singh, Carnegie Mellon University
INVITED

Low-dimensional systems and their atomically precise heterostructures are a modular material platform to study emergent spin and magnetism related phenomena. I will present our work(s) on exploring topological semimetals and layered magnets based low-dimensional heterostructures to realize novel spin-galvanic effects for electric field control of the magnetic order, demonstrate a new type of unidirectional magnetoresistance, and realize an unconventional form of anomalous Hall effect. First, I will discuss our experiments to employ spin-current with an out-of-plane spin polarization generated in a low-symmetry topological semimetal to deterministically switch and read the magnetic state(s) of perpendicularly polarized magnets. Secondly, I will discuss the experimental realization of unconventional form of anomalous Hall effect in a low-dimensional heterostructures, which is proportional to not only out-of-plane magnetization but also to in-plane magnetization component, potentially expanding the parameter space for designing dissipationless edge transport in low-dimensional systems. Furthermore, spin-defects can be engineered in low-dimensional systems – an appealing prospect for quantum sensing technologies. Time permitting, I will present our work aimed at utilizing designer spin defects embedded in a two-dimensional system to probe broadband spin dynamics.

4:45pm MI+2D-WeA-11 Surface Electronic Structure Comparison of Fe-Intercalated and 2h-TaS₂, Dejia Kong, Sree Sourav Das, Jacob St. Martin, University of Virginia, USA; Peter Siegfried, George Mason University; Zhiqiang Mao, Seng Huat Lee, The Pennsylvania State University; Ian Harrison, University of Virginia; Nirmal Ghimire, University of Notre Dame; Mona Zebarjadi, University of Virginia, USA; Zheng Gai, Oak Ridge National Laboratory, USA; Petra Reinken, University of Virginia, USA

Anisotropic ferromagnetic phases can be introduced to transitional metal dichalcogenide (TMD) TaS₂ through intercalating Fe in the van der Waals (vdW) gap. By deviating from the commensurate values (x = 1/4 or 1/3), the crystalline structure as well as the magnetotransport properties of the TMD system can be tuned. For instance, Fe_{1/4}TaS₂ has a centrosymmetric 2 × 2 structure while Fe_{1/3}TaS₂ has a non-centrosymmetric r3 × r3 supercell structure. The magnetic Curie temperature of Fe_xTaS₂ also exhibits a strong dependence on Fe concentration. We evaluate Fe_{0.28}TaS₂ and 2H-TaS₂ samples using STM/Spectroscopy (STM/S) and density functional theory (DFT) to investigate the real-space intercalant electronic structure comparatively and the potential phase segregation between the two commensurate compounds. Fe_{0.28}TaS₂ shows a supercell at 77 K, whereas 2H-TaS₂ displays no apparent supercell at the same temperature. Fe vacancy defects and clusters are discovered in the intercalated surface, and their surrounding local density of states (LDOS) shows non-trivial differences at energies compared to the pristine Fe_{0.28}TaS₂ area, which is related to Fe orbitals contributions based on the DFT calculations.

The STM work of this research was conducted at the Center for Nanophase Materials Sciences, ORNL, which is a DOE Office of Science User Facility.

5:00pm MI+2D-WeA-12 Chirality, Surface Termination and Anti-ferromagnetic Alignment in Fe(III) Spin Crossover Salts, Mohammad Zaid Zaz¹, University of Nebraska-Lincoln; Wai Kiat Chin, Arjun Subedi, Gauthami Viswan, University of Nebraska - Lincoln; Alpha T.N'Daiye, Advanced Light Source, Lawrence Berkeley National Laboratory; Alexander Wysocki, University of Nebraska-Kearney; Rebecca Lai, Peter A Dowben, University of Nebraska - Lincoln

Switchable molecular materials based on 3d transition metal complexes are a rich platform for exploring phenomenon related to symmetry breaking which include chirality and surface termination. In certain di-nuclear species, magnetic ordering between different metal ions is also witnessed. We explore chirality, surface termination and anti-ferromagnetic alignment in an Fe(III) spin crossover complex namely [Fe(qsal)₂Ni(dmit)₂] where, qsal = N(8quinolyl)salicylaldimine, and dmit²⁻ = 1,3-dithiol-2-thione-4,5-dithiolato. We employ spatially resolved Fe-L3,2 edge X-ray absorption spectroscopy to probe the chiral signature at the Fe metal center. Surface termination is studied by complementary X-ray photoemission

¹ Falicov Student Award Finalist

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spectroscopy and energy dispersive X-ray spectroscopy. These are further complemented by inverse photoemission spectroscopy and Fe, Ni-L3,2 edge X-ray absorption spectroscopy. Finally, we investigate the anti-ferromagnetic alignment in this system by X-ray magnetic circular dichroism measurements at the Fe and Ni core.

5:15pm MI+2D-WeA-13 Impact of Nanoscale Curvature on the Structural and Magnetic Properties of Co/Pd Alloys, *Asma Qdemat, Asma Qdemat, ORNL*

Researchers have studied a lot about the properties of magnetic thin films grown on flat substrates. This is mostly because it's easy to make them and there are well established ways to process them. However, researchers have not studied enough about how nanoscale curvature affects them. This study aims to fill that gap by directly comparing the structure and magnetic behavior of Co/Pd alloy thin films deposited on flat versus curved surfaces.

In this contribution, we will present a detailed investigation of the effects of how nanoscale curvature affects the structural and magnetic properties of Co/Pd alloys deposited on flat silicon substrates and highly ordered monolayers of 50 nm and 200 nm SiO_2 nanospheres, using molecular beam epitaxy (MBE). We used a variety of advanced methods to study our system, including magnetometry, X-ray reflectivity (XRR), polarized neutron reflectometry (PNR), and grazing-incidence small-angle neutron and X-ray scattering (GISANS/GISAXS) was employed to probe both depth-resolved and lateral properties.

Structural analysis via SEM and XRR revealed that films deposited on flat silicon maintained smoother, while those grown on curved nanospheres exhibited increased surface roughness and disrupted periodicity. In films on curved substrates, a parabolic scattering length density (SLD) model was necessary to capture the curvature-induced gradient in density profiles. GISAXS and GISANS confirmed these findings, showing less nanospheres ordering and greater lateral roughness, particularly in thicker films. Furthermore, magnetically, the nanoscale curvature significantly influenced anisotropy. SQUID measurements showed strong perpendicular magnetic anisotropy (PMA) in films on flat substrates, with square hysteresis loops and high remanence. In contrast, films on curved nanospheres had increased coercivity, reduced saturation magnetization, and a tilted magnetization axis, effects that were more pronounced in thinner films. These observations were further confirmed by PNR, which revealed that curvature changes the magnetic SLD profiles and increases the Co magnetic moment. This is likely due to strain and changes in the interfacial coupling.

Our findings show that nanoscale curvature is important in controlling how magnetic alloys behave. Curvature can reduce the uniformity of the structure and the magnetic properties. But it can also open up new ways to control local magnetic interactions by altering strain and anisotropy. These insights are very important for the development of flexible, conformal magnetic devices where precise control over magnetic anisotropy is required.

5:30pm MI+2D-WeA-14 Emergence of local magnetic moment in ternary TaWSe_2 single crystal via atomic clustering, *Jewook Park, Oak Ridge National Laboratory*

Ternary transition metal dichalcogenides (TMDs) provide a versatile platform to explore novel electronic and magnetic ground states via compositional substitution and local structural modulations. Using a combination of scanning tunneling microscopy and spectroscopy (STM/S), magnetic property measurements, and density functional theory (DFT) calculations, we analyze the emergence of local magnetic moments driven by the clustering of Ta atoms in ternary TaWSe_2 single crystals. STM topography reveals triangular clusters of Ta atoms embedded within W-rich regions of TaWSe_2 . These clusters exhibit a consistent shape and an orderly arrangement throughout the surfaces. DFT calculations show that these Ta clusters induce local strain, giving rise to localized magnetic moments. The magnetic behavior is further corroborated by temperature-dependent magnetization measurements, which exhibit a magnetic transition near 50 K. This study offers a pathway to engineer magnetism in TMD systems with potential applications in spintronic and quantum materials.

Nanoscale Science and Technology

Room 205 ABCD W - Session NS-WeA

Recent Advances in Nanoscience

Moderators: Deep Jariwala, University of Pennsylvania, Nikolai Klimov, NIST

4:15pm NS-WeA-9 The Role of Defects in Ion Induced $\beta\text{-Ga}_2\text{O}_3$ to $\gamma\text{-Ga}_2\text{O}_3$ Conversion, *Umutcan Bektas, Oskar M. Liedke, Helmholtz-Zentrum Dresden - Rossendorf, Germany; Huan Liu, Helsinki University of Technology, Finland; Fabian Ganß, Nico Klingner, René Hübner, Helmholtz-Zentrum Dresden - Rossendorf, Germany; Ilja Makkonen, Helsinki University of Technology, Finland; Andreas Wagner, Gregor Hlawacek, Helmholtz-Zentrum Dresden - Rossendorf, Germany*

Gallium oxide (Ga_2O_3) is a highly versatile material with applications in power electronics, optoelectronics, and battery technologies. Among its polymorphs, monoclinic $\beta\text{-Ga}_2\text{O}_3$ is the most chemically and thermally stable phase. However, controlling the metastable polymorph phases remains challenging, and fabrication technologies for nanoscale structures are still under development. This study aims to enhance the understanding of polymorph conversion mechanisms and to establish novel fabrication techniques for single-phase polymorph films, buried layers, multilayers, and various nanostructures of Ga_2O_3 .

We investigate $\beta\text{-Ga}_2\text{O}_3$ samples irradiated with different ions and fluences, as well as α - and $\kappa\text{-Ga}_2\text{O}_3$ thin films. Broad beam (BB) ion irradiation was employed to induce phase transformations in the near-surface region. The irradiated samples were characterized using transmission electron microscopy (TEM) and X-ray diffraction (XRD) to analyze structural changes. Complementary experiments using Positron Annihilation Lifetime

Spectroscopy (PALS) and Doppler Broadening Variable Energy Positron Annihilation Spectroscopy (DB-VEPAS) provided insights into defect types and concentrations.

Our results reveal the evolution of defect types and densities based on DB-VEPAS and positron lifetime measurements. During the phase transition from β - to $\gamma\text{-Ga}_2\text{O}_3$, a significant reduction in positron trapping sites is observed, indicating a decrease in defect density in the newly formed $\gamma\text{-Ga}_2\text{O}_3$ layer compared to the highly irradiated β material [1]. This observation aligns with previously reported high radiation hardness of Ga_2O_3 [2].

Additionally, we employed Neon-based helium ion microscopy to investigate the minimal achievable polymorph feature size, exploring the feasibility of future polymorph-based devices (see Figure 1).

This work is supported by the m-era.net project GoFIB and funded by the Saxonian government. Additional support from the COST Action CA19140 FIT4NANO is gratefully acknowledged.

References

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4:30pm NS-WeA-10 Development of Heavy Noble Gas Field Ion Sources Using an Iridium Coated Single Crystalline Tungsten Emitter, *Amina ZID, Helmholtz Zentrum Dresden-Rossendorf, Germany*

Gas Field Ion Sources (GFIS) have already demonstrated their efficiency in nano imaging and patterning due to their high brightness, high current density and superior spatial resolution [1]. This type of ion source typically employs light noble gases such as helium and neon. In the first case, negligible sputtering and fast diffusion enables image resolution as low as 0.5 nm, while the latter allows high resolution milling of small nanostructures with resolutions better than achievable with a conventional Liquid Metal Ion Source (LMIS). GFIS suffers from limitation in terms of material removal rate due to low achievable maximum current. Another limitation comes from the light ion species used, as well as bubble formation due to deep noble gas implantation making GFIS less efficient than LMIS for larger volume or high aspect ratio milling application with only shallow end of range defects. To overcome those limitations, we investigated the GFIS performance in a Focused Ion Beam (FIB) using heavier noble gases, namely argon and xenon.

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In addition, we consider an alternative emitter configuration. Commercial GFIS emitters are based on single-crystal tungsten tips, while we employ an iridium coated tungsten tip. Among noble metals, iridium confers the strongest bond with tungsten [2]. That particularity would allow the overall tip structure to withstand higher electric field than with any other noble metal coating. As a result, iridium coated tips enable higher beam currents without endangering the emitter stability. We also work with a single emission point opposed to the typical trimer configuration traditionally used in Helium Ion Microscopy (HIM).

In this work we will present the first FIB evaluation and performances based on this particular emitter using argon and xenon. Comparison to helium and neon based GFIS used in traditional HIM setups will also be covered.

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[2] Oshima, C.; Tomitori, M.; Shimoda, T.; Yasaka, A.; Asai, H.; Rokuta, E. Thermal Stability of Single-Atom Termination at a Pyramidal Apex of an Ir-W Tip. *Surface Science and Nanotechnology* **2018**

4:45pm NS-WeA-11 Unconventional Superconductivity in Quasi-1D ZrTe₃ Revealed by Ultra-Low-Temperature Scanning Tunneling Microscopy, Laxmi Bhurtel, Dongwon Shin, University of Tennessee Knoxville; Sang Yong Song, Benjamin Lawrie, ORNL; Petro Maksymovych, Clemson University; Wonhee Ko, University of Tennessee Knoxville

Quasi-one-dimensional (1D) superconductors possess anisotropic crystal structure and reduced dimensionality that possibly leads to unconventional superconductivity from strong electron correlation. ZrTe₃ is a quasi-1D material that displays both charge density waves and superconductivity. In this study, we probe the superconducting behavior of pristine and lightly Ni-doped ZrTe₃ with ultra-low-temperature scanning tunneling microscope (STM). The differential conductance (dI/dV) spectra reveal a clear superconducting gap for both compounds. The height dependence of dI/dV spectra is not consistent with BCS theory, implying an unconventional pairing mechanism in these materials. Our findings offer microscopic understanding of superconducting pairing mechanisms and electronic behavior in quasi-1D system.

5:00pm NS-WeA-12 Electronic and Phononic Structure of Doped Graphene/Perovskite Oxide Hybrid Heterostructure Studied by Scanning Tunneling Microscopy, Myeesha Mostafa, University of Tennessee Knoxville; Dongwon Shin, University of Tennessee, Knoxville; Woo Seok Choi, Sungkyunkwan University, Republic of Korea; Wonhee Ko, University of Tennessee Knoxville

Graphene's interaction with complex oxide opens a new pathway to engineering electronic properties of 2D material. The perovskite oxide SrTiO₃ (STO) as a high dielectric substrate along with graphene form a hybrid heterostructure that offers a novel platform to understand the Dirac fermion behavior modified by the unique substrate interaction. Scanning tunneling microscopy (STM) allows us to visualize the impact of complex oxide substrates on graphene's atomic and electronic properties. In this work, the ultra-low temperature STM was employed to investigate the structural and electronic properties of graphene directly grown on STO. The topographic image clearly reveals the honeycomb lattice of graphene with atomic resolution. Differential conductance (dI/dV) spectra display the shifting of Dirac point due to the electron doping effect of substrate. Additionally, the dI/dV spectra display a gap-like feature pinned to Fermi energy, which is associated with a phonon-induced inelastic electron tunneling. This study illustrates how perovskite substrates modulate electronic structure of 2D materials and motivates further analysis at lower temperature to resolve strain-induced shifts in phonon energy.

5:15pm NS-WeA-13 Unveiling High-Temperature Superconducting Pairing Symmetry in Monolayer FeSe via Tunneling Andreev Reflection, Dongwon Shin, Paolo Vilmercati, Norman Mannella, University of Tennessee, Knoxville; Petro Maksymovych, Clemson University; Wonhee Ko, Hanno Weitering, University of Tennessee, Knoxville

Recent advances in low-dimensional unconventional superconductors and their unique interface properties require new techniques to probe pairing symmetry, a crucial and often debated aspect of superconductivity. In particular, understanding the pairing symmetry of monolayer FeSe on SrTiO₃ remains a central controversy in the study of Fe-based superconductors. Remarkably, monolayer FeSe exhibits a superconducting transition temperature above 60 K, far exceeding that of bulk FeSe (\sim 6 K). While various scenarios have been proposed to explain this enhancement, the underlying mechanism and the nature of the superconducting order

parameter remain unresolved. In this study, we grew high-quality monolayer FeSe films on Nb-doped SrTiO₃ substrates using molecular beam epitaxy. We also characterized their atomic-scale structure and superconducting properties via scanning tunneling microscopy and spectroscopy (STM/S). Atomic-resolution images confirmed the high crystallinity of the films, and a well-defined superconducting gap was observed at 0.3 K. We further employed tunneling Andreev reflection measurements to investigate the superconducting order parameter. By acquiring spatially resolved STS spectra as a function of tip height z , we extracted the normalized tunneling decay constant κ/κ_0 , which reveals nontrivial quasiparticle tunneling characteristics in the superconducting state. This highly sensitive probe of superconducting gap symmetry provides direct insight into the mechanism of unconventional superconductivity, offering quantitative constraints for theoretical models and enabling the identification of possible pairing scenarios in monolayer FeSe.

Plasma Science and Technology

Room 201 ABCD W - Session PS1-WeA

Plasmas for Emerging Device Technologies

Moderators: Michael Gordon, University of California at Santa Barbara, Kenji Ishikawa, Nagoya University, **Scott Walton**, Naval Research Laboratory

2:15pm PS1-WeA-1 Main Etch Challenges in the GaN-based Devices, Patricia Pimenta Barros, Simon Ruel, Univ. Grenoble Alpes, CEA, LETI, France; David Cascales, Univ. Grenoble Alpes, CEA, Leti and CNRS, LTM, France; Nicolas Posseme, Univ. Grenoble Alpes, CEA, LETI, France; Thouelle Philippe, Lam Research, France; Eugénie Martinez, Univ. Grenoble Alpes, CEA, LETI, France; Bassem Salem, Univ. Grenoble Alpes, CNRS, LTM, France; Maxime Pezeril, Khatia Benotmane, Univ. Grenoble Alpes, CEA, LETI, France; François Gaucher, Lam Research, France; Laura Vauche, Yveline Gobin, Univ. Grenoble Alpes, CEA, LETI, France

INVITED

Thanks to the inherent properties of Gallium Nitride, the semiconductor industry envisages the introduction of GaN in a wide range of applications. For instance, GaN-based high electron-mobility transistors (HEMTs) have been adopted in power devices thanks to their high breakdown electric field and electron mobility[1]. Also, GaN's direct wide-band gap (3.4eV) is exploited into LED, microLED and displays for better photon emission.

Among the manufacturing steps of GaN-based devices, the plasma etching steps are part of the most critical ones as they have to satisfy morphological requirements without damaging the GaN material. Indeed, when patterning the GaN-based HEMTs, the electrical performances are directly linked to the damage induced by plasma etching at the gate bottom [2]. Depending on the architectures, the GaN etching step has to comply with different morphological criteria: i) high pGaN etching selectivity over AlGaN in pGaN gate transistors, ii) vertical profiles with bottom rounded corners in recessed-gate transistors.

This talk will focus on the main etching challenges that occur during the gate patterning of GaN-based HEMTs, and will give an overview of our recent outcomes. First, a GaN etching mechanism with a resist and SiN hardmask will be proposed based on morphological studies and the chemical analysis of the remaining byproducts on GaN sidewalls analyzed. The best etch parameters leading to vertical GaN sidewalls and bottom rounded corners with an etched-depth of 1 μ m will be shared.

In the case of pGaN gate structure, Cl₂/N₂/O₂ and BC₃/SF₆ based chemistries will be compared in terms of selectivity and profile. Secondly, the damage induced by plasma etching on the GaN surface was investigated. Thus, electrical characterizations have been conducted using either sheet resistance (R_{sheet}) or C-V measurements in order to simulate the pGaN and recessed-gate MOS transistors' behavior, respectively. The goal will be to compare the benefits and drawbacks of different Cl₂-based etching processes, and to identify the main degradation mechanisms.

In conventional etching processes, it has been shown that passivating chemistries like SiCl₄-based processes could be an alternative solution for improving recessed gate-MOS transistors [3]. In addition, we demonstrated that Atomic Layer Etching (ALE) reduces the damage induced by conventional etching [4]. Finally, this paper will compare ALE and bias

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pulsed processes.

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2:45pm PS1-WeA-3 Study of N-Polar GaN Etching by a CH₄/H₂/Ar Plasma for μLED Applications, *Sandra Kozuch, Simon Ruel, David Vaufrey, Olivier Renault, CEA-Leti, France*

The ability of Gallium Nitride (GaN) to form ternary alloys with Al or In for emission wavelength modulation makes it a material of choice for μLED (micro-Light Emitting Diodes) applications. The μLED studied structures are VTF (Vertical Thin Film) type implying the report of the GaN stack on a backplane resulting in a N-polar GaN exposed. The pixel fabrication involves a plasma etching step (mostly with a Cl₂-based chemistry), known to damage the material mostly at mesa sidewalls [1]. For instance, defects like lattice amorphization, nitrogen depletion, implantation or deposition of etching by-products can be responsible for non-radiative recombinations of electron-hole pairs. This phenomenon is heightened for smaller pixels and results in an efficiency loss for the devices with miniaturization.

To address these issues and improve device performances, there is a need to develop less damaging etch processes. A change of etching chemistry for CH₄/H₂ mix, and avoid using Cl₂, can be an interesting and still poorly investigated strategy: by-products formed by CH₄ and GaN are very volatile, preventing them from redepositing on the etched surface [2]. Moreover, H atoms can passivate donor states near the surface [3].

In this study, we propose to etch N-polar GaN with CH₄/H₂/Ar plasma in an ICP chamber, with the goal of understanding its etch mechanisms and impact on material degradation. Different etch parameters are studied as DC bias voltage, source power, pressure or gas ratio to found a maximum ER of 50 nm/min and 85° profile, as vertical sidewalls as for a chlorine-base etching.

Scanning Electron Microscopy (SEM) measurements enabled measuring N-polar GaN etching rate, carbon-containing by-products deposition rate and sidewalls verticality. The surface etched using the best conditions were first studied by X-Ray Photoelectron Spectroscopy to obtain N/Ga stoichiometry and study valence and core-level states to retrieve band bending and chemical bonding states. Secondly, cathodoluminescence was performed on the same samples to study the GaN Yellow Band emission (between 500 and 700 nm) linked to radiative defects emissions. Then, the results were compared with those of a Cl₂-based etch of reference. These characterizations aim to determine if the developed etching process is less invasive or not to the material.

[1] R.J.Shul et al., J. Vac. Sci. Technol.A, vol. 18, no 4, p. 1139–1143, juill. 2000, doi: 10.1116/1.582313.

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Plasma Science and Technology Room 201 ABCD W - Session PS2-WeA

Atmospheric Plasma

Moderators: Michael Gordon, University of California at Santa Barbara, Kenji Ishikawa, Nagoya University, Scott Walton, Naval Research Laboratory

3:00pm PS2-WeA-4 Investigating the Thermal Behavior of Atmospheric Pressure Plasma Jets on Different Surface Types, *Vladimir Milosavljevic, School of Physics, Clinical & Optometric Sciences, Technological University Dublin, Ireland & Faculty of Physics, University of Belgrade, Serbia, Ireland; James Lalor, School of Physics, Clinical & Optometric Sciences, Technological University Dublin, Ireland*

Atmospheric pressure nonthermal plasmas hold great promise for applications in environmental management, energy transformation, and material engineering. Although they operate at room temperature, nonthermal plasmas produce highly reactive species that can modify surfaces at the plasma/surface interface. This study examines the interaction of an Argon atmospheric pressure plasma jet (APPJ) with both insulating and conductive mesh surfaces. The dielectric barrier discharge APPJ functioned at 8 kV and 21 kHz.

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Previous research has analyzed how an atmospheric pressure plasma jet behaves when directed perpendicularly onto both dielectric and conductive flat surfaces, revealing that the jet maintains a laminar flow, expanding radially from the impact point. The highest temperature occurs at the central impact zone, with a radial decrease outward due to jet expansion and heat dissipation along the surface.

In contrast, this study introduces a novel method by treating a mesh substrate with 0.8 mm x 0.8 mm openings, allowing partial gas plume penetration. This enables thermal mapping of the interaction between the APPJ and the substrate, offering insights into the jet plume's thermal cross-section. A series of experiments explored how different materials, such as metals and polymers, respond to the APPJ's thermal energy by analyzing temperature rise, heat distribution, and cooling rates. The distance between the APPJ nozzle and the mesh surface (standoff distance) was adjusted from 0 to 70 mm, with thermal profiles recorded to identify the optimal distance for preventing surface overheating. Additionally, treatment time was varied between 0 and 240 seconds at a fixed standoff distance to evaluate thermal effects over different exposure durations.

A FLIR i7 thermal camera with a 140 x 140-pixel resolution was employed to capture precise thermal images, enabling detailed measurement of temperature gradients across treated surfaces. Its high accuracy and sensitivity were crucial for assessing the APPJ's thermal impact on various materials, ensuring reliable data acquisition throughout the study.

This research investigates the thermal behavior of APPJ treatments on metallic and polymeric surfaces, emphasizing the effects of standoff distance and treatment duration. The results indicate that steel, with its high thermal conductivity, heats and cools rapidly, whereas polypropylene retains heat longer due to slower heating. Findings also demonstrate that reduced standoff distances increase energy transfer, with material properties playing a crucial role in temperature distribution.

3:15pm PS2-WeA-5 Controlling Nitrogen Product Distributions in Plasma Electrolytic Reactors for Microbial Growth, *Brandon Kamiyama, Diep Nguyen, Mohammadali Eslamisaray, Emily Gillmore, Angela Tomita, Ting Lu, R. Mohan Sankaran, University of Illinois at Urbana Champaign*

Fixed forms of nitrogen are essential for the growth of plants that enable global food production, and for the growth of microorganisms which power critical processes beyond agriculture such as biomanufacturing and chemical production. Currently, nitrogen fixation is predominantly carried out by industrial processes (e.g., Haber-Bosch, Ostwald processes) that have large physical and environmental footprints. The development of alternative methods that are sustainable and deployable at a small scale for point-of-use production has emerged as one of our critical technological challenges. Among the different approaches being explored, plasmas in contact with liquids have shown great promise, capable of reacting nitrogen in air with water as a source of hydrogen at atmospheric pressure and near room temperature. However, a key challenge is that these processes generate many nitrogen products, including ammonium, nitrate, and nitrite ions, in addition to other products such as hydrogen peroxide.

In this work, we studied a direct-current plasma-based electrolytic reactor and correlated process conditions such as gas feed, pH, and electrode polarity with product yields and selectivity. In particular, molecular oxygen and pH were found to be key for controlling the selectivity between the reductive and oxidative species. These results provided insight into possible reaction mechanisms and enabled us to selectively synthesize nitrogen products as substrates for microbial growth and biosynthesis.

3:30pm PS2-WeA-6 Particle-in-Cell Modeling of the Reverse Anode Sheath in Parallel-Plate Sub-Atmospheric Pressure Hydrogen Plasmas, *Brian Jensen, Princeton University Plasma Physics Lab; David Graves, Princeton University*

Parallel-plate electrode plasmas are widely used as large-area semiconductor processing tools [1-4]. In these systems, non-equilibrium electrons with non-Maxwellian electron energy distribution functions (EEDFs) drive gas-phase reactions and enable surface modification [5]. Particle-in-cell (PIC) simulations are well-suited to capture such effects, but at pressures above a few torr, 2D and 3D simulations with appropriate reactor chemistry become increasingly expensive due to disparities between plasma and chemical length and time scales. To investigate these systems, this work presents a coupled 1D PIC-fluid model for hydrogen plasma reactors and studies the effectiveness of DC parallel plate systems as tools for large-area processing, particularly for diamond substrates. We characterize the reverse anode sheath for systems with gas pressures exceeding 10 Torr and describe the range of unique processing conditions available at the anode surface under these conditions.

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Room 201 ABCD W - Session PS3-WeA

ICP Modelling

Moderators: Thorsten Lill, Lam Research Corporation, **Shahid Rauf**, Applied Materials, USA

4:15pm PS3-WeA-9 Quantum Chemistry and Integrated Modeling for Understanding the Mechanisms of Selective and Cryogenic Atomic-Scale Etching, *Yuri Barsukov, Mingmei Wang, Qing Xu, Thorsten Lill, Lam Research Corporation* **INVITED**

Plasma etching for high aspect ratio vertical trenching in 3D-structured silicon-based devices is one of the most challenging steps in advanced semiconductor manufacturing. This process requires precise control of both ion and neutral fluxes to facilitate etching at the trench bottom while ensuring sidewall passivation to prevent lateral etching and feature distortion. As the range of chemical reactants used in industry continues to expand, a deeper understanding of plasma-surface interactions and surface reaction mechanisms becomes increasingly critical. Over the past decade, quantum chemistry has played a growing role in elucidating these mechanisms, providing valuable insights for optimizing plasma etching processes.

Quantum chemistry is widely used to investigate reaction mechanisms at the atomic level. Within the framework of transition state theory, the reactivity of various fluorine-based reactants with semiconductor materials has been calculated, revealing how etching with these reactants can be catalyzed, enhanced, and accelerated through vibrational excitation. This ab-initio approach enables the calculation of rate constants for key surface reactions and allows for the integration of surface reactions kinetics with plasma chemistry models. These kinetic models predict the dependence of etching rates and selectivity on plasma parameters. For example, the reactivity of fluorine (F) atoms and hydrogen fluoride (HF) molecules – two of the most commonly used reactants in the semiconductor industry – has been studied on silicon-based materials such as Si, SiN, and SiO₂.

Another crucial challenge in plasma-assisted etching is the efficient delivery of ions to the trench bottom. Accelerated ions lose kinetic energy through the collisions with sidewalls, leading to feature damage without effectively contributing to bottom etching. Despite their high initial energies in the keV range, the normal component of ion energy at the grazing incident is only in tens of eV. As a result, relatively weak chemical interactions between sidewall materials and incident ions play a crucial role in determining etching efficiency and feature integrity. Using ab-initio molecular dynamics, it has been demonstrated that ammonia fluoride ionic salts – the most common etching by-products that coat the sidewalls – provide more effective protection against damage and help prevent ion energy loss at lower temperatures. This discovery sheds light on the mechanisms of cryogenic plasma-assisted etching and highlights the importance of by-product formation in sustaining etching process.

4:45pm PS3-WeA-11 Simulation of an Inductively Coupled Plasma with a Two-Dimensional Darwin Particle-in-Cell Code, *Dmytro Sydorenko, University of Alberta, Edmonton, AB, Canada; Igor Kaganovich, Alexander Khrabrov, Princeton Plasma Physics Laboratory*

Electromagnetic simulation with an explicit algorithm has a severe limitation on the time step due to the large speed of light propagation resulting in the high numerical cost. Fully implicit electromagnetic algorithms do not have this limitation but are more complex to implement. Another option is the Darwin method omitting the electromagnetic wave propagation [1]. The Darwin method separates the electric field into solenoidal (electromagnetic) and irrotational (electrostatic) parts.

In this work, we propose a new Darwin scheme for simulation of low-frequency electromagnetic processes in laboratory plasmas. A two-

dimensional particle-in-cell code in Cartesian geometry has been developed based on the direct implicit Darwin electromagnetic algorithm described in Ref. 1. The new code has several significant modifications compared to the original algorithm. First, the SDF is replaced by a new method based on the equation for the vorticity of the solenoidal electric field. Unlike the SDF, the linear system of equations in the vorticity method is reliably solved using a standard iterative solver. Second, the electromagnetic fields are defined on staggered grids convenient for electromagnetic simulation. Third, the contribution of collisional scattering is included in calculation of the solenoidal electric fields. Fourth, the code includes several solvers for the self-consistent magnetic field with different boundary conditions. Once one of these methods is selected for a particular simulation, the choice can be verified by checking the energy conservation.

A two-dimensional particle-in-cell code has been developed using the modified direct implicit Darwin electromagnetic algorithm described in Ref. 2. The code is a valuable tool for simulation of various electromagnetic effects, for example the inductively coupled plasmas and the electromagnetic plasma waves. The code can be used to design future plasma thrusters.

References:

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5:00pm PS3-WeA-12 Exploring the Impact of Mask Geometries on High Aspect Ratio Silicon Etching Using Cl₂/O₂ Plasmas, *Shahid Rauf, Xingyi Shi, Han Luo, Jason Kenney, Geuntak Lee, Sonam Sherpa, Takumi Yanagawa, Applied Materials*

As computing technology advances, the demand for more intricate geometries in etching processes has surged, necessitating a deeper understanding of the underlying physics. While previous published computational studies predominantly focus on via and trench geometries, the challenges posed by alternative mask geometries remain largely unexplored. This study employs Monte Carlo-based feature scale simulations to investigate high aspect ratio silicon etching using Cl₂/O₂ plasma. Initially, we present the general behavior of etching features with a rectangular geometry to establish a baseline. Subsequently, we explore the influence of chemical composition and bias voltage pulsing on the etching profile, highlighting how these parameters can be optimized for improved precision and control. The study culminates in an analysis of the impact of mask geometry by comparing etching profiles produced with circular, square, and rectangular mask shapes. Our findings reveal significant variations in etching outcomes based on mask geometry, underscoring the need for tailored approaches in feature scale simulations. This research not only broadens the understanding of etching dynamics but also paves the way for more sophisticated design strategies in semiconductor manufacturing, addressing the evolving demands of modern computing technologies.

5:15pm PS3-WeA-13 Modeling of Remote Inductively Coupled Plasmas and Comparison to Experiments, *Mackenzie Meyer, David Boris, Michael Johnson, Jeffrey Woodward, Virginia Wheeler, US Naval Research Laboratory; Mark Kushner, University of Michigan; Scott Walton, US Naval Research Laboratory*

Plasma-enhanced atomic layer deposition (PEALD) utilizes plasma as a source of reactive species. Using plasma enables processing at low temperature and with materials that cannot be processed using thermal atomic layer deposition. Remote inductively coupled plasmas (ICPs) are utilized in PEALD as they limit damage to the substrate. Since the plasma is spatially removed from the substrate by 10s of cm, energetic ions are limited while radicals remain plentiful at the substrate location. However, questions remain about the physics of remote ICPs downstream of the plasma source. To help unravel the physics occurring in these devices, we model a remote ICP system using the 2D Hybrid Plasma Equipment Model (HPEM). The remote ICP system is based on the Veeco Fiji G2 source. We focus on pure Ar plasmas over a range of pressures and powers. Power is coupled both inductively and capacitively to the plasma. Based on the location of the powered end of the coil, the capacitively coupled power is deposited near the exit of the ICP and into the spatial afterglow. The results of the model are benchmarked against Langmuir probe measurements at these conditions. The effect of N₂ addition to the Ar plasma is also

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examined and benchmarked against measurements. These results are discussed in the context of PEALD.

This work is partially supported by the Naval Research Laboratory base program.

5:30pm PS3-WeA-14 Modeling of E-H Transition in Inductively Coupled Plasmas, Ashish Sharma, Rochan Upadhyay, Sudharshanaraj Thiruppathiraj, Dmitry Levko, Anand Karpatne, Radhika Mani, Lam Research Corporation

E to H transition is a phenomenon observed in plasma discharges and has been known to have a significant impact on the plasma etching characteristics. In the present study, we investigate the phenomenon of E-H transition for inductively coupled plasmas. These simulations have been conducted for a 2D GEC RF Reference cell in Cl₂ gas using VizGlow®. We study the transition of the plasma discharge from E-mode to H-mode and investigate the underlying physics governing the transition. We quantify the percentage of the input power absorbed in E mode and H mode and study the influence of TCP power, coil frequency and gas pressure on the power breakdown and E-H transition characteristics. Lastly, we analyze the plasma properties in E and H mode, mainly focusing on the differences in plasma densities, electron temperature and ion fluxes in these respective modes.

5:45pm PS3-WeA-15 Fully Kinetic Modeling of ICP Chambers Used for Plasma Processing, Daniel Main, Thomas Jenkins, Scott Kruger, John Cary, Tech-X Corporation

Low-temperature kinetic plasma simulations using particle-in-cell (PIC) and Monte Carlo methods (DSMC/MCC) for the chemistry can provide many advantages over fluid simulations, including detailed information about the Ion Energy Distribution Function (IEDF) and Ion Angular Distribution Function (IADF) that are critical for plasma processing. In addition, a fully kinetic approach does not make common assumptions made in fluid models, such as local conductivity or Maxwellian distributions of the plasma species. In this talk we present kinetic modeling results of inductively coupled plasmas in a 2D cylindrically symmetric geometry. We demonstrate how implicit methods can make these challenging simulations feasible by reducing computing times by factors of 20-200. We also demonstrate a method of providing constant power to the plasma, which further decreases the runtime needed to achieve steady-state discharges. We then apply DC and/or RF bias voltage below the wafer, introducing capacitive coupling self-consistently into the model to enable better etch control, and explore how steady-state ion fluxes and IEDF/IADFs at the wafer surface vary as a function of RF bias frequency, amplitude, and waveform shape. We show, for example, that a low-frequency CCP bias couples more efficiently with the ions leading to an increase in the RF-averaged ion energy. We also demonstrate that improved IEDF uniformity can be achieved through careful choice of the shape of the bias waveform.

6:00pm PS3-WeA-16 Comparative Analysis of Methods to Obtain EEDF in Plasma Simulations for Semiconductor Processing, Chenhui Qu, Matt Talley, Saravananapriyan Sriraman, Lam Research Corp.

Accurate determination of the Electron Energy Distribution Function (EEDF) is crucial for modeling plasma behavior and predicting gas-phase chemistry in semiconductor processing. Understanding the EEDF allows for precise control over plasma characteristics, essential for optimizing semiconductor manufacturing hardware and process technology. There are three primary methods for obtaining EEDF in plasma simulations: (a) kinetic particle approach using Monte Carlo, (b) the inline Boltzmann solver, and (c) the Maxwellian approximation, each with distinct advantages and limitations based on plasma conditions.

The kinetic approach offers the highest accuracy by treating electrons as particles and resolving electron trajectories under electromagnetic fields, capturing non-Maxwellian distributions and spatial variations. It provides detailed insights but is computationally intensive and may be prone to statistical noise.

At the farthest extreme, the Maxwellian approximation, while computationally efficient, assumes the electrons to be in thermal equilibrium and often fails to represent complex plasma behaviors accurately. While it reduces computational requirements, its applicability is limited and may not provide the necessary accuracy for advanced semiconductor processing at low pressures.

In the middle of the spectrum, the inline Boltzmann solver approach trades off accuracy to efficiency by solving the Boltzmann equation, in typically two-term or “few-term” expansion. The method offers a compromise between the kinetic approach and Maxwellian approximation, but can struggle under extreme non-equilibrium scenarios.

In this presentation, case studies of Inductively Coupled Plasma (ICP) and Capacitively Coupled Plasma (CCP) that demonstrate the impact of different approaches in obtaining EEDFs on plasma distributions, and ultimately the on-wafer results will be covered. Comparisons to experiments that validate the kinetic approach's superiority will be discussed highlighting the stringent standards required in semiconductor industry plasma simulations.

Surface Science

Room 209 CDE W - Session SS-WeA

Heterogeneous Catalysis II

Moderators: Alexander Kandratsenka, MPInat, Dan Killelea, Loyola University Chicago

2:15pm SS-WeA-1 "Single-Atom" Catalysis: Insights From Model Systems, Gareth Parkinson, TU Wien, Austria INVITED

Despite numerous successful syntheses and applications of single-atom catalysts (SACs), a fundamental gap persists between experimental approaches and theoretical modeling. Real-world catalysts are typically supported on complex powders and exposed to dynamic environments rich in potential ligands and contaminants. In contrast, density functional theory (DFT) calculations often rely on idealized models, such as low-index crystal facets and bulk-like atomic sites, which can oversimplify the real catalytic environment.

Model systems based on single-crystalline supports prepared under ultrahigh vacuum (UHV) conditions offer a valuable bridge between theory and experiment. These well-defined systems provide a testing ground to validate theoretical assumptions and gain atomistic insights into catalyst-support interactions.

As a case study, I will present experimental results on iron oxide surfaces—materials widely studied in SAC literature due to reports of high catalytic activity for metal adatoms on FeOx. Notably, many DFT studies adopt the hematite (α -Fe₂O₃) (0001) surface as a model, though its atomic-scale structure remains complex and contentious. Instead, we investigate the (1102) facet of hematite, which presents a stable, bulk-truncated (1×1) termination ideal for fundamental studies.

Our results demonstrate the adsorption behavior of Ir, Pt, and Rh single atoms on this surface. Crucially, stabilization of these atoms never occurs through simple adsorption at bulk-continuation sites. Instead, it involves either coadsorption of ligands or significant restructuring of the support itself—mechanisms that need to be accounted for in theoretical models of SACs.

2:45pm SS-WeA-3 Ligand-coordinated Supported Catalysts for Selective Hydrocarbon Chemistry, Steven Tait¹, Indiana University

A grand challenge in heterogeneous catalysis is to achieve high levels of selectivity by controlling the chemical uniformity of metal catalyst sites at surfaces. Our group has applied principles of on-surface metal-organic redox assembly to develop a new approach to this problem. Initial studies were conducted on model surfaces under ultrahigh vacuum conditions. Precise deposition control allowed for exploration of metal-ligand complexation requirements that would lead to highly stable 1D and 2D architectures. Reaction selectivity was tested by small exposures to reactive molecules. These systems provided models that have been adapted to high surface area supports under ambient conditions. Modified wet impregnation methods allow for loading of single-atom catalysts on high surface area powders at up to 1 wt%. X-ray photoelectron spectroscopy measurements demonstrate loading of metal and ligand on the surface and X-ray absorption spectroscopy, electron microscopy, and CO adsorption measurements demonstrate single atom character of the catalysts. These ligand-coordinated supported catalysts have been shown to be effective for a variety of reactions, including hydrosilylation, hydrogenation, dehydrogenation, and water-gas shift. Here, we examine the significant roles of the coordinating ligands and of the oxide support on catalyst structure, activity, and stability. Defect sites on the support and the expressed facets of the oxide have a strong influence on the state of the metal centers and show a significant impact on reaction activity. We also see strong influences due to changing functional group substituents in the ligands. Synthetic routes have been developed to incorporate carboxylic acid groups into the ligand framework to increase metal-ligand and metal-surface interactions. We compare this with systems involving co-ligand deposition. By loading the metal and ligand directly on the oxide support, it

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is possible to maintain a close contact of the metal to the oxide. These results provide new insights into the design and chemistry of supported single-atom catalysts.

3:00pm SS-WeA-4 Ethanol Oxidation over Single-atom Model Rh/Fe₃O₄(001) Catalysts, Daniel Baranowski, Physical and Computational Sciences Directorate and Institute for Integrated Catalysis, Pacific Northwest National Laboratory

The selective oxidation of alcohols like ethanol, a renewable feedstock, is of pivotal interest, both from a fundamental and industrial perspective.¹ Inspired by previous ultra-high vacuum studies performed on model single-atom Pd/Fe₃O₄(001) catalysts activating the low-temperature methanol to formaldehyde oxidation,² a series of model Rh/Fe₃O₄(001) catalysts were examined for the low-temperature ethanol to acetaldehyde oxidation. Distinct Rh active sites, including Rh adatoms, substitutional in-surface Rh, and Rh clusters, were prepared using different preparation conditions and amounts of Rh.³ The catalyst structures and activities were characterized by combining thermal desorption and photoelectron spectroscopies, and it was found that all model catalysts significantly reduce the temperature of the acetaldehyde production when compared to the bare Fe₃O₄(001) surface. There are, however, significant differences in the selectivities, not just between Rh single-atoms and clusters but also among the different single-atom species. The activity of all model systems was further tested during the presence of carbon monoxide. Surprisingly, the so far rather inactive in-surface Rh atoms turned out to exhibit promising properties when it comes to the upgrading of oxygenates.

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(3) Sharp, M. A.; Lee, C. J.; Mahapatra, M.; Smith, R. S.; Kay, B. D.; Dohnálek, Z. Preparation and Characterization of Model Homotopic Catalysts: Rh Adatoms, Nanoparticles, and Mixed Oxide Surfaces on Fe₃O₄(001). *The Journal of Physical Chemistry C* **2022**, *126* (34), 14448-14459. DOI: 10.1021/acs.jpcc.2c03426.

3:15pm SS-WeA-5 Structure of Chemisorbed 1,3-Butadiene on the Cu(111) Surface and Its Influence on Selective Hydrogenation on a Pd/Cu(111) Single-Atom-Alloy, Mohammad Rahat Hossain, Michael Trenary, University of Illinois - Chicago

The selective hydrogenation of 1,3-butadiene (BD) to 1-butene (1-B) is essential for refining alkene streams in high-quality polymer production. Traditional catalysts such as Pd and Pt exhibit nearly barrierless H₂ activation but suffer from CO-induced coking and excessive activity, which lowers selectivity. Single-atom alloy (SAA) catalysts, such as Pd/Cu(111), offer a promising alternative by leveraging the selective properties of Cu while maintaining Pd's hydrogenation activity. We investigated BD adsorption and hydrogenation on Cu(111) and a Pd/Cu(111) SAA using reflection absorption infrared spectroscopy (RAIRS), temperature-programmed desorption (TPD), and density functional theory (DFT). TPD and RAIRS studies reveal that BD adsorption on Cu(111) exhibits intermediate interaction strength—more substantial than physisorption on Ag(111) and Au(111) but weaker than chemisorption on Pd(110) and Pt(111). Unlike strongly reactive surfaces that induce BD dissociation upon heating, BD desorbs intact from Cu(111). DFT analysis suggests that BD adopts both di- π and tetra- σ chemisorbed configurations on Cu(111). Over a Pd/Cu(111) SAA, ambient-pressure hydrogenation experiments indicate a first-order reaction (1.12 \pm 0.03) for H₂ and zero-order (-0.12 \pm 0.01) for BD, with a turnover frequency of 36 s⁻¹ at 380 K and an activation energy of 63.2 \pm 2.8 kJ/mol. Complete BD conversion is achieved with 84% selectivity toward 1-B without butane formation. TPD in ultrahigh vacuum (UHV) shows that monolayer BD desorbs at 217 K. In contrast, multilayers desorb between 112 and 180 K. No surface-bound intermediates are detected during reaction conditions. Post-reaction Auger electron spectroscopy (AES) reveals no carbon deposition, indicating no BD dissociation. These findings provide insights into BD adsorption and selective hydrogenation mechanisms on Cu-based catalysts, with implications for improving alkene purification strategies.

3:30pm SS-WeA-6 Well-Defined Cu-Delafossite Catalysts, Dario Stacchiola, Brookhaven National Laboratory

Cu-based catalysts are active for partial and full oxidation reactions. Deciphering the local atomic environment and oxidation state of active centers in supported copper catalysts, as well as the design of materials to control their stability under reaction conditions remains a great challenge. We show here that mixed-oxides of copper delafossites with gallium, aluminum or iron (CuMO₂, Cu¹⁺ and M³⁺; M: Ga, Al, Fe) in the form of porous nanoplates and films are promising materials as model catalysts to explore the activity and stability of Cu¹⁺-activated reactions. *In situ* experiments allow the observation of dynamic processes and phases under reaction conditions.

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“CuGaO₂ Delafossite as a High-Surface Area Model Material for Cu⁺ Activated Reactions”

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“PLD of Delafossite Oxide Thin Films on YSZ (001) Substrates as Solar Water Splitting Photocathodes”

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4:15pm SS-WeA-9 Formation of Monodispersed Palladium–Tellurium Nanoclusters on WTe₂(001): The Role of Excess Tellurium and Water, Zdenek Dohnálek, Pacific Northwest National Laboratory INVITED

Understanding how metals and adsorbates interact with transition metal dichalcogenides is crucial for next-generation electronic, quantum, and catalytic applications. In this work, we explore palladium deposition on WTe₂(001) to reveal how mobile excess tellurium drives the formation of uniform, thermally stable PdTe_x nanoclusters. Surprisingly, these clusters assemble independently of intrinsic surface defects. Upon annealing, they adopt identical size and structure, remaining stable up to \sim 500 K. Further investigation reveals that, contrary to common belief, the surface defects are hydroxylated rather than bare Te vacancies. The hydroxylation results from the adsorption and dissociation of background water, even under ultrahigh vacuum conditions. Density functional theory modeling supports these observations, explaining both the preferential nucleation of PdTe_x clusters and the passivation of defects via water dissociation. These findings highlight how excess chalcogen atoms and water adsorption steer metal deposition, offering new pathways for creating robust, monodisperse nano-alloy structures for advanced quantum devices, microelectronics, and catalysts.

4:45pm SS-WeA-11 Thermally Driven Chemical and Morphological Transition of Nb₂O₅ to NbO, Jasper Brown, Van Do, Steven Sibener, University of Chicago

The structure and morphology of niobium surfaces plays a crucial role in the performance of superconducting radiofrequency (SRF) cavities, particle accelerators, and other advanced technological applications that require high-purity and low-defect materials. The presence of a native Nb₂O₅ oxide layer on Nb and anodized Nb surfaces introduces irregularities that can negatively influence superconducting properties, necessitating precise control over oxidative states. In this study, the dissolution-driven modification of Nb and anodized Nb surface roughness associated with the thermal reduction of Nb₂O₅ under high-temperature vacuum annealing conditions is examined. Using *in-situ* atomic force microscopy (AFM) the topographical evolution of Nb surfaces before and after oxide dissolution is characterized and changes in roughness at the nanoscale are quantified. Additionally, *in-situ* X-ray photoelectron spectroscopy (XPS) is employed to confirm the alteration of the surface oxide from Nb₂O₅ to NbO, providing insights into the chemical state evolution that drives this transformation. By systematically varying heating rates, annealing temperatures, and annealing times, the specific thermal and temporal conditions necessary to achieve the transition from pentoxide to monoxide are determined.

5:00pm SS-WeA-12 Size and Support Effects on Propanol Electro-Oxidation Catalyzed by Sub-Nano, Size-Selected Ptn Clusters, Zihan Wang, Lokesh Saravanan, Ratul Khan, Thaylon Hernandez, Scott Anderson, University of Utah

The electrocatalytic oxidation of 1-propanol and 2-propanol by size-selected Ptn clusters supported on indium tin oxide (ITO) and highly oriented pyrolytic graphite (HOPG) has been investigated. Ptn clusters are generated and mass selected in the gas phase, then soft landed (\sim 2 eV/atom) onto electrode surfaces prepared in UHV with controlled surface chemistry and defect density. After deposition, samples are transferred into a load-lock chamber, where aqueous electrochemistry can be carried out

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without air exposure. Electrochemical activity is evaluated using cyclic voltammetry (CV), and the cluster size and support effects are analyzed in combination with X-ray photoelectron spectroscopy (XPS), transmission electron microscopy (TEM), and scanning transmission electron microscopy (STEM).

We find that both the activity and selectivity for propanol oxidation depend on Pt_n size and the support surface structure. Furthermore, catalytic activity correlates with Pt core-level binding energies measured by XPS, suggesting that electronic structure is tuned by the cluster size and the support. For each support, activity varies with cluster size; overall, clusters supported on HOPG exhibit higher activity than those on ITO. In addition, the activity depends strongly on the ITO surface composition, which was varied by sputtering with Ar and annealing in O₂. For HOPG, the problem is that the weak Pt-HOPG binding leads to facile sintering, and atomic anchors such as nitrogen or titanium atoms are implanted to stabilize the clusters. The effects of the anchors on both electrochemical activity and stability, and on the cluster electronic properties will be discussed. This work is supported by the NSF Center for Synthetic Organic Electrochemistry (CHE-2002158).

5:15pm SS-WeA-13 Adsorption of Carboxylic Acids and Reaction-driven Morphological Changes on the Fe₃O₄(001) Surface, *Jose Ortiz-Garcia¹, Marcus Sharp, Benjamin Jackson, Mal Soon Lee, Peter Rice, Bruce Kay, Zbynek Novotny, Zdenek Dohnalek, PNNL*

Understanding the adsorption and conversion of carboxylic acids, such as formic acid and acetic acid, on oxide surfaces, including the cleavage of their C-O and C-H bonds, is essential for understanding CO₂ reduction and C-C coupling reactions. Formate acts as a key intermediate in CO₂ hydrogenation, while acetate serves as a crucial reactant in C-C coupling ketonization reaction. To unravel the catalytic activity and mechanistic details of these reactions, it is crucial to understand the interactions of carboxylic acids with model catalytic systems. We investigate the adsorption and reactions of formic acid (FA) and acetic acid (AA) on Fe₃O₄(001) using STM, XPS, LEED, and TPD. On the pristine surface, a $(\sqrt{2} \times \sqrt{2})R45^\circ$ reconstruction is observed, attributed to subsurface cation vacancies. FA and AA adsorb dissociatively, forming bidentate species and surface hydroxyls. At room temperature, both fully saturate the surface, exhibiting (1×1) periodicity from ordered bidentate species and hydroxyls, and (2×1) from distinct monolayer packing. Differences emerge upon annealing. For FA, annealing to 500 K leads to a rearrangement to the lowest energy (1×1) configuration, while at 600 K, partial recovery of the surface reconstruction and potential formation of single oxygen vacancy defects occur. Increasing the temperature to 700 K results in complete conversion of formate species and the formation of extended pits along the Fe rows. In contrast, AA shows stability up to 450 K without considerable morphological changes. Conversion begins at 550 K, with significant surface etching occurring at 650 K, leading to an irregularly pitted surface primarily elongated along the Fe rows. In comparing total etching for both molecules, AA leads to significantly more at approximately 21% of the surface area while FA etches only 3.3% of the surface. Higher etching for AA stems from additional hydrogen atoms leading to more H₂O formation via the Mars-van Krevelen mechanism and nonstoichiometric formation of CO₂ and CO, resulting in extensive pitting. Complete surface recovery is achieved via oxygen annealing at 930 K. To further understand the nature of the etch pit structures formed by these carboxylic acids, we employed density functional theory calculations, which provided insights into the atomic-scale structure of the etch pits. Simulated STM images closely align with experimental observations, reinforcing our understanding of the structural characteristics of the etched regions. Our findings highlight the importance of understanding carboxylate interactions with oxide surfaces, which is crucial for overcoming kinetic barriers in reaction pathways.

5:30pm SS-WeA-14 Oxidation of a Rh(111)/(322) Bisected Crystal, *Maxwell Gillum, Alexis Gonzalez, Elizabeth Serna-Sanchez, Allison Kerr, Stephanie Danahey, Loyola University Chicago; Arved Dorst, Johannes Dietrich, Georg-August Universität, Göttingen, Germany; Tim Schäfer, Georg-August Universität, Göttingen, Germany; Dan Killelea, Loyola University Chicago*

Metal-catalyzed oxidation reactions are a major application of heterogeneous catalysis and are a widely applied synthetic route for the production of chemicals and reagents essential to modern society. The studies herein further investigate the influences that step density has on the formation of oxygen-induced surface reconstructions, linking lab-based single crystal studies to the high defect density surfaces present in

industrial catalysis. The experiments focus on gaining structural information about the oxygen species present on the surface of a Rh(111)/(322) bisected crystal under various oxidative conditions utilizing low energy electron diffraction (LEED). These techniques are used in unison with temperature programmed desorption (TPD) and Meitner-auger electron spectroscopy (MAES) to identify optimal conditions for further study. We found that the (322) facet of the surface shows presence of oxide formation under oxidative conditions that are not aggressive enough to form oxide on the flatter (111) Rh surface. This indicates that the step edges play a much larger role in the formation of oxide on the Rh surface than previously thought.

Thin Films

Room 206 B W - Session TF1-WeA

VSHOP V – Vapor Synthesis of Hybrid Materials and Their Properties

Moderators: *Yifan Cheng, Virginia Tech, Matthias Young, University of Missouri*

2:15pm TF1-WeA-1 Hybrid Molecular Layer Deposition of Multi-Metal Alkoxide Resists for Electron Beam and Extreme Ultraviolet Lithography, *Long Viet Than, Stacey F Bent, Stanford University*

Molecular layer deposited (MLD) metal-organic photoresists have the potential to address the material challenges of extreme ultraviolet (EUV) lithography due to their advantages in thickness control and chemical homogeneity. Previous studies have utilized simple MLD schemes with a single precursor and counter-reactant pair to achieve patterning close to industrially relevant length scales. However, for further optimization, layer-by-layer deposition of multi-component films via a supercycle approach may be required to adjust properties such as sensitivity, contrast, etch resistance, mechanical strength, and others.

In this work, we explore the properties of multi-component MLD photoresists by depositing multi-metal alkoxide ('metalcone') films via both trimethylaluminum (TMA) and diethylzinc (DEZ), and ethylene glycol as the counter-reactant. Using a supercycle approach in which cycles of alucone growth (TMA and EG) are evenly distributed with cycles of zincone growth (DEZ and EG), we grow the multi-metalcone films with a range of Al/Zn ratios and characterize their properties. X-ray photoelectron spectroscopy (XPS) shows that significant transmetalation of Al and Zn occurs during deposition. However, the metal fraction can still be controlled between 40% and 95% Al (normalized against Al + Zn) by varying the fraction of alucone cycles within the supercycle between 0.25% and 50%. To assess the effect of the Al/Zn ratio on resist performance, line/space gratings with 24 nm half pitch are patterned on ~25 nm thick resist films via electron beam lithography as a proxy for EUV lithography and developed with hydrochloric acid at varying concentrations. The results show that compared to pure alucone or zincone films, the multi-metal resists have similar e-beam sensitivity (~70-100 mC/cm² depending on development conditions), but enhanced lithographic contrast (improving from a value of $\gamma = 0.38$ for alucone to a value of $\gamma = 6.3$ for the multi-metalcone) and pattern quality (reduced bridge defects and scumming). The improvements are observed even for minimal Zn incorporation in the multi-metalcone (~95% Al). From XPS studies of the resists after partial development, we attribute the improvement to the preferential dissolution of zincone from the unexposed multi-metal resist, which enhances solubility contrast. This work demonstrates the potential of supercycled MLD schemes to enable emergent interactions between components, vastly expanding the design space for this class of photoresists.

2:30pm TF1-WeA-2 High-Throughput MLD Screening of Photoresists for EUV Lithography via UV and E-Beam Exposure, *Duncan Reece, David Bergsman, University of Washington*

As semiconductor patterning pushes toward sub-5 nm features, next-generation photoresists must deliver high resolution, environmental and chemical stability, and compatibility with extreme ultraviolet (EUV) lithography processes. However, EUV photoresist materials explored to date still face challenges such as ease of deposition and achieving sub-nanometer chemical uniformity. Molecular layer deposition (MLD) offers precise control over thin-film structure and composition, enabling the design of hybrid materials tailored to meet these challenges. Previous work has demonstrated MLD-based EUV photoresists incorporating aluminum (Al) and tin (Sn); however, the influence of the organic reactant on the final photoresist properties remains largely underexplored. Using our custom

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high-throughput multi-chamber MLD system, we synthesized 18 organic-inorganic hybrid films from two organometallic precursors—trimethylaluminum diethylzinc, and tetrakis(dimethylamino)tin(IV)—paired with six organic linkers: hydroquinone bis(2-hydroxyethyl) ether, 1,2,4-trihydroxybenzene, 1,5-hexadiene-3,4-diol, 2-butyne-1,4-diol, cis-2-butene-1,4-diol, and 3,4-dihydroxy-1-butene. Film candidates were screened for growth rate, ease of deposition, uniformity, and ambient stability. To assess potential photochemical reactivity, UV-induced crosslinking, or structural rearrangement, we measured thickness changes before and after solvent exposure, both with and without deep UV treatment. Selected high-performing films were subjected to electron beam lithography as a stand-in for EUV testing, followed by development to evaluate feature resolution and pattern fidelity using scanning electron microscopy and profilometry. Mechanical durability was assessed via nanoindentation, while chemical transformations were characterized with Fourier Transform Infrared Spectroscopy (FTIR) and X-ray Photoelectron Spectroscopy (XPS). Our results identify material systems that combine robust environmental and chemical resistance with promising lithographic performance and photo-reactive behavior. While EUV lithography remains the ultimate target application, e-beam serves as a high-resolution surrogate to guide photoresist development. This integrated approach demonstrates the power of high-throughput MLD and multi-parameter screening for accelerating the discovery of advanced materials for next-generation lithographic technologies.

2:45pm TF1-WeA-3 Transforming Photo-Polymerized Organic Networks into Ceramics via Vapor Phase Infiltration (VPI), Ronan Neill, Li Zhang, Mark Losego, Georgia Institute of Technology

Micropatterning of 3-dimensional structures from arbitrary ceramic materials is complicated and often expensive. In this work, we explore a new platform technology for converting an easily patterned photopolymerizable resin into a 3D ceramic structure using vapor phase infiltration (VPI) and subsequent thermal combustion. VPI is a gas-phase technique in which inorganic vapors are sorbed into a polymer, creating an organic-inorganic hybrid material. Here we are interested in studying how the chemical design of this hybrid material can affect the thermal combustion process and its conversion to a final ceramic component, without significant cracking. Ethoxylated trimethylolpropane triacrylate (ETPTA) photo-polymerizable monomers are used because they are already known to create compliant networks that readily sorb high fractions of inorganic precursors during VPI. After VPI with trimethyl aluminum (TMA) and water, the hybrid films were thermally annealed to fully combust all organics. In this talk, we will discuss how process parameters including reactor temperature and precursor exposure duration affect cracking, shrinkage, and ceramic density. In general, increased precursor loading during VPI results in reduced cracking of the alumina film, and upwards of 60% of the original film thickness could be retained after organic burnout. To assess changes in the lateral dimension micro-patterned structures were also tested, and minimal change in lateral size were detected, likely due to substrate clamping.

3:00pm TF1-WeA-4 Measuring the Coefficient of Thermal Expansion for Vapor Phase Infiltrated Ultra-low-k Dielectric Materials for Advanced Packaging, Pragna Bhaskar, Li Zhang, Mohanalingam Kathaperumal, Mark Losego, Georgia Institute of Technology

Advanced interposers consist of alternate layers of copper and polymer dielectric materials. While copper has a low coefficient of thermal expansion (CTE) of 16 ppm/ °C, ultra-low-k dielectric materials have CTEs in the range of 50-150 ppm/ °C. This mismatch in CTE between copper and ultra-low-k dielectric materials results in lower thermomechanical reliability. Most methods available in literature involve the addition of oxide fillers to reduce the CTE of polymers. In this study, vapor phase infiltration (VPI) treatment is considered as a possible method to introduce AlO_x into dry films or spin-coated and cured films. Another challenge with respect to ultra-low-k dielectric films is the measurement of CTE. Conventional CTE measurement techniques such as thermomechanical analysis (TMA) require a sample thickness of the order of few millimeters. The films in the present study have thicknesses in the range of 0.5 to 5 µm matching closely with the typical dielectric layer thickness employed in advanced packaging substrates with very high-density interconnects. Therefore, TMA cannot be used for CTE measurement of these films. Instead, temperature dependent spectroscopic ellipsometry is used to track the thermal expansion of the films and determine their CTE. These measurements demonstrate the effectiveness of the VPI process to lower the CTE of low dielectric constant polymers by about 4 to 15 times depending on the dielectric polymer,

placing them near the CTE of copper. The chemical mechanisms for this lowering of the CTE will be discussed in this talk.

3:15pm TF1-WeA-5 Machine Learning Predictions for Selecting Organic Small Molecules in Atomic Layer Processing, Lucas R Kuehnel, Erick A Gutierrez-Monje, Anthony A Khouri, Campbell A Sweet, Matthias J Young, University of Missouri-Columbia

Selecting organic small molecule inhibitors for area-selective atomic layer deposition and organic precursors for oxidative molecular layer deposition requires knowledge of chemical properties such as pKa, oxidation potential, physical phase, and vapor pressure. However, these data are not readily available for many candidate molecules. Machine learning using molecule-based message passing graph neural network (MPNNs) provides a strategy to establish statistical models connecting molecular structure to these physical properties using tabulated data. These models can be used to rapidly predict the properties for compounds where this data has not been measured. Here, we employ Chempop, an established user-friendly MPNN framework, to predict chemical properties of organic small molecules relevant to atomic layer processing applications. We report on MPNN models to predict boiling point, melting point, pKa, oxidation potential, and vapor pressure given only SMILES strings as user input. At the time of submission, the mean absolute errors of baseline model predictions on unseen test data are 15.0 K for boiling point, 29.4 K for melting point, 0.749 log units for pKa, and 0.353 V for oxidation potential. The median absolute percent error is 12.5% for vapor pressure. We describe opportunities to integrate such models into semi-autonomous workflows for chemical innovation and discovery relevant to the atomic layer processing communities.

3:30pm TF1-WeA-6 Physical Vapor Deposition of Metal Iodide Thin Films for Radiation Detections, Jun Wang, Radiation Monitoring Devices Inc.; Matthew Loyd, Oak Ridge National Laboratory; Nicholas Anastasi, Lakshmi S. Pandian, Vivek V. Nagarkar, Radiation Monitoring Devices Inc.

Metal iodides, when doped with lanthanide elements, are crucial materials in radiation detection, medical imaging, and high-energy physics applications. They belong to a class of materials called scintillators, which emit photons (fluorescence) when exposed to ionizing radiation. Metal iodide scintillators offer high light output, good energy resolution and scalability, especially in the thin film format. They can be scaled up to a few inch² or more for practical applications. However, the hygroscopic nature of these materials hinders the development and commercialization of such scintillators. At Radiation Monitoring Devices, Inc., we specialize in overcoming these challenges and developing such metal iodide scintillators through a controlled growth environment and hermetic sealing techniques. Here we present the development of a well-known lithium iodide (LiI) scintillator, in a large micro-columnar thin film of up to 4 inch² in size via a physical vapor deposition in a special integrated glovebox system. The developed LiI film doped with europium (Eu) scintillator boasts a remarkable ultra-high brightness of approximately 22 times that of GS20 (commercially available screens), while the cerium (Ce) doped LiI film offers an ultra-fast decay time of 50 ns. Both films offer a high spatial resolution, excellent gamma-neutron discrimination and high detection efficiency for advanced thermal neutron imaging applications, which are especially suitable for integration with special neutron detectors in national neutron facilities such as Spallation Neutron Source (SNS) and High Flux Isotope Reactor (HFIR) at Oak Ridge National Laboratory. We report recent advancements in the fabrication and characterization of such next-generation LiI scintillator films for thermal neutron imaging applications.

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Thin Films

Room 206 B W - Session TF2-WeA

Fundamentals of Thin Films II

Moderator: Qihua Zhang, Pennsylvania State University

4:15pm TF2-WeA-9 Flipping the Switch on Tin Sulfide Deposition: From SnS to SnS₂, Christopher Brewer, Hy Nguyen, Reed Woolard, Amy Walker, University of Texas at Dallas

Tin sulfides (Sn_xS_y) are non-toxic and inexpensive materials with low band gaps, making them suitable for semiconductor applications and photovoltaic materials, such as solar cells. Sn_xS_y has three naturally

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occurring compositions, SnS , Sn_2S_3 , and SnS_2 . The ability to control the stoichiometry of a Sn_xS_y deposit is of interest for devices like SnS solar cells, where Sn_2S_3 contamination reduces the device efficiency. Tin disulfide is an emerging 2D layered metal dichalcogenide which has applications in electronics and as a photodetector. In this study we investigate the selective deposition of tin sulfides using chemical bath deposition (CBD) on organic substrates. We employ alkanethiolate self-assembled monolayers (SAMs) functionalized with $-\text{CH}_3$, $-\text{OH}$, and $-\text{COOH}$ terminal groups as model organic substrates. Our data shows that the substrate functionality does not strongly influence the composition of the deposit. Rather, the tin sulfide deposition can be flipped from SnS to SnS_2 by changing tuning the bath pH. Under basic conditions using tin(II) chloride and thioacetamide, pure SnS is deposited at $\text{pH} \geq 11$. The data also suggests that the functional group of the SAM directs the phase of the SnS deposited, providing potentially an easier route to the newly discovered cubic SnS phase. In contrast, under acidic conditions SnS_2 is deposited using tin(II) chloride and tartaric acid as a complexing agent. The deposition results will be discussed in the context of our mechanism based approach to tune the bath chemistry to achieve composition control of the Sn_xS_y deposit.

4:30pm TF2-WeA-10 Homoepitaxial Growth of ZrB_2 on a $\text{ZrB}_2(0001)$ Surface, *Michael Trenary, Ayoyele Ologun*, University of Illinois - Chicago

Zirconium diboride (ZrB_2), a group-IV metal-terminated diboride, is an extremely hard material with a high melting point of 3246 °C. Thin films of ZrB_2 can be grown conformally via chemical vapor deposition (CVD) using zirconium borohydride, $\text{Zr}(\text{BH}_4)_4$, as a precursor. Homoepitaxial growth of ZrB_2 was studied using scanning tunnelling microscopy (STM). Exposure of $\text{Zr}(\text{BH}_4)_4$ to the $\text{ZrB}_2(0001)$ surface at 1400 K led to the formation of ZrB_2 islands. Coarsening of the ZrB_2 islands into layers via Smoluchowski ripening was observed when the islands were left for 60 minutes at 1400 K before imaging at room temperature. In contrast, exposure at 900 K resulted in high-density clusters. Stepwise annealing at 1400 K led to the transformation of these clusters into a continuous thin film via thermal-induced coalescence, with moiré patterns observed as intermediate structures during this coalescence process.

4:45pm TF2-WeA-11 Multilayered Films for High Hardness, *Nestor Marquez Rios, Nathaniel McIlwaine, Jon-Paul Maria*, The Pennsylvania State University

Multilayered high entropy carbide films were synthesized by physical vapor deposition (PVD) using bipolar high-power impulse magnetron sputtering (HiPIMS) with methane gas as the carbon source. Shutter automation and asynchronous plasma were used to alternate between two HiPIMS cathodes, enabling modulation of the metal composition leading to superlattice structure formation. The resulting structure consists of two rock salt structured solid solution layers forming a periodic multilayer. Crystallinity was characterized by X-ray diffraction (XRD), which demonstrated the ability to grow multilayer sequences with modulated periods ranging from 3 nm to 50 nm, engineered to reach a total film thickness of 1.5 μm . Changes in the position of low and high order satellite peaks were observed confirming a multilayer period consistent with the designed bilayer thickness. Surface morphology and topography were characterized using scanning electron microscopy (SEM) and atomic force microscopy (AFM). Mechanical properties were evaluated using Knoop and Vickers microindentation techniques to determine the influence of nanoscale engineering by making multilayer on hardness.

5:15pm TF2-WeA-13 Machine-Learned Relationships between Particle Flux, Kinetic Energy, and Experimental Conditions in Pulsed Laser Deposition, *Zahra Nasiri, Dorien Carpenter, Jacob H Paiste*, University of Alabama at Birmingham; *Sumner B Harris*, Oak Ridge National Laboratory, USA; *Renato P Camata*, University of Alabama at Birmingham

In pulsed laser deposition (PLD), the kinetics of crystal growth is strongly dependent on the flux (Φ) and the kinetic energy (K) of plume species arriving at the substrate. These factors vary widely with target materials and deposition conditions. While scaling laws and prior experience provide some guidance, quantitatively predicting the dependence of Φ and K on the laser fluence (F) and spot area (A) is challenging. Even in well-established PLD laboratories, it is typical for only limited regions of the functions $\Phi(F, A)$ and $K(F, A)$ to be known for specific materials and laser wavelengths. Moreover, these regions often shift due to target surface evolution and subtle experimental variations, demanding time-consuming and costly re-optimization experiments.

Machine learning (ML) algorithms can process PLD plume diagnostic data in real time and generate high-quality dynamic models of $\Phi(F, A)$ and $K(F, A)$. These can be integrated into decision-making workflows to control

experimental actuation, either to maintain or deliberately adjust thin film growth conditions according to specified protocols.

In this work we show how high-fidelity representations of $\Phi(F, A)$ and $K(F, A)$ can be generated by Gaussian Process Bayesian Optimization (GPBO) from a small number of experiments. A Gaussian process regression model is trained on progressively accumulating data to produce surrogate models of the objective functions $\Phi(F, A)$ and $K(F, A)$. We compare active learning workflows using different acquisition functions and GP kernels with random sampling. We evaluate the process using synthetic PLD data generated by laser ablation-fluid dynamics simulations. The model produces physically plausible $\Phi(F, A)$ and $K(F, A)$ for specific PLD conditions and target materials. Typical results for PLD of copper (Cu) with $F = 1\text{--}10 \text{ J/cm}^2$ and $A = 0.8\text{--}13 \text{ mm}^2$ —obtained from 1000 model runs starting with random 3-point seed pairs of (F, A) —show that our GPBO process can discover optimum flux and kinetic energy conditions after as few as three iterations (i.e., experiments) using the probability of improvement (PI) acquisition function. Finally, we will show how introducing a physics-informed, structured mean in the Gaussian process—based on the well-known scaling behavior of Φ and K with vapor density (proportional to F) and Mach number of the expansion (proportional to A)—affects the performance of the GPBO.

Thursday Morning, September 25, 2025

2D Materials

Room 208 W - Session
2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM

2D Materials: Optoelectronics and Moire Excitons

Moderator: Daniel Yimam, Oak Ridge National Laboratory

8:00am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-1 Probing the Ultrafast Charge Dynamics and Exciton Emission from Single Atomic Defects in 2D Semiconductors by Lightwave-Driven STM**, *Laric Bobzien, Lysander Huberich, Jonas Allerbeck, Eve Ammerman, Nils Krane, Andres Ortega-Guerrero, Carlo Pignedoli, Oliver Gröning*, Empa, Swiss Federal Laboratories for Materials Science and Technology, Switzerland; *Joshua A. Robinson*, The Pennsylvania State University; *Bruno Schuler*, Empa, Swiss Federal Laboratories for Materials Science and Technology, Switzerland **INVITED**

Two-dimensional (2D) semiconductors provide an exciting platform to engineer atomic quantum systems in a robust, yet tunable solid-state system. This talk explores the intriguing physics of single point defects in transition metal dichalcogenide (TMD) monolayers, investigated through atomically resolved scanning probe microscopy.

We have determined the layer-dependent charge transfer lifetimes of selenium vacancies in WSe₂ on graphene substrates, spanning picosecond to nanosecond timescales [1]. By leveraging our recently developed lightwave-driven scanning tunneling microscope (THz-STM) [2,3], we could probe the ultrafast charge dynamics on the atomic scale. Time-domain sampling with a THz pump-THz probe scheme enabled capturing atomic-scale snapshots of transient Coulomb blockade, a hallmark of charge transport mediated by quantized defect states [4].

Moreover, the extended charge state lifetimes provided by hBN decoupling layers facilitated the local, electrical stimulation of excitonic emission from pristine MoS₂ and individual charged defects via STM luminescence (STML).

By combining the structural and electronic properties accessible by conventional scanning probe microscopy with the optical fingerprint from STML and the excited-state dynamics revealed through pump-probe THz-STM, we gain a comprehensive microscopic understanding of localized quantum states in low-dimensional materials.

References:

- [1]L. Bobzien et al. Phys. Rev. Lett. (accepted, arxiv: 2407.04508)
- [2]J. Allerbeck et al. ACS Photonics 10, 3888 (2023)
- [3]L. Bobzien et al. APL Mater. 12, 051110 (2024)
- [4]J. Allerbeck et al. arXiv:2412.13718 (2024)
- [5]L. Huberich et al. (in preparation)

8:30am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-3 Many-Body Effects on Excitons, Trions, and Defect-Bound States in 2D Materials**, *Kai Xiao, Taegwan Park, Alexander Puretzky*, Oak Ridge National Laboratory, USA; *Xufan Li*, Honda Research Institute; *Kyungnam Kang*, Oak Ridge National Laboratory, USA; *Austin Houston*, University of Tennessee, Knoxville; *Christopher Rouleau, David Geohegan*, Oak Ridge National Laboratory, USA

Two-dimensional (2D) materials, particularly transition metal dichalcogenides (TMDs) exhibit strong many-body interactions due to reduced dielectric screening and spatial confinement. These interactions, involving electrons, holes, excitons, phonons, and plasmons, give rise to emergent phenomena distinct from their bulk counterparts. In this talk, I will present our recent investigations into the many-body effects on the optical properties and ultrafast excitonic dynamics of monolayer and bilayer TMDs. Specifically, we synthesized isotopically pure monolayer MoS₂ and highly defective WS₂ via nonequilibrium chemical vapor deposition, enabling a controlled study of isotope effects, defects, and background doping on excitonic behavior. Using ultrafast laser spectroscopy and temperature-dependent optical spectroscopy, we observed pronounced many-body interactions, including exciton-phonon and exciton-electron coupling, which significantly influence exciton energy, dynamics, and light-matter interactions in both monolayer and bilayer TMDs. These strong interactions give rise to novel quantum states and make 2D materials promising platforms for next-generation optoelectronics, quantum information technologies, and fundamental condensed matter physics.

Synthesis science was supported by the U.S. Dept. of Energy, Office of Science, Materials Science and Engineering Division. This work was performed at the Center for Nanophase Materials Sciences, which is a DOE Office of Science User Facility.

8:45am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-4 Proximity-Induced "Magic" Raman Bands in TERS Spectra of MoS₂ / WS₂ @ 1L H-BN-Capped Gold**, *Andrey Krayev*, HORIBA Scientific; *Pavel Valencia Acuna*, PNNL; *Ju-Hyun Jung*, Pohang University of Science and Technology (POSTECH), Republic of Korea; *Cheol-Joo Kim*, POSTECH, Republic of Korea; *Andrew Mannix*, Stanford University; *Eleonora Isotta*, Max Planck Institute for Sustainable Materials, Germany; *Chih-Feng Wang*, PNNL

Recently it was proposed to use the monolayer h-BN – capped gold substrates as an ideal platform for the gap mode TERS and TEPL imaging, that on the one hand, should preserve strong gap mode enhancement of Raman signal due to small thickness (0.3 nm) of the dielectric h-BN layer, and on the other hand preserve strong TEPL response due to de-coupling of 2D semiconductors from the metallic substrate. TERS data collected on mono- and a few-layer-thick crystals of MoS₂ and WS₂ on 1L-h-BN-capped gold show both the TERS and TEPL response, confirming the validity of the proposed approach.

In addition to the enhancement of both the PL and Raman signal, in the course of assessment of TERS/TEPL response of mono- and a few-layer-thick crystals of MoS₂ and WS₂ deposited on 1L h-BN-capped gold we observed in TERS spectra, completely unexpectedly, appearance of Raman bands at about 796 cm⁻¹ and 76 cm⁻¹ which are not normally observed in regular Raman spectra of h-BN or WS₂/MoS₂. We can safely state that these "magic" bands belong to h-BN as they appear at the same spectral position in TERS spectra of both the monolayer MoS₂ and WS₂ deposited on the monolayer h-BN capped gold, moreover, the 796 cm⁻¹ band often was the strongest band observed in TERS spectra, even stronger than A' mode from WS₂ or MoS₂. Presence of the transition metal dichalcogenide (TMD) monolayer is mandatory for the appearance of these "magic" bands as they are absent outside of the monolayer TMDs in these samples. Literature search showed that similar (but not identical) phenomenon was observed earlier in h-BN encapsulated WSe₂,MoSe₂, and WS₂. There have been several significant differences between our data and the earlier reported one: in our case we have not been able to observe the "magic bands" in MoSe₂ and WSe₂ @ 1L h-BN@Au, while WS₂ monolayers deposited on the same substrate as WSe₂, showed expected response. More importantly, the excitation laser wavelength dependence in our case was completely different from what was reported earlier: in WS₂-based samples we observed strong "magic" bands with excitation at 830 nm, 785nm, 594nm, but not 633nm, the wavelength closest to the A exciton in this material. This excitation profile is remarkably reminiscent of the excitation profile of the monolayer WS₂ in intimate contact with silver where we observed strong dip of the intensity of main A' mode in TERS spectra at 633nm excitation wavelength.

We will argue that intricate interaction between the tip-substrate gap plasmon, TMD excitons and most probably, normally mid-IR-active phonons in h-BN is responsible for the appearance of observed "magic" bands.

9:00am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-5 Correlated Excitons in TMDC Moiré Superlattice**, *Sufei Shi*, Carnegie Mellon University **INVITED**

In a strongly correlated electronic system, Coulomb interactions among electrons dominate over kinetic energy. Recently, two-dimensional (2D) moiré superlattices of van der Waals materials have emerged as a promising platform to study correlated physics and exotic quantum phases in 2D. In transition metal dichalcogenides (TMDCs) based moiré superlattices, the combination of large effective mass and strong moiré coupling renders the easier formation of flat bands and stronger electronic correlation, compared with graphene moiré superlattices. Meanwhile, the strong Coulomb interaction in 2D also leads to tightly bound excitons with large binding energy in TMDCs. In this talk, we will discuss how to use optical spectroscopy to investigate excitonic physics and strongly correlated phenomena in TMDC moiré superlattice, along with correlated exciton states arising from strong interactions.

9:30am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-7 Sub-Stoichiometric Phases in 2D MoTe₂**, *Onyedikachi Alanwoko, Nirosha Rajapakse, Matthias Batzill*, University of South Florida

Atom vacancy formation in crystalline materials is energetically expensive. To lower the energy cost for non-stoichiometry, point defects can condense into energetically more favorable extended defects. Studies on Mo-dichalcogenides have shown that excess Mo is condensed into closed, triangular Mirror Twin Boundary (MTB) loops. These MTBs can form in high densities where the triangular loops connect and form a cross-hatched network of MTBs. Here we show through Scanning Tunneling Microscopy (STM) that periodically ordered MTB networks can obtain a homologous series of sub-stoichiometric MoTe_{2-x} phases. We systematically investigate

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the preparation conditions (which include a variation of the growth temperature, Te-desorption by post-growth annealing, and vapor-deposited Mo), enabling the controlled synthesis of these new phases. The different phases require different synthesis procedures, and once formed, these phases appear thermally stable in vacuum. The ability to control and create these different phases of MoTe₂ and other two-dimensional (2D) materials is a promising way of realizing new electronic and chemical properties of 2D materials. Particularly promising is the observation that we can react MoTe₂ with dissimilar transition metals to create new doped or alloyed 2D materials with potentially desirable properties.

11:00am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-13** **Microwave Imaging of Excitonic States and Fractional Chern Insulators in 2D Transition Metal Dichalcogenides**, *Zhurun Ji*, SLAC National Accelerator Laboratory/ MIT **INVITED**

Nanoscale electrodynamics offers a unique perspective on states with bulk-edge correspondence or spatially dependent excitations. I will introduce our latest advancements in optically coupled microwave impedance microscopy, a technique that enhances our capability to explore electrodynamics at the nanometer scale. I will discuss our recent studies utilizing this technology to extract spectroscopic information on exciton excitations within transition metal dichalcogenide systems. Additionally, I will share our recent findings on probing topological and correlated electronic states, specifically the fractional Chern insulator states in twisted TMD bilayers.

11:30am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-15** **Control and Properties of Single Dislocations in Van Der Waals Nanowires**, *Peter Sutter, Eli Sutter*, University of Nebraska - Lincoln

Line defects (dislocations) not only govern the mechanical properties of crystalline solids but they can also produce distinct electronic, thermal, and topological effects. Identifying and accessing this functionality requires control over the placement and geometry of single dislocations embedded in a small host volume to maximize emerging effects. We have identified a synthetic route that enables the rational placement and tuning of dislocation in van der Waals nanowires, where the 2D/layered crystal structure limits the possible defect configurations and the nanowire architecture puts single dislocations in close proximity to the entire host volume.¹ While homogeneous layered nanowires carry individual screw dislocations, the synthesis of radial (core-shell) nanowire heterostructures transforms the defect into a mixed (helical) dislocation whose edge-to-screw ratio is continuously tunable via the core-shell lattice mismatch.

Such deterministic control over defects now enables the probing of functionality arising with single dislocations. For example, germanium sulfide van der Waals nanowires carrying single screw dislocations incorporate Eshelby twist and thus adopt a chiral twisted structure,² which for the first time allowed the identification of chirality effects in the photonic properties of a single nanostructure.³ Using cathodoluminescence spectroscopy, whispering gallery modes could be excited and probed to directly compare the photonics of chiral and achiral segments in single nanowires. The data show systematic shifts in energy, which with the help of simulations are assigned to chiral whispering gallery modes in wires hosting a single dislocation.

The ability to design nanomaterials containing individual dislocations with controlled geometry paves the way for identifying a broad range of functional properties of dislocations, with the potential to herald a paradigm shift from the traditional strategy of suppressing dislocations to embracing and harnessing them as core elements of new technologies.

1. P. Sutter, R.R. Unocic, and E. Sutter, *Journal of the American Chemical Society* 145, 20503 (2023); DOI: 10.1021/jacs.3c06469
2. P. Sutter, S. Wimer, and E. Sutter, *Nature* 570, 354 (2019); DOI: 10.1038/s41586-019-1147-x
3. P. Sutter, L. Khosravi-Khorashad, C.V. Ciobanu, and E. Sutter, *Materials Horizons* 10, 3830 (2023); DOI: 10.1039/D3MH00693J

11:45am **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-16** **Two-Dimensional Keldysh Theory for Non-Resonant Strong-Field Ionization of Monolayer 2D Materials**, *Tsing-Hua Her*, UNC Charlotte; *Che-Hao Chang*, NTHU, Taiwan; *Kenan Darden*, UNC Charlotte; *Tsun-Hsu Chang*, NTHU, Taiwan; *Hsin-Yu Yao*, NCCU, Taiwan

Over the past decade, a diverse array of intense light interactions with monolayer two-dimensional (2D) materials have been reported, including low- and high-order harmonic generation (HHG), multiphoton absorption, optical injection of spin and charge currents, terahertz generation, and

laser-induced dielectric breakdown. These processes are all initiated by interband transition of electrons induced by light with photon energy smaller than the bandgap energy. Some modeling efforts based on perturbation theory were attempted but their discrepancies with experiments are at least one order of magnitude, highlighting the lack of theoretical understanding of strong-field ionization in monolayer 2D materials. In this work, we report a new formalism of strong-field ionization for monolayer two-dimensional semiconductors based on 2D Keldysh (KLD) theory [T. -H. Her et al., *Optica* 12, 538-545 (2025)]. We take this approach because the original Keldysh theory [L. V. Keldysh, *Soviet Physics JETP* **20**, 8 (1965)] is the only theory that yields, for simplified band dispersion, analytical formulas for the cycle-averaged non-resonant ionization rate in bulk solids induced by a monochromatic electric field of arbitrary strength. It provides a smooth transition between multiphoton and tunneling ionization as what we now call the ‘Keldysh parameter’, , varies from $>>1$ to $<<1$. Due to their analyticity, Keldysh’s formulas are widely employed for qualitative modeling of strong-field ionization in bulk solids. In this presentation, we generalize Keldysh’s formulas to monolayer two-dimensional semiconductors. We derive closed-form formulas and their asymptotic forms for a two-band model with a Kane dispersion. We also derive selection rules related to the parity of multiphoton orders near the band edge. We validate our theory by comparing it to recent experiments and modeling of strong-field ionization in monolayer transition metal dichalcogenides (TMDs) with very good agreement (Figs. 1-3 of supplemental document) Specifically, our theory predicts a higher interband electron tunneling rate for 2D compared to 3D in the MIR frequency range, which successfully explains the 10x discrepancy (Fig. 3) between the experiment and modeling for HHG from monolayer TMDs [Liu et al., *Nature Phys* 13, 262–265 (2017)]. Considering the tremendous success of the original Keldysh theory in describing strong-field optical phenomena in atoms and solids, our 2D Keldysh theory is expected to find a wide range of applications in intense light-2D material interaction, such as optical limiting, multi-photon photodetection, THz generation through quantum interference, and photo-carrier doping for HHG.

12:00pm **2D+AQS+EM+MI+MN+NS+QS+SS+TF-ThM-17** **Thickness Dependent Band Gap and Electrical Anisotropy of 2DSnSe**, *Marshall Frye, Jonathan Chin, Joshua Wahl, Jeremy Knight*, Georgia Institute of Technology; *Walter Smith*, Purdue University; *Dilara Sen, Samuel Kovach*, Kenyon University; *Frank Peiris*, Kenyon College; *Charles Paillard*, University of Arkansas; *Thomas Beechem*, Purdue University; *Anna Osterholm, Lauren Garten*, Georgia Institute of Technology

2D SnSe presents unique opportunities for optoelectronics, and scalable microelectronics, but it is first critical to understand how the electrical and optical response change upon downscaling. Tailoring the band gap and electrical anisotropy of 2D monochalcogenides, like SnSe, has previously been shown but the mechanisms that drive the changes in band gap are still not understood. This study reveals how changes in bond length and structure drive the thickness dependences of band gap, carrier mobility and lifetime of SnSe thin films. Molecular beam epitaxy is used to deposit (2h00) oriented SnSe thin films with thicknesses ranging from 4 nm to 80 nm. The direct band gap increases from 1.4 eV at 80 nm to 1.9 eV at 4 nm, underscoring the potential of SnSe as a tunable and direct band gap material for thin film optoelectronics. Raman spectroscopy shows different simultaneous changes in the crystal structure and bonding occurring parallel versus perpendicular to the 2D plane with decreasing film thickness. TEM further supports the hypothesis that the increase in the band gap with reduced thickness is due to changes in crystal structure resulting in a contraction of the out-of-plane SnSe covalent bonds, while the in-plane bond length increases. In addition to the reduction in band gap, tracking the time dependent photoluminescence shows an increase in carrier lifetime with decreasing film thickness, while Hall measurements show a change in the carrier mobility with decreasing thickness. Overall, this work provides the critical missing insight needed to design these optically and electronically relevant 2D materials for scalability.

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Actinides and Rare Earths

Room 207 A W - Session AC+MI-ThM

Superconductivity, Magnetism, Electron Correlation and Complex Behavior

Moderators: Krzysztof Gofryk, Idaho National Laboratory, James G. Tobin, University of Wisconsin-Oshkosh

8:00am **AC+MI-ThM-1 Phase Transition and Magnetism in UTe₂**, *Dominik Legut*, VSB - Technical University of Ostrava, Czechia; *Alexander Shick*, Institute of Physics CAS, Prague, Czechia; *Urszula Wdowik*, VSB - Technical University of Ostrava, Czechia INVITED

For the magnetic properties of UTe₂ the correlated band theory implemented as a combination of the relativistic density functional theory with exact diagonalization [DFT+U(ED)] of the Anderson impurity term with Coulomb repulsion U in the 5f shell needs to be applied. This allows us to determine the orbital to spin ration as well as number of the uranium valence states in close correspondance with recent experiment (XANES, XMCD). The uranium atom 5f -shell ground state with 33% of f² and 58% of f³ configurations is determined[1]. In contrast to the above, for the bonding in UTe₂ it is satisfactory to be modelled by DFT+U methodology. We theoretically determined the lattice contribution to the specific heat of UTe₂ over the measured temperatures ranging from 30 to 400 K as well as the orthorhombic-to-tetragonal phase transition pressure of 3.8 GPa at room temperature in very good agreement with the recent experimental studies. Last, but not least we determined the Raman spectra that were compared with recent Raman scattering experiments as well.

[1] A. B. Shick, U. D. Wdovik, I. Halevy, and D. Legut, Spin and Orbital Magnetic Moments of UTe₂ induced by the external magnetic field, *Scientific Reports* **14**, 25337 (2024), <https://doi.org/10.1038/s41598-024-75321-4>.

[2] U. D. Wdowik, M. Valiska, A. Cabala, F. Borodavka, E. Samolova, and D. Legut, Raman spectroscopy and pressure-induced structural phase transition in UTe₂, *Frontiers of Physics*, **20**, 014204 (2025), <https://doi.org/10.15302/frontphys.2025.014204>.

8:30am **AC+MI-ThM-3 Single-ion Anisotropy Controls Magnetic Excitations in REMn₆Sn₆ (RE = Tb, Dy, Ho) Ferimagnetic Kagome Metals**, *Kelsey Collins, Michael Susner, Michael Newburger*, Air Force Research Laboratory, Materials and Manufacturing Directorate, USA INVITED

The REMn₆Sn₆ family of materials, where RE is a generic rare earth trivalent cation, have attracted much interest due to their complex electronic and magnetic structures. This complexity arises from the coupling of highly anisotropic lanthanide ions spins with large spin-orbit couplings to the spins of the Mn atoms, which are arrayed in a kagome lattice, a lattice topology known to give rise to exotic topological phenomena. This interplay of magnetic anisotropy and electronic topology motivates investigation into the magnetic excitations of these materials, which unlike the ground state magnetic structures of this family have not been extensively studied. Herein, we use Brillouin light scattering to measure the magnon spectra of TbMn₆Sn₆, DyMn₆Sn₆, and HoMn₆Sn₆, measuring the magnon frequency, lifetime, and intensity as a function of applied magnetic field and sample temperature. We find that the identity of the lanthanide effectively tunes the frequency of the magnon over a range from ~18 GHz (Tb) to ~5 GHz (Ho) at zero applied field. Despite the difference in the magnetic ground states between a canted easy-axis (Tb) and easy-cone (Dy, Ho) spin orientation, these three congeners respond remarkably similarly to a magnetic field. Quantitative fitting of the three magnon dispersions reveals that the tuning of the magnon frequencies stems primarily from the differing magnetic anisotropies of the lanthanide ions. This work demonstrates that the anisotropy of the trivalent ion controls not only the magnetic ground state, but also the magnetic excitations, in this family of topological magnets.

8:45am **AC+MI-ThM-4 Suppression of the CDW State in UPt₂Si₂ by Ir Substitution; 5f States Into Bonding**, *Ladislav Havela*, Charles University, Faculty of Mathematics and Physics, Czechia; *Volodymyr Buturlin*, Idaho National Laboratory; *Silvie Cerna, Oleksandra Koloskova*, Charles University, Faculty of Mathematics and Physics, Czechia; *Daniel Chaney*, ESRF, Grenoble, France; *Peter Minarik*, Charles University, Faculty of Mathematics and Physics, Czechia; *Mayerling Martinez Celis*, CRISMAT, University of Caen, France; *Dominik Legut*, Charles University, Faculty of Mathematics and Physics, Czechia

5f states in light actinides adopt either an itinerant, i.e. bonding, nature, or they preserve their localized atomic character similar to free ions and they

stand aside from bonding. The large pool of known U intermetallics comprises mainly compounds with itinerant 5f states. One of exceptions is arguably UPt₂Si₂, at which some features of 5f localization were identified [1,2]. One of its interesting features is the Charge Density Wave (CDW) with a propagation vector (0.42,0,0), developing below $T = 320$ K [3]. Importantly, practically identical CDW appears also in multiple rare-earth isotopes REPt₂Si₂ with localized (or empty) 4f states, all crystallizing in the tetragonal structure type CaBe₂Ge₂[4]. While the CDW phenomenon is very interesting per se (one can discuss whether it is primarily due to phonon softening of Fermi surface nesting), one can also assume it as a sensitive indicator of the 5f localization. The only U-based sibling, UIr₂Si₂, is undoubtedly an itinerant antiferromagnet and no CDW has been reported.

Here we describe results of the study of the pseudo-ternary system U(Pt_{1-x}Ir_x)₂Si₂. The γ coefficient of 32 mJ/mol K² of UPt₂Si₂ starts to increase for $x > 0.05$, reaching 100 mJ/mol K² for 20% Ir, which indicates that the localization with 5f states out of the Fermi level is suppressed already for low Ir concentrations. Variations of lattice parameters a, c are non-monotonous, but the unit cell volume tends to decrease, which is compatible with the progress in 5f bonding. The Néel temperature T_N of the AF order decreases towards 6 K in UIr₂Si₂. The diffuse X-ray scattering experiment at ESRF, ID28 beamline, reveals that the CDW state, developing gradually below 400 K, is still present for $x = 0.05$, where γ is still rather low, 33 mJ/mol K². Further CDW development will be revealed at a forthcoming experiment.

This work was supported by the Czech Science Foundation under the grant # 25-16339S.

[1] R.A. Steeman et al., *J. Phys.: Condens. Matter* **2**, 4059 (1990).

[2] R.A. Steeman et al., *J. Magn. Magn. Mater.* **76&77**, 435 (1988).

[3] J. Lee et al., *Phys. Rev. B* **102**, 041112(R) (2020).

[4] M. Falkowski et al., *Phys. Rev. B* **101**, 174110 (2020).

9:00am **AC+MI-ThM-5 Revisiting Unconventional Superconductivity in Thorium-Doped UBe₁₃**, *Yusei Shimizu*, The University of Tokyo, Japan; *Mitja Krel, Andreas Leithe-Jasper, Markus König, Ulrich Burkhardt, Nazar Zaremba, Thomas Lühmann, Manuel Brando, Eteri Svanidze*, Max Planck Institute for Chemical Physics of Solids, Germany INVITED

The uranium-based superconductors have attracted considerable interest because of their unusual superconducting (SC) and normal-state properties. Among them, UBe₁₃ (cubic O_h^6 , space group #226) has attracted much attention as a promising candidate for spin triplet superconductivity since the early stage [1]. The strong sample dependence of this superconductivity [2,3] and the lack of understanding of its 5f electronic state make the unraveling of superconductivity in UBe₁₃ even more difficult. In particular, the non-monotonic Th concentration dependence of T_{sc} in U_{1-x}Th_xBe₁₃ and occurrence of SC double transition of heat capacity with a small amount of thorium ($0.019 < x < 0.045$) [4-8] are quite anomalous properties, and understanding this multiple SC phase diagram is important for elucidating the true nature of uranium spin triplet superconductors.

In this study, we focus on the low-temperature physics on thorium-doped UBe₁₃ and we revisit their unusual SC and normal-state properties. We have fabricated polycrystals of U_{1-x}Th_xBe₁₃ ($x = 0.01, 0.015, 0.02, 0.03, 0.04, 0.05, 0.07$) in an arc furnace. We determined their lattice constants from x-ray powder diffraction. Previous studies have found double transition of superconductivity at $0.019 < x < 0.045$ in heat capacity [5-8]. In order to clarify whether this double SC transition is intrinsic, we have performed detailed EDS (Energy Dispersive X-ray Spectroscopy), low-temperature heat-capacity and electrical resistivity measurements for U_{1-x}Th_xBe₁₃. The EDS results show that the distribution of Th is uniform within the crystals and that there is no heterogeneous U_{1-x}Th_xBe₁₃ composition within the experimental accuracy. Furthermore, the low-temperature heat capacity results for U_{1-x}Th_xBe₁₃ show that for $x = 0.02, 0.03, 0.04$ a second transition occurs in the SC state, while for $x = 0.015, 0.05$ only one SC transition is observed, which is consistent with previous studies. In our presentation, we will discuss the detail of SC $H-T-x$ phase diagram and non-Fermi-liquid behavior in U_{1-x}Th_xBe₁₃.

[1] H. R. Ott et al., *Phys. Rev. Lett.* **50**, 1595 (1983); H. R. Ott et al., *Phys. Rev. Lett.* **52**, 1915 (1984). [2] A. Amon et al., *Sci. Rep.* **8**, 10654 (2018). [3] H. M. Voltz et al., *Philos. Mag.* **98**, 2003 (2018). [4] J. L. Smith et al., *Physica B* **135**, 3 (1985). [5] H. R. Ott et al., *Phys. Rev. B* **31**, 1651(R) (1985). [6] R. H. Heffner et al., *Phys. Rev. Lett.* **65**, 2816 (1990). [7] F. Kromer et al., *Phys. Rev. Lett.* **81**, 4476 (1998). [8] F. Kromer et al., *Phys. Rev. B* **62**, 12477 (2000). [9] Y. Shimizu et al., *Phys. Rev. B* **96**, 100505(R) (2017).

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Atomic Scale Processing Mini-Symposium

Room 206 A W - Session AP+AS+EL+EM+PS+TF-ThM

Advancing Atomic Scale Processing through Modeling and Simulation

Moderator: Sagar Udyavara, Lam Research Corp

8:00am AP+AS+EL+EM+PS+TF-ThM-1 Multiscale Simulations for Atomic Scale Processing, *Michael Nolan*, Tyndall Institute, Ireland **INVITED**

In modern semiconductor device fabrication, the dimensions involved require atomic level control over materials deposition and etch. Atomic Level Processing, exemplified by Atomic Layer Deposition (ALD) and thermal atomic layer etch (tALE), is therefore critical deposition and etch of relevant materials. Further scaling and use of complex three-dimensional structures means that Thermal ALE will take centre stage in etching. The key chemistry takes place at surfaces which drives the self-limiting characteristics and other advantages of these atomic level processing approaches. In this presentation I will discuss how atomistic simulations based on first principles Density Functional Theory, ab initio Molecular Dynamics and kinetic Monte Carlo methods can be used to predict the chemistry of atomic level deposition and etch processes. I will first discuss the key chemistries involved in atomic level processing chemistries and the challenges that we have identified in this exciting area. The first scientific topic is the simulation of plasma enhanced deposition (PE-ALD) of metals, using the example of cobalt for next generation interconnects. This is the first example of an atomistic level study of the full PE-ALD cycle for Co metal and show that the process requires use of ammonia or mixed H₂/N₂ plasma. Calculated energy barriers for key steps give guidance regarding the temperatures required for the process. We show how substrate pre-treatment can reduce nucleation delay and therefore allow selectivity in deposition of the target film. Finally we show how kinetic Monte Carlo can be used to predict the structure of deposited metal films on different nitride substrates using data from DFT level simulations. The second example is molecular layer deposition of hybrid materials, using alucone as the prototypical example. Comparison of aliphatic with functionalized aromatic molecules allows differences in film properties to be understood. A further application of this involves selective, templated deposition of target films using block co-polymer infiltration where differences in reactivity of a precursor in two polymers promotes selective deposition of the target films. Finally, I present our work on self-limiting thermal atomic layer etching (ALE), highlighting how simulations can (1) predict the window of self-limiting etch (2) unravel the difference between amorphous and crystalline substrates and (3) probe the impact of surface orientation on tALE chemistry, all of which are important for future, selective thermal ALE processing on complex 3D substrates.

8:30am AP+AS+EL+EM+PS+TF-ThM-3 The Si-Cl₂-Ar⁺ Atomic Layer Etching Window: Fundamental Insights from Molecular Dynamics Simulations and a Reduced Order Model, *Joseph Vella*¹, TEL Technology Center, America, LLC, USA; *David Graves*, Department of Chemical and Biological Engineering Princeton University

Plasma assisted atomic-layer etching (ALE) processes are frequently characterized by the ALE window. This is a range of ion energies where the amount of substrate etched remains constant as a function of the ion energy. Silicon (Si) etch by alternating exposure to chlorine gas (Cl₂) and argon ions (Ar⁺) is frequently used as a demonstrative example to illustrate concepts of ALE, including the ALE window.^[1] Despite this, when examining the literature, properties of the ALE window for this system remain obscure. For example, Kim et al.^[2] studied Si-Cl₂-Ar⁺ ALE and report that the ALE window should be below 40 eV. On the other hand, Park et al.^[3] report the ALE window as being from 70 to 90 eV. Still others report an Ar⁺ ion energy of 50 eV as being within the ALE window.^[4] In this talk, we aim to resolve these contradictory reports by studying the Si-Cl₂-Ar⁺ ALE with classical molecular dynamics (MD) simulations and a reduced order model (ROM).^[5] The MD results show that the range of Ar⁺ ion energies where the amount of Si etched per cycle (EPC) remains relatively constant is from 15 eV to 20 eV, which is very narrow. The EPC in this region is also less than one atomic layer, because atomic Cl sputtering is significant. The results also show that a large ion fluence (roughly 4.2 10¹⁶ ions/cm² for 15 eV ions) is required to remove all Cl from the near surface region, which is a key insight when developing processes that achieve "true ALE". Using the ROM, parameters can be varied to observe their effect on properties of the ALE window. For example, by increasing the threshold sputtering energy of

Si, the width of ALE window can be increased. While this study focuses on the relatively simple Si-Cl₂-Ar⁺ system, it is clear learnings from this study can be extended to other systems.

References

- [1] T. Lill, "Atomic Layer Processing: Semiconductor Dry Etching Technology" (Wiley-VCH, Weinheim, 2021).
- [2] B. Kim, S. Chung, and S. M. Cho, "Layer-by-layer Etching of Cl-adsorbed Silicon Surfaces by Low Energy Ar⁺ Ion Irradiation", *Appl. Surf. Sci.* 2002, 187, 124-129.
- [3] S. Park, K. Min, B. Yoon, D. Lee, and G. Yeom, "Precise Depth Control of Silicon Etching using Chlorine Atomic Layer Etching" *Jpn. J. Appl. Phys.* 2005, 44, 389-393.
- [4] K. J. Kanarik, T. Lill, E. A. Hudson, S. Sriraman, S. Tan, J. Marks, V. Vahedi, and R. A. Gottscho, "Overview of Atomic Layer Etching in the Semiconductor Industry", *J. Vac. Sci. Technol. A*, 2015, 33, 020802.
- [5] J. R. Vella, Q. Hao, M. A. I. Elgarhy, V. M. Donnelly, and D. B. Graves, "A Transient Site Balance Model for Atomic Layer Etching", *Plasma Sources Sci. Technol.*, 2024, 33, 075009.

8:45am AP+AS+EL+EM+PS+TF-ThM-4 Influence of Fluorination and Oxygenation Sources on the Thermal Atomic Layer Etching of MoS₂, *Spencer Smith*, *Jacob A. Tenorio*, *Icelene Leong*, *John D. Hues*, *Steven M. Hues*, *Elton Graugnard*, Boise State University

Atomic layer etching (ALE) has emerged as a pivotal technique in the precise fabrication of two-dimensional (2D) materials, particularly molybdenum disulfide (MoS₂), which holds promise in the semiconductor industry due to its high mobility in monolayer form. The ability to precisely etch amorphous and crystalline MoS₂ films provides a pathway for controlling thickness, which is critical to achieving desired electrical and optical properties. Previous studies used MoF₆ and H₂O in thermal ALE of MoS₂. Here, we report studies of alternate sources of fluorination and oxygenation and evaluate their impact on thermal ALE of MoS₂. Oxygen sources include water and ozone, and fluorine sources include HF/Pyridine and MoF₆. Etch rates, uniformity, and surface chemistry post ALE were characterized using spectroscopic ellipsometry, atomic force microscopy, and X-ray photoelectron spectroscopy. Results indicated at ALE of amorphous MoS₂ with HF with either H₂O or O₃ showed no signs of etching at 200 °C or 250 °C. Whereas the combination of MoF₆ + O₃ at 250 °C on amorphous MoS₂ films exhibited an etch rate of 1.6 Å/cycle and a mass loss of 44 ng/cm². Further MoF₆ + O₃ etching at 200 °C showed a mass loss of 19 ng/cm², similar to prior reports using MoF₆ + H₂O at 200 °C. Surface morphology showed little change from etching, but surface oxygen concentration increased. This research further expands the capabilities for atomic layer processing of 2D materials.

9:00am AP+AS+EL+EM+PS+TF-ThM-5 Insights Into Atomic Layer Etching of Diamond Surfaces, *Jack Draney*, *Athanassios Panagiotopoulos*, *David Graves*, Princeton University

Thanks to its nitrogen vacancy color centers, diamond is a candidate for many quantum applications from quantum sensing to quantum computing. Pristine surfaces engineered for each application are required for good device performance. We investigated atomic-scale plasma processing as a method for reaching these pristine diamond surfaces. Our investigation takes the form of combined experiments and molecular dynamics simulations, allowing atomic-scale insights into the effects of argon / oxygen atomic layer etching on diamond surfaces.

9:15am AP+AS+EL+EM+PS+TF-ThM-6 Benchmarking Large Language Models for Atomic Layer Deposition, *Angel Yanguas-Gil*, *Matthew T. Dearing*, *Jeffrey W. Elam*, *Jessica C. Jones*, *Sungjoon Kim*, *Adnan Mohammad*, *Chi Thang Nguyen*, *Bratin Sengupta*, Argonne National Laboratory

In this work we introduce an open-ended question benchmark, ALDbench, to evaluate the performance of large language models (LLMs) in the field of atomic layer deposition. Our benchmark comprises questions with a level of difficulty ranging from graduate level to domain expert current with the state of the art in the field. Human experts reviewed the questions along the criteria of difficulty and specificity, and the model responses along four different criteria: overall quality, specificity, relevance, and accuracy. We ran this benchmark on an instance of OpenAI's GPT-4o using an API interface. This allows us to fine tune hyperparameters used by the LLM for text generation in a way that is not possible using conventional chat-based interfaces.

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The responses from the model received a composite quality score of 3.7 on a 1 to 5 scale, consistent with a passing grade. However, 36% of the questions received at least one below average score. An in-depth analysis of the responses identified at least five instances of suspected hallucination. We also observed statistically significant correlations between the following question and response evaluation criteria: difficulty of the question and quality of the response, difficulty of the question and relevance of the response, and specificity of the question and the accuracy of the response. Finally, we will address other issues such as reproducibility, impact of hyperparameters on the quality of the response, and possible ways in which the performance of the LLMs can be further improved.

[1] A. Yanguas-Gil et al, *J. Vac. Sci. Technol. A* 43, 032406 (2025)

9:30am AP+AS+EL+EM+PS+TF-ThM-7 Developing a “Digital Twin” for Area-Selective Deposition on 3D Nanopatterns, *Nicholas Carroll, Gregory Parsons*, North Carolina State University

Area-selective deposition (ASD)—a bottom-up patterning technique that enables precise material deposition on specific regions while preventing deposition elsewhere—has garnered significant attention as an augmentation to lithographic patterning of nanoscale features during semiconductor manufacturing. Some potential applications, such as contact-over-active-gate, will require multiple ASD materials to be deposited in sequence, heightening the challenge of effective process design. Given the vast time and resources required for experimental assessments of process integration, demand is rapidly growing for a “digital twin” (i.e. a software representation of a physical system) of device fabrication sequences. A comprehensive ASD digital twin will require advances in analyzing atomic layer deposition (ALD) reactor design and mechanistic insights into interactions between inhibitor molecules, ALD reactants, and substrate surfaces over time as reactions proceed.

We have recently developed a stochastic lattice model describing metal oxide ASD on planar substrates, including means to visualize the film shape and extent of lateral overgrowth during ASD.^[1] Parameters in the model can be adjusted based on steric hindrance during each half-cycle, differences in interfacial energies between the non-growth surface and the growing film, and the preferred molecular bonding orientations. These factors elucidate subtleties in shape evolution during ASD, but results to date have been limited to vertical and lateral growth on 2D surfaces. A functional ASD digital twin must describe ASD on arbitrary 3D nanopatterns and on sub-lithographic feature sizes, including effects of selectivity loss where the selectivity decreases as film thickness increases.

We will present recent efforts in our group to extend the functionality of the stochastic lattice model to describe ASD on 3D substrates, including surfaces with pattern dimensions less than 10 nm. On very small features, for example, the model shows that lateral growth during ASD results in a wide distribution of feature separation distances, even when the growth per cycle is uniform across a growing film surface. We will also discuss intricacies that need to be considered to integrate multiple ASD steps into processes involving more complex “multi-color” substrates where several substrate materials exposed to reactants simultaneously. We believe that such insight will be critical for the realization of a functional digital twin model of atomic-scale processing needed for future semiconductor devices and other advanced manufacturing processes.

(1) Carroll, N. M.; Parsons, G. N. *J. Vac. Sci. Technol. A* **42** (6), 062411 (2024).

9:45am AP+AS+EL+EM+PS+TF-ThM-8 Activation of C-X Bonds on Transition Metal Surfaces: Insight from DFT Studies, *Matias Picuntureo*, Universidad Tecnica Federico Santa Maria, Chile; *Ilker Tezsevin, Marc Merkx*, Eindhoven University of Technology, The Netherlands; *Scott Semproni, Jun-Ruey Chen*, Intel Corporation; *Adriaan Mackus*, Eindhoven University of Technology, The Netherlands; *Tania Sandoval*, Universidad Tecnica Federico Santa Maria, Chile

Area-selective atomic layer deposition (AS-ALD) represents an advanced bottom-up nanofabrication technique enabling selective material growth on targeted areas of patterned substrates. In advanced semiconductor manufacturing, such as next-generation processes at the back end of line (BEOL), small molecule inhibitors (SMIs) can enable AS-ALD through the selective formation of inhibitor layers on metal surfaces that block deposition.

A recent study by Merkx et al. reported hydrogenolysis and potentially dehydrogenation of aniline on Ru surfaces during AS-ALD, leading to the formation of a carbonaceous layer with enhanced inhibition performance. This highlights the importance of understanding the driving forces behind the surface chemistry of SMIs.

To explore whether similar surface-mediated reactions can occur for other inhibitor–metal combinations, we employ density functional theory (DFT) to investigate the adsorption and dissociation mechanisms of benzene-derived SMIs on Ru(0001), Mo(110), and W(110) surfaces.

To enable a systematic comparison across different molecules and surfaces, our study focuses on radical-mediated dissociation pathways involving the cleavage of functional groups from the aromatic ring. This approach allows us to isolate the effect of the functional group and its interaction with the metal surface in determining the reaction thermodynamics between the molecular and dissociated adsorbed states.

We find that charge transfer to the adsorbed inhibitor modulates its dissociation energy landscape. The resulting radical intermediates are substantially stabilized through coordination with the metal surface. We further explore their subsequent hydrogenation, which transforms these surface-bound radicals into more stable, saturated species. Lastly, we show that the fate of reaction by-products—whether they remain adsorbed or desorb into the gas phase—can significantly impact the overall reaction thermodynamics and shift the equilibrium toward or away from product formation.

The investigation of the reaction pathways explored in this study contributes to the fundamental understanding of molecule–surface interactions during AS-ALD and offers insight that may support future strategies for the rational design of small molecule inhibitors.

References:

[1] Merkx et al., *J. Chem. Phys.* 160, 2024.

11:00am AP+AS+EL+EM+PS+TF-ThM-13 Descriptor-driven analysis of inhibitors for AS-ALD processes, *Joost F. W. Maas, Marc J. M. Merkx*, Eindhoven University of Technology, Netherlands; *Matías Picuntureo, Lucas Lodeiro*, Universidad Tecnica Federico Santa Maria, Chile; *Adriaan J. M. Mackus*, Eindhoven University of Technology, Netherlands; *Tania E. Sandoval*¹², Universidad Tecnica Federico Santa Maria, Chile

Area selective atomic layer deposition (AS-ALD) is a bottom-up technique that can address some of the challenges that limit the nanofabrication of complex structures, which require patterning and alignment at the atomic scale. Currently, one of the most robust strategies to carry out AS-ALD is with the use of small molecule inhibitors (SMIs), that selectively adsorb and inhibit the non-growth surface (NGS) and prevent precursor adsorption. These SMIs range from a variety of functionalities and structures depending on the target NGS, and their selection is based on specific criteria, such as reactivity, volatility, and safety.^{1,2}

Currently, the library of tested inhibitor molecules is very limited, therefore finding the best candidate for a given surface is challenging. Using computational tools can significantly accelerate the expansion of this library through high-throughput screening and recent advances in machine learning. In the case of the use of descriptors,³ the goal is to correlate the performance of the SMIs e.g., measured in terms of their stability, as adsorption energy, with the dependence on materials or molecular properties. The derived correlations can serve to establish general guidelines for SMI selection, expanding the analysis to other molecules not included in the initial study. This approach has proven to be very successful in reducing computational costs in other fields, such as heterogeneous catalysis and drug discovery.

In this presentation, we provide an overview of the dependency between a list of descriptors and the adsorption energies of SMIs candidates on a variety of relevant NGS, such as oxides, nitrides, and metals. We explore descriptors based on the molecular properties, such as electronegativity, electrophilicity, and orbital energy, as well as descriptors based on the electronic structure of the material, such as d-band center. Results indicate a strong correlation with the adsorption energy (E_{ads}) and electronegativity of the core-atom on the adsorption of oxides and nitrides, as well as the d-band center on the adsorption on metal surfaces. Moreover, our data highlights the differences in reactivity across surfaces and the challenges in surface passivation across surfaces with similar surface sites. Overall, this study provides important insights into the use of descriptor-driven analysis in the selection of the right SMI candidates for the advancement of ASD processes.

[1] A. Mameli and A. Teplyakov *Acc. Chem. Res.* 2023, 56, 2084–2095.

[2] P. Yu, et al. *Appl. Surf. Sci.* 2024, 665, 160141.

[3] C. Chen, et al. *J. Phys. Chem. C* 2025, 129, 13, 6245–6253.

¹ TFD Paul Holloway Award Winner

² JVST Highlighted Talk

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11:15am AP+AS+EL+EM+PS+TF-ThM-14 Understanding Plasma-Induced Bonding and Composition Changes in SiCN ALD via kMC-DFT Modeling
Ting-Ya Wang, University of Texas at Austin; **Hu Li**, Peter Ventzek, Tokyo Electron America; **Gyeong Hwang**, University of Texas at Austin; **Jianping Zhao**, Tokyo Electron America

Plasma-enhanced atomic layer deposition (PEALD) enables low-temperature processing of silicon carbonitride (SiCN), a critical low-k material for advanced interconnects. However, energetic plasma species—including both ions and radicals—can significantly influence surface reactions, film composition, and structural evolution, ultimately affecting material properties such as dielectric constant and mechanical strength. A comprehensive understanding of these species-specific effects is essential for process optimization.

Integrating kinetic Monte Carlo (kMC) with density functional theory (DFT) offers a powerful approach for simulating ALD. However, a key challenge in kMC lies in the need for a predefined list of permissible events. Traditionally, researchers manually compile a set of reactions deemed most significant. Yet, the vast number of possible events on a surface, combined with the importance of rare events in ALD, raises concerns about the authenticity and completeness of outcomes derived from manually curated reaction lists.

To address this, we developed an atomistic, off-lattice, three-dimensional simulator that integrates kMC with DFT. We employed a strategic approach to construct a comprehensive event list, capturing a broad spectrum of potential surface reactions. This year, we expand our study in four key directions: (1) comparison of ion- and radical-driven reaction pathways to delineate their distinct roles in modifying surface chemistry; (2) evaluation of different plasma chemistries (e.g., N₂ vs. NH₃) to understand how reactive species impact film stoichiometry and termination; (3) simulation of multi-cycle growth to track the evolution of defects and compositional shifts; and (4) simulation predictions against experimental data such as XPS and IR spectra.

Our findings reveal a synergistic interplay between ions and radicals in shaping the formation of Si–N, Si–C, and C–N bonding networks. The simulation platform enables insights into plasma–surface interactions, offering a predictive framework for optimizing SiCN PEALD processes.

11:30am AP+AS+EL+EM+PS+TF-ThM-15 Understanding SiCN Film Oxidation Mechanism Through Density Functional Theory, **Tsung-Hsuan Yang**, **Hu Li**, **Jianping Zhao**, **Peter Ventzek**, Tokyo Electron America

Low dielectric constant (low-k) spacers are essential components in advanced microelectronic devices for mitigating parasitic capacitance and crosstalk, leading to enhanced device performance. Among low-k materials, silicon carbon nitride (SiCN) is widely used for its tunability in dielectric constant, leakage current and chemical robustness. However, the long-term stability of SiCN films is often compromised by atmospheric moisture, leading to the formation of silicon oxide. To address this issue, we utilize density functional theory (DFT) to elucidate the fundamental oxidation mechanisms of SiN and SiC components by H₂O. Reaction rates were estimated with a combination of transition state theory and Arrhenius equation, enabling prediction of oxidation rates under various processing conditions. Additionally, H₂O diffusion within SiCN films was modeled, demonstrating a direct correlation between film density and oxidation kinetics. More importantly, the findings in this work can be applied in depositing SiOCN film as the oxidation mechanisms are predicted to be similar with other oxidation agents. Knowledge of these oxidation mechanisms enables precise control of the SiOCN film deposition process, facilitating component tunability.

11:45am AP+AS+EL+EM+PS+TF-ThM-16 From Bulk Titanium Nitride to Small Molecule Inhibitors: a DFT Study Aiming Towards Area-Selective Atomic Layer Deposition, **Lucas Lodeiro**, Universidad Técnica Federico Santa María, Chile; **Marc J. M. Merkx**, Eindhoven University of Technology, The Netherlands; **Dennis M. Hausmann**, **Rachel A. Nye de Castro**, LAM Research; **Adriaan J. M. Mackus**, Eindhoven University of Technology, The Netherlands; **Tania E. Sandoval**, Universidad Técnica Federico Santa María, Chile

Titanium Nitride (TiN) is a hard and inert ceramic used as a protective coating, and in microelectronics for its metallic behavior. TiN thin films improve devices performance as conductive connection and diffusion barrier, and can be further functionalized to promote specific applications. Atomic Layer Deposition (ALD) enables precise TiN film deposition, with temperature controlling crystal growth facet. However, achieving area-selective ALD (AS-ALD) on TiN is challenging, because the lack of information of surface groups present in deposited TiN, requiring reliable

surface models to search for solutions for precursor selectivity and inhibition with Small Molecule Inhibitors (SMIs) at atomic scale.

This study uses Density Functional Theory (DFT) to examine TiN surface properties, crystal facets, and surface chemistry. It also explores the adsorption of various organic and inorganic precursor (Al, Si, Ti-based) and SMI (aryl, aldehyde, and nitrogen-based) molecules on TiN with the aim of studying their potential for AS-ALD processes with TiN as growth or non-growth area.

Our findings on crystal facets align with experimental data, showing the (001) facet is the most stable, followed by the (111) facet, which is observed at high deposition temperature.[1] The reactivity and functionalization strategies of these surfaces differ significantly. The (001) surface shows low reactivity (especially with H₂O, NH₃, and H₂), resulting in bare surface sites.[2] Conversely, the (111) surface is reactive and can undergo hydrogenation, altering its electronic properties.

The differences in electronic surface properties significantly affect surface chemistry and the adsorption mechanism of the different molecules. The (001) surface exhibits metallic behavior, with strong interactions with various functional groups (for example, -1.8 eV for Benzaldehyde, BA), similar to copper surfaces.[3] In contrast, adsorption on the (111) surface is weaker and mainly dispersive (-0.8 eV for BA), highlighting the importance of the TiN film facet. Experimental findings show enhanced inhibition of BA and higher selectivity for low temperature deposited TiN, which could indicate the presence of the (001) surface, and a more stable inhibitor adsorption.

The key findings of this study offer valuable insights into surface reactivity and electronic properties to use TiN in AS-ALD process. Ultimately, this work aims to provide insights into controlling TiN deposition at the nanoscale, opening avenues for advanced microfabrication and surface engineering applications.

[1] Met. Mater. Int. 2001, 7, 621–625.

[2] J. Phys. Chem. C 2013, 117, 38, 19442–19453.

[3] Chem. Mater. 2025, 37, 1, 139–152.

12:00pm AP+AS+EL+EM+PS+TF-ThM-17 Trimethylaluminum Reactivity on SiO₂ Surfaces at Cryogenic Temperatures – Implications for Al₂O₃ ALD, **Leonhard Winter**, **Ravi Ranjan**, **Francisco Zaera**, University of California, Riverside

The atomic layer deposition (ALD) of aluminum oxide films on solid substrates using trimethylaluminum (TMA) and water is often considered a prototypical ALD process. Several investigations have attempted to understand the mechanistic details of this deposition by following the corresponding steps *in situ* under reaction conditions. To gain a more fundamental understanding, we have set out to study this system following a UHV surface-science approach, slowing down the reaction, decreasing the gas exposures and substrate temperature, and following the progress of the reactions using surface science techniques. We chose to study this chemistry on SiO₂ films grown *in situ* onto a Ta support because SiO₂ is one of the most common substrates in the microelectronics industry.

We investigated the adsorption and reaction of TMA with SiO₂ by using X-ray photoelectron spectroscopy (XPS) and temperature-programmed desorption (TPD). We found that TMA starts to react with the SiO₂ surface at \approx 110 K, i.e. below the cryogenic temperatures required for multilayer condensation. This low-temperature chemistry appears to be complex, as multiple reaction pathways can be deduced from analysis of the TPD data. In addition to the expected product methane, we observed the formation of ethylene and heavier fragments, probably also containing Al. The complex behavior of TMA on SiO₂ is not limited to low temperatures, as the loss of alkyl groups continues over several hundred kelvins upon heating of the sample. Isothermal adsorption experiments show that at room temperature the TMA uptake is self-limiting with an initial sticking coefficient that is approximately 4–5 times smaller than at cryogenic temperatures, where multilayer growth occurs. To model ALD-type growth, we alternately dosed TMA and water at 200 K and followed the chemical composition of the surface with XPS. The results are in agreement with the expected ALD behavior, which shows that ALD growth is possible at these extremely low temperatures for the TMA/water system. The two precursors were also co-dosed in a CVD-type deposition, which results in the growth of multilayer films of aluminum oxide on the SiO₂ substrate. Surprisingly, the growth was observed to proceed faster at 200 K than at room temperature, which we explain by a kinetic effect of prolonged residence times of the precursors at lower surface temperatures.

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Electronic Materials and Photonics

Room 205 ABCD W - Session EM-ThM

Advances in Material Deposition Techniques

Moderators: Francois Fabreguette, Micron, John Muth, North Carolina State University

9:00am EM-ThM-5 The CO_x Thermal Oxidation Process for CO₂ Capture, *Marshall Buffett*, Voiland School on Chemical Engineering

Rising carbon dioxide emissions have driven research into sustainable methods for converting carbon rich waste gases from industry into value-added materials. One such method is the CO_x Thermal Oxidation Process (CO-OP), in which CO or CO₂ reacts with magnesium silicide (Mg₂Si) to produce crystalline silicon encapsulated in both graphitic and amorphous carbon. The resulting composite shows potential as a lithium-ion battery anode, while the process itself offers a method for CO₂ removal. However, industrial gas streams are rarely pure and the influence of feed composition on CO-OP remains unexplored. While CO-OP with CO₂ has been studied, implementation in industrial processes would be impractical if it required purified CO₂. This study investigates how feed compositions common in methane steam reforming (CO₂, CO, CO+H₂, and CO₂+H₂) affect the morphology of the produced composite and how these morphology changes influence battery performance. Preliminary results indicate that CO increases the carbon content of the composite as compared to CO₂ and creates a core/shell structure, increasing mechanical stability. Morphology, surface area, and carbon distribution vary significantly with gas composition which in turn affects the battery performance significantly. X-ray diffraction confirms high purity across all samples after leaching. These insights guide future improvement of CO-OP for integration with industrial emission streams, creating a new method of carbon capture and improving battery technology.

Plasma Science and Technology

Room 201 ABCD W - Session PS1-ThM

Plasma Diagnostics

Moderators: Thierry Chevolleau, CEA-LETI, France, Pingshan Luan, TEL Technology Center America

8:00am PS1-ThM-1 Floating Probe-Based Plasma Potential Measurement in Low-Temperature Radio Frequency Inductively Coupled Plasma, *Isak Lee, Chulhee Cho, Inho Seong, Wonnyoung Jeong, Minsu Choi, Byeongyeop Choi, Jami MD Ehsanul Haque, Seonghyun Seo, Woobeen Lee, Dongki Lee, Wongyun Park, Jinyeok Jang, Shinjae You, Chungnam National University, Republic of Korea*

Accurate measurement of plasma potential is essential for understanding sheath structures and particle dynamics. Among the available methods, the floating probe offers a simple approach but tends to underestimate the actual plasma potential due to electron flux from the plasma. To address this, we developed a modified floating probe that minimizes electron flux, enabling more accurate measurement of the plasma potential. The effectiveness of this technique was assessed by comparing the measured potentials with those obtained from a Langmuir probe. To evaluate their applicability, floating potentials were systematically measured under various conditions—including pressure, RF power, and probe configurations—and their variations were analyzed. As a result, we observed that reducing electron flux led the floating potential to approach the actual plasma potential. This study introduces a simplified and robust diagnostic method for plasma potential measurement, with high applicability to various plasma processing systems and low-temperature plasma research.

8:15am PS1-ThM-2 Global Model Enabled Quantitative Diagnosis of Reactive Species in a Plasma Chamber Using RGA, *Seonghyun Seo, Wonnyoung Jeong, Chungnam National University, Republic of Korea; Sijun Kim, Laboratoire de Physique des Plasma (LPP)CNRS, Republic of Korea; Youngseok Lee, Chulhee Cho, Inho Seong, Minsu Choi, Byeongyeop Choi, Chungnam National University, Republic of Korea; Jami Md Ehsanul Haque, Chungnam National University, Bangladesh; Woobeen Lee, Isak Lee, Dongki Lee, Shinjae You, Chungnam National University, Republic of Korea*

As plasma etching technologies become increasingly constrained with the advancement of high-aspect-ratio and high-precision patterning techniques such as atomic layer etching (ALE) and high aspect ratio contact (HARC) etching, the need for accurate control and quantitative analysis of reactive species within the process chamber has become increasingly important.

Among the diagnostic tools used to analyze reactive species in the chamber, the residual gas analyzer (RGA) is widely adopted due to its accessibility, but its use has been largely limited to qualitative analysis.

This study proposes a diagnostic method to quantify radical densities by applying global modeling to RGA measurements. First, a Langmuir probe was inserted into the ionizer of the RGA to experimentally measure the electron density and electron energy distribution. These data were used as inputs for the global model to calculate electron-neutral collision rate coefficients for the radical species.

Then, to convert the measured RGA signals into absolute radical densities, we experimentally determined the mass-dependent transmission probability through a quadrupole mass filter, which reflects how the detection efficiency varies with species mass. By incorporating this transmission function along with previously obtained electron-related parameters, a global model was constructed to determine radical densities from the RGA signals.

To verify the reliability of the proposed method, it was compared with existing diagnostic approaches for quantifying radical species in plasma processes. Additional validation was carried out by evaluating the applicability of the global model under varying process conditions, including RF power and chamber pressure. This study demonstrates that reactive species in plasma environments can be quantitatively analyzed using the proposed RGA-based method.

8:30am PS1-ThM-3 Absolute Atomic Density Measurements in Hydrogen- and Oxygen-Containing Plasmas for Atomic-Scale Processing, *Jente Wubs, Thomas van den Biggelaar, Marnix van Gurp, Erwin Kessels, Eindhoven University of Technology, Netherlands; Jordyn Polito, James Ellis, Harm Knoops, Oxford Instruments Plasma Technology, UK* **INVITED**

Hydrogen- and oxygen-containing plasmas are often used in atomic-scale processing technologies such as atomic layer deposition (ALD) and etching (ALE). Examples include the deposition of oxide layers and the etching of nitrides. To accelerate process development and optimization, physical analysis of the plasma is essential. In particular, measurements of key radicals – such as hydrogen and oxygen atoms – are required, as these radicals are known to affect on-wafer outcomes during ALD and ALE processes. Knowledge of their densities (and, ideally, their spatial and temporal distributions) is therefore of major importance, not only to understand the plasma chemistry pathways driving these processes, but also to identify relevant plasma regimes for achieving optimal processing conditions.

Available diagnostic techniques for measuring the densities of plasma radicals include probe-based methods and optical techniques, with the latter having the advantage of being non-invasive. A popular technique in both research and industry is optical emission spectroscopy. However, although this technique is experimentally relatively straightforward, analyzing emission spectra to obtain information on ground-state densities requires collisional-radiative models, which are only valid under specified conditions. Alternatively, ground-state densities can also be measured directly with absorption-based techniques, thus avoiding the need for modeling excitation processes. However, atomic absorption transitions from the ground-state to higher-energy states mostly lie in the vacuum ultraviolet part of the spectrum. The technical difficulties associated with this spectral region can be circumnavigated by using a technique called two-photon absorption laser induced fluorescence (TALIF), which does not require vacuum conditions and allows for measurements with high spatial and temporal resolution. However, TALIF is rather expensive and experimentally challenging, as it involves a bulky laser system and a complex calibration procedure. It is therefore less suited for monitoring atomic densities in industrial settings. Nevertheless, owing to the good accuracy and unparalleled spatial resolution, TALIF measurements are still of immense value when studying industrial plasmas, as they are necessary for the validation of e.g. probe-based methods and plasma models.

This contribution provides an overview of several plasma diagnostic techniques for detecting radicals relevant to ALD and ALE processes. Results on the densities of key plasma species in a commercial plasma source used for atomic-scale processing will be presented as well.

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9:00am **PS1-ThM-5 RF-Compensation-Free Langmuir Probe Technique via AC-Driven Biasing in a RF Plasma, Inho Seong, Chulhee Cho, Wonnyoung Jeong, Sijun Kim, Chungnam National University, Republic of Korea; Minsu Choi, Chungnam National University, Republic of Korea; Byeongyeop Choi, Chungnam National University, Republic of Korea; Ehsanul Haque Jam, Chungnam National University, Bangladesh; Seonghyun Seo, Woobeen Lee, Isak Lee, Dongki Lee, Chungnam National University, Republic of Korea; Shinjae You, Chungnam National University, Republic of Korea**

Langmuir probe diagnostics in RF plasmas typically require filter to compensate for the RF fluctuations. This is commonly achieved by designing resonant filters that present high impedance at the fundamental frequency and its harmonics. However, fabricating such filters is often challenging due to the need for precise tuning and stability under plasma conditions, which can lead to increased system complexity. In this work, we present a novel method to perform Langmuir probe measurements without the need for conventional RF filters. By applying an AC-driven bias to the probe, we effectively suppress the influence of RF fluctuations, enabling direct plasma parameter measurements. We analyzed this novel technique and validated it through experiments, confirming the feasibility of simplified, filter-free probe diagnostics in a RF plasma.

9:15am **PS1-ThM-6 Space and Phase-Resolved Ion Velocity Distribution Function Measurements in Electron Beam Generated E × B Plasma, Sung Hyun Son, Princeton University; Ivan Romadanov, Princeton University Plasma Physics Lab; Nirbhav Chopra, Princeton University; Yevgeny Raitses, Princeton University Plasma Physics Lab**

Electron beam (e-beam) generated plasmas with applied electric and magnetic ($E \times B$) fields are promising for applications that require efficient generation of ions and radicals in low-pressure environments [1]. We report spatially and phase-resolved measurements of the ion velocity distribution function (IVDF) in this plasma source using a planar laser-induced fluorescence (PLIF) system. A continuous-wave tunable diode laser produces a laser sheet that irradiates the plasma, and the resulting fluorescence is captured by an intensified CCD (ICCD) camera. Fluorescence images recorded at varying laser wavelengths are converted into two-dimensional IVDFs using the Doppler shift principle [2]. The PLIF measurements are validated against a conventional single-point laser-induced fluorescence (LIF) method using photomultiplier tube (PMT)-based detection at various positions. The phase-resolving capability of the system is tested by oscillating the plasma between two nominal operating modes with distinct density profiles, with the ICCD camera triggered by the externally driven plasma oscillation. The resulting oscillations in fluorescence intensity show good agreement with plasma density variations measured by electrostatic probes, demonstrating the system's ability to resolve phase-dependent dynamics. The measured IVDFs reveal several signatures of ion dynamics in this plasma source that could influence its material processing characteristics. In particular, radially outflowing ions and anomalous ion heating in the plasma periphery, both anticipated by theoretical studies and potentially detrimental to gentle plasma processing [3], are observed and reported.

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9:30am **PS1-ThM-7 Short Duty Cycle Pulsing of an RF Driven ICP with Electronegative Gases, Banks Peete, Carl Smith, North Carolina State University; James Prager, Paul Melnik, Tim Ziemba, Eagle Harbor Technologies; Sung-Young Yoon, Meehyun Lim, Sungyeol Kim, Samsung Electronics, Republic of Korea; John Mattingly, Steve Shannon, North Carolina State University**

Many common gases used for plasma enhanced processes in semiconductor manufacturing have electronegative properties; the gas molecules will attach free electrons in a plasma to form negatively charged ions. These gases are a vital presence in etching processes because of their ability to form certain reactive species. However, electron attachment can form plasma instabilities that vary in amplitude and frequency based upon the power delivery design, power density, and gas composition. These instabilities disrupt power delivery, leading to challenges in consistency for industrial applications. Power delivery networks that do not rely on traditional impedance matching have been studied previously to demonstrate expanded process capabilities for pulsed RF power delivery,

most notably through reduced power delivery latency and more rapid electron-ion pair production. This work expands the study to evaluate the performance of a matchless RF power delivery network with regard to electron-ion pair production, plus power delivery latency and stability when used with an electronegative plasma. The ability to quickly apply RF power with minimal delay, enabled by the matchless pulser, allows the RF to be turned on and off before the instabilities can fully manifest while still producing a controllable peak electron density over a short pulse cycle time. Thus, the plasma avoids the onset of the instability in electron density and temperature that is characteristic of electron attachment instabilities in electronegative plasmas by achieving the desired peak density on a time scale faster than the onset of the instability. This can expand the stable operating space for industrial plasmas reducing the reliance on very specific gas mixture, pressure, and power parameters where the instability does not occur.

This work is supported by a grant from the Samsung Mechatronics Research Division, Suwon, Republic of Korea.

9:45am **PS1-ThM-8 Probing Microwave-Driven Plasmas: Impact of N₂ Addition in Ar/N₂ Plasma, Nafisa Tabassum, North Carolina State University; Abdullah Zafar, Timothy Chen, Kelvin Chan, Applied Materials; Steven Shannon, North Carolina State University**

A microwave-driven plasma operating at 2.45 GHz is investigated by means of optical emission spectroscopy, laser absorption spectroscopy, laser induced fluorescence, probe diagnostics, and plasma simulation package Zapdos. A mixture of Ar/N₂ is used as the operational gas with N₂ partial pressure varied from 0 % to 25 % of total gas pressure. The effect of N₂ partial pressure, gas pressure, and delivered power density are investigated in the range of 70 mTorr - 1 Torr and 0.25-1.25 W/cm³. Electron density, electron temperature and plasma potential were measured using a single Langmuir probe. Imaging of the plasma using an ICCD camera was used to estimate the physical extent of the plasma. Relative concentrations of molecular nitrogen N₂, ionized molecular nitrogen N₂⁺ and atomic nitrogen N were obtained through optical emission actinometry as a function of pressure and delivered power density. The following lines are used in this study: N₂ : $C^3\Pi_u \rightarrow B^3\Pi_g$ at $\lambda = 337.1$ nm, N₂⁺ : $B^2\Sigma_u^+ \rightarrow X^2\Sigma_g^+$ at $\lambda = 391.0$ nm, N: $3p^4S_{3/2}^0 \rightarrow 3s^4P_{5/2}^0$ at $\lambda = 746.8$ nm, and Ar: $2p_1 \rightarrow 1s_2$ at $\lambda = 750.4$ nm. . The transition between the under-dense and over-dense operating regimes, influenced by variations in the delivered power density, gas pressure, and N₂ partial pressure has been mapped to these plasma generated species. This study identifies hysteresis effects during changes in delivered power densities and pressure near the critical power, P_c , for transition from the under-dense to over-dense condition. In particular, the critical power required for this transition decreases with increasing pressure. This hysteresis behavior is further confirmed through observations of plasma diameter variations under different pressure and power density conditions. The influence of the partial pressure of N₂ in Ar - N₂ plasma on the mode transition and hysteresis is investigated. This study explores how plasma-generated species form, their roles in ionization pathways within a multi-species gas mixture, and how these factors affect the transition from under-dense to over-dense regimes. These dynamics, in turn, influence the critical power required for the transition and the spatial distribution of the plasma-generated species.

Plasma Science and Technology Room 201 ABCD W - Session PS2-ThM

Plasma Sources

Moderator: Necip Uner, Middle East Technical University

11:00am **PS2-ThM-13 Controlled Electron-Enhanced Silicon Etching with H₂ Background Gas and Positive Sample Voltage, Sumaira Yasmeen, Andrew Cavanagh, University of Colorado at Boulder; Harsono Simka, Samsung Electronics; Steven George, University of Colorado at Boulder**

Controlled electron-enhanced silicon etching can be achieved with H₂ background gas and positive sample voltage. Electrons impinged on the silicon surface at normal incidence at currents of ≥ 200 mA over surface areas of ~ 4 cm². The electron energy was ~ 140 -240 eV defined by the grid bias on the hollow cathode plasma electron source and positive sample voltages. The H₂ pressures were < 3 mTorr. The silicon etching for Si(100) and a-Si at room temperature was measured using in situ spectroscopic ellipsometry. The etched silicon thickness was linear versus time during electron-enhanced etching. The etch rates increased progressively with larger positive sample voltages (Figure 1). Si(100) etched slower than a-Si.

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For example, the etch rates were \sim 2.6 Å/min for crystalline Si(100) and 9.9 Å/min for a-Si under the same conditions at an incident electron energy of 140 eV with a positive sample voltage of +90V.

Without the positive sample voltage, the silicon etch rates were negligible. In addition, electron-enhanced Si etching was not accomplished using a D₂ background gas instead of a H₂ background gas. These results support the proposed mechanism for electron-enhanced Si etching, where H₂ produces H⁺ via dissociative electron attachment (DEA) according to H₂ + e⁻ \rightarrow H₂⁺ \rightarrow H + H⁺. The positive voltage on the sample stage then pulls the H⁺ negative ions to the silicon sample to react with silicon to produce SiH₄ as an etch product (Figure 2). The low-energy electrons required for DEA are secondary electrons produced by the primary electrons impinging on the silicon surface.

The energy of secondary electrons from silicon peaks at \sim 2-3 eV and drops off rapidly at higher energies approaching 10 eV. The peak of the DEA cross section for H₂ is 3.75 eV. In comparison, the peak of the DEA cross section for D₂ is 14.0 eV. The D₂ background gas may not be effective for silicon etching because D⁺ is not produced by DEA, as the secondary electron energy from silicon is too low. These results demonstrate a new mechanism for controlled electron-enhanced silicon etching based on H₂ DEA from secondary electrons and H⁺ attraction to the positive sample voltage on the silicon sample.

11:15am PS2-ThM-14 Investigation of Temporal, Spatial and Angular Evolution of High-Power Impulse Magnetron Sputtering with Positive Cathode Reversal, Tag Choi, Zachary Jeckell, Sam Pickholtz, Matt Egly, Matt Salek, Ricky Pickering, Aaron Hackett, Dren Qerimi, David Ruzic, University of Illinois at Urbana-Champaign

High-Power Impulse Magnetron Sputtering (HiPIMS) is a Physical Vapor Deposition (PVD) technique that delivers sub-microsecond high power pulses, enhancing ionization rate, ion energy and its directionality. Furthermore, a positive cathode reversal feature has been added to enhance the deposition rate and control the ion energy. These HiPIMS capabilities contribute to notable improvements in film quality, including higher density, stronger substrate adhesion, and enhanced step coverage, making HiPIMS with positive cathode reversal well-suited for advanced thin-film applications. Among the many challenges in the semiconductor industry, achieving uniform and dense thin films remains a critical focus. Addressing this requires a deeper understanding of the underlying plasma behavior during deposition. Thus, this study utilizes a Plasma Sampling Mass Spectrometer (PSM) to investigate the temporal, spatial, and angular evolution of titanium HiPIMS plasma with positive cathode reversal. A custom-built, high-vacuum compatible magnetron was mounted on both linear and rotational actuators, enabling detailed exploration of ion behavior across different positions and angles. The system allows for 40–300 mm axial translation, 90 mm azimuthal movement, and up to 90° rotation. Key HiPIMS parameters—such as main pulse duration, peak current, delay time between the main and positive kick pulses, kick pulse length, and kick voltage—were systematically varied to assess their individual impact on plasma characteristics. Additionally, the study examines the controllability between gas and metal ions, exploring its potential for process optimization and application-specific tailoring.

11:30am PS2-ThM-15 University-Scale Extreme-Ultraviolet Lithography Source, Jan Uhlig, Max Miles, Dren Qerimi, David Ruzic, University of Illinois at Urbana Champaign

To elevate our laboratory's research capabilities in Extreme-Ultraviolet (EUV) photoresist development, we have engineered a university-scale EUV light source designed for lithography applications at a fraction of the cost of commercial EUV tools. This innovative system leverages a Neodymium-doped yttrium aluminum garnet (Nd:YAG) Laser-Produced Plasma (LPP) with a swappable Tin (Sn)-based target to generate EUV radiation, offering an economical alternative to the high-cost infrastructure typically required for EUV lithography. Departing from an earlier dual EUV Multilayer Mirror (MLM) configuration, the current setup employs direct EUV exposure facilitated by a 150 nm Zirconium (Zr)-based transmission filter to isolate the EUV spectrum with high efficiency. A broad-spectrum photodiode detector, tailored to EUV wavelengths, provides accurate dosimetry, and its measurements are corroborated through successful exposure of EUV-sensitive photoresist-coated wafers. Experimental investigations have explored a range of target materials, including pure Sn and Sn-doped ceramics (typically 5 at%), utilizing Spectraflux 100B (Lithium Metaborate/Lithium Tetraborate 80/20) as a foundational component. Optical Emission Spectroscopy (OES) serves as an auxiliary diagnostic tool, enabling real-time monitoring of the LPP characteristics. Optimization

efforts have focused on critical parameters—laser power, beam focus, operating pressure, and target composition—to achieve precise dose control and maximize EUV output while simultaneously addressing debris mitigation, a persistent challenge in LPP systems. The results demonstrate reliable photoresist exposure with adjustable EUV dosage, positioning this system as a cost-effective yet powerful platform for academic research. Compared to multimillion-dollar commercial EUV tools, this setup provides an accessible means to explore novel EUV photoresist modifications, with ongoing projects targeting enhancements in line-edge roughness and reductions in the minimum dose required for full development. This affordable, university-scale tool thus bridges a critical gap, enabling advanced EUV lithography studies without the prohibitive expense of industrial-grade equipment.

11:45am PS2-ThM-16 Understanding the Plasma in Dielectric Barrier Discharges for Plasma-Enhanced Spatial Atomic Layer Deposition, Ralph Houben, Antoine Salden, Jente Wubs, Richard Engeln, Erwin Kessels, Julian Held, Bart Macco, Eindhoven University of Technology, Netherlands

Plasma-enhanced atomic layer deposition (PE-ALD) has enriched the ALD field, with the non-equilibrium nature of the plasma allowing for the synthesis of novel materials, tuning of material properties, and deposition at low temperatures. Pivotal to advancing the field of PEALD has been the detailed understanding of the plasma chemistry, including the role of reactive species and ions in driving surface reactions.

However, many emerging application in green technologies, including photovoltaics, batteries, and catalysis, require high-throughput, large-area deposition methods. Batch (thermal) ALD has already proven itself in the field of passivation layers for solar cells, yet plasmas are not easily integrated into such batch ALD systems. Spatial ALD (SALD) offers a route to incorporate plasmas using dielectric barrier discharges (DBDs), operating at atmospheric pressure and over large areas. Yet, the properties of DBDs and their influence on ALD deposition remain far less understood compared to the well-studied conventional PEALD plasmas.

We demonstrate how the DBD is implemented in the SALD tool used for deposition. The SALD setup consists of a head with multiple parallel slits through which precursors and co-reactants flow, separated by inert gas. The DBD plasma is applied over one of these gas channels, enabling plasma-enhanced surface reactions in a spatially separated, continuous process. This approach allows us to combine the scalability of SALD with the enhanced reactivity of plasma species.

We furthermore present a systematic study of a DBD source that is currently being integrated on our spatial ALD tool. Using optical emission spectroscopy, we investigate the gas temperature in the afterglow of the N₂/O₂ plasma, finding temperatures between 310 and 400 K depending on input power, which is compatible with ALD processes. Additionally, broadband absorption spectroscopy is used to quantify reactive species including O₃ and NO_x radicals, as function of N₂/O₂ ratio and input power, finding ozone densities of 10^{15} cm⁻³. This indicates that the reactive species flux can be finely tuned via gas composition. At low O₂ dilution, we have indications that atomic O can become an important radical species. Current work focuses on the influence of these different radical regimes on the deposition processes on our spatial ALD tool for various materials, and their properties.

To conclude, our work contributes to bridging the gap between DBD plasma physics and ALD chemistry for plasma-enhanced spatial ALD, providing a pathway toward optimizing plasma conditions for scalable, atmospheric-pressure ALD processes aimed at clean energy applications.

Surface Science

Room 209 CDE W - Session SS-ThM

Surface Electrical, Magnetic, and Optical Properties

Moderators: Tim Schäfer, Georg-August Universität, Göttingen, Melanie Müller, Fritz Haber Institute of the Max Planck Society

8:00am SS-ThM-1 Storing and Processing Information in the Magnetic Quantum States of Single Surface Adsorbed Atoms, Harald Brune, Swiss Federal Institute of Technology Lausanne, Switzerland INVITED

The magnetic properties of single surface adsorbed atoms became one of the core interests in surface and nanoscience in 2003, where single Co atoms on Pt were reported to have 200 times the magnetic anisotropy energy of bulk Co [1]. Even 1000 times this energy was reached for single Co atoms on thin MgO films [2]. In a classical picture, this suggests that

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these single atoms should be rather stable magnets. However, despite numerous efforts, the magnetic quantum states of all investigated single surface adsorbed transition metal atoms had very short magnetic relaxation times, below 1 μ s.

Immediately after changing from 3d elements to rare-earth atoms, a few adsorbate/substrate combinations could be identified, where the magnetization vector of a single atom is indeed stable over hours in the absence of an external magnetic field [3,4]. Therefore, these systems are single atom magnets and enable magnetic information storage in the smallest unit of matter. We will give an overview over the present adsorbate/substrate systems exhibiting single atom magnet behavior [3 – 10] and explain the essential ingredients for this surprising stability of single spin systems that are exposed to numerous perturbations from the environment. These atoms can be placed very close and still individually be addressed, conceptually enabling information storage at densities by 3 orders of magnitude larger than presently used devices.

Now the fundamental research field turns its attention to quantum coherent spin operations in single surface adsorbed atoms. If they have long enough coherence times with respect to the time it takes to perform a single quantum spin operation, these would be single atom quantum bits. The requirements for long coherence times of the magnetic quantum states are quite different from the ones of magnetic relaxation times. We will illustrate this with a few examples and point out single rare-earth atom systems that lend themselves already now as quantum repeaters in telecommunication [11], creating hope that single atom qubits may indeed become reality [12].

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8:30am SS-ThM-3 Nonadiabatic Dynamics Simulations of Carbon Atom Scattering from Au(111), Alexander Kandratsenka, MPInat, Germany
Measurements of energy loss spectra of carbon atom scattered off Au(111) surface conducted recently at Dalian Coherent Light Source facility suggest involvement of nonadiabatic effects. In order to construct a theoretical model describing that we are going to use the Independent-Electron Surface Hopping (IESH) approach, where the interaction of an incident atom (or molecule) with the surface induces the overlap of atomic and metallic orbitals facilitating energy exchange between projectile's nuclear degrees of freedom and ehp of a metal. The first step here is to produce full-dimensional potential energy surfaces for each single-electron state relevant for the dynamics. In case of C atom, these are triplet (ground state) and singlet spin states of a neutral C, and quartet and doublet states of C anion. The second step is to perform nonadiabatic dynamics simulations to study the influence of Intersystem Crossing regions on the carbon atom energy loss spectra.

8:45am SS-ThM-4 Oxidation of Ni-Based Superalloys: Closing the Gap from Adsorption to Microstructure, William Blades, Juniata College; Keithen Orson, University of Virginia, USA; Juran Niu, Alexei Zakharov, MAX IV Laboratory, Sweden; Jerzy Sadowski, Brookhaven National Laboratory; Petra Reinke, University of Virginia, USA

Ni-based superalloys are coveted for their corrosion resistance and formation of highly inert passive layers which limit degradation in a wide range of environments. Our work probes the oxidation process from the initial oxygen adsorption on a pristine alloy to the nanometer scale oxide layer using scanning tunneling microscopy and spectroscopy (STM/STS), and electron spectroscopies including X-ray photoelectron spectroscopy (XPS), and X-ray photoemission electron spectroscopy (XPEEM). We bridge the gap between single atom alloy to the complex solid solution surface, and realistic microstructure.

The Ni-Cr system has become a widely used model system for the study of oxidation, and passivity. It reflects the competition between Ni and Cr oxidation, the interplay between thermodynamic preference for chromia formation and kinetic limitations imposed by reactant transport in the alloy. The main factors which control the oxidation are alloy composition, temperature and crystallographic orientation. We will discuss the interplay between these factors on the oxide nucleation and growth between 200°C to 600°C with 5at% to 22at%Cr.

The delayed nucleation of NiO on Ni(100) is lifted on Ni-15Cr(100) leading to the rapid growth and step edge reconstruction with NiO. The chromia nuclei remain spherical due to their lack of epitaxial preference, although local segregation of Cr islands and a Cr(100)p(2'2) reconstruction is observed. Distinct variations in nucleation rate occur as a function of crystallographic orientation on Ni-15Cr(111) and several higher index surfaces on polycrystalline alloys. The direct observation of chromia nucleation on Ni-22Cr and Ni-22Cr-Mo with XPEEM opens the window to understanding the role of Mo, whose addition leads to high quality, chromia dominated, protective oxide layers. Adding Mo, or W modulates the surface chemistry towards chromia formation, and switches the growth to a layer-by-layer mode. Both, the barrier towards chromia formation, and the chromia-alloy interfacial energies are modified in favor of a dense protective layer.

A model which represents the alloy surface as a random solid solution will be used to capture adsorbate induced segregation as the initial step leading from adsorption towards oxide nucleation. The distribution of Cr in the surface is captured using fractal dimensions, percolation models and distribution functions combined with a systematic variation of diffusion constants for Cr. The outcome of the calculations is compared to nuclei densities and distributions from experiment.

9:15am SS-ThM-6 Chemically Interrogating N-Heterocyclic Carbenes at the Single-Molecule Level Using Tip-Enhanced Raman Spectroscopy, Nan Jiang, University of Illinois - Chicago

N-heterocyclic carbenes (NHCs) have been established as powerful modifiers to functionalize metal surfaces for a wide variety of energy and nanoelectronic applications. To fundamentally understand and harness NHC modification, it is essential to identify suitable methods to interrogate NHC surface chemistry at the spatial limit. Here, we demonstrate tip-enhanced Raman spectroscopy (TERS) as a promising tool for chemically probing the surface properties of NHCs at the single-molecule scale. We show that with subnanometer resolution, TERS measurements are capable of not only unambiguously identifying the chemical structure of individual NHCs by their vibrational fingerprints but also definitively determining the binding mode of NHCs on metal surfaces. In particular, by investigating low-temperature NHC adsorption on Ag(111), our TERS studies provide insights into the temperature dependence of the adsorption properties of NHCs. Furthermore, we investigate the mobility of a model NHC on Ag(111). Two distinct molecular behaviors are observed, depending on substrate preparation. Room-temperature deposition leads to diffusing NHC-Ag adatom complexes exhibiting a ballbot-like motion, chemically identified by TERS through their spectroscopic fingerprint. By contrast, NHCs deposited at low temperature are stabilized on Ag(111) as isolated single molecules directly bound to the substrate. Significantly, a desorption/readorption scenario is suggested for the displacement of NHCs by moving otherwise immobile single NHCs deposited at low temperature via STM manipulation, with their trajectory traced to atomic precision. This work suggests the potential of single-molecule vibrational spectroscopy for investigations of NHC surface modification at the most fundamental level.

9:30am SS-ThM-7 Atomic-Scale Spectroscopy of Ultrafast Charge Order Dynamics in Charge-Density Wave Materials, Sebastian Loth, University of Stuttgart, Institute for Functional Matter and Quantum Technologies, Germany

INVITED

In materials with mobile electrons, electron-phonon coupling and electron-electron interaction can cause the emergence of charge-ordered phases, such as charge-density waves or Mott insulators. These ordered electronic states feature collective excitations that are absent in conventional metals but are fundamental to understanding correlated electron physics. By combining scanning tunneling microscopy with terahertz excitation (THz-STM) [1,2], we achieve simultaneous atomic spatial and femtosecond temporal resolution to directly visualize these dynamics at their intrinsic length and time scales. The extreme field enhancement at the STM tip apex produces localized THz fields reaching MV/cm [3]. This enables localized excitation of surfaces by the electric field of the THz lightwave through THz-induced Coulomb forces [4] and ultrafast screening currents. We apply this

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technique to two prototypical CDW systems: the incommensurate CDW in 2H-NbSe₂ and the commensurate CDW in 1T-TaS₂. In NbSe₂, we observe collective phase excitations at sub-THz frequencies that originate from atomic pinning sites, revealing how disorder dictates local dynamics and creates heterogeneity in the response [5]. In contrast, TaS₂ exhibits rapid reconfigurations within individual domains that show layer stacking dependence. These measurements demonstrate how ultrafast THz excitation at surfaces can manipulate electronic order in quantum materials with extreme spatial precision. This approach provides insights into the atomic-scale mechanisms governing CDW pinning. The ability to resolve these fluctuations in real space at the scale of individual impurities provides a new route to unraveling the electronic dynamics of disordered correlated materials. References: [1] Cocker, T. L., et al. *Nat. Photon.* 7 620 (2013). [2] Cocker, T. L., et al. *Nature* 539 7628 (2016). [3] Abdo, M., et al. *ACS Photonics* 8 702 (2021). [4] Sheng, S., et al. *Phys. Rev. Lett.* 129 043001 (2022). [5] Sheng, S., et al. *Nat. Phys.* 20 1603 (2024).

11:00am SS-ThM-13 Measuring Properties of Single Defects, Dopants and Quantum Dots with nm Spatial Resolution, Peter Grutter, McGill University, Canada

INVITED

Semiconductor interfaces often have isolated trap states which modify electronic properties. We have developed a framework to quantitatively describe a metal-insulator semiconductor (MIS) device formed out of a metallic AFM tip, vacuum gap, and semiconducting sample. This framework allows the measurement of local dopant concentration, bandgap and band bending timescales with nm scale resolution of different types of defects on semiconductors such as Si, 2D MoSe₂ and pentacene monolayers [1].

With this method, we have characterized individual defects at the Si-SiO_x interface. We show that surface charge equilibration timescales, which range from 1–150 ns, increase significantly around interfacial states [2]. We conclude that dielectric loss under time-varying gate biases at MHz and sub-MHz frequencies in metal-insulator-semiconductor capacitor device architectures is highly spatially heterogeneous over nm length scales. We have also analyzed two-state fluctuations localized at these interfacial traps, exhibiting bias-dependent rates and amplitudes. When measured as an ensemble, these observed defects have a 1/f power spectral trend at low frequencies [3]. Low-frequency noise due to two level fluctuations inhibits the reliability and performance of nanoscale semiconductor devices, and challenges the scaling of emerging spin based quantum sensors and computers. The presented method and insights provide a more detailed understanding of the origins of 1/f noise in silicon-based classical and quantum devices, and could be used to develop processing techniques to reduce two-state fluctuations associated with defects.

Force detection with single electron sensitivity can be used to perform localized electron energy level spectroscopy on semiconductor quantum dots, individual ferrocene molecules and atomically precisely positioned dopant atoms in Si. Single electron force spectroscopy allows the measurement of Coulomb blockade and eigen state energy levels, shell structure, excited state energies, coupling strength to electrodes, molecular vibrations, reorganization energies, electron-nuclear coupling (Franck-Condon blockade), stability diagrams (i.e. coupling between qdots) and double dot coherence time (for a recent review see [4]). I will describe the challenges and progress towards applying this single electron force spectroscopy technique to atomically precisely positioned quantum dots in Si.

References:

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11:30am SS-ThM-15 Activating Elastic Conformation of a Single Molecule via Qplus AFM Tip, Markus Zirnheld, A.M. Shashika D. Wijerathna, Yuan Zhang, Old Dominion University

Mechanical properties of molecules adsorbed on material surfaces are increasingly vital for the applications of molecular thin films. In this study, we induce molecule conformational change on a single molecule through the application of mechanical load and quantify the associated force and energy required via a combination of a low temperature (~ 5.4 K) ultra-high vacuum (~10⁻¹⁰ Torr) Scanning Tunneling Microscope (STM) and Qplus Atomic Force Microscope (Q+AFM). The molecule under investigation, TBrPP-Co (II) (a cobalt porphyrin), deposited on an atomically clean gold

substrate, typically has two pyrrolic units (resembling pentagon rings) tilted upward and the other two downward. An atomically sharp Pt/Ir tip of the STM/Q+AFM, which vibrates with a high frequency (~ 30kHz), is employed to run over a single TBrPP-Co(II) molecule at different heights with 0.1 Å as decrements and meanwhile to record tip-molecule interaction strength in the form of tip frequency change. When the tip approaches the threshold distance to the molecule, the mechanical load by the tip becomes large enough to trigger the elastic conformation of the molecule and cause pyrrolic units to flip their orientation in the opposite direction. Due to the sensitive nature of tip-molecule interaction, the pyrrolic units flipping can be directly visualized by STM, where upward-tilted pyrrolic units appeared as two bright protrusions, contrasting with the appearance of downward-tilted pyrrolic units. By processing frequency change, we obtain a three-dimensional mechanical force and potential maps for the single molecule TBrPP-Co(II) with the resolution of angstrom level. Our results indicate that a potential barrier of ~ 49 meV is needed to activate the elastic conformational switch responsible for inducing pyrrolic units flipping of a single TBrPP-Co(II) molecule.

KEYWORDS

single molecular switch, mechanical load, qplus atomic force microscope, energy barrier, elastic conformational change, porphyrin molecule

11:45am SS-ThM-16 Local Superconductor-to-Semiconductor Phase Transition in WS₂ Controlled by STM Tip, TeYu Chien¹, University of Wyoming

Transition metal dichalcogenides (TMDs) are a unique class of materials that often host electronic correlation and strong spin orbital coupling. TMDs are two-dimensional (2D) layered materials with van der Waals (vdW) force between the layers allowing various stacking structures. Thus, TMDs often have polymorphic crystal structures, which exhibit drastically different physical properties. In WS₂, the most stable 2H phase is a topologically trivial semiconductor, while the metastable 2M phase is superconducting (SC) with critical temperature of 8.8 K. The 2M phase is also reported to be possible topological SC. A zero-bias peak has been reported inside magnetic vortices via scanning tunneling microscopy (STM) measurements and is considered to be a candidate of the Majorana Zero Modes (MZMs). It also has been reported that the metastable 2M phase WS₂ can be converted into 2H phase by heating. Thus, it is interesting to explore the possibility of creating topological SC anti-dot in nm scale to host the potential MZMs. In this study, we demonstrate a precise control of 2M to 2H phase transition in WS₂ using a STM tip “current pulsing” method. The resulting phase transition areas are notably sharply hexagonal following the 2H lattice orientation and can range from 30-350 nm in diameter. The effects of the electric field and tunneling current on the conversion will be discussed to provide insights of the conversion mechanism.

Funding acknowledgement: NSF OSI-2228841

12:00pm SS-ThM-17 Multimodal Tool Combining Multichannel HREELS and ARPES/XPS to Study Electron-Boson Coupling, Takahiro Hashimoto, Timo Wätjen, Scienta Omicron AB, Sweden; Xin Zhang, Andrew Yost, Daniel Beaton, Scienta Omicron, Inc.; Harald Ibach, Stefan Tautz, François Bocquet, Forschungszentrum Jülich GmbH, Germany

Electrons in quantum materials couple to bosonic excitations, such as phonons and magnons, making it essential to characterize both these excitations and the electronic band dispersion. Multimodal characterization, where a single sample is analyzed using multiple complementary techniques, offers a powerful approach to uncovering the interplay between various excitations and electronic structure. High-resolution electron energy loss spectroscopy (HREELS) is a technique for observing surface excitations including phonons, magnons, plasmons, excitons, and vibrational modes. Multimodal characterization has been difficult with a traditional single channel HREELS instrument because it requires its own detector, the measurements are time consuming, and angular resolution is limited. To improve the efficiency of HREELS measurements and to realize multimodal measurement with photoemission spectroscopy, we developed a solution by combining a monochromatic collimated electron source and a hemispherical electron analyser, commonly used for ARPES and XPS. The multichannel 2D detector of the analyser simultaneously measures hundreds of channels in both the energy and angular directions, and the measurements are orders of magnitude faster than the single channel setups. By adding a light source for photoemission spectroscopy, this setup becomes a multimodal

¹ JVST Highlighted Talk

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characterization tool that combines state-of-the-art HREELS and ARPES/XPS using the same electron analyser. It allows to study the interplay between various surface excitations and electronic properties including electron-phonon coupling and electron-magnon coupling. Also, recent examples of HREELS measurements, including anisotropic exciton dispersion and topological phonons, are discussed to showcase the power of multichannel HREELS to observe novel excitations.

Thin Films

Room 206 B W - Session TF+CPS+MS+EM-ThM

Thin Films for Microelectronics I

Moderators: Elton Graugnard, Boise State University, Robert Grubbs, IMEC Belgium

8:00am **TF+CPS+MS+EM-ThM-1 Pushing the Limits of Vertical NAND Storage Technology with ALD-based Ferroelectrics**, *Prasanna Venkatesan, Georgia Institute of Technology; Asif Khan, Georgia Institute of Technology, USA* **INVITED**

Solid-state drives (SSDs) continue to serve as the foundation of long-term active data storage in modern data centers. Over the past decade, conventional vertical NAND (vNAND) technology has achieved a remarkable 50x increase in storage density, enabled by advances in physical scaling (x-y and z dimensions) and logic scaling (from multi-level cell, MLC, to quad-level cell, QLC). The explosive growth of artificial intelligence (AI)—with models like GPT-4 surpassing a trillion parameters—has further accelerated the demand for high-capacity, high-performance storage systems to support petabyte-scale datasets.

Today's state-of-the-art vertical NAND devices offer densities nearing 30 Gb/mm² with over 300 stacked layers. However, extending this scaling trajectory to 1000 layers and beyond—targeting storage densities exceeding 100 Gb/mm²—poses significant challenges. Chief among these are reliability concerns intrinsic to charge-trap flash technologies, such as lateral charge migration and the poor endurance of higher logic level operations.

To overcome these limitations, ferroelectric field-effect transistors (FeFETs) have emerged as a promising alternative, enabling further z-direction scaling with improved reliability. This presentation will highlight recent advances in atomic layer deposition (ALD)-based ferroelectric gate stack engineering, and how these innovations can support the development of next-generation NAND architectures capable of 1000-layer integration and ultra-high-density storage.

8:30am **TF+CPS+MS+EM-ThM-3 Electrical Properties of BaTiO₃ Thin Films Prepared by Atomic Layer Deposition**, *Jiayi Chen, Asif Khan, Mark Losego, Georgia Institute of Technology*

This talk will discuss our efforts to develop a robust atomic layer deposition process (ALD) to create ferroelectric BaTiO₃ thin films. Ferroelectric materials are potential candidates for future low voltage RAM and NAND memory because of their reversible two polarization states under low external electric field. While the CMOS compatible gate dielectric materials HfO₂ and Hf_{0.5}Zr_{0.5}O₂ are ferroelectric, they have high coercive fields that make it difficult to lower switching voltages below 1 V. Therefore, perovskite ferroelectric materials, like BaTiO₃ are desirable to use for these applications because their coercive voltages can be an order of magnitude lower, approaching 0.1 V. However, these ferroelectric films must be deposited by ALD to match the conformality and small thickness requirements desired for RAM and NAND memory. This talk will present the electrical properties of BaTiO₃ thin films deposited by an ALD process using Bis-(1,2,4-triisopropylcyclopentadienyl)-Barium and Titanium Isopropoxide precursors. We are able to achieve dielectric constants as high as 15 in as-grown (non-crystalline) thin films, and 140 in annealed (crystalline) thin films, with low leakage current (10⁻⁴ A / cm² at 3 V). Specifically, we will focus on the variations of dielectric constant and leakage current as we optimize deposition recipe, BaTiO₃ thin films' stoichiometry, scale down the thickness from 50 nm to 10 nm, and measure at cryogenic and elevated temperatures. We will also discuss the implications of these measurements, and the possible route to achieve ferroelectric BaTiO₃ thin films by ALD.

8:45am **TF+CPS+MS+EM-ThM-4 Interlayer-Modulated Coercive Field in HfZrO₂ Ferroelectric Devices**, *Marshall Frye¹², John Wellington-Johnson, Lance Fernandes, Prasanna Ravindran, Asif Khan, Lauren Garten, Georgia Institute of Technology*

Ferroelectric NAND (FeNAND) using Hf_{0.5}Zr_{0.5}O₂ (HZO) offers increased memory density, speed, and decreased operation voltage of NAND compared to charge trap flash technology.^[1] However, to compete with charge trap flash, the memory window of FeNAND must be increased above 6 V for 3 bit/cell operation or above 8 V to enable 4 bit/cell operation.^[1] Since the memory window is directly related the ferroelectric coercive field (E_c), finding pathways to increase the coercive field of HZO is critical to enable FeNAND. Prior studies show that inserting a dielectric interlayer can increase the coercive field, but the mechanism driving the increase in E_c beyond just adding a capacitor in series is still unclear.^[2]

The goal of this work is to test the hypothesis that the increased defect states in the dielectric-HZO interface cause in-built fields that then increase the coercive field.^[3] First, we fabricate 19 nm HZO both with and without Al₂O₃ interlayers or adjacent layers. Varying the layer thicknesses and positions via atomic layer deposition allows for the determination of how the device structure impacts the ferroelectric switching. Polarization-electric field hysteresis loops and positive-up-negative-down (PUND) show ferroelectric switching for each of the films, with a remnant polarization (2P_r) up to 27.4 μ C/cm². The coercive field increases from 1.01 MV/cm in devices without an additional dielectric layer (19 nm HZO) to 3.11 MV/cm in a 3 nm Al₂O₃ interlayer inserted between two 8 nm layers of HZO (8 nm HZO-3 nm Al₂O₃-8 nm HZO). First-order reversal curve (FORC) analysis reveals an increase in internal bias field in devices with dielectric layers, potentially due to defects at the Al₂O₃- HZO interface. X-ray photoelectron spectroscopy valence band measurements confirm an increase in mid-gap defect states at this interface compared to bulk of the film. Additionally, temperature-dependent modulus spectroscopy is used to evaluate the activation energy and defect concentration in samples with and without a dielectric layer. These findings provide key insights into mechanisms to modulate coercive field in HZO, enabling the design of FeNAND devices with larger memory windows.

References

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- [3] D. Das et al., *Int. Electron Devices Meet. IEDM*, **2023**

9:00am **TF+CPS+MS+EM-ThM-5 Towards Low-Resistance p-Type Contacts to 2D Transition Metal Dichalcogenides Using Plasma-Enhanced Atomic Layer Deposition**, *Ageeth Bol, University of Michigan, Ann Arbor* **INVITED**

One major limitation of 2D transition metal dichalcogenide (TMD) based FETs is the high contact resistance between metallic electrodes and semiconducting channels, particularly for p-type contacts. In this presentation I will address how PEALD of p-type TMDs can be used to improve this contact resistance. First, I will go over controlled doping strategies to form p-type 2D TMD contact materials using PEALD, with an emphasis on Nb Doped WS₂. Our recent results show contact resistance values as low as 0.30 ± 0.26 k Ω · μ m between Pd and PEALD Nb_xW_{1-x}S₂, demonstrating that low resistance contacts between metal and p-type TMDs are possible. Then, I will discuss reducing unintentional p-doping introduced during PEALD of TMDs. PEALD TMDs typically contain some level of hydrogen impurities that leads to unintentional p-doping. We have shown that these impurities can be reduced by introducing an Ar plasma C step in the standard PEALD TMD process. Finally, the use of remote plasmas in PEALD for contact deposition can lead to the creation of undesired impurities and defects in the 2D TMD channel, possibly impacting electronic behavior. I will present some first insights into the defects that are created during PEALD on 2DTMDs and how we can reduce the number of plasma-induced impurities and defects.

9:30am **TF+CPS+MS+EM-ThM-7 DOE's Energy Efficiency Scaling for Two Decades (EES2): Featuring ALD-Fabricated Microelectronics Devices for Ultra-Energy-Efficient Computation at Argonne National Laboratory**, *Emilie Lozier, U.S. Department of Energy, Advanced Manufacturing Office; Jeffrey Elam, Argonne National Laboratory; Desiree Salazar, Energetics; Tina Kaarsberg, U.S. Department of Energy, Advanced Manufacturing Office*

Electricity demand in the U.S. is projected to grow ~2% annually, potentially reaching a 50% increase compared to today by 2050 (International Energy

¹ AVS Russell and Sigurd Varian Awardee

² TFD James Harper Award Finalist

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Agency 2025). A major driver of this growth is the rise of energy-intensive AI computation, according to a bottom-up analysis of data center energy use published by Lawrence Berkeley National Laboratory (LBNL) in December 2024. Including cryptocurrency mining, LBNL's report projects that data-center-based computation could account for roughly a quarter of total U.S. electricity consumption by 2028. While efforts are underway to increase generation to the grid, any solution must simultaneously address the energy efficiency of compute if it is to be successful. Kicking off three years ago, the U.S. Department of Energy (DOE) Advanced Materials and Manufacturing Technologies Office (AMMTO) has already been leading a multi-organization effort united around the shared aim of advancing ultra-energy-efficient compute technologies. This collaborative effort, known as the Energy Efficiency Scaling for Two Decades (EES2) initiative, is uniquely situated to take on this energy challenge. Through EES2, DOE/AMMTO has convened eight working groups representing more than 70 voluntarily pledging organizations across industry, academia, nonprofits and the National Labs to draft an R&D Roadmap describing technologies-to-beat to achieve biennial energy efficiency doubling for the compute stack compounding to a 1,000X efficiency increase by 2040. Moreover, Version 1.0 of the R&D Roadmap (available here: <https://eere-exchange.energy.gov/FileContent.aspx?FileID=f4234e29-cc0c-4a56-a510-86b616ab5535>) has spurred a suite of EES2-identified and DOE-funded research projects to pursue some of the most promising technologies for enabling ultra-energy-efficient computation. This presentation will highlight one such project at Argonne National Laboratory – with collaborators at Stanford University, Northwestern University, and Boise State University – that has been advancing two-dimensional semiconductor field-effect transistors (2D-FETs) and memtransistors, both fabricated with atomic layer deposited (ALD) molybdenum sulfide (MoS_2) with potential to achieve 50X and 10,000X energy efficiency improvements, respectively. Along with timely project updates, this presentation will also discuss how the Argonne project will integrate with the finalized Version 1.0 of the EES2 R&D Roadmap, that is due to be published in the second half of 2025.

9:45am TF+CPS+MS+EM-ThM-8 Self-Limiting Atomic Layer Deposition of Few-Layer MoS_2 , Sungjoon Kim, Jeffrey Elam, Argonne National Laboratory
Computational energy consumption has been increasing exponentially, making energy-efficient microelectronics and computing an urgent need. Three-dimensional integrated circuits (3D ICs) and neuromorphic computing promise to revolutionize information technology by drastically reducing the energy consumption of computers, and two-dimensional (2D) semiconductors like molybdenum disulfide (MoS_2) can enable such technologies. However, scalable and controllable manufacturing processes are still needed to realize the technology's full potential. Here, we demonstrate the uniform and controlled deposition of few-layered MoS_2 using atomic layer deposition (ALD) for the purposes of memtransistor fabrication. By leveraging the equilibrium shift from material deposition to material etching, a self-limiting deposition of MoS_2 is achieved where material growth is stopped after the initial few layers. The resulting few layer MoS_2 was characterized using Raman spectroscopy and X-ray photoelectron spectroscopy, and was used to fabricate and test memtransistors. This deposition strategy is straightforward, robust and more scalable compared to other methods such as powder CVD and exfoliation.

11:00am TF+CPS+MS+EM-ThM-13 Integrated Magnetoacoustic Isolator with Giant Non-Reciprocity, Bin Luo, Benyamin Davaji, Nian-Xiang Sun, Department of Electrical and Computer Engineering, Northeastern University **INVITED**

Recent advances in integrated nonreciprocal components—such as isolators and circulators—have enabled transformative wireless communication and sensing technologies, including full-duplex radio, in-band self-interference cancellation, and protected high-power transmission systems. While commercial ferrite-based isolators offer low insertion loss and high power handling, their reliance on kOe-level bias fields, high-temperature ferrite growth, and bulky permanent magnets severely limits their compatibility with CMOS processes and low-power applications.

To address these limitations, magnetoacoustic isolators have emerged as a promising class of passive, CMOS-compatible, and power-efficient nonreciprocal devices. These isolators consist of magnetic heterostructures integrated within the propagation path of surface acoustic waves (SAWs) on piezoelectric substrates. Magnetoelastic and magnetorotational coupling mechanisms enable strong spin wave–acoustic wave interactions, generating hybrid magnetoacoustic waves with dramatically asymmetric

damping rates in opposite directions. This asymmetry yields unidirectional transmission, fundamental to nonreciprocal operation.

Despite progress, early devices suffered from weak non-reciprocity, primarily due to a mere helicity mismatch effect and an inherent symmetric spin wave dispersive relation in single-layer magnetic films. Recent efforts have focused on engineering magnetic stacks with nonreciprocal spin wave dispersion. Key examples include: (i) **interfacial Dzyaloshinskii–Moriya interaction (iDMI) stacks** like CoFeB/Pt , (ii) **interlayer dipolar-coupled (IDC) stacks** such as $\text{FeGaB}/\text{SiO}_2/\text{FeGaB}$, and (iii) **RKKY synthetic antiferromagnets** like $\text{CoFeB}/\text{Ru}/\text{CoFeB}$. These architectures achieve nonreciprocity strengths up to 250 dB/mm. Recent demonstrations using shear-horizontal waves in LiTaO_3 substrates coupled to ferromagnetic and anti-magnetostrictive bilayers have yielded nonreciprocity levels of 60–82 dB/mm with simpler fabrication.

Nevertheless, a persistent challenge remains in reducing insertion loss while maintaining wide bandwidth and high isolation. We will introduce our recent efforts in a **fundamental mode SAW-driven magnetoacoustic isolator with giant non-reciprocity** and a **wideband nonreciprocal magnetoacoustic isolator based on non-collinear dipolar-coupled ferromagnetic stacks**. The talk will provide a comprehensive overview of the mechanisms, material platforms, and experimental breakthroughs driving the field of magnetoacoustic isolators. We will highlight the path toward integrated, low-loss, and high-performance nonreciprocal components for future quantum, RF, and IoT systems.

11:30am TF+CPS+MS+EM-ThM-15 Stress Control and Thermal Stability of a FeCo-Ag Multilayer Thin Films for Use in Magnetoelectric Heterostructures, Thomas Mion, Konrad Bussmann, US Naval Research Laboratory

This investigation studies the stress control and thermal properties of FeCo/Ag multilayer thin films prepared by sputter deposition for their potential applications in magnetoelectric heterostructure devices. While development of magnetoelectric devices has increased, the practical implementation of magnetic thin films is often confounded by additional processing and packaging steps which can be detrimental to the quality of the magnetic film and subsequently the performance of the device. We show the annealing of the FeCo/Ag multilayers is robust until annealing temperatures reach 300 – 400 C where a breakdown of the Ag leads to an increased coercive field, and annealing >400 C is severely detrimental to the soft magnetism of the system as the Ag layers deteriorate. Additionally, as-deposited stress can play a dominant role in micromechanical devices when released. We will show the stress control of this ferromagnetic thin film through in-situ substrate bias allows the films to be tailored from a broad range of +320 MPa tensile to -300 MPa compressive with application of up to a -120 VDC bias during deposition.

11:45am TF+CPS+MS+EM-ThM-16 Extraordinary Magnetoresistance in High-Mobility SrTiO_3 Thin Films, Zhifei Yang¹, Shivasheesh Varshney, University of Minnesota; Sreejith Sasi Kumar, Tristan Steegemans, Rasmus Bjørk, Dennis Valbjørn Christensen, Technical University of Denmark; Bharat Jalan, University of Minnesota

Magnetoresistive sensors are widely used to detect magnetic fields by measuring changes in electrical resistance. One such effect, extraordinary magnetoresistance (EMR), arises from the geometry of semiconductor–metal hybrid structures that combine high-mobility semiconductors with highly conductive metals. EMR strongly depends on both the semiconductor's mobility and the quality of the metal–semiconductor contact (ohmic contact with low contact resistance). The device geometry further influences boundary conditions and current paths under magnetic fields, enabling flexible design and performance tuning. While most previous EMR studies have focused on III-V semiconductors and 2D materials, there has been limited exploration of oxide-based systems.

Here, we demonstrate EMR in high-quality La-doped SrTiO_3 thin films grown on SrTiO_3 (001) substrates using hybrid molecular beam epitaxy (MBE). We grow films with carrier concentrations ranging from $\sim 2 \times 10^{17} \text{ cm}^{-3}$ to $\sim 1 \times 10^{20} \text{ cm}^{-3}$, achieving Hall mobilities from $\sim 300 \text{ cm}^2/(\text{V}\cdot\text{s})$ up to over 50,000 $\text{cm}^2/(\text{V}\cdot\text{s})$ at 1.8 K. Using an asymmetric device geometry that breaks mirror symmetry between voltage probes, we observe corresponding asymmetry in magnetoresistance (MR) measurements. With embedded metals that are ohmic contacts to SrTiO_3 , we achieve an MR $((R(B) - R(0))/R(0))$, where $R(B)$ is the measured resistance at magnetic field

¹ AVS Graduate Research Awardee

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B) approaching 9000% at 9 T and 1.8 K, which is over 3900% higher than the intrinsic MR of SrTiO_3 – a *world record* for an oxide-based EMR device! Finite element simulations of current flow and MR in these SrTiO_3 -based hybrid structures align well with experimental data, validating the design principles. These results establish the potential of complex oxide systems for low-temperature EMR sensors and open opportunities for integrating oxide heterostructures in future magnetoelectronic devices. In this presentation, we will discuss the hybrid MBE growth and microfabrication of high-mobility SrTiO_3 thin films, along with device optimization strategies and detailed magnetotransport measurements across various temperature and magnetic field ranges.

12:00pm **TF+CPS+MS+EM-ThM-17** Examining the Spin Structure of Altermagnet MnTe Epilayers Grown by Molecular Beam Epitaxy, *Qihua Zhang*¹, The Pennsylvania State University; *Mingyu Yu*, University of Delaware; *Alexander Grutter*, *Christopher Jenson*, *William Ratcliff*, *Julie Brochers*, National Institute for Science and Technology (NIST); *Narendirakumar Narayanan*, *Thomas Heitmann*, University of Missouri; *Nitin Samarth*, *Stephanie Law*, The Pennsylvania State University

As a new class of magnetic materials, altermagnets feature alternating arrangement of magnetic moments with zero net magnetization, a typical characteristic of an antiferromagnet; yet they also feature large spin splitting in its electronic band structure. NiAs-phase (α -) MnTe has gained significant attention as a candidate of altermagnet family owing to its large spin-splitting energy and high transition temperature. In this study, we investigate the altermagnet properties of MBE-grown α -MnTe layers using neutron diffraction experiments. We first study and optimize the growth conditions of MnTe layers grown directly on InP (111)A substrates. It is seen that using a lower growth temperature result in a narrower full-width-at-half-maximum (FWHM) in the x-ray diffraction (XRD) rocking curves, but will introduce whiskers on the surface, while increasing the Te/Mn flux ratio improves both the crystalline quality and the surface morphology. With a temperature window of 250-400 °C and a Te/Mn flux ratio of 3, we further obtain high quality α -MnTe films with a 0.8 nm surface roughness and a corresponding threading dislocation density of $\sim 7.5 \times 10^8 \text{ cm}^{-2}$. Temperature-dependent neutron diffraction measurements were performed on the MnTe films grown with optimized conditions. A fitted Néel temperature of 304 K was obtained based on the half-order antiferromagnetic peak along the (0001) direction, which confirmed the bulk-like antiferromagnetic behavior in the α -MnTe. Using polarized neutron reflectometry, substantial spin asymmetry is captured while very small net magnetization (up to 4 emu/cm³) across the MnTe layer is obtained, highlighting a near-to-ideal stoichiometric α -MnTe. Angle-resolved photoemission spectroscopy is further used to confirm the spin splitting in the electronic band structure. This study carefully clarifies the magnetic band structure in a promising altermagnet candidate and introduces potential methods of controlling the ferromagnetism in the materials.

¹ TFD Distinguished Technologist Award

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2D Materials

Room 208 W - Session 2D+AQS+MI+NS+QS+TF-ThA

2D Materials: Magnets and Topological Phenomena

Moderators: Rafik Addou, The University of Texas at Dallas, Zhurun Ji, MIT

2:15pm 2D+AQS+MI+NS+QS+TF-ThA-1 Non-Local Transport from Magnetic Topological Superconductivity in 2D Fe-Chalcogenides, *Kenneth Burch*, Boston College INVITED

Magneto-Chiral topological superconductivity is a rare phase long pursued for error-free quantum computation. Its 1D chiral modes possess topologically protected long-range coherence well beyond that of the cooper pairs, which could be fruitful for quantum transduction and low-temperature spin transport. While evidence for such modes is mounting, unambiguous signatures, such as non-local transport via co-tunneling, remain elusive. I will describe our realization of 1D chiral hinge modes mediating the direct tunneling of electrons from source to drain in FeTe0.55Se0.45. Specifically, I will discuss our evidence that the non-local tunneling signatures are decoherence-free and emerge from this material's combination of surface magnetism, bulk topology, and superconductivity. Time remaining, I will discuss how these advances can be used for Majorana Circuits and future efforts in cryogenic spintronics

2:45pm 2D+AQS+MI+NS+QS+TF-ThA-3 Integer and Fractional Chern insulators in moiré MoTe₂, *Yihang Zeng*, Purdue University INVITED

The fractional Chern insulator (FCI), a lattice analogue of the renowned fractional quantum Hall state, was theorized to exist without external magnetic field. FCI provides a pathway towards novel topologically ordered quantum phases that are useful for decoherence-free quantum computation. Two-dimensional (2D) moiré materials, featuring strong correlation, non-trivial band topology and unparalleled tunability, stands as an ideal platform for realizing FCI. In this talk, I will first present our innovative optoelectronic detection method, which is capable of detecting the chemical potential in arbitrary 2D materials. Employing this new technique, we successfully observed an FCI and integer Chern insulator in the zero magnetic field limit in MoTe₂-based moiré materials. We further study the FCI and ferromagnetism as a function of twist angle.

3:15pm 2D+AQS+MI+NS+QS+TF-ThA-5 Conducting Scanned Probe Investigations of the Bismuthine Termination of Intrinsic Topological Superlattice Bi₂-Bi₂Se₃, *Lakshan Don Manuwege Don, Mysidia Leff, Md. Sakauat Hasan Sakib*, Miami University; *Seth Shields*, The Ohio State University; *Joseph Corbett*, Miami University

Topological materials, characterized by symmetry-protected electronic states and robust surface conduction, represent a frontier in quantum materials research. Their non-trivial band topology enables dissipationless edge states, spin-momentum locking, and resilience to disorder, making them strong candidates for spin-orbit torque devices, magnetic field sensors, and polarized light detectors, to name a few. These properties have positioned topological materials as important material of interest as development of scalable quantum technologies grows.

In this study, we explore the atomic and electronic properties of the bismuthine-terminated topological semimetal Bi₂-Bi₂Se₃ using scanning tunneling microscopy (STM) and conductive atomic force microscopy (C-AFM). Bi₂-Bi₂Se₃ is an intrinsic superlattice material's comprised of a Bi₂Se₃ quintuple layer (QL) slab and a 2D Bismuthine (Bi₂) layer separated by a van der Waals gaps. The topological surface state on the 001 orientation depends on the terminating layer, with two distinct possible topologically protected surface states.

The unique step heights between the Bi₂Se₃ QL and Bismuthine layer enable termination characterization through careful step height analysis. Atomically resolved STM measurements on a Bismuthine terminated step reveal a distinct honeycomb lattice, while scanning tunneling spectroscopy (STS) captures a Dirac cone in local density of states centered at the Fermi level, in excellent agreement with angle-resolved photoemission spectroscopy (ARPES).

Using C-AFM under ambient conditions, we investigate force-dependent I-V spectroscopy. Utilizing step height analysis, we find a bismuthine terminated step and perform point spectroscopy. At low applied forces, differential conductance (dI/dV) spectra reveal a Dirac cone, mirroring STM results and confirming the presence of topologically protected surface states even under ambient conditions! As mechanical force increases, we observe a transition in transport behavior, from quantum tunneling to Ohmic conduction. Additionally, a voltage and force-dependent crossover from direct tunneling to Fowler-Nordheim tunneling is identified.

Our findings revealing the atomic structure and Dirac cone of the bismuthine termination in the topological semimetal Bi₂-Bi₂Se₃. Interestingly these feature are observable even under ambient condition. We find no degradation with time, freshly grown sample versus those that have sat for months give the same results.

3:30pm 2D+AQS+MI+NS+QS+TF-ThA-6 Local Spectroscopy Study of Gate-controlled Energy Gap in Monolayer 1T'-WTe₂, *Tiancong Zhu*, Purdue University; *Zehao He*, University of California at Berkeley; *Michal Papaj*, University of Houston; *Samuel Stoltz*, Department of Physics, University of California, Berkeley; *Tianye Wang, Canxun Zhang, Yan-Qi Wang, Joel Moore, Zi Qiang Qiu, Feng Wang, Michael Crommie*, University of California at Berkeley

The interplay between strong correlation and topology can lead to intriguing quantum phases of matter. In monolayer 1T'-WTe₂, the non-trivial topology gives rise to the quantum spin Hall insulator (QSHI) phase, characterized by helical 1D edge states surrounding the insulating 2D bulk. While experimental evidences support quantized conductance through the 1D helical edge states, the nature of the insulating bulk, whether attributed to spin-orbit coupling or strong correlation, remains under debate. Here, we employ scanning tunneling microscopy and spectroscopy (STM/S) on gate-tunable 1T'-WTe₂ devices to shed light on this problem. Our samples are fabricated using a combination of molecular beam epitaxy (MBE) and van der Waals (vdW) stacking technique, which allows us to synthesize high-quality monolayer 1T'-WTe₂ films on a gate tunable graphene field effective transistor supported by hBN. Gate-dependent STS reveals a substantial energy gap in 1T'-WTe₂ at its charge neutrality, which diminishes when the Fermi level is tuned into either the conduction or valence band. STS across the sample edges shows that the edge states persist at all gate voltages, while Fourier transform-STM measurement in the bulk further shows the evolution of the bulk band structure at different carrier densities. We will compare our experimental data with existing theoretical models, such as the SOC-induced gap and the proposed excitonic insulator phase, and suggest future experimental directions to further elucidate the origin of the energy gap.

3:45pm 2D+AQS+MI+NS+QS+TF-ThA-7 Exploring Moiré Magnetism in Twisted Two-Dimensional Magnets, *Liuyan Zhao*, University of Michigan INVITED

Moiré superlattice emerges from the interference between two mismatched atomic lattices, and it has led to tremendous success in designing and tailoring the electronic states in two-dimensional (2D) homo- and hetero-structures. Yet, the power of moiré superlattice in controlling the spin degree of freedom and thus modifying the magnetic states is much less explored. Only very recently after the development of 2D magnet research, there have been a few experimental attempts in realizing moiré magnetism in twisted 2D magnet homo-structures. In this talk, I will show our recent effort in studying magnetic phases in twisted double bilayer chromium triiodide (CrI₃) and progressive steps towards realizing moiré magnetism. Noting that bilayer CrI₃ is a layered antiferromagnet and that any homogeneous stacking of two bilayers necessarily produces zero magnetization, we have revealed, in twisted double bilayer CrI₃, an unexpected net magnetization showing up at intermediate twist angles and its accompanied noncollinear spin textures. I will show the optical spectroscopy signatures of this twist-induced magnetic phase, then discuss its dependence on twist angle, external magnetic field, and temperature.

Actinides and Rare Earths

Room 207 A W - Session AC+MI-ThA

Early Career and Rising Stars

Moderators: *Krzysztof Gofryk*, Idaho National Laboratory, *Evgeniya Tereshina-Chitrova*, Charles University, Prague, Czech Republic, *Itzhak Halevy*, Ben Gurion Uni. Be'er Sheva, *Edgar Buck*, PNNL

2:15pm AC+MI-ThA-1 Combinatorically Estimating the Orbital Occupancy of Actinides using an Entropic Approach, *Miles Beaux, Benjamin Heiner*, Los Alamos National Laboratory INVITED

Predicting material properties in *f*-block elements, especially actinides, is complicated by their complex electronic structures, such as multiconfigurational ground states and strong correlation effects. These structures arise from large electron degrees of freedom, posing challenges in modelling their behavior. A non-integer orbital occupancy representation describes the superposition mixing of multiple near-energy degenerate configurations. This representation generalizes by approximation to

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established ground states in elements with simpler electronic structures and enables an over-approximation of entropy for multiconfigurational ground state structures. A complementary combinatorial approach applies Hund's rule constraints to establish an under-approximation of entropy. Together, these methods bracket entropy limits, providing insights into electronic configurations that most significantly contribute to the multiconfigurational ground states of actinide elements to a low order approximation. Under an energy degeneracy assumption weighted by configuration permutations, calculations iteratively refine the contributing configurations, yielding low-order orbital occupancy estimates that align with experimental data and theoretical models. (LA-UR-25-22711)

2:45pm AC+MI-ThA-3 Applications of Scanning Tunneling Microscopy in Heavy Element Studies, Benjamin Heiner¹, Miles Beaux, Los Alamos National Laboratory

Scanning Tunneling Microscopy and Spectroscopy (STM/S) are powerful techniques for investigating atomic, molecular, and surface properties. At Los Alamos National Laboratory, a specialized instrument designed to contain and probe samples containing heavy elements (i.e. actinides) allows us to study of the most uncharacterized elements on the periodic table. This capability has facilitated new insights into the electronic structure of plutonium oxides, intermetallics, and complexes. Using temperature-resolved STS, we can directly and continuously measure the total density of states of these materials across the Fermi energy, addressing a critical gap in experimental plutonium data. These advancements provide valuable information for understanding the electronic behavior of plutonium, with implications for fundamental science and nuclear materials research. Additionally, our ongoing efforts aim to apply these techniques to molecular complexes containing a single actinide atom, enabling both STM imaging and localized STS probing of individual actinide atoms. (LA-UR-25-22710)

3:00pm AC+MI-ThA-4 Electronic Structure of Uranium-Based Ferromagnet UPS, Sabin Regmi, Idaho National Laboratory; Alexei Fedorov, Lawrence Berkeley National Laboratory; Dariusz Kaczorowski, Polish Academy of Sciences, Poland; Peter Oppeneer, Uppsala University, Sweden; Krzysztof Gofryk, Idaho National Laboratory

Strongly correlated f-electron systems often exhibit intriguing properties such as unconventional superconductivity and heavy fermion behaviors. Particularly in 5f-electron systems, the understanding of the relation between f electrons and observed physical properties has been a challenge due to their duality. Here, we present an angle-resolved photoemission spectroscopy (ARPES) study of uranium-based ferromagnet UPS, supported by density-functional theory calculations. Measurements carried out at on and off-resonant photon energies suggest strong contribution from U 5f in the vicinity of the Fermi level and c-f hybridization. The results reveal the Fermi surface, underlying electronic structure in this system, and the nature of the 5f electrons in this ferromagnetic material. This work provides a valuable platform to advance the fundamental understanding of the 5f electronic structure in uranium-based and actinide materials in general.

***This work is supported by Idaho National Laboratory's laboratory directed research and development (LDRD) program and the US Department of energy (DOE) Basic Energy Sciences, Materials Sciences and Engineering Division.*

3:15pm AC+MI-ThA-5 The Plutonium Auto-reduction Reaction, Predicting Kinetics, and Assessing Impacts to Surface Science Measurements, Timothy Gorey, Daniel Rodriguez, Sarah Hernandez, Los Alamos National Laboratory

Plutonium is a fascinating and difficult material to measure in vacuum systems due to its auto-catalytic reduction of higher oxides into plutonium sesquioxide (Pu_2O_3). This “auto-reduction” reaction complicates surface science measurements aiming to understand higher oxides, because these layers, when exposed to vacuum as is required for many surface-sensitive techniques (e.g. X-ray Photoelectron and Auger Electron spectroscopies (XPS and AES), and Secondary Ion Mass Spectrometry (SIMS)) spontaneously converts into sesquioxide. This presentation will discuss an XPS-focused study into the nuances of high oxide (PuO_2) surface analysis and propose likely mechanistic origins for the auto-reduction reaction as well as methods to predict the chemical progression of the surface.

3:30pm AC+MI-ThA-6 Magnetic Properties of UP_2 Probed by High-Magnetic Field, Volodymyr Buturlim², Sabin Regmi, Idaho National Laboratory; Rubi KM, High Magnetic Field Laboratory, Los Alamos National Laboratory; Dariusz Kaczorowski, Polish Academy of Sciences, Poland; Neil Harrison, Los Alamos National Laboratory; Krzysztof Gofryk, Idaho National Laboratory

Due to its complex tetragonal crystal structure, with three distinct uranium sites, UP_2 stands out among other uranium dipnictides such as UAs_2 , USb_2 , and UB_2 . UP_2 exhibits antiferromagnetic ordering at ambient pressure with $T_N = 204$ K and an effective moment of $\mu_{\text{eff}} = 2.29 \mu_{\text{B}}/\text{U}$. The neutron scattering experiment indicates that the ordered moment is parallel to the $[0\ 0\ 1]$ direction and equals $2.0 \mu_{\text{B}}/\text{U}$. There is, however, a lack of information regarding the magnetic properties of UP_2 in high magnetic fields, particularly concerning its magnetic phase diagram. Here we present detailed experimental and theoretical studies of the magnetic properties of oriented high-quality single crystals of UP_2 . The measurements were performed at the High Magnetic Field Laboratory, Los Alamos National Laboratory, using pulsed magnetic fields up to 60 T. We will discuss details of the obtained phase diagram and its relationships to the localization/delocalization of 5f-electrons in this material.

3:45pm AC+MI-ThA-7 Properties of Carbon-Related Point Defects in Plutonium Oxides, Andrew Rowberg, Kyoung Eun Kwon, Scott Donald, Lawrence Livermore National Laboratory

Carbon is a ubiquitous impurity; therefore, investigating how it incorporates in materials is vital for understanding their properties, stability, and performance. Here, we evaluate the formation of carbon impurities in the most common stoichiometric plutonium oxides, PuO_2 and Pu_2O_3 , which has not been systematically studied to date. We use hybrid density functional theory calculations to compute formation energies and other relevant properties of carbon species in various configurations. We find the stability of carbon defects to be strongly dependent on charge state and oxygen coordination environments. Accordingly, these properties can influence the phase evolution between PuO_2 and Pu_2O_3 . We also evaluate the interactions between carbon and other defects present in these oxides.

4:00pm AC+MI-ThA-8 Vacancy-mediated Conduction Tunability in Epitaxial SmN, Kevin Vallejo, Volodymyr Buturlim, Zachery Cresswell, Brelon May, Brooke Campbell, Idaho National Laboratory; Bobby Duersch, University of Utah; Krzysztof Gofryk, Idaho National Laboratory

We establish the relationship between native N vacancies, introduced through varying growth parameters, and electronic properties of SmN thin films grown via molecular beam epitaxy grown on $\text{MgO}(001)$. We show substrate temperature having a larger impact on V_N formation during growth than the ratio of Sm to N atoms. We observe a transition from insulating to conducting behavior of the film over a range of two orders of magnitude, from highly resistive to highly conductive. X-ray photoelectron spectroscopy and room temperature electrical transport results confirm the rapid degradation of the film despite the presence of capping layers. A ferromagnetic feature in the film is shown through low-temperature resistivity measurements to be the onset of ferromagnetic behavior. These promising results indicate a path forward in the epitaxy of versatile materials able to provide monolithic integration of different electronic behaviors without the associated strain brought about by heteroepitaxial integration of dissimilar materials. The integration between SmN and several transition metal nitride compounds has the potential to unlock new electronic and spintronic device architectures with low strain barriers.

Atomic Scale Processing Mini-Symposium Room 206 A W - Session AP+PS+TF-ThA

Emerging Applications for Atomic Scale Processing (ALD/ALE) including Precursors and Surface Reactions

Moderator: Robert Bruce, IBM Research, T. J. Watson Research Center

2:15pm AP+PS+TF-ThA-1 ALD Thin Films for Protecting Limestone Cultural Heritage, Gillian Boyce, Suveena Sreenilayam, University of Maryland, College Park; Eleonora Balliana, Elisabetta Zendri, Università Ca' Foscari Venezia, Italy; Raymond Phaneuf, University of Maryland, College Park

From natural erosion to pollution-accelerated decay, stone cultural heritage deteriorates constantly through interactions with the environment. Common protective treatments such as acrylic polymers are generally prone to degradation and loss of performance, and they are often limited in

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their ability to achieve uniform and conformal coverage across a stone's topographical features. In this work, we report on the results of investigations of atomic layer deposited (ALD) amorphous alumina thin films for the protection of calcium carbonate substrates of a wide range of porosity against acid-based dissolution. The protective effects of the ALD coatings were investigated by aqueous acid immersion. The solution pH was tracked over time for a constant volume of acetic acid solution with an initial pH of 4 with the stone samples immersed. We find the protective effect of ALD alumina coatings is extremely promising, with 90 nm thick coatings slowing the average rate of pH evolution significantly, by between one and two orders of magnitude, depending on the porosity of the substrate. The eventual failure of the ALD coatings during immersion was also investigated, with the development of pits on the substrates, whose area fraction correlates to the changing pH of the acid solution during immersion. The variation of the protective action of the films with thickness is consistent with kinetics which are limited by diffusion within the pits, rather than through the films. Our findings point to the dominant role of defects in the thin films in their eventual failure.

2:30pm AP+PS+TF-ThA-2 Atomic Layer Depositionon Ceramic NanopowdersforPrecisely Engineered Microstructure of Sintered Ceramics, Eric Bissell, Alexandros Kostogiannes, Steve Lass, Anna Zachariou, Brian Butkus, Luis Tomar, Terrick Mcnealy-James, Ayelen Mora, Blaine Mauri-Newell, University of Central Florida; Nicholas Rudawski, University of Florida, Gainesville; Romain Gaume, Parag Banerjee, University of Central Florida

In this work, we have utilized the conformal nature and monolayer control of growth of ALD films to develop ≤ 10 nm, ultrathin diffusion barriers on the surfaces of ceramic nanoparticles. The barrier layer restricts grain growth during sintering leading to formation of bulk, nanocrystalline ceramics which demonstrate unique properties such as superior hardness and optical transparency, otherwise not achievable using traditional powder preparation and sintering steps.

Zinc oxide (ZnO) nanoparticles of 60 nm nominal diameter were coated with 1 or 10 nm of Al₂O₃in a custom-built, rotary ALD powder reactor. In situ mass spectrometry was used to end point the half-reaction pulse times. The powder was subsequently mixed at a 1:1 mass ratio with uncoated ZnO nanoparticles where the uncoated ZnO served as the 'control' sample undergoing the exact thermal and pressure cycling as the coated regions. The powder mixtures were subsequently compacted and hot pressed at 850 °C under uniaxial loading of 150 MPa. The sintered ceramics reveal that the 1nm and 10nm 'shell' Al₂O₃ layers effectively restrict grain size of the ZnO to 89 ± 23 nm and 55 ± 7 nm respectively, whereas the uncoated regions grow large polycrystalline grains of 601 ± 104 nm and 717 ± 80 nm respectively. The crystal structure analysis reveals ZnO in its thermodynamically stable wurtzite phase with no evidence of secondary phase formation. This study demonstrates the broad applicability of ALD based coating technology to the field of ceramics for fine microstructural control and precise tunability of bulk properties.

2:45pm AP+PS+TF-ThA-3 Hot-Wire-Assisted Atomic Layer Deposition of Transition Metals, Kyeongmin Min, Han-Bo-Ram Lee, Incheon National University, Republic of Korea

To replace conventional Cu interconnects, atomic layer deposition (ALD) of low figure-of-merit (FOM) materials such as cobalt (Co) and nickel (Ni) is crucial. While noble metals have been extensively studied as alternative interconnect materials due to their excellent performance, the high cost necessitates the development of low cost materials with superior properties. However, existing Co and Ni ALD processes inevitably require plasma to achieve high purity, leading to inherent limitations such as poor step coverage due to radical recombination and unavoidable damage to 3D structures caused by energetic ions and photons. In this study, we studied transition metal ALD processes using a hot-wire-activated counter reactant, enabling the deposition of high-purity films without generating energetic ions or photons. NH_x radicals were generated by exposing NH₃ counter reactant gas to a filament heated over 1300 °C. Due to the high thermal energy of the filament, NH₃ gas molecules dissociated into high energy radicals, which played a crucial role as reactants in the transition metal ALD processes. The concentration of NH_x radicals was studied as a function of the hot wire temperatures and correlated with the physical properties of films. The purity of transition metal films was analyzed using X-ray photoelectron spectroscopy (XPS) and Auger electron spectroscopy (AES). Based on the results of this study, we believe that the hot-wire-assisted ALD process can be widely utilized in various applications where overcoming the limitations of conventional plasma ALD is essential.

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3:00pm AP+PS+TF-ThA-4 Ni Thin Film Deposition Using Hot Wire ALD and Non-Halogen Precursor, Mruthunjaya Uddi, Mike Denchy, Prawal Agarwal, Josh Kintzer, Patryk Radyjowski, Advanced Cooling Technologies Inc.

Scale up of pure phase nickel (Ni) thin film deposition process for various applications of catalysis, microelectronics, chemical sensors, and MEMS, especially, using environmentally friendly non-halogen precursors is challenging. ALD is a variation of Chemical Vapor Deposition (CVD), with the complete metal deposition reaction broken into two half steps. Since each half-step saturates at a single atomic layer, a very precise control over deposition can be achieved. Although slower than CVD deposition rates, ALD can enable precise, uniform, conformal coating of Ni thin films. Recently, we assembled an automated Hot Wire Atomic Layer Deposition (HW-ALD) reactor and demonstrated Ni thin film deposition using a non-halogen precursor nickelocene and NH₃. The hot wire implementation enabled the non-halogen chemistry pathway. The details of reactor design, operation parameters and characterization of the Ni thin film deposited will be presented. Future experiments will involve large area (> 15 cm diameter) substrate coating with Ni thin films and the uniformity of distribution will be studied.

3:15pm AP+PS+TF-ThA-5 Pyroelectric Calorimetry for ALD, Ashley Bielinski, Argonne National Laboratory

A deeper understanding of the self-limiting surface reactions that make up ALD processes is vital for the development of many emerging applications such as area and site selective ALD processes that rely on chemical differentiation between a range of surface sites. Natural variation and defects in real surfaces necessitate in situ measurements of these surface reactions in order to develop a complete picture of the process. These in situ measurements can be combined with computational results on simplified model surfaces to help understand not only the single most favorable reaction pathways but also changes in the reactions as surfaces dynamically approach saturation and reactions on a realistic range of surface conditions.

Pyroelectric calorimetry can be used to quantitatively measure the heat evolved during an ALD surface reaction with high time resolution within a single saturating precursor reaction. This approach has been used to measure the reaction enthalpy of various ALD precursor reactions during the deposition of Al₂O₃, ZrO₂, and MgO. Analysis of the heat generation rate profiles of these processes in combination with techniques such as in situ spectroscopic ellipsometry and quartz crystal microgravimetry have provided insight into properties including multi-step reaction mechanisms and the driving role of entropy in certain reaction mechanisms. Recent hardware developments further enable measurements of precursor delivery and reaction kinetics. Knowledge of the mechanisms, thermodynamics, and kinetics of these reactions will guide the development of future ALD processes and provide the necessary parameters for the development of more complex and accurate computational models.

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3:30pm AP+PS+TF-ThA-6 Fabrication of Atomically-Precise Nanoimprint Masks by STM Lithography, James Owen¹, Ehud Fuchs, John Randall, Zvex Labs

The Semiconductor industry is struggling to continue to follow Moore's Law. For both technical and economic reasons, it is likely that the ASML High-NA Extreme Ultraviolet Lithography (EUV) tools will be the last photolithography technology to push to higher resolutions. Simultaneously, E-Beam Lithography (EBL) mask writers, while improving throughput by

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going highly parallel, are also very near the end of resolution improvements. The industry does not appear to expect any significant downscaling of devices beyond what will be possible with the ASML High-NA EUV tool which has a resolution of 8 nm.

The DOE Advanced Materials and Manufacturing Technologies Office (AMMTO) sponsored Semiconductor Industry Energy Efficiency Scaling (EES2) roadmap has identified EUV as a significant contributor to the energy budget of advanced digital electronics. Strikingly, EUV is so inefficient that only about 0.04% of the beam energy actually affects the resist. The EES2 roadmap proposes that replacing EUV with Nanoimprint lithography (NIL) would be a way to improve the energy efficiency of semiconductor manufacturing. NIL offers equal and better resolution and precision than EUV, with up to 90% lower energy costs, resulting in lower costs of production. However, NIL uses a mold of the pattern to be printed on the wafer as a mask and the best resolution of the current EBL mask writers is 15nm. Therefore, a mask writing technology with better resolution than EBL is required; it must provide resolution at least as good as the High NA EUV tool's 8nm to be widely adopted.

We describe a pathway towards unprecedented resolution in nanoimprint mask fabrication. Ultrahigh-precision NIL templates are made by writing sub-nm-precision patterns on Si(001) using Scanning Tunnelling Microscope(STM) lithography followed by selective growth via atomic layer deposition of a hard mask such as TiO₂, which is then used as an etch mask for Reactive Ion Etching to form a Si template, replicating the STM pattern. This template would then be transferred into a quartz template using existing step and flash NIL processes which will then be used to pattern devices on the die or wafer scale. We show that sub-10 nm feature sizes and full-pitch gratings with feature radius of curvature down to 1.5 nm in the lateral dimension are achievable, although the throughput is currently much too slow to be industrially feasible at the moment. This process therefore addresses the EES2 goal of improving the energy efficiency during manufacturing of digital electronics.

3:45pm AP+PS+TF-ThA-7 Three-In-One Isolation New Integration Solution for Monolithic CFET, Junjie Li, Longrui Xia, Institute of Microelectronics of the Chinese Academy of Sciences, China; **Mingmei Wang**, Lam Research Corporation

Introduction: Monolithic complementary transistors (CFET) will replace gate all around field-effect transistor (GAA FET) in technology nodes below 1nm [1]. CFET stacks N-type transistors on top of P-type transistors to reduce footprint and increase transistor density. Therefore, it is important to isolate the gate and source drain, as well as the gate of the upper and lower transistors. The current publicly available solution is to isolate the gate and source drain of the outer wall and inner wall, and isolate the gate of the upper and lower transistors with an intermediate isolation layer (MDI). This is achieved through three process steps, requiring at least three atomic layer deposition and atomic layer etching[2] (figure 1 of supplemental material). In order to simplify the process and reduce its difficulty, this article proposes a new process integration scheme that combines the above three steps into one deposition step and one etching step to achieve.

Results and Discussion :

Conclusion: We conducted a detailed comparison between the publicly available CFET process flow and the new process flow proposed in this article, as shown in Figure 2 f supplemental material, and ultimately successfully implemented a new three-in-one integrated solution of inner and outer side spacers and MDI. And demonstrated the results of key intermediate steps such as concave dummy gate and CH_x dummy gate self-aligned etching source drain.

Reference:

- 【1】 C. Cavalcante, VLSI, (2025).
- 【2】 T.Lill, VLSI (2025).

4:00pm AP+PS+TF-ThA-8 New Silicon-containing Precursors for Metal Silicide Films, **Sean Barry**, Dexter Dimova, Carleton University, Canada

Group 3 metals, particularly scandium and yttrium, offer tunable electropositivity when incorporated in thin films. They are attractive for next-generation microelectronic applications, including silicide and germanide thin films in gate-all-around FET architectures. However, suitable precursors for vapor phase deposition of lanthanide films remain scarce. In this work, we explore a new family of geminal diamidosilane (gDAS) ligands, designed for both homoleptic and heteroleptic coordination to Group 3 centers. These ligands provide modular steric control and enhanced volatility, allowing for the design of thermally stable precursors.

We report the synthesis and characterization of several Sc and Y complexes with methyl- and tert-butyl-substituted gDAS ligands. Thermogravimetric and isothermal analyses reveal decomposition pathways involving γ -hydride elimination, which is critical for understanding volatility and thermal stability in thin film deposition. Notably, Y(gDAS)₃ precursors exhibit promising volatility, while extended thermolysis suggests silicide incorporation may be feasible under atomic layer deposition conditions. We also demonstrate preliminary hydrogenation and dehydrocoupling strategies to prepare silicon-containing intermediates compatible with gDAS ligand frameworks. This presentation will show the groundwork for tailored ligand design strategies that enable selective, low-temperature deposition of lanthanide-silicon films.

4:15pm AP+PS+TF-ThA-9 Conversion-free Atomic Layer Etching of ZnO Using Hydrofluoric Acid and Trimethylgallium for Reduced Residues, **Taewook Nam**, Sejong University, Republic of Korea; **Steven George**, University of Colorado Boulder

Thermal atomic layer etching (ALE) is a crucial technique for advanced semiconductor manufacturing, offering precise material removal with sub-nanometer control. While various etching mechanisms exist, including the widely used fluorination-ligand exchange reaction, some materials are etched via a "conversion" mechanism where the original material is converted into a different compound before being removed. This conversion-based ALE, as seen in zinc oxide (ZnO) etching with hydrofluoric acid (HF) and trimethylaluminum (TMA), can leave undesirable residues of the converted material, Al₂O₃, on the surface, which is detrimental for fabricating high-performance, sub-nanometer scale devices.

In this study, we present a novel, conversion-free thermal ALE process for ZnO using HF and trimethylgallium (TMG) as precursors. This alternative chemistry was investigated using a suite of characterization techniques, including quartz crystal microbalance (QCM) and quadrupole mass spectrometry (QMS). ZnO films were initially grown via atomic layer deposition (ALD) using diethylzinc (DEZ) and water at 100°C. QCM measurements during the ALE process showed self-limiting mass gain during HF exposure and mass loss during TMG exposure, confirming the characteristic digital nature of the process. The etch rate was found to increase with temperature, reaching 3.82 Å/cycle at 300°C.

A significant advantage of the HF-TMG process is its ability to etch at temperatures as low as 30 °C, which is dramatically lower than the ≥ 240 °C required for the conventional HF-TMA process. This difference in temperature is attributed to the distinct reaction mechanisms of the metal precursors. While TMA exposure converts ZnO to Al₂O₃, enabling the subsequent unwanted deposition of AlF₃ during HF exposure, TMG exposure results in mass gain from precursor adsorption without conversion. The absence of this competing ALD reaction allows for effective, low-temperature ALE with HF-TMG. QMS analysis further supports this, showing no evidence of conversion and confirming a fluorination-ligand exchange mechanism.

The conversion-free nature of the HF-TMG process also leads to a notable reduction in residual contamination on the etched surface. X-ray photoelectron spectroscopy (XPS) confirms that the HF-TMA process leaves significant concentrations of both F (8.6 at.%) and Al (8.9 at.%) on the surface after ALE. In contrast, the HF-TMG process results in much lower residual concentrations of both F (1.1 at.%) and Ga (2.4 at.%).

MEMS and NEMS

Room 205 ABCD W - Session MN1-ThA

RF and Magnetic MEMS

Moderators: Robert Davis, Brigham Young University, **Sushma Kotru**, University of Alabama

2:15pm MN1-ThA-1 Control of Magnetoelastic Properties for Magnetoelectric Magnetic Field Sensors, **Margo Staruch**, US Naval Research Laboratory **INVITED**

The increasing demand for low SWaP-c magnetic field sensors has led to heightened interest in magnetoelectric MEMS and NEMS resonators. The direct coupling of the piezoelectric and magnetic phases allows for highly sensitive readoff of AC magnetic fields via an induced voltage. Dynamic sensing modalities, achieved by driving the piezoelectric phase at a resonance, have also been demonstrated to significantly decrease the noise floor and improve sensitivity. Much of the recent focus has been on maximizing the sensitivity of the resonant frequency to a field either through magnetoelastic effects or the ΔE effect. At NRL, efforts have been

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focused on fabricating clamped-clamped beam resonators with heterostructured AlN and magnetostrictive layers that operate at the fundamental bending mode. In this presentation, methods to improve the figures of merit including the piezomagnetic coefficient and the change in frequency with magnetic field (df/dH) through selection and control of the deposition of the magnetic phase will be explored. The impacts of boundary conditions and film stresses on the resonance behavior and the selection of the resonance modes will be established. Considerations of the development of shape anisotropy due to the high aspect ratio of the beams and resultant angular dependence of the sensitivity will emphasize the use of these resonating beams as vector magnetometers. Lastly, recent results on the limit of detection and noise floor of the sensors will be presented. Based on these results, design parameters for future packaged MEMS field sensors will be discussed.

2:45pm MN1-ThA-3 Low-Loss Wideband Nonreciprocal Magnetoacoustic RF Isolators Enabled by Non-Collinear Dipolar-Coupled Ferromagnetic Stack, Bin Luo, Department of Electrical and Computer Engineering, Northeastern University; **Andreas Winkler, Hagen Schmidt**, SAWLab Saxony, Leibniz IFW Dresden, Germany; **Vipul Sharma, Mingzhong Wu**, Department of Physics, Northeastern University; **Benyamin Davaji, Nian-Xiang Sun**, Department of Electrical and Computer Engineering, Northeastern University

Nonreciprocal RF isolators and circulators have enabled full duplex radio systems and protection of power amplifiers from back-reflections in high power microwave transmitters, greatly boosting the spectral efficiency and coordination in mesh or relay networks for modern wireless communication systems like 5G, IoT, and future 6G [2]. However, conventional RF isolators and circulators are bulky, expensive with high power consumption owing to CMOS-incompatible ferrites with high growth temperature in oxidizing environment and the need of permanent magnet/electromagnets for operation via Faraday rotation [2]. Recently, non-reciprocal magnetoacoustic RF devices exhibit substantial nonreciprocity with remarkable power efficiency and CMOS compatibility [1] [3-7]. They consist of a magnetic stack within the SAW path between two interdigital transducers (IDTs) on a piezoelectric substrate. By applying RF voltage on IDTs, the induced SAW propagates and interacts with spin waves in a magnetic stack. The magnon-phonon interactions lead to hybrid magnetoacoustic waves that exhibit a much higher backward loss rate than the forward one or vice versa [2]. Despite progress using various magnetic heterostructures, such as FeGaB/Al₂O₃/FeGaB [3, 4] and synthetic antiferromagnetic CoFeB/Ru/CoFeB stacks [6, 7], prior demonstrations often suffer from high insertion loss (>40 dB) due to the inefficiency of higher-order SAW harmonics. Additionally, devices with giant nonreciprocity often exhibit narrow bandwidths, and vice versa. Here we demonstrate a low-loss wideband non-reciprocal magnetoacoustic RF isolator based on a non-collinear dipolar-coupled ferromagnetic FeGaB/SiO₂/FeGaB stack driven by SAW fundamental mode at 2.87 GHz on 128° Y-X cut LiNbO₃ substrate (Figure 1). By intentionally misaligning uniaxial anisotropies in the two ferromagnetic layers (10° and 70° to k_{SAW}) using in-situ angled magnetic field depositions, multiple wideband nonreciprocity has been first realized from 2.48 to 3.15 GHz with reduced insertion loss (Figure 2). The maximum nonreciprocity reaches ~40 dB (200 dB/mm) near modulated SAW peaks, where standing waves enhance acoustic resonance. The device demonstrates a low insertion loss of ~13 dB off-resonance and ~25 dB on-resonance at 2.87 GHz, with ~10 dB nonreciprocity (33.3 dB/mm) (Figure 3). The ultra-compact, low-loss, wideband non-reciprocal, integrated magnetoacoustic isolator shows great potential for low power compact full-duplex radio/radar communication systems [2], efficient and coherent excitation of ground state NV⁻ centers [8] and nonreciprocal quantum information transfer in future magnon-phonon transducers [9].

3:00pm MN1-ThA-4 High-Q Diamagnetically Levitated Mechanical Resonators for Magnetic Field Sensing, Pooja Roy, Samira Yasmin, University of Central Florida; **Yunong Wang, Philip Feng**, University of Florida; **Jaesung Lee**, University of Central Florida

Diamagnetically levitated and trapped systems hold great promise in the development of high-performance, anchor-less resonant devices with excellent stability. This scheme generates sufficient levitation force via diamagnetism, enabling three-dimensional (3D) trapping at room temperature without external power input (Supplementary Fig. 1).

In this work, we combine theoretical analysis with experimental investigation to explore the complete levitation behavior and rigid body resonances of diamagnetically levitated graphite/dielectric composite

plates, ranging in size from millimeters to centimeters and in mass up to 680mg. These systems exhibit stable, clamping-free levitation with low energy dissipation and high quality (Q) factors, making them promising candidates for high-precision sensing applications.

The fabricated composite plates, in which graphite particles are embedded in a dielectric material (nonconducting epoxy), are diamagnetically levitated over permanent magnets (Supplementary Fig. 2). Their resonant performance is measured by using a laser interferometry system (Supplementary Fig. 3), where resonance motions of the plates are excited by simultaneously applying both AC and DC signals to the permanent magnets. A representative device with a mass of 34mg (Device 1) exhibits multiple resonant modes, including a primary resonance at $f=19.7\text{Hz}$ with $Q=7$ in air. Operating the devices in vacuum, significantly improves the Q factor to $Q=1400$ at 10mTorr and $Q=33,000$ at 0.6mTorr (Supplementary Fig. 4). A larger 680mg device (Device 2) shows a resonance at $f=20.35\text{Hz}$ with $Q=17,000$ at 24μTorr.

To evaluate frequency stability and resonant sensing performance, we implement Device 2 into a phase-locked loop (PLL), achieving an Allan deviation of $\sigma_A \approx 2.5 \times 10^{-8}$ at averaging time of $t=10\text{ms}$ (Supplementary Fig. 5). Upon applying a ~2mT magnetic field, we find clear resonance frequency shift; the device shows magnetic field sensing responsivity of 0.45Hz/T, with a sensitivity of 0.15mT/Hz^{1/2}.

This extensive experimental characterization manifests high- Q resonant levitated microsystems with significant mass and enhanced sensitivity, laying the foundation for advanced levitation technologies and the development of next-generation resonant sensors.

MEMS and NEMS

Room 205 ABCD W - Session MN2-ThA

Bio and Flexible/Wearable Devices

Moderators: Matthew Jordan, Sandia National Laboratory, **Margo Staruch**, Naval Research Laboratory

3:15pm MN2-ThA-5 Fabrication of Wearable Carbon Microelectrode Arrays for Bioimpedance, Robert Davis¹, Nick Allen, Sharisse Poff, Shiu-hua Wood Chiang, Brian Jensen, Richard Vanfleet, Brigham Young University Reusable, dry microelectrodes for bioimpedance measurements can enable wearable health monitoring devices. Here we demonstrate the fabrication of carbon composite microelectrode arrays designed specifically for wrist-based bioimpedance. Carbon electrodes are chemically inert and can form 3D structures for positive skin engagement. The electrodes were fabricated using carbon nanotube-templated microfabrication, in which patterned carbon nanotube forests were infiltrated with a nanocrystalline carbon matrix material to create a solid structure. The electrode material was tested for strength and wear resistance by three-point bending. The fabricated electrode arrays were mechanically and electrically adhered to pads on a flexible printed circuit (FPC) using an anisotropic conductive adhesive film, which was cured with pressure and heat. A controllable alignment and attachment technique was developed to simultaneously attach all electrodes in the array to the FPC. Human subject bioimpedance data verified that the electrodes were effective in measuring bioimpedance from 100 kHz to 200 MHz.

3:30pm MN2-ThA-6 3D Ultrablack Microstructures for Wearable Optical Spectroscopy, Bridgett Kemper², Woodson Parker, Brigham Young University; **Tyler Westover**, Octavian Solutions; **Richard Vanfleet, Robert Davis**, Brigham Young University

Miniaturized spectrometers could enable the application of spectroscopy in wearable devices such as fitness/health monitors. Here we will present the fabrication of miniaturized spectrometers with integrated carbon nanotube parallel-hole collimators for use in diffuse light spectroscopy. The microscale collimators are precise optical elements balancing low reflectance with low transmission through the high aspect-ratio carbon nanotube hedges that isolate the holes. The collimators are grown on a transparent fused silica substrate allowing the fragile collimators to remain on the transparent substrate for integration into optical systems.

¹ JVST Highlighted Talk

² JVST Highlighted Talk

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3:45pm MN2-ThA-7 A Tetrapolar Bioimpedance Sensor with Electropolymerized PEDOT:PSS Electrodes for Improved Stability in the Gastrointestinal Tract, *Mateo Lim, Justin Stine, Reza Ghodssi, University of Maryland College Park*

Inflammatory bowel diseases, such as Ulcerative Colitis and Crohn's disease, cause degradation of the mucosal barrier throughout the gastrointestinal (GI) tract. This leads to afflicted regions of intestinal tissue having higher permeability, increasing the uptake of undesired bacteria and exacerbating inflammation. Bioimpedance is a direct monitoring method that has been identified to relate tissue conductivity with alterations in permeability. Through integration of a bioimpedance sensor on the surface of an ingestible capsule, we can wirelessly measure impedance throughout the GI tract (Fig. S1a). However, adapting these sensors to maintain performance in the GI environment is challenging. Here, we present the fabrication of a tetrapolar impedance sensor with poly 3,4-ethylenedioxythiophene (EDOT) and polystyrenesulfonate (PSS) dopant (PEDOT:PSS) electropolymerized onto gold (Au) electrodes for minimal fouling in simulated GI fluids (Fig. S1b). The PEDOT:PSS film decreases electrode interfacial impedance while enhancing the charge transfer capability (CTC).

The Au electrodes are patterned onto a polyimide substrate with photolithography, electron-beam evaporation, and liftoff. The sensor is coated with a biocompatible Parylene-C layer to insulate the electrical traces, and the electrodes and contact pads are subsequently exposed using reactive ion etching (Fig. S2a). The electrodes are coated with a PEDOT:PSS film via chronopotentiometry (CP) using a BioLogic VSP potentiostat (current density: $5\mu\text{A}/\text{mm}^2$) for 180s in a solution of 10mM EDOT and 2M PSS (Fig. S2b). The CTC of bare Au and PEDOT:PSS electrodes were characterized using cyclic voltammetry (CV) in phosphate buffered saline (PBS), resulting in a 375-fold increase in current response for the PEDOT:PSS sensor (Fig. S3a). Sensor reliability and drift were verified using simulated gastric fluid (SGF, pH 1) and simulated intestinal fluid (SIF, pH 6.8) to represent the traversal through the GI tract. Electrochemical impedance spectroscopy (EIS) measurements from 100Hz to 100kHz were recorded at 5-minute intervals over 90 minutes with the EVAL-AD5940BIOZ development kit while the sensor was immersed in the GI fluids. Overall, the impedance measurement remained invariant with frequency; hence, 10kHz was selected for analysis. The average impedance over time was observed to increase at 7.6%/hr and 0.04%/hr for SGF (Fig. S3b) and SIF (Fig. S3c), respectively. These results demonstrate minimal sensor degradation over prolonged exposure to GI fluids, marking an important step towards realizing non-invasive bioimpedance sensing in the GI tract.

4:00pm MN2-ThA-8 Development of Ingestible Capsule Technologies for Sensing Gut Serotonin Toward Understanding the Gut-Brain Axis, *Sydney Overton, Michael Straker, Reza Ghodssi, University of Maryland, College Park*

Serotonin (5-HT) is a biomarker of the gut-brain axis (GBA), regulating neurological and gastrointestinal (GI) functions such as mood and GI motility. Notably, 95% of 5-HT is produced in the GI tract and secreted below the epithelium. Furthermore, 5-HT is implicated in GI and neurological diseases, motivating interest in understanding 5-HT dynamics for diagnostics, treatments, and unveiling the underlying pathways of the GBA. However, research insights have been limited by the absence of appropriate tools for quantifying 5-HT in the gut. Here we present a system engineering approach to address this critical technology gap using ingestible capsules. We report the miniaturization of an electrochemical biosensor and integration with a meso-scale electromechanical actuator to create a module for real-time quantification of subepithelial-5-HT (Fig. S1).

Our novel biosensor for penetrating the GI epithelium and measuring underlying 5-HT features a surface-modified carbon fiber microelectrode (CFME) working electrode and a quasi-reference/counter electrode (QRCE). Fabricated using additive manufacturing and microfabrication, the QRCE incorporates four 3D-printed microneedles (MN) with $60\mu\text{m}$ sharpness and is functionalized via electron-beam deposition. Directly assembling the biosensor in a micromotor-driven cam and follower (CnF) mechanism simplifies assembly, resulting in a more compact module. Future integration with custom printed circuit board (PCB) electronics would enable precise control of actuation and electrochemical measurements, while biocompatible packaging ensures safe traversal through the GI tract.

We modeled the integrated biosensor-CnF using dynamic simulation to estimate actuation time and displacement of the follower, demonstrating a

total displacement of 1.0mm at a cam angle of 45.8° . Next, we demonstrated the repeated actuation of the CnF, where the biosensor was displaced outside the capsule $823\pm28\mu\text{m}$ in 0.3s, dwells for 5s for an electrochemical measurement, then returns inside the capsule shell (Fig. S2e). Subsequently, we measured the CnF's actuation force to be $3.85\pm0.1\text{mN}$, which is 10x greater than the 0.3mN insertion force of the biosensor previously characterized (Fig. S3a-b). To validate the biosensor, cyclic voltammetry (CV) was conducted in Agar GI tissue phantoms spiked with $10\mu\text{M}$ 5-HT. The resultant peak oxidation current of $0.1\mu\text{A}$ at 0.4V compared to a PBS control confirmed the electrochemical detection of 5-HT (Fig. S3c). By integrating MEMS biosensing and meso-scale actuators into a compact module, we have demonstrated the first step towards an ingestible capsule capable of detecting micromolar concentrations of 5-HT.

Plasma Science and Technology

Room 201 ABCD W - Session PS+AIML-ThA

Plasma Modelling AI/ML

Moderators: *Kenji Ishikawa, Nagoya University, Japan, Angelique Raley, TEL Technology Center, America, LLC*

2:15pm PS+AIML-ThA-1 Machine Learning for Low Temperature Plasma Applications, *Abhishek Verma, Kallol Bera, Shahid Rauf, Applied Materials, Inc.* INVITED

Low temperature plasmas are used for numerous depositions and etch applications in the semiconductor industry. The field is rapidly advancing driven by volumes of multimodal and complex spatiotemporal data from both experiments and simulations. Machine learning in combination with plasma modeling and simulation offers a wealth of techniques that could play key role in plasma source discovery, design and decision making. These techniques can also augment domain knowledge for plasma reactor control and process development. In this talk, we present our work on machine learning applications to modeling, control, and optimization of plasma chambers. To overcome the challenge of high computational cost associated with high fidelity plasma models for rapid and many-query analyses, we present a deep learning based non-linear surrogate modeling method. Our numerical experiments on capacitively coupled plasmas show that deep learning-based model can learn an efficient latent space representation of spatiotemporal features of plasma characteristics. Moreover, we extended this approach with physics informed neural networks to improve predictive accuracy and generalization while being data efficient. Physics informed approaches could also effectively incorporate expert knowledge while learning physics implicitly. Furthermore, we present application of regression methods for circuit estimation of collisional sheath in moderate pressure capacitively coupled plasmas. The novel sheath model which includes collisional effects, ion current responses to sheath voltage and harmonics based resistive elements, builds on parametric flexibility using machine learning while maintaining interpretability. The talk outlines machine learning methodologies for modeling, optimizing, and controlling plasmas for semiconductor applications.

2:45pm PS+AIML-ThA-3 Contour-Based Objectives for Robust Etch Model Selection, *Chad M. Huard, Prem Panneerchelvam, Shuo Huang, KLA; Lewis Hill, Janet Hopkins, KLA UK; Mark D. Smith, KLA*

As device scaling increasingly relies on 3D rather than CD scaling, etch has become a critical and challenging step, often limiting further scaling. The demand for high-quality, predictive etch models is growing, yet our understanding of surface mechanisms during dry etching remains limited. Techniques like XPS, SIMS, and AES provide clues to surface reactions, but the pathways are not immediately clear. First-principles computational methods such as DFT, quantum MD, and classical MD offer insights but are constrained by computational resources and turnaround times. We present a Monte Carlo profile model that bridges the gap between first-principles and empirical models by using simplified chemistry mechanisms calibrated with experimental data. Traditional models often rely on 'best-effort' mechanisms, risking calibration issues due to high dimensionality or model errors due to omission of critical pathways. We propose a unified method for evaluating etch mechanisms using rigorous contour-based objectives, which maximizes entitlement from metrology data and results in better model development/selection compared to gauge-based metrics. This approach identifies the simplest model that fits the data, addresses degeneracy in models and calibration objectives, and enhances model predictiveness.

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3:00pm PS+AIML-ThA-4 NAND Pillar Etch: Plasma and Feature Profile Modeling in Dry Etch Process, *Harutyun Melikyan, Ebony Mays, NAND Pathfinding - Micron Technologies; Ali Bhuiyan, Sumeet Pandey, Advanced Modeling - Micron Technologies; Jagannath Mahapatra, Micron Technologies, USA*

In this work we developed a model to study the Feature Profile Modeling (FPM) in the dry etch plasma process for NAND pillar etch. The model developed takes in process parameters, that is process knobs such as temperature, pressure, flowrates, Power, Frequency, Voltage as inputs. The output from the model is Feature profile information such as Etch rate, Etch Depth, Variation of CD with height, Twisting, Ellipticity, Necking (HM), Bowing (ONO) etc. This methodology makes possible the ability to correlate process knobs on an equipment directly to the feature profile. This can enable us to get a detailed sensitivity analysis of feature profile with respect to process knob on the equipment (like constructing a sort of digital twin for that equipment). In addition, the feature profile (for HAR) for the future nodes can be inferred from process knobs and recipe information even before running the experiments.

3:15pm PS+AIML-ThA-5 Machine Learning of Simulated Nanosecond UV Laser Ablation Plumes, *Jacob Paiste, University of Alabama at Birmingham; Sumner Harris, Oak Ridge National Laboratory; Shiva Gupta, University of Alabama at Birmingham; Eric Remington, Samford University; Robert Arslanbekov, CFDRC Research Corporation; Renato Camata, University of Alabama at Birmingham*

Laser-generated plasmas are a rich laboratory of complex spatiotemporal phenomena emerging from coupled thermodynamic, electromagnetic, and quantum mechanical processes. The strength of laser-solid and laser-plasma interactions can vary over multiple orders of magnitude while gradients of density, temperature, and flow velocity give rise to shocks, instabilities, and turbulence in multiphase flows. Deep learning can be used to encode these complex spatiotemporal dynamics to discover correlations between the conditions under which a laser-generated plasma is produced—including the wide chemical and thermophysical diversity of ablation targets—and the resulting plasma flows. Predictive models can then be built to infer the fundamental properties of irradiated solids and plasmas, enabling a new experimental modality for measuring material properties like thermal conductivity or critical temperature. However, no databases of experimental or simulated laser-generated plasmas currently exist, so proof-of-concept for the efficacy of deep learning for this task is difficult to obtain.

In this work, we carry out a deep learning study on synthetic laser-generated plasma data. The synthetic data sets are produced using a combined laser ablation-fluid dynamics simulation based on the Hertz-Knudsen model, including phase explosion when a target temperature exceeds the thermodynamic critical temperature. The model is implemented on an open-source Adaptive Cartesian Mesh framework that enables laser ablation plume simulations out to centimeter distances over tens of microseconds for any elemental material with well-defined thermophysical parameters.

We generate a training dataset by simulating UV nanosecond pulsed laser ablation of elemental targets of Be, B, Na, Mg, Al, Sc, Ti, V, Fe, Co, Cu, Zn, Rb, Cs, Ta, W, and Pt with systematic variation of laser fluence (1–10 J/cm²) and laser spot area (0.8–13 mm²). We use (2+1)D convolutional neural networks (CNNs) to encode spatiotemporal plume dynamics for regression and classification problems using our simulated data. Results indicate that given a plume image sequence and associated laser parameters, we can not only predict which element the plasma was generated from with high confidence but also predict the set of thermophysical properties of the material. These results serve as proof-of-principle for plasma plume dynamics as strong predictors of fundamental material properties and motivate new experimental measurement techniques using laser ablation.

4:00pm PS+AIML-ThA-8 PSTD Business Meeting & Awards Ceremony,

Surface Science

Room 209 CDE W - Session SS-ThA

Late Breaking Discoveries from the Rising Stars in Surface Science

Moderator: *Nan Jiang, University of Illinois - Chicago*

2:15pm SS-ThA-1 Molecular Nanosystems at Interfaces, *Johannes Barth¹, TU Munich, Germany* INVITED

The utilization and organization of molecular species is an important issue for advancing nanoscale science and underpins the development of novel functional materials. To this end we explore molecular bonding and assembly at well-defined homogenous surfaces, textured templates, nanoelectrodes and 2D-sheet layers. The developed bottom-up fabrication protocols employ tailored building blocks and exploit both supramolecular engineering and on-surface covalent synthesis. Structure formation, chemical conversions, electronic and other characteristics are addressed by a multitechnique experimental approach, whereby scanning probe microscopy provides molecular-level insights that are frequently rationalised with the help of computational modeling. We work toward a rationale for the control of single molecular units and the design of nanoarchitectures with distinct functional properties.

3:15pm SS-ThA-5 THz-Induced Metastability and Atomic-Scale Dynamics of Local Charge Order in 1T-TaS₂, *Melanie Müller²³, Fritz Haber Institute of the Max Planck Society, Germany*

Light-induced control of quantum materials has opened new frontiers in condensed matter physics, enabling the manipulation of electronic and structural phases on ultrafast timescales. While time-resolved pump-probe techniques provide insight into these dynamics, they typically lack the spatial resolution needed to probe atomic-scale variations arising from defects, heterogeneity, or domain boundaries.

Recent advances in ultrafast scanning tunneling microscopy (STM) have enabled real-space imaging of ultrafast dynamics with angstrom resolution. In particular, THz-lightwave-driven STM (THz-STM) has emerged as a powerful tool [1,2] for probing femtosecond carrier dynamics, molecular vibrations, and collective excitations at the sub-nanometer scale. However, applying THz-STM to quantum materials with easily perturbed ground states remains challenging, as it requires STM operation under intense localized THz fields that can strongly perturb the system. This is especially critical in layered materials such as 1T-TaS₂, where electron-phonon coupling, electron correlations, and stacking-dependent charge order render the system highly sensitive to external perturbations.

I will present THz-STM of the ultrafast dynamics of local charge order in the layered transition metal dichalcogenide 1T-TaS₂. At low temperatures, 1T-TaS₂ exhibits a commensurate charge density wave (CDW) phase with an insulating gap that arises from a complex interplay of electron correlations and interlayer orbital interactions. Starting from the C-CDW ground state, we demonstrate that THz excitation in the STM drives 1T-TaS₂ into a metastable state (MS) with a modified quasi-stationary insulating gap, which we assign to a THz-driven modification of the interlayer stacking order. On top, THz-lightwave-driven tunneling allows to probe the photoinduced dynamics of the collective charge order within the MS. In particular, coherent oscillations in the THz-driven tunnelling current reveal the 2.45 THz amplitude mode of the CDW, which persists in the MS. In addition, we find an unknown 1.36 THz mode that emerges near a local defect, which can be assigned to an interlayer shear mode which coherently modulates the interlayer orbital overlap and the low-energy states in 1T-TaS₂.

These results highlight the dual role of the tip-enhanced THz fields in THz-STM, both as a driver of metastability and for probing local ultrafast dynamics, and highlight the influence of defects on the dynamics of local charge order.

3:30pm SS-ThA-6 Plasmonic Probes for Liquid-Phase Tip-Enhanced Raman Spectroscopy, *Naihao Chiang⁴⁵, University of Houston*

Tip-enhanced Raman spectroscopy (TERS) combines the chemical specificity of surface-enhanced Raman spectroscopy (SERS) with the

¹ Surface Science Keynote Lecture

² JVST Highlighted Talk

³ Rising Star in Surface Science

⁴ JVST Highlighted Talk

⁵ Rising Star in Surface Science

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unmatched spatial resolution of scanning probe microscopy (SPM). During the last few years, there has been an explosion of interest and activity in nanoscale vibrational spectroscopy. One of the key factors for successful TERS implementation is the quality of the plasmonic probes used. Electrochemically etched silver or gold tips are commonly used in scanning tunneling microscopy (STM) -based TERS, and sub-nanometer chemical mappings of single-molecule have been demonstrated under ultrahigh vacuum conditions.

We are developing plasmonic probes for scanning ion-conductance microscopy (SICM) and electrochemical STM (EC-STM) to extend TERS into the liquid phase. For SICM-TERS, quartz nanopipettes (<100 nm) were sputter-coated with silver or gold under high vacuum. SERS of small molecules directly tethered on the plasmonic nanopipettes were used to optimize the fabrication parameters. For EC-STM-TERS, electrochemically etched probes were coated with commercial ultraviolet (UV) cured polymers, aiming for a better chemical resistance and lower background signal compared to conventional nail-polish coatings. In the future, we expect these liquid-phase TERS probes to provide chemical information at interfaces relevant to the emerging catalysis, energy, and bioengineering applications.

3:45pm **SS-ThA-7 Surface Science Reception**,

Thin Films

Room 206 B W - Session TF+CPS+MS+EM-ThA

Thin Films for Microelectronics II

Moderators: Lauren Garten, Georgia Institute of Technology, Christophe Vallee, University at Albany

2:15pm **TF+CPS+MS+EM-ThA-1 Area Selective Deposition Processing in the Memory Industry: How to Take Advantage of the High-Volume Manufacturing Environment**, Francois Fabreguette, Jeff Hull, Huicheng Chang, Erik Byers, Gurtej Sandhu, Micron Technology **INVITED**

Aggressive scaling from node to node in the memory industry has led to a paradigm shift towards Area Selective Deposition (ASD) technique to overcome traditional processing challenges. For example, punches or etches not being capable anymore in High Aspect Ratio structures $>100:1$ can be replaced by selective deposition processes on the sidewall only, eliminating the need to clear a bottom contact. Likewise, ASD can be used to heal a contact seam that can easily form when the deposited metal pinches off at the top of a High-Aspect ratio structure, leaving void in the middle of the filled contact. Finally, in tiered structures used for 3D memory scaling, ASD allows for dielectric re-deposition on one tier type selective to the other tier type for cell sculpting without any critical dimension penalty. The present abstract covers a few examples of ASD processes developed in Micron High Volume Manufacturing environment: The state-of-the-art 300mm wafer tooling capability as well as multiple full-wafer inline metrology techniques (such as X-Ray fluorescence, X-ray Photoelectron Spectroscopy, X-Ray Reflectivity, Ellipsometry, Atomic Force Microscopy) allows to characterize the loss of selectivity on the non-growth surfaces on wafer-level. This provides across-wafer inhibition efficiency, which is critical for Area Selective Deposition future adoption in large scale production. The case study of ASD TiN using new high-temperature oxide inhibitors is presented. The systematic inline metrology characterization of the inhibited blanket oxide surfaces after TiN deposition at various temperatures is used to determine the best selectivity conditions as well as individual inhibitor performance benchmarked to the best-known oxide inhibitor typically used in the ASD community. Besides, Fourier Transform Infrared (FTIR) spectroscopy, Water Contact Angle measurements (WCA) and carbon content from XPS measurements were performed immediately after inhibition. They provided the surface signature of each inhibitor and were correlated to their overall inhibition efficiency.

2:45pm **TF+CPS+MS+EM-ThA-3 BEOL-compatible (≤ 300 °C) top-gate $\text{HfO}_2/\text{ZnSnO}$ Transistors Enabled by Atomic Layer Deposition for Advanced Memory Integration**, Changyu Park, Jinsung Park, Joohee Oh, Hyoungsub Kim, Sungkyunkwan University, Republic of Korea

Amorphous oxide semiconductors (AOSSs) are promising channel materials for three-dimensional (3D) dynamic random-access memories (DRAMs) owing to their structural uniformity from a stable amorphous phase, low-temperature processability, and extremely low off-state current enabled by their wide bandgap [1]. Atomic layer deposition (ALD) further enhances their applicability by offering conformal coverage in high-aspect-ratio

structures and high film quality at low processing temperatures. Among the various AOSSs, zinc tin oxide (ZTO) is particularly attractive due to its efficient carrier transport, facile composition tunability, reliance on earth-abundant elements, and high thermal stability [2]. For back-end-of-line (BEOL) integration in 3D DRAM, ZTO must be combined with ALD-grown high-k dielectrics in top-gate architectures; however, most previous studies have primarily focused on bottom-gate thin-film transistors (TFTs) [3,4].

In this work, we demonstrate the fabrication and characterization of top-gate TFTs with ZTO channels and HfO_2 gate dielectrics, both integrated via ALD at temperatures up to 300 °C for BEOL-compatible processing. Guided by the ALD growth behavior of ZnO and SnO_2 , ZTO films with various compositions were deposited using a super-cycle method with diethylzinc (DEZ) and tetrakis(dimethylamino)tin(IV) (TDMASn) at 250 °C, employing ozone (O_3) as the oxidant. After annealing of the ZTO channel at 300 °C for 1 h in ambient air, indium tin oxide source/drain electrodes were formed. The HfO_2 gate dielectric was subsequently deposited via ALD using O_3 at 230 °C. The extracted average parameters of top-gate TFTs with an optimized ZTO composition confirmed their suitability for DRAM cell operation, exhibiting a threshold voltage (V_{th}) of 0.15 V, a saturation mobility of $4.3\text{cm}^2/\text{V}\cdot\text{s}$, a subthreshold swing of $76\text{mV}/\text{dec}$, and an on/off current ratio exceeding 10^7 . Device reliability was further evaluated through positive and negative bias stress tests at ± 3 MV/cm, resulting in V_{th} shifts of $+0.47$ V and -0.12 V, respectively, which are comparable to recent reports on bottom-gate device configuration [3].

[1] A.R. Choi *et al.*, *Chem. Mater.* **36**, 2194 (2024)

[2] B. Lu *et al.*, *Curr. Opin. Solid State Mater. Sci.* **27**, 101092 (2023)

[3] J. Choi. *et al.*, *ACS Appl. Electron. Mater.* **7**, 215 (2025)

[4] J.S. Hur *et al.*, *Nanoscale Horiz.* **9**, 934 (2024)

3:00pm **TF+CPS+MS+EM-ThA-4 Photoluminescence Spectroscopy of Ultra-Thin GeSn Alloys Grown on Ge-on-Si Substrates**, Vijay Gregory, Lia Guo, Jay Mathews, University of North Carolina at Charlotte

Silicon (Si) based devices have dominated the electronics industry over the past decades but are not suitable for making lasers due to their optical properties. As an indirect bandgap semiconductor, Si has inefficient optical emission and therefore cannot be used to make a light source on a Si chip. As an alternative, germanium (Ge), incorporated with tin (Sn), can be grown on Si and is currently being used for photonic devices. GeSn exhibits direct bandgap emission at room temperature and is ideal for an on Si light source. However, they suffer from low intensity due to high defect densities which cause nonradiative recombination.

In this work, we study GeSn/Ge/Si samples with varying percentages of Sn. The materials were grown with sub 100 nm thickness resulting in fully strained thin films which reduce the dislocations caused by lattice relaxation. The emission spectrums of these ultra-thin layers were measured using photoluminescence (PL) spectroscopy to probe the quality of the materials as on Si light sources.

3:15pm **TF+CPS+MS+EM-ThA-5 Highly Ordered NiO (111) Films on Sapphire Substrates via Low-Temperature Hollow Cathode Plasma-ALD and Their Post-Deposition Annealing Characteristics**, Fatih Bayansal, Steven Allaby, Habeeb Mousa, Helena Silva, Necmi Biyikli, University of Connecticut

Nickel oxide (NiO) is a promising p-type wide band gap semiconductor material for next generation optoelectronic and energy devices. In this study, the growth process and thermal annealing behavior of NiO thin films grown on c-plane sapphire substrates by hollow-cathode plasma-assisted atomic layer deposition (HCP-ALD) method were investigated. NiCp_2 was used as the nickel precursor heated at 100°C , and O_2 plasma was preferred as the oxidizing agent under 100W rf-power and 20 sccm flow rate. The films were grown within a substrate temperature range of 100 – 250°C .

The obtained film samples showed high transmittance in the visible spectrum and exhibited strong absorption in the UV spectrum. Optical band gap values determined by Tauc analysis were found between 3.54 and 3.59eV . The refractive indices increased with the growth temperature and reached 2.38 , while the extinction coefficient and film porosity decreased for higher temperature films. X-ray diffraction (XRD) analyses revealed that the films exhibit a highly textured structure with exclusive (111) orientation. No peaks belonging to any other phase or crystal plane were observed. Moreover, grazing incidence XRD (GIXRD) measurements showed no detectable peaks, confirming the monocrystalline film character, and suggesting a surface-parallel alignment and potentially dense and thin film

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morphology. In addition, shifts in the diffraction peaks were observed depending on the growth temperature.

In order to evaluate the thermal stability and performance of the films, the samples grown at 250°C were annealed at 300, 350 and 400°C. Ongoing studies include characterization of electrical properties (Hall effect) such as carrier density, mobility and conduction type as well as crystal structure (XRD, TEM) and chemical composition (XPS). This holistic approach will contribute to understanding the impact of post-deposition annealing on the crystal quality and charge transport properties of NiO films.

This work contributes to the development of optimized p-type oxide semiconductors for transparent electronics and heterojunction-based devices through controlled low-temperature ALD process and post-deposition thermal engineering.

3:30pm TF+CPS+MS+EM-ThA-6 Textured Growth and Electrical Characterization of Zinc Sulfide on Back-End-of-the-Line (BEOL) Compatible Substrates, Claire Wu, Mythili Surendran, Anika Priyoti, Gokul Anilkumar, University of Southern California; Chun-Chen Wang, Taiwan semiconductor Manufacturing Company, Taiwan; Cheng-Chen Kuo, Cheng-Hsien Wu, Taiwan Semiconductor Manufacturing Company, Taiwan; Rehan Kapadia, University of Southern California; Xinyu Bao, Taiwan Semiconductor Manufacturing Company, Taiwan; Jayakanth Ravichandran, University of Southern California

Scaling of transistors has enabled continuous improvement in the performance of logic devices, especially with recent advances in materials engineering for transistors. However, there is a need to surpass the horizontal limitations in chip manufacturing and incorporate the vertical or third dimension. To enable monolithic three-dimensional (M3D) integration of high-performance logic, one needs to solve the fundamental challenge of low temperature (<450 °C) synthesis of high mobility n-type and p-type semiconductor thin films that can be utilized for fabrication of back-end-of-line (BEOL) compatible transistors.¹ Transition metal oxides are promising n-type materials; however there is a lack of p-type materials that can meet the stringent synthesis conditions of BEOL manufacturing. Zinc sulfide (ZnS), a transparent wide band-gap semiconductor, has shown room temperature p-type conductivity when doped with copper² and crystallizes below 400°C when grown by pulsed laser deposition (PLD).³ Here, we report growth of crystalline thin films of ZnS by PLD on a variety of amorphous and polycrystalline surfaces such as silicon nitride, (SixNy) thermal silicon dioxide, (SiO₂), hafnium dioxide, (HfO₂), yttrium oxide (Y2O₃), platinum, sapphire (Al₂O₃), and titanium nitride (TiN). X-ray diffraction shows texturing of ZnS on all surfaces, including when ZnS is directly grown on HF buffered oxide etched silicon. Crystalline quality is investigated using grazing incidence wide angle X-ray scattering measurements. Surface and interface quality is measured using X-ray reflectivity and atomic force microscopy measurements. Electrical characterization of the ZnS films is done by J-V measurements of ZnS on platinum and metal-oxide-semiconductor capacitor (MOSCAP) measurements of ZnS on SiO₂ on heavily doped silicon. The J-V measurements indicate low leakage current on the order of 10-8 A/cm² with electric field of 0.013 MV/cm² and the MOSCAP characteristics show bilayer capacitor behavior, which points to ZnS being highly intrinsic with very low unintentional, electrically active point defects. Further work on doping ZnS with copper or other p-type candidate dopants are needed to demonstrate ZnS as a dopable wide band gap semiconductor for channels compatible with BEOL manufacturing. This work showcases the capability of novel thin film growth technique of a wide band-gap sulfide semiconductor in BEOL compatible conditions with potential for technological applications in transistor manufacturing.

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- 2.R. Woods-Robinson et al., Adv. Electron. Mater. 2, 1500396 (2016)
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3:45pm TF+CPS+MS+EM-ThA-7 Thermal Atomic Layer Deposition of Molybdenum Phosphide Films, John D. Hues, Wesley Jen, Nolan Olaso, Steven M. Hues, Elton Graugnard, Boise State University

Aggressive scaling of semiconductor technology nodes has led to copper-based interconnects beginning to approach the maximum scaling limit of the material, beyond which unacceptably high increases in interconnect resistance due to electron scattering at grain boundaries and interfaces begins to cause degradation of device performance. New materials are required for interconnect applications beyond the 7 nm node to produce devices with acceptable signal delay and power consumption parameters. Topological semimetals are one family of materials that are of interest for the replacement of copper in interconnect applications due to the

predicted favorable resistance scaling, which results from topologically protected surface states that suppress electron scattering and act as conduction pathways in nanoscale films. This decrease in interconnect resistance has the potential to improve the efficiency of integrated circuits through reduced RC delay and reduced energy consumption, which is under increased scrutiny due to increasing computing demands, such as generative artificial intelligence and cloud computing. In order to aid in the integration of these promising materials into production environments, scalable synthesis methods, such as atomic layer deposition (ALD), are needed. In addition to the development of deposition chemistries for these materials, insight into how processing conditions impact the performance of the resulting film are also of importance. Here, we report on a new thermal ALD deposition chemistry for molybdenum phosphide (MoP) using molybdenum(V) chloride (MoCl₅) and tris(dimethylamino)phosphine (TDMAP) at temperatures between 350 °C and 425 °C. In-situ and ex-situ characterization of the resulting films was performed using quartz crystal microbalance (QCM), x-ray photoelectron spectroscopy (XPS), x-ray diffraction (XRD), atomic force microscopy (AFM), scanning electron microscopy (SEM), and four-point probe measurements. QCM measurements demonstrated a linear mass increase of 164 ng/cycle at 375 °C. Film deposition was confirmed through XRD and XPS chemical state analysis. The resulting films were near stoichiometric as determined via XPS. AFM and SEM characterization revealed a polycrystalline morphology with nanoscale grain sizes. Four-point probe measurements of the as-deposited films indicated non-ideal electrical performance which was subsequently improved through post deposition annealing. Although more work is needed to improve electrical performance, this new ALD chemistry may provide a method for the deposition of MoP films at the dimensions required for next generation technology nodes.

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2D Materials

Room Ballroom BC - Session 2D-ThP

2D Materials Poster Session

2D-ThP-1 Molecular Beam Epitaxy Synthesis and Characterization of 2D

InSe, *Emily Toph, Eric Vogel, Georgia Institute of Technology; Brent Wagner, Georgia Tech Research Institute*

InSe, a monochalcogenide two-dimensional (2D) semiconductor¹ with a large room-temperature electron mobility of approximately $10^3 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$, is a promising material for high-sensitivity Hall sensors², ballistic transistors,³ and non-volatile memory applications.⁴ The In-Se system contains many different stable phases⁵ including selenium rich In_2Se_3 and selenium deficient In_4Se_3 phases. The synthesis of InSe is challenging due to the narrow stability range of its stoichiometry on the phase diagram and the need for a surface morphology with large grain lateral growth. Therefore, synthesizing high-quality InSe requires a detailed understanding of how the synthesis parameters affect the structure and stoichiometry of In_{x}Se_y thin films near and within the narrow range of stability for InSe.

The growth of 2D InSe thin films has been achieved using a novel molecular beam epitaxy (MBE) two-step method involving an indium precursor layer, which effectively suppresses the formation of unwanted phases and allows for high-quality films.⁶ This work builds upon this novel approach by investigating how synthesis parameters, including substrate temperature, precursor flux, and deposition time influence the structural and stoichiometric properties of InSe thin films deposited on sapphire substrates. The chemical bonding, crystalline structure, and morphology of the thin films are characterized by X-ray Photoelectron Spectroscopy, Raman spectroscopy, X-ray diffraction and Atomic Force Microscopy. By understanding how these synthesis parameters impact film quality, the optimal synthesis conditions for InSe thin film deposition can be further refined, enhancing the potential for device applications.

References

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2D-ThP-3 Charge Transfer States at the Monolayer WS₂/HAT-CN Interface,

Xu He, Antoine Kahn, Princeton University

Understanding how WS₂ interacts electronically with organic molecules is very important for hybrid optoelectronics and energy harvesting applications, where charge separation at the interface governs device function. In this work, we investigate a heterojunction between monolayer WS₂ and 1,4,5,8,9,11-hexaaazatriphenylene hexacarbonitrile (HAT-CN) to study energy level alignment and interfacial charge transfer.

The combined ultraviolet photoelectron spectroscopy and inverse photoemission spectroscopy (UPS/IPES) measurements show that the pristine monolayer WS₂ has an ionization energy (IE) of 6.00 eV and an electron affinity (EA) of 3.44 eV with a 2.56 eV electronic gap, while films of pristine HAT-CN show an IE of 9.48 eV and EA of 5.66 eV with a 3.82 eV electronic gap. These values suggest a type-II energy level configuration at the interface, providing an energetic driving force for electrons to transfer from WS₂ into HAT-CN.

Raman and Photoluminescence (PL) spectroscopies, and X-ray photoelectron spectroscopy (XPS) were performed on 1L-WS₂ with 0, 3.75, 7.5, and 15nm HAT-CN thicknesses. The Raman signature of WS₂ remains consistent across different thicknesses of HAT-CN, suggesting that the WS₂ lattice remains intact despite HAT-CN presence. XPS confirms HAT-CN adsorption on WS₂. PL spectra reveal a >90% quenching of the intrinsic WS₂ emission at around 633nm after HAT-CN deposition without visible PL peak shift. This significant PL quenching indicates the formation of a charge transfer (CT) state at the interface. The large difference in electronic gaps of 1L-WS₂ and HAT-CN suggests that it is not a Frenkel energy transfer. A device with mechanically transferred 1L-WS₂ and HAT-CN is being constructed and tested for photocurrents. We expect to see an external quantum efficiency (EQE) spectra whose absorption in the energy range below the electronic gap of both 1L-WS₂ and HAT-CN will provide direct evidence for the formation of CT states at the interface.

A systematic study on the evolution of the WS₂ VBM and HAT-CN LUMO positions is performed with combined UPS/IPES by evaporating 0, 0.5, 1, 2, 5, and 10nm HAT-CN on 1L-WS₂ on p-Si. This series of energy alignment studies show that the 1L-WS₂/HAT-CN interface shows a slight relaxation of the CT gap, which aligns well with the loss of electrons from WS₂ into HAT-CN layer.

This work demonstrates how tailoring the energy level alignment in hybrid 2D/organic heterojunctions can enable interfacial charge transfer. Our findings underscore the potential of engineering van der Waals interfaces between TMD monolayers and molecular semiconductors for novel excitonic devices and energy conversion applications.

2D-ThP-4 Enhanced Etching and Surface Cleaning of MoS₂ via Pre-Fluorination and Plasma-Activated Desorption, *Shoaib Khalid, Yury Polyachenko, Yuri Barsukov, Stephane Ethier, Igor Kaganovich, Princeton University Plasma Physics Lab*

Transition metal dichalcogenides (TMDs) are a class of layered materials that have garnered significant attention for their unique electronic, optical, and mechanical properties. Their tunable bandgap, high carrier mobility makes them ideal candidates for applications in next-generation electronics, optoelectronics, and energy storage devices. This study, based on ab initio molecular dynamics (AIMD) calculations, suggest that pre-fluorinating the MoS₂ surface before Ar plasma bombardment significantly enhances the etching yield and improves surface smoothness. Additionally, we propose a strategy to remove excess fluorine adsorbed on sulfur using low-energy electrons from the plasma. Our results show that F⁻ ions migrate much faster than neutral F atoms, facilitating their desorption. We also find that when H atoms are adsorbed on the surface, F⁻ ions diffuse until they encounter an H adatom, leading to the desorption of stable HF molecules. This approach of utilizing low-energy reactive species from plasmas offers an effective method for surface transport and cleaning of electronegative adsorbates, such as halogens, from the MoS₂ surface.

This research was supported by the Princeton Plasma Physics Laboratory under U.S. Department of Energy Prime Contract No. DE-AC02-09CH11466.

2D-ThP-5 2d Topological Phases, β -Sn Transformation, and Implications for Topological Superconductivity, *Cheng-Maw Cheng, National Synchrotron Radiation Research Center, Taiwan; Ye-Shun Lan, National Tsing Hua University, Taiwan; Shu-Hua Kuo, National Synchrotron Radiation Research Center, Taiwan; Yen-Hui Lin, National Tsing Hua University, Taiwan; Jing-Yue Huang, National Synchrotron Radiation Research Center, Taiwan; Pin-Jui Hsu, Horng-Tay Jeng, National Tsing Hua University, Taiwan*

Two-dimensional topological materials offer unique electronic properties that are promising for next-generation quantum and spintronic devices. In particular, 2D topological insulators (TIs) host robust spin-polarized edge states protected by a bulk band gap induced by spin-orbit coupling, while topological nodal line semimetals (TNLSMs) feature one-dimensional band degeneracies protected by crystalline symmetries. Despite theoretical predictions, experimental realization of 2D TNLSMs remains scarce. In this work, we report the synthesis and characterization of a monolayer cubic β -Sn phase grown on a Cu(111) substrate via sequential deposition. Starting from low-temperature growth of α -Sn (stanene), we observed a well-defined honeycomb lattice using scanning tunneling microscopy (STM) and low-energy electron diffraction (LEED), consistent with prior reports. Subsequent Sn deposition led to a structural phase transition into a high-coverage, single-layer β -Sn with a body-centered tetragonal structure. This transition was confirmed by STM and angle-resolved photoemission spectroscopy (ARPES), revealing a dramatic change in the electronic structure. Combined with first-principles density functional theory (DFT) calculations, we demonstrate that monolayer β -Sn hosts two distinct types of nodal lines—coexisting in a single 2D mono-elemental material. This observation marks the first realization of a 2D topological semimetal featuring dual nodal line types. Given β -Sn's known superconductivity in bulk form, our findings establish ultrathin β -Sn as a promising platform for exploring 2D topological superconductivity and potentially hosting Majorana fermions.

2D-ThP-9 Discretized Atomic Layer Deposition Recipe for Wafer-scale Synthesis of MoS₂, *Sachin Shendokar, Shyam Aravamudhan, North Carolina A&T State University*

Monolayer MoS₂, a 2D material, holds enormous promise for transcending the fundamental limits of silicon-based electronics and continuing the downscaling of transistors and logic circuits for energy-efficient computing. However, major research efforts are needed to overcome many fabrication and integration challenges including wafer-scale growth control, doping,

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contacts, gate stack, and reliability. In this work, we attempt to address one of the challenges, namely wafer-scale synthesis of MoS₂. Atomic Layer Deposition (ALD) is one of the most promising techniques for wafer-scale growth of MoS₂ due to its conformal, self-limiting, and low-temperature characteristics. We present here a novel discretized ALD recipe for wafer-scale deposition of uniformly thick MoO₃, further, to sulfurize to stoichiometric MoS₂. This is an alternative approach for ALD to determine temperature and time based on the Arrhenius equation and first -order reaction kinetics. Wafer-scale uniformity, film morphology, composition and crystallinity were measured using a comprehensive set of characterization techniques including ellipsometry, AFM, XPS, Raman, XRD and Photoluminescence measurements.

2D-ThP-10 Modeling Synthesis Pathways for Transition Metal Dichalcogenide Monolayers with Quantum and Statistical Learning Techniques, Andrew Messecar¹, Western Michigan University; Chen Chen, Isaiah Moses, Wesley Reinhart, Joan Redwing, The Pennsylvania State University; Steven Durbin, University of Hawai'i at Mānoa; Robert Makin, Western Michigan University

The ability for machine learning technologies to estimate patterns from information has made them a top approach for optimizing the growth and characterization of a broad range of material systems, including few and single atomic layer materials such as transition metal dichalcogenides (TMDs). In this work, we have applied both quantum and classical machine learning approaches to investigate and model the metal-organic chemical vapor deposition (MOCVD) of TMD thin films as grown with dihydrogen chalcogenide gas and transition metal hexacarbonyl precursors. Several hundred discrete records of MOCVD-grown TMD samples synthesized in a single laboratory have been organized into material-specific data sets. For each growth trial, Raman spectra characterizing the resulting sample have been utilized to assess monolayer coverage. The distance between the A_{1g} and E_{2g} Raman mode peaks in each spectrum was measured and associated with the respective growth record as an output variable within the data set. The MOCVD synthesis parameter data was subsequently mapped to the measured A_{1g} and E_{2g} Raman mode peak distance using supervised learning techniques. A combination of p-value calculations, Pearson's correlation coefficients, SHAP values, and regression tree splitting rules were used to analyze the statistical importance of each MOCVD operating parameter for influencing the expected value of the distance between the A_{1g} and E_{2g} Raman mode peaks. Various quantum as well as classical supervised machine learning approaches – including k-nearest neighbors, tree-based models, and quantum support vector machines, were fit to the data and compared for generalization performance. In the case of MoS₂, generalizing beyond the training data indicates that maximizing both the Mo(CO)₆ injector hydrogen gas flow during the growth step and the value of the Mo(CO)₆ flow during the reaction temperature ramp up step is forecasted to result in a minimization of the A_{1g} and E_{2g} Raman mode peak distance. This predicted reduction of the peak distance between the A_{1g} and E_{2g} vibrational modes in Raman spectra acquired of MoS₂ thin films corresponds with improved monolayer coverage. This methodology is applicable to additional TMD materials and characterization features of interest.

*This work was funded by Penn State 2DCC-MIP through the NSF cooperative agreement DMR-1539916 as well as by the National Science Foundation (grant number DMR-2003581).

2D-ThP-12 Band Gap Opening in AB-Stacked Bilayer Silicon, Kumar Vishal, Hong Huang, Yan Zhuang, Wright State University

Despite their potential as of being the excellent candidates for advancing CMOS technology to its physical limits, the presence of an opened energy bandgap in either single- or bilayer- silicene poses a significant challenge, hindering its applications in the main stream semiconductor industry. Previous attempts, including applying external electric field, surface decoration, nanopatterning, and applying uniaxial strain along designate directions, have proven insufficient in meeting the stringent demands of CMOS technology concerning operational reliability, processing environment sensitivity, product yield, and achievable processing standards. Recently a number of research reported that applying of the biaxial in-plane strain leads to energy bandgap opening in AA-stacked bilayer silicene, however the maximum energy bandgap opening is limited to 16 meV.

In this work, we present a theoretical study of the opening of energy bandgap in AB-stacked bilayer silicene. Employing the Density Functional Theory (DFT), our investigations have taken into account of the effects of both ferromagnetism and antiferromagnetism, alongside external biaxial in-plane strain/stress and vertical biasing effects. Within a strain range spanning from -5.17% to 10.35%, we observed a strain-tunable energy bandgap opening with a maximum of 380 meV at a strain level of 7.76%. Notably, beyond this strain range, the energy bandgap remains closed. In addition, under compressive strain, the energy band diagram presents spin-generated features, with discernible energy band splitting. On the contrary, tensile strain leads to a break of the spin generation, except at specific high symmetry points such as . We further observe a degeneration of the energy band diagram at these high symmetry points upon the application of gate voltage along the vertical direction. The coupling of the ferromagnetism and antiferromagnetism between the two silicene layers results in a transition from metallic material to semiconductor. The potential of the opened bandgap makes the AA-stacked bilayer silicene a very promising candidate material to be applied in the CMOS technology, while the strain-induced tunable bandgap opening offers immediate potential for applications in the infrared (IR) spectrum. In addition, the spin-induced band diagram degeneration may holds promise for integrated spintronics applications.

Actinides and Rare Earths

Room Ballroom BC - Session AC-ThP

Actinides and Rare Earths Poster Session

AC-ThP-2 Deep Fission Track Analysis for Nuclear Forensics, Noam Elgar, Ben Gurion University Be'er Sheva, Israel; Itzhak Halevy, Rami Babayew, Ben Gurion Uni. Be'er Sheva, Israel; Mark Last, Itzhak Orion, ben Gurion Uni. Be'er Sheva, Israel; Jan Lorincik, research centre rez, Czechia; Yaakov Yehuda-Zada, Galit Katarivas Levy, ben Gurion Uni. Be'er Sheva, Israel; Aryeh Weiss, bar-ilan university, israel; Erez Gilad, ben Gurion Uni. Be'er Sheva, Israel

Abstract Summary:

Fission Track Analysis (FTA) is a key method in nuclear forensics for detecting fissile materials. This study proposes a novel deep learning approach to automate the segmentation and classification of star-shaped patterns in microscopic images, reducing the need for manual analysis.

Methodology:

Using a U-Net fully convolutional neural network, the research focuses on identifying star-like features in microscopy. A custom simulation tool generated artificial star shapes for training, alongside a new, diverse image database. Models were trained separately for small stars (under 60 μ m, fewer than 10 branches, no black center) and larger, more complex patterns. An adaptive thresholding method was introduced to improve data labeling and background noise filtering.

Key Findings:

The model reached 92.04% accuracy for small star classification and an ROC AUC of 0.84. For multi-class tasks, it achieved 86.3% accuracy in distinguishing star quality and 82.63% accuracy in recognizing stars with varying numbers of branches. Advanced classification models reached an AUC of 0.90.

Conclusion:

This study shows that deep learning can significantly enhance FTA by automating star pattern detection and classification, offering a more efficient and accurate tool for nuclear forensic analysis.

AI/ML Mini-Symposium

Room Ballroom BC - Session AIML-ThP

AI/ML for Scientific Discovery Poster Session

AIML-ThP-1 AI Agents for Semiconductor Processing: A New Benchmark for Autonomous Materials Synthesis, Angel Yanguas-Gil, Argonne National Laboratory

Over the past year there has been an increasing interest in leveraging foundation and large language models to design AI agents that can interact with experiments to solve materials science and synthesis problems. One of the challenges of this approach is that testing the performance of these agents require access to automated labs. In contrast to benchmarks testing abilities such as knowledge, math skills, or reasoning, there is a lack of

¹ JVST Highlighted Poster

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benchmarks that can help both design and evaluate agents without the access to dedicated experimental facilities.

In this work, we introduce Semibench, a benchmark to evaluate AI agents' ability to operate and solve synthesis challenges in the context of semiconductor processing. This benchmark introduces two core ideas: first, it introduces virtual tools that simulate the output of real life experiments. This allows us to test an agent's ability to solve a wide range of challenges involving different tool configurations, amount and nature of information that is accessible, and process complexity. Second, it focuses on the concept of microtasks, challenges designed to have a unique solution. This allows us to define quantitative performance metrics for the agent based on how far the proposed solution is to the ground truth. For Semibench, we have focused on three different techniques that are commonly used in the context of microelectronics: atomic layer deposition, sputtering, and reactive ion etching. For each challenge in the benchmark, agents are exposed to a collection of virtual tools and asked to solve specific questions by providing a sequence of synthesis steps. These steps involve selecting the right configurations for each of the tools, such as the precursor channels in the case of ALD, or the targets and power for sputtering, or the etching recipe for RIE.

We have applied this benchmark to agents based on leading large language models, such as OpenAI's o1 an o3 family of reasoning models. The results show that these agents can correctly identify the sequence of steps in a wide range of conditions. However, they struggle when they need to use quantitative data that is not provided explicitly to solve these challenges. These results provide useful information about how to design useful models and their limitations for thin film applications.

AIML-ThP-2 Domain Knowledge + AI for Chemically Accurate Potentials: Application to Diamond Surfaces, John Isaac Enriquez, Princeton University Plasma Physics Lab; **Yoshitada Morikawa**, Osaka University, Japan; **Igor Kaganovich**, Princeton University Plasma Physics Lab

Machine learning interatomic potentials (MLIPs) are powerful tools for accelerating atomistic simulations, but their reliability depends critically on training set construction. A common strategy is to build universal MLIPs from open-source databases, offering transferability but often sacrificing accuracy particularly in surfaces and interfaces with highly diverse chemical environments. These databases are dominated by equilibrium structures, leaving reaction pathways undersampled, forcing potentials to extrapolate in chemically critical regions—a limitation in catalysis, surface chemistry, and defect dynamics where reactive events dominate. Specialized MLIPs built via active learning can achieve higher accuracy but typically rely on molecular dynamics (MD) and committee models to sample configuration space. Because rare reactions are unlikely to appear within accessible timescales, discovery is left to chance, often requiring long simulations or many iterations. As a result, such MLIPs may fit training data well but fail to capture the most chemically relevant regions.

To address this limitation, we introduce DIAL (Domain-Informed Active Learning), a chemically targeted strategy that augments conventional active learning. Rather than relying solely on MD and uncertainty-driven sampling, DIAL incorporates both established reaction pathways and those identified via nudged elastic band (NEB) calculations. Training datasets are enriched with configurations along these pathways, particularly near transition states. By integrating data-driven active learning with domain knowledge of chemical processes, this approach ensures that the potential is trained on the chemically important regions of configuration space.

Using DIAL, we developed a specialized MLIP for diamond surfaces and interface reactions. The potential enabled large-scale molecular dynamics simulations that reproduced graphitized and oxidized surface morphologies and reaction products, while providing new insights relevant to diamond-based electronics and quantum technologies. In particular, the model captured thermal degradation mechanisms and suppression, facet-dependent oxidative etching, and suggested strategies for controlling surface termination to preserve quantum-relevant color centers. Although demonstrated on diamond, the DIAL framework is general and applicable to other reactive materials systems, including catalysis and battery interfaces.

These results demonstrate how DIAL bridges data-driven methods with domain expertise, highlighting the value of collaboration between materials scientists and AI specialists in advancing the next generation of materials discovery.

AIML-ThP-3 AI Operating System for Accelerating Semiconductor R&D Process Development, Suresh Ayyalsamy, Manish Sharma, Elucida Labs

Advanced plasma etch and deposition process development in semiconductor R&D requires the simultaneous optimization of dozens of interdependent parameters against stringent nanometer-scale metrics. Today, process engineers face a fragmented workflow characterized by siloed data, inefficient experimentation, manual analysis, and limited integration between process settings and physical outcomes. These bottlenecks slow discovery, drive up costs, and hinder knowledge transfer across teams.

We present Elucida Labs, an AI-native operating system designed to transform semiconductor R&D environments across both etch and deposition. Our system enables process teams to reduce experimental burden, shorten learning curves, and converge to target specifications faster. By embedding AI-driven intelligence directly into R&D workflows, Elucida Labs demonstrates how AI can amplify human expertise, accelerate innovation, and reshape the economics of semiconductor process development.

AIML-ThP-4 Physics-Informed Neural Networks for One-Dimensional Capacitively Coupled Plasma Physics Problems, Uvini Balasuriya Mudiyanseilage, Jesse Jing, Arizona State University; **Abhishek Verma, Kallol Bera, Shahid Rauf**, Applied Materials Inc.; **Kookjin Lee**, Arizona State University

Physics-Informed Neural Networks (PINNs) offer a flexible framework for solving coupled partial differential equations by embedding physical laws directly into the training process. In this work, we develop and evaluate a PINN approach for modeling one-dimensional capacitively coupled plasma (CCP) discharges, governed by electron continuity equation under the drift-diffusion approximation and uniform ion density assumption, coupled with Poisson's equation for self-consistent electrostatic plasma description. The governing equations are non-dimensionalized to improve numerical stability and facilitate learning across disparate physical scales. The model consists of two separate fully connected networks—one for electron density and one for electric potential—augmented with Fourier Feature Mapping to capture multi-scale spatial variations and trained with exact Dirichlet boundary conditions enforced for both electron density and potential. Collocation points are sampled throughout the spatio-temporal domain to compute physics-based residuals directly. Our PINN approach successfully approximates the finite difference method (FDM) solution, achieving an average L^2 relative error of 3.55% for electron density and 3.89% for electric potential over spatio-temporal domain. To address training stiffness and gradient flow issues commonly observed in multi-equation PINNs, we are currently exploring adaptive loss balancing via gradient-based reweighting, as well as Neural Tangent Kernel (NTK) analysis. Preliminary results reveal a significant imbalance in the convergence rates of the two governing equations: the continuity equation loss decreases much faster than that of the Poisson's equation, necessitating disproportionately higher loss weights for the Poisson term to achieve balanced convergence. The model is currently being extended to include ion continuity and momentum conservation equations.

Atomic Scale Processing Mini-Symposium

Room Ballroom BC - Session AP-ThP

Atomic Scale Processing Poster Session

AP-ThP-2 Thermal Atomic Layer Etching of Lanthanum Oxide Using Acetylacetone and Ozone, Aziz Abdulagatov, Jonathan Partridge, University of Colorado at Boulder; **Charles Dezelah**, ASM Microchemistry Ltd., Finland; **Steven George**, University of Colorado at Boulder

Thermal atomic layer etching (ALE) of lanthanum oxide (La_2O_3) was demonstrated using sequential exposures of acetylacetone (Hacac) and ozone (O_3). Hacac reacts with La_2O_3 by a ligand addition and hydrogen transfer reaction to form volatile $La(acac)_3$ and H_2O according to: $La_2O_3 + 6Hacac \rightarrow 2La(acac)_3 + 3H_2O$. Ozone was then used to remove carbon residue resulting from Hacac exposure on the surface.

In situ spectroscopic ellipsometry (SE) was used to monitor the film thickness change with number of ALE cycles. SE observed the linear decrease of La_2O_3 film thicknesses versus number of Hacac and O_3 cycles. Semicrystalline La_2O_3 thin films displayed etch rates of 0.2, 0.4 and 0.69 $\text{\AA}/\text{cycle}$ at 230, 250 and 270 °C, respectively. The SE studies also showed that the Hacac and O_3 surface reactions were self-limiting.

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Atomic force microscopy (AFM) analysis of semicrystalline La_2O_3 on Si with a thickness of 20 nm displayed surface smoothing versus ALE cycles. The RMS surface roughness was 3.3 Å prior to ALE and 0.9 Å after ALE. Quadrupole mass spectrometry (QMS) was also utilized to study the Hacac- O_3 etch process on crystalline La_2O_3 powder at 250 °C. $\text{La}(\text{acac})_3$ organic fragments were detected during Hacac exposure. During O_3 exposure, combustion products were observed from the oxidation of organic residuals left from Hacac exposures.

Hexafluoroacetylacetone (hfacH) has also been utilized instead of Hacac to etch La_2O_3 . One advantage of Hfac over Hacac is that Hfac has a lower pKa value and hfac-metal complexes are generally more volatile. However, La_2O_3 ALE using hfacH and O_3 displayed a substantially lower etch rate of 0.06 Å/cycle at 250 °C. This result was attributed to significant film fluorination by Hfac as revealed by XPS analysis. Etching lanthanum fluoride using the Hfac- O_3 chemistry is more challenging.

AP-ThP-3 Spontaneous Etching of SiO_2 by Co-Adsorbing Polar Molecules with HF, Marcel Junige, Steven M. George, University of Colorado Boulder
Spontaneous etching is characterized by a physicochemical reaction of a thin film surface with a reactant vapor that releases volatile products with a continuous etch rate. Spontaneous etching provides the benefit of a single processing step with simply one etchant exposure, as well as typically high inherent selectivity.

Previous work has demonstrated that anhydrous HF vapor does not spontaneously etch SiO_2 . However, co-adsorbing ammonia (NH_3) with HF has led to rapid SiO_2 spontaneous etching. These results have suggested that the nature of the active etch species changes in the presence of NH_3 . Without co-adsorbed NH_3 , the active etch species is believed to be F^- . With the polar NH_3 co-adsorbate, the active etch species is thought to switch to HF_2^- . [Junige, George: *Chem. Mater.* **36**, 6950 (2024)]

Co-adsorbing polar molecules with HF has been proposed to form HF_2^- species to enable SiO_2 etching. Examples of suitable polar molecules include dimethylamine ($(\text{CH}_3)_2\text{NH}$: 1.0 D), NH_3 (1.4 D), methanol (CH_3OH : 1.7 D), water (H_2O : 1.85 D), or ethylene glycol ($(\text{CH}_2\text{OH})_2$: 2.28 D); where the number in parentheses refers to the dipole moment of the respective molecule in the gas phase. In theory, these polar co-adsorbates solvate HF and stabilize the dissociation products H^+ and F^- . As a result of this more extensive HF dissociation, F^- species at increased concentration react further with HF to produce HF_2^- species.

In situ spectroscopic ellipsometry (iSE) experiments were performed to test the idea that other polar molecules co-adsorbed with HF may enable SiO_2 spontaneous etching. These investigations revealed that co-adsorbing H_2O or CH_3OH with HF did not spontaneously etch SiO_2 at 200 or 275 °C. The adsorption and desorption kinetics of H_2O or CH_3OH molecules at SiO_2 surfaces might not yield an adequate solvation layer at these elevated temperatures. In contrast, co-adsorbing DMA+HF enabled SiO_2 spontaneous etching with a substantial etch rate of 34.70 Å/min at 200 °C. Similar results have been observed previously for NH_3 +HF co-dosing at 275 °C. These results suggested that co-adsorbing polar molecules with HF to form HF_2^- species can etch SiO_2 if there is sufficient solvation. Co-adsorbing $(\text{CH}_2\text{OH})_2$ +HF, as well as $(\text{CH}_2\text{OH})_2$ adsorbed layers on SiO_2 surfaces, may be tested in future experiments.

AP-ThP-6 Atomic Scale Processing (AP7) Sustainable Semiconductor Manufacturing (SM): Oral Session (or Poster)DOE's Sandia Project on Tunnel Field Effect Transistor (TFET) for 10X Microelectronics Energy Efficiency in a General Purpose Transistor, Desree Salazar, CLEAResult Energetics, DOE/AMMTO; Emilie Lozier, DOE-EERE; Shashank Misra, Sandia National Lab; Tina Kaarsberg, DOE-EERE

Abstract—The United States Department of Energy (DOE) Advanced Materials and Manufacturing Technology Office (AMMTO) is leading a multi-organization effort to counter alarming trends in U.S. computing energy use (e.g. [LBNL 2024 forecasts - lbnl-2024-united-states-data-center-energy-usage-report.pdf](https://eta-publications.lbl.gov/sites/default/files/2024-12/lbl-2024-united-states-data-center-energy-usage-report.pdf)) - that data centers will account for 26% of US electricity use by 2028 when cryptomining is included) with its initiative in energy efficiency scaling for two decades (EES2) for microelectronics. Under this initiative, DOE/AMMTO has funded a portfolio of EES2 device technology R&D projects that promise >10X energy efficiency increase by 2030. This [talk] will highlight the first of these projects with Sandia National Laboratories to build on atomically precise manufacturing techniques to create a vertical tunnel field effect transistor (vTFET). Updates will be provided on the successful integration of front end

of line (FEOL), back end of line (BEOL) and mid-end of line (MEOL) manufacturing processes (especially thermal budget) to fabricate this vTFET in a CMOS compatible process. One important discovery of the research in this area is “ultradoping” which makes the abrupt doping profiles needed for efficient vTFETs far more manufacturable. This talk also will present how these Sandia results integrate with version 1.0b of the EES2 roadmap that will be issued in Summer 2025. Version 1.0a of the Roadmap is available at [EES2 Roadmap Version 1.0 \[https://eere-exchange.energy.gov/FileContent.aspx?FileID=f4234e29-cc0c-4a56-a510-86b616ab5535\]](https://eere-exchange.energy.gov/FileContent.aspx?FileID=f4234e29-cc0c-4a56-a510-86b616ab5535).

AP-ThP-7 Atomic Layer Deposition of Vanadium Oxide on Silicon Oxide and Kapton Substrates, Mohamed Asrif, Shyam Aravamudhan, North Carolina A&T State University

Multilayer optical coatings play a vital role in the propagation of light in photonic devices through selective reflection, transmission, and absorption of specific wavelengths. Among transition metal oxides, Vanadium Oxide (VO_2) shows significant promise due to its high corrosion resistance at low temperatures, high tensile strength, and high electrical conductivity. This work aims to enhance the performance and durability of optical coatings by depositing VO_2 thin films using Atomic Layer Deposition (ALD), a technique offering precise and conformal deposition of ultra-thin films with Angstrom-level thickness control at low temperatures, making it a preferred method of growing thin films on planar and nanostructured surfaces. Vanadium Oxide (VO_2) films were synthesized on Silicon and Kapton Substrates by the ALD method using the precursor Tetrakis (ethylamino) vanadium (TEMAV). Results from XPS confirmed successful deposition, as the binding energies for vanadium ($\text{V}2\text{p } 1/2$ and $\text{V}2\text{p } 3/2$ orbitals were both present) and oxygen were both present, as well as residual traces of Carbon and Nitrogen. XRD measurements for the 7 nm sample and the 21 nm sample revealed that the films were amorphous, deposited at 150 °C. AFM results indicated mostly smooth surfaces with an RMS roughness value of between 0.2 and 0.3 nm. However, on a larger scale, that RMS roughness value increased to around 17 nm, indicating that there were signs of agglomeration in the deposition. Raman spectroscopy of the 21 nm sample exhibited spectral features corresponding to mixed oxidation states of vanadium, suggesting partial crystallinity post-annealing. Characterization of the 42 nm samples are still in progress. Post-deposition annealing at ~500 °C in ultra-high vacuum will be utilized to generate crystallization, then samples will undergo comprehensive determination of the structural and surface chemistry.

AP-ThP-8 Development of ALD-ZrN for Diffusion Barrier Layer in ULSI-Cu Interconnects, Jun Tanaka, Jun Yamaguchi, Noboru Sato, Naoki Tamaoki, Atsuhiko Tsukune, Yukihiro Shimogaki, The University of Tokyo, Japan

To achieve higher performance and lower power consumption in ULSI devices, transistors have been continuously miniaturized and integrated at higher densities, resulting in the reduction of Cu interconnect linewidths. However, as the linewidth approaches the mean free path of electrons in Cu (~40 nm), the effects of inelastic electron scattering at grain boundaries and sidewall interfaces become non-negligible, leading to increased resistivity. Furthermore, the conventional diffusion barrier TaN, used to prevent Cu penetration into interlayer dielectrics, has a much higher resistivity than Cu (Cu:1.68 $\mu\Omega\text{-cm}$, TaN:135 $\mu\Omega\text{-cm}$), and its thickness reduction is limited due to the need to maintain barrier integrity. As a result, the proportion of Cu in the interconnect cross-section decreases with scaling, causing a sharp increase in line resistance. Additionally, increased resistance at the via bottom due to the barrier layer also becomes problematic.

In this study, we focused on ZrN as a novel diffusion barrier material. ZrN possesses the lowest resistivity (13.6 $\mu\Omega\text{-cm}$) among transition metal nitrides [1] and maintains its barrier properties even after annealing at 500 °C [2]. To deposit ZrN films, we employed thermal atomic layer deposition (ALD), which is suitable for conformal coating in narrow damascene trenches. $\text{Zr}[\text{N}(\text{CH}_3)_2]_4$ was used as the precursor, NH_3 as the reactant gas, and N_2 as the carrier/purge gas.

Figure 1 shows the thickness and resistivity of ZrN films deposited at 250 °C as a function of ALD cycles. Film thickness increased linearly with the number of cycles, indicating excellent controllability, although the resulting resistivity was not yet ideal. Figure 2 presents the growth per cycle (GPC) at various deposition temperatures, revealing a stable ALD window between 150 and 250 °C. Figure 3(a) shows the dependence of film density and resistivity on NH_3 supply time for ZrN deposited at 200 °C, which lies within the ALD window. Increasing the NH_3 supply time led to higher film density and lower resistivity. Since no significant change in film composition was

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observed by XPS (Fig. 3(b)), the densification is attributed to improved surface reactions during the NH_3 pulse. When a film deposited with a 5 sec NH_3 supply was etched using an Ar ion gun in the XPS chamber and its resistance measured, removal of the surface oxide layer significantly reduced the resistance (Fig. 4). Suppressing surface oxidation at elevated temperatures after deposition is expected to further reduce the resistivity.

- [1] C. C. Wang *et al.*, *Journal of Materials Science*, **30**, 1627–1641 (1995).
- [2] M. B. Takeyama *et al.*, *Japanese Journal of Applied Physics*, **61** SJ0802 (2022).

AP-ThP-9 Comparative Evaluation of SiO_2 Atomic Layer Etching Using NF_3 and SF_6 Gases via a Combined Thermal and Remote Plasma Approach, *Min Kyun Sohn, Jieun Kim, Sun Kyu Jung, Min-A Park, Jin Ha Kim, Jaeseoung Park, Subin Heo, Sang-Hoon Kim, Jeong Woo Park, Seong Hyun Lee, Dongwoo Suh, Electronics and Telecommunications Research Institute, Republic of Korea*

Atomic Layer Etching (ALE) is a critical technology enabling atomic-scale precision in advanced semiconductor device fabrication. Although obtaining detailed etching characteristics from various fluorine-based gases is crucial for optimizing etch per cycle (EPC) and selectivity, experimental data on gases other than commonly used hydrogen fluoride (HF) or C-F combined gases remain limited. This study investigates silicon dioxide (SiO_2) ALE processes utilizing sulfur hexafluoride (SF_6) and nitrogen trifluoride (NF_3) gases, employing a combined thermal and remote plasma-assisted approach at a process temperature of 300°C. The selection of SF_6 and NF_3 gases was guided by their distinct environmental impacts, radical generation efficiencies, and their potential effects on etching characteristics.

In this study, a surface modification approach using trimethylaluminum (TMA), followed by selective removal with remotely generated fluorine radicals, was systematically evaluated. By combining thermal isotropic surface modification with highly reactive fluorine radicals generated via remote plasma, this method effectively leverages the advantages of both isotropic thermal etching and plasma-enhanced high EPC. Experimental results indicated that NF_3 gas generated significantly higher fluorine radical densities than SF_6 under identical thermal and remote plasma conditions, resulting in enhanced EPC. However, in the case of NF_3 gas flow rates above 20 sccm, the significantly higher density of fluorine radicals generated expanded beyond the ALE regime into conventional plasma etching territory, limiting uniform atomic-level control. In contrast, fluorine radicals generated by SF_6 remained within optimal quantities for true ALE conditions, even at a relatively high flow rate of 100 sccm. Additionally, the remote plasma-assisted method effectively minimized ion-induced surface damage, thus promoting superior etching quality.

Our findings highlight that selecting the appropriate gas (NF_3 or SF_6) based on specific process requirements is critical, as each gas offers distinct advantages. Future research will explore mixed-gas processes combining SF_6 and NF_3 to synergistically enhance their respective benefits and further optimize ALE performance.

Acknowledgments This work was supported by the Electronics and Telecommunications Research Institute(ETRI) grant funded by the Korean government [25ZH1240]

AP-ThP-11 Characterizing Remote Ar/H₂ plasmas for Atomic Precision Processing, *David Boris, Maria Sales, Peter Litwin, Michael Johnson, Mackenzie Meyer, Virginia Wheeler, Jeffrey Woodward, Scott Walton, U.S. Naval Research Laboratory*

In comparison to thermal atomic layer deposition (ALD) plasma-enhanced atomic layer deposition (PE-ALD) generally offers the benefit of substantially reduced growth temperatures and greater flexibility in tailoring process conditions to achieve desirable film characteristics. Among the approaches used to tailor film properties is the inclusion of Ar/H₂ plasma exposures in the PEALD growth cycle as a means to either mitigate carbon contamination or as a reduction step that converts metal oxide films to metallic films. When employing these Ar/H₂ plasma exposures however, control over the flux and energy of ions is needed to avoid unwanted damage to the growth surface. In addition, Ar/H₂ plasmas produce atomic H radicals, and VUV photons which also need to be considered when choosing process conditions. In this work we aim to characterize the production of ions, atomic neutrals, and photons within remote Ar/H₂ inductively coupled plasma sources commonly used for PEALD. The information gained in characterizing these systems will then be used to guide the choice of process conditions for PEALD growths involving Ar/H₂ plasma exposures. Langmuir probe and retarding field energy analyzer

(RFEA) measurements were used to characterize the charged particle flux within these systems, and optical emission and VUV emission spectroscopy was used to characterize the atomic H density and VUV photon characteristics respectively. This work is supported by the Office of Naval Research through the Naval Research Laboratory base program.

AP-ThP-12 From Inhibitor to Promoter: Role of Hexafluoroacetylacetone in Tailoring TiO_2 Growth on MgO Surfaces, *Sanuthmi Dunuwila, John R. Mason, Andrew Teplyakov, University of Delaware*

Magnesium oxide (MgO) is a key material in electronic and optoelectronic devices due to its wide bandgap, optical transparency, and thermal stability. However, the performance of MgO -based multilayer systems is often limited by interfacial inconsistencies, especially when deposited via such techniques as sputtering, which introduce surface defects. Surface modification strategies have emerged to address these issues, particularly in enhancing compatibility with atomic layer deposition (ALD) processes.

This work explores the surface modification of sputter-deposited amorphous MgO films using 1,1,1,5,5,5-hexafluoro-2,4-pentanedione (hfach), a fluorinated β -diketone. Although this compound has been reported as a small-molecule inhibitor in selected ALD processes, this study demonstrates that hfach acts as a growth promoter for TiO_2 deposition on MgO with thermal ALD that utilizes TDMAT and H_2O as co-reactants. Water contact angle (WCA) measurements confirm that hfach alters the MgO surface from hydrophilic to hydrophobic, yet TiO_2 nucleation is enhanced on the modified surface, challenging conventional interpretations of surface energy and precursor accessibility.

This study uses a suite of primary surface characterization tools, X-ray photoelectron spectroscopy (XPS), atomic force microscopy (AFM), time-of-flight secondary ion mass spectrometry (ToF-SIMS), X-ray diffraction (XRD), and scanning electron microscopy (SEM) to confirm successful TiO_2 deposition.

These findings challenge the prevailing notion of hfach as a growth inhibitor and highlight its context-dependent behavior. The modified surface facilitates nucleation, likely due to altered surface energy and local chemical environment, suggesting a potential role for hfach as a growth promoter. This study contributes to the understanding of molecular surface chemistry and offers new insight into improving interface quality in multilayer oxide systems.

By redefining the function of fluorinated ligands in ALD chemistry, this work opens opportunities for more controlled and efficient deposition strategies in advanced electronic device fabrication.

AP-ThP-13 Chemistry of a 2D Material Fe_3GaTe_2 for Atomically-Precise Processing: Etching and ALD, *Marissa D. Piña, Andrew V. Teplyakov, University of Delaware*

Fe_3GaTe_2 is a 2D van der Waals material that displays intrinsic ferromagnetism above room temperature along with strong perpendicular anisotropy, making it a possible candidate for spintronics and magnonics applications. Recent computational studies have shown that the Fe_3GaTe_2 Curie temperature becomes elevated and its magnetic properties are tunable at the monolayer, demonstrating the importance of obtaining ordered and defect-free thin film and monolayer structures of this material by using atomically-precise treatments.

To determine whether Fe_3GaTe_2 can be etched controllably in nearly atomic layer etching regime, we performed a chlorine gas dose followed by an acetylacetone dose on Fe_3GaTe_2 flakes exfoliated onto a silicon substrate. AFM and XPS after the chlorine dose at elevated temperature show a partially etched but rougher surface. The consequent acetylacetone dose at the same temperature shows further etching. We aim at exploring atomic layer etching of Fe_3GaTe_2 under further optimized and controlled conditions. We are also exploring the etching mechanism to determine why the chlorine dose causes the initial change.

To explore the role of surface structure and chemistry of Fe_3GaTe_2 in ALD reactivity and also to determine whether ALD is feasible on Fe_3GaTe_2 flakes, we followed the ALD of Al_2O_3 on unmodified Fe_3GaTe_2 flakes. We observed alumina growth from TMA/water deposition cycles on Fe_3GaTe_2 after 10 and 30 cycles in a similar amount compared to what was grown on the reactive silicon substrate, as confirmed by ToF-SIMS depth profiling. We are currently evaluating the changes in Al_2O_3 growth after chemical surface modification of Fe_3GaTe_2 with small organic molecules.

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AP-ThP-14 Atomic Layer Etching of HfO_2 and ZrO_2 on Nanotrench Structures Using NbF_5 and TiCl_4 , *Boyun Choi, Getasew Zewdie, Hyeyoung Shin, Nari Jeon*, Chungnam National University, Republic of Korea

High-k oxides such as HfO_2 and ZrO_2 are critical for advanced transistor integration, but their atomic-level patterning remains a bottleneck. We examined thermal atomic layer etching (ALE) of these oxides using NbF_5 and TiCl_4 . Distinct material-dependent behaviors were observed: HfO_2 exhibited smooth, self-limiting etch per cycle, whereas ZrO_2 showed significant surface roughening and high Cl incorporation. Surface chemical analysis confirmed that the degradation in ZrO_2 arises from unstable chlorinated intermediates. Density functional theory (DFT) calculations support this interpretation, indicating stronger and more disruptive TiCl_4 interactions with ZrO_2 compared to HfO_2 . ALE was further applied to nanohole structures with 150 nm diameter and 2000 nm depth. In this geometry, HfO_2 displayed topographically selective removal, attributed to crystallinity-related microstructural variations across the etched regions. These results demonstrate that both reactant chemistry and oxide microstructure govern ALE performance. The combined experimental and computational insights provide a framework for selective patterning of high-k dielectrics and offer process guidelines for enabling integration of HfO_2 and ZrO_2 in future nanoscale transistor and interconnect architectures.

AP-ThP-16 Area-Selective Deposition with Aromatic Self-Assembled Monolayer Blocking Layers, *Michelle Paquette, Andrew Molder, Raja Bale, University of Missouri-Kansas City; Sharmistha Bhattacharjee, Ben Garland, Lehigh University; Nathan Oyler, University of Missouri-Kansas City; Nicholas Strandwitz, Vamseedhara Vemuri, Lehigh University*

Area-selective deposition (ASD) is an important strategy in improving the fidelity of and/or reducing the complexity of current semiconductor patterning processes. Dielectric on dielectric (DoD) deposition is of interest for fully self-aligned via flow; however known DoD processes are limited in terms of materials, selectivities, and processing ranges. A common strategy for achieving ASD is to use a blocking layer on the non-growth surface (e.g., a metal) to be able to deposit a target material selectively on the desired surface (e.g., a dielectric). The most well-established blocking layers are self-assembled monolayers (SAMs) based on long alkyl chains, such as dodecanethiol. While these have demonstrated extremely promising results, they present limitations such as restricted processing windows (e.g., temperature), a typical requirement for solution-phase processing, long exposure times, limited stability (temperature, time, chemical), and presence of defects (e.g., pinholes) resulting from disorder or alkyl chain distortions. We have investigated an alternative class of blocking layers based on aromatic thiol SAMs, sometimes referred to as small molecule inhibitors. We demonstrate how the atomic structure of the aromatic derivative influences SAM formation and blocking ability, and demonstrate improved blocking of typical atomic layer deposition oxide films over state-of-the-art dodecanethiol SAMs.

AP-ThP-17 Thermal Characterization of Carborane Compounds for Advanced Thin Film Deposition, *Michael Stoll, Gyanendra Bhattarai, Rupak Thapa, University of Missouri-Kansas City; Mark Lee, Twelfth Vertex LLC; Nathan Oyler, Michelle Paquette, University of Missouri-Kansas City*

Carboranes, with their unique icosahedral boron-based cage structures, are promising molecular precursors for advanced thin film deposition techniques such as plasma-enhanced chemical vapor deposition (PECVD) and molecular layer deposition (MLD). Their high vapor pressures and chemical stability make them ideal for vapor-phase delivery in high- and ultra-high vacuum systems, enabling the fabrication of ultra-pure films. We report the following thermal properties of a series of carborane compounds: vapor pressure, enthalpy of sublimation, melting points, and specific heat capacities. Using thermogravimetric analysis (TGA) and differential scanning calorimetry (DSC), optimized isothermal and dynamic measurement protocols were developed with benzoic acid as a calibration standard to ensure precision. Vapor pressure curves were constructed, and Antoine coefficients were derived to characterize the compounds over a temperature range suitable for deposition (0.1–10 Torr at <200 °C). The results provide critical insights into the vapor pressures, thermal stability and phase behavior of carboranes, advancing their application in next-generation electronic devices and novel material architectures.

Authors: MS Michael Stoll, PhD Gyanendra Bhattarai, PhD Rupak Thapa, PhD Mark Lee, PhD Nathan Oyler, PhD Michelle Paquette

AP-ThP-18 Atomic Layer Deposition of Iridium from (EtCp)Ir(CHD) and Molecular Oxygen on the Anric AT650P ALD Tool, *Eliza Spear, Anric Technologies; Mughees Khan, Harvard University Center for Nanoscale Systems; Philippe de Rouffignac, Anric Technologies*

Iridium metal films were deposited by atomic layer deposition (ALD) reaction between 1-ethylcyclopentadienyl-1,3-cyclohexadieneiridium(I) [(EtCp)Ir(CHD)] and molecular oxygen at 250 °C in the Anric AT650P ALD tool. The Ir growth rate was 0.5 Å/cycle. Ir films were growth on thermally oxidized SiO_2 with and without a 10 nm Ta_2O_5 interlayer. Ir films grown on Ta_2O_5 appear smoother and more continuous under SEM compared to films on SiO_2 , consistent with a previous report by Schmitt et al. for Ir grown from ALD with $\text{Ir}(\text{acac})_3$ and oxygen, who report that Ta_2O_5 delays Ir nucleation and yields higher substrate coverage compared to SiO_2 [1]. The resistivity of a 42 nm Ir film on Ta_2O_5 was ca. 12 $\mu\Omega\text{-cm}$. Optical properties of iridium films were modeled using variable angle spectroscopic ellipsometry with interference enhancement [2]. An extinction coefficient >5 at 633 nm was obtained for Ir films thicker than 20 nm on Ta_2O_5 .

[1] P. Schmitt et al. Coatings 2021, 11, 173. DOI: 10.3390/coatings11020173

[2] J. N. Hilfiker et al. Thin Solid Films 2008, 516, 7979-7989. DOI: 10.1016/j.tsf.2008.04.060

AP-ThP-19 Plasma-enhanced Atomic Layer Etching of Tungsten Disulfide, *Jeremy Mettler, Justin Boles, Vincent Donnelly, University of Houston*

Transition-metal dichalcogenides (TMDs) are a class of 2D materials of interest for future semiconductor devices due to their favorable scaling properties compared to bulk 3D materials. These materials take the general form of MX_2 , where M is a transition metal such as Mo or W and X is a chalcogen such as S or Se. TMDs are inherently 2D, consisting of in-plane covalently bonded sheets held together by cross-plane van der Waals forces which render the “bulk” monolayer surface-terminated. While these materials hold promise in semiconductor applications, processes for high-volume manufacturing of TMDs remain in the early stages of development. One key challenge is obtaining uniform, monolayer growth of TMD films over large areas, which is currently challenging using CVD growth which often results in the formation of multilayer “islands”. Controllable subtractive processes such as atomic layer etching (ALE) may be useful in etching back these features, yielding large area monolayer films. While some TMDs such as MoS_2 have been more thoroughly studied, other promising materials such as WS_2 require further study to develop at-scale processes for ALE. To achieve ALE of WS_2 in this work, a two-step process was employed. First, films of WS_2 were exposed to fluxes of oxygen radicals in the afterglow of an Ar/O_2 inductively coupled plasma (ICP). In the absence of ion bombardment oxygen radicals removed S from the surface and formed a tungsten oxide layer 1-2 monolayers thick (as measured using in-situ XPS). Next, an Ar/BCl_3 plasma was used to selectively etch the tungsten oxide layer relative to the underlying WS_2 . While no etching was observed in the afterglow, direct exposure to the ICP plasma without substrate bias was able to significantly reduce the tungsten oxide concentration after 10s, with complete removal occurring after ~40s. XPS measurements following the BCl_3 process confirmed the WS_2 film was restored to pre-processing stoichiometry and that the etch process was self-limited to 1-2 monolayers/cycle. Optical emission spectroscopy was used to monitor etchant species, and the BCl_3 was observed to be highly dissociated, primarily forming BCl rather than BCl_2 .

Applied Surface Science

Room Ballroom BC - Session AS-ThP

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AS-ThP-1 EUV Induced Degradation Studies on Reticles by XPS, *Shriparna Mukherjee¹, Alessandro Troglia, Véronique de Rooij-Lohmann, TNO Science and Industry, the Netherlands*

EUV reticles play an important role in the semiconductor manufacturing since their quality directly impacts the resolution and accuracy of the transferred image onto the wafer. This, in turn, affects the performance and yield of the resulting chips. Meanwhile, these reticles are very costly and subject to degradation. Better understanding of degradation mechanisms is therefore necessary to improve the designs and further increase the lifetime. Under the framework of the European project 14ACMOS, TNO develops metrology for reticle degradation assessment. Test samples are produced for metrology studies by inducing degradation on various types of

¹ JVST Highlighted Poster

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reticles. One of the criteria is that the degradation should be non-reversible upon exposure to the ambient, as the samples will be transported to metrology equipment in ambient conditions. Also, it is preferred to have lateral variations and real EUV-induced degradation. Different types of reticles (multilayer blank, absorber blank, patterned reticles) were exposed to EUV at TNO's EUV beam line 2 (EBL2). To facilitate oxidation, water and oxygen were introduced into the exposure chamber. XPS analysis was performed before and after the EUV exposures. Severe oxidation of Ru and Si were primarily observed on the multilayer blank. Moreover, compared to the pre-XPS, the post XPS analysis showed significant decrease in Ru while no such decrease was observed in case of Mo/Si. This might indicate that EUV induced oxidation resulted in intermixing or surface segregation and delamination in the multilayer blanks.

AS-ThP-2 Advanced Characterization of Sputter Induced Effects on the Work Function Using a Combined ToF-SIMS/SPM Instrument, *Bertram Schulze Lammers, Julia Zabel, Andreas Pelster, Derk Rading, Thomas Grehl, IONTOF GmbH, Germany*

The work function is the minimum energy required to remove an electron from a solid surface. This quantity can be directly related to the Fermi level which is of major interest for solid-state physics, material science, and semiconductor applications. Kelvin Probe Force Microscopy (KPFM) combines Scanning Probe Microscopy (SPM) with the electrostatic Kelvin probe method. It can laterally resolve the work function difference between the probing tip and the sample surface together with the corresponding surface topography.

Although the work function describes a macroscopic property of a solid, it may vary locally due to doping, surface contamination or surface oxides. Therefore, clearly defined measurement conditions are required to avoid artifacts and to gain reliable results.

For this work, a combined instrument for time-of-flight secondary ion mass spectrometry (TOF-SIMS) and SPM is used. It enables working under clean UHV conditions, preparation and measurement take place completely in-situ. As mentioned above, the work function of the sample is not measured absolutely but relatively to the probing tip. Once the chemical termination of the tip changes due to e.g. wear or oxidation, the reference is changed, and a general comparison is not possible anymore.

Furthermore, the resulting voltage differences from varying work functions causes additional contributions to the tip-sample force interaction leading also to artifacts in topography measurements. This variation may be sample specific but can also be artificially induced by the ion beam. Separating the work function effect from the topography signal enhances the reliability of the SPM results.

For comparative studies or quality control purposes it is mandatory to control the reference, determined by the termination of the tip. This can be achieved by in-situ tip cleaning, as is performed by the ion sources of the TOF-SIMS. The ion milling removes unknown contaminations and potentially sharpens the tip apex, resulting in a well-defined tip as a reproducible reference.

As a model system, a silicon wafer is bombarded with different doses of different ions, to compare the effect on the work function. Known tip and sample conditions allow a clear correlation between work function variations and the ion bombardment to characterize the sputter induced effects on the work function.

This work demonstrates the possibilities of KPFM for the investigation of implants, doping or compound semiconductors. In addition, it aims at separating the effects of the work function in topographic measurements and therefore remove artifacts.

AS-ThP-3 Effect of Pulse Duration and Multi-shot Ablation in Femtosecond Laser Ablation (fs-LA) XPS Depth Profiling of Indium Phosphide, *Charlie Chandler¹, University of Surrey, UK; Dhilan Devadasan, Simon Bacon, Tim Nunney, Thermo Fisher Scientific, UK; Mark Baker, University of Surrey, UK*

Femtosecond laser ablation (fs-LA) is a newly developing XPS depth profiling technique which avoids the chemical damage observed using traditional monatomic and gas cluster ion beam sputtering [1]. The laser pulse duration plays a key role in determining the involvement (or not) of thermal processes in the ablation mechanism. InP is a thermally sensitive compound semiconductor material, as shown by enhanced preferential sputtering effects being observed when profiled using a gas cluster ion beam compared to a monatomic ion beam [1]. As such, it is a useful test material for studying the effects of laser pulse length on chemical

composition during profiling. fs-LA XPS depth profiles of bulk InP were recorded using a 1030 nm laser for pulse durations varying between 160 fs and 6 ps. To ensure the true chemical composition could be retained at ultrashort pulse lengths, a multi-shot regime at a laser energy below the ablation threshold was required. The effect of laser pulse duration and variation of the number of shots per ablation level on the chemical composition, ablation threshold energy and crater surface morphology during profiling will be presented and discussed.

[1] M.A.Baker et al, *Applied Surface Science* 654 (2024) 159405

AS-ThP-4 Applications of Femtosecond Laser Ablation (fs-LA) XPS Depth Profiling, *Mark Baker, Charlie Chandler, University of Surrey, U.K.; Simon Bacon, Dhilan Devadasan, Adam Bushell, Tim Nunney, Richard White, Thermo Fisher Scientific, UK*

XPS depth profiling is widely employed to determine the chemical composition and offer chemical state information for thin films, thin film devices, coatings, surface treatments and surface degradation processes. Traditionally, XPS depth profiling has been performed through sputtering, using a monatomic or gas cluster ion beam (GCIB). However, many materials suffer from ion beam induced chemical damage during profiling, resulting in distorted chemical compositions and incorrect chemical state information being recorded during the depth profile. Recently, in a new approach to XPS depth profiling, ion beam sputtering has been replaced by femtosecond laser ablation (fs-LA). This new methodology has been shown to offer significant advantages over sputtering: (i) avoidance of chemical damage; (ii) profiling to much greater depths (several 10s microns); (iii) faster profiling speeds; (iv) ease of varying the ablation rate for different materials [1]. Using a 1030 nm wavelength, 160 fs pulsed laser, fs-LA XPS depth profiles will be shown for selected thin films, coatings, devices, surface treatments and oxidised surfaces, demonstrating the capabilities of this new technique.

[1] M.A.Baker et al, *Applied Surface Science* 654 (2024) 159405

AS-ThP-5 Standardless, Semi-quantitative ToF-SIMS depth profiling using the Full Spectrum Method (FSM), *Nicolas Molina Vergara, University of Texas at Austin; John Curry, Tomas Babuska, Sandia National Laboratories; Filippo Mangolini, University of Texas at Austin*

The quantitative evaluation of the depth-dependent chemical composition of thin films plays a pivotal role in the development of novel technologies across several sectors, from electronics to medicine. While Time-of-Flight Secondary Ion Mass Spectrometry (ToF-SIMS) offers exceptional chemical sensitivity and spatial resolution as well as the possibility of acquiring data as a function of depth from the surface (through sputtering), standardless quantification has remained a significant challenge due to matrix effects and the complex physics of secondary ion generation. Here, we demonstrate the first successful implementation of the Full Spectrum Method (FSM) for quantitative concentration depth profiling of inorganic thin films using ToF-SIMS. The FSM approach—though documented in only six publications over two decades—effectively minimizes matrix dependencies by leveraging large ion clusters that incorporate numerous neutral atoms, thereby decreasing the ratio of charged particles per cluster. In this study, we systematically quantified molybdenum, sulfur, and oxygen concentrations in physical vapor deposited MoS₂ thin films with varying stoichiometries. Our ToF-SIMS measurements achieved excellent agreement with complementary Rutherford Backscattering Spectrometry performed on reference samples from identical deposition batches. This validation not only establishes FSM as a viable pathway for standardless, semi-quantitative ToF-SIMS analysis of complex inorganic systems, but also enhances the analytical capabilities of ToF-SIMS for characterizing complex organic specimens, layered structures, and heterogeneous thin films central to emerging technologies in electronics, energy storage, and catalysis.

AS-ThP-6 Insights Into Battery Chemistry Using TOF-SIMS, XPS, and AES, *Jacob Schmidt, Sarah Zaccarine, Amy Ferryman, Physical Electronics USA*

Battery devices are complex, multi-layered systems with many surfaces and interfaces that contribute directly to performance. Increased global energy demands and environmental concerns have driven the need for next-generation battery materials with excellent performance and stability, low cost, and improved safety. But the multi-component interfaces and dynamic nature of these systems leads to challenges with their characterization. Developing new materials and technologies to meet energy storage needs requires physicochemical characterization approaches with high-spatial resolution, chemical and morphological information, and correlation of properties.

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Time-of-flight secondary ion mass spectrometry (TOF-SIMS), X-ray photoelectron spectroscopy (XPS), and Auger electron spectroscopy (AES) are complementary techniques that, when utilized together, can provide a holistic understanding of complex systems such as batteries. TOF-SIMS offers ppm-level insight into molecular bonding and structural composition, and allows for a wide variety of samples, both in composition (organic or inorganic) and in format (powders, thin films, electrodes). AES provides high-spatial-resolution spectra, images, and maps for nm-range analysis of defects and small sample features. XPS and hard X-ray XPS (HAXPES) can be used to obtain short-range chemical state information. Additionally, these multi-technique instruments have features beneficial to battery device analysis including air-free handling via an inert environment transfer vessel; co-located images, and in-situ/operando analysis of chemical changes as they occur. By using these complimentary techniques, the mass spectra, elemental and chemical-state maps, sputter depth profiles, and electronic structures can all be determined. This poster will highlight these powerful combined capabilities on a range of battery materials that can be used to drive next-generation stability and performance.

AS-ThP-7 Update on New Guides and Tools to Encourage and Facilitate Generation and Reporting of Reliable and Reproducible Information Using Surface Analysis Methods, *Don Baer, Lyndi Strange*, Pacific Northwest National Laboratory

A review of recent literature has revealed several common flaws and limitations in surface analysis using various methods, particularly XPS, as well as a notable deficiency in reporting critical sample, instrument, and analysis parameters essential for assessment of the reported information by readers and any efforts to replicate the results. The core assumption is that new and casual method users want to do quality research, but with the increasing number of techniques involved in many research activities, it is a challenge to have expertise for each method. Multiple efforts have been made in response to the identified problems, each intended to provide easily accessible and useful information and tools that can assist an analyst in avoiding the limitations and faulty analyses found in the literature. This poster will provide updated information on some of these efforts. Topics to be addressed include: 1) as a reviewer or reader, you do not need to be an XPS expert to recognize many peak fitting and analysis issues in XPS, 2) an overview of topics addressed in the topical paper collections Reproducibility Challenges and Solutions I and II appearing in the Journal of Vacuum Science and Technology A, 3) an overview of the topics discussed in the shorter Notes and Insights papers now appearing in Surface and Interface Analysis, 4) information about a series of detailed instrument papers starting to appear in Surface Science Spectra to help with instrument parameter reporting and providing descriptions of instrument operation modes, 5) overview of two new ISO standards for reporting on the selection, handling, storage and preparation of samples for surface analysis to be recorded and included as part of sample provenance information, and 6) other journal and web-based papers and platforms intended to assist peak fitting, parameter reporting and error identification.

AS-ThP-10 XPS Characterization of Thiol-Carbazole Self-Assembled Monolayers for Work Function Modulation in Organic Electronics, *Mohamed Nejib Hedhili, Yu-Ying Yang, Shadi Fatayer, Martin Heeney, King Abdullah University of Science and Technology (KAUST), Saudi Arabia*

Tuning electrode work functions through self-assembled monolayers (SAMs) is a key strategy for optimizing charge injection in organic electronic devices. In this work, we investigate the interfacial chemistry of thiol-carbazole SAMs bearing bromo (Br) and tert-butyl (tBu) substituents using X-ray photoelectron spectroscopy (XPS) and correlate the findings with changes in the gold work function. XPS confirms successful chemisorption of all SAMs onto Au through characteristic S 2p peaks near \sim 162.0 eV, indicating formation of Au-S bonds. Despite similar anchoring, the electronic nature of the substituents significantly influences the resulting interfacial dipole. The electron-withdrawing Br group in Br-2SCz induces a strong upward shift in the gold work function by $+0.71$ eV, reaching \sim 5.48 eV, which favors hole injection. In contrast, the bulky electron-donating tBu group in tBu-2SCz lowers the work function to \sim 4.52 eV, enabling improved electron injection. These results highlight how molecular substituents can modulate the electrostatic landscape at the metal interface, offering a precise method for controlling energy level alignment in organic semiconductor devices.

AS-ThP-11 Study of F2 Thermal Etching combined Remote Plasma treatment for Channel Release in Process of Gate-all-around FET, *Junjie Li, Institute of Microelectronics of Chinese Academy of Sciences, China; Mingmei Wang, Lam Research Corporation*

Introduction: Gate-all-around (GAA) transistor will replace fin field-effect transistor (FinFET) in technology nodes below 3nm compared with FinFET process[1], GAA process mainly adds three process modules, among which channel release is extremely important. This step requires complete removal of the SiGe sacrificial layer while preserving the Si channel. Although some excellent SiGe selective etching methods have been reported such as gas-phase etching[2] or remote plasma source (RPS) etching [3], However, most of these literatures focus on optimizing etching profile, yet rarely mention the interface state of the Si channel after etching. In this article, we focus on the morphology after different etching depths, obtain interface state density through different schemes, and ultimately develop gate-all-around devices (GAA) to study the effects of different schemes on the electrical characteristics of the devices. This study provides insights and references for the industry in selecting channel release methods.

Results and Discussion: Figure 1 shows the morphology obtained by combining F₂ gas reaction with remote plasma source at different etching depths, and the results show good morphology control from 5nm to 50nm. Figure 2 shows that the scheme exhibits high etching selectivity under high-resolution transmission electron microscopy, and the channel atoms remain intact. Figure 3 shows that adding RPS processing can reduce the interface state. Figure 4 shows the channel of the GAA device released by the combination of F₂ gas and RPS, and the electrical characteristics are better than those released by F₂ alone (with lower subthreshold (ss) characteristics). Conclusion: We propose a new etching method combining F₂ gas and remote plasma, which respectively helps enhance channel mobility and improve subthreshold swing (SS). This offers references and insights for path finding in channel release method and facilitates the volume manufacturing of GAA.

Reference:

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AS-ThP-12 Which Instrument Should You Use for High Lateral Resolution Chemical Analysis - SEM/EDS or ToF-SIMS?, *Vincent Smentkowski, Deliang Guo, GE Vernova Advanced Research Center; Felix Kollmer, ION-TOF GmbH, Germany*

Scanning electron microscopy (SEM) coupled with energy dispersive spectroscopy (EDS) is often the instrument of choice when researchers desire rapid high lateral resolution chemical analysis. Time of flight secondary ion mass spectroscopy (ToF-SIMS) instrumentation has matured over the past few decades – state of the art instruments can now perform rapid high lateral resolution chemical analysis of all elements (including H and Li), however its use as a microscopy technique is often overlooked.

BAM-L200, is a certified reference material prepared from a cross-sectioned epitaxially grown layer stack of Al_(0.70)Ga_(0.3)As and In_(0.2) Ga_(0.8)As on a GaAs substrate. The surface of the cross sectional BAM-L200 sample provides a flat pattern with layer widths down to 1 nm. Calibration distances, grating periods and layer widths have been certified by TEM with traceability to the length unit. The combination of gratings, isolated narrow lines and sharp edges of wide lines offers plenty of options for the determination of lateral resolution, sharpness and calibration of length scale for analytical instruments.

In this poster, we will compare line scan traces generated using ToF-SIMS and EDS on a SEM. We will show that the lateral resolution using the 20% 80% rule, is 21 nm for ToF-SIMS and 54 nm for EDS. In addition to being faster and providing higher lateral resolution imaging, ToF-SIMS also allows for the collection of a full mass spectrum (all elements from H to U, and high mass molecular fragments) at every volume element; ToF-SIMS also has much higher chemical sensitivity (detection limit for most elements is in the ppm to ppb range); and ToF-SIMS does not require the deposition of a thin conductive coating.

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AS-ThP-13 Time Evolution of Chemical Reactions During Aluminium Oxide

Atomic Layer Deposition on InAs, Eleni Charitoudi, Nishant Patel, Sina Ritter, Lund University, Sweden; Rosemary Jones, Max IV Laboratory, Sweden; Joachim Schnadt, Lund University, Sweden; Esko Kokkonen, MAX IV Laboratory, Sweden; Rainer Timm, Lund University, Sweden

In this project, we are studying the atomic layer deposition (ALD) of Al_2O_3 on InAs. The interest in this system stems from the intrinsic properties of III-V semiconductors for electronic applications. Specifically, InAs has a narrow, direct band gap and high electron mobility, making it a good candidate to outperform Si-based Metal Oxide Semiconductor Field Effect Transistors (MOSFET) regarding speed and power consumption¹. The detrimental native oxide should thereby be replaced by a so-called high-k oxide such as Al_2O_3 , allowing a smaller gate size. However, the performance of this system is limited due to high defect density in the InAs/ Al_2O_3 interface², which is related to incomplete removal of the native oxide layer. The precise deposition of Al_2O_3 on InAs is achieved through the ALD process, enabling the production of thin films with atomic-scale precision. It is characterized by its layer-by-layer mechanism and self-limiting interaction of two gaseous precursors with the substrate³. In our case, two half-cycle depositions were performed using trimethylaluminum (TMA) and water as precursors. A common method to study the chemical composition and interface quality of ALD films is to perform X-ray photoelectron spectroscopy (XPS) measurements after the entire process or after each half-cycle. Here, we went a step further and used ambient pressure XPS (AP-XPS) to observe time-resolved surface chemical reactions occurring during the ALD half-cycles. For this purpose, the ALD process was implemented in the ALD cell of the SPECIES beamline at the MAX IV Laboratory⁴.

During the first half-cycle, i.e. the deposition of TMA, the As-oxide was removed entirely, simultaneously with the formation of Al components and organic TMA ligands on the sample surface. In contrast, the In-oxide decreased, but still a small amount remained at the interface. Also, it was observed that the formation of Al_2O_3 started already during the initial TMA deposition. During the water deposition, a slight increase in In-Oxide was taking place, indicating the reoxidation of the InAs/ Al_2O_3 interface, which is in contrast to the findings from previous AP-XPS studies of HfO_2 ALD on InAs⁵. These results help to understand the reaction dynamics of ALD processes and the role of the metalorganic precursor, as well as to improve the interface in future MOS-based electronics.

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AS-ThP-14 Enhanced Sensitivity in Low-Energy Inverse Photoemission Spectroscopy with an Off-Axis Parabolic Mirror for Efficient Light Collection, Jong-Am Hong, Kyu-Myung Lee, Min-Jae Maeng, Yongsup Park, Kyung Hee University, Republic of Korea

Inverse photoemission spectroscopy (IPES) is a powerful tool for investigating unoccupied electronic states where the electron beam is incident upon the sample and the emitted photons are detected. However, its broader application is hindered by inherently low sensitivity, caused by the low probability of photon emission during the transition of free electrons to the unoccupied states. To enhance sensitivity through improved photon collection, an off-axis parabolic (OAP) mirror is designed and fabricated for the low-energy version of the IPES (LEIPS). Optical simulations showed that the OAP mirror increased photon collection efficiency from 3.06% to 63.3%, which is experimentally validated in the lowest unoccupied molecular orbital (LUMO) spectra of C60 thin films. The OAP mirror-LEIPS system is applied to study the energy level alignment (ELA) of pentacene films on substrates with different work functions (WF). By measuring both the highest occupied molecular orbital (HOMO) and LUMO levels, the evolution of transport gaps and the ELA of HOMO and LUMO with the Fermi level are analyzed. Pentacene exhibited n-type behavior on a low WF substrate (Cs_2CO_3) and switched to p-type on a high WF substrate (ITO). The OAP mirror-enhanced LEIPS system significantly reduced the time required for such experiments, enabling efficient and reliable measurements.

Biomaterial Interfaces

Room Ballroom BC - Session BI-ThP

Biomaterial Interfaces Poster Session

BI-ThP-1 Antifouling Properties of Plastron Forming, Ultra-Porous, Superhydrophobic DCP- and PFPE-Based Coatings, Georg Friedrich Breilmann, Louisa Vogler, Onur Özcan, Axel Rosenhahn, Ruhr-University Bochum, Germany

One key problem of humanity for several thousand years has been biofouling. It occurs on artificial surfaces by creating biofilms consisting of organic matter, such as proteins, lipids or bacteria within seconds after immersion into seawater.^[1,2] In addition, macrofoulers, e.g. algae or barnacles can attach and form slimy layers on the surfaces.^[3,4] Biofouling has several detrimental consequences such as higher greenhouse gas emissions during propulsion, transfer of invasive species, and an increased work required to maintain immersed surfaces, all affecting both economy and environment.^[5] To combat the formation of biofouling we created superhydrophobic surfaces (SHSs), which form a protective air layer between water and the submersed surface, so called plastrons. Five ultra-porous SHSs with different porosities, three based on ethylene glycol dicyclopentenyl ether methacrylate and two based on perfluoropolyether urethane methacrylate, were prepared by introducing porogens during the polymerization process. The coatings were tested regarding their superhydrophobicity, plastron formation, and plastron longevity. The wettability was analyzed by static and dynamic water contact angle goniometry to determine the wetting hysteresis as important quantities that characterize the ability of the terminating molecules of the coatings to reorientate once in contact with water. In addition, the water sliding angle was determined as an important property characterizing superhydrophobicity. Furthermore, the plastron forming and retaining properties of these SHSs were characterized by the visual plastron coverage, and the antifouling performance (AF) was tested in static attachment assays using the diatom *Navicula perminuta*. Additionally, the AF performance was investigated for fully functional plastrons, plastrons that were maintained for seven days by joule heating, and coatings on which the plastron decayed during this period.

References

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BI-ThP-2 Surface Sterilization by 260-280 nm Ultra-Violet C LEDs : Reducing the Probability of One Remaining Pathogen On A Surface to Less Than 10^{-6} – a Reproducibility & Accuracy, Aarav Sathish, Arizona State University, SiO2 Innovates LLC, Arizona State University; Nicole Herbots, University of Missouri Kansas City, Arizona State University, University of California Santa Cruz; Arjun Prabhu, Arizona State University; Anya Arun, SiO2 Innovates LLC; Zaid Abu-Salah, University of Missouri Kansas City, SiO2 Innovates LLC; Viraj Amin, University of Missouri Kansas City, SiO2 Innovates LLC, Arizona State University; Nachiket Rajinikanth, University of Missouri Kansas City, SiO2 Innovates LLC; Aditya Tyagi, SiO2 Innovates LLC; Yash Soni, SiO2 Innovates LLC, Arizona State University; Kush Patel, SiO2 Innovates LLC, Arizona State University, University of California Santa Cruz; Ashwin Suresh, SiO2 Innovates LLC, Arizona State University, University of Arizona; Shreyash Prakash, SiO2 Innovates LLC, Arizona State University; Nimith Gurijala, SiO2 Innovates LLC, Arizona State University, Washington University in St. Louis; Siddharth Jandhyala, SiO2 Innovates LLC, Arizona State University, Duke University; Arjun Sekar, SiO2 Innovates LLC, Northwestern University; Srivatsan Swaminathan, SiO2 Innovates LLC, Arizona State University, Ichan School of Medicine at Mount Sinai; Eric Culbertson, SiO2 Innovates LLC; Robert Culbertson, Arizona State University Antimicrobial resistance (AMR), hospital-acquired infections (HAI) and outbreaks are rising. 3M of AMR infections kill 50,000/y in the US and 1.3 M/ globally. AMR is projected to surpass cancer as the leading cause of death by 2050. Viral outbreaks now occur approximately every two years – twice as often as in the past 200 years: H1N1 (2009), MERS (2012), Ebola (2014), Zika (2015), and Covid (2019).

Effective surface sterilization must be rapid, reliable, safe, easy-to-deploy, and low-cost to address these issues. Sterilization, as defined by the US FDA, the EU and the International Standard Organization (ISO) is reducing

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the 'probability for a single viable microorganism to less than 10^{-6} ', a Sterility Assurance Level (SAL) of 6. Accepted methods (vaporized hydrogen peroxide (VHP), Ethylene Oxide(EtO), gamma irradiation (g), or autoclaving) cannot be used in public and hospital spaces, due to environmental, time, materials, and energy costs .

UVC irradiation eradicates pathogens by breaking bonds in nucleic acid pairs in DNA/RNA in water disinfection (SAL = 3) via 253.7 nm UVC fluorescent tubes. This work investigates whether low-cost low power LEDs can sterilize surfaces rapidly and reliably using *Lactobacillus Acidophilus*. (*Lacto. A*) as test pathogen and 260-280 nm UVC LEDs arrayed in a 4 cm² square with a power density of $0.8 \pm 0.04 \text{ mW/cm}^2$ at 1 cm via two experiments, A and B. Two sets of *Lacto. A*. solutions are calibrated to a concentration of 1×10^7 and 2×10^7 Colony Forming Units (CFUs)/mL, and then serially diluted from 1.0×10^9 to 1.0×10^9 . In A and B, three sets of 10 agar plates are inoculated. The control set, 'No UVC' is compared to 2 irradiated sets, 'UVC1 and 2'. One half of the surface of each plate in UVC 1 and 2 is irradiated for 180 s, the other half left unirradiated.

Irradiation for 3 min yields an energy density of $144 \pm 7 \text{ mJ/cm}^2$ on a 4 cm² square area with 2.5×10^5 CFUs/mL on the surface in A and 5×10^5 CFUs on the surface in B. In A, at a distance of 1.5 cm, 94 ± 1 CFUs are left on the UVC1 culture set and 9 ± 3 CFUs on the UVC2 culture set. Thus, an average of 52 CFUs remain after UVC irradiation. This yields an SAL of 4. In B, at a distance of 1cm, UVC irradiation leaves an average of 7.5 CFUs remaining. This yields an SAL of 5. Therefore, UVC LEDs irradiation can consistently reach SALs above 3. The energy density at 1 cm needs to be increased by a factor of 10 to achieve sterilization with a SAL of 6, thus to $1.4 \pm 1 \text{ J/cm}^2$. This can be achieved by increasing the UVC LED power density to 8 mW/cm², or extending the duration of UVC exposure to 30 min.

BI-ThP-3 Dynamic Bonding (Dybonding) in DPD for Simulating DNA Hybridization and Self-Assembly, *Christina Bayard*, Yaroslava Yingling, North Carolina State University

Many problems modeled using Dissipative Particle Dynamics (DPD) require the ability to simulate chemical reactions, such as polymerization, cross-linking, DNA hybridization, and ligand-receptor binding, to accurately capture mesoscale phenomena in soft and biological materials. However, standard DPD force fields are inherently non-reactive, limiting their applicability to systems where bond formation or chemical specificity plays a critical role. In this work, DPD was utilized to explore how initial conditions influence the formation of Quantum Dot (QD)-DNA assembled condensates, a system driven by DNA hybridization between QDs functionalized with complementary strands. To address the computational challenge posed by modeling reactive behavior with inherently non-reactive force fields, we implemented an internally developed method called dynamic bonding (dyBonding), deployable within the Large-scale Atomic/Molecular Massively Parallel Simulator (LAMMPS) simulation package. DyBonding enables selective, permanent bond formation based on distance and probabilistic rules between defined bead types. We further refined the approach to support directional, strand-specific bonding, allowing for complete DNA hybridization. This tailored approach offers a robust and efficient solution for modeling chemically reactive processes in DPD, expanding its applicability to a broader range of self-assembling and biofunctional systems. These novel methodologies substantially improve computational precision and expand the functionalities of widely used simulation packages such as LAMMPS. Enhanced understanding of nucleic acid interactions across multiple spatial and temporal scales enables the design of advanced materials for applications in drug delivery, therapeutics, and beyond.

BI-ThP-4 Plasma Diagnostics for the Modification of Naturally Derived Biopolymers, *Bethany Yashkus*, Mollie Corbett, Joshua Blechle, Wilkes University

Naturally derived biopolymers such as silk fibroin and chitosan show promise for use in biomedical devices due to their mechanical strength and slow degradation profile. Because these polymers are naturally hydrophobic, limitations in cell adhesion present challenges in applications that require short term degradation. To combat this, the surfaces of these materials are being altered using various inductively coupled plasma modification techniques. Surface analysis has shown that utilizing polymeric precursors with polar functionality, such as acrylic acid, can deposit a thin hydrophilic coating over the surface through plasma enhanced chemical vapor deposition (PECVD). Molecular precursors, such as N₂, have also been used to alter hydrophilicity by introducing polar groups to the surface via plasma functionalization. In this work, acrylic acid treatments reduce the water contact angle (WCA) of silk fibroin from 75° to

47°, whereas nitrogen plasma treatments reduce WCAs from 75° to 40° for silk and 95° to 25° for chitosan.

To achieve a significant change in chitosan WCA, treating the sample for two minutes with a 25 mTorr, 115 W N₂ plasma containing 10% Ar has proven effective. In addition, when the films are casted on glass slides, the observed WCA of the glass is highly correlated with the WCA of the biopolymer. This suggests a synergy between the film and the underlying material. Due to these complex relationships, predicting ideal treatment conditions is not possible. Because little is known about the mechanisms that drive these surface modifications, optical emission spectroscopy (OES) is being employed to observe gas phase species during treatments and make diagnostic calculations such as species densities and vibrational temperatures. By cataloguing the trends in plasma species behavior with and without the presence of the biopolymer, key mechanistic contributors can be identified. Such insights allow for fine procedural adjustments, ultimately leading not only to desired surface outcomes but to reproducible plasma conditions.

BI-ThP-5 Effect of Surface Oxidation on Carbonic Anhydrase Immobilization on Graphene Oxide: A Molecular Dynamics Study, *Merve Fedai*, Albert Kwansa, Youngwoo Hwang, Jialong Shen, Sonja Salmon, Yaroslava Yingling, North Carolina State University

Carbonic anhydrase (CA) enzymes, which catalyze the conversion of carbon dioxide (CO₂) to bicarbonate (HCO₃⁻), are promising candidates for improving the efficiency of existing carbon capture processes. However, their natural forms often lack the stability needed to maintain high activity over extended periods, especially under harsh industrial conditions. Immobilizing enzymes on surfaces is a widely used strategy to improve their durability and reusability. Experimental studies have shown that surface attachment can help overcome stability limitations, provided that catalytic activity is preserved. Graphene (GRA) and graphene oxide (GO) are effective matrices for enzyme immobilization due to their simplicity as model surfaces, electrical conductivity, and tunable surface chemistry. To examine the molecular-level interactions of this biomaterial system, all-atom molecular dynamics (AMD) simulations were performed. CA was modeled in contact with both GRA and GO surfaces to evaluate how surface chemistry affects enzyme structure and function. Various GO surfaces were constructed with oxidation levels ranging from 0% to 68% in 5% increments using a custom-built workflow for a systematic investigation of how surface oxidation modulates enzyme-surface interactions and potentially influences catalytic behavior. The simulations showed that oxidized GO surfaces form stronger hydrogen bonds and electrostatic interactions with CA, which help maintain the enzyme's structure, particularly near the active site. In contrast, GRA surfaces exhibit weaker binding, which may offer less stabilization but create fewer barriers to CO₂ diffusion. In addition to structural effects, the simulations revealed differences in CO₂ diffusion into the enzyme's active site. While GO enhances structural stability, stronger interactions may slightly restrict substrate access. GRA, on the other hand, allows faster diffusion but provides less structural support. Previous work with a different biomolecule suggested that GO oxidation levels between 15–25% yielded the best performance for biomaterial applications. However, due to the greater rigidity of CA, it remains uncertain whether the same range leads to optimal interaction and activity. These findings demonstrate that biomolecule-specific surface oxidation levels can be tuned to optimize enzyme performance.

BI-ThP-7 Differential Detection of Viral and Bacterial Infections by Macroscopic Epi-Fluorescence Combining DNA and RNA Specific Stains, *Nithish Prakash*, Sudharshini Ram, David Guo, Arizona State University / SiO2 Innovates LLC / InnovaBug LLC / Microbe Lab-On-Chip LLC; Viraj Amin, SiO2 Innovates LLC / Innovabug LLC / University of Missouri - Kansas City (School of Medicine) / Microbe Lab-On-Chip LLC; Arya Saravanan, Sriram Rajesh, Nila Kathiravan, Arizona State University / SiO2 Innovates LLC / InnovaBug LLC / Microbe Lab-On-Chip LLC; Robert J. Culbertson, Arizona State University; Eric J. Culbertson, SiO2 Innovates LLC / Microbe Lab-On-Chip LLC; Nicole Herbots, Arizona State University / SiO2 Innovates LLC / InnovaBug LLC

Six viral outbreaks in the last 15 years increased the need for viral detection at a triage level to contain these outbreaks. Standard viral diagnostics with rapid antigen testing yield ~58% False Negatives (FNs), and plaque assays take days to weeks for results. Annually, misdiagnosed infections cost hospitals \$4.6 Billion, and antimicrobial resistance results in 35,000 deaths.

This work aims to reduce misdiagnoses to <10%, the gold standard, in detecting viral infections in 0.1mL of biofluids - blood, urine, etc. One fluorescent stain for bacterial DNA and one for viral RNA are combined to

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detect and distinguish bacterial and viral infections using Macroscopic DNA/RNA Epifluorescence (MaDRE). These stains were used with flattened drops on a *super hydrophilic* strip with ~ 1.5 mm diameter, $100\ \mu\text{m}$ thin film, and surface area of $\sim 1.8\ \text{cm}^2$, in order to prototype a low-cost, hand-held Small Blood Volume Diagnostic (SBVD) device, ViroBugTM.

7×10^{10} Colony Forming Units (CFU)/mL of a benign virus, *T4 Bacteriophage*, are serially diluted into 10 solutions. $0.5\ \text{mL}$ of each of the 10 dilutions ($1.0, 10^{-1}, 10^{-2} \dots 10^{-9}$) is combined in a 1:1 ratio of undiluted 7×10^{10} CFUs/mL benign *E. Coli* bacteria host cells. As a control, each *T4 : E. Coli* mix is tested via plaque assays. Six identical $0.1\ \text{mL}$ drops of each *T4 : E. Coli* mix are applied onto test strips. $0.1\ \text{mL}$ of safe green DNA-specific fluorescent dye is applied to the drops and photographed under $470\ \text{nm}$ of blue light. Third, 0.1mL of safe red RNA-specific fluorescent dye is added to be fluoresced and imaged.

The ratio of green bacterial fluorescence (R_G) over blue illumination (R_B) and the ratio of red viral fluorescence (R_R) over green bacterial fluorescence (R_G) are calculated via a self-built app, FastRGBTM. Raw ratios R_G/R_B and R_R/R_G are calibrated with background fluorescence to reduce photo-detector error, yielding $R_{G\text{Net}}$ and $R_{R\text{Net}}$.

After analyzing 80 drops, $R_{G\text{Net}}$ is 4.5 ± 0.3 with a relative error e of $\pm 7\%$. When *T4* is diluted to 10^{-9} , $R_{G\text{Net}}$ increases to 12 ± 2.6 , with a bacterial load of 5×10^8 CFUs/mL with e of $\pm 33\%$. Meanwhile, $R_{R\text{Net}}$ decreases from 1.8 ± 0.2 for 5×10^8 CFUs/mL for *1.0 T4 Phage* to 1.3 ± 0.06 for 50 CFUs/mL at 10^{-9} *T4 Phage* dilution.

$R_{G\text{Net}}$ correlation with *T4* load is 0.94 while $R_{R\text{Net}}$ correlation is 0.96 . Bacterial fluorescence ($R_{G\text{Net}}$), indicative of host cell survival, increases with decreasing viral load. Across 80 drops, 2 were identified as outliers, yielding an error rate of 2.5% . ViroBugTM produces rapid and accurate diagnoses using biofluid samples, fluorescent dyes, and automated color analysis.

BI-ThP-9 Impact of Marine Biocides on Early Biofilm Community Development, *Kailey Richard*, Naval Research Laboratory; *Sara Tuck, Kenan Fears*, Naval Research Laboratory, USA

Biofouling, the accumulation of unwanted flora and fauna on submerged assets, is an ongoing challenge within the maritime industry. Biofouling build-up increases fuel consumption, drag coefficients, and operational costs in addition to facilitating the transfer of environmental and pathogenic bacteria from one location to another. Antifouling coatings are the typical method for biofouling control with copper being the main constituent. In biological systems, copper is tightly regulated and, and to exploit this, some antifouling coatings contain high amounts of copper (I) oxide. Despite these high loadings, the efficacy of these coatings is rapidly declining with the emergence and spread of copper tolerant species.

Microbial communities have been found to form dense communities on these high copper loaded coatings suggesting resistance and speculated to lay the foundation for subsequent fouling. Therefore, new alternatives are being used to combat this. To gain an understanding of the mechanisms responsible for the loss of antifouling performance, coated and uncoated polyvinyl chloride panels were deployed at field sites to harvest early biofilms. From these collections, we isolated, cultured, and identified bacterial species. Biocide tolerance profiles were developed by re-exposing individual colonies to four different biocides on microdiluted agar and broth solutions.

BI-ThP-10 Impacts of Substrate Type on Barnacle Morphology Using Microcomputed Tomography, *Brittney Mitchell, Beatriz Orihuela*, Duke University; *Gary Dickinson*, The College of New Jersey; *Daniel Rittschof*, Duke University

Barnacle biofouling poses significant environmental and economic challenges. A deeper understanding of the barnacle-substrate interface provides insights into barnacle physiology, adhesive performance and substrate contributions. Here, we leverage microcomputed tomography (μCT) to non-destructively characterize the interface and investigate how natural and engineered substrates influence barnacle morphology including adhesive plaque and plate development. Our reconstructions reveal that substrate topography affects barnacle morphology. Changes to the adhesive plaque and exoskeletal plates on planar surfaces and across surface boundaries suggest barnacle morphologies are responsive to some substrate chemistries. We find calcium containing substrates undergo corrosion and erosion, which we hypothesize is related to calcium uptake into barnacle exoskeletons. Overall, these findings underscore the morphological adaptability of barnacles in response to physical, topographic and chemical substrate properties. Insights into these

interactions at the interface could help guide material selection and manufacturing in biofouling applications.

Chemical Analysis and Imaging at Interfaces

Room Ballroom BC - Session CA-ThP

Chemical Analysis and Imaging at Interfaces Poster Session

CA-ThP-1 Depth Profiling of Perovskite Tandem Solar Cells Using Small Ar Gcib in Cluster Sims at Cryogenic Temperatures, *Kate McHardy, Naoko Sano, Mark Mills*, Ionoptika Ltd., UK

Many Secondary Ion Mass Spectrometry (SIMS) instruments can perform at cryogenic temperatures, however, complex sample handling requirements and high cryogen consumption have meant that such experiments have hitherto been expensive and complicated. Utilising Ionoptika's J Series III cluster SIMS instrument with Cryo stage, we show that long-term Cryogenic studies may be carried out on both soft and hard materials, with demonstrable improvements in results compared to RT analysis. We demonstrate 3D depth profiling of perovskite solar cells and show that the precision of the depth profile is increased at Cryo temperatures when compared with RT analysis. The current common approach to analyse such samples is to peel off the hardest capping layer and then analyse the perovskite layers using Ar GCIB to sputter and Bi to analyse. Alternatively, a Cs beam may be used to sputter to just above the interface, and then low energy an Ar GCIB and Bi beam used for sputtering and analysis. However these approaches are flawed; the peeling process can cause migration of elements to the free surface, and Cs and monoatomic Ar sputtering can cause intermixing of consecutive layers. The J Series III Cluster SIMS system employs GCIB as the primary ion beam which can sputter and analyse simultaneously, meaning no sputter-only cycles. For thin layers, this is crucial, as it precludes loss of information about the layers and/or interface. In addition, the GCIB used has a high (70 kV) beam energy and provides a range of cluster sizes from monoatomic to large cluster sizes such as 30k. We have previously demonstrated use of smaller cluster beams to sputter through $1.5\ \mu\text{m}$ thickness of perovskite solar cell samples from the capping layer to the glass substrate with less preferential sputtering and intermixing effects. Therefore, J Series III analysis using a small cluster GCIB promises to show more 'genuine' information than the current dual beam method for hard and mixed materials including metals and organics. In this work, pristine and aged samples of perovskite tandem solar cells are analysed with an Ar350 Cluster at 70 keV beam in the J Series III at RT and cryo temperatures to demonstrate the suitability, less intermixing effect and lack of preferential sputtering especially at cryo temperatures that show higher depth resolution and sputter rate with less damage. We conclude that analysis of hybrid semiconductor samples results in superior data when conducted with small clusters at Cryogenic temperatures.

CA-ThP-2 Uncovering Coke-Resistant Two-Dimensional Metal Carbide Catalysts Using ToF-SIMS, *Tobias Misicko*, Louisiana Tech University and Oak Ridge National Laboratory; *Gabriel Parker*, Oak Ridge National Laboratory; *Yang Xiao*, Louisiana Tech University; *Xiao-Ying Yu*, Oak Ridge National Laboratory

Catalysts can be described by three important aspects: activity, selectivity, and stability. Activity is the ability of a catalyst to convert reactants into products. Selectivity is the ratio of the desired product to the total amount of converted molecules. Stability is the ability of a catalyst to maintain activity with respect to time on stream (TOS, time since initial contact of reactant gas to the catalyst bed) in continuous reactors. MXene, a class of two-dimensional metal carbides, can be used as a support material to create a coke-resistant nanolayer catalyst with excellent activity, selectivity, and stability. MXene has empirical formula of $M_{n+1}X_nT_x$, where M is an early transition metal, X is a carbon or nitrogen, and T is a surface functional group (such as F^- or OH^-). In our prior studies,^[1,2] platinum (Pt) was loaded onto Mo_2TiC_2 MXene using incipient wetness impregnation to synthesize a 0.5% (wt.) Pt/ Mo_2TiC_2 Pt nanolayer MXene catalyst. The Pt nanolayer catalyst exhibited excellent activity with turnover frequencies (TOFs, converted molecules per surface Pt atom) of $0.4 \sim 1.2\ \text{s}^{-1}$ for converting methane^[1] and ethane^[2]. 0.5% Pt/ Mo_2TiC_2 displayed high selectivity, with over 98% to C_2 products for non-oxidative coupling of methane (NOCM) and over 95% selectivity for catalytic dehydrogenation of ethane to ethylene. Robust catalyst stability is obtained with no loss in catalytic activity for 72 hr. and 24 hr. for NOCM and ethane dehydrogenation, respectively, owing to its strong coke-resistance. However, the active site and surface activity are not easy to study. In this presentation, we used

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time-of-flight secondary ion mass spectrometry (ToF-SIMS) to investigate MXene catalytic effects. ToF-SIMS is a highly sensitive surface analysis technique, capable of molecular, atomic, and isotopic analysis. Depth profiling and mass spectral mapping allow for analysis of subsequent monolayers of the catalyst's surface. Measurements, including surface spectra, two-dimensional imaging, secondary electron imaging, and depth profiling (three-dimensional imaging), were used to probe the surface and reveal structures of both unloaded Mo_2TiC_2 MXene support and 0.5% Pt/ Mo_2TiC_2 nanolayer MXene catalysts. The large dispersion of Pt^+ ions throughout the bulk of Pt/ Mo_2TiC_2 nanolayer MXene supports the hypothesis that the MXene channel prohibits access to the terrace site, a critical site for the structure-sensitive coking reaction.

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CA-ThP-4 Tapping into Charge Storage with Operando-XPS using Coplanar Capacitors and Ionic Liquid Mixtures, Ezgi Kutbay, Sefik Suzer, Bilkent University, Turkey

We use X-Ray Photoelectron Spectroscopy under bias to track surface population and electrical potentials on multilayered graphene electrodes with two ionic liquid mixtures, one containing the same cation (DEME+) and two different anions (TFSI- and BF4-) and the other one with two different cations (DEME+ and Rb+) and same anion (TFSI-). As bias increases, peak intensities change and binding energies shift, revealing both ion concentrations and also the local electrical potentials simultaneously. In addition the capacitance of the device increases significantly, providing crucial insights for developing new energy storage devices.

CA-ThP-6 Meeting the Demand for Surface Sensitivity: The Role of LEIS, Joshua Pinder¹, Brigham Young University; Stanislav Prusa, Central European Institute of Technology, Czechia; Matthew Linford, Brigham Young University

Low-Energy Ion Scattering (LEIS) provides unmatched sensitivity to the outermost atomic layers of materials, making it a critical tool for surface analysis. This poster presents a practical guide to LEIS spectral interpretation, featuring spectra from a diverse range of materials. While covering key theoretical aspects, the focus remains on practical insights for researchers who rely on LEIS data, whether through collaboration or literature. Topics include surface peak identification, reionization effects, multiple scattering, contamination impacts, and material-specific spectral features. Spectra from modern high-sensitivity LEIS instruments illustrate both fundamental and advanced phenomena across various materials of technological interest. By clarifying LEIS spectral characteristics and applications, this guide aims to enhance accessibility and understanding within the broader scientific community.

CA-ThP-7 Mass Spectral Molecular Mapping Shows Benefits of Thermal Evaporation in Prelithiated Silicon-Based Composite Electrodes, Ivan Matyushov², Gabriel Parker, Amanda Musgrove, Gabriel Veith, Xiao-Ying Yu, Oak Ridge National Laboratory

Key words: ToF-SIMS, prelithiation, anode, solid-state lithium-ion battery, lithium silicate/Silicon carbon composites have become increasingly popular as potential anodes for solid-state lithium-ion batteries due to their large storage capacity. However, their current application is inhibited by the disruptive volume expansion and continuous solid electrolyte interface (SEI) layer formation that reduces their initial columbic efficiency (ICE). Prelithiation is used to counteract the loss of lithium ion (Li^+) by adding reserved lithium ions to the electrode. Prelithiation via thermal evaporation is a newly developed technique with limited studies on its effectiveness and process variations. Thermal evaporation was done through a 400-steel mesh placed over the electrode which directed the lithium metal deposition and diffusion into 'islands' or channels in a set of electrodes. Using this steel mesh resulted in less strain and volumetric expansion in the electrodes. Time-of-flight secondary ion mass spectrometry (ToF-SIMS) is used to highlight the benefits of prelithiation via thermal evaporation with a steel mesh in this study. Three ToF-SIMS measurement modes are used to visualize the deposition of lithium into 'islands', to identify Li_xSi_y alloy and $\text{Li}_x\text{Si}_y\text{O}_z$ silicate formation, and to display the distribution of lithium throughout the electrodes. The SIMS molecular imaging results validate the formation of the LiSi alloy and $\text{Li}_x\text{Si}_y\text{O}_z$ silicate upon prelithiation. Through depth profiling three-dimensional and surface two-dimensional imaging in

SIMS, we confirm that prelithiation by thermal evaporation effectively incorporates lithium into the silicon composite anode as desired. The multimodal mass spectral imaging results help validate the effectiveness of thermal evaporation for prelithiation, particularly in combination with a steel mesh.

CA-ThP-9 Evaluation of Imbedded Barium in Graphite for Nuclear Engineering in ToF-SIMS, Gabriel Parker, Thomas Muth, Victor Bautista, Xiao-Ying Yu, Oak Ridge National Laboratory, USA

Advanced manufacturing of cermets, heat-resistant materials made of ceramic and sintered metal, is necessary for radio isotope production to decrease waste and increase efficiency. The High Flux Isotope Reactor (HFIR) at the Oak Ridge National Laboratory currently uses Al as the filler material for irradiation targets. While Al has offered the ease of use and high thermal conductivity, it is limited by the post processing procedures creating a high charge density of the Al cation, creating instable aluminum nitrates, and forming oxidation decreasing the overall performance of the irradiation target. Transitioning from Al to a graphite matrix could reduce the issues aluminum poses. Graphite has similar thermal stability, thermal conductivity, and chemical properties. The manufacturing process using carbon can reduce waste by lowering solution volumes and overall complexity. ^{223}Ra is a radio isotope used for cancer treatments and is produced via a series of beta decays starting with ^{226}Ra . To test method development, Ba, is used as a surrogate to radium. This work examines the barium encapsulation by graphite using time-of-flight secondary ion mass spectrometry (ToF-SIMS). Specifically, high resolution spectroscopy and 2D/3D imaging modes were used to study the BaCO_3 pellets prepared in different manner. Current manufacturing process uses a mixture of graphite and barium carbonate either vacuum hot pressed or cold pressed and sintered. The mass spectrometry results verify that BaC as this is the preferred extraction radio isotope and not the oxide or carbonate. Also, depth profiling results show the BaCO_3 , BaC_2 , and BaO distributions across the surface and into the bulk of the pellet, indicative of the usefulness of different pellet processing steps.

Key words:

Barium, Radium, Graphite, Advanced Manufacturing, Nuclear Engineering, Radioisotopes, ToF-SIMS

CA-ThP-10 Potential Use of REELS and Electron Elastic Peak Spectroscopy for Measuring and Mapping Atomic Mass resolved distributions in SEM, Philippe Staib, WSI

Elastically backscattered electrons suffer a small kinetic energy loss with the interacting atom. The interaction is electrostatic and is described as a Rutherford backscattering process. Energy Shifts of the peak caused by the recoil energy loss only depends on the atomic mass M of the surface atom. The broadening and splitting of the elastic peak is described in [1]. The recoil energy loss is given by the simplified formula:

$$E_{\text{recoil}} = 4 \left(\frac{m_e}{M} \right) \sin^2 \left(\frac{\theta}{2} \right) E_p$$

with M the mass of the recoil atom, m_e the electron mass, θ the scattering angle and E_p the electron kinetic energy in eV.

The measurement of the recoil energy loss requires a high energy resolution analyzer to accurately measure the elastic peak position and shape. The compact energy analyzer described in [2,3,5] is mounted in a SEM chamber. The intensity of the elastic peak is strong and allows the measurement of recoil losses at low primary beam current below one nA thus well compatible with SEM beam currents. The elastic peak intensity depends upon the backscattering cross-section and atomic density. The backscattering coefficient can be given by the empirical Everhart formula based on the Rutherford model [4]. It essentially depends upon the atomic number Z.

Therefore the elastic peak shows an energy shift related to the atomic mass M of the scattering atom and an intensity corresponding to the Z and atomic density of the scattering atom. At 10 keV primary beam energy the calculated recoil loss values are:

Ag (108) 0.1 eV, C (12) 0.91 eV, O (16) 0.7 eV, H (1) 10 eV

The present analyzer can detect energy shifts of low mass materials from H to Si.

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¹ JVST Highlighted Poster

² JVST Highlighted Poster

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CA-ThP-11 Edge-Localized Strain in MoS₂ Nanobubbles Resolved at 5 nm by Chemical Imaging and Geometric Mechanics, *Sayantan Mahapatra*, Argonne National Laboratory, USA; *Soumyajit Rajak, Nan Jiang*, University of Illinois - Chicago; *Jeffrey Guest*, Argonne National Laboratory, USA

The formation of nanoscale bubbles is an unavoidable consequence during the transfer of two-dimensional materials onto target substrates, driven by van der Waals interactions at the interface. While often viewed as imperfections, these nanoscale bubbles have garnered considerable scientific interest due to the substantial in-plane strain gradients they induce, which in turn give rise to a variety of intriguing optoelectronic effects, particularly in semiconducting transition metal dichalcogenides. Determining and analyzing the strain distribution within nanobubbles at the nanoscale is crucial for advancing our understanding of these underlying strain-induced effects. Here, we present a high-resolution scanning tunneling microscopy-based tip-enhanced Raman spectroscopic investigation of localized nanoscale strain distribution within the nanobubbles formed between the monolayer MoS₂ and Au interface. By employing cryogenic temperature (78 K), we successfully differentiate the nanoscale Raman signatures between the nanobubble edge and pristine MoS₂. We verify a maximum tensile strain of ~1.15–1.34% at the nanobubble edge, which gradually diminishes toward the center, yielding a cross-sectional strain profile consistent with a doughnut-shaped distribution. Furthermore, we report achieving ~5 nm spatial resolution in probing such edge-localized strain within the nanobubble. In addition, comparative average strain analysis of such MoS₂ nanobubbles is conducted via geometric mechanistic analysis, such as membrane and nonlinear plate theories, providing key insight into the geometric nature near the bubble edge. Our findings provide fundamental information about strain-induced nanoscale chemical understanding of 2D materials on the nanometer scale, paving the way for practical applications of nanobubbles in strain-engineered optoelectronic devices.

CHIPS Act : Semiconductor Manufacturing Science and Technologies

Room Ballroom BC - Session CPS+MS-ThP

CHIPS Act: Semiconductor Manufacturing Science and Technologies Poster Session

CPS+MS-ThP-2 Nanostructural Characterization of 3D DRAM by 3D Reconstruction, *Wenbin Fan*, Applied Materials

As the continuous scaling of Dynamic Random Access Memory (DRAM) technology, semiconductor industry is evolving from two-dimensional (2D) to three-dimensional (3D) DRAM to provide the massive amounts of memory required for AI applications. 3D DRAM is expected to require advanced processes (deposition, etching and doping capabilities) to shape and form increasingly precise 3D structures across a 300mm wafer. In this work, a methodology for characterizing the nano structure of 3D DRAM to optimize these various processes is introduced as a promising solution to overcome current metrology limitation in semiconductor industry. Virtually reconstruction of 3D DRAM by hundreds of 2D Scanning Electron Microscopy (SEM) images is successfully demonstrated, offering superior detailed 3D nanostructure and extending the traditional SEM or Transmission Electron Microscopy (TEM) capability. Quantitative analysis on the reconstructed 50-pair Si/SiGe multilayers 3D DRAM is presented with excellent results in the measurements of 2D/3D Critical Dimension (CD) and defectivity.

CPS+MS-ThP-3 Summer Program Advancing Robotics and Knowledge in Microelectronics for K-12 (SPARK), *Parmida Amngostar, Soheyl Faghri Hagh, Alireza Fath, Yi Liu, Ian Cassidy, Swarup Chakraborty, Alexander Hoefer, Lanham Tran, Cooper Duggan, Dryver Huston, Jackson Anderson, Tian Xia*, University of Vermont

Since global trade disruption highlighted supply chain vulnerabilities, domestic semiconductor manufacturing has emerged as a national priority, as evidenced through passage of the CHIPS and Science Act in 2022. With this boost in spending comes the risk of workforce shortages, with as many as 58% of new jobs at risk of being unfilled [1]. In Vermont, IBM Microelectronics (now GlobalFoundries) have had a continuous presence since 1957, creating a robust ecosystem of semiconductor manufacturing

and design expertise, however local workforce challenges remain. While Vermont has a 91.2% high school completion rate, only 57% of those age 18-24 go on to attend an institution of higher education [2]. Traditionally, microelectronics and semiconductor concepts are not covered in the K-12 curriculum, leaving nearly half the population underinformed about a vital employment industry.

In this work we bridge the microelectronics education gap in Vermont through a workshop developed to educate K-12 science teachers, enabling them to more confidently introduce concepts in the classroom and informal settings. The developed workshop was run for the first time in June of 2025 and covered topics such as electrical prototyping, board and integrated circuit design, programming microcontrollers, interfacing with sensors, microelectronics fabrication, and advanced robotics. Activities were developed such that they could be run in a K-12 setting using the kits provided to teachers during the workshop. Materials have been published at the program website for free use [3]. The initial cohort consisted of 13 teachers from across the state whose instructional focus varied from 4th through 12th grade. Feedback from the attendees will be presented, along with learnings and considerations for any others hoping to offer a workshop like this in their jurisdiction.

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This work was supported by NSF grant No. 2119485 and the V-GaN Tech Hub.

CPS+MS-ThP-4 Ge and GeSn Photodetectors for Infrared Application: Toward Si-Compatible High Responsivity Devices., *Q.M. Kamrunnahar, Yining Liu, Jay Mathews*, University of North Carolina at Charlotte

Silicon photodetectors are crucial for current optoelectronics due to their CMOS compatibility, scalability, and low fabrication cost. Si is suitable for various applications, from imaging to on-chip optical interconnects, for these features. But the native absorption edge at ~1.1 μm has limited the application of Si in the telecom and critical infrared (IR) communication windows. This shortcoming has created the necessity for advanced materials that can extend detection beyond the range of silicon while remaining compatible with large-scale integration. In this case, Germanium (Ge) is a suitable option with its strong absorption up to ~1.55 μm. It has emerged as one of the most promising and widely used materials for telecom-band photonics and electronics. Recently, GeSn has shown its potential at the extended range of 2.5 to 3 μm. The behavior of Ge can be gained as a direct bandgap by adding tin (Sn). Thus, Ge and GeSn-based photodetectors could be strong candidates in the IR region and can replace the highly expensive InGaAs or HgCdTe photodetectors. In this work, we are presenting our current project to fabricate Ge and GeSn based photodetectors which can work in the infrared region. We have successfully fabricated initial devices using standard microfabrication techniques (Photolithography, etching, ebeam evaporation and lift off) and still working to improve the responsivity and detectivity of the photodetectors which is comparable with industry.

Spectroscopic Ellipsometry

Room Ballroom BC - Session EL-ThP

Spectroscopic Ellipsometry Poster Session

EL-ThP-1 ATR-Ellipsometry Using a Custom Liquid Cell, *Madison Coleman, Mar Diehl, Madison Meaney, Tyler Adams*, Weber State University; *Jeremy VanDerslice*, J.A. Woollam Co., Inc.; *Alyssa Mock*, Weber State University

A custom multi-bounce, prism-based liquid cell has been developed for use with infrared ellipsometry to enable quantitative analysis of liquids and the species dissolved within them. Traditional optical methods for liquid-phase analysis often rely on attenuated total reflection (ATR), where changes in signal intensity are caused by absorption via interaction between the evanescent wave and the liquid sample. In contrast, this approach leverages ellipsometric polarization measurements, capturing the reflected light's amplitude ratio (Ψ) and phase difference (Δ). These measurements probe molecular vibrations in the fingerprint region, enabling analysis of the chemical composition of liquids.

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Conventional optical measurement schemes are limited in the IR spectrum for liquid applications due to strong absorption, particularly in water-based systems. The ATR measurement technique addresses this limitation by coupling light into a prism and probing the sample with the evanescent wave produced by total internal reflections. Our new method combines the traditional ATR concept with ellipsometric detection. Multiple internal reflections within a high-index prism produce evanescent waves that repeatedly interact with the liquid sample. The repeated interactions with the liquid enhance sensitivity to small constituent fractions of species within the liquid. By capturing both the intensity and the polarization changes, this configuration extends the sensitivity of ellipsometric measurements to liquid environments.

The prism is housed in a custom-built sealed liquid cell and cut to provide a 45° angle of incidence. Submerged length wise in the liquid, the prism supports multiple internal reflections, with each reflection generating an evanescent field that probes the sample. Our results demonstrate the potential of ellipsometric ATR for concentration-based analysis of complex liquids, with future applications in quality control for the food, beverage, and water industries.

EL-ThP-2 Engineering the Optimal Filter: Quantitative Assessment of Linear and Nonlinear Noise-Reducing Filters in Spectroscopy, David Aspnes, North Carolina State University; **Long Le**, Vietnam Academy of Science and Technology, Viet Nam; **Young Kim**, Kyung Hee University, Republic of Korea

The objective of any noise-reduction filter is to preserve information and eliminate noise, both to the maximum extent possible. Up to now filters have been assessed by trial-and-error. Here, we report a cost function that quantifies the action of a filter on information and noise in a spectrum, that is, on distortion and leakage, respectively. For linear filters, which act by direct-space (DS) convolution or (equivalently) by selective attenuation of reciprocal-space (RS) Fourier coefficients, the expression is exact. Consequently, optimal parameters for any linear filter operating on any spectrum can now be determined unambiguously. We find that the best practical linear filter is the Gauss-Hermite filter introduced by Hoffman and co-workers in 2002 [1].

Nonlinear filters operate differently, retaining low-order Fourier coefficients exactly up to the white-noise cutoff and replacing those in the white-noise region with model-independent most-probable analytic extrapolations. With distortion nominally eliminated and noise input limited to retained coefficients, these should outperform any linear filter. However, the only known example, the corrected-maximum-entropy (CME) approach [2], can be used only with positive-definite spectra consisting of superpositions of Lorentzian absorption lines. Here, we report a forward-prediction approach with performance equivalent to the CME, but one that is based on physical principles and is completely general. Examples dealing with spectroscopic-ellipsometric and other types of data, for instance X-ray photoelectron and Auger electron spectra, will be presented.

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EL-ThP-3 Ellipsometry Measurements of Mn-doped Indium Tin Oxide Thin Films Deposited on Glass Substrates by DC Magnetron Sputtering, Costel Constantin, Masoud Kaveh, David Lawrence, James Madison University

Decades of intensive research on transparent conducting oxides (TCOs) have enabled advancements across a wide range of technologies, including flat-panel displays, photovoltaic cells, LEDs, transparent electronics, smart windows, and wearable devices. TCOs are unique in that they combine high electrical conductivity with optical transparency, a property made possible by their wide bandgaps. Among them, indium oxide (In_2O_3) and tin-doped indium oxide (ITO) are widely used due to their excellent optical transmission and tunable electrical conductivity, which can be adjusted by varying the tin content and deposition conditions. More recently, manganese-doped ITO (Mn-ITO) has attracted attention for applications in spintronic devices. In this study, Mn-ITO thin films with Mn concentrations ranging from 0 to 12.8% were deposited on glass substrates using DC magnetron sputtering. The structural, electrical, and optical properties of the films were systematically investigated. Optical characterization using spectroscopic ellipsometry revealed a monotonic decrease in the energy bandgap with increasing Mn content. X-ray diffraction analysis of the undoped ITO films, using the (440) peak, yielded a lattice constant of approximately 10.15 Å, which is smaller than the standard value of ~11.2 Å. A possible explanation for this deviation is discussed.

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Electronic Materials and Photonics

Room Ballroom BC - Session EM-ThP

Electronic Materials and Photonics Poster Session

EM-ThP-1 Comparison of Experimental Analysis and Theoretical Calculation of the Lattice Dynamics, Phonon and Vibrational Spectra Dynamics of Titanium Nitride and Oxynitride, Ikenna Chris-Okoro, Sheilah Cherono, Wisdom Akande, Swapnil Nalawade, Mengxin Liu, Barbee Brianna, Brooklyn Jenkins, Ghanashyam Gyawali, Bishnu Bastakoti, Shyam Aravamudhan, J. David Schall, Dhananjay Kumar, North Carolina A&T State University

Titanium nitride (TiN) and its isostructural oxide derivative, Titanium oxynitride (TiNO) has gained interest in industry as a cost-effective alternative material to noble metals and refractory metals with wide range of applications especially in the optoelectronics and plasmonic. However, there still remain some gaps and disagreement in the literature on specific optical and photoelectrochemical properties of TiN and TiNO, due to difficulty and the varying approach in quantifying defects, vacancies, oxidation state and direct impact of impurities in experimental results.

In this study, thin films of TiN and TiNO were synthesized via pulse laser deposition on sapphire. Structural properties of these thin films were investigated using X-ray Diffraction and Reflection (XRD, XRR), X-ray Photoelectron Spectroscopy (XPS), Rutherford backscattering spectrometry (RBS), Raman Spectroscopy and Fourier Transform Infrared Spectroscopy (FTIR). To corroborate our experimental observations, the phonon dispersions and Raman active modes are calculated using the virtual crystal approximation for rutile TiO_2 and rocksalt TiNO and molecular dynamics simulations were used to calculate the phonon density of states. The results shows that the incorporation of nitrogen atoms does not significantly alter the phonon dispersions of rutile TiO_2 . However, it results in the emergence of new phonon modes at approximately 7.128 THz (237.65 cm⁻¹) at the Gamma point, which corresponds to the experimentally observed Multi-Photon Phase-MPP (240 cm⁻¹-R). From the experimental and theoretical studies, a multilayer optical model has been proposed for the TiN/TiNO epitaxial thin films for obtaining individual complex dielectric functions from which many other optical parameters can be calculated.

This work was supported by a DOE EFRC on the Center for Electrochemical Dynamics and Reactions on Surfaces (CEDARS) via grant # DE-SC0023415. Part of the work has used resources established by the Center for Collaborative Research and Education in Advanced Materials (CREAM) via NSF PREM grant # DMR-425119 PREM. ML and GG are jointly supported by the CEDARS and CREAM projects.

EM-ThP-3 Singlet Fission from Tetracene and Charge Transfer to Metal Halide Perovskites, Yutong Ren¹, Antoine Kahn, Princeton University

Metal halide perovskites (HaPs) have garnered widespread interest for light-harvesting and light-emitting applications due to their exceptional optoelectronic properties and relatively simple fabrication methods. However, like with other semiconductors, HaP-based solar cells lose excess energy through thermalization when absorbing photons with energy that exceeds the absorber bandgap.¹ A promising strategy to reduce these losses and improve photon utilization is to exploit singlet fission, whereby a high-energy singlet exciton formed in an adjacent layer splits into two triplet excitons.^{2,3} By transferring these triplet excitons into a HaP film engineered with a composition that aligns the absorber's bandgap closely with the exciton energy, one can effectively harvest this otherwise wasted energy. In our work, we demonstrate that singlet fission in the molecular semiconductor tetracene (Tc) efficiently generates triplet excitons⁴ that are energetically matched to the bandgap of a Sn–Pb based HaP, offering a viable pathway toward improved device performance.

In this study, we investigate the electronic structure of Sn–Pb-based HaP films and their interfaces with Tc using ultraviolet photoelectron spectroscopy (UPS) and inverse photoemission spectroscopy (IPES). Based on the work by Nagaya et al.,⁵ we introduce a second molecular donor, zinc phthalocyanine (ZnPc), at the interface to engineer a more staggered energy alignment between Tc and the perovskite film, thereby promoting an energetically more favorable sequential electron transfer plus formation of a charge transfer (CT) state ($\text{ZnPc}^+ - \text{HaP}$). UPS/IPES measurements suggests that the CT state lies approximately between the Tc triplet energy and the HaP energy gap, which is favorable for triplet transfer. Complementary photoluminescence (PL) and time-resolved PL (tr-PL)

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measurements provide guidance for selecting alternative donors with deeper or shallower HOMO levels to replace ZnPc and further refine the interfacial energetics. Moreover, optoelectronic characterization reveals insights into undesirable charge carrier recombination pathways at the organic/HaP interface. Collectively, our results underscore the potential of singlet fission to enhance the efficiency of perovskite solar cells and reduce the cost of the energy that they generate.

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EM-ThP-7 Growth of MAPbI₃ Single Crystals for Radiation Detection and Sensor Applications, *Basak Bagci, Shams Noor, Ge Yang, North Carolina State University*

Hybrid halide perovskites such as methylammonium lead iodide (MAPbI₃) offer exceptional promise for ionizing radiation detection due to their high atomic number, strong photon absorption, low trap densities ($\sim 10^{10}$ cm⁻³) and excellent defect tolerance. In particular, single-crystal MAPbI₃ stands out for its excellent charge transport properties, including high mobility-lifetime ($\mu\tau$) products $\sim 1.2 \times 10^{-2}$ cm²/V and X-ray sensitivities exceeding $250 \mu\text{C Gy}^{-1} \text{cm}^{-2}$, which are critical for achieving high-sensitivity, low-noise performance in X-ray and gamma-ray detectors.

This study focuses on the growth of MAPbI₃ single crystals dissolving methylammonium iodide (MAI) and lead iodide (PbI₂) in gamma-butyrolactone (GBL), followed by controlled heating to induce crystal formation. Experimental efforts will explore the effects of precursor concentration, temperature ramp rates, and growth dynamics on crystal size, morphology, and electronic characteristics. The harvested crystals are intended for use in radiation detection and broader sensor applications, and they will also serve as a baseline for future comparisons with triple-cation and doped perovskite systems.

Our work builds on previous ITC reports but demonstrates a new synthesis protocol that yields centimeter-scale MAPbI₃ crystals with low visible defect density and improved reproducibility. Unlike earlier studies, our method carefully regulates supersaturation and convection to promote steady lateral crystal expansion. Preliminary optical and structural analyses confirm phase purity and high crystallinity, while ongoing electrical characterization is focused on quantifying $\mu\tau$ values under bias and assessing detector sensitivity and leakage current under X-ray flux. To address the well-known stability limitations of MAPbI₃, we are implementing post-growth annealing strategies, encapsulation and/or low-temperature storage under inert conditions to suppress decomposition. These steps aim to improve the operational durability of the material and establish a foundation for stable detector integration.

By establishing a reliable and reproducible synthesis and growth protocol, this work aims to produce high-purity, low-defect MAPbI₃ crystals suitable for device integration. Future steps include evaluating charge transport characteristics, assessing detector performance under radiation exposure, and exploring strategies for enhancing long-term material and device stability. The insights gained from this study are expected to contribute to the development of scalable, low-cost perovskite-based radiation detectors with improved resolution and sensitivity.

EM-ThP-8 Chemical Vapor Deposition of Uniform and Large-Scale MoS₂ Using Heterogeneous Precursor, *Xiaokai Zhu, Duke University; Gang Seob Jung, Oak Ridge National Laboratory; Jiahui Yang, Duke University; Xuguo Zhou, Boston College; Zhe Shi, Massachusetts Institute of Technology; Victoria Ravel, Chung-Li Lin, Xingjian Hu, Zihan Peng, Aaron Franklin, Duke University; Qiong Ma, Boston College; Tania Roy, Haozhe Wang, Duke University*

The mass production of large-scale single-layer molybdenum disulfides (MoS₂) is necessary for the fabrication of next-generation electronics. However, the current chemical vapor deposition (CVD) strategies are hard to produce uniform and large-scale single-layer MoS₂. Here, we developed a CVD strategy using heterogeneous precursors for synthesizing high-quality single-layer MoS₂. Different from the traditional CVD strategies where the growth promoter and Mo source are mixed, our strategy employs heterogeneous precursors where the growth promoter and Mo source are positioned separately in two layers. During heating, the growth promoter initially volatilizes and condenses on the substrate to create a promoter-rich environment. In that case, a large amount of promoter accumulates and

spreads uniformly on the substrate, leading to the growth of millimeter-scale single-layer MoS₂ on both SiO₂/Si and sapphire substrates. Raman spectroscopy and atomic force microscopy (AFM) imaging have confirmed the MoS₂ layer number. Raman and photoluminescence (PL) mapping indicated outstanding spatial uniformity of the film. Selected-area electron diffraction revealed single crystal properties within a 5 μm × 5 μm area. An array of field-effect transistors based on the as-grown single-layer MoS₂ demonstrated excellent electrical properties (10E-7 on/off ratio). Compared to traditional CVD strategies, the coverage ratio of single-layer MoS₂ increased from 66.7% to 90.3%, and the device yields increased from 6.0% to 74.0%. The growth mechanism was investigated by density functional theory (DFT) calculations concluding that the energy barrier for MoS₂ growth on salt is significantly lower. As a result, after the growth of the first layer, no additional layers tend to grow on top of it and all single-layer flakes merge together to form a continuous film with multiple domains which have been visualized by second harmonic generation (SHG) imaging and molecular dynamics (MD) simulation. This method provides a new understanding of the mechanism of the promoting agent in CVD MoS₂ growth, presents a new paradigm for high-quality MoS₂ fabrication, and consequently will benefit large-scale 2D semiconductor applications.

EM-ThP-9 Comprehensive Study of Tandem CdSeTe Photovoltaic Devices Using Alternative Subcell Absorber Layers: Bandgap Engineering, *Chowdhury Haque, Philip (Sanghyun) Lee, University of Kentucky; Kent Price, Morehead State University*

Tandem CdSeTe thin-film photovoltaic devices represent a promising frontier in solar energy technology, utilizing innovative bandgap engineering to enhance efficiency (>30 %) by broadening absorbing spectrum of impinging light. Although CdSeTe cells have been heralded for their high conversion efficiency (23.1 %), but limitations arise when single-junction designs fail to capture the full spectrum of solar radiation. Tandem devices (dual-junction or multi-junction) address this challenge by integrating multiple subcell absorber layers, each with optimized bandgap energy to selectively absorb different portions of the solar spectrum.

The introduction of alternative subcell absorber layers in the tandem structure is pivotal for expanding device performance by overcoming the fundamental limitation of a single-layer photovoltaic device by capturing larger ranges of wavelength of sunlight. Absorber layers are carefully selected and engineered to achieve bandgap tuning that maximizes spectral overlap while maintaining material compatibility. A top cell has larger bandgap, which can absorb shorter wavelength light. A bottom cell has smaller bandgap, capturing longer wavelength light.

For dual-junction tandem device configurations, we investigated the band alignment of top and bottom subcell materials to achieve the optimized bandgap between two subcells through bandgap engineering. From the theoretical study, bandgaps of dual-junction tandem devices are 1.5 - 1.8 eV and 1.4 - 1.5 eV for top and bottom (CdSeTe) subcells, respectively. The theoretical maximum power conversion efficiency (PCE) is 33.16 %. Multiple top and bottom absorber candidates were explored, including CdZnTe (Eg = 1.75-1.8 eV) and CdMnTe (1.7-1.75 eV) for a top subcell and CdSeTe (1.4 - 1.5 eV) for a bottom subcell. To optimize tandem devices, the current matching technique is used to determine the optimal thickness of each subcell. For the top layers, the thickness of CdMnTe is 450 nm, and for CdZnTe, it is 398 nm. The thickness of the bottom layer is approximately 2.4 μm to achieve the best performance in a two-terminal tandem device. With spectral filtering and current matching, CdMnTe/CdSeTe tandem devices demonstrate an open-circuit voltage (Voc) of 1.52 V, a short-circuit current density (Jsc) of 15.7 mA/cm², and a fill factor (FF) of 82.1%, resulting in power conversion efficiency of 19.61 %. In contrast, CdZnTe/CdSeTe tandem devices demonstrate an Voc 1.51 V, Jsc 16.2 mA/cm², and FF 75.52 % with PCE 18.54 %. In summary, the best PCE is MgZnTe 19.61%, indicating that these devices are promising candidates for high-performance tandem solar cells.

EM-ThP-10 Ferroelectric Tunnel Junction NVM Stability, *M. David Henry, Sandia National Laboratories*

Ferroelectric (Hf,Zr)O₂-based tunnel junctions have shown significant promise as two-terminal resistive non-volatile memory (NVM) devices, exhibiting excellent area scaling capabilities and a high degree of compatibility with complementary metal-oxide-semiconductor (CMOS) technology. These devices can operate in a binary state, characterized by a high resistance state (HRS) and a low resistance state (LRS), as well as support multiple intermediate resistance states. From semiconductor physics, we describe the transport behavior using a combination of Ohmic conduction and Poole Frenkel (PF) defect mediated conduction. At low field

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(10^{-5}V/cm) , Ohmic conduction dominates whereas at medium to high field a modified PF dominates. From the conduction mechanism, several factors can influence the stability of resistance states for a binary and multistate based devices including temperature, imprint, and even the act of reading out the state. This work will discuss these factors and demonstrate the functionality of these ferroelectric tunnel junction devices in both 5-bit and 4-bit configurations, enhancing data storage density and enabling advanced functionalities.

EM-ThP-11 *Ab Initio* Molecular Dynamics Modeling of Amorphous Titanium Silicon Nitride, *Somilkumar Rathi, Parag Banerjee*, University of Central Florida; *Raymond Atta-Fynn*, Los Alamos National Laboratory

Amorphous titanium silicon nitride is a ceramic material that has emerged as a strong candidate for a next-generation, ultra-thin diffusion barrier material in semiconductor device fabrication. As device dimensions shrink, TiSiN is increasingly considered a viable alternative to traditional TaN- and TiN-based barriers due to its structural tunability (crystalline to amorphous) enabled by doping. Moreover, its ease of synthesis and electrical properties are comparable to those of conventional barrier materials even at much lower thicknesses, facilitating integration into advanced device nodes. In this work, *ab initio* molecular dynamics simulations based on the quench-from-the-melt technique were employed to model amorphous titanium silicon nitride by systematically doping stoichiometric TiN with Si until clear signatures of amorphization emerged.

We observed that the onset of amorphization occurs when the fraction of Si in TiN reaches at least 25%. The distributions of various bond lengths and bond angles were analyzed to gain insight into the geometry of the structures. The angular-momentum-resolved electronic density of states was used to analyze the interactions between the Ti, N, and Si electron states. The amorphization process is explained by the reduction in ionicity and the increase in covalency induced by Si incorporation.

EM-ThP-12 Spectroscopic Characterization and Defect Identification in Wide Bandgap Semiconducting Materials, *Praveena Manimunda*, HORIBA

Wide bandgap semiconductors such as silicon carbide and Ga_2O_3 are used in power electronics, high power and high temperature devices. Achieving defect free, doped wide bandgap semiconductors are still a challenge. In this study spectroscopic characterization techniques such as photoluminescence, Raman and cathodoluminescence methods are utilized to identify microscopic defects in 3C-SiC, n-type 4H-SiC and shape engineered SnO_2 nanostructures grown on Ga_2O_3 nanowires. Semiconducting oxide nanostructures with a wide range of morphologies are emerging as a viable candidate for applications such as optical and mechanical resonators and solar cells. However, attaining effectively doped oxide nanowires with controllable conductivity is still a challenge. [1,2] Designing semiconducting oxide nanostructures requires extensive understanding of their morphology and demands efficient multimodal characterization methods. Multimodal spectroscopy is the concept of combining several different spectroscopies onto one platform, thereby expanding the range of analytical capabilities available on that single platform. Besides the obvious benefit of cost reduction, having multiple analytical spectroscopies offers the added benefit of sample colocalization so that multiple complementary measurements can be made at the same location of the sample. The benefit of colocalization is particularly important as feature sizes get smaller, from a few microns to nanometers in size. Using patterned silicon grid sample and embedded position-sensing technology, coordinates of region of interest transferred between different spectroscopic tools. Raman, Photoluminescence, cathodoluminescence and Time Resolved Photoluminescence (TRPL) techniques were used to characterize growth induced defects.

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EM-ThP-13 Flexible Perovskite Solar Cells with Reusable Stainless-Steel Foil Substrates, *Pramod Baral*, Verde Technologies Inc.

Flexible Perovskite Solar Cells with Reusable Stainless-Steel Foil Substrates

Pramod Baral¹, Vivek Babu¹, Francesca Brunetti²

1. *Verde Technologies Inc., Waterbury Center, Vermont, 05677, USA*
2. *CHOSE (Centre for Hybrid and Organic Solar Energy), Department of Electronic Engineering, University of Rome Tor Vergata, 00133, Italy*

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Perovskite solar cells (PSCs) have achieved power-conversion efficiencies (PCEs) of 27% on rigid glass substrates, yet their flexible counterparts are more attractive for lightweight, portable and roll-to-roll manufacturing applications. Conventional polymer substrates such as PET and PEN, however, are limited by low thermal tolerance, modest barrier properties, and single-use constraints. Here, we demonstrate stainless-steel (SS) foil as a multifunctional application that simultaneously serves as a flexible substrate, conductive bottom electrode, and robust barrier layer, offering high thermal and mechanical stability as well as reusability across multiple fabrication cycles. Our device stack SS/ $\text{NiO}_x/\text{MeO-4PACz/PEAI/FAPI/3MTPAI/C}_{60}/\text{BCP/Cu}$ fabricated via scalable slot-coating of the perovskite absorber and high-vacuum evaporation of the electron transport layer (ETL) and top electrode layers, achieves PCEs approaching 10% under standard 1-sun illumination. Performance is currently constrained by optical absorption losses in the semi-transparent Cu electrode, which limit photocurrent generation. To address this, we are transitioning to low-temperature high-vacuum sputtered transparent conducting oxides such as indium tin oxide (ITO) and indium zinc oxide (IZO), which offer higher transparency and lower sheet resistance while remaining compatible with roll-to-roll processing. This approach highlights a realistic pathway toward scalable flexible perovskite solar cells (FPSCs) exceeding 20% efficiency, enabling cost-effective deployment in building-integrated photovoltaics, mobile systems, and off-grid power applications.

Light Sources Enabled Science Mini-Symposium

Room Ballroom BC - Session LS-ThP

Light Sources Enabled Science Mini-Symposium Poster Session

LS-ThP-1 Ultrafast Materials Characterization at the NSF-NeXUS Facility, *Seth Shields, Tim Scarborough, Conner Dykstra, John Beetar, Ziling Li, Roland Kawakami, Jay Gupta*, Ohio State University

The National Science Foundation (NSF) National eXtreme Ultrafast Science Facility (NeXUS) is a new open access user facility that provides access to extreme light to researchers around the world. The facility contains a mix of optical and analytical capabilities that allow for the study of chemical and material properties on the time scale of femtoseconds to attoseconds and on the length scale of angstroms. A customized high power, high repetition rate (800 W @ 100 kHz) Yb-doped fiber laser and pulse compression scheme from Active Fiber Systems GmbH is used to produce extreme ultraviolet light (XUV) through high harmonic generation. The XUV light is conditioned through three beamlines, which provide tailored light to a variety of end stations, three of which support materials analysis: X-ray absorption/reflection spectroscopy (XAS/XRS), Angle Resolved Photoemission Spectroscopy (ARPES), and Scanning Tunneling Microscopy (STM).

The combination of an ultrafast XUV beamline with more traditional condensed matter characterization tools, such as ARPES and STM, provides expanded capabilities for user experiments. ARPES is a surface sensitive technique that typically uses a helium discharge lamp to eject photoelectrons, and measurement of their energy and momenta allows for the study of electronic structure in reciprocal space. The addition of a beamline capable of providing light in an optical-pump XUV-probe arrangement allows the NeXUS ARPES to probe charge and carrier dynamics with sub-picosecond time resolution.

STM is a surface characterization technique used to study physical and electronic structure, with angstrom scale spatial resolution, by measuring the tunneling current across a nanoscale junction between the sample and an atomically sharp metal tip. At NeXUS, Thetailed light provided by the beamline addresses two long-standing weaknesses of STM measurements: poor time resolution ($> \sim 1 \mu\text{s}$), and lack of elemental specificity. The beamline allows for optical-pump probe measurements, which combine ~ 100 fs time resolution with angstrom scale spatial resolution of the STM. Additionally, XUV light can be tuned across an atomic core edge, resulting in a spike in photocurrent that is collected by the STM tip, yielding a spatially resolved elemental map of a surface.

This poster will present the preliminary results and progress during the commissioning and inaugural user experiments at NeXUS.

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MEMS and NEMS

Room Ballroom BC - Session MN-ThP

MEMS and NEMS Poster Session

MN-ThP-1 Statistical Analysis of 3D Printability and Mechanical Performance in Reinforced Polymer Composites, Vladimir Milosavljevic,
School of Physics, Clinical & Optometric Sciences, Technological University Dublin, Ireland; Alison J. Clarke, Denis P. Dowling, I-Form Centre, School of Mechanical & Materials Engineering, University College Dublin, Belfield, D04 C1P1 Dublin, Ireland

The study explores the challenges and opportunities in 3D printing continuous fiber-reinforced polymers, with a focus on Polylactic Acid-Stainless Steel Fiber (PLA-SSF) composites. Statistical analysis of the printed parts highlighted deviations from design specifications, especially in acute angles and tight radii, emphasizing the need for optimized printing parameters and tooling paths. Fiber migration and excess polymer deposition were identified as key factors influencing geometric distortions, particularly at smaller radii and more acute angles. The study also developed a curvature bending stiffness (CBS) testing methodology to assess the mechanical performance of PLA-SSF composites, comparing them with neat PLA, nylon with short carbon fibers (Onyx), and nylon with continuous carbon fibers (Onyx-cCF). Results showed that PLA-SSF composites exhibited the highest CBS, with stiffness increasing linearly as radii decreased from 20 mm to 3 mm. PLA and PLA-SSF samples failed by tensile fracture, while Onyx samples deformed without fracturing. By employing statistical techniques, the study achieved a robust analysis of the printability and mechanical performance. The non-parametric Kruskal-Wallis test allows for the comparison of medians across multiple groups, such as different materials or different geometries, providing a reliable way to assess differences in mechanical performance without relying on normal distribution assumptions. Moreover, regression analysis is valuable for modeling relationships between printing parameters and outcomes such as dimensional accuracy or mechanical performance. This technique helps optimize printing parameters to achieve better results. Further, the Wilcoxon Signed-Rank Test, a nonparametric method, is useful for comparing as-printed dimensions with designed dimensions, especially when data does not follow a normal distribution. It provides a robust way to assess deviations from design specifications. The findings highlight the geometric limitations of 3D printing continuous fiber-reinforced polymers and suggest that adjusting printing speeds and tooling paths can mitigate distortions. This work provides critical insights into optimizing the printability and mechanical performance of reinforced polymer composites for advanced manufacturing applications. Moreover, the findings not only provide insights into improving the geometric accuracy and mechanical properties of 3D-printed composites but also suggest potential applications in structural health monitoring and sensor technologies. This work contributes to advancing the understanding of reinforced polymer composites for high-performance manufacturing applications.

MN-ThP-2 Performance of Copper Filled Through Glass Vias for Radio Frequency Applications, Jessica McDow, Scott Grutzik, Matthew Jordan,
Sandia National Laboratories

The material properties of glass such as low dielectric constant and loss, low roughness, adjustable coefficient of thermal expansion (CTE), and low electrical conductivity at high frequencies make it a desired material for high function radio frequency (RF) device interposers.¹ Through glass vias (TGV) are a key technology for incorporating 3D integration techniques into RF devices as a way of improving device performance, increasing I/O per unit volume, simplifying design and assembly, and allowing for a more compact system. Vias are typically filled with copper (Cu) to form an electrical connection from one surface to another. Although TGVs are a promising technology, they are subject to thermo-mechanical reliability challenges due to the interaction between glass and Cu during thermal cycling. The thermal mismatch between copper ($CTE_{Cu} = 16.7e^{-6}/^{\circ}C$) and glass ($CTE_{glass} = 3.4-9.0e^{-6}/^{\circ}C$) can cause reliability issues, such as glass fractures, Cu protrusion, and Cu via sliding and delamination which are difficult failure mechanisms to predict.

In this work, Corning SG3.4 glass was bonded to an Si carrier with vias fabricated of diameters 30 μm , 50 μm , and 75 μm in both square and hexagonal arrays with three different pitches being investigated 120 μm , 160 μm , 200 μm . These samples were tested in various methods to study the mechanical and thermomechanical stability of Cu filled TGVs. For thermomechanical stability, the vias were filled with Cu through an electrochemical deposition (ECD) process with a 30 nm platinum seed

layer. The variation in TGV geometry was studied to determine the yield strength of glass for the different TGV geometries and densities. This was used to develop optimal design and process parameters for future TGV applications in RF devices. The Cu filled TGV samples were heated in a reflow oven which allows for controlled ramp rates and dwell times while keeping the substrates in an inert environment. Observed fractures and Cu protrusion was recorded to determine yield strength. Mechanical stability was studied through various flexure method tests to understand how the glass performed with the various via densities. This work demonstrates novel design and process parameters for reliability of through glass vias for future generation RF devices. Different via geometries and densities were analyzed to determine the yield strength of a glass interposer, relieving stress and reliability issues within RF devices.

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¹K. Pan et al., 2021 IEEE 71st Electronic Components and Technology Conference (ECTC), pp. 1660-1666, doi: 10.1109/ECTC32696.2021.00263.

MN-ThP-3 3D Microfluidic Integrated Electronic Packaging for Enhanced Thermal Management via Two Photon Polymerization, Angel Yglesias¹,
University of Texas at El Paso

Thermal management currently stands in the way of optimizing chip performance for the increasingly powerful and compact microsystems needed for heterogenous integration. Utilizing 3D printing, this work addresses these current thermal management limitations by actively cooling a device die mounted directly onto a microfluidic channel, to provide a package level cooling solution. Historically thermal management has been addressed at the board level through heat sinks and lead frames, where the package simply provides a passive thermal conduction conduit between the lead frame and PCB below. Designs to incorporate active cooling onto PCBs have shown promise but require larger systems real estate and are not in direct contact with the die, limiting performance. Alternatively, die level cooling designs use standard microfabrication techniques to etch channels directly onto the backside of semiconductor dies to yield high performance, but at the cost of increasingly the complexity of the cleanroom fabrication steps. The proposed design is a printed microfluidic pin-fin cooling package printed using two photon polymerization (2PP). 2PP uses a laser to selectively cure a photopolymer resin or photoresist, allowing direct writing of polymer microstructures with features down to 200 nanometers. Through 3D printing, not only do structural design options become vast, but optimization of microfluidic effects, thermal resistance, and heterogeneous integration can be performed. We have previously demonstrated metal microfluidic packages using direct metal laser sintering, but this work explores the capabilities and resulting performance of 3D microfluidic packaging utilizing 2PP manufacturing techniques. Where previous work utilized designs with no variable features in the Z-direction, the 2PP packaging work implements spiral topologies to enhance fluidic interactions with the die. Scanning electron microscopy and fluidic cooling performance are explored to characterize the 2PP manufactured microfluidic packages for comparison to the state of the art.

MN-ThP-4 Smart Wearable with Companion App for Tracking UV Index and Physical Activity, Zach Nesnidal, Sushma Kotru, Mason Wright,
The University of Alabama

Excessive exposure to ultraviolet radiation is a leading cause of skin cancer, sunburn, and premature aging. Use of mobile apps is gaining interest of consumers for overall health management including UV index (UVI) monitoring. These apps and stationary weather stations offer general UV Index forecasts, but they fail to provide accurate, real-time data for individuals based on their location, orientation, and environmental conditions. We have designed a wearable which integrates a UV sensor with a step counter and have developed a companion mobile application. This wearable can provide real time UV index, which is displayed on a low power OLED screen, along with other information. A microcontroller enables periodic sampling and built in Bluetooth capability, while a 110mAh rechargeable lithium-ion battery provides hours of operation on a single charge. The electronics are housed in a 3D-printed PLA enclosure with a fused quartz window to ensure high UV transmittance and physical protection. Multiple devices were fabricated and tested. Calibration of the devices was performed by comparing device output to a commercial UV meter under various outdoor conditions. The sensors on all devices exhibited a linear voltage-UVI relationship that needed minimal tuning.

¹ JVST Highlighted Poster

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Bluetooth integration allows real-time UVI readings to be viewed and stored on a mobile app, with support for exposure notifications, historical tracking, and actionable insights and advice based on skin-type to keep the user better informed and protected. This work demonstrates the feasibility of affordable, personalized UV exposure monitoring and recording the physical activity which can be valuable for broader applications in public health, dermatology, and wearable tech. Design, fabrication and testing of the wearable and development of the mobile app will be presented.

Nanoscale Science and Technology Room Ballroom BC - Session NS-ThP

Nanoscale Science and Technology Poster Session

NS-ThP-1 Single and Dual Sintering Techniques on Flexible Metal Nanoparticle Patterns, *Md. Mahfujur Rahman, Rajib Chowdhury, Seonhee Jang*, University of Louisiana

The application of metallic nanoparticle (NP) inks has become the center of developing flexible printed electronic devices such as solar cells, displays, wearables, and sensors. The approach of defining the mechanical, electrical, and material properties of printed patterns depends on the type of metallic NPs. The most utilized NPs are silver (Ag), gold (Au), and copper (Cu). Ag NPs are highly considered for their excellent electrical conductivity and resistance to oxidation. On the other hand, Cu NPs are highly preferred because of their affordability to Ag NPs, yet they are highly prone to oxidation. During printing of metallic NP inks for conductive patterns, a lack of electrical conductivity in the patterns is observed because of induced organic additives and stabilizing agents. Consequently, sintering is essential for removing these organic residues and enhancing the conductivity of the printed patterns.

This study focuses on utilizing two metallic inks of Ag NP ink (PSI-211, NovaCentrix) and Cu NP ink (CP-008, NovaCentrix) to fabricate the conductive patterns on flexible polyimide (PI) sheets. Either single or dual sintering processes were conducted to optimize the electrical conductivity. For the single sintering process, the printed metal NP patterns were subjected to either laser irradiation (LO) or thermal treatment (TO). During the LO sintering process, the Ag and Cu NPs underwent Nd:YAG laser irradiation at 600 and 800 mJ for 15 and 30 s, respectively. For the TO sintering process, Ag and Cu NPs were introduced in a formic acid (FA) vapor environment at 140 and 260 °C for 1.5 and 15 min, respectively. The dual sintering method involved thermal treatment followed by laser irradiation (TL) and laser irradiation followed by thermal treatment (LT).

After sintering, a microstructural analysis was conducted using scanning electron microscopy. The analysis confirmed that the LT condition for sintering of the Ag NP pattern showed improved particle agglomeration and necking. Atomic force microscopy (AFM) analysis revealed the highest roughness of 48 nm, indicating superior grain growth. With a resistance ratio (R/R_0) of 1.75 during the folding test, the Ag NP pattern sintered using the LT condition showed the lowest electrical sheet resistance. Through agglomeration and coalescence during sintering, the Cu NP pattern sintered with the TO condition displayed the most uniform grain growth. The Cu NP pattern sintered under the TO condition had the highest mechanical Vickers hardness of 55.36 N/mm² because of the improved connection between the NPs. Additionally, the Cu NP pattern showed the highest roughness value of 51.36 nm.

NS-ThP-3 The Nanoscale Materials Characterization Facility (NMCF) at the University of Virginia, *Catherine Dukes, Diane Dickie, Graham Frazier, Helge Heinrich, Art Lichtenberger, Joe Thompson, Richard White*, University of Virginia

The **Nanoscale Materials Characterization Facility and Innovations in Fabrication** clean-room microfabrication/biomanufacturing facility are advanced user facilities within UVa's School of Engineering and Applied Science. Our instruments are available for researchers from academic and industrial institutions on a pay-for-time basis. We provide comprehensive services in materials preparation and processing, as well as a suite of advanced analytical techniques. Researchers are welcome to (1) visit the **NMCF** for collaborative sample science or (2) send specimens for remote analyses by one of five expert instrument scientists, ensuring personalized guidance and optimized results.

We operate two transmission electron microscopes: a 200kV Talos system and a 300 kV Themis with probe correction for sub-Å resolution and monochromated EELS. Both offer EDS for compositional analysis and mapping, as well as sample holders for in-situ cooling, heating, biasing,

liquid-cell and gas-cell experiments. A Helios dual-beam FIB-SEM is used for surface, cross-sectional, and 3D imaging, EDS analysis, orientation mapping with electron-backscatter diffraction and TEM sample preparation. Additionally, two standalone scanning electron microscopes are available: a Quanta 650 FE-SEM with EDS and EBSD, and a Phenom XLG2 environmental SEM for electron imaging and EDS.

Four X-ray powder diffraction systems are available for analyzing bulk composition and phase orientation, with specialized stages for in situ heating and X-ray reflectivity. An X-ray fluorescence spectrometer provides highly sensitive elemental analysis for $Z > 10$. The facility also features an integrated Renishaw Raman spectrometer/Bruker AFM system for molecular identification, surface chemistry, and nano-scale topography, along with a Invenio-S FTIR for chemical fingerprinting and organic material identification.

For quantitative surface composition and chemistry, two X-ray photoelectron spectrometers are available: a Versaprobe III small-spot instrument with ion gun for depth profiling, hot-cold stage, and processing chamber; and a HiPP-Lab ambient-pressure XPS with *in-situ* high-temp liquid cell, plasma processing, glove box, sample prep chamber and gas reaction cell. Optical instrumentation includes a white-light profilometer for surface metrology, and a digital light microscope for 2D/3D imaging and videography.

A complete suite of metallurgical equipment for cutting, mounting, polishing, sputter coating, etching, and plasma cleaning, as well as Rockwell and Vickers hardness testing, is also available.

Contact: <https://engineering.virginia.edu/NMCF>

NS-ThP-4 Exciton-Polariton Devices from Two-Dimensional Chalcogenide Semiconductors, *Deep Jariwala*¹, University of Pennsylvania

The isolation of stable atomically thin two-dimensional (2D) materials on arbitrary substrates has led to a revolution in solid state physics and semiconductor device research over the past decade. A variety of other 2D materials (including semiconductors) with varying properties have been isolated raising the prospects for devices assembled by van der Waals forces. Particularly, these van der Waals bonded semiconductors exhibit strong excitonic resonances and large optical dielectric constants as compared to bulk 3D semiconductors..

First, I will focus on the subject of strong light-matter coupling in excitonic 2D semiconductors, namely chalcogenides of Mo and W. Visible spectrum band-gaps with strong excitonic absorption makes transition metal dichalcogenides (TMDCs) of molybdenum and tungsten as attractive candidates for investigating strong light-matter interaction formation of hybrid states. We will present our recent work on the light trapping in multi-layer TMDCs when coupled to reflective substrates. Next, I will show the extension of these results to superlattices of excitonic chalcogenides, multilayer halide perovskites as well as metal organic chalcogenolates. These hybrid multilayers and materials offer a unique opportunity to tailor the light-dispersion in the strong to ultra-strong coupling regime. Finally, if time permits, I will discuss the physics of strong light-matter coupling and its applications in phase modulator devices, photovoltaic devices as well as control of light in magnetic semiconductors:

NS-ThP-5 Scalable Photonics with Low-Dimensional Superlattices, *Jason Lynch, Deep Jariwala*, University of Pennsylvania

Superlattices of III-V semiconductors have long been used in state-of-the-art photodetectors, light emitting diodes, and lasers while plasmonic superlattices promise to surpass the diffraction limit of light and confine light on the nanometer scale. However, both cases typically use three-dimensional media which do not leverage the advantages of improved electro-optical properties, flexibility, and stability found in low-dimensional media. Recent research has demonstrated superlattices with monolayer semiconductors, but they normally use exfoliated flakes which limit their lateral areas to several square microns. As the growth of large-area, low-dimensional materials becomes more common, integrating low-dimensional media into superlattices promises to improve the performance of commercially available photonic devices. In this poster, we highlight two of our recent works that use 2D layers to improve the tunability and stability of centimeter-scale superlattices. First, we stack monolayer transition metal dichalcogenides (TMDCs) into a superlattice to increase the light-matter interaction strength without sacrificing their ideal monolayer properties. By electrostatically doping the TMDC layers, the system is actively modulated between the strong and weak coupling regime of

¹ JVST Highlighted Poster

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exciton-polaritons which drastically alters reflected light. Using spectroscopic ellipsometry, the TMDC superlattice is observed to produce a full 2π phase shift in the reflected light. Second, we improve the thermal stability in a TiN-dielectric hyperbolic superlattice by replacing the three-dimensional Al_2O_3 with two-dimensional hBN. The new mixed-dimensional interface prevents atoms from diffusing across the TiN-hBN interface. This results in the superlattice maintaining its stratified geometry upon annealing at high temperatures (800 °C) for at least 10 hours. Both works study centimeter-scale superlattices whose fabrication techniques (wet-transfer and sputtering) can be implemented commercially. Therefore, our work promises to bring the improved qualities of low-dimensional media to practical, large-area photonic systems.

NS-ThP-6 Optical Readout Approaches for Photonic Thermometry, Kevin Douglass, Michal Chojnacky, Thinh Bui, CH S S PAVAN Kumar, Nikolai Klimov, National Institute of Standards & Technology

NIST is developing a fully packaged photonic-based temperature sensor with the aim of replacing resistance-based thermometry. One of the major deliverables of our photonic thermometry project is creating readout methodologies tailored to the measurement need from highest accuracy metrology applications to real world temperature sensing with fit-for-purpose accuracy in a robust deployable system. Over the past year we have developed and tested various photonic readout strategies to achieve these various goals. These approaches will be described in detail with supporting data to compare their respective advantages and disadvantages.

NS-ThP-7 A Comprehensive Investigation of Raman Laser-Induced Structural Modification in CVD-Grown Monolayer MoS_2 , Sieun Jang, Seonha Park, Songkil Kim, Pusan National University, Republic of Korea

Molybdenum disulfide (MoS_2) has been extensively explored to be utilized as an electronic material in a variety of device applications. In particular, the tunability of MoS_2 enhances its electrical properties making it an intriguing candidate for field-effect transistors (FETs), while also extending beyond electrical properties to structural phase engineering. Raman laser irradiation offers a straightforward method to induce modifications via thermal processes without the intervention of other chemical substances. However, most studies on the modification of MoS_2 have focused on multi-layered structures or have been conducted under low-power laser conditions, leaving the feasibility of phase transition in monolayer MoS_2 elusive. In this study, we fundamentally elucidated the effects of high-power Raman laser irradiation on the surface of chemical vapor deposition (CVD)-grown monolayer MoS_2 under ambient conditions and uncovered the underlying mechanisms of laser-induced modifications by applying intense photon energy with highly interactive reactions. Our results revealed both etching and deposition phenomena in two discernible regions, and it can be demonstrated by intensity threshold based on the spatial distribution of laser irradiance within the laser spot. Furthermore, phase transition was found to be inhibited due to the promoted oxidation and the deposition of hydrogenated amorphous carbon, and p-type doping was observed, likely occurring in the region beneath the hydrogenated amorphous carbon deposition as substitutional doping on the 2H phase of MoS_2 . To compare the thermal effects, MoS_2 modifications were further analyzed using simplified heat transfer estimations. These findings deepen our understanding of how Raman laser irradiation modifies MoS_2 under ambient conditions, providing guidelines for optimizing its modification processes.

NS-ThP-8 Reconstructing the Cross-Sectional Form Factor in Nanoscale Line Gratings via Critical-Dimension SAXS, Philipp Wieser, Center for Functional Nanomaterials, BNL, Austria; Kevin Yager, Center for Functional Nanomaterials, BNL, Canada

As technology nodes shrink toward single-digit nanometer dimensions, non-destructive shape metrology with sub-nanometer precision becomes increasingly important. Here, we present improvements to critical-dimension small-angle x-ray scattering (CD-SAXS) methods as metrology for line gratings patterned by electron-beam and extreme-ultraviolet (EUV) lithography. We introduce a rounded-trapezoid model to capture realistic cross-sections of lithographic patterns, especially in the developed resist. We further address a fundamental limitation of CD-SAXS: the sparse sampling of reciprocal-space due to the concentration of scattering into sharp grating peaks. To overcome this limit, we explore the concept of engineering the grating repeat (structure factor), to more faithfully reconstruct the pattern's shape (form factor). We explore three complementary strategies: (i) systematically varying the fundamental pitch, (ii) embedding multiple pitches in designed supercells, and (iii) introducing controlled aperiodic disorder. The resulting ensemble of SAXS patterns

yields a more complete description of the cross section and enables to include statistical variability of the cross section directly into the model calculations.

NS-ThP-9 Phase Retrieved Atomic Structure of Nanoparticles by Using 4D STEM, Chien-Nan Hsiao, National Center for Instrumentation Research, National Institutes of Applied Research, Taiwan; Yu-Ting Peng, Department of Engineering and System Science, National Tsing Hua University, Taiwan; Wen-Hao Cho, Wei-Chun Chen, Su-Chun HSIAO, National Center for Instrumentation Research, National Institutes of Applied Research, Taiwan; Chien-Chun Chen, Department of Engineering and System Science, National Tsing Hua University, Taiwan

Atomic resolution microstructure of Au-Pd nanoparticles is characterized by a 4D STEM (scanning transmission electron microscopy). A defocused electron probe is raster-scanned across the specimen atom by atom, with one electron diffraction pattern recorded at each probe position in real-space by a pixelated array detector in reciprocal-space. The acquisition parameters of electron ptychographic experiments were optimal design, such as the electron probe semi-angle, real- and reciprocal space sampling, exposure time and field of view. It is found that the high dynamical range of the detector collection capacity ensures that scattered electron information is completely preserved, which enhances the S/N ratio of convergent beam electron diffraction (CBED) patterns. In addition, the phase image of object and electron probe are retrieved by an algorithm, the resolution of phase retrieved image is approaching to 0.59 Å. Moreover, the simultaneously atomic morphology is mapped by center of mass (COM) analysis differential phase contrast (DPC) technique.

NS-ThP-10 AFM Measurements of Nanoscale Changes on CHO Cell Surface Induced by Met Receptor Activation, Kenta Sawada, Keisuke Miyazawa, Takehiko Ichikawa, Makiko Kudo, Katsuya Sakai, Kanazawa University, Japan; Hiroki Sato, Yokohama City University, Japan; Kunio Matsumoto, Takeshi Fukuma, Kanazawa University, Japan

Cell migration and proliferation involve cell surface changes induced by signal transduction via cell membrane proteins. However, detailed mechanisms of these processes have not been fully understood. Atomic force microscopy (AFM) can visualize cell surface changes in liquids and hence has been applied to the studies in drug discovery and medical research by visualizing cell surface changes induced by biological and pharmaceutical molecules. However, practical applications and measurement examples remain limited. In this research, we investigated signal transduction mediated by cell membrane receptor called Met. Cell migration and proliferation are known to be promoted by Met. However, cell surface changes during these processes remain unclear. Thus, we investigated structural changes of the cell surface induced by Met activation by AFM. In this research, we used Chinese Hamster Ovary (CHO) cells. Two cell lines were cultured on plastic dishes: cells not expressing Met (Met-KO) and cells overexpressing Met (Met-in). AFM measurements were performed using NanoWizard 4 (Bruker) in L-15 medium (Fig. 1a). Figure 1b(i) shows AFM image of the Met-in cell surface. In this image, protrusions and fibers are observed as indicated by the arrows in Fig. 1b(i), which are probably microvillus (blue arrows) and F-actins (green arrows), respectively. Thus, in this study, surface areas of microvilli in the AFM images of the Met-KO and Met-in cells were estimated by extracting areas higher than a threshold value (Fig. 1b(ii)). The result reveals that the Met-in cells show larger surface area of microvilli than Met-KO cells (Fig. 1c). These results suggest that Met activation promotes F-actin formations through subsequent signal transduction, which increases the number of microvilli on the cell surface. This is consistent with the previous report confirming the cell motility enhancement caused by the Met activation. Meanwhile, the spatial resolution of a typical AFM in living cell measurements is not sufficient to visualize molecular-scale distributions or structural changes of Met on the cell surface. Thus, technical improvements of AFM measurements such as suppressing cell surface fluctuations and increasing measurement speed are required. Thus, we have recently developed techniques aiming for molecular-scale AFM measurements at cell surfaces. In this presentation, we introduce measurement examples using not only a typical AFM method but also our recently developed AFM technique. Such advancements in AFM technology should enable direct visualization of various structural changes of the cell surface and investigation of the mechanisms of cellular functions.

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NS-ThP-11 Manufacture of Liquid Metal Alloy Ion Source Tin-Lead for Advancement of Ion Beam Technologies and Applications, Bryan Flores, Alex Andrei Belianinov, Michael Titze, Shei Sia Su, Coleman Burdette Cariker, Sandia National Laboratories; Ricardo Dacosta, University of California - Riverside

Focused Ion Beam (FIB) Technology has significantly advanced in capability and performance over the past decades. FIBs in today's research play vital roles in material analysis, imaging, device fabrication, life sciences, and medicine – all at the nano-scale. Initially, Gallium (Ga) was the only available FIB ion source while other elements were largely unavailable. The low melting point of Ga ($T_m = 29.6^\circ\text{C}$) in addition to the emitted ionic species being 99% majority singularly charged (Ga^+) gave Ga the early advantage over other FIB source technologies. However, the advent of Wien-filter (ExB mass filter) FIBs to separate distinct ion species, in combination with eutectic Liquid Metal Alloy Ion Sources (LMAIS) has vastly increased the library of ion species generated in FIBs enabling nanoscale fabrication and analysis. Ion species with various charge states and with multiple elements can all be emitted from a single LMAIS. With assistance of a Wien filter the desired ion species can be selected from a mass spectrum. Here we detail the creation and characterization of a eutectic Tin-Lead (SnPb) LMAIS through its appropriate IV curves, mass spectrum, and spot size. We expect future applications in nano-scale and/or quantum research and applications such as solid-state quantum emitters or Group-IV color centers in Diamond (SnV¹).

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NS-ThP-12 Characterization of GAA FETs using Noise Spectroscopy after Displacement Damage, Ricardo Dacosta, Coleman Cariker, Bryan Flores, Shei Sia Su, Alex Belianinov, Michael Titze, Sandia National Laboratories, USA

Gate-all-around (GAA) field effect transistors (FETs) have been announced as the next generation of transistors by all major integrated device manufacturers. GAA FETs are targeted for logic nodes with sub 3nm size and are projected to operate at ultralow voltages ($<0.7\text{ V}$) and high performance ($>4\text{ GHz}$). By having the gate fully surround the channel GAA FETs isolate the sensitive channel regions of the device from the silicon substrate. This device architecture is expected to make GAA FETs behave like radiation-hard-by-design silicon-on-insulators (SOI) devices by significantly improving the dose-rate upset (DRU) response at similar total ionizing dose (TID) compared to conventional FETs.

Despite GAA NSFETs being expected to be radiation hard against DRU, the full effect of radiation damage on these devices is complex. GAA FETs are much smaller than current state of the art FETs which is an advantage as it allows for scaling device density. Due to this reduction in size each individual device has a much lower chance of being damaged via radiation. However, displacement damage (DD) and subsequent damage cascades have a much larger effect on a singular device, damaging a relatively larger region of devices. Statistical models and experimental data indicate that single ion collision events lead to an increase in subthreshold leakage current. Additionally, high damage levels show a significant reduction on forward current, which can permanently disable devices. Devices are predicted to become increasingly more vulnerable to such damage as they become smaller.

Noise spectroscopy can help illuminate the underlying defects responsible for device degradation in a DD environment. Preliminary noise spectra data show after sufficient irradiation ($\sim 2.6 \times 10^{13}\text{ ions/cm}^2$) these devices exhibit a significant increase in low frequency noise. Further analysis shows gate-drain tunneling as a source of subthreshold leakage current, with source-drain tunneling increasing with more radiation fluence. In this poster we will explore the effects of DD via irradiation on GAA FETs using noise spectroscopy.

We thank International Business Machines for providing devices, specifically Vijay Narayanan, Miaomiao Wang, Julian Warchall, and Huimei Zhou. Sandia National Laboratories is a multimission laboratory managed and operated by National Technology & Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International Inc., for the U.S.

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Plasma Science and Technology

Room Ballroom BC - Session PS-ThP

Plasma Science and Technology Poster Session

PS-ThP-2 Dependence of MQW Sidewall Damage on Ion Incident Angle: Insights from Molecular Dynamics Simulations, Eun Koo Kim, Hyun Woo Tak, Geun Young Yeom, Sungkyunkwan University (SKKU), Republic of Korea
Micro-LED (uLED) technology is emerging as a next-generation display solution due to its high brightness, energy efficiency, and scalability. In uLEDs, multiple quantum wells (MQWs) serve as the primary light-emitting layers, and preserving their optical performance is critically dependent on minimizing sidewall damage. As the lateral dimensions of uLEDs continue to shrink, the increasing proportion of sidewall area makes it critical to control the damage that is inevitably introduced during plasma etching processes. Such damage leads to increased non-radiative recombination at the sidewalls, which in turn significantly degrades the external quantum efficiency of the device. [1]

Although several approaches such as sidewall passivation using various materials and post-treatment techniques [2], as well as atomic layer etching (ALE), have been proposed to mitigate this issue [3], a comprehensive understanding of how the ion incident angle affects MQW sidewall damage remains lacking.

In this study, we employ molecular dynamics (MD) simulations to investigate the angle-dependent characteristics of ion-induced sidewall damage in MQW structures. Specifically, the analysis is categorized into (1) physical damage induced solely by ion bombardment and (2) damage resulting from ion bombardment after reactive radical adsorption—simulating typical RIE and ALE conditions. The simulations are designed to quantitatively evaluate the extent of structural damage in terms of penetration depth, surface roughness, sputtering yield, and dislocation formation, as functions of ion incident angle, ion kinetic energy, and ion dose.

The results of this study provide atomistic insights into the mechanisms of ion angle-dependent sidewall damage of MQWs and offer valuable guidance for optimizing plasma etching processes in advanced uLED fabrication.

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PS-ThP-4 Atomic Layer Etching of GaN Micro Light-Emitting Diodes with Different Sidewall Slope, Yun Jae Park¹, Geun Young Yeom, Hong Seong Gil, Jong Woo Hong, Sungkyunkwan University (SKKU), Republic of Korea

GaN-based micro light-emitting diodes (μLEDs) are widely used in display technologies due to their high brightness and high endurance in harsh environment. However, during the reactive ion etching (RIE) process for device definition of GaN-based μLEDs, damage to the activation layer or sidewalls can significantly degrade the device's external quantum efficiency (EQE). To mitigate this, various methods, such as optimizing the etch process or conducting post-etch processes (passivation insulator deposition, annealing, wet etching), have been studied to remove the damaged layer. However, more precise damage control techniques are needed as device dimensions shrink. [1]

In this study, we propose combination of wet etching with a plasma-based anisotropic atomic layer etching (ALE) process to remove sidewall damage induced by ICP-RIE. Tetra methyl ammonium hydroxide (TMAH) wet etching, commonly used to remove the damaged layer and to improve the etch profile in GaN-based μLEDs, is dependent on the crystal orientation, causing changes in the sidewall angle during processing. We examined how well the optimized ALE process could be applied to remove remaining sidewall damage across various sidewall angles, which vary with TMAH treatment time. To analyze the effect of ALE, we observed changes in electrical and optical performance, confirming improvements in both EQE and I-V characteristics when sidewall damage was effectively eliminated.

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Furthermore, transmission electron microscopy (TEM) analysis revealed that the damaged lattice region near the sidewall had been removed, supporting the physical recovery observed through electrical characterization.[2]

This study shows that sidewall angle, etching, and surface treatment all play an important role in enhancing μ LEDs performance. The results suggest that employing ALE to precisely control the sidewall can improve the efficiency of GaN-based devices.

References:

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PS-ThP-5 Anomalous Behavior of Plasma Potential in a Planar Helical Resonator Discharge, *Un Jae Jung, Yeong Jae Jeong, Min Seok Kim, Chin Wook Chung*, Hanyang University, Republic of Korea

Since a helical resonator plasma source does not require a matching network, it enables high-efficiency discharges and is considered a promising next-generation plasma source. An anomalous increase in plasma potential is observed in a planar helical resonator. As the applied power increases from 10 to 50 W, the plasma potential first increases and then shows a decreasing trend, similar to the E-to-H mode transition observed in inductively coupled plasmas (ICPs). Interestingly, as the power is further increased to approximately 400 W, the plasma potential increases again. The abnormal increase in plasma potential observed at high power disappears when a Faraday shield is inserted between the antenna and the plasma. This behavior is attributed to the significant amplification of the helical antenna voltage caused by resonance. These findings provide insight into the mechanism of plasma potential formation in planar helical resonator discharges and the role of antenna-plasma coupling.

PS-ThP-6 Low-damage Atomic Layer Etching process for GaN-based Light Emitting Diodes, *Chan Ho Kim, Jong Woo Hong, Geun Young Yeom*, Sungkyunkwan University (SKKU), Republic of Korea

Today, due to its wide direct bandgap and high efficiency, Gallium Nitride (GaN) based devices have gained significant attention in various applications such as light-emitting diodes (LEDs) and power semiconductors. As the critical dimension of LED devices becomes smaller, reactive ion etching (RIE) process is widely used to fabricate GaN based devices to achieve anisotropic profile. However, ion bombardment during RIE process causes surface damage, which deteriorates GaN based LED device performance. This problem becomes more significant as critical dimension of LED device becomes smaller due to the higher ratio of sidewall area to total area.

In this study, atomic layer etching (ALE) process is introduced after RIE process to remove damage caused by RIE process in GaN based structure, including multi-quantum well (MQW) layer composed of InGaN and GaN. In TEM images, the MQW layer appeared indistinct after RIE process. Although wet etching followed by RIE improved layer visibility to some degree compared to RIE process, ALE process made the MQW layer more clear than wet etched MQW, indicating more appropriate damage removal. X-ray photoelectron spectroscopy (XPS) analysis exhibited that RIE induced damage changed the atomic ratios of N/Ga and Ga/In relative to reference data. However, after ALE process followed by RIE, the atomic ratios were returned similar to the reference data, although wet etch process also slightly restored atomic ratios. Furthermore, like XPS analysis data, Raman spectroscopy revealed that ALE process removed damage more efficiently compared to wet etch. Photoluminescence (PL) measurements at the same area showed that, as device size decreased, the damage caused by RIE is worse. However, PL intensity improvement was observed after ALE treatment and, as device size is smaller, the improvement in PL intensity is higher. Therefore, compared to wet etch process after RIE, ALE offers superior surface damage removal, especially showing its effectiveness in smaller devices.

PS-ThP-7 Comparison of SiN_x/SiO_x contact hole etching between CF₄ and low global warming gas, *Jun Won Jeong, Geun Young Yeom, Jong Woo Hong*, Sungkyunkwan University (SKKU), Republic of Korea

Demands for thinner, lighter, and higher-resolution panels in digital devices such as mobile phones, TVs, and laptops has led to the evolution of display technology such as LTPS (Low-Temperature Polycrystalline Silicon)

technology. [1-2] LTPS thin film transistor (TFT) uses the excimer laser annealing (ELA) for crystallizing amorphous silicon (a-Si) at lower temperatures, therefore, LTPS achieves significantly higher electron mobility than conventional a-Si. [3] In the device processing for next-generation LTPS TFT, optimizing the SiN_x/SiO_x stack contact hole dry etching process is critical. This requires high SiN_x/SiO_x stack etch rates, minimal sidewall damage, and anisotropic etch profiles, and, conventionally, CF₄ is generally used in the SiN_x/SiO_x stack contact hole etching. This study compares the conventional perfluorocarbon (PFC) CF₄ gas with low global warming potential gases in the dry etching of SiN_x/SiO_x stack contact holes.

By using low global warming potential gases instead of conventional CF₄ in the etching of SiN_x/SiO_x stack, little lower SiN_x/SiO_x etch rates compared to CF₄ were obtained, however, much similar etch selectivity between SiN_x and SiO₂ in addition to higher etch selectivity over photoresist could be observed. In addition, more anisotropic etch profiles of contact hole and the lack of microtrenching at the edge of contact hole could be obtained with low global warming gases. The etch mechanism could be confirmed by observing the plasma characteristics with OES and QMS, and by measuring the surface characteristics after etching with XPS.

Therefore, for the contact hole etch processing, it is believed to be possible to replace CF₄ having a high global warming potential with alternative low global warming gases with enhanced etch characteristics.

PS-ThP-8 Enhancing Etch Characteristics of MTJ using RF-Biased RIBE, *Kyoung Chan Kim, Yun Jong Jang, Hong Seong Gil, Woo Chang Park, Dae Yeon Ha, Su Jeong Yang, Geun Yeong Yeom*, Sungkyunkwan University, Korea

STT-MRAM is actively researched as a next-generation memory due to its non-volatility, fast operation, high stability, and ease of scaling, all of which are essential for high-performance computing and AI advancements. Materials such as CoFeB, Ru, MgO, etc. are used in the Magnetic Tunnel Junction (MTJ) layer for data storage in addition to CoPt and CoIr to enhance magnetization stability. A common etching method for these MTJ stack layers is Ar⁺ Ion Beam Etching (IBE). However, the Ar⁺ IBE process leads to MTJ etch by-products redepositing on the pattern sidewalls. Tilting the substrate during Ar⁺ IBE is generally used to address this issue but does not fully resolve issues like shadow effects especially for recent high aspect ratio and small CD patterns. Previously, to address these issues, Reactive Ion Beam Etching (RIBE) has been investigated with reactive gases such as CO/NH₃ and Cl₂ to improve volatility of etch by-products. However, this can degrade the MTJ magnetization properties. RIBE process using H₂/NH₃ mixed gases has been also investigated to mitigate some of these issues. This study aims to improve etching characteristics by using mainly physical etching with slight chemical assistance by RF-biasing. Ar gas is injected for physical etching while H₂/NH₃ mixed gas is injected on to the substrate for chemical effect. When RF power is applied to the substrate, the plasma of H₂/NH₃ mixed gas is discharged on the substrate and induces RF-Biased RIBE. SEM images were taken to analyze etch characteristics. TEM measurements were conducted to analyze the sidewall residues.

PS-ThP-9 Etch Characteristics of Ru-Pt Composite Using Halogen-Based Gases, *Hyeong Joon Eoh, Geun Young Yeom*, Sungkyunkwan University (SKKU), Republic of Korea

The lithography process is a key step in patterning, and it is one of the most challenging processes in the introduction of high-resolution semiconductor manufacturing. To overcome this challenge, advancements in photolithography technology have been progressing in the direction of utilizing shorter wavelength light sources. This has led to the development of Extreme Ultraviolet Lithography (EUVL), which is now used in a few nm processes. High-NA EUVL is a further refinement of this technology, enabling stable patterning even at sub-2 nm processes. As the photomask for EUVL, reflective mask containing patterned EUV absorbing layer is used. TaN-based EUV absorber is generally used as an EUV mask absorber but, for High-NA EUV systems, a new EUV mask absorbing layer is known to be required to reduce image distortion, which degrades pattern quality. Ru-Pt composite is a strong candidate to replace the TaN-based absorber, considering the above conditions. In this study, the etch characteristics of the Ru-Pt composite are examined using halogen-based plasmas. The Ru/Pt composition ratio was varied, and the corresponding etch characteristics were investigated.

When etching the Ru-Pt composite using fluorine-based gas in an ICP system, the etch rate increased with increasing Ru content in the Ru-Pt composite. In contrast, under chlorine-based gas chemistry, the etch rate increased with increasing Pt content in the Ru-Pt composite. In the case of

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pure Ar+ ion sputtering without halogen gases, the etch rate increased with increasing Ru content in the composition. The effects of various process conditions on the etch characteristics of Ru-Pt composite required for EUV mask will be shown in the presentation.

PS-ThP-11 Isotropic Atomic Layer Etching of MoS₂ using Oxygen Plasma and Organic Solvent Vapor, Sunjae Jeong, Hyewon Han, Jieun Kang, Jimin Kim, Geunyoung Yeom, Sungkyunkwan University (SKKU), Republic of Korea
Preciselayer control of two-dimensional transition metal dichalcogenides (TMDs) is essential for the implementation of high performance electronic and optoelectronic devices. Atomic layer etching (ALE), which allows for precise layer control, can be performed using either thermal or plasma-based methods, enabling uniform etching. While conventional anisotropic etching has primarily been carried out through radical adsorption followed by ion-induced desorption, the increasing complexity of three-dimensional semiconductor device structures has led to a growing demand for isotropic etching techniques.

In this study, we utilize a method in which reactive radicals are generated through oxygen plasma and adsorbed onto the MoS₂ surface, followed by exposure to organic solvent vapor to facilitate the desorption of individual layers, thereby enabling precise layer control. Compared to conventional etching methods, this approach allows for damage-free processing while significantly improving the uniformity and precision of layer removal. Additionally, we compare the etching performance based on the chemical structure of the organic solvent vapor and the process temperature, emphasizing differences in reactivity and volatility during the etching process. These are important parameters in determining the efficiency and selectivity of the etching process. Our results confirm that the MoS₂ layers can be etched using a controlled manner, with approximately one monolayer removed per cycle, as verified through Raman spectroscopy and atomic force microscopy (AFM) analysis.

By achieving precise layer control of MoS₂, this study represents a significant advancement in the integration of TMD materials into next-generation electronic and optoelectronic devices. The findings contribute to the broader field of advanced materials research, paving the way for improved manufacturing techniques that meet the demands of future semiconductor technologies.

PS-ThP-12 Anticathode Effect on Multimodal Azimuthal Oscillations in Electron Beam Generated ExB Plasma, Nirbhav Chopra, Applied Materials, Varian Semiconductor Equipment; Yevgeny Raitses, Princeton Plasma Physics Laboratory

Electron beam (e-beam) generated plasmas with applied crossed electric and magnetic (ExB) fields are promising for low-damage (gentle) material processing [1]. However, these plasmas can be subject to the formation of plasma non-uniformities propagating in the ExB direction. These rotating plasma structures (or 'spokes') enhance the transport of electrons and ions across the magnetic field, which can harm the gentle processing capability of plasma. In this work [2], we investigate the role of electrostatically active boundaries on the spoke formation by incorporating a variable bias conducting boundary (known as an anticathode) placed on the axially opposite side of the cathode. Our findings indicate suppression of azimuthal modes occurs when the anticathode is electron collecting. Furthermore, we show the highest frequency azimuthal mode is selectively suppressed by biasing the anticathode to an intermediate potential between the cathode and anode potentials. These findings suggest a link between the axial electron confinement in the e-beam generated plasma and azimuthally propagating plasma structure formation.

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PS-ThP-13 Plasmonic Plasma Process for Room Temperature Growth of Ultra-Thin Dielectric Films, Takeshi Kitajima, Machiko Miyake, Toshiki Nakano, National Defense Academy, Japan

Catalytic surface reactions utilizing gold nanoparticle plasmons have been utilized in various applications in recent years.¹ We have applied hot electrons supplied from gold nanoparticles to plasma surface reactions to use them to form high-quality ultrathin films at room temperature.² We focused on the mixed effect of visible light for plasmon excitation and plasma VUV emission and discovered the effect of green light excitation that promotes radical nitriding. Due to the mercury probe measurement and TEM imaging, the film grown have superior dielectric feature and uniformity with less plasma induced damage in spite of nonuniform formation of gold nanoparticles. In the growth sequence, Au was vapor-

deposited on a SiO₂/Si(100) substrate in an ultra-high vacuum chamber with an average thickness of 0.4 nm by electron beam deposition to form Au nanoparticles (C) on the surface. A 30 mTorr N₂-inductively coupled plasma was generated in the attached chamber, and the sample was irradiated with N radicals (R) that passed through a 30 line/inch SUS304 single mesh with the configuration shown in Fig.1(a) for 5 minutes. A filter and a white LED controlled the wavelength of light (L), and VUV light from N₂ plasma was mixed. The reaction condition consisting of the above is RLC. Fig.1(b) shows the dielectric characteristics of the SiON film {leakage current and EOT (equivalent oxide film thickness) when 1 V is applied}. In green light suitable for Au plasmons, the hot electrons (~ 4 eV) generated by the deexcitation of plasmons enabled the bond conversion from Si-O to Si-N the ultra-thin SiON shows the same characteristics as the thermal oxide film. By mixing VUV, it is possible to increase the film thickness further and reduce leakage. Cross-sectional TEM image of SiON film after plasmonic process is shown in Fig.1(c). Beneath the Au particle SiON film with wide range of uniformity is confirmed and the single crystal lattice of Si substrate is clearly identified. Mixture of Au atoms into the dielectric film is examined with EDX spectrum shown in Fig.1(d). Au peak at 2.121 keV and 9.712 keV are less than the detection limit. From the above, it is considered that the reaction between the adsorbed N radicals and Si proceeded, and a good quality SiON film was formed by superimposing the photoelectron emission from the VUV light on the hot electron injection from the Au nanoparticles by green light irradiation.¹ C. Clavero, *Nat. Photonics* **8**, 95 (2014) 2 T. Kitajima, M. Miyake, K. Honda, and T. Nakano, *J. Appl. Phys.* **127**, 243302 (2020).

PS-ThP-14 Interaction of Sapphire (Single-Crystal Al₂O₃) and Ni-Based Alloy Surfaces with Halogen-Containing Plasmas and Gases, Takuya Ishihara, Hidenobu Tochigi, Azbil corporation, Japan; Hojun Kang, Osaka University, Japan, Republic of Korea; Kazuhiro Karahashi, Satoshi Hamaguchi, Osaka University, Japan

In semiconductor manufacturing processes such as dry etching or chemical vapor deposition, capacitance manometers are widely used as essential vacuum pressure sensors to monitor and control the pressures of process gases. These gauges must be corrosion-resistant against process gases such as halides and their radicals generated by the plasmas. The diaphragm material of the manometer is especially important because, if its surface is altered by such corrosive gases, the sensor would send imprecise output signals possibly with the zero-point drift or pressure sensitivity shift. The errors are caused by the changes in mechanical properties of the diaphragm arising from the formation of the modified surface layer. For this reason, Ni-based alloys or polycrystalline ceramics of aluminum oxide (Al₂O₃) are typically used as the diaphragm material of capacitance manometers. More recent capacitance manometers employ sapphire (single-crystal α -Al₂O₃) as their diaphragm material, which is of specific interest in this study[1]. Recent studies on the interactions of polycrystalline Al₂O₃ with fluorine-containing plasmas indicated the formation of aluminum fluoride layers on Al₂O₃ exposed to such plasmas[2,3,4,5,6]. We have reported the results of ion beam experiments to understand the surface modification mechanisms of Ni-based alloys and polycrystalline Al₂O₃ film by fluorine-containing plasmas[7]. In this study, similar ion beam experiments with sapphire substrates have been executed to compare the surfaces of single-crystal Al₂O₃ and polycrystalline Al₂O₃. In addition, Ni-based alloy samples were exposed to xenon difluoride (XeF₂) gases for 1,3,6, and 12 months, and their fluorinated surfaces were analyzed and compared with the sapphire surfaces under the same conditions reported previously[7].

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PS-ThP-15 3D Feature Profile Simulation with Realistic Plasma Chemistry for High Aspect Ratio Etching in the Memory Industry, Ju Won Kim, Seong Yun Park, Hae Sung You, Jae Hyung Park, Jeonbuk National University, Republic of Korea; Kook Hyun Yoon, Sung Sik Shin, Dong Hun Yu, KWTsolution, Republic of Korea; Yeon Ho Im, Jeonbuk National University, Republic of Korea

The memory industry has faced drastic challenges in high aspect ratio etching processes consisting of ON stacks (SiO₂/SiN) or SiO₂ to achieve higher cell densities or cell capacities. Recently, the problems encountered in HAR etching processes are mainly due to abnormal profiles such as necking, bowing, random distortion. Despite these difficulties, current process development is still largely based on trial and error due to the inherent complexities of plasma physics and chemistry and plasma-surface interactions. To address this issue, we have developed a 3D feature profile simulation platform called K-SPEED, which includes a zero-D reactor simulation, a multi-level set algorithm, a ballistic transport algorithm and a surface reaction model. The accuracy of this approach has been verified by the intensive comparative study of experimental evidence. In this work, we investigated the origin of abnormal profiles using realistic 3D feature profile simulation along with key process conditions. We believe that our process simulation platform will significantly help to optimise the HAR process for the next generation of memory devices.

PS-ThP-16 Plasma Anodization for the Production of AlF₃ Layers, Scott Walton, Naval Research Laboratory; Javier del Hoyo, NASA; Michael Johnson, Naval Research Laboratory; Luis Rodriguez de Marcos, NASA; Makenzie Meyer, John Murphy, Naval Research Laboratory; Manuel Quijada, NASA; Maria Sales, Virginia Wheeler, David Boris, Naval Research Laboratory

Efficient ultraviolet (UV) mirrors are essential components in space observatories for UV astronomy. Aluminum mirrors with fluoride-based protective layers are commonly the baseline UV coating technology; these mirrors have been proven to be stable, reliable, and have a long flight heritage. However, despite their acceptable optical performance, it is still insufficient for future large telescopes in which several reflections are required. Recently, a readily scalable, plasma-based passivation process was developed to produce a thin AlF₃ layer on the surface of aluminum. The passivation process uses an electron beam generated plasma produced in a fluorine-containing background (SF₆ or NF₃), to simultaneously remove the native oxide layer while promoting the formation of an AlF₃ layer with a tunable thickness. This process has the characteristics of established aluminum anodization approaches – either electrochemical or plasma – except here, fluorine replaces oxygen as the reactant. The process takes advantage of the ability of electron beam driven plasmas produced in electronegative gas backgrounds to generate substantial densities of negative ions, which can be delivered to the surface and utilized to grow the fluoride layer. While layer thickness scales with applied bias as expected, the growth rates are challenging to understand. In this presentation, we will discuss the process using operating parameter studies, plasma diagnostics, and materials characterization, with an eye on understanding the growth mechanisms and the potential for better process control. This work is supported by the Naval Research Laboratory base program and NASA grant no. NNH20ZDA001N/20APRA200093.

PS-ThP-18 Experimental Investigation of the Interactions between Piezoelectric Crystals and Plasma Discharges, Jinyu Yang, Zhongyu Cheng, Sean Kerr, David Go, University of Notre Dame

Direct piezoelectric effect of non-centrosymmetric crystals, such as lithium niobate (LN) and lead zirconate titanate (PZT), provides opportunities to develop energy conversion plasma sources that remedy the need for high-voltage power supplies by directly transforming mechanical energy into plasma generation. To date, insight into the fundamental interactions and coupled physics between piezoelectric materials and plasma behaviors remains in its early stages. In this work, we utilized LN and PZT piezoelectric transformers (PTs) as model systems to investigate whether the level of the mechanically induced polarization in a piezoelectric crystal appreciably alters the behavior of a pulsed helium plasma jet impinging upon its surface, and whether these interactions manifest themselves in electrical characteristics. Preliminary optical and electrical characterization revealed that the morphology of the plasma jet plume and its contact at the plasma-crystal interface varied when the plasma jet generation was synchronized to different phases (i.e., different levels of polarization) of the input voltage to the PT. While no appreciable difference was observed in the plasma jet current, the current through the PT exhibited obvious suppression by the plasma jet, with the degree of suppression depending on the phase synchronization. Future studies will aim to achieve a more comprehensive

understanding of these phenomena using time-resolved imaging technology and to determine if the dominant plasma properties, such as electron density and electron temperature, are also sensitive to the changes in polarization. Experimental findings from this work will be compared with simulation results, assisting in the development of a multi-dimensional, pizeo-plasma coupled model.

PS-ThP-19 Tailoring of Pulse Voltage Waveform for Monoenergetic Ion Energy Distributions, Seokhyeon Ha, Heyonho Nahm, Minseok Kim, Heejae Yang, Chin-Wook Chung, Hanyang University, Korea

Tailored voltage waveform on DC-pulsed bias has recently attracted interest as an effective means to control ion energy distribution functions (IEDFs). As the ion density increases, ion charging on the substrate increases, leading to a broadening of the IEDFs. For more advanced control of the IEDFs, a feedback system between the ion density and the applied voltage waveform is developed. To tailor the voltage waveform based on the measured ion density, a real-time ion density monitoring system is required. We employed a floating harmonic probe to measure the ion density in real time. Using the measured ion density, the slope of the voltage waveform is determined. This enables the IEDFs to remain narrow at various conditions

PS-ThP-21 Plasma-Assisted Uptake and Thermal Removal of Hydrogen in Liquid Lithium for Hydrogen Storage Applications, Braden Moore, University of Illinois at Urbana Champaign; Daniel O'Dea, University of Illinois at Urbana Champaign, UK; Meenakshi Sharma, University of Illinois at Urbana-Champaign, India; Elliot Sherman, Zach Nordan, Loren Calleri, Riley Trendler, David Ruzic, University of Illinois at Urbana Champaign

Lithium hydride is a potential material for reversible hydrogen storage applications due to its high hydrogen content and energy density. Metal hydrides, in general, enable high mass density storage of hydrogen at low pressures and moderate temperatures, making them attractive for integration into future energy systems. While solid-state metal hydrides have been studied for this purpose, hydrogen uptake in liquid lithium for energy storage applications remains relatively underexplored. Hydrogen production through industrial-scale electrolysis or thermochemical splitting often involves high-temperature systems that could inherently maintain lithium in its molten state during hydrogenation. The University of Illinois at Urbana-Champaign (UIUC) has constructed the Actively Pumped Open-Surface Lithium Loop (APOLLO), which consists of a flowing lithium loop, a lithium free-surface, a hydrogen plasma source, and a distillation column for the thermal extraction of hydrogen. The flowing liquid lithium surface can be exposed to an Electron Cyclotron Resonance (ECR) hydrogen plasma source that has been characterized with an array of 16 Langmuir probes, a Retarding Field Energy Analyzer (RFEA), and actinometric spectroscopy. The hydrogenated liquid lithium then flows to an inductively heated Hydrogen Distillation Experiment (HyDE), which thermally treats the lithium at temperatures above 700°C to remove hydrogen. This presentation will focus on preliminary measurements of hydrogen uptake and removal at very low hydrogen concentrations. Future work will expand to higher hydrogen concentrations that are more applicable for an efficient energy storage system.

PS-ThP-23 Ion & Electron Energy Control with High Voltage Tailored Bias Waveforms in a CCP, James Prager, Paul Melnik, Josh Perry, Chris Bowman, Timothy Ziemba, Kenneth E. Miller, EHT Semi

The demand for solid-state non-volatile memory storage has increased the importance of plasma etching for producing high aspect ratio (HAR) features. To minimize defects in HAR features, precise control of the ion energy distribution function (IED) is essential. Additionally, controlling the electron energy distribution function (EED) is crucial to prevent positive charge buildup, which can distort etched features. EHT Semi has developed a high-voltage bipolar pulse generator that operates at 400 kHz. This system generates negative bias voltage waveforms that are flatter than those produced by standard sinusoidal radio-frequency generators, enhancing control over IEDs and process stability.

EHT conducted both experimental and computational studies to understand the interaction between bias waveforms and plasma properties. Using the bipolar pulser with a capacitively coupled RF plasma source, ion and electron energy distributions were measured with a retarding field energy analyzer (RFEA) at bias voltages up to 1.5 kV. Argon/oxygen plasmas were briefly investigated. The hybrid plasma equipment model (HPEM) code was employed to create a computational analogue of the CCP chamber, further elucidating the system's capabilities.

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PS-ThP-24 An RF Generator Driving an Inductively Coupled Plasma Source Without a Matching Network, *Timothy Ziembra, Chris Bowman, Paul Melnik, Josh Perry, Connor Liston, James Prager, Kenneth E. Miller, EHT Semi*
Inductively coupled plasma (ICP) sources are used throughout the semiconductor and thin film industries. ICPs are driven by a radio frequency (RF) generator that is impedance matched to the plasma. However, matching networks increase the cost, complexity, and thermal management requirements of ICPs, which all scale with power of the RF generator. Additionally, the breakdown is often unreliable and takes a significant amount of time.

EHT Semi has developed a new RF generator that eliminates the need for a matching network. This RF generator is being tested on ICPs across a range of experimental parameters (power, neutral pressure, and gases). EHT will present results on breakdown time and reliability compared to traditional RF generators with a matching network. The generator response to plasma impedance changes and constant and variable power will also be presented.

PS-ThP-25 Investigation of Ion Flux/Sidewall Interactions in High Aspect Ratio (HAR) Features, *Tanjina Akter, David S. Kanfer, Steven Shannon, North Carolina State University*

Ion interaction with vertical sidewalls in high aspect ratio etching plays a critical role in the etch profile of features in advanced memory devices. Feature distortions such as notching, bowing, and footing can occur due to deposition, sputtering, or charge accumulation brought about by ion interaction with these sidewalls. Charge accumulation is one of these interaction types that contribute to profile distortion. Simulations have been conducted to spatially map this charge buildup, however, there is no diagnostic to provide experimental validation of this accumulation of charge. A novel diagnostic probe has been developed to measure the surface charge distribution inside the HAR features. The probe consists of an array of 10:1 aspect ratio vias (100 nm diameter) on PECVD Oxide with an aluminum ring encircling each via at varying heights. Voltage pickups from the aluminum rings enable the interpretation of a charge profile within the feature through differential measurement of voltage from an adjacent ring where the etched via is absent. This paper presents preliminary characterization of the ion particle flux and ion energy flux for an experimental CCP reactor that will be used to test this probe. A dual RF bias configuration with high (65 MHz) and low frequency (13.56 MHz) bias on each electrode has been employed to better control the ion energies. The control of ion flux distribution through the manipulation of the driving RF waveform can aid in mitigating charge-induced distortions and optimizing plasma processing for HAR structures. The IEDF was obtained by putting an RFEA on the lower-frequency electrode. Bimodal IEDFs were found for the pressure range of 1-100 mTorr, electron densities of 10^9 - 10^{11} cm $^{-3}$, and sheath potential of 50-1000 V using argon gas. The voltage at the top and bottom aluminum rings of a HAR via at the probe are calculated to be \sim 400 mV and \sim 100 mV respectively for the electron density of 10^{10} cm $^{-3}$ and electron temperature of 4 eV, indicating that the design will have sufficient measurement resolution to measure these charge distributions.

This work is supported by the Department of Energy Office of Fusion Energy Sciences (DOE OFES Grant DE-SC0024545).

PS-ThP-26 Real Time Plasma Temperature Profiling Using Short Wave Infrared Imaging, *Logan Holler, Drhuval Patel, Qerimi Dren, David Ruzic, University of Illinois at Urbana-Champaign; Michael Stowell, Lyten*

Recent research has increasingly focused on the growth of graphene within atmospheric pressure plasmas. While it is well established that graphene formation is highly temperature-dependent, the distinction between the formation of graphene flakes versus nodules remains insufficiently characterized within plasmas. A key step forward centers on better mapping the temperatures across our different plasma mixtures. However, conventional diagnostic tools often fall short: most diagnostic systems only provide one-dimensional snapshots, and physical probes degrade rapidly under the high temperatures present in these environments.

To overcome these limitations, we propose the use of Short-Wave Infrared (SWIR) imaging as a nonintrusive method to obtain real-time, spatially-resolved temperature measurements across our plasma systems. SWIR imaging leverages blackbody radiation emissions to determine temperature by integrating spectral radiance over the detectable range of our camera. Provided that the camera's solid angle to the plasma remains fixed, changes in the integrated spectral intensity can be used to derive

temperature ratios. By calibrating the system using a known temperature region within the plasma, we can correlate image intensity with absolute temperature for the same or similar plasmas by finding temperature ratios proportional to flux ratios. This allows for dynamic temperature mapping throughout the plasma, which is limited only to the refresh rate of the SWIR Camera.

Two methods are being developed to model and validate this approach. The first involves the insertion of a tungsten rod perpendicular to the flow of the plasma, which is incrementally raised through the plasma and allowed to reach thermal equilibrium at each position. This enables time-resolved images to determine temperature gradients and validate our current simulations. The second method involves varying gas mixtures to generate a calibration dataset, allowing the system to be adapted to different plasma environments. These experiments aim to correlate temperature regions with distinct graphene growth, such as flake versus nodule formation. Real-time, full-plasma monitoring also allows for characterizing how dynamic changes to the plasma occur, offering insight into the factors influencing graphene morphology.

PS-ThP-27 Monitoring Net CO₂ Dissociation Rates in the Effluent of Common Plasma Discharges with Optical Emission Spectroscopy, *Andrew C Herschberg, Nathan Bartlett, Jameson Crouse, Jaime Robertson, Emily Greene, David N Ruzic, University of Illinois at Urbana-Champaign*

Carbon dioxide is an important gas for many plasma discharges, among these include carbon capture and chemical conversion technologies. Such plasma-based systems offer increased sustainability by reducing net carbon footprints and limiting waste from industrial processes. During plasma excitation, much of the CO₂ present in the inlet flow will be reduced into CO or other products. Therefore, the CO₂ dissociation fraction can be used as a metric for extent of reaction and to optimize process efficiency. Many methods can be employed for this purpose; in this work, an OES method of interest is compared against a standard QMS measurement. These metrologies are implemented into the exhaust gas from a flowing inductively coupled plasma containing CO₂ and N₂. The OES method employs a self-actinometry technique, comparing the line ratios from the CO Angstrom and N₂ second positive spectroscopic systems. This is implemented through a Genco OPTIX Remote Spectrometer for a more direct comparison to a differentially pumped SRS Residual Gas Analyzer. Overall both methods were comparable, measuring similar dissociation fractions under tested parameters, with a maximum dissociation of approximately 90%. Actinometric constants for the OES method were stable, deviating by as little as 2% across tested conditions. Implementation of the OES self-actinometric method will require calibration on system of interest, but showed to be more consistent with lower error than the QMS method.

PS-ThP-28 Measurement and Modelling of Sn-H₂ Vapor Diffusion Coefficients in the Transition Flow Regime, *Jameson Crouse, Nathan Bartlett, Emily Greene, University of Illinois at Urbana-Champaign; Shiva Rajavali, ASML; Andrew Herschberg, University of Illinois at Urbana-Champaign; Sergio Ferraris, Niels Braaksma, ASML; David Ruzic, University of Illinois at Urbana-Champaign*

Extreme ultraviolet (EUV) lithography sources use tin in the process of generating 13.5nm wavelength light. Accurate modeling of neutral tin transport is important to understand how the tin coats different sections of the EUV source, which can reduce effectiveness. Modelling relies on knowledge of the diffusion coefficients of neutral tin vapor through molecular hydrogen. This work experimentally and numerically determined the diffusion coefficients of tin through molecular hydrogen at different tin temperatures and ambient pressures. Two experimental projects were used along with a CFD simulation and molecular dynamics simulation. For the most recent experiments, a known amount of tin is evaporated using an inductively heated crucible into a pipe with a known flow profile at a known ambient pressure. An OpenFOAM CFD model of the pipe is used to determine the flow profile within the pipe, along with the use of a diffusion model to predict tin transport. The pipe is inside of a large EUV source chamber prototype which can handle high hydrogen flows. Deposited tin is measured downstream of the pipe at varying distances with witness plates of different materials. Thickness measurements done with a profilometer are used to measure tin flux downstream of the Sn vapor source, which is then compared to the CFD model. Inertia and diffusion coefficients are adjusted in the model to match modelled fluxes to the experiment. A separate experiment is conducted utilizing mass loss measurements of a long crucible kept at a constant temperature and pressure over multiple hours, with tin evaporating out at a known rate. A variety of analytical and

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numerical coefficients were then compared to experimental fits of mass flux vs position to find the diffusion coefficient. Chapman-Enskog and Fick's law are the main analytical models utilized. A LAMMPS molecular dynamics model is also utilized to provide a wide array of results across the parameter space studied in this work, which is found to follow Chapman-Enskog theory well, even at lower pressures. The LAMMPS model uses mean squared displacement of Sn to calculate diffusion as the particles interact with H₂ through a LennardJones potential. The results detail diffusion coefficients of tin in molecular hydrogen for varying temperatures, pressures, and hydrogen flow speeds with minimized error for each measurement and converging results between experiments."

PS-ThP-29 Simultaneous Deposition and Removal of Tin in a Hydrogen Plasma Environment, Nathan Bartlett, Jameson Crouse, Andrew Herschberg, Emily Greene, Jaime Robertson, Jack Granat, Lucia Suarez Heredero, Matias Habib, Karl Vu, David Ruzic, University of Illinois at Urbana-Champaign

Tin laser produced plasmas (LPPs) are used to generate 13.5 nm light in state-of-the-art extreme ultraviolet (EUV) lithography tools. Inside these tools, hydrogen gas is used as a buffer gas to decelerate ions from the LPP and is photoionized in the process creating a steady background hydrogen plasma. This plasma etches away tin as it accumulates on the wall of the EUV source forming the volatile compound stannane. Accurate etching rates of tin are needed to model tin accumulation inside of an EUV source. In this work, we present the results of a new experiment at the University of Illinois at Urbana-Champaign where tin vapor is simultaneously deposited and etched off of a substrate. In the experiment, a high temperature effusive source is used to deposit tin vapor onto a substrate while a hydrogen microwave plasma is used to generate hydrogen radicals and remove tin from the surface. Etch rates are presented as well as the morphology of tin accumulated onto the substrate surface. The experiment is simulated using a transport and surface chemistry model ran in the OpenFOAM framework. Results from the experiment are compared with the model and used to validate the model.

PS-ThP-30 Plasma Cleaning Performance and GWP Reduction Using ClF₃ as an NF₃ Alternative in Semiconductor Manufacturing, Dong Ha Song, Sun Jae Jeong, Ga Hee Oh, Geun Young Yeom, Sungkyunkwan University (SKKU), Republic of Korea

The effective removal of process residues from the chamber following Si-based deposition is critical for ensuring process uniformity and maintaining tool performance in semiconductor manufacturing. Nitrogen trifluoride (NF₃) has been widely adopted for this purpose, but its high global warming potential (GWP) presents increasing environmental concerns. In response, chlorine trifluoride (ClF₃), a highly reactive gas with significantly lower GWP, has emerged as a promising alternative [1].

In this work, we evaluated the cleaning performance of ClF₃ compared to NF₃ in plasma-enhanced environments, focusing on both etch rate and spatial uniformity across the chamber. Silicon dioxide and silicon nitride-coated wafers were strategically placed within the chamber to quantify residue removal efficiency under both gases. To further improve gas utilization, we introduced nitrogen (N₂) as a diluent and analyzed the impact of its partial pressure on cleaning effectiveness.

The experimental results demonstrate that introducing N₂ allows for a reduction in overall gas consumption while maintaining comparable etch performance. Moreover, ClF₃ not only offers environmental benefits but also delivers efficient cleaning across various chamber regions, making it a viable low-GWP alternative for next-generation plasma cleaning processes [2].

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PS-ThP-31 EUV PR Patterned SiON Etching with Enhanced Selectivity and LER Control Using Ion Beam Technique, Yun Jong Jang, Hong Seong Gil, Kyoung Chan Kim, Woo Chang Park, Dae Yeon Ha, Geun Young Yeom, Sungkyunkwan University (SKKU), Republic of Korea

As extreme ultra-violet (EUV) lithography advances toward sub-10 nm patterning, the etch challenges associated with thin, low-resistance EUV photoresists (PR) become increasingly critical. This study presents a novel ion beam etching approach employing a grid pulsing technique to enhance

the etch selectivity and line edge roughness (LER) control for EUV PR-masked SiON structures. In the proposed method, Ar/H₂ plasma is generated in an inductively coupled plasma as a source chamber, while a fluorocarbon gas mixture (CF₄:C₄F₈) is injected into the downstream process chamber. Pulsing the grid voltages modulates the ion energy temporally, alternating between high-energy etching and low-energy fluorocarbon deposition phases.

We observed that decreasing the pulse duty ratio from 100% to 50% significantly increased SiON-to-EUV PR etch selectivity (approaching ∞) and reduced LER from 9.6 nm (continuous mode) to 6.1 nm, closely matching the unetched reference (5.8 nm). XPS and FTIR analyses showed increased fluorocarbon presence at lower duty ratios, correlating with reduced PR damage and improved LER while maintaining etch profile quality. Ion energy distribution measurements confirmed the alternating high/low-energy ion bombardment mechanism as key to balancing selectivity and LER.

These results highlight grid pulsing as a powerful, tunable method for precision etching in EUV-based semiconductor processing, offering new opportunities for sub-10 nm node integration with minimized pattern distortion.

PS-ThP-32 Reduction of Plasma-Induced Damage via Ultra-Low Electron Temperature Plasma in Gate-All-Around FET Fabrication, Kim Hyungdong, Chung ChinWook, Nahm HyunHo, Ha Seokhyun, Hanyang University, Korea

HfO₂ and TiN are representative materials used as gate oxides and metal gates in gate-all-around structures. However, damage caused by plasma during plasma processing has recently become a major concern due to its significant impact on device performance. In this paper, an ultra-low-electron-temperature (ULET) plasma ($T_e < 1$ eV) is applied to improve the etch characteristics of HfO₂ and TiN. The ULET plasma is generated using an inductively coupled plasma with a DC-biased grid. Results show that the ULET plasma reduces surface roughness by 33% for HfO₂ and 38% for TiN compared to conventional plasma. The residual concentration of fluorine decreases by 14% for HfO₂ and 58% for TiN, indicating an improvement in surface impurity levels. The improvements are attributed to the lower ion energy in ULET plasma, which suppresses ion bombardment damage. Our findings demonstrate that mitigating plasma ion damage to HfO₂ and TiN effectively prevents performance degradation and expands the process window in semiconductor manufacturing, and enables the implementation of more diverse device structures.

PS-ThP-33 Micro-Masking Effects in TCP-ICP RIE with Fluorine-Based Plasmas: Influence of Alumina and Quartz Dielectric Screens, Giuseppe Libero Bufo, Pascual Muñoz, Daniel Pastor, Universitat Politècnica de València UPV, Spain

Surface quality is a key factor in microelectronics and photonics fabrication, where even slight increases in roughness can degrade optical or electrical performance. During plasma etching, micro-masking can lead to surface roughening and the formation of particle-like features, which are generally undesirable for high-precision patterning.

In this study, we investigated unexpected surface roughening during the etching of silicon dioxide (SiO₂) and silicon nitride (SiN) films in a transformer-coupled inductively coupled plasma (TCP-ICP) reactive ion etching (RIE) system using CF₄ and CF₄/O₂ gases. Despite testing different combinations of chamber pressure, source power, substrate power, and gas flow ratios, the etched surfaces consistently exhibited nanometer-scale roughness and micro-masked features with an average area greater than 200 nm² per feature. Scanning electron microscopy (SEM) and energy-dispersive X-ray spectroscopy (EDX) revealed the presence of aluminum and fluorine on the etched surfaces, with an Al:F atomic ratio of approximately 1:3.6, indicating that the deposited material is likely aluminum fluoride (AlF₃). A plausible mechanism involves fluorination of the alumina protective screen located beneath the quartz window, followed by ion-assisted sputtering and redeposition onto the wafer surface, where the low volatility of AlF₃ under these conditions leads to persistent micro-masking. The dielectric screen serves to shield the quartz window from direct plasma exposure but can thus become a source of redeposition.

To assess the role of reactor hardware on surface quality, the 1 mm-thick alumina screen was replaced with a quartz screen of similar geometry. A direct comparison using the same CF₄/O₂ etch recipe on unpatterned 300 nm SiN-on-Si wafers showed a significant improvement: atomic force microscopy (AFM) measurements revealed a root-mean-square roughness R_q of 5.25 nm with the alumina screen, reduced to 0.49 nm with the quartz

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screen, representing a tenfold improvement. SEM inspections further confirmed the elimination of micro-masked surface features with the quartz dielectric screen.

This investigation identified the source of the micro-masking, enabling a screen material change that significantly improved the etch process. Beyond providing a practical mitigation strategy, this study underlines the importance of considering hardware-induced micro-masking in the development of roughness-sensitive microelectronic and photonic fabrication processes.

PS-ThP-34 Computational Study of a Radio-Frequency Positive Ion Source for Neutral Beam Injectors, Mohammad Sazzad Hossain, Amanda Lietz, Tom Regev, Arthur Mazzeo, Keanu Ammons, Florian Laggner, Miral Shah, Kirtan Davda, Steven Shannon, North Carolina State University; Evan Kallenberg, Brendan Crowley, Tim Scoville, General Atomics

The Large, Uniform Plasma for Ionizing Neutrals (LUPIN) is a radio-frequency (RF) inductively coupled plasma (ICP) chamber designed to demonstrate and optimize a positive ion source upgrade for the neutral beam injection system on the DIII-D tokamak. LUPIN is designed to operate at up to 20 kW of RF power at 2 MHz, coupling energy through a cylindrical quartz vessel (20 cm in length, 10 cm radius) to achieve target ion current densities of 1500 A/m². This work presents fluid-kinetic modelling of a LUPIN H₂ plasma with parametric sweeps in RF power, pressure and frequency to study their impact on plasma chemistry, density, and ion flux at the grid. The effects of each operational parameter on plasma density, ion flux, and uniformity were investigated and the density was validated against experimental measurements. Increasing power shifts the primary ionization channel from molecular to atomic with diminishing flux increases due to skin-depth contraction and rarefaction, higher frequency localizes heating and raises H₂⁺ and H₃⁺ delivery to the grid, while elevated pressure boosts ionization yet degrades ion transport due to increase in collisionality.

This work is supported by US DOE under DE-SC0024523 and DE-FC02-04ER54698.

PS-ThP-35 Amorphous Carbon Deposition: Insights from Plasma Dynamics, Feature Scale Modeling, and Density Functional Theory, Purva Paranjape, Purdue University, USA; Kallol Bera, Applied Materials Inc.; Rupali Sahu, Nakul Nuwal, Sathya Ganta, Prashant Kulshreshtha, Applied Materials, Inc.

With advances in nanoelectronics, 3D integration of semiconductor devices has become essential. Amorphous carbon gapfill is critical for enabling vertical stacking. Plasma Enhanced Chemical Vapor Deposition (PECVD) is widely used to deposit these sacrificial layers. Achieving conformal, void-free deposition is vital for structural integrity. Partial gapfill studies help identify process conditions that yield such profiles. Hydrocarbon-based PECVD at intermediate pressures shows non-monotonic deposition behavior: decreasing then increasing with pressure. At lower pressures, films exhibit overhangs and high bottom deposition. At higher pressures, deposition becomes conformal and void-free.

To understand these mechanisms, we use a multi-scale modeling approach combining 1D plasma simulations, 3D feature-scale modeling, and Density Functional Theory (DFT). The plasma model includes continuity equations, drift-diffusion for electrons, ion momentum conservation, energy balance, and Poisson's equation. A particle model with collisions is used to calculate ion energy and angular distribution using electric fields from the plasma model. Feature-scale simulations use Monte Carlo methods to model particle transport, surface reactions, and profile evolution. DFT provides adsorption energies of plasma-generated species on carbon surfaces, revealing the relative importance of surface processes.

Simulations show that flux of dissociation-generated radicals decreases, while polymerization-generated radicals increase with pressure. Ion flux remains stable, but ion energy drops and angular spread broadens. At lower pressures, deposition is ion-assisted via dissociated radicals. At higher pressures, chemisorption of polymerized radicals dominates. DFT shows stronger adsorption of dissociated radicals. Feature-scale modeling reproduces experimental profiles, validating our multi-scale model. Directional ion-assisted deposition causes overhangs at low pressure; chemisorption leads to conformal films at high pressure. A pinch-off occurs at intermediate pressures due to competing mechanisms. Our study highlights the role of plasma-surface interactions due to ion flux, energy, angular distribution, and neutral fluxes in controlling feature profiles. The validated model helps identify optimal conditions for desired feature profiles.

PS-ThP-36 Spatiotemporal Analysis of a Submerged Water Plasma Driven with Nanosecond Long Voltage Pulses, Michael Johnson, David Boris, Lina Petrova, Naval Research Laboratory, USA; Mackenzie Meyer¹, National Research Council; Scott Walton, Naval Research Laboratory, USA

Atmospheric pressure plasmas generate a distinct chemical and electrical environment ideal for treating water, making them attractive for applications in wound healing, chemical synthesis, nanomaterial fabrication, and water remediation. These plasmas can operate in a nonequilibrium regime when driven by short pulses of power, lasting tens to hundreds of nanoseconds, that energize electrons but are too short to significantly heat the surrounding gas. This study investigates the impact of pulse width on plasma-water interactions by applying 70–350 ns pulses to an argon plasma submerged in water. Plasma properties are analyzed using optical emission spectroscopy and electrical measurements. Results indicate that within the first 15 ns of the pulse, the plasma fully fills the gap between the electrodes. After this initial stage, the plasma expands to occupy the entire inter-electrode space for the remainder of the pulse, forming an arc-like plasma where current flow is regulated by the power supply. Essentially, pulse width determines how long the plasma remains in this high-current state. Optical emission spectroscopy revealed that argon dominates the emission immediately after plasma formation, but over time, hydrogen emission becomes more prominent as the plasma dissociates water molecules. This results in higher power consumption at longer pulse widths due to increased energy transfer to the water. Spatial emission profiles show uniform hydrogen emission across the reactor, whereas argon emission weakens near the positive electrode. Significant broadening of emission lines was observed during the pulse, with Stark broadening of hydrogen lines used to estimate electron density. Measurements indicate that a substantial electron density persists for several microseconds after the pulse, likely due to residual voltage on the electrodes during power supply neutralization. At the longest tested pulse width (350 ns), the post-pulse current lasted nearly 10 μs, highlighting not only the influence of pulse width on plasma dynamics but also the importance of other system parameters in determining plasma lifetime.

This work was partially supported by the U.S. Naval Research Laboratory Base Program.

PS-ThP-37 Reliable Monitoring of Plasma Chamber Cleaning via a Newly Developed Endpoint Evaluation Sensor, Suyoung Jang, Dohyeon Kim, Kyongnam Kim, Daejeon University, Republic of Korea

This study presents the development and application of a Cleaning Endpoint Evaluation Sensor (CEES) to enhance monitoring accuracy and uniformity control during NF₃-based remote plasma cleaning in semiconductor equipment. Increasing chamber pressure increases fluorine radical density and improves etch reactivity, but cleaning non-uniformities persist, particularly in structurally constrained “dead volume” regions, such as the undersides of substrates, where reactive species cannot effectively reach. Conventional diagnostics, such as Optical Emission Spectroscopy (OES), lack the capability to verify cleaning completion in these challenging areas. In contrast, the CEES directly measures the removal of thin films that mimic actual process residues, providing real-time, spatially resolved endpoint evaluation. Experimental results demonstrate a strong correlation between CEES measurements and actual etch behavior, enabling the identification of regions where cleaning remains incomplete even when OES indicates completion. These findings highlight the potential of CEES as an effective tool for monitoring cleaning uniformity and determining the true endpoint of plasma-cleaning processes. Integration of CEES into advanced diagnostic platforms could significantly improve process reliability and efficiency in semiconductor manufacturing.

PS-ThP-38 Effect of H₂O Addition on Fluorocarbon Layer Formation on SiO₂ and Si₃N₄ Films in C₄F₈ Plasmas, Haegeon Jung, Heeyeop Chae, Sungkyunkwan University (SKKU), Republic of Korea

The effect of H₂O addition to C₄F₈/Ar plasmas on fluorocarbon (CxFy) layer formation was investigated on SiO₂ and Si₃N₄ films and compared with O₂ addition. Tailoring of the fluorocarbon layer is a critical factor in achieving high selectivity and profile precision in high-aspect-ratio contact (HARC) etching. Etching was performed at 21 mTorr, 20°C, 30s, 130W source power, and no bias power. The fluorocarbon layer on SiO₂ was 26 nm in C₄F₈-only plasmas. O₂ addition reduced the thickness to 6 nm, and H₂O addition reduced it to 21 nm. The fluorocarbon layer on Si₃N₄ was 8.9 nm in C₄F₈-only plasmas. O₂ addition decreased the thickness to 3.9 nm, and H₂O addition increased it to 12.5 nm. Oxide surface promotes carbon scavenging to

¹ JVST Highlighted Poster

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CO/CO₂, and ion-assisted removal is strong, and the fluorocarbon layer on SiO₂ remains thin with bias [1,2]. Nitride surface lacks an efficient carbon-removal path to CO/CO₂, and NH_x/Si-F_x terminations increase CF_x retention, and ion bombardment cross-links and densifies the film, and the fluorocarbon layer on Si₃N₄ remains thick with bias [1,3]. SiO₂ surface provides polar sites that increase CF_x residence time and lower the nucleation barrier. CF_x nuclei survive more readily, and continuous-film formation is rapid. Interfacial Si-F_x formation depletes F and weakens F-driven thinning, and the layer on SiO₂ becomes thick in C₄F₈-only plasmas without bias [2,4,5]. Si₃N₄ surface shows slow initial nucleation, and F access is easy before continuity, and thickness increase is limited, and the layer on Si₃N₄ stays thin without bias [1,4]. H₂O addition increased the fluorocarbon layer thickness on Si₃N₄ and decreased it on SiO₂. The increase on Si₃N₄ is attributed primarily to hydrofluorination-driven NH_x/Si-F_x terminations that promote CF_x retention, and transient ammonium fluorosilicate(AFS) formation may also occur under HF/NH_x-rich conditions, although it was not directly detected in this study [7,8]. O₂ addition inhibits fluorocarbon growth by oxidizing carbon species and scavenging CF_x radicals [6]. These results demonstrate substrate-dependent control of fluorocarbon growth by gas-phase H₂O, and sidewall passivation can be tuned precisely, and selectivity and profile precision improve in advanced etching applications.

PS-ThP-39 Data-Driven Sputtering Yield Prediction for DC Magnetron Sputtering, Eunseo Lee, Hae June Lee, Pusan National University, Republic of Korea

Plasma-based sputtering systems are widely used for physical vapor deposition of thin films. Among them, DC magnetron sputtering offers enhanced ionization efficiency through the magnetic confinement of secondary electrons near the target, leading to high deposition rates. A key process parameter in this system is the sputtering yield, which represents the number of atoms ejected per incident ion. The sputtering yield is known to vary depending on the ion energy, angle, and target surface condition, particularly as the target undergoes erosion during prolonged operation. In this work, we present a machine learning based framework for predicting sputtering yield variation during target erosion in a DC magnetron sputtering environment. To generate data for model training, we performed a particle-in-cell with Monte Carlo collisions (PIC-MCC) simulation for argon discharge. From the simulations, we extracted time-resolved ion energy and angular distributions (IEDAs), as well as spatially varying plasma parameters, such as potential and density, near the target surface. The extracted plasma features were used as input data for a supervised neural network (NN) model. The sputtering yield corresponding to each condition was calculated using Yamamara's semi-empirical equation based on the incident energy and angle of argon ions. The trained NN model is intended to capture complex nonlinear relationships between plasma dynamics and surface response to enable fast estimation of yield variations without relying on time-consuming physical simulations. This approach is expected to serve as a practical tool for analyzing the impact of target erosion and optimizing process control in magnetron sputtering systems.

PS-ThP-40 Ultra-Low Temperature Dopant Activation Enabled by Plasma Enhanced Annealing, Zhihao Ma, University of Texas at Dallas; Mahsa Shekarnoush, Yuanning Chen, Malcolm Bevan, Harvey Stiegler, MicroSol Technologies Inc.; Lawrence Overzet, University of Texas at Dallas

The formation of highly doped, ultra-shallow junctions is critical for the continued scaling of advanced semiconductor devices. However, achieving high dopant activation while preserving lattice integrity remains a fundamental challenge.

Conventional annealing techniques such as furnace annealing and rapid thermal annealing (RTA) typically require processing temperatures above 800 °C to activate dopants and repair implantation damage. Although effective, these high-temperature treatments inevitably induce excessive dopant diffusion, junction broadening, and thermal degradation of fragile device materials, restricting their suitability for next-generation technologies.

Plasma Enhanced Annealing (PEA) has emerged as a compelling alternative, offering an ultra-low thermal budget through localized and controllable energy delivery from plasma ions. By tailoring ion energy, flux, dose, and species, PEA enables efficient dopant activation at substantially lower substrate temperatures (300–500 °C). This precise, near-surface energy transfer preserves shallow junction profiles, mitigates implantation-induced defects, and maintains device integrity while achieving high activation efficiency.

In this study, implanted silicon wafers were annealed using PEA, and their post-process properties were systematically evaluated using four-point probe measurements and Raman spectroscopy. Relative to conventional thermal annealing (TA) and RTA under identical conditions, PEA demonstrated noticeably superior electrical activation which is demonstrated by significantly reduced sheet resistance together with enhanced crystallinity. 500 °C PEA of shallow boron implants reached essentially the same sheet resistance as for RTA at 800 °C. Moreover, a comparative analysis of different inert ion species revealed distinct influences on dopant activation efficiency and lattice recovery.

These results establish PEA as a robust and versatile technique for forming highly activated, thermally stable, ultra-shallow junctions, positioning it as a strong candidate for integration into next-generation semiconductor device manufacturing.

PS-ThP-41 Tailored Waveforms for Ion Energy Control in ALE Applications, Sebastian Mohr, Hyungseon Song, Lucy Manukyan, Quantemol Ltd., UK

Atomic layer etching (ALE) is increasingly used in the manufacturing of semiconductor tools as they give more control over the resulting etching profiles than traditional etching techniques. While different approaches to ALE exist, many of them employ plasmas in one or more steps of the ALE process, be it to use the neutral radicals produced in the plasma to alter the surface or the ions to remove the altered top layer [1].

For such applications, independent control of ion flux and ion energy is highly desirable. Single frequency capacitively coupled discharges (CCPs) do not offer this, as the input power affects both flux and energy. Dual frequency discharges allow this to some extent, but it is limited due to, for example, increased ionization by secondary electrons at high powers of the low frequency. Furthermore, traditional CCPs usually produce bimodal ion energy distribution functions which can cover several 10s to 100s of eV with sharp peaks at either end, so the ion energy cannot be easily limited to a small interval of energies, which is desirable especially for ALE applications, so that the ions remove the top layer of the surface but do not damage the underlying bulk [1].

An alternative approach to achieve this desired control are tailored waveforms. These can range from so-called asymmetric waveforms combining a fundamental frequency with even multiples [2] to non-sinusoidal waveforms typically consisting of sharp voltage peaks [1] followed by a relatively long interval of an almost constant voltage. While it has been demonstrated that these type of CCPs offer independent control of ion flux and energy and/or are able to limit the ion energy to narrow energy intervals, they have not yet been well studied in industrial applications.

This presentation will show continued efforts to simulate industrial applications of tailored waveform CCPs using the well-established 2D plasma simulation code HPEM [3]. In these discharges, the plasma is sustained via ICP coupling, while the tailored waveforms are applied to an rf-electrode staging the wafer. Former simulations have shown the intended effect in case of blank metal electrodes, i.e. almost monoenergetic IEDFs at the electrode. In the continued simulations, we investigate the effects of wafers on the produced IEDFs, for example via charging effects.

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[2] U Czarnetzki et al *Plasma Sources Sci. Technol.* **20** 024010 (2011)

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Quantum Science and Technology Mini-Symposium

Room Ballroom BC - Session QS-ThP

Quantum Science and Technology Mini-Symposium Poster Session

QS-ThP-1 Frugal Quantum Magnetometry for Education, John Muth, Jonathan Rabe, North Carolina State University

The use of color centers for magnetometry is well established, with the nitrogen-vacancy (NV) center in diamond being the most prominent example. Recently, there has been growing interest in using silicon carbide as a more cost-effective alternative material. However, for educational purposes, the cost of associated optics and electronics can present a significant barrier with many approaches costing in excess of \$10,000.

This poster presents the design of a printed circuit board using off-the-shelf electrical components, integrated with an adjustable 3D-printed optical

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mount. The entire system can be built for under \$500 (excluding the cost of the diamond). The stand-alone device is compact and portable, and can be connected to a laptop for data acquisition and analysis.

Collected data demonstrate that the system achieves sensitivity in the low microtesla range and that hyperfine splitting can be observed. It can be used to generate color maps that visualize Zeeman splitting and to investigate how the orientation of NV centers affects the fitting of the zero-field splitting. As an alternative to optically detected magnetic resonance (ODMR) in diamond, the use of spin-dependent recombination to enable an all-electrical quantum magnetometer based on silicon carbide will also be briefly discussed.

QS-ThP-5 Accurate Atomic Correlation and Total Energies for Correlation Consistent Effective Core Potentials (ccECP) for Transition Metals, *Aqsa Shaikh*, North Carolina State University, India

In this work we utilize the correlation consistent effective core potentials (ccECPs) and present highly accurate correlation and total energy calculations for a selected set of transition metals and other heavy elements. We calculated the total energies using a variety of sophisticated correlated methods including configuration interaction (CI), coupled-cluster (CC) to multiple excitations and also with stochastic sampling approaches such as Quantum Monte Carlo (QMC). Calculations were performed with basis sets up to cc-pV5Z to limit discrepancies and then extrapolated to estimate the complete basis set limit. Kinetic energies were similarly assessed through CI to various excitation levels. We also present diffusion Monte Carlo (DMC) energies, providing insight into fixed-node/phase biases in single-reference trial wave functions. These results establish reliable benchmarks for ccECP performance across a broad spectrum of electronic structure methods, ensuring their utility in future high-accuracy calculations in correlated deterministic and stochastic frameworks.

QS-ThP-6 Optimization of DC Magnetron Sputtering Process for Coherent Nb-based Superconducting Quantum Electronics, *Kiana Reed, Joseph Falvo, Marcelo Velasco-Forest, Ivan Lainez, Kasra Sardashti*, Laboratory for Physical Sciences

Niobium (Nb) is a widely used superconducting material in thin-film form for quantum and superconducting electronic applications. In this work, we develop a robust Nb sputtering process optimized for evaluating candidate substrates for superconducting qubits. Thin Nb films were deposited on Si (001) substrates using direct current (DC) magnetron sputtering under varying powers and deposition times. Initial process optimization was guided by DC transport measurements, including critical temperature, critical field, and residual resistance ratio. Promising recipes were further assessed by fabricating Nb/Si coplanar waveguide resonators and measuring their internal quality factors at microwave frequencies. To mitigate dielectric losses at the metal–substrate interface, we implemented surface cleaning methods such as ex-situ HF etching (solution and vapor) and in-situ argon ion milling. Film morphology and interface quality were characterized using atomic force microscopy and scanning electron microscopy. Building on the optimized deposition parameters, we outline a pathway for screening alternative qubit-compatible substrates, including sapphire and silicon carbide.

QS-ThP-7 Tunable Superconducting Properties in Mesoscopic SNS Island Arrays, *Shiva Dahal*, Winston-Salem State University; *Bernadeta Srijanto*, Oak Ridge National Laboratory; *Kasra Sardashti*, University of Maryland College Park; *John Yi*, Winston-Salem State University

Superconductor array islands offer a uniquely tunable platform for probing fundamental quantum phenomena and advancing next-generation technologies. By precisely controlling Josephson coupling, charging energy, and disorder, these mesoscopic superconductor–normal-metal–superconductor (SNS) arrays enable direct exploration of key quantum phase transitions, including the superconducting–insulating transition and Berezinskii–Kosterlitz–Thouless (BKT) physics. Using advanced lithographic techniques, we pattern superconducting (Nb or Al) islands on thin metal films (Pt, Fe, Co, Ni, and Au) to investigate how geometry, size, spacing, and arrangement affect superconducting, resistive, and magnetic properties, including the critical temperature. Variations in island spacing and film thickness, combined with the use of metals with distinct electronic characteristics, are designed to uncover new strategies for controlling superconductivity and engineering high-performance heterostructures. Scanning electron microscopy (SEM) and atomic force microscopy (AFM) verify fabrication accuracy, surface morphology, and dimensional precision, with observed uniformity and sharp edge definition expected to minimize scattering centers and defects, thereby preserving coherence and enhancing proximity-induced superconductivity. Resistivity measurements

will probe the proximity effect, while magnetic characterization under applied fields will reveal flux dynamics and vortex behavior. The use of different metal films with varying electronic and transport characteristics is expected to yield novel material innovations. Overall, this research seeks to develop new strategies for controlling superconductivity, providing valuable insights into the design and fabrication of high-temperature superconductors and quantum devices. By combining precision nanofabrication, systematic materials variation, and rigorous transport and magnetic characterization, this work bridges fundamental condensed-matter physics with practical quantum device engineering, driving both scientific discovery and technological innovation.

QS-ThP-8 Probing the Functional Efficacy of Tunable SSWM Microring Resonators as Couplers for Tri-State Entanglement in Photonic Quantum Processors, *Arsh Jha*, North Carolina Central University

Quantum photonic processors offer major advantages over classical computing through massive parallelism. Conventional two-photon couplers, however, are limited in scalability and flexibility. We present a photonic quantum circuit architecture using a Spontaneous Six-Wave Mixing (SSWM) microring resonator, adapted from classical photonics, as an active logic element generating triphoton entanglement. These three-photon interactions reduce coupler requirements and enable more qubits (greater integration density), hence allowing for greater computational power.

Decoupling allows qubits to temporarily store quantum information without unwanted interactions. Using MEEP simulations, the decoupled state was achieved by sweeping the ring index *nring* (semiconductor-compatible refractive index tuning) from 2.05 to 2.20 with the bus waveguide fixed at 2.05, until no light propagated into the ring. Coupling coefficients decreased from 0.1094 to 0.0200 (showing detuning) while the Q-factor remained stable (335.9 to 433.38), confirming robust functionality. Coupling spectra retained their shapes with only amplitude reductions, indicating unchanged behavior.

Photon state integrity was evaluated using a custom QuTiP-based photon–photon interaction model, with three modes of four photons each evolving under a Hamiltonian derived from the kappa interaction matrix. For both states, photon purity remained near 1, fidelity averaged 0.9 ± 0.1 , and entropy stayed close to zero. Wigner function analysis showed minimal but consistent state differences, with their time-dependent rotation revealing precise windows for targeted control.

To measure circuit-level performance, a custom quantum photonic architecture was created: three data qubits underwent five different protocol classes i.e. teleportation, simple squeezing, etc. They operated under realistic noise channels with ancilla-assisted measurement. Kappa matrices (*k*) determined entanglement strengths and were swept over time from [0, *kmax*] to simulate detuning. This was compared to the control without kappa to determine if detuning affected circuit performance.

Metrics showed that the tunable SSWM microring resonator demonstrates strong potential in quantum photonic circuits with 4/5 protocols receiving better or consistent performance with (bi-state) detuning. Its protocol-dependent performance highlights opportunities for targeted applications, and future work will focus on simulation denoising and broader frequency sweeps to ensure robust, energy-efficient operation.

Advanced Surface Engineering Room Ballroom BC - Session SE-ThP

Advanced Surface Engineering Poster Session

SE-ThP-2 Geometry Matters in Magnetron Sputtering: From Source Placement to Film Quality, *Esteban Broitman, Rickmer Kose, Sven Kelling*, SENTYS Inc.

Magnetron sputtering remains a premier thin-film deposition technique, with its performance critically dependent on the spatial relationship between magnetron cathodes and the target–substrate assembly. In this review, we collate experimental findings from the literature into three principal geometric classifications: sputter-up versus sputter-down magnetron orientations, planar versus confocal magnetron arrangements, and on-axis versus off-axis substrate positioning.

For each geometric class, we assess how the arrangement influences plasma confinement, governs the angular dispersion of sputtered species, and ultimately controls key film attributes—including mass density, residual stress, microstructural development, and step-coverage uniformity. By establishing quantitative correlations between spatial parameters and

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these film properties, we formulate a design-oriented framework to aid researchers in choosing the optimal magnetron configuration for targeted material performance.

To demonstrate practical application, we highlight state-of-the-art deposition chambers and magnetron source designs that permit rapid, tool-free reconfiguration of source-substrate geometry. Such adaptable platforms enable real-time tuning of deposition conditions, granting precise control over thin-film growth *in situ*.

Surface Science

Room Ballroom BC - Session SS-ThP

Surface Science Poster Session

SS-ThP-1 Exploring the Oxidation State Void between Single-Atom Alloys and Single-Atom Catalysts: Insights from RhCu and PtCu Alloys, *Vinita Lal¹, E. Charles H. Sykes*, Tufts University

Our aim is to explore the phase space between single-atom alloys (SAAs) and single-atom catalysts (SACs), where both the support and the single-site species exist in a partially oxidized state. SAAs have been extensively studied for hydrogenation, dehydrogenation, and coupling reactions, with growing interest in their potential for selective oxidation chemistry. However, their behavior under oxidizing conditions remains less understood. Since oxidation plays a crucial role in numerous catalytic processes, uncovering how oxygen interacts with SAAs and influences their reactivity and selectivity is essential for expanding their applicability in oxidation reactions. By investigating these interactions, we aim to provide new insights into the catalytic potential of SAAs and bridge the knowledge gap between SAAs and SACs.

To achieve this, we use well-defined model systems to study oxygen-mediated reactivity in SAAs. We investigate the oxidation of RhCu(111) SAAs using iodomethane as a probe molecule to examine how pre-adsorbed oxygen affects C-H activation and C-C coupling on both Cu(111) and RhCu(111). Through temperature-programmed desorption (TPD) and density functional theory (DFT) modeling, we show that C-H activation is inhibited on oxidized RhCu(111) compared to Cu(111) and that product selectivity follows distinct trends on SAAs relative to Cu(111) as a function of oxygen coverage. Expanding this framework, we explore O₂ activation and methanol oxidation on the PtCu(111) SAA system. TPD, X-ray photoelectron spectroscopy (XPS), and DFT analyses reveal that Pt slightly inhibits Cu(111) oxidation, contrasting with the promoting effect of Rh single atoms. However, Pt does not significantly alter Cu's selectivity in methanol oxidation, highlighting the complex role of different single-atom species in oxidation chemistry.

By shifting the focus from traditionally studied reducing conditions to oxidized environments, this work deepens our understanding of SAA reactivity and provides a foundation for tuning single-site catalysts for selective oxidation reactions. Our findings contribute to a broader understanding of how SAAs operate under oxidizing conditions, offering insights that could help guide the design of catalysts with enhanced functionality for industrially relevant oxidation processes.

SS-ThP-2 Development and Application of an Optimized Photo-Assisted Metal-Assisted Chemical Etching for Overcoming Fabrication Challenges in GaN Schottky Diodes, *Krystal Woodruff*, Kyma Technologies

Gallium nitride (GaN) has come up as a highly promising semiconductor material due to its wide band-gap, high breakdown voltage, and excellent thermal properties, making it ideal for high-power, high-frequency devices. Metal-assisted chemical etching (MacEtch) offers an adaptable approach to patterning GaN by combining the anisotropic control typical of dry etching with the cost-effectiveness and lower sidewall damage associated with wet etching. In this study, Kyma GaN wafers were subjected to MacEtch with a variety of solution concentrations, temperatures, and etch durations. The resulting etched structures were characterized using techniques such as scanning electron microscopy, white light interferometry, and optical microscopy.

The findings revealed a clear relationship between MacEtch parameters and subsequent GaN etch rates and surface morphologies. When applied as a trenching technique to Schottky diode structures, moderately etched devices showed improved reverse breakdown voltage, as expected from the trench architecture over planar structures. Ultimately, the work

demonstrates how MacEtch can be used as an alternative to dry etching, as well as its ability to be used as a trenching technique to enhance the blocking voltage performance of GaN-based Schottky diodes. With refined processes and careful control of environmental factors, MacEtch holds significant promise for advancing GaN device fabrication, particularly in high-power applications.

SS-ThP-3 Product Promoted Acetylene Cyclotrimerization to Benzene and Propyne-Acetylene Coupling to Toluene on Ag(111), *Nipun Kahagalla Dewage*, Tufts University; *Santu Biswas*, Tulane University; *Dennis Meier*, *Volkan Cinar*, Tufts University; *Matthew M. Montemore*, Tulane University; *Charles Sykes*, Tufts University

Benzene (C₆H₆) and toluene (C₇H₈) are irreplaceable chemical feedstocks for various products ranging from pharmaceuticals to building materials. They are primarily produced through petroleum cracking and reforming, which require high energy input, severe operating conditions, and lack 100% selectivity. With the shift from oil to shale gas as a hydrocarbon feedstock, there is an interest in alternative methods to produce C₆H₆ and C₇H₈. One promising pathway is the cyclotrimerization of acetylene (C₂H₂), which uniquely achieves 100% selectivity to C₆H₆ on the Ag(111) surface. However, it requires more than a monolayer (ML) of acetylene to initiate the benzene formation, necessitating high reactor pressures that could limit its industrial feasibility.

In the first study, acetylene cyclotrimerization on Ag(111) was investigated using Temperature Programmed Desorption (TPD), 12 Kelvin Scanning Tunneling Microscopy (STM), and Density Functional Theory (DFT) to explore how 2D compression by the reaction product benzene affects reaction rate. Isotopically labeled benzene (C₆D₆) was used to investigate the coadsorption of benzene and acetylene. Our results demonstrate that coadsorbed benzene (1/3 ML C₆D₆) enhances acetylene conversion and lowers the threshold acetylene coverage from 1 ML to ~0.3 ML. Increasing C₆D₆ coverage up to 1 ML further enhances acetylene conversion, whereas an increase beyond 1 ML reduces both conversion and benzene yield due to decreased surface site accessibility for acetylene. DFT calculations show that the presence of two parallel and slightly overlapping benzene molecules with two acetylene molecules on a 4×4 Ag slab has the lowest energy for the rate-limiting step of forming the C₄ reaction intermediate compared to other possible coadsorbed configurations. The local organization was further investigated by STM confirming similar molecular density of acetylene and benzene as used for the DFT calculations.

In our second study, C₂H₂ and C₃H₄ were coadsorbed to examine the coupling between C₂H₂ and C₃H₄ by TPD and DFT. C₂H₂ and C₃H₄ undergo coupling at a full monolayer of coadsorbed molecules. However, C₇H₈ is just a byproduct (~5%), while C₆H₆ remained the main product (95%). C₃H₄ does not couple with itself to form either benzene or trimethylbenzene on Ag(111), which aligns with the high reaction barrier for C₃H₄ self-coupling suggested by DFT due to sterics.

These findings provide fundamental insights into product-driven promotion of acetylene cyclotrimerization and hetero-coupling of C₂H₂ and C₃H₄ on Ag(111), informing strategies for catalyst design and identifying a new reaction pathway for toluene production.

SS-ThP-4 Ni Nanocluster formation and Intercalation in Graphene/Ir(111) Heterostructures, *Shilpa Choyal*, University of Illinois at Chicago; *Michael Trenary*, *Nan Jiang*, University of Illinois - Chicago

The interfacial engineering of graphene-metal heterostructures through atomic intercalation presents a powerful approach for modulating electronic properties while preserving graphene's structural integrity. This investigation examines the temperature-dependent evolution of transition metal nanoclusters on epitaxial graphene/Ir(111) surfaces, with emphasis on intercalation mechanisms and their effects on the electronic structure of graphene.

Using high-resolution scanning tunneling microscopy (STM) and low-energy electron diffraction (LEED), we characterized the structural transformations occurring when Ni is deposited onto graphene/Ir(111) at various temperatures. The pristine graphene layer exhibits a characteristic moiré pattern with 2.5 nm periodicity, resulting from lattice mismatch between graphene and Ir(111). Upon metal deposition at ambient temperature, Ni nanoclusters demonstrate remarkable site selectivity, exclusively nucleating at fcc sites among three possible adsorption positions. At ambient temperature, these nanoclusters form triangular islands aligned with the substrate's close-packed directions, spanning multiple moiré units with lateral dimensions of 10-15 nm and vertical heights of 1.4 nm.

¹ SSD Morton S. Traum Award Finalist

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Thermal annealing at 900 K induces Ni intercalation between graphene and Ir(111), as evidenced by the disappearance of surface clusters and emergence of a reverse moiré pattern compared to graphene on Ir(111). After intercalation, atop sites appear as bright protrusions instead of depressions. For Ni intercalation, we observe two distinct moiré patterns which are round and clover-like in shape, arising due to intercalation under two different adsorption sites. Upon further annealing to 1500 K, the intercalated metals adopt pseudomorphic growth on Ir(111), maintaining epitaxial registry despite significant lattice mismatch. This indicates substantial electronic interaction with both graphene and substrate. These insights advance the fundamental understanding of interfacial phenomena in two-dimensional materials and provide pathways for developing graphene-based electronic devices with tailored properties.

SS-ThP-5 Understanding Azide Modifications on Metal Oxides: A Window Into a New Class of Small Molecule Inhibitors, *John Mason, Andrew Teplyakov, University of Delaware*

Recent developments in area selective atomic layer deposition (AS-ALD) target requirements for smaller sized features as well as better control over surface chemical modification that governs the selectivity. This has brought attention to the use of small molecule inhibitors (SMIs) as a tool to assist in altering surface reactivity and thus enabling the miniaturization of these features. Azides are a common molecular species that has gained interest for surface modifications due to their non-reactive biproducts, nitrogen doping capabilities, and reactivity when brought into contact with a surface. This study aims to explore the reaction pathways for two different azides, trimethylsilyl azide and benzyl azide, and their reactions on metal oxide surfaces to see what conditions are needed to react with these surfaces, and what the surface species is afterwards. Using in-situ infrared spectroscopy and X-ray photoelectron spectroscopy we aim to observe the bonding configuration of these azide molecules on metal oxides and to explore the stability of the resulting surfaces as a pathway towards utilization of azides as SMIs.

SS-ThP-6 Surface Properties of Zirconium diboride (0 0 0 1) and Homoepitaxial Growth of Zirconium diboride as determined by Scanning Tunneling Microscopy, *Michael Trenary, Ayoyele Ologun¹, University of Illinois - Chicago*

Zirconium diboride, ZrB_2 , a group-IV metal-terminated diboride, is an extremely hard material with a high melting point of 3246 °C and can be grown conformally via chemical vapor deposition (CVD) using zirconium borohydride $Zr(BH_4)_4$ as a precursor. Using ultrahigh vacuum scanning tunnelling microscopy (STM), we investigated the atomic-scale structure of $ZrB_2(0001)$ and the homoepitaxial growth of ZrB_2 on this surface. After exposures of $Zr(BH_4)_4$ to $ZrB_2(0001)$ at 1473 K and immediately cooling to room temperature, Zr -terminated bilayer islands of ZrB_2 were observed. Coalescence of the ZrB_2 islands was observed when the substrate was left for 60 minutes at the deposition temperature before imaging at room temperature. In contrast, exposure at 900 K resulted in high-density clusters. Stepwise annealing at 1400 K led to the transformation of these clusters into a continuous thin film via thermal-induced coalescence.

SS-ThP-7 Comparing Computational Methods for Predicting STM Images, *Kaitlyn Handy, Alex Kandel, University of Notre Dame*

Scanning tunneling microscopy (STM) allows for an image to be constructed of a molecular surface. STM utilizes a tunneling current that interacts with the electronic density of states to produce a topographic image of a surface. With the knowledge of how these STM images are created, then theoretical predictions for molecular surface STM images can be produced and compared to experimental data to verify predicted molecular geometries.

There are two different methods for predicting STM images that are being investigated through this work. The first method calculates molecular electron density from gas-phase calculations. The STM images are then generated by varying the tunnel decay, current, and molecular orbitals. The second method is VASP; calculating the full electronic structure of the molecule in the presence of a surface to create a predicted STM image. This study aims to determine the conditions that the gas-phase STM images, which are computationally cheaper, are able to produce results comparable to VASP. Thus far, the accuracy of these images has been found to depend on molecular planarity and the orientation of the molecule relative to the surface.

SS-ThP-8 Investigation of sub-Nanoscale Light-Matter Interactions in Carbon Nanomaterials Using Tip-Enhanced Raman Spectroscopy, *Yuto Fujita², Keio University, Japan; Norihiko Hayazawa, RIKEN, Japan; Maria Vanessa Balois-Oguchi, Institute of Science Tokyo, Japan; Satoshi Yasuda, Japan Atomic Energy Agency, Japan; Takuo Tanaka, RIKEN, Japan; Tomoko K. Shimizu, Keio University, Japan*

Tip-enhanced Raman spectroscopy (TERS) is a powerful technique for exploring novel optical phenomena, especially light-matter interactions at the nanometer scale [1]. It takes advantage of the near-field light generated at the apex of a sharp metallic tip. By utilizing the gap-mode between the tip apex and a metallic surface, spatial resolutions of approximately 1 nm [2] or even sub-nanometer resolution [3,4] can be achieved. In this study, we use a scanning tunneling microscope (STM)-based TERS system with sub-nanometer resolution in ambient conditions [4] to examine light-matter interactions in carbon nanomaterials under sub-nanometer scale light confinement in a working environment. While conventional far-field Raman spectroscopy of carbon nanotubes (CNTs) shows a weak D-band, typically attributed to defect-induced scattering, we found that TERS spectra revealed a significantly enhanced D-band, suggesting a different excitation mechanism. We propose that the high wavenumber of the near-field light preserves momentum conservation for electronic transitions associated with the D-band in TERS measurements, a role typically played by defects in conventional Raman scattering [5]. These findings highlight the unique effects of sub-nanoscale light confinement on electronic excitations in materials. Further discussions, including results for graphene, will be presented.

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SS-ThP-9 Localized Physical and Chemical Manipulation of Surfaces via Thermal Scanning Probe Lithography (t-SPL), *Nicholas Hendricks, Emine Çağın, Heidelberg Instruments Nano AG, Switzerland*

Modification of thin film surfaces is of the utmost importance for various applications ranging from biosensors and spintronics to flat optics and magnonics. To push the performance of such applications to the next level, the optical, electrical, chemical, or magnetic properties need to be locally controlled at the sub-50nm length scale. To convert thin film surfaces, the use of direct-write lithography techniques is often employed where the film is manipulated by electrons, photons, or ions. These energetic particles can induce physical and chemical changes, however, the direct use of thermal energy as the stimulus could provide a more universal stimulus as well as an alternative route for such modifications. With thermal scanning probe lithography (t-SPL), enabled by the NanoFrazor from Heidelberg Instruments, the use of heat to perform direct-write patterning conversions is possible [1-5].

t-SPL generates patterns by scanning an ultrasharp tip over a sample surface to induce local changes with a thermal stimulus. By using thermal energy as the stimulus, it is possible to perform various conversion processes such as functional surface group deprotection, precursor conversion, and crystallization. Along with an ultrasharp tip, with a radius less than 10nm, the t-SPL cantilever contains several other important functions such as an integrated thermal height sensor, a capacitive platform for electrostatic activation, and an integrated heating element. By having a cantilever with such properties, it's possible to generate 2D and grayscale chemical gradients where surface chemistry is critical.

In this presentation, the background and workings of t-SPL will be introduced along with the lithography and processing steps necessary to create chemical gradients through the deprotection of functional groups for enzyme and protein patterning. The patterning of a phase change material (PCM) of GeSbTe (GST) will also be discussed where sub-300nm phase changes have been optically observed.

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SS-ThP-10 Probing the Oxygen-Driven Metal-Support Interactions in Pt/TiO₂ with Near-Ambient Pressure Spectroscopy and Microscopy, **Gaurav Anand¹, Florian Kraushofer, Matthias Krininger, Marina de la Higuera-Domingo, Lorenz Falling, Barbara A.J. Lechner**, Technical University Munich, Germany

Platinum supported on titanium dioxide (Pt/TiO₂) is a prototypical model system for studying redox reactions and understanding metal-support interactions in surface science studies for heterogeneous catalysis. The Pt/TiO₂ interface serves as a dynamic active site, and can modulate catalytic activity, particularly under mild reaction conditions. However, as we approach more realistic environments - where elevated temperatures and pressures introduce complex, intertwined interactions between the metal particles, the oxide support, and gas-phase species - more sophisticated experimental probes are required. For example, in oxidizing environments the behavior of Pt on rutile TiO₂ remains debated. While encapsulation via classical strong metal support interaction (SMSI) - where Pt is buried by a reduced TiO_x ($x < 2$) overlayer¹ - has been well-documented in reducing conditions, recent observations suggest that oxidizing conditions can also lead to encapsulation via a "non-classical" mechanism.² In the latter scenario, a stoichiometric TiO₂ layer is observed to overgrow Pt, but the driving forces behind this phenomenon remain unclear, partly due to ill-defined defect densities within the oxide support.

We employ near-ambient pressure scanning tunneling microscopy (NAP-STM), X-ray photoelectron spectroscopy (NAP-XPS), and low-energy ion scattering (LEIS) to investigate the Pt/TiO₂(110) interface under oxygen pressures ranging from ultra-high vacuum (UHV) to 1 mbar. Our results reveal a strong correlation between the oxidation state of Pt, the stability of Pt nanoparticles, and the stoichiometry of the TiO₂ support.³ Under low oxygen pressures and on reduced TiO₂ substrates, Pt nanoparticles become encapsulated by stoichiometric TiO₂ overlayers, likely driven by substrate reoxidation and the presence of metallic Pt, while the classical SMSI-driven TiO_x ($x < 2$) overlayer remains unchanged. In contrast, at higher oxygen pressures, Pt nanoparticles exhibit increased resistance to encapsulation, potentially due to Pt oxidation.⁴ Furthermore, on near-stoichiometric TiO₂ substrates, encapsulation is suppressed even at near-ambient oxygen pressures, allowing Pt nanoparticles to undergo oxidation instead. These findings provide new insights into the complex nature of metal-support interactions in oxidizing environments and offer a more nuanced understanding of Pt/TiO₂ catalysts under realistic reaction conditions.

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SS-ThP-12 Methanol Dehydrogenation on Pt / Cu (111) Single Atom Alloy Surface, **Michael Trenary, Vishwa Don Lokugan Hewage**, University of Illinois - Chicago

Pt/Cu(111) single atom alloys (SAAs) have been reported to catalyze the non-oxidative dehydrogenation of alcohols, selectively forming the corresponding aldehydes and hydrogen. They do so by facilitating O-H bond cleavage to form an alkoxy intermediate and C-H bond cleavage of the alkoxy to form the aldehyde. In this study, methanol dry dehydrogenation reactions on Pt/Cu(111) SAA surfaces were investigated using reflection absorption infrared spectroscopy (RAIRS) and temperature programmed desorption (TPD) to determine reaction intermediates and pathways. Although no formaldehyde desorption was observed from Cu(111), 0.02 ML of formaldehyde desorbs from a Pt/Cu(111) surface at 375 K. A RAIRS peak at 1005 cm⁻¹ on the SAA surface, observed at 250 K, was assigned to the C=O stretching mode of methoxy, compared to the corresponding methoxy C=O stretching peak(1005 cm⁻¹) on an oxygen-pre-adsorbed Cu(111) surface. The methoxy yield (0.001 ML), estimated from the CO stretching peak area on the SAA surface, was lower than the number of Pt single atoms (0.04 ML), contrary to the expectation that a single Pt site could form multiple methoxy molecules via spillover onto Cu sites. To assess the effect of background CO, the formaldehyde yield was compared to an SAA surface where Pt sites were blocked by CO dosed at 250 K. The formaldehyde yield decreased by approximately 50%, confirming that background CO

suppresses the reaction yield on the Pt/Cu (111) SAA surface. These findings provide insights into the mechanistic role of Pt sites in methanol dehydrogenation and the impact of surface species on catalytic efficiency.

SS-ThP-13 Automated Workflows in Photoelectron Spectroscopy: Enhancing Reproducibility and Efficiency, **Jonathan Counsell, Liam Soomary**, Kratos Analytical Limited, UK; **Chris Moffitt**, Kratos Analytical Inc.

The widespread application of X-ray Photoelectron Spectroscopy (XPS) and Ultraviolet Photoelectron Spectroscopy (UPS) in materials characterization necessitates automation to improve workflow efficiency and analytical consistency. Reproducibility challenges, stemming from operator-dependent data processing and spectral interpretation, threaten the reliability and broader utility of these techniques. Automated data handling systems mitigate analyst bias, reduce errors, and enhance the comparability of results across different laboratories.

This work explores the implementation of automated workflows in XPS and UPS, focusing on large-area analysis, depth profiling, and data compilation. We examine key challenges such as X-ray-induced damage, transmission and analysis area calibration, surface uniformity, and quantification consistency. Case studies will highlight automated solutions for handling complex material systems, demonstrating the role of advanced data processing in standardizing spectral interpretation. Furthermore, we discuss recent developments in high-throughput XPS systems that incorporate automated spectral fitting, background subtraction, and large-scale data integration, improving data reliability and reducing manual intervention [1,2].

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SS-ThP-15 Kevion: An Ion Irradiation Facility for Transformative Research in Space Science at the University of Virginia, **Adam Woodson, Catherine Dukes, Aubrey Carley, Robert Johnson**, University of Virginia; **Jeroen Terwisscha van Scheltinga**, Leiden University, Netherlands; **John Ihlefeld, Petra Reinke, Robin Garrod, Ilseodore Cleeves**, University of Virginia

The KiloElectron Volt ION (KEVION) irradiation facility for space science — a new NASA Planetary Science Enabling Facility — is under development within the Laboratory for Astrophysics and Surface Physics at the University of Virginia (LASP-UVa). This user-focused facility, available at no cost to NASA Planetary Science Division (PSD) grantees, is comprised of four integrated components: (1) a 25–300 keV Pelletron ion accelerator to provide positive atomic or molecular ions over a wide range of species, charges, and energies; (2) a novel, new ultrahigh vacuum (UHV) chamber called "GRAINS" that incorporates X-ray photoelectron spectroscopy, mass spectrometry, hyperspectral imaging, and more for holistic studies of geologic samples and other materials; (3) an established, well-tested cryogenic UHV chamber, aptly named "ICE", for studies concerning the irradiation of condensed gas targets; and (4) a minimally equipped, user-configurable UHV chamber called "TEST" for instrument testing, calibration, and prototyping. The KEVION is expected to facilitate transformative research in space weathering, radiolysis, radiosynthesis, sputtering, radiation damage, surface charging, and instrument development/response testing.

A full-time facility instrument scientist is available to assist with experiment planning, instrument operation, instrument training, and data analysis. The KEVION facility will be fully operational by the end of 2025, though the GRAINS chamber will be ready for use without the Pelletron by the summer of 2025. The facility will be accessible both in person and remotely. Specific details of the Pelletron accelerator and analytical techniques associated with each end chamber are summarized on the KEVION website at <https://engineering.virginia.edu/kevion>, and on the NASA Science Mission Directorate website at <https://smd-cms.nasa.gov/wp-content/uploads/2023/06/KEVION.pdf>.

Investigators submitting proposals to any of the NASA PSD funding programs are encouraged to integrate the KEVION facility into their research plans. We also welcome non-PSD academic, governmental, and industrial clients to make use of the facility at a nominal, tiered hourly rate. For more information email Cathy Dukes at cdukes@virginia.edu or Adam Woodson at akw8r@virginia.edu.

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SS-ThP-16 The Importance and Reporting of NAP-XPS Instrument Parameters, Braxton Kulbacki¹, Joshua Pinder, Jacob Crossman, Matthew Linford, BYU

X-ray photoelectron spectroscopy (XPS) data acquisition is directly affected by a variety of instrumental and software parameters. Accordingly, gaining a full picture and proper understanding of the material being analyzed and reported on, requires adequate reporting of these parameters. With recent advancements in XPS technique, XPS has become more commonplace. Although XPS is being used at an increasing rate, the number of XPS experts has not increased at the same rate. Thus, inadequacies in reporting are becoming more prevalent. A variant of XPS, called Near-ambient pressure XPS (NAP-XPS) is important because it allows data to be taken at much higher pressures than is done conventionally. Many samples that cannot be analyzed by conventional XPS can be analyzed by NAP-XPS. This poster examines parameter reporting within NAP-XPS – containing publication results from 2021 to 2023, highlighting gaps in parameter documentation. The reported parameters include the electronic analyzer (spectrometer), photon flux, X-ray source (synchrotron or anode) and energy, spot size, pass energy, dwell time, incident angle, substrate temperature, aperture size and distance, background gas, and fitting parameters such as background and peak shape. The general findings show that, on average, less than 50% of instrument parameters are recorded. A survey of X-ray sources revealed that over 50% of NAP-XPS experiments are conducted at synchrotrons. There is considerable variation in the frequency of parameter reporting: for instance, the analysis chamber pressure is reported 94% of the time, while dwell time is only reported 6% of the time. The large majority (92%) of papers contain fit data, but fewer than 50% of the literature report fitting parameters. Less than 5% of NAP-XPS studies are operando, among other findings. By emphasizing the critical role of various NAP and XPS parameters, we aim to promote best practices and enhance data reliability across the field.

SS-ThP-17 Landing Energy Dependent Surface Conformation of Electrosprayed Foldamer Molecules, Dennis Meier², Tufts University, Germany; Shengming Zhang, Benedikt Schoof, Technical University Munich, Germany; Patrick Lawes, Karlsruhe Institute of Technology (KIT), Germany; Pengfei Zhao, Andreas Walz, Annette Huettig, Hartmut Schlichting, Joachim Reichert, Technical University Munich, Germany; Anthoula C. Papageorgiou, Technical University Munich, Greece; Ivan Huc, Ludwig-Maximilians-University of Munich, Germany; Johannes V. Barth, Technical University Munich, Germany

Biomimetic molecules hold great potential for molecular devices, where preserving their secondary structure is crucial for maintaining functional properties. When assembled in well-ordered two-dimensional configurations, such molecules can exhibit unique characteristics. For example, helical aromatic foldamers are promising for molecular recognition and molecular machinery. Many of these macromolecules, however, cannot be sublimed by, e.g., organic molecular beam epitaxy onto surfaces in ultra-high vacuum (UHV). Electrospray controlled ion beam deposition (ES-CIBD) combines non-destructive landing onto surfaces with a low level of contaminants in UHV, due to soft ionization *via* electrospray ionization, mass filtering and control of the landing energy.

We addressed the deposition of two oligoamides of 8-amino-2-quinoline-carboxylic acid with different lengths on metallic surfaces in a UHV environment using ES-CIBD. In particular, we investigated how their landing energy during deposition influences the helical conformation. On the surface, the conformation of the molecules was unambiguously identified through real-space single-molecule imaging *via* scanning tunneling microscopy. At a low landing energy, the helix of the molecular structure was preserved after adsorption. Thermal treatment of the surface induces unfolding of the molecules. Increasing the landing energy resulted in mostly unfolded and partially folded molecules. At high surface coverages, a well-ordered self-assembly of the unfolded molecules was formed. We thus unravel the influence of the landing energy upon adsorption of complex molecules and provide a pathway for depositing intact molecules with well-defined secondary conformations on surfaces in UHV.

SS-ThP-18 Understanding Pt-Based Catalysts for Dehydrogenation of Methylcyclohexane for Use in Liquid Organic Hydrogen Carriers, Mengxiong Qiao, Bhawana Rayamajhi, Andreas Heyden, Donna A. Chen, University of South Carolina

Hydrogen is a promising source of clean and renewable energy, but a major challenge lies in its storage and transportation. The use of liquid organic hydrogen carriers (LOHC) allows hydrogen to be stored in organic molecules that are liquids at room temperature and therefore suitable for transportation through the existing infrastructure for petroleum. For example, the methylcyclohexane (MCH)-toluene pair has been used for the catalytic cycle of hydrogenation to store hydrogen and dehydrogenation to release hydrogen. While inexpensive and efficient catalysts are already available for hydrogenation, there is still the need for the development of selective dehydrogenation catalysts that inhibit deactivation due to carbon fouling.

In this work, model surfaces consisting of Pt(111), supported Pt clusters, and single-crystal Pt-Sn alloy surfaces were prepared in ultrahigh vacuum (UHV, $P \leq 2 \times 10^{-10}$ Torr) and then transferred directly into a high-sensitivity flow reactor operated in recirculation mode for kinetic studies under realistic pressure conditions. The turnover frequency for MCH dehydrogenation on the Pt(111) surface was four times lower than for Pt clusters supported on highly oriented pyrolytic graphite (HOPG) at 300 °C, and this behavior is attributed to the higher activity of undercoordinated sites that exist on the clusters. Furthermore, the ordered Pt-Sn alloy surfaces prepared by depositing and annealing Sn films on Pt(111) had less carbon deposition compared to on Pt(111) itself, as determined by post-reaction X-ray photoelectron spectroscopy.

The reaction mechanism of MCHdehydrogenation to toluene was also investigated using a combination of DFT and microkinetic modeling techniques on Pt(111), Pt(100), and Pt(211). A microkinetic analysis with a continuous stirred tank reactor (CSTR) model identified the intrinsic catalytic activity, dominant reaction mechanism, and rate-controlling steps for the conversion of MCH to toluene. These results suggest that for Pt catalysts, the more open (100) and (211) facets are more active. However, the calculations also suggest that thermodynamically all Pt surfaces favor coke formation although the kinetic barriers for Pt(111) are at least 1 eV higher than for the more open surface facets. Thus, the most coke-resistant Pt surface should be the one in which the step sites are blocked, perhaps by an inactive metal like Sn.

SS-ThP-19 Structural Study of Rhodium-Based Metal Surfaces, Elizabeth Serna-Sanchez, Alexis Gonzalez, Maxwell Gillum, Stephanie Danahey, Dan Killelea, Loyola University Chicago

Heterogeneously catalyzed oxidation reactions, such as the catalytic process of converting CO to CO₂, are extensively utilized for the production of modern commodities. However, there is little information known about the atomic level details of these catalytic processes. In order to further our understanding of the process at an atomic level, the investigation herein will focus on characterizing structures of oxygen on Rh model catalysts. Scanning tunneling microscopy (STM) images illustrate how the behavior of oxygen is affected by features such as surface defects and step width. Alongside the STM, other techniques such as temperature programmed desorption (TPD), and low energy electron diffraction (LEED) are used to identify the various species of oxygen and the structures they form on the surface.

SS-ThP-20 Self-assembly and On-surface Reactivity of β -diketonato Molecules on Au(111), Chamath Siribaddana, Nan Jiang, University of Illinois Chicago

Self-assembly and on-surface reactions of organic molecular building blocks are two versatile processes that can be utilized to synthesize well-defined nanostructures with functional properties. It is essential to study the intricate details of these processes at the nanoscale to achieve their controllability. This would enhance the ability to create defect-free nanoarchitecture with long-range order and the desired symmetry. The final nanoarchitecture depends on the properties of the molecule/molecules used as the building block, i.e., symmetry, functional groups, and intermolecular interactions; properties of the substrate, i.e., crystallinity, symmetry, catalytic activity, and molecule-substrate interactions, and reaction conditions, i.e., substrate temperature and byproducts. Ultra-high vacuum (UHV) conditions and single-crystalline surfaces offer a pristine and controlled environment to synthesize nanostructures and investigate how these factors influence their formation. Scanning tunneling microscopy (STM), with its sub-molecular resolution, enables detailed probing of these factors at the local scale. In this study, the

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self-assembly and on-surface reactivity of a β -diketonato molecule on Au(111) were explored using UHV-STM across a range of substrate temperatures. At room temperature, the molecules self-assemble primarily through intermolecular halogen bonding, with minimal influence from molecule-substrate interactions. At higher substrate temperatures, an Ullmann coupling reaction via a surface-assisted activation of C-I leads to the growth of a robust self-assembly stabilized by intermolecular C-C bonds. The symmetry of the underlying substrate has a templating effect on the symmetry of this resultant robust covalent organic network type self-assembly despite not affecting its precursor assembly, which is conformationally flexible. The progression of the reaction with respect to the substrate temperature reveals thermodynamically favorable conditions for network units with varying sizes and symmetry. These insights into self-assembly and on-surface reactivity enhance the design of synthetic pathways that lead to nanomaterials with desired functionalities.

SS-ThP-21 Transformation of TiN to TiNO films via In-situ Temperature-dependent Oxygen Diffusion Process and their Electrochemical Behavior, *Sheilah Cherono, Dhananjay Kumar*, North Carolina A&T State University

Titanium oxynitride (TiNO) thin films represent a multifaceted material system applicable in diverse fields, including energy storage, solar cells, sensors, protective coatings, and electrocatalysis. This study reports the synthesis of TiNO thin films with controlled amount of oxygen using pulsed laser deposition. A comprehensive structural investigation was conducted by X-ray diffraction (XRD), X-ray photoelectron spectroscopy (XPS), Non-Rutherford backscattering spectrometry (N-RBS) and X-ray absorption spectroscopy (XAS), which facilitated a detailed analysis that determined the phase, composition, and crystallinity of the films. Structural control was achieved via temperature-dependent oxygen in-diffusion, nitrogen out-diffusion, and the nucleation growth process related to adatom mobility. The XPS analysis indicates that the TiNO films consist of heterogeneous mixtures of TiN, TiNO, and TiO₂ phases. The correlation between the structure and electrochemical behavior of the thin films was examined. The TiNO films with relatively higher N/O ratio, meaning less oxidized, were more electrochemically active than the films with lower N/O ratio (more oxidized films). Films with higher oxidation levels demonstrated enhanced crystallinity and greater stability under electrochemical polarization. These findings demonstrate the importance of substrate temperature control in tailoring the properties of TiNO film, which is a fundamental part of designing and optimizing an efficient electrode material.

This work was supported as part of the Center for Electrochemical Dynamics and Reactions on Surfaces (CEDARS), an Energy Frontier Research Center funded by the U.S. Department of Energy, Office of Science, Basic Energy Sciences at the North Carolina A&T State University under award DE-SC0023415. The work also used resources at the ALS of LBNL, supported by the Director, Office of Science, Office of Basic Energy Sciences, of the US Department of Energy under Contract No. DE-AC02-05CH11231. Part of the work was performed using the resources of NSF-PREM Collaborative Research and Education in Advanced Materials Center (grant number DMR-2425119) and the Joint School of Nanoscience and Nanotechnology, a member of the National Nanotechnology Coordinated Infrastructure (NNCI), which is supported by the National Science Foundation (Grant ECCS-2025462). Also, the work was partially supported by project ELIRO/RDI/2024-015 and National Nucleus Program LAPLAS VII – contract no. 30N/2023.

SS-ThP-22 XPS Study of Initial Oxygen Adsorption on ZrB₂ (0001) at Room Temperature, *Cosmic Gober*, University of Illinois - Chicago

Zirconium diboride (ZrB₂) is an ultra-hard material with a melting point of 3246 °C, making it suitable for extreme environment applications such as hypersonic vehicles and cutting tools. Understanding its interactions with molecular oxygen (O₂) is crucial for predicting its performance. This study investigates the nascent stages of oxygen uptake on the ZrB₂(0001) surface at room temperature. A clean, well-ordered ZrB₂(0001) surface, confirmed by a characteristic (1x1) low energy electron diffraction (LEED) pattern, was exposed to O₂ dosages ranging from 0.01 to 1.0 L. X-ray photoelectron spectroscopy (XPS) was employed to track the evolution of surface composition. Analysis of the O 1s spectra following even minimal exposures reveals multiple distinct oxygen species. Two primary components were identified: one at a binding energy of 533.8 eV corresponding to oxygen adsorbed on the surface, and another at 531.4 eV attributed to oxygen incorporated into the subsurface region. These findings indicate that even at very low O₂ exposures at room temperature, oxygen not only dissociatively adsorbed onto the ZrB₂(0001) surface but also begins to penetrate the subsurface layers. This work demonstrates the capability of

XPS to distinguish initial surface and subsurface oxygen species on ZrB₂(0001). The observation of subsurface oxygen at room-temperature exposures provides critical experimental data for understanding the onset of its oxidation pathway.

SS-ThP-23 Enhanced Electrocatalytic and Supercapacitance Performances of Transition Metal Oxynitride Thin Films, *Brianna Barbee*, North Carolina A&T State University

The importance of research in the field of non-conventional energy generation and storage cannot be overemphasized in order to be less dependent on limited resources in nature. Our research has established the effectiveness of the pulsed laser deposition (PLD) method for the synthesis of an emerging class of transition metal oxynitride (TMON) material systems in epitaxial thin film form. The material systems cover a wide range of compositions that exhibit the physicochemical properties needed in electrocatalysis and extended-life electrochemical energy storage. The attraction of TMONs over more widely studied transition metal oxides (TMOs) is rooted in the polarizability, electronegativity, and anion charge of nitrogen versus that of oxygen, which induces an enormous change in the physical and chemical properties of the resulting compounds. TMON films were deposited in the absence and presence of liquid nitrogen stage in the PLD chamber, which is capable of adsorbing the residual oxygen in the PLD chamber. The films were characterized using high resolution x-ray diffraction, x-ray reflectometry techniques, and x-ray photoelectron spectroscopy. The electrochemical supercapacitor measurements on the TiNO films using cyclic voltammetry have shown that the specific capacitance values are amongst the highest values reported for the recently top-tier nanoscale electrode materials.

SS-ThP-24 The Initial Oxidation Reactions of Compositionally Complex Alloys, (Cr-Mn-Fe-Co-Ni), *Farzad Bastani*, University of Virginia, USA; *Keiheen Orson, John R. Scully*, University of Virginia; *Petra Reinke*, University of Virginia, USA

The Cr-Mn-Fe-Co-Ni alloy with near-equimolar composition, known as the Cantor alloy, is a single-phase face-centered cubic solid solution and a compositionally complex alloy (CCA). These materials are stable as high configurational entropy solid solutions. CCAs can phase-separate into multiphase systems and thus form compositionally and structurally complex surfaces. This complexity presents challenges for understanding surface reactions, particularly in catalysis and oxidation. This work examines the oxidation of polycrystalline Cantor, focusing on the composition and evolution of surface oxides as a function of time and temperature. Samples are sputter-annealed, and SRIM simulations model defect generation to consider near-surface defects in oxidation. Oxidation is studied under three conditions: (i) native oxide formed in ambient conditions, (ii) oxygen exposure in vacuum at variable temperatures, and (iii) cryogenic oxidation to “freeze” kinetics, suppress bulk diffusion, and isolate surface-limited reactions and O₂ dissociation. In-situ angle-resolved X-ray photoelectron spectroscopy (AR-XPS) is used to track chemical composition and layering in the alloy and oxide. Ni oxide formation is consistently suppressed, and Cr and Mn preferentially form stable oxides under all conditions. Co oxide appears only in the native oxide, which also contains Cr hydroxide and Cr, Mn, and Fe oxides in proportions similar to those formed under vacuum oxidation, highlighting its role as a persistent surface state. Vacuum-grown oxides display temperature-dependent selectivity: at 77K, oxidation is limited and surface-bound; at 298K, Fe oxide is still observed; and at 600K, only Cr and Mn oxides persist, suggesting enhanced thermodynamic control and surface Fe depletion. Oxide structure varies by route: native oxides are chemically mixed and layered, while elevated temperature vacuum oxides form binary (Cr-Mn) phases.

These results show that surface oxide chemistry is governed more by kinetic and thermodynamic factors than by bulk composition. We also examine how surface enrichment and segregation (induced by identical treatments at different fixed temperatures) affect oxide structure and stability. Activation barriers are tracked by correlating temperature-dependent XPS data with selective oxide formation to map energy thresholds for surface composition changes. Future work will extend the materials space to multiphase alloys and explore the effects of crystallographic orientation, mechanical properties, and microstructural stability of Cantor alloys at cryogenic temperatures, including potential embrittlement, phase separation, and aqueous corrosion.

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SS-ThP-25 Atomic-Scale Investigation of Electron-Induced Processes at Single-Atom Alloy Active Sites, *Nima Rajabi¹, Charles Sykes, Tufts University; Phillips Hutchison, Emily Carter, Princeton University*

Single-atom alloys (SAAs) have captured significant interest as promising thermo- and electro-catalytic materials and most recently in the plasmonic photocatalytic field due to their unique electronic and chemical properties. Unlike thermal catalysis, plasmon photocatalysis enables energy-efficient, selective molecular activation via localized surface plasmon resonance (LSPR), which reduces energy consumption and provides more control over the reaction. However, the details of the mechanism by which adsorbates react or desorb are still unclear. Using scanning tunneling microscopy (STM) and spectroscopy (STS), we investigate the topography and electronic structure of four different SAAs—NiAg(100), PtAg(100), PdAg(100), and RhAg(100)—and their role in electron-stimulated CO desorption. STS and density functional theory (DFT) allow us to correlate local density of states with electron energy and probe the mechanism of desorption. Specifically, we can identify states associated with transient negative ion (TNI) formation, which plays a crucial role in facilitating plasmon-induced charge transfer. In plasmon-driven photocatalysis, this TNI state can arise from chemical interface damping (CID) or Desorption Induced via Electronic Transition (DIET), key decay pathways of LSPR. Our results indicate that SAAs exhibit drastically different CO desorption rate dependence on electron energy.

Moving forward, we explored the possibility that the TNI state contributes to bond weakening, leading to more efficient CO removal—a major challenge in catalytic processes. To further support our experimental findings, we employed DFT calculations and embedded correlated wavefunction (ECW) methods. These studies provide additional insights into the electronic structure modifications induced by CO adsorption and desorption. DFT results align with experiments, showing similar desorption trends for RhAg, PtAg, and PdAg, while NiAg deviates, suggesting a different mechanism possibly linked to TNI state formation via electron injection. Our findings provide deeper insights into the electronic and catalytic properties of SAAs and offer guidance for designing more efficient and sustainable photocatalysts that minimize the use of precious metals.

SS-ThP-28 Mechanism of the Water-Gas Shift Reaction on Magnetite Catalysts Studied by Near-Ambient Pressure X-ray Photoelectron Spectroscopy, *Akash Aoki, Haruka Matsuda, Seikai Kurosawa, Yuki Tsujikawa, Hiroshi Kondoh, Tomoko K. Shimizu, Keio University, Japan*

The water-gas shift (WGS) reaction is a chemical process that produces hydrogen and carbon dioxide from water and carbon monoxide. It is widely used in industrial hydrogen and ammonia production, particularly in combination with steam methane reforming and the Haber-Bosch process. The WGS reaction proceeds in two stages: the high-temperature shift (HT-WGS), which primarily aims at hydrogen production, and the low-temperature shift (LT-WGS), which focuses on carbon monoxide conversion^[1].

In this study, we address the unresolved mechanism of the HT-WGS reaction using near-ambient pressure X-ray photoelectron spectroscopy (NAP-XPS). The commonly used $\text{Fe}_2\text{O}_3\text{-Cr}_2\text{O}_3$ catalyst is known to be reduced to Fe_3O_4 under reaction conditions. Therefore, we investigate the chemical states of both the catalyst surface, specifically $\text{Fe}_3\text{O}_4(111)$, and adsorbed gas species under reaction conditions.

A clean $\text{Fe}_3\text{O}_4(111)$ surface was prepared by the procedure reported previously^[2]. H_2O and CO were co-exposed to the surface at a total pressure of 0.1 Torr with a 1:1 ratio, and XPS spectra were recorded during stepwise heating. Evolution of O1s and C1s spectra indicates increases of OH and H_2O , and formation of COOH. Fe2p and 3p regions confirms the oxidation and reduction states of $\text{Fe}_3\text{O}_4(111)$ during the chemical reaction.

These results not only provide clues for identifying the gas adsorption process in the HT-WGS, but also offer insights into the state of the Fe_3O_4 catalyst under reaction conditions. Moving forward, we aim to elucidate the reaction pathway of the HT-WGS through reproducibility tests under similar conditions and comparisons with results obtained under varying conditions.

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SS-ThP-29 Selective Hydrogenation of Styrene to Ethylbenzene Over a Pd/Cu(111) Single-Atom-Alloy Surface, *Mohammad Rahat Hossain, Michael Trenary, University of Illinois - Chicago*

The selective hydrogenation of styrene to ethylbenzene is of industrial significance due to its role in purifying xylene-rich streams used for para-xylene production, a key precursor to polyester fibers and PET plastics. Trace styrene can disrupt downstream separation and catalytic processes, especially in adsorptive purification systems. However, achieving high selectivity is challenging, as conventional catalysts often induce aromatic ring hydrogenation or xylene isomerization. Catalysts that can selectively hydrogenate the vinyl group while preserving the aromatic core are therefore essential. Single-atom alloy (SAA) catalysts have emerged as promising candidates for such transformations. In these systems, small amounts of an active metal are atomically dispersed in a less reactive host. The isolated active atoms serve as active hydrogen dissociation sites, while the surrounding relatively inert atoms suppress undesired over-hydrogenation. This ensemble effect enhances chemo-selectivity and reduces precious metal usage, making SAAs attractive platforms for probing structure-reactivity relationships in hydrogenation catalysis. In this study, we investigated the hydrogenation of styrene to ethylbenzene over a Pd/Cu(111) SAA under ambient pressure using reflection absorption infrared spectroscopy (RAIRS). The appearance of gas-phase ethylbenzene peaks below 3000 cm^{-1} (due to sp^3 C-H stretches) and the loss of the styrene vinyl bending mode at 909 cm^{-1} confirm successful hydrogenation. Auger electron spectroscopy (AES) of the post-reaction surface revealed carbon deposition, suggesting some dissociation. No spectral features associated with cyclohexyl ethylbenzene were detected, indicating high selectivity. The reaction showed 100% conversion with excellent selectivity toward ethylbenzene. A turnover frequency (TOF) of 36 s^{-1} at 380 K was observed, significantly higher than that for pure Cu, confirming the role of Pd sites. The activation energy was determined to be 31 ± 5 kJ/mol. The reaction order was found to be zeroth order in styrene and first order in hydrogen. Further investigations on in-situ identification of surface-bound intermediates via RAIRS are currently in progress.

SS-ThP-31 Energetics of Methanol Adsorption on H- and CO-Precovered Pt (111) Surface, *Arjan Saha, Washington State University; Valeria Chesnyak, Oregon State University; Marcus Sharp, Pacific Northwest National Laboratory; Nida Janulaitis, University of Washington; Zbynek Novotny, Pacific Northwest National Laboratory; Charles T. Campbell, University of Washington; Líney Árnadóttir, Oregon State University; Zdenek Dohnálek, Pacific Northwest National Laboratory*

Understanding the adsorption energy of reactants on metal surfaces is fundamental to catalysis and electrocatalysis, including processes such as methanol synthesis, Fischer-Tropsch synthesis, and hydrogen fuel cells. These adsorption energies provide critical links between the catalyst structure and activity and serve as essential benchmarks for validating computational methods, such as density functional theory. Single crystal adsorption calorimetry (SCAC) is the only technique capable of directly measuring the heat of adsorption of molecules on single crystal surfaces [1]. While interactions between reactants and metal surfaces have been extensively studied, the influence of coadsorbed species such as hydrogen and carbon monoxide remains poorly understood. Here, we use SCAC to investigate how strongly bound adsorbates, such as H and CO, affect methanol adsorption and binding on Pt (111). We quantify the differential heat of adsorption of methanol on Pt (111) pre-covered with well-defined (1×1) H and ($\sqrt{3} \times \sqrt{3}$) R30° CO adlayers [2]. The initial heat of adsorption decreases from 65 kJ/mol on bare Pt (111) to ~55 kJ/mol on H/Pt (111) and to ~45 kJ/mol on CO/Pt (111). The coverage-dependent heats further reveal details about the changes in methanol-surface and methanol-methanol interactions. These results demonstrate the significant impact of coadsorbed species on methanol binding and provide important insights into surface interactions relevant to electrodes and catalytic metal nanoparticles.

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SS-ThP-32 Correlating Stress Development and Nanopattern Formation of Si Under Low-Energy Ion Bombardment, *Marlene Ludwig, Ellie Stonecipher, Benli Jiang, Karl Ludwig*, Boston University

Self-organized pattern formation on materials as a result of broad-beam Ion Beam Sputtering (IBS) has long been observed but important disagreements about fundamental causes remain. Previous research has confirmed the presence of surface nanopatterns on Si under room-temperature IBS and shown that the surface of the crystalline sample is amorphized. It's also known that codeposited impurities on samples during bombardment potentially affect sample surface stress. To minimize impurities, our experiments focused on bombardment using an experimental arrangement of demonstrated purity which was checked by X-ray Photoelectron Spectroscopy (XPS). This allows results to be attributed to IBS itself, rather than as a result of codepositing impurities. Silicon thin wafers were bombarded with 500 eV Ar⁺ ions at a 65° incidence angle, which is known to be the regime in which self-organized patterns form. Both real-time and *post-facto* methods were used to analyze samples. During bombardment, the Multi-Beam Optical Stress Sensor (MOSS) method was used to study wafer curvature and determine stress development in real-time. After bombardment, *post-facto* Atomic Force Microscopy (AFM) and Grazing-Incidence Small-Angle X-ray Scattering (GISAXS) were used to analyze surface morphology and determine possible patterning. While stress development was observed, optimization of experimental conditions is still ongoing and aims to elucidate the relationship between stress development and nanopattern formation.

This work was partly supported by NSF DMR-2117509, NSF REU-2244795, and MRI-2216008.

SS-ThP-33 XPS Analysis of PTFE Decomposition Induced by 10–500 eV Electron Beam Irradiation, *Hao Yu, Jackson King, Sylwia Ptasińska*, University of Notre Dame

Per- and polyfluoroalkyl substances (PFAS) have become a significant environmental concern due to their exceptional resistance to degradation in aquatic environments, leading to increasingly stringent global regulations on their production, use, and recycling. Among PFAS treatment strategies, electron beam irradiation has attracted attention for its ability to degrade highly stable fluorinated compounds. Low-energy electron (LEE, below 30 eV) irradiation, as a precise and controllable method for inducing specific chemical modifications on surfaces, may also provide a pathway for initiating bond scission and surface functionalization through its interaction with PFAS.

Polytetrafluoroethylene (PTFE; C₂F_{2n+2}) was selected as the research target due to its simple PFAS structure and exceptional chemical stability among PFAS compounds. PTFE films with a thickness of 12 μm were deposited onto carbon tape, which was then mounted on a stainless steel holder. An electron gun installed in the X-ray photoelectron spectroscopy (XPS) system, normally used to neutralize surface charge accumulation, was employed as the LEE irradiation source. The electron energy range was 10–500 eV, with a beam current of 100 μA, for durations of up to 24 hours under vacuum. In-situ XPS measurements were performed before and after LEE irradiation, under a base pressure of approximately 2 × 10⁻¹⁰ mbar. Survey spectra from the range of 1200 to 0 eV, and core-level spectra of C 1s, O 1s, and F 1s were recorded.

Electron energies in the 10–500 eV range were found to induce chemical changes in the PTFE surface. Survey spectra showed a general decrease in signal intensity with irradiation, accompanied by modification in both C 1s and F 1s regions. At higher energies, fluorocarbon environments were rapidly altered, while lower-energy electrons produced more gradual but still detectable changes. The lowest-energy regime (10 eV) showed significant consistency with the dissociative electron attachment (DEA) process. These findings highlight the energy-dependent pathway for electron-driven PTFE degradation and provide insights relevant to controlled polymer surface modification.

SS-ThP-34 Quartz Crystal Microbalance Measurement of Premelting at the Ice-Substrate Interface, *Blake R Hance, Steven Sibener*, University of Chicago

Premelting of ice, the formation of a quasi-liquid water layer at the surface of ice below the bulk melting point, is poorly understood but instrumental in understanding interactions at the ice surface. We present a study of premelting using a novel quartz crystal microbalance (QCM) method to acoustically probe the quasi-liquid layer (QLL) at the buried ice-substrate interface at a variety surfaces. The quasi-liquid layer is found to vary from slightly thicker than the thickness of one ice bilayer (0.37 nm) at -15 °C to 2.25 nm at -0.5 °C. We find that hydrophobicity has a strong impact on the

temperature dependence of premelting, with the QLL being thicker on more hydrophobic surfaces at lower temperature. These findings improve our understanding of the impact of substrate features on ice premelting at buried interfaces and demonstrate the utility of QCM for investigating these systems.

SS-ThP-35 Visualizing Inhomogeneous Molecular Adsorption Structures on a Solid Surface by Three-Dimensional Atomic Force Microscopy, *Keisuke Miyazawa, Takeshi Fukuma*, Kanazawa University, Japan

In three-dimensional atomic force microscopy (3D-AFM), AFM tip is three-dimensionally scanned at a solid-liquid interface, and interaction force applied to the tip is recorded to generate a 3D force image with subnanometer-scale (< 1 nm) resolution. Recent studies suggested that 3D-AFM images show molecular adsorption structures at various solid-liquid interfaces in real space. This unique capability of 3D-AFM is strongly demanded in many industrial fields, where molecular adsorption layer is widely used for controlling surface properties. For example, magnetic hard disks (HDS) in hard disk drive (HDD) are coated with a 1-2 nm lubricant layer made of perfluoropolyether (PFPE) to protect the HD from mechanical damage. To improve the reliability and capacity of HDD, understanding of the real-space molecular adsorption structures of lubricants is required for further thinning of the lubricant layer; however, it is difficult because of the lack of a direct imaging technique. In this study, we demonstrated 3D-AFM measurements of PFPE lubricant layers on the HD (Fig. 1a). Figure. 1b shows the xz cross-section obtained from the 3D force image (Fig. 1c) measured on a commercially available HD. The molecular-scale fibrillar contrasts in Fig. 2b-c directly show the complicated and inhomogeneous arrangements of PFPE lubricant molecules. We also performed systematic experiments using different thicknesses and molecular species of PFPE lubricants and successfully visualized the changes in the molecular adsorption structures using 3D-AFM. As shown in this research, 3D-AFM provides molecular adsorption structures in real space and contributes to further molecular-scale improvement of practical materials in various industrial fields.

SS-ThP-36 Reorientation in Vertically Aligned Polycrystalline MoS₂ Films Due to Shear, *Shima Karimi*, North Carolina A&T State University

MoS₂ films grown via chemical vapor deposition are found in a growing number of applications. The size and orientation of the film depends on the growth kinetics set by the deposition parameters. Growth along the edges is energetically favored relative to highly passivated basal plane which leads to vertical alignment. While this vertical orientation is common, it leaves reactive sites exposed, making the films more sensitive to oxidation and humidity. In this work, molecular dynamics simulations were carried out to investigate the reorientation of vertically aligned MoS₂ films during contact and shear. An Indent-Hold-Slide-Retract (IHSR) procedure was applied to model adhesion and frictional behavior. We observe that bonding between the exposed edges of the opposing surfaces drives pull-out of individual MoS₂ sheets from the surface. These flakes are then entrained into the sliding interface and are reoriented horizontally during subsequent sliding which results in lowered friction. The transition toward basal alignment produces a marked reduction in friction and resembles the experimentally observed “run-in” process of MoS₂ coatings. This effect is more pronounced in films with larger grain sizes. We hypothesis that the disorder present in smaller grain sized films produces a higher degree of initial passivation which in turn reduces sheet pull out and reorientation. These results provide atomistic insight into how grain size, density, and microstructural order govern the early sliding response of MoS₂ coatings, linking edge bonding, adhesion, and basal-plane reorientation to the emergence of stable low friction.

SS-ThP-37 Transition Metal Carbides as Pluripotent Catalysts and Support: Materials Synthesis and Reaction Studies, *Keithen Orson, Fanyue Kong, Antonio Valavanis, Prasanna Balachandran, Kory Burns, Ji Ma, Chris Paolucci, Leonid Zhigilei, Sen Zhang, Petra Reinke*, University of Virginia

A long standing challenge in heterogeneous catalysis is the reliance on Pt-group metals which play a major role in the energy transition to renewables. They have been designated by DOE as critical elements and finding substitutions remains a daunting challenge. Transition metal carbides such as Mo and W carbides can be used as catalysts, supports and electrodes but present with complexity in surface chemistry and materials synthesis. The reactions on TMCs as a compound catalyst require therefore modified scaling laws and reassessment of reaction mechanisms in conjunction with materials characteristics.

We combine methods for materials synthesis far from equilibrium, computational approaches to describe carbide surface reactions, and

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surface and electrochemical studies of reactions and material stability. For the carbide materials we aim to control carbide composition, doping with transition metals, defect inventory, and carbide phase for modulation of electronic and surface structure.[2] To reach the unique combination of carbide material characteristics and produce carbide phases not accessible with conventional thermal synthesis, we employ additive manufacturing (AM) using laser powder bed fusion (LPBF) and pulsed laser ablation in liquids (PLAL). Defects, phase distribution and surface reactions are studied with STEM, XPS and related methods. We include DFT calculations to understand and predict the role of defects and phase. We will discuss our results in AM based synthesis and control of carbide materials and introduce carbide surface recovery using graphite inclusions studied with ambient pressure XPS. An initial set of DFT calculations links materials characteristics to surface chemistry, and a workflow to develop potentials for MD calculations will be presented. This presentation illustrates our integrated approach which includes computational and experimental studies on carbide surface reactions including electrochemical characterization, materials synthesis using AM, and the concomitant development of potentials for MD simulations. We will discuss results from all aspects of our work and show their integration in pursuit of carbide development.

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SS-ThP-39 On-Surface Synthesis of Porous Nanographene with Spin-½ and Spin-3/2 States, Mamun Sarker, University of Nebraska - Lincoln; *Haiyue Huang*, University of California, Los Angeles; *Percy Zahl*, Brookhaven National Laboratory; *Prineha Narang*, University of California, Los Angeles; *Alexander Sinitskii*, University of Nebraska - Lincoln

Molecular design is a powerful tool for growing graphene nanostructures with atomic precision, enabling control over their electronic and physical properties. Precisely tuning these properties is essential for advancing the next generation of graphene-based electronic and spintronic devices. Porous nanographene with tailored spin systems represents a new frontier for carbon-based quantum and spintronic materials. Its intrinsic pore architecture, combined with unpaired π -electrons, provides a unique platform to stabilize and control spin states. Here, we demonstrate the on-surface synthesis of porous nanographene from a carefully designed molecular precursor using a combination of solution-phase chemistry and on-surface cyclodehydrogenation under ultra-high vacuum (UHV) on Au(111), as visualized by scanning tunneling microscopy (STM). Scanning tunneling spectroscopy (STS) revealed clear magnetic fingerprints, including a weak Kondo resonance. Depending on precursor design, the system hosts either spin-½ or spin-3/2 ground states. By combining differential conductance spectra and orbital maps with density functional theory (DFT) and advanced multiconfigurational CASSCF calculations, we confirmed their spin states. This work establishes porous nanographene as a versatile platform for engineering multi-spin systems, advancing prospects in molecular magnetism, spintronics, and quantum science.

Thin Films

Room Ballroom BC - Session TF-ThP

Thin Film Poster Session

TF-ThP-1 Thickness and Elemental Quantification of (Ultra)Thin Films Revisited, Markus Sauer, Jakob Rath, Annette Foelske, TU Wien / AIC, Austria; Dieter Ingerle, TU Wien / XRC, Austria

Many approaches have been taken towards precise determination of overlayer thickness and (elemental) quantification of thin/ultrathin films (0.5–100 nm). X-ray reflectivity (XRR) and X-ray photoelectron spectroscopy (XPS) as well as spectroscopic ellipsometry are commonly used to provide information about sample composition and layer depth (1–3). However, each of these methods has its limitations and specific techniques/sample geometries etc. might require extensive preparation and/or do not allow for the use of ultra-high vacuum instrumentation. In addition, some of these methods as well as alternatives like Rutherford Backscattering/Elastic Recoil Detection Analysis (RBS/ERDS) require expensive equipment and/or access to large-scale facilities which is not always an alternative in every day-use cases.

Herein we report a broad comparison of different techniques including most of the above-mentioned ones (XPS, SEM-EDX, XRR, Ellipsometry) as well as Auger-Meitner Electron Spectroscopy (AMES), X-ray fluorescence (WXRF and GIXRF) and Raman spectroscopy for two sets of reference

materials: HfO_2 on SiO_2/Si (4) and Fe/Ni thin films with different relative compositions.

We provide an approach for choosing different methods and method combinations depending on the requirements/sample surface size/roughness etc. for laboratory scale application beyond the reference material case. In addition, limitations of each method in terms of precision and applicability are discussed.

A roadmap is laid out for finding the most useful way of reaching the desired precision for quantification and thickness determination trying to use methods that are available to a large number of researchers in academia and industry.

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TF-ThP-3 Electrical and Mechanical Stability of Flexible Low-Dielectric Constant Carbon-Doped Oxide (SiCOH) Thin Films Under Repeated Mechanical Stress, Rajib Chowdhury¹, SeonHee Jang, University of Louisiana at Lafayette

The microelectronics industry continuously advances materials science to enhance integrated circuit (IC) performance. Interconnect structures are becoming critical as the transistor density increases. It also limits the chip speed due to increased resistance-capacitance (RC) delay. Traditionally, aluminum (Al) and silicon oxide (SiO_2) were utilized as metal and dielectric materials, which were replaced with copper (Cu) and low dielectric constant carbon-doped silicon oxide (low- k SiCOH, $k < 4$) to improve the RC delay and power consumption. Simultaneously, flexible electronics have gained attention, utilizing polymer substrates for applications like wearable devices and displays. However, integrating low- k flexible dielectric films with polymer-based substrates remains challenging due to the low glass transition temperatures of the substrates. Besides, it is essential to study the mechanical stability of materials for the integration of flexible electronic devices. This study explores the applicability of the low- k SiCOH thin films for flexible electronics by observing the effects of repeated mechanical bending tests.

Flexible low- k SiCOH films were produced onto flexible indium tin oxide-coated polyethylene naphthalate (ITO/PEN) substrates by plasma-enhanced chemical vapor deposition (PECVD) of a tetrakis (trimethylsilyloxy)silane precursor. The films were deposited at room temperature with the RF plasma power varied from 20 to 100 W. The films were subjected to bending tests with up to 10000 bending cycles. Mechanical characterization was performed by nanoindentation testing for the elastic modulus and hardness. Chemical bonds were characterized by Fourier transform infrared (FTIR) spectroscopy, and the atomic concentration was measured by X-ray photoelectron spectroscopy (XPS). The dielectric constant was measured from capacitance-voltage measurements.

The pristine SiCOH films had a mechanical strength of up to 9.1 GPa and a low k -value down to 2.00. The films were optically transparent, smooth, and hydrophobic. The prominent chemical peaks of CH_x , $\text{Si}-\text{CH}_3$, $\text{Si}-\text{O}-\text{Si}$, and $\text{Si}-(\text{CH}_3)_x$ were identified for pristine films from the analysis of FTIR spectra. Upon repeated mechanical bending tests with bending cycles up to 10,000, the flexible SiCOH films maintained their transparency, smoothness, and hydrophobicity and showed a stable k -value below 4.0. No significant changes in the FTIR spectra were observed, and no cracks or delamination were observed in the films. The SiCOH films showed stable physical, chemical, and electrical properties under repeated mechanical bending.

¹ TFD James Harper Award Finalist

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TF-ThP-4 The Impact of Copolymer Molecular Sequence on Electronic Transport, Mahya Mehregan, Jack Schultz, University of Missouri-Columbia; Matthew Maschman, Matthias Young, University of Missouri, Columbia

This work demonstrates the successful formation of EDOT-co-Py copolymer thin films using oxidative molecular layer deposition (oMLD), with electrical conductivity values intermediate between those of PEDOT and PPy. By controlling the molecular sequence during copolymerization via the sequential surface reactions afforded by oMLD, we investigate the influence of monomer arrangement on electronic conductivity. Our findings reveal that the electrical conductivity of the copolymer thin films is not determined by the composition ratio of EDOT and Py but is instead strongly influenced by the block length of each monomer chain. These block lengths modulate the electron energy well depths for electron transport along the copolymer chains, which in turn affects conductivity. Our analysis reveals that the energy well depth in Boltzmann transport modeling exhibits a sigmoidal relationship with the separation distance between conductive domains, rather than the previously assumed linear dependence. We identified a critical domain size of >3 monomer units (corresponding to 1.4 nm) that significantly alters electronic conductivity, consistent with electron hopping distances observed in biomolecules. This suggests a universal length scale for electronic interactions in polymers.

TF-ThP-5 Synthesis of Bismuth-based EUV Photoresists using Molecular Layer Deposition, Jane Keth¹, Duncan Reece, David Bergsman, University of Washington

Extreme ultraviolet (EUV) photolithography has seen substantial interest from the semiconductor industry as a tool to create sub-10 nm features, which are necessary to improve device performance. To use this process, EUV-compatible photoresists are needed that are highly absorbing of EUV light, can be deposited as a thin film, and have high etch resistance. Many photoresist materials have been explored to meet this need, including polymer films exposed to vapor-phase infiltrants, polymer films combined with metal additives, and hafnia-based nanoparticle thin films. However, these resists tend to be limited to low viscosity resist formulations or use deposition methods like spin coating that struggle to form conformal coatings. One promising strategy for creating these resists involves using molecular layer deposition (MLD) to synthesize hybrid inorganic-organic films directly on the surface of interest. MLD is a vapor-phase layer-by-layer thin film deposition process that can deposit films with subnanometer thickness and compositional control. While MLD has been used to make aluminum, hafnium, and tin-based EUV photoresists, films based on other elements may be beneficial. In this work, we will present on using a Bismuth-based MLD process to grow hybrid organic-inorganic EUV photoresists. Using a specialized parallelizing reactor unique to the Bergsman research group, we explore the growth of Bi-based photoresists with different organic linkers, characterizing their composition and testing their ambient stability and chemical stability. After studying the as-deposited resists, we treat the resists to UV light and measure their subsequent chemical structure and stability. This data is used to derive the understanding of how Bi-based EUV photoresists can be further optimized for EUV photolithography.

TF-ThP-6 Hollow-Cathode Plasma-Assisted ALD of CuO Thin Films: Evaluating Self-Limiting Growth Conditions and Material Properties, Fatih Bayansal, Steven Allaby, Habeeb Mousa, Helena Silva, Necmi Biyikli, University of Connecticut

Copper oxide (CuO) is a promising p-type semiconductor material with potential applications for energy and optoelectronic devices. In this study, we conducted a comprehensive saturation study within the scope of our initial attempts to grow CuO films by hollow-cathode plasma-assisted atomic layer deposition (HCP-ALD) followed by material characterization study to evaluate the structural, optical, and electrical properties of grown samples.

During CuO growth experiments, copper(II) hexafluoroacetylacetone hydrate $[\text{Cu}(\text{hfac})_2 \cdot \text{xH}_2\text{O}]$ and O_2 plasma were used as the metal precursor and oxidizing agent, respectively. Saturation experiments performed on Si(100) substrates at 150 °C showed that the growth rate reached the saturation regime when the precursor pulse duration increased above a certain threshold. This demonstrated that surface-controlled self-limiting ALD behavior is achieved under appropriate plasma conditions. On the other hand, CuO formation was suppressed in the growths performed using only Ar plasma or O_2/Ar mixture, and metallic or non-stoichiometric

structures were observed in some samples. These results confirmed the critical role of reactive oxygen species for CuO growth.

After determining the self-limiting growth window, the synthesis temperature was gradually increased to 250°C and film deposition studies were carried out on n-Si, sapphire, and quartz substrates. Initial transmittance measurements showed that as the temperature increased, the films exhibited higher transmittance in the visible region, thus increasing the film smoothness and quality.

X-ray diffraction (XRD) analyses revealed that the films grown in optimized O_2 plasma conditions contained polycrystalline CuO phases with (110), (002) and (111) planes. In Ar-oriented plasma environments, Cu_3N phases were observed, suggesting that oxidation was incomplete, or nitrogen doping occurred. These findings indicate that the HCP-ALD process is extremely sensitive to plasma composition and precursor-plasma interactions.

Hall effect, XPS, and TEM analyses are ongoing to determine the electrical, chemical, and structural properties. This research provides the basis for reliable CuO film growth at low temperature, and future process optimizations are aimed at the production of phase-pure, stoichiometric, and electrically active p-type CuO films.

TF-ThP-7 Low-Temperature Atomic Layer Deposition of ZnO Thin Films on Cotton for Flexible Electronics, Habeeb Mousa, Steven Allaby, Fatih Bayansal, University of Connecticut; Md Sazid Bin Sadeque, Tamer Uyar, Cornell University; Helena Silva, Necmi Biyikli, University of Connecticut

The development of flexible electronics has advanced rapidly, with applications from sensors and energy storage to wearables. Among these, photodetectors (PDs) are of growing interest due to their potential roles in health monitoring, security, and optical communication. Zinc Oxide (ZnO), with its wide bandgap, stability under long-term light exposure, and high sensitivity to UV/visible radiation is an ideal material for such devices. However, fabricating thin film-based devices on textiles often affects their mechanical properties such as flexibility, durability, and washability. This work presents an approach that leverages low-temperature atomic layer deposition (ALD) of ZnO on cotton to achieve flexible PDs while preserving the inherent properties of cotton.

ZnO was deposited on cotton (woven bleached, 98 gsm) substrates using diethylzinc (DEZ) and H_2O as Zn precursor and co-reactant respectively in a thermal ALD reactor at 120 °C. The unit ALD cycle in which 20 sccm N2 is used as the carrier gas consists of 0.5s DEZ pulse, 30s purge, 0.5s H_2O pulse, 30s purge steps. Following the deposition of ZnO layers on cotton, interdigitated electrodes consisting of 200 nm Cr was evaporated by e-beam deposition to create the metal-semiconductor-metal (MSM) structures.

The resulting ZnO films on cotton are characterized in terms of their structural, morphological, compositional, and photo-response properties. X-ray diffraction analysis revealed the polycrystalline nature of the as-grown ZnO layer on cotton. The photo-response characteristics of the fabricated MSM-PD device structures were placed under a solar simulator (Newport 94022A) at a distance of ~20 cm. The bias voltage was scanned from -10 to 10V in a 100-mV step under dark and illuminated conditions. The resulting photo-current at 10V bias showed ~160-fold increase when compared to dark current (from 5.5 nA to 888 nA). Moreover, our study displays an effective ZnO-based photodetector on cotton at low bias voltage of 1V where the photocurrent increased from 0.58 nA to 74 nA (~128 fold increase) highlighting the potential for low-power wearable sensing applications. In order to investigate the sensitivity and stability of the device, the photocurrent-time measurements were conducted by applying five 'ON/OFF' pulses at a bias voltages 10 V. The 'ON' state and 'OFF' state lasted for 5 mins each. The sensitivity was calculated and found to be 271. Future studies could focus on further characterizing the spectral photo-response under various environmental conditions and optimizing the device architecture by exploring different doping strategies, or composite structures that can enhance light absorption.

TF-ThP-8 The Impact of Bismuth Surfactants on MBE-Grown InSb Thin Films for Applications in Mid-Infrared Devices, T. Pan Menasuta, John H. McClearney, Thomas E. Vandervelde, Tufts University

Indium antimonide (InSb), an important narrow direct bandgap semiconductor (0.17 eV at 300K), is highly optically sensitive in the mid-wave infrared (MWIR, 2-5 μm) spectrum. InSb-based devices are crucial for thermal imaging, spectroscopy, and astronomy as a result of atmospheric transmission and thermal emission characteristics. [1-5]. Its broad sensitivity (1.5-7 μm) also enables gas detection. However, reproducible

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growth of high-quality InSb epitaxial layers via molecular beam epitaxy (MBE) is challenging due to its low melting point. The epitaxial process requires lower growth temperatures and is prone to crystalline and surface defects. Optimal InSb growth occurs at 385°C with a V: III ratio of 1.2. Accurate temperature control is challenging at these lower temperatures, which further complicates the narrow optimal growth range and can negatively impact the film properties. Controlling surface morphology during growth is critical for advanced optoelectronic devices.

Bismuth surfactancy in MBE has been shown to improve surface morphologies in many III-V materials [6, 7]. A very low bismuth flux can modify the adlayer surface before desorption, and has been shown to improve the morphology of the surface in multiple materials [6–8]. To our knowledge, no systematic studies have been reported on the effects of Bi surfactancy on MBE growth of InSb thin films [6, 7, 9]. This study investigates the effects of Bi surfactancy on InSb MBE growth over a wide range of growth temperatures (280–410°C). Two series of homoepitaxial InSb(100) films were grown by MBE: a control set and a set grown with Bi surfactancy, with identical parameters otherwise. The temperature was calibrated using the RHEED pattern transition c(4x4) to a(1x3), which is reported to occur at 370°C [10, 11]. The surface morphology and elemental distribution were analyzed using AFM and SEM-EDS, while XPS confirmed the absence of Bi incorporation. Finally, TEM was performed to analyze the film's lattice structure.

TF-ThP-11 Mesoporous Metal Fluoride Films with Ultra-low Tunable Refractive Index for Broadband Antireflection, Choon-Gi Choi, Thin Film Materials Research Center, Korea Research Institute of Chemical Technology (KRICT), Republic of Korea; Dong In Kim, Soonmin Yim, Saewon Kang, Sun Sook Lee, Korea Research Institute of Chemical Technology (KRICT), Republic of Korea; Ki-Seok An, Thin Film Materials Research Center, Korea Research Institute of Chemical Technology (KRICT), Republic of Korea

Porous materials are of great interest in various fields such as optics, biology, energy, and catalysis. While energy and catalysis applications focus on achieving high porosity, optical applications demand not only low-refractive-index (RI) materials that overcome the limitations of naturally occurring substances but also the formation of a smooth RI gradient from the substrate to air. This requires both high porosity and precise control over it. Conventional methods for fabricating porous structures, including templating, self-assembly, and zeolitic synthesis, typically rely on sacrificial templates, which must be removed through chemical etching or thermal treatment, potentially damaging the host material and limiting scalability.

In this study, we present mesoporous metal fluoride films composed of MgF₂ and LaF₃, fabricated using a simple, template-free, one-step precursor-derived method. Pores spontaneously form during solidification due to the inherent instability of La(CF₃OO)₃. Electrostatic interactions between Mg(CF₃OO)₂ and La(CF₃OO)₃ precursors enable the controlled formation of mesoporous structures with finely tunable RI values ranging from 1.37 to 1.16. By stacking layers of MgF₂(1-x)-LaF₃(x) with different compositions, a graded refractive index (GRIN) antireflection coating (ARC) is achieved, delivering excellent broadband performance with an average transmittance of ~98.03% in the 400–1100 nm range. Despite these advances, a refractive index gap still remains between the fluoride composite and air, primarily due to the inherently high RI of LaF₃.

To address this, we propose an innovative approach that enables precise tuning of porosity using micelle-assisted MgF₂ precursor intermediates. As micellization increases the size of the MgF₂ precursor clusters, the resulting solidified MgF₂ grains and the intergranular voids between them also increase, allowing for the fabrication of MgF₂ structures with ultra-low RI (~1.04) and fine RI control increments. When applied as a GRIN ARC on quartz substrates, this strategy achieves an average transmittance of ~97.96% across the 250–1100 nm spectral range.

This research was supported by Nano-Material Technology Development Program through the National Research Foundation of Korea (NRF) funded by Ministry of Science and ICT (grant no. 2021M3H4A3A01055854).

TF-ThP-12 A New Approach to Control Metal Deposition on Dielectrics Selectively Using an Aldehyde Inhibitor, Chi Thang Nguyen, Kailey E. Jones, Jacob Bohreer, Bratin Sengupta, Jeffrey W. Elam, Argonne National Laboratory, USA

Selective metal deposition on dielectric surfaces (MoD) is essential for advanced microelectronics applications, particularly in the context of the ongoing transition from 2D to 3D device architectures. However, achieving this selectivity remains challenging due to the similar surface chemistries of many dielectrics. In this work, we introduce a new approach for selectively

controlling metal deposition on dielectric substrates by area-selective atomic layer deposition (AS-ALD) using an aldehyde inhibitor. Butyraldehyde was employed as an inhibitor to selectively adsorb on and passivate Al₂O₃ surfaces while leaving SiO₂ surfaces unaffected. As a result, the adsorption of the ruthenium precursor, [Ru(TMM)(CO)₃], was prevented on the aldehyde-inhibited Al₂O₃ surface in subsequent Ru ALD cycles and the Ru grew selectively on the SiO₂ surface. The inhibitor adsorption behavior, surface blocking properties, and film selectivity were investigated using water contact angle, ellipsometry, scanning electron microscopy (SEM), transmission electron microscopy (TEM), and X-ray photoelectron spectroscopy (XPS) measurements. We believe that AS-ALD using aldehyde inhibitors offers a promising pathway for area-selective MoD in general, and for the integration of Ru into complex interconnects and 3D nanoarchitectures in particular, for next-generation microelectronic devices.

TF-ThP-13 Al₂O₃ ALD Mechanism of Li₆PS₅Cl: Toward Interface Engineering in Sulfide-Based Solid-State Electrolytes, Kyobin Park, Donghyeon Kang, Vepa Rozyyev, Anil Mane, Francisco Lagunas, Hacksung Kim, Fulya Dogan, Zachary Hood, Peter Zapol, Justin Connell, Jeffrey Elam, Argonne National Laboratory

Sulfide-based all-solid-state batteries (ASSBs) have emerged as a compelling alternative to conventional Li-ion batteries owing to their superior gravimetric and volumetric energy densities and enhanced safety characteristics. However, sulfide electrolytes such as Li₆PS₅Cl (LPSCl) are prone to chemical and electrochemical degradation upon contact with cathode and anode materials during cycling, giving rise to significant chemo-mechanical instability. Additionally, LPSCl exhibits extreme sensitivity to moisture and air exposure, leading to the release of toxic H₂S gas and the formation of resistive, electrochemically inactive interphases. Atomic layer deposition (ALD) offers a promising strategy to mitigate LPSCl degradation by depositing an ultrathin, conformal buffer layer on the LPSCl that is chemically and electrochemically stable. When properly engineered, this coating not only suppresses interfacial decomposition but can also improve ionic conductivity and mechanical integrity while minimizing electronic conductivity. Despite its potential, the interfacial reaction mechanisms between ALD precursors and LPSCl remain poorly understood.

In this study, we elucidate the reaction mechanism of Al₂O₃ ALD using trimethylaluminum (TMA) and H₂O on LPSCl through a combination of in situ and ex situ characterizations supported by density functional theory (DFT) calculations. In situ Fourier transform infrared (FTIR) spectroscopy and ex situ nuclear magnetic resonance (NMR) measurements revealed the surface functional groups involved in TMA chemisorption and subsequent H₂O reactions during the initial ALD cycle. Continued ALD cycling demonstrated steady Al₂O₃ growth, as observed by FTIR. Ex situ X-ray photoelectron spectroscopy (XPS) confirmed the formation of new interfacial bonds, while ex situ Raman spectroscopy verified the structural preservation of bulk LPSCl after ALD. Complementary DFT calculations enabled identification of the most thermodynamically favorable reaction pathways for precursor adsorption and film growth. Together, these results provide mechanistic insight into the ALD process on sulfide electrolytes and offer design principles for optimizing interfacial coatings in ASSBs, with implications for broader applications across sulfide-based solid electrolyte systems.

TF-ThP-14 Controlling the Structural and Electrocatalytic Properties of Pulsed Laser Deposited Ruthenium Oxide thin films for Oxygen Evolution Reactions, Jonathan McNair, STEM Early College at North Carolina A&T State University; Russell Boone, Grimsley High School; Ikenna Chris-Okoro, Sheilah Cherono, Mengxin Liu, Ghanashyam Gyawali, Veluchamy Palaniappagounder, Shyam Aravamudhan, Dhananjay Kumar, North Carolina A&T State University

Globally there has been a push for renewable energy sources that can serve in the future as an alternative to the conventional energy sources in existence today that continually lead to environmental degradation. In line with this, research efforts have been geared towards studying the sustainability and reliability of these possible alternatives. In this light, hydrogen generation through the splitting of water is proposed.

This study investigates the electrochemical and structural properties of single crystal ruthenium dioxide (RuO₂), focusing on the effect of varying oxidation state (sub-stoichiometric-RuO_{2-x}, stoichiometric RuO₂, and hyper-stoichiometric RuO_{2+x}) and lattice strain on electrochemical water

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splitting particularly in the oxygen evolution reactions (OER) in 0.1M KOH. Electrochemical Impedance Spectroscopy (EIS) and Cyclic Voltammetry (CV) were used to characterize RuO₂'s behavior in alkaline environments, extracting key parameters such as solution resistance (R_s), charge transfer resistance (R_{ct}), and double-layer capacitance (C_{dl}). RuO₂ thin films were grown through the Pulsed Laser Deposition (PLD) on single-crystal sapphire (Al₂O₃) substrates at varying oxygen pressures (25–75 mTorr) at substrate temperatures 600°C at 4800 pulses. Structural characterization was performed using X-ray diffraction (XRD), X-ray Photoelectron spectroscopy (XPS), X-ray absorption spectroscopy (XAS), Non-Rutherford Backscattering Spectrometry (NRBS), Atomic Force Microscopy (AFM) and Scanning Electron Microscopy (SEM). Atomic modelling was carried out using Vesta to understand the epitaxial growth and relationship between the film and substrate. The films' electrochemical performance was evaluated via CV and Linear Sweep Voltammetry (LSV), with emphasis on the effect of crystal structure and oxidation state on OER activity. These results, validate RuO₂ as a promising material for water splitting applications well as illustrates the importance of deposition ambient control in tailoring the properties of RuO₂ film, which is a fundamental part of the design and optimization of an efficient electrode material.

This work was supported by the NSF-PREM on the Collaborative Research and Education in Advanced Materials Center (via grant # DMR-2425119) and the DOE EFRC on the Center for Electrochemical Dynamics and Reactions on Surfaces (CEDARS) via grant # DE-SC0023415.

TF-ThP-15 Pulsed Laser Deposition and Characterization of Titanium Oxynitride Thin films for Renewable Energy Applications, Russell Boone, Grimsley High School; Jonathan McNair, Sheilah Cherono, Ikenna Chris-Okoro, Mengxin Liu, Ghanashyam Gyawali, Veluchamy Palaniappagounder, Shyam Aravamudhan, Dhananjay Kumar, North Carolina A&T State University

In our world today, despite the efforts of various governments and institutions, fossil fuel unfortunately remains the main source of electricity in the United States and globally. These energy sources create toxic emissions, pollute the atmosphere while promoting climate change. In line with the global shift towards developing sustainable fuels, efforts are needed to develop material systems and processes that can convert molecules in the air (e.g. water, carbon dioxide, and nitrogen) into renewable energy products. In response to preventing a continued dependence on fossil fuels, the splitting of water to produce hydrogen fuel and oxygen is proposed.

In this study Pulsed laser deposition (PLD) technique has been used to grow titanium oxynitride (TiNO) thin films on sapphire (Al₂O₃) for renewable energy applications. A pulsed Krypton Fluoride (KrF) excimer laser (Wavelength=248nm, pulse duration=30ns) was used, with a laser repetition rate of 10 Hz, 6000 pulses, and a deposition temperature of 600°C.

Structural properties of the films were investigated using X-ray Diffraction and Reflection (XRD, XRR), X-ray Photoelectron Spectroscopy (XPS), Atomic Force Microscopy (AFM) and Scanning Electron Microscopy. Structural modelling was performed using Vesta to understand the epitaxial growth and relationship between the film and substrate.

Electrochemical Impedance Spectroscopy (EIS) and Cyclic Voltammetry (CV) were used to characterize titanium oxynitride (TiNO) behavior in alkaline environments, extracting key parameters such as solution resistance (R_s), charge transfer resistance (R_{ct}), and double-layer capacitance (C_{dl}). EIS data, analyzed with Nyquist plots and Randles circuit modeling, these results confirmed the presence of both resistive and capacitive elements, validating as a promising material for water splitting applications.

This work was supported by the NSF-PREM on the Collaborative Research and Education in Advanced Materials Center (via grant # DMR-2425119) and the DOE EFRC on the Center for Electrochemical Dynamics and Reactions on Surfaces (CEDARS) via grant # DE-SC0023415.

TF-ThP-16 Understanding the Electrocatalytic Reaction Kinetics of Ruthenium Dioxide Thin Films using Tafel Equations, Jonathan Roop, Ghanashyam Gyawali, Mengxin Liu, Sheilah Cherono, Ikenna Chris-Okoro, Wisdom Akande, Brianna Barbee, Veluchamy Palaniappagounder, Shyam Aravamudhan, Dhananjay Kumar, North Carolina A&T State University

This research focuses on the study of hydrogen and oxygen evolution reaction kinetics of ruthenium dioxide (RuO₂) thin films in alkaline and acidic media using Tafel slope analysis. The study has given insights into the rate-determining step, kinetics, and mechanisms that govern electrochemical reactions at the RuO₂ electrode and electrolyte interface.

The Butler-Volmer equation was also combined with the Tafel equation at higher overpotentials, which has allowed us to establish a connection between the magnitude of the Tafel Slope and the mechanism of the rate-determining step of the reaction. RuO₂ is an ideal candidate as an electrocatalyst because it is intrinsically stable, corrosion-resistant, and has low resistivity, making it viable for water splitting applications. The RuO₂ films were grown on (0001) plane Al₂O₃ under different deposition conditions, using a pulsed laser deposition method. A three-electrode cell and KOH and HClO₄ electrolytes with different concentrations were used for Linear Sweep Voltammetry testing. The OER and HER overpotential (h) was plotted as a function of log(j), for which the Tafel slope is calculated using the Tafel equation, $h = a + b \log(j)$. For example, Tafel Slope results in 1.0M KOH provide $b_{OER} = 115 \text{ mVdec}^{-1}$ for the 4800-pulse sample and, $b_{OER} = 150 \text{ mVdec}^{-1}$ for the 2100-pulse sample. While Tafel Slope results in 0.1M HClO₄ provide $b_{HER} = 115 \text{ mVdec}^{-1}$ for the 4800-pulse sample and, $b_{HER} = 160 \text{ mVdec}^{-1}$ for the 2100-pulse sample. This data suggests a thicker RuO₂ film will result in more kinetic activity on the surface in alkaline and acidic media. Future work will consist of different characterization methods to verify these results and compare our experimental data to theoretical data for further understanding the mechanisms and steps limiting the reactions of RuO₂ thin films as a working electrode.

TF-ThP-17 Crystallinity's Contribution Toward Electrocatalysis of Ruthenium Dioxide Thin Films, Salil Pai, Ghanashyam Gyawali, Mengxin Liu, Sheilah Cherono, Ikenna Chris-Okoro, Wisdom Akande, Brianna Barbee, Veluchamy Palaniappagounder, Shyam Aravamudhan, Dhananjay Kumar, North Carolina A&T State University

In this study, high-quality ruthenium dioxide (RuO₂) thin films were developed as electrocatalysts, synthesized on sapphire (Al₂O₃) substrates via pulsed laser deposition (PLD)—both materials selected for their financial and logistical accessibility. The investigation centered on the relationship between film crystallinity and electrocatalytic performance, comparing two sets of samples: a more crystalline, thicker set deposited with 4800 pulses, and a less crystalline, thinner set deposited with 2100 pulses. Deposition parameters were held constant at a growth rate of 10 pulses per second, a substrate temperature of 600 °C, and a (100) film orientation. Epitaxial growth and crystallinity were assessed through X-ray diffraction/reflectivity, atomic force microscopy, and Hall effect measurements. Electrochemical analysis via the three-probe method revealed a broad potential window with reversible redox behavior, indicating robust electrochemical activity. Charge transfer dynamics were further examined via electrochemical impedance spectroscopy across varying applied potentials and potassium hydroxide concentrations. The thicker, more crystalline films exhibited enhanced performance and long-term stability compared to their thinner, less crystalline counterparts, reinforcing the conclusion that higher crystallinity is critical for electrocatalytic efficiency. These findings underscore the promise of RuO₂ thin films as durable, high-performance electrocatalysts for energy conversion and storage, while also motivating future studies to systematically explore how deposition parameters—thickness, temperature, orientation, and growth rate—govern crystallinity and, by extension, catalytic performance.

TF-ThP-18 Power-Modulated Thermally Assisted Oxygen Plasma for Enhanced Reliability in TiO₂/TiO_{2-x} Memristors, Beom Gu Lee, Chungdaro 1, Republic of Korea; Jae-Yun Lee, 409, Chungdaro 1 E8-1, Republic of Korea; Sung-Jin Kim, Chungdaro 1, Republic of Korea

The advancement of TiO₂-based memristors is critical for next-generation neuromorphic systems and non-volatile memory devices due to their simple structure, scalability, and stable resistive switching properties. However, achieving high endurance and uniform switching remains a major challenge. Precise control of oxygen vacancy distribution is essential to improve device reliability and performance.

In this work, we propose a thermally assisted oxygen plasma process with RF power modulation for the fabrication of glass/ITO/TiO₂/TiO_{2-x}/Ag memristors. The plasma treatment was conducted at various RF powers (0–80 W) under optimized thermal conditions to investigate its influence on resistive switching endurance, retention stability, and conduction mechanisms. Device performance was evaluated through I–V measurements, endurance cycling, and retention tests.

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TF-ThP-19 Pholuminescence on Room-temperature Germanium-Tin (GeSn), *Lia Guo, Vijay Gregory, Jay Mathews*, University of North Carolina at Charlotte

The use of silicon (Si) in the optics and photonics industry is very popular due to its electronic properties and compatibility with CMOS technology, as well as other semiconductor devices. Germanium (Ge) is an alternative material that can be grown on Si substrates and is now used in photonic devices. However, both Ge and Si suffer from non-radiative processes due to being indirect band-gap materials. Unlike Si, Ge is a quasi-direct bandgap semiconductor and can be band engineered through strain or Sn alloying. Similar to Ge, germanium-tin (GeSn) has shown potential in the photonics industry with a greater focus on light sources. Photoluminescence spectroscopy was carried out using a NIR 980nm laser to probe the optical properties of the GeSn/Ge/Si samples. These measurements were analyzed with reference to Rutherford backscattering and cross-sectional TEM.

Undergraduate Poster Session Room Ballroom BC - Session UN-ThP

Undergraduate Poster Session

UN-ThP-1 Nitrogen Plasma Treated-Polyactic Acid: Examining pH Variations During Degradation, *Imaandeep Bual, Morgan Hawker*, California State University, Fresno

Polyactic acid (PLA) is a promising biodegradable polymer that degrades at a faster rate than conventional fossil fuel polymers and can combat the growing issue of plastic pollution. Moreover, it is an excellent alternative to the growing issue of microplastics because it can be readily degraded through hydrolysis. Although PLA is biodegradable, it induces environmental change when degrading. Specifically, the degradation of PLA in soil via hydrolysis has been shown to lower the soil's pH, adversely affecting plant growth. Previous research demonstrates that certain plants containing nitrogen-processing bacteria use nitrogen moieties to raise the pH of soil. Furthermore, PLA has been shown to degrade at an accelerated rate in alkaline conditions. We hypothesize PLA degradation can be induced by introducing nitrogen functional groups on the surface via nitrogen plasma treatment (NPT), which can then act as Lewis bases upon degradation. The impact of NPT on PLA degradation has not been previously investigated at large.

This study examined the change in pH as NPT PLA degraded in room temperature DI (deionized) water. PLA films were fabricated and plasma treated in an inductively-coupled plasma reactor using nitrogen gas as the precursor. Plasma treatment parameters including 30 W, 328 mTorr, and two minutes of treatment time were selected based on previous literature and optimized to maximize nitrogen incorporation. NPT PLA films and untreated control films were then submerged in 10 mL of DI water at room temperature to initiate degradation. Changes in pH of NPT and control PLA films were compared after degradation. Previous results showed no significant difference in pH change associated with one week of degradation of PLA between control and NPT films, necessitating longer-term degradation studies of NPT PLA film degradation with a specialized pH probe. Collectively, NPT shows potential to alter the chemical degradation of PLA when compared to native PLA degradation.

UN-ThP-3 Investigation of Spinel and Sapphire Plasma Etching for Development of Anti-Reflection Nanostructures, *Sean Campbell, Thomas Hutchens, Stephanie Alvarez, Jacob Hay, Tyler Benge, Ishwar Aggarwal*, The University of North Carolina at Charlotte

In the field of high-energy lasers, there is a need for optical windows that exhibit high transmittance in the visible to mid-wave-infrared wavelength range (MWIR). This can be done with the patterning of nanoscale anti-reflective (AR) structures onto spinel and sapphire substrates. AR structured surfaces (ARSS) have shown to exhibit higher laser damage thresholds compared to thin-film AR coatings. The substrates are etched with a reactive ion plasma etcher and subsequently characterized with the help of a Fourier Transform Infrared Spectrometer(FTIR). Different etch chemistry and their respective etch rates were investigated, as well as optical transmission performance of the materials at visible to MWIR wavelengths. Future work involves masking of the substrate via photoresist and fine-tuning the scalability of the masking and etching process to larger substrate form factors.

UN-ThP-5 Freshwater Biofouling Analysis of Nano-Textured and Anti-Reflection Coated Windows, *Stephanie Alvarez, Thomas Hutchens, Sean Campbell, Jacob Hay, Tyler Benge, Ishwar Aggarwal*, University of North Carolina at Charlotte

Most high performance optical components, like lenses and windows are designed for sterile, low-contaminate environments, however, optical systems used by the Navy often operate in harsh marine and sandy environments. Improving the lifespan of optical elements in these conditions is essential. Optical elements with anti-reflective (AR) coatings or structured surfaces, which feature nano-textured elements, are particularly vulnerable to degradation. This study aims to evaluate the impact of submerged environments on these components. Long term testing was conducted on five 1-inch-diameter fused silica windows with different surface treatments: a polished blank, a hydrophilic "web-like" AR, a hydrophobic "moth-eye" AR structured surface (ARSS), a commercially available ARSS and a thin-film AR coating. Samples produced in-lab are done through high-vacuum mask deposition and plasma etching to produce the AR structured surface desired. Prior to submersion, the contact angles and optical transmission spectra of each window was measured. The samples were placed in a flotation housing unit and submerged in a semi-controlled biological freshwater environment for 30 days. Once removed, the windows were analyzed for biofouling accumulation and changes to optical performance. This experiment aims to identify how surface coatings and nano-structures influence the biofouling resistance of optical elements, providing insights into improving optical components durability in challenging environments.

UN-ThP-6 Sol-Gel Hyper-Hydrophilic Anti-Fog Coatings Study & Model Of Surface Condensation Vs. Current Anti-Fog Strategies To Maximize Time-To-Fog & Optical Properties On Medical Lenses, *Nicole Herbots, Sio2 Innovates LLC / Infinitum BioMed LLC / UV One Hygienes Inc. / Arizona State University Department of Physics; Arya Bhakta¹, Sio2 Innovates LLC / Case Western Reserve University; Shreyash Prakash, Sio2 Innovates LLC / Infinitum BioMed LLC; Viraj Amin, Sio2 Innovates LLC / Infinitum BioMed LLC / University of Missouri-Kansas City School of Medicine; Ashwin Suresh, Sio2 Innovates LLC / Infinitum BioMed LLC / University of Arizona Department of Physiology; Srivatsan Swaminathan, Sio2 Innovates LLC / Infinitum BioMed LLC / Arizona State University / Icahn School of Medicine at Mount Sinai; Visheshwar Swaminathan, Sio2 Innovates LLC / Infinitum BioMed LLC / UV One Hygienes Inc.; Dora D. Suppes, Mark Russell-Hill, Infinitum BioMed LLC / UV One Hygienes Inc.; Robert J. Culbertson, Arizona State University Department of Physics; Eric J. Culbertson, Providence Santa Rosa Memorial Hospital / Sio2 Innovates LLC*

Endoscope lenses easily fog within closed body cavities, disrupting the visual field during surgery within minutes. Lens opacification is due to water vapor condensation, which forces surgeons to remove the scopes, wipe their lenses, and reinsert them. Repeated scope wiping and reinsertion increases infection risks, length of surgery and OR use, and tissue scarring due to prolonged air exposure.

Current strategies to inhibit fogging, such as alcohol-based coatings and heating, introduce complications. For example, alcohol solutions evaporate quickly and irritate damaged tissue due to their acidity. Another strategy is to pre-heat endoscope lenses; this requires reheating due to the cooling of small diameter lenses (2- 12 mm) connected to 30-200 mm endoscopes. Textured lens surfaces rapidly wear and are very difficult to clean and sterilize.

This work has developed a phenomenological model for fogging on smooth surfaces: the SEE (or Surface Energy Engineering) model with direct surface energy measurements. SEE has guided development and testing of new *hyper-hydrophilic* sol-gel coatings, KnoxFog¹, using two key properties to inhibit fogging. First, coating' surfaces are *super-hydrophilic*, meaning molecules condense in 2D sheets (Frank-Vander Merwe Growth Mode) instead of 3D droplets (Volmer-Weber Growth Mode). Second, nanopores in the Sol-Gel absorb water as the condensate thickens. This combination yields a lasting anti-fog coating, where water condenses for 2+ hours into a continuous, flat film, free of optical distortion and droplets, even when exposed to blood and tissue debris.

Using four pairs of endoscopes *in vitro*, at T= 38±2°C, the time-to-fog (TTF) of a pair of identical endoscopes whose lens is coated with KnoxFog is compared in a closed cavity *simultaneously* with a pair of bare lenses and two pairs using the current anti-fog strategies. TTFs of KnoxFog coatings exceed 131 min with a variation of < 1 %. TTFs of bare lenses average less

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than 8 ± 8 min. In these same simultaneous conditions of water evaporation, a variation of 100% can occur in surgery due to a lack of controlled surface conditions on bare lenses. KnoxFog™ improves TTF by $1625 \pm 1\%$ over bare lenses, reduces by two orders of magnitude the TTFs unpredictability of bare lenses, and improves over lens tip heating, whose TTF averaged less than 1 min *in the same conditions*, and on alcohol-based coatings, whose TTF averages 47.5 min with a variability of 56%.

In vivo animal studies show that KnoxFog performance significantly increases TTFs and optical clarity while reducing the need for frequent lens cleaning from blood and tissues.

¹Trademark owned by SiO2 Innovates

UN-ThP-8 An Investigation into the Optoelectronic Properties of Layered and Vertically Aligned MoS₂-MoSe₂ Heterostructures on Different Substrates, *Elycia Wright*, Clark Atlanta University; *Kedar Johnson*, Clemson University; *Amari Gayle*, *Robin Rousseau*, *M.K. Indika Senevirathna*, *Michael D. Williams*, Clark Atlanta University

Two-dimensional transition metal dichalcogenide (TMD) materials offer exciting opportunities for various applications, particularly due to their unique layer-sensitive band structures, valley-selective optical coupling, and remarkable catalytic activities. Their notably large exciton binding energies and strong nonlinear optical responses underscore their potential. Moreover, by strategically stacking different monolayer TMD materials, we can create heterostructures that allow tuning band gaps across visible to infrared spectrum. This approach enhances their optoelectronic properties and opens new avenues for advancements in fields such as optoelectronics and photonics.

This research investigates the optoelectronic properties of MoSe₂-MoS₂ heterostructures grown on various substrates, including gallium nitride (GaN) and sapphire, using the chemical vapor deposition (CVD) technique. The study also examines how the choice of substrate affects the growth of layered versus vertically aligned heterostructures. We utilize CVD techniques because they have proven more effective for producing samples with extensive monolayer growth than the commonly used exfoliation method. By analyzing the differences in bandgap, the Raman and infrared (IR) vibrational modes, we aim to reveal the unique properties of these heterostructures.

UN-ThP-9 Correlation Analysis of In Situ Atomic Layer Deposition Mass Spectrometry Data for Surface Reaction Analysis, *Ayelen Mora*, *Eric Bissel*, *Parag Banerjee*, University of Central Florida

Atomic Layer Deposition (ALD) enables precise, conformal thin-film coatings on high-surface-area nanoparticle powders through sequential, self-limiting reactions. However, coating nanoparticle beds presents unique challenges, including precursor diffusion limitations, particle agglomeration, and extremely high surface areas (reaching \sim 10s of m^2/g). These factors complicate the ALD process, making it essential to monitor reaction progress and identify saturation ("end-pointing") within the powder bed.

In this work, we employ quadrupole mass spectrometry (QMS) as an *in situ* diagnostic tool to study Al₂O₃ ALD on ZnO nanoparticle powder beds. Using trimethylaluminum (TMA) and ozone (O₃) as precursors at a deposition temperature of 120 °C, we track methane (CH₄) evolution—a key reaction byproduct—to gain insights into surface reaction kinetics and saturation behavior. Furthermore, we develop multivariate analysis tools to interpret ALD reaction dynamics in powder bed reactors with the hope of enabling better process control and optimization.

UN-ThP-10 Naturally Derived Polymers for Biomedical Applications: Stabilizing Hydrophilicity after Nitrogen-Plasma-Treatment, *Mina Abdelmessih*¹, *Morgan Hawker*, California State University, Fresno

Polylactic acid (PLA) and chitosan (CS) are popular biopolymers that display tremendous potential for scaffolding applications in the biomedical field. Both polymers are renewable: PLA is produced from renewable feedstock, while CS is obtained through the deacetylation of chitin. The use of these polymers in biomedical-related applications such as scaffolding is promising due to their non-toxicity *in vivo* and biodegradability. Additionally, they each contain distinct mechanical and degradation properties suitable for different applications. However, both polymers have a hydrophobic surface, which restricts their biomedical implementations where cell adhesion is critical (e.g., in applications related to tissue and bone engineering). There is some evidence that cell adhesion and growth are facilitated by hydrophilic surfaces. Radio-frequency nitrogen plasma treatment displays promise in increasing the polymers' hydrophilicity, but also displays

potential aging instability with hydrophobic recovery. This poses a significant problem for applications of the treatment especially when considering storage-induced aging. Approaches to prevent this phenomenon in PLA and CS are widely unexplored.

This work investigated the impact of various aging conditions (storage in vacuum, cold temperature, and air) on the surface hydrophilicity of PLA and CS after exposure to nitrogen plasma. Films were prepared as model substrates using the solvent-casting method, and treated in a RF plasma reactor under optimized parameters (power, pressure, and treatment time). After treatment, the films were aged in the different aging environments for two weeks. Throughout the aging period, multiple surface analyses were conducted on samples exposed to the various preservation environments, including untreated samples as controls. Surface wettability analysis utilizing water contact angle goniometry displayed that vacuum aged PLA films and cold temperature aged CS samples possess the least hydrophobic recovery in comparison to other aging conditions. Surface chemical composition of PLA and CS samples was examined using x-ray photoelectron spectroscopy. These treatment preservation methods to PLA and CS have potential to positively impact their future use in the biomedical field as scaffolds.

UN-ThP-12 Bacterial Infection Detection in Drops Flattened into Thin Films by Super-hydrophilic Collection Surfaces using Macroscopic DNA/RNA Epi-Fluorescence: A hand-held sensor for Bacterial Infection Diagnosis: BacteroBug™, *Arya Saravanan*, SiO2 Innovates/Arizona State University, Life Sciences & BioChemistry; *Sriram Rajesh*, SiO2 Innovates LLC; *Nila Kathiravan*, SiO2 Innovates LLC/InnovaBug LLC; *Sudharshini Ram*, *Nithish Prakash*, SiO2 Innovates LLC/InnovaBug LLC/ViroBug LLC; *Viraj Amin*, SiO2 Innovates LLC/InnovaBug LLC/University of Missouri - Kansas City (School of Medicine); *David Guo*, SiO2 Innovates LLC/Innovabug LLC/Drexel University/University of Arizona School of Medicine; *Eric J. Culbertson*, SiO2 Innovates LLC/InnovaBug LLC/Microbe Lab-On-Chip LLC; *Robert J. Culbertson*, Arizona State University Department of Physics; *Nicole Herbots*, SiO2 Innovates LLC/InnovaBug LLC/Microbe Lab-On-Chip LLC/Arizona State University

In 2025, the gold standard for bacterial infection diagnosis, developed in the 70s, is plate culturing. State-of-the art infection diagnostics use the universally accepted Colony Forming Units (CFUs) counting on cultured plates, which requires 10-30 mL of blood, urine, sputum, etc... and 2-3 days for results.

However, about 40% of all positive cultures are false positives due to contamination from skin pathogens and handling in blood, urine, sputum, etc... during collection or environmental contaminations.

Per the NIH, false positives are "independently associated with increased subsequent laboratory charges (+20%) and IV antibiotic charges (+39%)". The excess of diagnosed infections costs US hospitals about \$20+Billions/year in 2025. False positives lead to administration of antibiotics in healthy patients, leading to antibiotic resistance, and to more than 48,000 US deaths/ year.

New, reliable methods are needed for bacterial detection, loads, infection diagnosis.

The present research investigates whether Macroscopic DNA Epi-Fluorescence (MaDRE) can be used for bacterial detection, and whether macroscopic epi-fluorescence intensity scales quantitatively with bacterial load in small volume drops using fluorophores developed for fluorescence microscopy. To sort detected microbes by class, 3 fluorophore combinations are designed to detect DNA/RNA in live bacteria and protozoa, RNA in viruses, and fungi-specific proteins.

A quantitative study was thus conducted to establish whether a MaDRE-based device is viable in accuracy and reproducibility. An initial stock solution in Luria Broth is diluted logarithmically into 10 bacterial serial loads from 1.0 to 10^{-9} for calibration. Next, MaDRE's sensitivity is tested on these 2 x ten bacterial loads, to establish whether 520 nm fluorescence intensity of safe green DNA fluorophores I_G scales reproducibly with bacterial concentration. The two sequential experiments were conducted by applying four 0.1 mL identical drops from each of the 20 solutions on 2 hyper-hydrophilic prototype strips.

I_G is normalized to the 497 nm excitation intensity, I₀, before and after 0.1 mL dye drops are applied, as R_{G/B}. The difference between post-dye R_{Raw} and pre-dye R_{Bgd} yields the net R_{Net}.

R_{Net} averages of 8.5 ± 2.1 for 300k *E.Coli* CFU/mL, and 3.6 ± 0.34 for 100 k *E.Coli* CFU/mL. Thus, R_{Net} decreases 250% with a decrease of one order of

¹ JVST Highlighted Poster

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magnitude in bacterial load. Pre-dye R_{Bgd} averages $= 1.8 \pm 0.25$, thus lower by a factor 2 to 4 than post-dye R_{Net} .

Hence, the normalized fluorescence ratio $R_{G/B}$ scales with bacterial concentration consistently using 0.15 mL drops, and a handheld, small volume device is presently prototyped, BacteroBug™.

UN-ThP-14 Statistical Optimization of Polynomial Fits for Carbon Bonding Analysis in XPS, *Garrett Lewis, Matthew Linford, Alvaro Lizarbe, Brigham Young University; David Aspnes*, North Carolina State University

X-ray photoelectron spectroscopy (XPS) is a valuable tool for surface-level chemical analysis, particularly effective in assessing carbon hybridization states through the D-parameter, which distinguishes sp^2 and sp^3 bonding. Because this analysis involves differentiation, proper signal smoothing is critical to minimize the effects of noise. In this work, we explore high-order polynomial fitting as a general approach to prepare carbon Auger data for D-parameter analysis. To enhance reproducibility and reduce subjectivity, we introduce an algorithmic method for identifying the most suitable polynomial orders for smoothing. This approach evaluates the underlying structure of the data to balance over- and underfitting without relying on visual judgment. The results demonstrate that using statistical tools to guide polynomial selection leads to more reliable analysis of carbon bonding in XPS data. While developed for carbon Auger analysis, this method can be extended to other contexts where spectral smoothing is required for derivative-based measurements.

UN-ThP-15 Formation of Etch Masking Layer on Fiber Optic Tip via Laser Annealing for ARSS, *Riley van Ravesteyn, Jacob Hay, Stephanie Alvarez, Sean Campbell, Tyler Benge, Ishwar Aggarwal, Thomas Hutchens*, UNC Charlotte

In high-energy laser systems containing fiber optics cables, cable end faces and connectors are susceptible to laser induced damage, prompting the development of novel methods to increase the interface laser induced damage thresholds (LiDT). This can be done by applying a nano-scale anti-reflective structured surface (ARSS) to the end of these connectors. ARSS have been shown to exhibit a higher LiDT than conventional thin-film, anti-reflection (AR) coatings. Typical methods for fabricating ARSS involve masking and plasma etching steps. To apply ARSS to a fiber optic cable connector with performance in longer wavebands, like infrared, annealing of a gold film deposited via e-beam evaporation on the end of the connector is needed. This study focuses on a method for annealing, utilizing an off-the-shelf 1.6 W, 450 nm wavelength laser to deliver energy through the fiber optic cable in order to heat the opposing fiber endface to annealing temperatures, preserving the connector and fiber packing. Successful annealing was achieved on the fiber tip, forming an “island” mask layer, verified by scanning electron microscope imaging. Future goals for this project include developing the plasma etching step, and making the annealing process a readily available resource for commercial usage.

UN-ThP-16 Investigating the Surface Evolution of the Self-Assembly of Quinone Derivatives on Au(111) Using Ambient STM and CV, *Carla Plaisance, Nazila Hamidi, Erin Iski*, University of Tulsa

Quinones are an interesting class of redox active molecules due to their ability to undergo a reversible two electron transfer process. These molecules can be utilized in a multitude of applications from energy storage and electrochemical carbon dioxide capture to redox mediators in batteries. This research used ambient Scanning Tunneling Microscopy (STM) to observe the interactions of the quinone derivative, 2,3-dichloro-5,6-dicyano-1,4-benzoquinone, on the surface of Au(111) at room temperature following varying times of immersion. Immersion times in a saturated solution of the molecule in 0.1M HClO₄ varied from 30 minutes to 15 hours in order to study the effects of immersion on the adsorption kinetics, surface coverage, orientation, and self-assembly of the molecule on the surface. Cyclic voltammetry (CV) measurements were used in tandem with STM imaging to confirm redox activity and to act as a mode of electrochemical and topographical comparison for the different immersion times. STM imaging revealed that the immersion time influenced the molecular orientation and surface coverage of the quinone derivative on the crystal and that the best molecular resolution was achieved with minimal immersion times, which were needed to limit the amount of molecules on the surface. While these molecules and their associated derivatives have been extensively studied under ultra-high vacuum (UHV) and low temperature (LT) environments, it is critical to understand their adsorption behavior under ambient conditions and to interrogate their stability on electrodes in air. These findings highlight the ability of using STM in ambient conditions to study redox-active systems which have a wide range of applications in electrochemistry and molecular electronics.

UN-ThP-17 Recommendations & Justifications for Peak Fitting PDMS & Similar Polymers, *Heidi Meyers, Joshua Pinder, Matthew Linford, George Major*, Brigham Young University

Peak fitting is a critical tool that enables the determination of a substance's chemistry through data analysis techniques such as X-ray Photoelectron Spectroscopy (XPS). However, obtaining accurate and meaningful results can be challenging. By examining a few common, though sometimes overlooked, errors, we can improve the accuracy of data fitting. Some of these errors include overfitting, fitting noisy data, and peak envelope filling.

By applying these recommendations to our own experiments, we provide justifications and reasoning behind polymer peak fitting, specifically for Polydimethylsiloxane (PDMS). One useful approach is to compare pure SiO₂ to PDMS. Comparing measured reference data to unknown samples helps predict peak shapes and intensities, particularly for the contributing oxygen and silicon peaks. Valuable resources for measured spectra include Beamson & Briggs (especially for polymer databases) and Surface Science Spectra.

These guidelines aim to provide a practical foundation for accurate peak fitting in polymer systems.

UN-ThP-18 Structural Characterization of Gadolinium-Doped Indium Tin Oxide Thin Films Grown on Various Substrates for Dilute Magnetic Semiconductor Applications, *Landon Brown, Masoud Kaveh, David Lawrence, Costel Constantin*, James Madison University

Dilute magnetic semiconductors (DMS) are materials of great interest because they combine semiconducting and magnetic properties, enabling simultaneous control of electron charge and spin—an essential feature for emerging spintronic technologies. These materials hold promise for the development of faster, low-power electronic devices and quantum computing components. Gadolinium-doped indium tin oxide (Gd-ITO) thin films are promising DMS candidates, as gadolinium exhibits near room-temperature ferromagnetism ($T_C \approx 290$ K). In this study, Gd-ITO thin films with Gd concentrations ranging from 0% to 16% were deposited using DC magnetron sputtering. The films, approximately 1 μm thick, were simultaneously grown on silicon, oxidized silicon, quartz, and sapphire substrates. X-ray diffraction (XRD) measurements were conducted to compare lattice constants across all substrates. The FullProf Suite, employing the Le Bail method, was used to accurately extract lattice parameters.

UN-ThP-19 Benchmarking Active Learning Protocols for Collaborative Cross-Facility Autonomous Workflows, *Stephen Xiao*, Oak Ridge National Laboratory; *Ryan Lewis, Noah Paulson*, Argonne National Laboratory; *Yongtao Liu, Sumner Harris*, Oak Ridge National Laboratory

Self Driving Labs (SDLs), which combine robotic automation with machine-learning-driven design of experiments, will benefit from cross-facility collaborative workflows by mutually enriching research capabilities through shared experimental and computational resources. Here, we prototype a cross-facility workflow by conducting a simple color-mixing experiment, which is analogous to a wide variety of possible chemical synthesis/processing experiments. Automated robotic color-mixing experiments are conducted at Argonne National Laboratory's Rapid Prototyping Lab (RPL), and the resulting data are streamed to Oak Ridge National Laboratory for machine-learning surrogate modeling in sequential decision-making. This results in an autonomous experimental workflow sharing robotic infrastructure at one facility and computing resources at another. We first created a digital twin of the color-mixing experiment to benchmark surrogate model choice, acquisition function, and experiment batch size to select the appropriate active learning protocol which balances both equipment time-cost and material cost. We find that a Gaussian process surrogate with an expected improvement acquisition function outperforms both Bayesian neural network (BNN) and random forest surrogates. We then deploy the optimal active learning protocol in the cross-facility autonomous workflow in real color-mixing experiments and compare the performance with the digital twin.

UN-ThP-20 Atom-based Quantum Sensors: Electromagnetic Induced Transparency in Rubidium, *Brian Holloway*, United States Military Academy; *Michael Speer*, West Point; *Tyler Catapano*, United States Military Academy

Atom-based quantum sensors are emerging as powerful tools for detecting electromagnetic signatures, offering advantages in size, weight, power consumption, and cost. One promising approach involves Electromagnetically Induced Transparency (EIT)—a quantum interference effect that enables precise, Doppler-free spectroscopy in atomic systems.

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Our group has developed a sensor based on EIT in a dilute gas of Rubidium atoms, where electromagnetic radiation excites atoms into high-lying Rydberg states. We recently achieved Rydberg-level EIT for principal quantum numbers 53, 54, 68, and 85, allowing us to probe the hyperfine structure of Rubidium with high resolution.

We performed detailed spectroscopic analysis including:

- Frequency spacing measurements between $53^2D_{3/2}$ and $53^2D_{5/2}$ states using quantum defect theory.
- Line shape analysis to identify homogeneous and inhomogeneous broadening mechanisms.
- Angular momentum coupling studies using relative peak heights and Clebsch-Gordon coefficient ratios.
- Microwave-induced splitting of EIT features (Autler-Townes effect), which provides insight into transition dipole matrix elements in multi-level atomic systems.

These results contribute to a deeper understanding of atomic interactions in Rydberg-state atoms and offer a validated experimental framework for advancing atom-based quantum sensing technologies.

UN-ThP-21 Electrodialytic Separation of Cobalt and Nickel in the Presence of EDTA, *Jonah Buck, Samuel Perkins*, Oregon State University

Cobalt and nickel are toxic heavy metal ions often found in waste solutions from battery recycling and energy product manufacturing facilities. Both are classified as critical materials by the United States and other governments due to their importance in energy technology and national security. However, their similar atomic radii and identical charge makes traditional separation techniques largely ineffective. Prior research has been performed into the selective conjugation of ethylenediaminetetraacetic acid (EDTA) with nickel over cobalt to form an anion to facilitate better electrochemical separation. This study investigates electrodialytic separation in the presence of EDTA as a solution for recovering the critical materials from industrial wastewater solutions.

Using a BED 1-2 electrodialysis bench from PCCell GmbH (Germany), we use various ion exchange membrane configurations to draw the Ni(EDTA) anions out of an acidic solution consisting of equal parts cobalt and nickel and an Ni:EDTA molar ratio of 85:100. The supporting ions are sulfates (sulfuric acid, metallic sulfate hydrates).

Preliminary analysis using inductively coupled plasma optical emission spectroscopy (ICP-OES) shows that over 85% of nickel can be effectively extracted from a solution containing cobalt with this method, with minimal cobalt co-transport. Ongoing experimentation aims to optimize various experimental variables such as membrane selection and current density to increase separation efficiency. EDTA-assisted electrodialysis is a promising strategy for critical metal recovery from industrial wastewater in a potentially scalable and environmentally conscious manner. Recovered materials could then be reused in their respective processes.

UN-ThP-22 Denoising X-ray Photoelectron Spectroscopy Data by Fourier Analysis, *Kristopher Wright, Matthew Linford, Alvaro Lizarbe, Garrett Lewis*, Brigham Young University; *David Aspnes*, North Carolina State University; *David Morgan*, Cardiff University, UK; *Mark Isaacs*, University College London, UK; *Jeff Terry*, Illinois Institute of Technology

Smoothing X-ray photoelectron spectroscopy (XPS) spectra is widely discouraged. Indeed, filtering data should not be employed as a means to repair poorly taken data. However, there are times when special circumstances would warrant the use of a filter to denoise XPS data. We propose using Fourier analysis to denoise spectra in these circumstances. The Gauss-Hermite filter displayed in this poster makes improvements on the boxcar and Savitsky-Golay filters in artifact-reduction. We compare filtered low-scan number spectra with signal averaged "true" spectra taken over many scans.

Vacuum Technology

Room Ballroom BC - Session VT-ThP

Vacuum Technology Poster Session

VT-ThP-1 Deposition and Sublimation of Argon Sphere Immersed in a Non-Condensable Gas Over an Wide Range of the Knudsen Number, *Felix Sharipov*, Universidade Federal do Paraná, Physics Department, Brazil; *Denize Kalempa*, Universidade de São Paulo, Brazil; *Irina Graur*, Aix-Marseille University, France

Rarefied gas flows involving phase transitions on solid surfaces are of both scientific and practical interest, particularly, for the development and

optimization of vacuum systems, heat exchangers, and chemical reactors, etc. For example, heat and mass transfer driven by the sublimation of solid particles plays a crucial role in advancing technologies based on chemical vapor deposition in vacuum chambers. In the kinetic theory of gases, evaporation and condensation, analogous to sublimation and deposition, have been extensively studied using the Boltzmann equation and the Direct Simulation Monte Carlo method. However, most existing studies rely on simplified models with hypothetical molecular masses and the hard-sphere potential for intermolecular interactions. In this work, we consider a solid argon sphere surrounded by its vapor and helium as a background gas. The temperature and pressure of the mixture are set such that argon undergoes sublimation or deposition, while helium solely reflects off the solid surface. To capture flow regimes ranging from free-molecular to transitional and viscous, we employ a kinetic model for the linearized Boltzmann equation to compute mass and heat transfer from the argon sphere to the surrounding gas mixture. To assess the influence of interatomic interactions on the flow dynamics, calculations are performed using both the hard-sphere model and ab initio potentials. The results demonstrate that the partial pressure of helium significantly impacts the mass and energy transfer rates from the particle due to phase transitions occurring on its surface.

VT-ThP-2 Experimental Characterization of Water Outgassing Energetics on Bare and Magnetite-Coated Low-Carbon Steel Surfaces, *Aiman Al-Allaq*, ODU - Jefferson Lab; *Md Abdullah Al Mamun, Matthew Poelker*, Jefferson Lab; *Abdelmageed Elmustafa*, ODU

This work presents a detailed experimental setup and methodology for comparative outgassing analysis between bare and magnetite-coated AISI 1020 low-carbon steel chambers. Using a custom-built throughput apparatus, we measured outgassing rates under various thermal conditions. Binding energies obtained through Sips isotherm modeling (0.9-0.97 eV for bare steel, 1.12-1.24 eV for magnetite) and activation energies derived from rate-of-rise accumulation measurements (0.33-0.68 eV for both surfaces) provide complementary perspectives on the energy landscape governing water interactions with these surfaces. The difference between these energy parameters offers insight into the shape of the potential energy diagram, revealing the height of the desorption barrier relative to the adsorption well depth. This comprehensive energetic picture helps explain the counterintuitive finding that magnetite, despite its higher binding energy, exhibits worse outgassing performance after thermal treatment. Our analysis demonstrates how the combination of throughput measurements and multiple energy characterization techniques creates a more complete understanding of surface-gas interactions critical for vacuum system optimization. This approach provides both fundamental insights into desorption processes and practical guidance for thermal treatment protocols in vacuum applications requiring extremely low outgassing rates.

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2D Materials

Room 208 W - Session 2D+AQS+EM+NS+QS+TF-FrM

2D Materials: Devices and Applications

Moderator: Kai Xiao, Oak Ridge National Laboratory

8:15am 2D+AQS+EM+NS+QS+TF-FrM-1 Charge Transport in Printed Films of Two-Dimensional Materials for Printed and Wearable Electronics, *Felice Torrisi*, Imperial College London, UK **INVITED**

Printed electronics has emerged as a pathway for large scale, flexible, and wearable devices[1], Internet-of-Things[2] and smart textiles[3]. Graphene and related two-dimensional (2D) materials offer an ideal platform of novel materials for high performance printed electronics [4,5]. Electronic inks from 2D materials with different electronic properties have been developed to print the different elements of a device: semiconducting or semimetallic inks in the active layer, insulating inks for dielectrics, and conducting inks for electrodes[6].

In this talk I will describe the charge transport mechanisms of surfactant- and solvent-free inkjet-printed thin-film devices of representative few-layer graphene (semi-metal), molybdenum disulphide (MoS₂, semiconductor) and titanium carbide MXene (Ti₃C₂, metal) by investigating the temperature, gate and magnetic field dependencies of their electrical conductivity.[7]

Charge transport in printed few-layer MXene and MoS₂ devices is dominated by the intrinsic transport mechanism of the constituent flakes. On the other hand, charge transport in printed few-layer graphene devices is dominated by the transport mechanism between different flakes.[7]

[1] Torrisi, F. & Carey, T. "Graphene, related twodimensional crystals and hybrid systems for printed and wearable electronics" *Nano Today* 23, 73 (2018).

[2] C. Scholten et al. "Advanced Technologies for Industry – Product Watch: Flexible and printed electronics", doi: 10.2826/29513 (2021).

[3] Carey, T. et al. "Fully inkjet-printed two-dimensional material field-effect heterojunctions for wearable and textile Electronics" *Nat. Commun.* 8, 1202 (2017).

[4] Torrisi, F. et al. Inkjet-printed graphene electronics. *ACS Nano* 6, 2992{3006 (2012).

[5] F. Torrisi & T. Carey "Printing 2D Materials" in "Flexible Carbon-based Electronics" Editors P. Samori and V. Palermo, Ed.: Wiley-VCH, Weinheim, Germany, 2018. ISBN: 978-3-527-34191-7.

[6] D. Akinwande "Two-dimensional materials: printing functional atomic layers" *Nat. Nanotechnol.* 12, 287 (2017).

[7] E. Piatti, A. Arbab et al. "Charge transport mechanisms in inkjet-printed thin-film transistors based on two-dimensional materials" *Nature Electronics* 4, 893 – 905 (2021).

8:45am 2D+AQS+EM+NS+QS+TF-FrM-3 Antimony as a Contact Material for Two-Dimensional Semiconductors: Interface Chemistry and Thermal Stability, *Fernando Quintero Borbon, Joy Roy, Robert Wallace, Rafik Addou*, University of Texas at Dallas

Antimony (Sb), a semimetal, has emerged as a promising contact material for two-dimensional (2D) semiconductors. Sb contacts have been shown to achieve ultra-low contact barriers. The formation of a Sb–Se bond has been demonstrated as an effective doping strategy in n- and p-FETs with a single WSe₂ channel through Sb–Pt contact modification. These findings underscore the necessity for further investigation into the interface chemistry and thermal stability of Sb on transition metal dichalcogenides (TMDs), to determine whether the interaction remains van der Waals or becomes chemically reactive upon thermal processing.

The present study offers a comprehensive study of the interface chemistry between Sb and TMDs, in particular MX₂ (M = Mo or W; X = S or Se), using X-ray photoelectron spectroscopy (XPS). Sb was deposited in ultra-high vacuum conditions (UHV) on bulk TMD surfaces, followed by annealing in UHV at 100°C, 200°C, and 300°C. The XPS measurements revealed an absence of chemical or interfacial reactions at room temperature, 100°C, and 200°C. However, upon annealing at 300°C, complete sublimation of the Sb layer was observed. These findings support the van der Waals nature of the interface, confirming that the interaction between Sb and the underlying TMDs remains non-reactive up to 200 °C. This thermal stability and inertness suggest that Sb could be a promising candidate for integration in 2D heterostructures and devices that require clean, weakly interacting interfaces.

[1] Y.-T. Lin et al. *Nano Lett.* (2024) 24, 8880–8886

[2] Z. Wang et al. *Adv. Funct. Mater.* (2023) 33, 230165

[3] T. Su et al. *J. Phys. D: Appl. Phys.* 56 (2023) 234001

[4] Wang et al. *Adv. Funct. Mater.* (2023) 33, 2301651

[5] Chou et al. *IEEE International Electron Devices Meeting (IEDM)*, San Francisco, CA, USA (2021) 7.2.1-7.2.4.

9:00am 2D+AQS+EM+NS+QS+TF-FrM-4 Metal-to-Semiconductor Transition in Niobium Sulfoselenide Alloy and Niobium Sulfide Films by Compositional Control and Post Growth Sulfurization, *Tinsae Alem, Abir Hasan, Kory Burns, Nikhil Shukla, Stephen McDonnell*, University of Virginia

Transition metal dichalcogenides (TMD) have attracted increasing scientific interest due to their diverse properties including a tunable bandgap, optical anisotropy, low power consumption, and good elasticity. In this study, low-dimensional TMD films were grown with molecular beam epitaxy (MBE) to investigate the effects of varying chalcogen (sulfur and selenium) content in niobium sulfoselenide (Nb_xSe_{2-x}) alloys. Here, we focus on their electrical resistivity and electronic properties, including the transition from metallic to semiconducting behavior to have precise control over the material's electrical conductivity. Additionally, we analyzed the semiconductor-to-metal transition in Nb₂S films following post-growth sulfurization and the corresponding changes in resistivity. These MBE grown films were characterized using in-situ x-ray photoelectron spectroscopy (XPS) to analyze the chemical composition. Next, the electrical resistivity of films was calculated using their sheet resistance measured with a Jandel 4-point probe, and their thickness was estimated using x-ray reflectivity (XRR). We used transmission electron microscopy (TEM) to visualize these MBE-grown films at the atomic scale, enabling the correlation of atomic structure with electronic properties. Lastly, the temperature coefficient of resistance (TCR) measurements was performed to understand the resistivity of the films with temperature dependence and to determine their metallic and semiconducting behavior. Our results demonstrate that the transition from metal to semiconductor occurs with the addition of sulfur into the niobium selenide film. We also observed a trend of increasing resistivity as the sulfur content was increased in niobium selenide film. This work explores the potential of tuning the energy gap of TMD materials, making them ideal candidates for tunable nanoelectronics in various applications.

9:15am 2D+AQS+EM+NS+QS+TF-FrM-5 Evolution of the Electronic Gap of Directly Synthesized Versus Mechanically Transferred WS₂ Monolayer to Multilayer Films, *Xu He, Antoine Kahn*, Princeton University

Transition metal dichalcogenides (TMDs) have emerged as promising electronics and optoelectronics materials for their strong light-matter interaction, large exciton binding energies, and bandgap tunability through the control of composition and the number of layers. Among TMDs, WS₂ stands out for its strong photoluminescence and spin-orbit coupling, making it ideal for exploring charge transfer and interfacial phenomena. However, discrepancies in reported energy levels (electronic gap, ionization energy, electron affinity) remain due to variations in growth and measurement methods, impeding device design.

In this study, we directly compare the band structure of WS₂ films from monolayer to multilayer (up to four layers) prepared by two commonly used methods: direct growth via metal-organic chemical vapor deposition (MOCVD) and mechanical exfoliation with layer-by-layer transfer. We utilize a suite of characterization techniques, including Raman spectroscopy, photoluminescence (PL), UV-vis absorption, and X-ray photoelectron spectroscopy (XPS), to probe vibrational modes and optical transitions. A combination of ultraviolet photoelectron spectroscopy (UPS) and inverse photoemission spectroscopy (IPES) allows us to directly study the evolution of ionization energy and electron affinity, hence the electronic gap of the materials.

We find that the electronic gap (E_g) of WS₂ consistently decreases with increasing layer number, reaching bulk-like values by the trilayer for mechanically transferred layers. The exfoliated monolayer is found to have an E_g of 2.43 eV, which reduces to around 1.97 eV at the trilayer and stays at 1.98 eV for the tetralayer. This layer-dependent E_g reduction is driven firstly by an upshift of the valence band maximum (VBM) at the 1L-2L transition and then by a downshift of the conduction band minimum (CBM) at the 2L-3L transition.

Comparing differently processed layers, we find the MOCVD-grown monolayer WS₂ to exhibit an electronic gap of 2.56 eV, larger than 2.43 eV for the mechanically transferred one. The slightly larger E_g in MOCVD-grown monolayers also yields a higher exciton binding energy (~0.55 eV)

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than in exfoliated monolayers (~ 0.43 eV). XPS analysis indicates that MOCVD samples contain more oxygen-related defect species, likely contributing to the subtle band gap differences and a small blue shift of their optical spectra relative to exfoliated layers.

Overall, this comparative study highlights the influence of the fabrication methods on the fundamental electronic structure of WS_2 . These findings provide important guidelines for tailoring band alignments for WS_2 -based heterostructures and optoelectronic devices.

9:30am 2D+AQs+EM+NS+QS+TF-FrM-6 2D Phase Diagram of Iron Sulfides on Au(111):From Hexagonal to Square Atomic Arrangement and Beyond, *Andrea Berti*, University of Trieste, Italy; *Marco Bianchi*, Paolo Lavori, Silvano Lizzit, Elettra-Sincrotrone Trieste, Italy; *Philip Hofmann*, Aarhus University, Denmark; *Alessandro Baraldi*, University of Trieste, Italy

Despite extensive research on two-dimensional (2D) materials, almost all experimentally synthesized 2D systems derive from van der Waals crystals (vdW). While the use of vdW crystals has been remarkably successful, it inherently restricts the 2D materials landscape to compounds that are already layered in their bulk form. Less than 5% of known inorganic materials possess a layered structure suitable for exfoliation, and the vast majority of functional compounds—such as oxides, sulfides, and nitrides—do not belong to this category. In recent years, increasing efforts have focused on the realization of truly two-dimensional monolayers from non-vdW compounds, which could unlock novel properties in fields such as high-temperature magnetism, catalysis, and strongly correlated electron phenomena. Beyond the class of vdW materials, only a limited number of compounds have so far been theoretically predicted to be stable in the 2D limit. In this context, iron–sulfur compounds have recently emerged as promising candidates. Density functional theory predicts that both hexagonal FeS_2 and tetragonal FeS phases can exist as stable monolayers, exhibiting strain-tunable magnetic properties. Although the Mermin-Wagner theorem precludes long-range magnetic order in ideal 2D isotropic systems, magnetic anisotropy can lift this constraint and allow stable ordering, enabling tunable magnetism at the atomic scale, which is essential for spintronics, as well as other emerging phenomena such as topological effects, multiferroicity, and proximity effects in heterostructures. However, compared to their bulk counterparts, Fe–S systems generally display a rich phase diagram, characterized by multiple stoichiometries and atomic arrangements. A similar complexity may also persist in the 2D limit, highlighting the need for a systematic experimental investigation into which 2D FeS_x phases can actually form. For this purpose, we systematically grow and characterize iron sulfide monolayers on Au(111) via in-situ co-deposition of Fe and S. Low-energy electron diffraction (LEED), scanning tunneling microscopy (STM), and X-ray photoelectron spectroscopy (XPS) reveal two primary phases: one with a hexagonal atomic arrangement consistent with FeS_2 (Fig. 1a), forming a moiré superstructure, and one with a square arrangement (Fig. 1b). By tuning sulfur exposure, we observe additional phases with varying stoichiometry and atomic arrangement, all belonging to the same 5×5 superstructure family (Fig. 1c). These results confirm the existence of a complex 2D phase diagram for FeS_x monolayers, establishing them as a versatile and tunable platform for exploring 2D magnetism in non-vdW systems.

9:45am 2D+AQs+EM+NS+QS+TF-FrM-7 The Electronic Band Structure and Conduction Band Formation of $HfSe_3$, *Gauthami Viswan*¹, University of Nebraska-Lincoln, USA; *Alexey Lipatov*, South Dakota School of Mines and Technology; *Alexander Sinitskii*, University of Nebraska-Lincoln, USA; *Jose Avila*, Synchrotron SOLEIL and Université Paris-Saclay, France; *Takashi Komesu*, University of Nebraska-Lincoln, USA; *Maria C. Asensio*, Madrid Institute of Materials Science (ICMM), Spain; *Peter A. Dowben*, University of Nebraska-Lincoln, USA

Abstract: The anisotropic structure of Group 4 transition metal trichalcogenides (TMTCs) have gained significant interest due to their possible application in optoelectronics. In this work, the band structure of quasi one-dimensional $HfSe_3$ was investigated with nano-spot angle resolved photoemission spectroscopy (nanoARPES). $HfSe_3$ has a rectangular surface Brillouin zone where the effective hole mass along the chain direction is -0.27 m_e which is smaller compared to the effective hole mass along the direction perpendicular to the chains, -1.17 m_e . The effective hole mass extracted from the band structure along different high symmetry directions is compared with that of TiS_3 and ZrS_3 from prior studies.¹ X-ray absorption spectroscopy (XAS) has been used to characterize the unoccupied states of $HfSe_3$ and will be compared to the XAS spectra of HfS_3

² and TiS_3 and ZrS_3 .³ The metal chalcogenide hybridization for Hf differs from the Ti and Zr trichalcogenides. This may be due to the increase in effective atomic number leading to strong spin-orbit interaction of Hf based TMTCs.

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10:30am 2D+AQs+EM+NS+QS+TF-FrM-10 Applications of Two-dimensional Materials in Energy, Water, and Healthcare, *David Estrada*, Boise State University

INVITED

The rapidly evolving field of 2-dimensional (2D) materials continues to open new frontiers in fundamental and applied research across water purification, healthcare, and energy applications. This talk will highlight our recent work in the synthesis of 2D and layered-materials-based inks, enabling energy innovations in microsupercapacitors, triboelectric nanogenerators, and electron devices [1-3]. In water applications, we introduce a flowing electrode capacitive deionization (FE-CDI) system utilizing $Ti_3C_2T_x$ MXene electrodes to efficiently remove and recover ammonia from synthetic wastewater and carbonates from simulated ocean water. This FE-CDI system demonstrates promising potential for managing nitrogen and carbon cycles while improving access to clean water [4]. In healthcare, the intersection of graphene and biology offers a powerful avenue for musculoskeletal tissue engineering, where graphene's exceptional physical properties contribute to fundamental biological insights [5-7]. Lastly, this talk will highlight recent insights into WS_2 nucleation and film growth on sapphire using tungsten hexacarbonyl and hydrogen sulfide precursors in an AIXTRON 2D Close Coupled Showerhead MOCVD 3×2 reactor, with in situ photoreflectometry monitoring. Together, these findings highlight the transformative role of 2D materials beyond graphene in addressing critical engineering challenges and advancing sustainable solutions across diverse fields.

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11:00am 2D+AQs+EM+NS+QS+TF-FrM-12 Electronic Structure Modulation in 2D Metal–Graphene–Metal Electrocatalysts for CO_2 Reduction and Hydrogen Evolution Reactions, *Arturo Medina*, Ines Saih, Vikas Muralidharan, Georgia Institute of Technology; Jinwon Cho, NREL; Faisal Alamgir, Georgia Institute of Technology

Two-dimensional metal–graphene–metal (M/Gr/M) heterostructures provide a versatile platform for tuning electrocatalytic behavior through controlled interfacial strain and charge redistribution. In previous work, orbital-level descriptors were introduced to explain how pseudo-epitaxial strain alters the electronic structure of ultrathin metals, driving changes in

¹ SSD Morton S. Traum Award Finalist

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catalytic activity for the CO₂ reduction reaction (CO₂RR). These concepts were grounded in density functional theory and validated experimentally by correlating spectroscopic strain signatures with shifts in catalytic onset potential.

Building on this framework, the present study expands the scope and range of electrocatalytic reactions studied in M/Gr/M systems. We integrate new measurements on the hydrogen evolution reaction (HER), exploring whether the same strain–electronic structure–reactivity relationships observed in CO₂RR extend to HER kinetics. This includes analysis of onset potentials, overpotentials, and durability across a diverse set of M/Gr/M configurations. Various metals from the 3d to 5d series were investigated as candidate electrocatalysts, deposited as atomically thin layers on single-layer graphene. The graphene is supported by both metal and metal oxide substrates, enabling systematic modulation of ligand effects and interfacial bonding.

To probe strain and charge transfer, we employ a suite of synchrotron-based and lab-scale techniques including carbon K-edge near-edge X-ray absorption fine structure (NEXAFS), extended X-ray absorption fine structure (EXAFS), ultraviolet photoelectron spectroscopy (UPS), X-ray photoelectron spectroscopy (XPS), and electron energy loss spectroscopy (EELS). We track strain-induced modifications in electronic structure through synchrotron-based spectroscopy, revealing systematic correlations between interfacial bonding, orbital structure, and catalytic performance. By comparing systems with and without graphene, we isolate the role of interfacial bonding in modulating both electronic structure and catalytic behavior.

This work experimentally explores theoretical predictions for HER in M/Gr/M systems and provides new insight into how strain-induced orbital modulation governs charge transfer and reactivity across multiple electrocatalytic reactions. Together, these results highlight M/Gr/M structures as a model system for disentangling the fundamental interactions between dimensionality, strain, and catalytic function.

11:15am 2D+AQs+EM+NS+QS+TF-FrM-13 Large Area Nanostructuring of Van Der Waals Materials for Photon Harvesting in the Flat Optics Regime, Matteo Barelli¹, Francesco Bautier de Mongeot, Simone Di Marco, University of Genoa, Italy; Rajesh Chennuboina, University of Genoa, India; Giorgio Zambito, Giulio Ferrando, University of Genoa, Italy; Matteo Gardella, CNR-IMM, Italy; Maria Caterina Giordano, University of Genoa, Italy

2D-Transition Metal Dichalcogenides (2D-TMDs) are two-dimensional semiconductors featuring high optical absorption coefficient combined with good transport and mechanical properties. Although mechanically exfoliated TMD flakes ensure the best optoelectronic properties, homogeneous large-area growth techniques are mandatory for real-world applications [1,2]. At the same time, in view of light conversion applications in the extreme thickness regime of 2D-TMDs, it is essential to develop effective photon harvesting flat optics strategies derived from nanophotonics.

Here we demonstrate that periodic modulation of few MoS₂ and WS₂ on large area nanostructured samples fabricated by laser interference lithography (either MoS₂ nanostripes arrays or conformal MoS₂ layers grown on top of nanogrooved silica templates). These nanopatterned layers can effectively steer light propagation via Rayleigh Anomalies in the flat optics regime, promoting strong in-plane electromagnetic confinement and broadband omnidirectional photon absorption enhancement, with strong impact in photoconversion. [3,4].

As a case study, we investigate the photocatalytic performance of periodically corrugated MoS₂ layers for photodissociation of Methylene Blue (MB), a widely used yet harmful textile dye. Under optimized angles coupling light to photonic anomalies, MB degradation is two times faster compared to planar MoS₂ films [5]. Additionally, periodic TMD nanostripes serve as directional scatterers, expanding possibilities for advanced light manipulation.

Another major challenge is the scalable fabrication of 2D van der Waals (vdW) heterostructures, often limited to micrometric flakes. Here, we demonstrate large-area (cm²-scale) nanoscale reshaping of vdW heterostructures. Specifically, we report a flat-optics platform using vertically stacked WS₂-MoS₂ heterostructures endowed with type-II band alignment, forming periodic nanogratings [6]. These engineered large-area

vdW heterostructures enable scalable applications in nanophotonics, photoconversion [7], and energy storage.

We recognize funding by the NEST - Network 4 Energy Sustainable Transition - PNRR partnership.

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11:30am 2D+AQs+EM+NS+QS+TF-FrM-14 Exploring the Temperature Coefficient of Frequency (TCf) in Graphene Trampoline Resonators, Yunong Wang, Nawara Tanzee Minim, S M Enamul Hoque Yousuf, Philip Feng, University of Florida

In this work, we report the first experimental investigation of the temperature coefficient of resonance frequency (TCf) in graphene trampoline nanoelectromechanical system (NEMS) resonators. Trampoline resonators are widely used in photothermal sensing applications thanks to their superior thermal isolation, enabling high sensitivities. Leveraging the exceptional mechanical strength, thermal stability, and ultralow mass of two-dimensional (2D) materials, graphene trampoline resonators offer a compelling platform for ultrafast infrared (IR) detection. Characterizing the TCf is essential for designing sensors with stable performance across a wide temperature range, enabling high-resolution IR detection, and developing robust NEMS for advanced light sensing applications.

We use focused ion beam (FIB) to make trampoline structure on our graphene drumhead resonator. The resonance characteristics of the device are measured by using a laser interferometry system. An intensity-modulated 405 nm blue laser is employed to drive the device photothermally, and a 633 nm He-Ne laser is used to read out device resonance motions. The reflected light is detected by a photodetector and converted to an electrical signal, which is analyzed by a network analyzer to obtain the resonance response. To measure the resonance frequency at different temperatures, we regulate the temperature of the device with a metal ceramic heater. The temperature of the chip is measured by a platinum resistance temperature sensor.

We measure the resonance response of the device at different temperatures and extract the resonance frequency and quality (Q) factor by fitting the measured spectrum to the damped simple harmonic resonator model. The drumhead resonator with 20 μm diameter shows a resonance frequency $f=3.44$ MHz and $Q=528$, while after FIB, the trampoline structure achieves a significantly higher $f=13.03$ MHz and $Q=5509$. As temperature increases, the negative thermal expansion of graphene causes an upward shift in resonance frequency. We observe a TCf exceeding 30,100 ppm/ $^{\circ}\text{C}$ from the drumhead structure, extracted from frequency shifts between 30 $^{\circ}\text{C}$ and 60 $^{\circ}\text{C}$. After we FIB the drumhead structure into a trampoline, we found that the TCf reduced to 588 ppm/ $^{\circ}\text{C}$.

A lower TCf value from the stage heating-up method is desirable for stable operation across varying thermal conditions. Due to geometric isolation and reduced thermal coupling to the substrate, the trampoline is expected to exhibit a smaller TCf than its drumhead counterpart. This makes the trampoline resonator a strong candidate for IR sensing applications that require stable performance over a broad range of temperatures.

Actinides and Rare Earths

Room 207 A W - Session AC+MI-FrM

Spectroscopy, Spectrometry, 5f Behavior and Forensics

Moderators: Ladislav Havela, Charles University, Czech Republic, Gertrud Zwicknagl, Technical University Braunschweig, Alison Pugmire, LANL

8:15am AC+MI-FrM-1 Exploring the Surface Chemistry of Plutonium using ToF-SIMS, Sarah Hernandez, Los Alamos National Laboratory INVITED

Plutonium metal is highly reactive by immediately forming an oxide layer when exposed to air and quickly forming a hydride when exposed to hydrogen. The fundamental understanding of the impact of impurities and defects on the effect of oxidation and corrosion of Pu is limited in both experimental and theoretical studies. Time-of-Flight Secondary Ion Mass Spectroscopy (ToF-SIMS) is a unique surface science technique that is highly

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sensitive to the first 1-2 monolayers of the surface (<1nm) and can detect all isotopes (including hydrogen) at parts-per-million levels, which gives a comprehensive survey of surface constituents. This technique also provides a structural and reactivity, chemisorption versus physisorption, information and complements other surface science techniques, such as X-ray photoelectron spectroscopy (XPS). In general, ToF-SIMS may provide a more in-depth analysis of surface constituents that otherwise might not be detected or deconvolute from a complex XPS spectra. A newly installed ToF-SIMS nanoToF 3 at LANL uses a 30 kV Bi_3^{++} liquid metal ion gun as the primary ion source and has a mass resolution of 12,000 ($\Delta m/m$), thus providing a new level of mass resolution and sensitivity on Pu surfaces that was not previously achieved. I will show recently collected ToF-SIMS results of hydrogen and oxygen gas reactions on alpha-Pu and 2 at. % Ga stabilized δ -Pu surfaces and how they compare with other.

8:45am AC+MI-FrM-3 HERFD vs XAS: The Case for Equivalence, *J G Tobin*, U. Wisconsin - Oshkosh

The advent of new, powerful, highly efficient, multi-component, X-ray monochromators used in the detection of tender x-rays has revolutionized spectroscopic investigations of the 5f electronic structure. All of the new experiments are, in essence, variants of X-ray Emission Spectroscopy (XES), where the improved monochromatized detection, applied to novel specific decay pathways, plays a key role. In HERFD (High Energy Resolution Fluorescence Detection) a type of Resonant Inelastic X-Ray Scattering (RIXS), the monochromatized XES detection allows the performance of a scattering experiment with vastly improved resolution. It is argued here that HERFD devolves into a higher resolution version of X-Ray Absorption Spectroscopy (XAS). It has been shown that the M_4 and M_5 spectra are essentially direct measurements of the j-specific ($5f_{5/2}$ and $5f_{7/2}$) Unoccupied Density of States (UDOS), which can be directly correlated with the UDOS from Inverse Photoelectron Spectroscopy (IPES) and Bremsstrahlung Isochromat Spectroscopy (BIS). [1-3] Furthermore, a remarkable level of agreement is achieved between a model based upon the UDOS of Th and a series of HERFD and IPES/BIS results with various 5f occupation levels. [4-6] Finally, the historical record of XAS will be examined, demonstrating the success of various resonant decay schemes as measures of the underlying XAS.

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9:00am AC+MI-FrM-4 Room Temperature H_2 Dosing on Polished α -Pu Surfaces with XPS, *Daniel Rodriguez*¹, *Timothy Gorey*, *William Ponder*, *Alessandro Mazza*, *Raymond Atta-Fynn*, *Sarah Hernandez*, Los Alamos National Laboratory

Plutonium (Pu) is a complex element with an interesting electronic structure, and it is also a material of great importance for both nuclear energy and security. To better understand its interaction with gases, surface analysis of the alpha (α) variant provides valuable insight when coupled with a technique such as X-ray photoelectron spectroscopy (XPS). Different core electron orbitals may be probed, and binding energies from emitted electrons provide information on the local chemical state, i.e., degree of oxidation, reduction, or carbonization within the α -Pu.

Here we investigated the effect of hydrogen (H_2) gas dosing of α -Pu surfaces, which reacts and forms plutonium hydride (PuH_2) at temperatures >100 °C. By slowing the kinetics at room temperature, we may witness H_2 dynamics on native α -Pu surfaces, and view how Pu materials such as oxidized and carbonized forms evolve with H_2 exposure. In addition, we present our findings from density functional theory (DFT) validating experimental observation. To provide an example, Fig. 1 shows a plot of various Pu 4f spectra. In red, metal α -Pu is observed after having been sputtered to remove both surface contaminants and the native oxide layer. The defining metal feature in the $4f_{7/2}$ peak is seen at ~ 422.2 eV. Next, the sample was dosed with H_2 gas for 198 Langmuir (L) (blue line), and then the exposure was increased (green line) until reaching 396 L. A clear reduction in the signal's intensity is seen in both the $5/2$ and $7/2$ metal peaks. Secondly, the $7/2$ satellite shows an increase in signal, which is indicative of surface passivation. Clearly, more is needed to know what these H_2 induced changes signify, and this presentation will show additional spectra from the O 1s, C 1s, and the Pu valence band, along with DFT to contextualize the ongoing mechanisms of H_2 with the α -Pu surface.

9:15am AC+MI-FrM-5 Ab Initio Modeling of Hydrogen Interaction with the Surface of α -Pu, *Raymond Atta-Fynn*, *Sarah Hernandez*, Los Alamos National Laboratory

Hydrogen (H) reacts strongly with plutonium (Pu) metal, with the reaction primarily initiated on the metal surface. However very little is known theoretically about H dynamics on the surface of the ambient temperature phase of Pu, namely α -Pu. In this regard, we carried out calculations on H interactions with the α -Pu(020) surface using density functional theory-based geometry optimizations and *ab initio* molecular dynamics at 300 K. Molecular H_2 dissociated spontaneously on the metal surface at room temperature, resulting in atomic H chemisorption. The energy barriers to diffusion of the chemisorbed H from the surface into the subsurface and bulk layers were modeled using accelerated *ab initio* molecular dynamics. The magnitudes of the energy barriers to H diffusion in relation to hydride formation will be discussed.

9:30am AC+MI-FrM-6 A Novel Lexan-Aerogel Detector for Fission Track Analysis for Advancing Nuclear Forensics, *Itzhak Halevy*, *Rami Babayev*, *Yaakov Yehuda-Zada*, Ben Gurion University Be'er Sheva, Israel; *Galit Bar*, Soreq Nuclear Research Center, Israel; *Noam Elgad*, *Mark Last*, Ben Gurion University Be'er Sheva, Israel; *Jan Lorincik*, Research Centre Řež, Czechia; *Itzhak Orion*, Ben Gurion University Be'er Sheva, Israel; *Shay Dadon*, Nuclear Research Center Negev, Israel; *Aryeh M. Weiss*, Bar Ilan University, Israel; *Galit Katarivas Levy*, Ben Gurion University Be'er Sheva, Israel

Fission track analysis is a technique employed in nuclear forensics to identify and examine fission isotopes. This technique is specific for small samples in the range of a few picograms or to analyze bigger samples and check for homogeneity.

In the old Lexan detector, the tracks are pretty close, and that limits much the ability to count the tracks and analyze the length of the tracks. The main target of the fission track is to locate the fission ions in between a lot of other isotopes. The located fission ions could be transferred to other techniques like ICP-MS for further analysis. Better separation between tracks and analysis could lead to showing the yield of fission products, which is specific to every fission isotope. The yield fission products are two humps on the graph that are equal in area. One hump is around $A=95, 135$; in the length of the track histogram, the two humps look different due to the difference in dE/dx of the different energies. The light elements hump looks narrow, and the heavy elements hump looks wide; still, the area of those humps is equal. We created a novel detector for fission track analysis with the Lexan-modified detector.

This innovative detector exhibits more dispersion of fission tracks. In this innovative approach, we adhered aerogel to the Lexan. The aerogel has a low absorption coefficient; hence, it does not substantially obstruct the fission products in the detector. The incorporation of aerogel modifies the geometric configuration, enlarges the dimensions of the fission track stars, and increases the separation between individual tracks, as seen in Fig. 1 in the supplement. A fission track star of a size of 150 microns can reach 350 microns with the aerogel configuration. Given that the fission products are distributed isotopically while the aerogel is two-dimensional, it is necessary to employ stereoscopic projection to facilitate their integration. An illustration of this enhancement of the fission track star is seen in Fig. 1, where the dimensions of the fission track star are greater and the tracks are widely spread. The newly developed analytical program, **Finder**, may utilize a 2D representation of the fission track star. Whether an actual star or a simulated star, of a fission track to conduct analysis and provide 3D

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evaluations, therefore illustrating the fission yield of the fission isotope. The analysis of the fission track star is shown in Fig. 2, supp. The fission track analysis of ^{235}U star in that software is depicted in Fig. 3 supp.

Fission track length before the detector and in it are shown in that figure of the fission track analysis of ^{235}U star.

Atomic Scale Processing Mini-Symposium Room 206 A W - Session AP+EM+PS+TF-FrM

Area Selective Processing and Patterning

Moderators: Steven M. George, University of Colorado at Boulder, Angelique Raley, TEL Technology Center, America, LLC

8:15am AP+EM+PS+TF-FrM-1 Exploring Intermolecular Interactions of an Acetylacetone Variant as Small Molecule Inhibitor for Area-Selective ALD, Eric Ha Kit Wong, Marc J. M. Merkx, Joost F. W. Maas, Eindhoven University of Technology, The Netherlands; Ilker Tezzevin, Eindhoven University of Technology, Netherlands; Wilhelmus M. M. Kessels, Eindhoven University of Technology, The Netherlands; Tania E. Sandoval, Universidad Tecnica Federico Santa Maria, Chile; Adriaan J. M. Mackus, Eindhoven University of Technology, The Netherlands

Self-assembled monolayer (SAMs) and small molecule inhibitors (SMIs) are two types of inhibitors for area-selective atomic layer deposition (AS-ALD). One critical requirement for inhibitors is to form densely packed adsorbate layers on the non-growth area. SMIs can be delivered in the vapor phase, which makes them compatible with existing industrial processes. However, the random sequential adsorption of SMIs tend to leave gaps in between the adsorbates (1). Intermolecular interactions could improve SMI packing and coverage, potentially leading to a higher selectivity.

π - π interaction is an important class of intermolecular interactions that has been employed in different fields (2). To exploit π - π interactions in SMIs, one can introduce aromatic backbones to the molecule. In this work, 3-phenyl-2,4-pentanedione (Hppa (3)) is used as the structural variant of acetylacetone (Hacac) for inhibiting ALD on Al_2O_3 as the non-growth area over the growth area of SiO_2 .

Using in-situ reflection-absorption infrared spectroscopy, we examined saturation behaviour, precursor blocking, and thermal desorption of Hppa. The results indicate that Hppa has similar adsorption behaviour as compared to Hacac, in terms of saturation dosages and bonding configurations. Still, various important differences are found: Firstly, the Hppa adsorbates exhibit a transition from a flat-lying configuration at low coverage, to a standing-up configuration at high coverage, suggested by the emergence of the sp^2 $\nu(\text{CH})$ peak. This indicates that the adsorbates are in orientations that could contribute to π - π interaction. Secondly, the results of blocking tests suggested that Hppa adsorbates are not displaced from the surface by bis(diethylamino)silane (BDEAS) precursor molecules, in contrast to the Hacac case in which ca. 5% of acac adsorbates are removed from the surface by BDEAS. Thirdly, Hppa adsorbates does not show thermal desorption at 150 °C for 10 hours. Instead, the increase in peak area suggest that the adsorbates might undergo rearrangement to other orientations. In summary, our results suggest that the Hppa can be an effective SMI for AS-ALD.

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8:30am AP+EM+PS+TF-FrM-2 the Influence of Intermolecular Interaction on the Packing of Small Molecule Inhibitors: A Simulation Study, Joost Maas, Marc Merkx, Eindhoven University of Technology, Netherlands; Tania Sandoval, Universidad Tecnica Federico Santa Maria, Chile; Adrie Mackus, Eindhoven University of Technology, Netherlands

In recent years, using small molecule inhibitors (SMIs) has become one of the main approaches to achieve area-selective atomic layer deposition (AS-ALD). The main challenge for area-selective deposition (ASD) using SMIs is to obtain a high packing of inhibitor molecules on the surface. Due to the vapor phase dosing, molecules arrive one-by-one at random locations, which leaves gaps in between the inhibitors where potentially a precursor can adsorb, causing loss of selectivity.[1]

In this work we explore the use of attractive intermolecular interactions for achieving higher packing of SMIs via simulations. When employing small

molecules, it is expected that van der Waals interactions are too weak to contribute to packing. Consequently, one of the main questions of this work is how strong the interaction has to be to facilitate ordering of molecules on the surface. In addition, the synergy of intermolecular interaction and diffusion of SMIs over the surface is investigated.

The simulation method used for studying the packing of molecules with intermolecular interaction and diffusion is an augmented random sequential adsorption (RSA) model.[1] During every loop of the RSA model, either adsorption or diffusion takes place, based on the adsorption and diffusion rates. The intermolecular interaction energy is implemented in the form of a Metropolis-Hastings algorithm.[2] In the initial work, the molecule is a simple disk on a hexagonal grid with periodic boundary conditions, considering nearest neighboring blocking.

It was found that the coverage of the SMI improves significantly for low diffusion barriers and attractive intermolecular interaction. For interactions energies stronger than approximately -0.15 eV, the formation of domains of higher density on the surface is observed. The results suggest that coverage can be improved significantly by selecting SMIs with sufficient interaction energy and a low diffusion barrier.

1. J. Li; et. al., *JVST A* **2022**, 40 (6), 062409
2. M. Kalos; et. al., *The Annals of Statistics* **1986**, 22 (4), 1701-1762

8:45am AP+EM+PS+TF-FrM-3 Tuning Surface Reactivity by Small Molecule Modifiers in Area-Selective ALD: Small Molecule Inhibitors (SMI) vs. Small Molecule Promoters (SMP), Andrew Teplyakov, University of Delaware

In area-selective deposition, selectivity of surfaces could be manipulated to either suppress or promote surface reactivity with respect to the target reactants. Using model ALD processes with TiO_2 (TDMAT/water) or Al_2O_3 (TMA/water), the deposition onto semiconductor surfaces modified with small fluorine-containing molecules is analyzed by spectroscopic and microscopic techniques, including depth profiling with ToF-SIMS, supplemented by computational DFT modeling. The fluorinated functional groups are designed for easy spectroscopic characterization to analyze the potential AS-ALD schemes on silicon, as well as on oxide materials, including TiO_2 , MgO , and Al_2O_3 . The initial deposition steps are analyzed by comparing the behavior of modified surfaces with that of pristine substrates, and the distribution of the fluorine and fluorine-containing fragments within the ALD-deposited layers is followed by ToF-SIMS depth profiling once these F-containing functionalities are buried under the overgrown layers. This approach allows for identification of the deposition processes for both small molecule inhibitors (SMIs) and small molecule promoters (SMPs).

9:00am AP+EM+PS+TF-FrM-4 Topographically Selective Atomic Layer Etching of HfO_2 and ZrO_2 Using NbF_5 and TiCl_4 , Boyun Choi, Getasew Zewdie, Hyeyoung Shin, Nari Jeon, Chungnam National University, Republic of Korea

As transistor dimensions continue to shrink, conventional SiO_2 gate dielectrics no longer provide adequate capacitance or leakage control, leading to the widespread adoption of high-k oxides such as HfO_2 and ZrO_2 . Yet, achieving atomic-level patterning of these oxides remains a key challenge for advanced device integration. In this study, we investigate their thermal atomic layer etching (ALE) behaviors using NbF_5 and TiCl_4 as representative halide reactants. A pronounced contrast emerges: HfO_2 undergoes smooth, self-limiting etching cycles, whereas ZrO_2 exhibits surface roughening and substantial chlorine incorporation. Density functional theory calculations clarify this difference by showing that TiCl_4 reacts more aggressively with ZrO_2 surface species, destabilizing the surface and degrading etch quality. Extending ALE to nanohole structures with a diameter of 150 nm and a depth of 2000 nm, we further observe topographically selective removal of HfO_2 . This selectivity is linked to microstructural factors such as crystallinity, indicating that not only chemical reactivity but also structural variations critically influence ALE outcomes. Taken together, these results establish a mechanistic framework for understanding how reactant chemistry and microstructure jointly govern the etching of high-k oxides. Such insights provide practical guidelines for enabling selective integration of HfO_2 and ZrO_2 in next-generation transistors and interconnect architectures, where atomic-scale precision and material specificity are indispensable.

9:15am AP+EM+PS+TF-FrM-5 Area Selective ALD for Future Engineering Challenges, Stacey Bent, Stanford University INVITED

The continued downscaling of electronic device dimensions requires the development of new, precise patterning methods that are compatible with high-volume manufacturing. Atomic level processing, and in particular area

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selective atomic layer deposition (AS-ALD), continues to gain attention as an important method to achieve nanoscale features at the sub-10 nm length scale. It is well known that tuning the surface chemistry of the substrate can be used to either inhibit or enhance ALD nucleation, leading to selective deposition. A key strategy for AS-ALD has been the use of inhibitors which can alter the native surface reactivity to block nucleation in thermal as well as plasma-assisted ALD. This inhibition approach enables good selectivity in AS-ALD of thin films on a variety of substrate materials, including dielectrics and metals, and I will present several inhibitor-based AS-ALD systems. Importantly, the ALD precursor also plays a key role in influencing selectivity. Results show that precursor size can have a significant influence on the ability of inhibitors to prevent ALD nucleation. However, precursor size alone is not the defining metric, and I will share examples that highlight the influence of other precursor effects, such as precursor-inhibitor reactivity and miscibility. Ultimately, developing molecular design rules for both inhibitors and ALD precursors will be critical for applying AS-ALD more widely to future challenges in microelectronics fabrication.

9:45am AP+EM+PS+TF-FrM-7 Controlling ASD of a Multi-Color System: PEDOT ASD between SiN, Si-H, and SiO₂ by Pre-Treatment Adjustment, Jeremy Thelven, Nicholas Carroll, Gregory Parsons, North Carolina State University

Complex 3D device architectures are proposed as the solution to make devices more energy efficient.¹ These architectures require many lithographic steps where the high costs of EUV lithography limits device throughput. As such, there is a need for process augmentation to reduce the EUV burdening. A potential solution is area-selective deposition (ASD), where film deposition occurs on a “growth” surface while it is inhibited on an adjacent “non-growth” surface allowing for bottom-up processing.

While ASD conveys the notion of selective deposition between two surfaces, however, in fabrication more might be exposed. Therefore, it is crucial to look at multiple surfaces, a “multi-color system.” The goal being to have the versatility of depositing the desired material only on the desired location(s). It is then important to know processes that activate or deactivate specific surfaces in a multi-color system.

Poly(3,4-ethylenedioxythiophene)(PEDOT) was deposited by oxidative chemical vapor deposition(oCVD) using 3,4-ethylenedioxythiophene(EDOT) monomer and antimony pentachloride(SbCl₅) as reactants to analyze how various pre-treatment strategies can tune the ASD between Si-H, SiN, and SiO₂ surfaces. As a control, single-material coupons were treated with a diluted hydrofluoric acid(DHF) wet etch prior to PEDOT oCVD. Results showed ~30nm of ASD on SiN and SiO₂ vs. Si-H. Three different pre-treatment strategies were evaluated: 1 cycle of molybdenum hexafluoride(MoF₆)/N₂, 7 cycles of N,Ndimethylaminotrimethylsilane(DMATMS)/N₂, and 7 cycles of DMATMS/N₂ followed by a water soak. Ellipsometer, water contact angle, XPS, and SEM results show that MoF₆ served to simultaneously activate and deactivate the Si-H and SiO₂, respectively, allowing for PEDOT ASD on SiN and Si-H vs. SiO₂. DMATMS exposure deactivated only the SiO₂ showing PEDOT ASD on SiN vs. SiO₂ and Si-H. Including a water soak after the DMATMS activated the Si-H to PEDOT deposition resulting in a deposition configuration of Si-H and SiN vs. SiO₂.

Overall, the concept of tunable selectivity for a three-color system is demonstrated by these results. These pre-treatment strategies providing a better understanding into controlling selectivity.

1.Datta, S.; Chakraborty, W.; Radosavljevic, M. Toward. *Science* **2022**, 378 (6621), 733–740.

10:00am AP+EM+PS+TF-FrM-8 Kinetics Model for Selective Thermal Etching of Si_{1-x}Ge_x in F₂/Ar, Yi Chen, Daniel Cho, University of California, Los Angeles; John Hoang, Nicholas Altieri, Ji Zhu, Samantha Tan, Lam Research Corporation; Jane Chang, University of California, Los Angeles

The selective etching of Si_{1-x}Ge_x over Si enables the fabrication of the gate-all-around field-effect transistors. Thermal etching of Si/Si_{1-x}Ge_x at near room temperature features high selectivity, exhibiting a non-linear relationship between etch rate and Ge% (Fig. 1(a)). There are no reported reaction mechanisms explaining this unique Ge%-dependent phenomenon.

In this work, thin films of Si_{1-x}Ge_x of varying Ge content (Ge% = 0 to 1) were etched thermally by molecular F₂ gas at near room temperature under different F₂ partial pressures (0.5 to 10 mTorr) in Ar. The etch rates were quantified by ellipsometry measurement and the relationship between etch rate and Ge% resembled those shown in Fig. 1(a). Reported Si_{1-x}Ge_x etch

selectivity ranges from 100 to 1000 and the unpublished maximum etch selectivity is from 200 to 250. The unpublished experimental data is being reviewed for public release and will be presented at the conference. A kinetics model was established in this work to elucidate the reaction pathways in thermal etching of Si_{1-x}Ge_x by F₂, considering reactions between atomic fluorine and various surface species and the interplay between reaction products involving Si and Ge. The model result (Fig. 1(b)) yielded the unique volcano-shaped relationship between etch rate and Ge%, validating the reactions considered in the model captured the main kinetics during F₂ etching of Si_{1-x}Ge_x.

10:30am AP+EM+PS+TF-FrM-10 Area-Selective Deposition by Surface Engineering for Applications in Nanoelectronics: Enablement of 2d and 3d Device Scaling and Self-Alignment, Silvia Armini, IMEC Belgium INVITED

At advanced nodes targeting 10 nm feature size and below, lithography starts to dominate costs (EUV, multiple mask passes per layer, pattern placement error,...). Complementary techniques and materials are needed to continue 2D scaling and extend the Moore’s law. On the other hand, 2D scaling is reaching its limitations driving the transition to 3D and vertical integration schemes (such as 3DNAND, 3DDRAM, CFET...), which result in higher devices density per unit area and lower production cost. Area-selective atomic layer deposition (AS-ALD) is rapidly gaining interest because of its potential application in self-aligned fabrication schemes for next-generation nanoelectronics. In addition, ASD allows coping with high aspect ratio and complex 3D architectures. The strong sensitivity of ALD to surface chemistry and its self-limiting nature are particularly appealing for ASD.

In this talk I will illustrate a variety of ASD processes and applications spanning from nano-interconnects, logic and memories to patterning.

11:00am AP+EM+PS+TF-FrM-12 MO-Mo? Oh No! The Problem of Carbon in Metalorganic Molybdenum Deposition, Kyle Blakeney, David Mandia, Matthew Griffiths, Jeong-Seok Na, Raihan Tarafdar, Jeremie Dalton, Lam Research Corporation

Molybdenum (Mo) halides and oxyhalides comprise the sole class of precursors that can deposit Mo metal films by ALD/CVD with sufficient purity for applications in advanced microelectronic devices. Unfortunately, solid, low vapor pressure Mo chloride precursors have challenges in flux stability and low vapor pressure. Metalorganic (MO) precursors are commonly used to address some of these challenges and are useful alternatives to halides for many non-metal films such as SiO₂, SiN, TiN, Al₂O₃, etc. Despite much effort, MO-precursors have not met the performance of chloride precursors for depositing pure Mo.

This presentation will summarize key findings of MO-Mo process development by the Lam ALD/CVD Metals concept and feasibility (C&F) group. Included will be typical precursor tests using coupon process modules, 300mm C&F chambers, fundamental mechanistic investigations of Mo surface reactivity, and novel deposition pathways such as conversion-reduction (Figure 1) and alloy formation (Figure 2).

11:15am AP+EM+PS+TF-FrM-13 The Effects of Process Chemistry on Blocking Chemisorption in ALD: Thin Film Precursor, Co-Reactant and Co-Adsorbate, Jay Swarup, James Jensen, Jeffrey Gao, James Engstrom, Cornell University

Achieving area selective deposition requires preventing growth on the non-growth surface (NGS), which often involves the use of molecules to block growth on those surfaces. Careful choice of the ALD process chemistry, thin film precursor and co-reactant, as well as the blocking molecule and how it is administered, is important. We report here a systematic examination of the effects of the precursor, co-reactant and co-adsorbate/blocking molecule on preventing growth of Al₂O₃ on SiO₂. We also consider the effects of temperature, and the dosing sequence employed for the blocking species. Concerning the precursor we compare trimethylaluminum (TMA) to a non-pyrolytic precursor containing only Al-N bonds and no Al-C bonds, i.e., BDMADA-Al [1]. For co-reactants we compare H₂O to t-BuOH. Finally, we consider two blocking species: octadecyl trichlorosilane (ODTS), and dimethylamine trimethylsilane (DMATMS). In this study we employ a quartz-crystal microbalance to monitor ALD *in situ* and in real-time, and the deposited thin films have been characterized *ex situ* using X-ray photoelectron spectroscopy, and a variety of techniques. Concerning the “pristine” processes, i.e., ALD in the absence of a blocking molecule, the properties of the films (density, C incorporation, stoichiometry, growth rates) are comparable using either BDMADA-Al or TMA as the precursor under similar reaction conditions. These species also react similarly with H₂O and t-BuOH as the co-reactant, where steady growth with the latter is

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only observed at sufficiently high temperatures. Concerning blocking growth, we have observed a number of identifiable trends. First, employing the same ALD process chemistry, ODTs produces better blocking in comparison to DMATMS in cases involving a single dose of the blocking molecule. When comparing TMA and BDMADA-Al, we observe that for both blocking molecules that the latter is more efficiently blocked. These two observations demonstrate the importance of molecular size as the larger BDMADA-Al is more efficiently blocked, and the larger ODTs is better for preventing growth. Temperature has a definitive effect on the efficiency of preventing growth where we find that higher temperatures lead to more effective blocking of growth. The dosing sequence employed for the blocking species also plays an important role. Repetitive dosing of DMATMS in an "ABC" process provides superior blocking with respect to a single pre-exposure, and these results exceed those produced by ODTs.

[1] J. V. Swarup, H.-R. Chuang, J. T. Jensen, J. Gao, A. L. You and J. R. Engstrom, *J. Vac. Sci. Technol. A* **43**, 022404 (2025).

MEMS and NEMS

Room 205 ABCD W - Session MN1-FrM

Integration and Multiphysics

Moderators: Philip Feng, University of Florida, Jaesung Lee, University of Central Florida

8:15am MN1-FrM-1 MEMS-Enabled Photonic Integrated Circuits, *Marcel Pruessner, Todd Stievater, Nathan Tyndall, Steven Lipkowitz, Jacob Bouchard, Kyle Walsh*, US Naval Research Laboratory **INVITED**

Photonic integrated circuits (PICs) are maturing and are rapidly finding application beyond telecommunications, including for sensing and quantum photonics. Many of these applications require PICs that operate at non-telecom wavelengths (e.g. in the visible wavelength spectrum) as well as PICs with new functionality enabled by micro-electro-mechanical systems (MEMS). In collaboration with AIM Photonics, we have developed a foundry PIC platform optimized for visible wavelengths focusing on reducing propagation loss and designing efficient PIC components¹. At the same time, we have also investigated novel functionality in PICs enabled by MEMS. This presentation will focus on "MEMS-enabled photonic integrated circuits," their fabrication and incorporation in PIC foundries, and novel functionality enabled by combining PICs with MEMS. A variety of MEMS-enabled PIC devices will be discussed including MEMS-tunable phase shifters² and optical cavities³, optical forces in cavity optomechanical systems⁴, mode conversion using MEMS perturbation⁵ and phase matching⁶, and broadband waveguide thermal emitters⁷ enabled by MEMS bulk micromachining techniques⁸.

¹ <https://doi.org/10.1117/12.3012847>

<https://doi.org/10.1364/OE.504195>

and

² <https://doi.org/10.1364/OE.24.013917>

and

<https://doi.org/10.1364/OSAC.419410>

³ <https://doi.org/10.1063/1.2883874>

and

<https://doi.org/10.1364/OL.44.003346>

⁴ <https://doi.org/10.1364/OE.19.021904>

and

<https://doi.org/10.1103/PhysRevLett.108.223904>

and <https://doi.org/10.1021/acspolymers.8b00452>

⁵ <https://doi.org/10.1364/OE.488624>

⁶ <https://doi.org/10.1364/OL.474806>

⁷ <https://doi.org/10.1038/s41467-024-48772-6>

⁸ <https://doi.org/10.1063/5.0252536>

8:45am MN1-FrM-3 Crack-Free Growth and Improved Saturation Magnetization of NiCuZn Ferrite Films by Combining Sputtering and Sol-Gel Methods, *Sushma Kotru, Roni Paul*, The University of Alabama

NiCuZn ferrite films exhibit diverse applications in high-frequency wearable electronics, inductors, electromagnetic interference filters, and antennas due to their high resistivity, low eddy current losses, high permeability, and significant saturation magnetization. The demand for depositing thicker films, particularly for power electronics, is increasing. Conventional deposition methods such as electrodeposition and screen printing are limited for integrating NiCuZn ferrite films on Si substrates. In this study, we developed a hybrid approach combining sputtering and sol-gel deposition to prepare films with thicknesses ranging from ~240 nm to 1.8 μ m. A thin sputter-deposited NiCuZn ferrite layer served as a seed layer (SL) to enable crack-free thick film growth and to improve magnetic performance upon

annealing. Structural analysis was performed using X-ray diffraction (XRD) and field emission scanning electron microscopy (FESEM), while magnetic properties were measured using a vibrating sample magnetometer (VSM). The maximum saturation magnetization of **310 emu/cm³** was achieved for a 240 nm-thick film annealed at 800 °C. With increasing thickness, the saturation magnetization decreased slightly, from **310 emu/cm³ (240 nm)** to **280 emu/cm³ (1.8 μ m)**, yet remained higher than previously reported values. The sputtered SL effectively suppressed crack formation during post-annealing above 600 °C and promoted more homogeneous film growth compared to sputtering or sol-gel methods alone. These results demonstrate that the hybrid deposition approach enables high-quality thick ferrite films suitable for **miniaturized inductors and power electronics applications**.

9:00am MN1-FrM-4 Integration of Metal Microsystems for Gas Sensing, *David Hayes, Henry Davis, Jeremy Cook, Jordan Grow, James Harkness, Isa Kohls, Richard Vanfleet, Brian Jensen, Nathan Crane, Robert Davis*, Brigham Young University

Microfluidic devices are a versatile and powerful class of analytical and production tools with applications spanning medical diagnostics, drug development, food safety, and chemical production among others. A subset of microfluidic devices are microscale gas chromatography columns, which offer high speed chemical separations and system miniaturization. Hermetic sealing of micro chromatography channels and interfaces are challenges that have inspired a wide range of solutions. We will describe our developments in interfacing to both 3D printed metal microcolumns and machined metal microfluidic structures using pressure-controlled microbrazing.

9:15am MN1-FrM-5 Nanomechanical Resonances of Graphene Membranes Integrated on LiNbO₃-on-Insulator Chips, *Nawara Tanzee Minim, S M Enamul Hoque Yousuf, Yunong Wang, Philip Feng*, University of Florida

We present the integration and dynamic characterization of graphene membrane suspended over engineered dual-depth trench structures on a lithium niobate (LiNbO₃) -on-insulator (LNOI) substrate for probing out-of-plane flexural resonances. The substrate comprises a 600 nm LiNbO₃ film atop 4.7 μ m thermally grown SiO₂ and a bulk silicon handle wafer, enabling piezoelectric compatibility and optical transparency. The device features rectangular trenches (12 μ m \times 70 μ m, 300 nm deep) patterned via lithography and etching, with centrally embedded circular cavities (12 μ m diameter, 1.5 μ m deep) fabricated with focused ion beam (FIB) milling after carbon coating to introduce localized geometric perturbation. The structure is actuated using a broadband piezoelectric shaker coupled to the chip, inducing flexural motion across the suspended regions, and resonance modes are detected using laser interferometry. This architecture enables the comparative analysis of flexural eigenmodes in shallow vs. deep trench regions, highlighting the effect of local stiffness gradients, boundary conditions, and air damping. The use of LiNbO₃ as the underlying substrate introduces unique opportunities for acousto-optic and electro-mechanical coupling due to its strong piezoelectric and nonlinear optical properties. By leveraging the anisotropic elastic constants of LiNbO₃ and the high mechanical compliance of graphene, this platform facilitates the study of mode hybridization (coupling between localized modes of the deep circular trench and delocalized modes of the surrounding shallow trench, mediated by the continuous graphene membrane) and strain-tunable resonances through in-plan actuation of piezoelectric response in nanoscale membranes. Furthermore, the dual-depth trench geometry introduces spatially varying boundary stiffness, enabling mode localization and geometric control over frequency splitting. These architectures are compatible with SAW devices and LiNbO₃ photonic circuits, offering a pathway to integrated NEMS-photonic systems for sensing, transduction, and filtering applications.

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MEMS and NEMS

Room 205 ABCD W - Session MN2-FrM

2D and NEMS

Moderators: Marcel Pruessner, Naval Research Laboratory, Yanan Wang, University of Nebraska-Lincoln

10:30am MN2-FrM-10 Optomechanical Resonant Pixels with Metasurface and Phonon Engineering for Uncooled Infrared (IR) Detection, *Philip Feng*, University of Florida INVITED

In this invited talk, we will present experimental demonstration and theoretical analysis of ultrathin trampoline-shaped nano-optomechanical resonators with strong potential for uncooled ultrasensitive infrared (IR) detection. We analyze and design trampoline resonators with high optothermal-mechanical transduction responsivities, strong thermal isolation, and multiple high-Q nanomechanical resonances that are suitable for low-noise optical transduction. We explore optimized designs by analyzing and understanding the multiple engineering tradeoffs involving both properties of the constitutive materials and parameters of geometric design and fabrication processes. We demonstrate resonant pixels enabled by various ultrathin trampoline designs, made of both silicon nitride (SiN) and atomically thin 2D materials. 05

11:00am MN2-FrM-12 Controlled Thinning of Semiconductor Membranes Using Low-Fluence Laser Pulses at MHz Frequencies, *Shahadat Hossain, Renato Camata*, University of Alabama at Birmingham

Free-standing ultrathin membranes of two-dimensional (2D) materials exhibit distinct mechanical, electronic, and optical properties compared to their bulk counterparts, making them promising for novel nanoscale devices. Controlled thinning of these membranes is an effective approach for customizing them to nanoelectromechanical systems (NEMS). In this study, we show that low-fluence laser pulses at MHz frequencies allow precise thinning of molybdenum disulfide (MoS_2) membranes.

MoS_2 flakes exfoliated from bulk crystals are freely suspended over 5- μm diameter circular wells of 285-nm depth, etched on silicon wafers. The thinning process is monitored using Fabry-Perot interferometry (633-nm laser), which allows measurement of the resonance frequency and Q-factor of the membranes. The fluence of the MHz frequency-modulated thinning laser (405 nm) ranged from 10 $\mu\text{J}/\text{cm}^2$ to 30 $\mu\text{J}/\text{cm}^2$, which is significantly lower than that of single-pulse laser irradiation techniques typically used in 2D material thinning.

We employ existing models from thin plate elasticity theory and tension-dominated membrane theory to predict the resonance frequencies of plate-like and membrane-like resonators. This provides insight into the frequency scaling of 2D membranes as a function of the number of atomic layers. We validate the models by experimental resonance frequency measurements. This combined experimental-theoretical approach enables accurate layer differentiation and Q-factor extraction, permitting basic studies of the nanomechanical properties of our resonators. Our experimental system integrates charge-coupled device imaging with resonance frequency analysis, allowing layer quantification. In a typical experiment, the resonance frequency of a plate-like resonator initially measures 47 MHz but suddenly drops to 25 MHz. The resonance frequency then increases monotonically with time until it reaches 51 MHz as the Q-factor varies from 5.5 to 71. The abrupt frequency drop corresponds to a sudden change in the number of layers from 130 to six. The six-layer membrane is then gradually thinned until eventually reaching monolayer thickness after multiple hours of irradiation. These findings reveal a variation in mechanical stiffness consistent with a shift between plate and membrane regimes. In the plate regime, the abrupt resonance change is likely driven by laser-induced superheating, whereas in the membrane regime, material removal via sublimation results in a gradual frequency evolution. This MHz variant of laser thinning allows precise control over MoS_2 layer thickness down to the monolayer limit and may contribute to advancing NEMS fabrication in next-generation devices.

11:15am MN2-FrM-13 Electrical Tunability of AlN Nanoelectromechanical Resonators, *Sariha Azad, Tahmid Kaisar, Timothy Caplice*, University of Florida; *Philip X.-L. Feng*, University of Florida, Gainesville

Electrical tunability in piezoelectric resonators is essential for applications requiring reconfigurable frequency control, including radio-frequency (RF) communications, sensing, and analog computing. Among available piezoelectric materials, aluminum nitride (AlN) stands out due to its CMOS compatibility, low dielectric loss, and high acoustic velocity, making it a strong candidate for integration into tunable MEMS platforms. Prior work

has demonstrated voltage-induced frequency modulation in AlN resonators through piezoelectric field coupling, and strain-mediated deformation. Contour-mode AlN resonators with DC-bias-induced stress have shown frequency tuning ranges of 10–50 kHz under 20–80 V, with performance constrained by anchor loss and *Q* degradation[1]. Laterally vibrating AlN resonators have demonstrated similar shifts, with tuning rates of 100–300 ppm achieved using field-induced strain, though these effects become increasingly nonlinear at higher voltages[2]. In AlN, the modest electromechanical coupling limits tuning efficiency, with practical frequency shifts typically below 100 ppm under DC biases approaching the dielectric breakdown threshold, ranging from 40 to 120 V for 100–150 nm thick films depending on quality and deposition conditions. In this work, we show a comparative study of out-of-plane flexural mode AlN resonators. Two device architectures have been fabricated, the first type is a buckled membrane, comprising a compressive-stress 120 nm-thick AlN layer on top of a tensile low- or high-stress SiN base (50–100 nm). The second type is a non-buckled membrane, formed without SiN to create a flat, mechanically neutral structure. Both types incorporate a symmetric Pt/AlN/Pt stack with 25–75 nm-thick electrodes. The resonators have been characterized with applied DC polarization voltage swept between 0 and 5 V to analyze the voltage responsivity of resonance frequency. The experimental results show that buckled AlN membrane NEMS resonators exhibit negative voltage responsivities ranging from -3.58 to -6.33 kHz/V over resonance frequencies of 5–9.4 MHz. On the other hand, the non-buckled membranes demonstrate a positive voltage responsivity of 2.83 kHz/V over the resonant frequency at 1.78 MHz. Across both device types, frequency shifts of \sim 20 kHz have been achieved under low tuning voltages (up to \pm 5V), without reaching nonlinearity.

[1]G. Piazza et.al. "Piezoelectric Aluminum Nitride Vibrating Contour-Mode MEMS Resonators," *J. Microelectromechanical Syst.*, vol. 15, no. 6, pp. 1406–1418, Dec. 2006

[2]R. Tabrizian and F. Ayazi, "Laterally-excited silicon bulk acoustic resonators with sidewall AlN," pp. 1520–1523, Jun. 2011

11:30am MN2-FrM-14 Probing Velocity Limits of Resonant SiC Electromechanical Cantilevers, *Aswathi Madhu, Philip Feng*, University of Florida, Gainesville

In inertial sensing applications harnessing resonant micro/nanoelectromechanical systems (MEMS/NEMS), maximizing velocity while ensuring structural integrity poses important challenges in design, fabrication, and characterization of the resonant transducers. This study aims to explore the limits of velocity of such devices built on a SiC thin film platform to exploit the excellent elastic properties of SiC including its high fracture limit. We report on analytical modelling and computer simulations, combined with experimental investigation of the velocity limits of singly-clamped SiC NEMS cantilevers lithographically patterned on a 500 nm-thick 3C-SiC film on top of 500 nm SiO_2 insulating layer on Si substrate. The specific goal is to determine the highest achievable velocity by enhancing displacement amplitude without exceeding the material's fracture limit.

In this study, first theoretical analysis is done to explore the trade-off between maximum displacement amplitude and resonant frequency, and the results are validated using finite element simulations in COMSOL Multiphysics™. The fundamental resonant frequencies of SiC cantilevers, with dimensions $8 \mu\text{m} \times 200 \text{ nm} \times 500 \text{ nm}$, are 3.25 MHz for in-plane and 6.32 MHz for out-of-plane motion. The preliminary results from initial measurements show a linear dependency between peak amplitude and applied actuation gate voltage, indicating the potential for scalable performance. These results provide insight into the dynamic range limitations MEMS structures operating near their mechanical limits.

To further study the material-dependent performance, the results are also compared with experimental data from 4H-SiC cantilevers fabricated using bulk micromachining and focused ion beam (FIB) milling. The comparison shows how the yield stress and fracture limit of 3C-SiC and 4H-SiC affect the estimation of the maximum achievable velocity. This work offers valuable guidance for designing future high-performance SiC inertial devices that balance velocity and structural robustness.

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Plasma Science and Technology

Room 201 ABCD W - Session PS1-FrM

Plasma Processes for Coatings and Thin Films

Moderators: Erwin Kessels, Eindhoven University of Technology, the Netherlands, Scott Walton, Naval Research Laboratory

8:15am PS1-FrM-1 First-Principles Study on Film Stress Mechanisms of

Amorphous Carbon: The Role of Bond Hybridization, Yusuke Ando, Nagoya University, Japan; Hu Li, Jianping Zhao, Tokyo Electron America, Inc.; Masaaki Matsukuma, Tokyo Electron Technology Solutions Ltd., Japan; Kenji Ishikawa, Nagoya University, Japan; Peter Venzek, Tokyo Electron America, Inc.

Amorphous carbon (a-C) is a highly versatile material with tunable properties, including hardness, electrical conductivity and optical transparency, which can be tailored through control over its fraction of hybridized bonds and its content of hydrogen. Among a-C materials, hydrogenated amorphous carbon (a-C:H) has been widely utilized as an etching hard mask in semiconductor fabrication processes due to its superior resistance to fluorinated gas plasma and its facile removal via oxygen plasma treatment.

With the continuous advancement of semiconductor fabrication technology, particularly in 3D flash memory devices, increasing number of stacking layers necessitates the development of high-aspect ratio etching techniques. To meet this requirements, a-C hard masks must exhibit enhanced etch resistance to withstand prolonged plasma exposure while maintaining controlled residual stress to prevent delamination and wafer bending. a-C films are typically deposited via plasma enhanced chemical vapor deposition (PECVD) with hydrocarbon-based plasma, and experimental observation shows that bias voltages promoted an increased sp^3 -C fraction and higher film density, thereby improving etch resistance. However, this increase in density is also accompanied by elevated residual stress, presenting a critical trade-off between etch resistance and mechanical stability. A fundamental understanding of stress generation and relaxation mechanisms is essential for optimizing a-C hard masks for advanced semiconductor applications.

While experimental investigations have provided valuable insights into stress behavior, the underlying structural factors governing stress generation remain insufficiently understood from a theoretical perspective.

In this study, as a first step, we have systematically analyzed influence of hybridized bonding configurations on residual stress of carbon films. By employing first-principles calculation, we modeled and evaluated various defective diamond-like carbon structures with identical densities, allowing us to isolate and compare the effects of geometrical properties other than density on stress generations. Our results indicate that, to varying degrees, a lower sp^3 -C fraction and shorter mean bond length contribute to increased compressive stress. These conclusions are tested on hydrogenated systems as well. Based on these findings, we propose a mechanism of stress-relief that can guide process optimization in fabricating high-performance a-C hard masks.

8:45am PS1-FrM-3 AVS John Thornton Award Talk: Creating a Dream Team: Thin Films, Plasma Chemistry, Holistic Approaches, and Non-Traditional Pathways, *Ellen R. Fisher*, University of New Mexico **INVITED**

Today, plasma processing is a well-known and powerful technique to modify the surface of materials, and create new materials, especially thin films. John A. Thornton was a pioneer in developing plasma processing of thin films. He was also a dedicated educator, having mentored numerous students. In this presentation, we present a holistic approach to plasma processing of thin films, linking the gas phase, the gas-surface interface, and relevant materials characterization. Often, the ultimate goal of these plasma-modification studies is to explore various pathways to tune and tailor the surface of a material, while maintaining bulk properties and material integrity for a desired application. Specific systems discussed will include semiconductor materials, membrane coatings, and metal oxides. Similarly, the development of the next generation of inventors and discoverers requires alternative approaches and new tools. To that end, the use of the science of team science (SciTS) tools and approaches provides alternative pathways to tune and tailor the environment necessary for creating effective teams. This can be realized by being the Archintor™ of a team's networks. Social network analysis (SNA) allows teams to discover how team members connect, including through learning, collaboration, and leadership networks. Fundamental SNA concepts and Archintor™ examples will be presented from real science and engineering teams, providing unique insight into the development and deployment of productive teams.

Collectively, these studies exemplify the comprehensive approach to solving challenges in the plasma community, a tribute to the legacy of John A. Thornton.

Plasma Science and Technology

Room 201 ABCD W - Session PS2-FrM

Plasma in EUV Scanner Technology

Moderators: Erwin Kessels, Eindhoven University of Technology, the Netherlands, Scott Walton, Naval Research Laboratory

9:15am PS2-FrM-5 Measurement of Cold Spit Tin Particle Trajectories in a

Hydrogen Plasma, Jaime Robertson, University of Illinois Urbana-Champaign; Raoul de Rooij, Andrei Yakunin, Victoria Voronina, ASML, Netherlands; David Ruzic, University of Illinois at Urbana-Champaign

The extended exposure of tin (Sn) particles to hydrogen radicals has demonstrated the ejection of sub-micron sized particles from a surface covered in micron sized Sn droplets. This work experimentally investigates the three mechanisms, spitting, etching, and particle lift off, behind the mass transport of Sn, focusing on measuring the size, velocity, and directionality of the particles and the frequency of particle migration. Using a quartz crystal microbalance (QCM), measurements of the mass flux from a surface covered in micron sized droplets of Sn were performed with plasma radical densities similar to and greater than in the scanner. While etching rates of Sn by hydrogen were measured similar to other reports, significant, acute decreases in the mass were also observed throughout the duration of testing associated with either spitting or particle lift off. Further imagery, on a SEM, of the surface before and after exposure to hydrogen plasma confirmed a change in surface morphology. Larger Sn droplets appeared to have cratering along the surface, believed to be the result of cold spitting Sn. This is due to buildup of hydrogen beneath the surface forming a pressure gradient within the Sn particles leading to surface fracturing and particle ejection. An additional test was designed with a silicon wafer placed above the surface of the Sn droplets that captured cold spit particles. An SEM was then used to measure the size and position, allowing for the interpretation of mass and directionality of Sn leaving the surface. Velocity of spit particles is being determined by measuring the deflection of the cold spit particles through an electric field, having a known charge buildup on the surface. Based on the distance traveled before reaching the chamber walls, the incident velocity of particles is calculated. Measurement of liquid spit particles is underway using aerogel, with diagnostic techniques like ballistics work. The liquid particles are captured in the aerogel before using a uCT to generate a 3D rendering of the surface. Based on the cratering characteristics such as depth and width found at the surface of the aerogel, velocity of each particle is calculated. Additionally, this work is being performed on various surface materials to determine how the preferential recombination of hydrogen radicals with various surface materials impacts the rate of degradation of the Sn. Initial tests revealed a reduction in mass loss rates for gold when compared to aluminum. This is likely due to the greater recombination coefficient of gold when compared to aluminum.

9:30am PS2-FrM-6 Benefits and Challenges of Plasma in EUV Lithography Scanners, *Seth Brussard*, ASML **INVITED**

Extreme Ultraviolet (EUV) lithography is a key enabling technology in semiconductor manufacturing, facilitating the production of the most advanced microchips with smaller feature sizes and greater complexity. Central to this technology is the generation of EUV light through the interaction of plasma and lasers. This presentation explores the critical role of these and other types of plasma present in EUV lithography scanners, highlighting innovations, challenges, and future research directions. The challenges include consistently generating EUV light via laser-produced tin plasma, preventing carbon deposition on optics, and minimizing defects in produced circuits. Addressing these challenges involves multidisciplinary research in plasma-materials interaction, measurements (plasma diagnostics) and control. The ongoing research is aimed at further improving the efficiency and capabilities of EUV lithography systems, driving the development of more advanced and powerful semiconductor devices.

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10:00am PS2-FrM-8 Stannane Decomposition and Sticking Coefficient in Extreme Ultraviolet Lithography Environments, *Emily Greene, Nathan Barlett, Jameson Crouse, Eric Mushrush, Alex Shapiro, University of Illinois; Niels Braaksma, ASML; David Ruzic, University of Illinois*

In extreme ultraviolet (EUV) lithography environments, large quantities of tin are evaporated, leading to the deposition of tin on various chamber surfaces, including collector mirrors. Hydrogen plasma etching is used to remove these deposits, but this process also produces stannane (SnH_4). Since stannane exists in a gaseous state under operational conditions, it can be evacuated from the chamber via a vacuum pump. However, stannane is unstable and often decomposes, causing the redeposition of tin on chamber surfaces. This work aims to experimentally study the decomposition of stannane on EUV-relevant surfaces as a function of temperature. Stannane is synthesized in liquid form through the reaction of lithium aluminum hydride with tin tetrachloride. The liquid stannane is then released into a vacuum chamber containing a temperature-controlled stage equipped with a quartz crystal microbalance (QCM). This setup enables the quantitative determination of the stannane sticking coefficient as a function of surface material and temperature. To analyze surface morphology after stannane exposure, scanning electron microscopy (SEM) is used to image the exposed samples. Additionally, this study seeks to determine the vapor pressure of stannane gas by measuring the pressure of a sealed liquid stannane vessel as it is submerged in chemical slurries of varying temperatures. By improving the understanding of stannane decomposition, this investigation aims to enhance the maintenance and efficiency of EUV lithographic systems.

Plasma Science and Technology Room 201 ABCD W - Session PS3+TF-FrM

Plasmas and PVD

Moderators: *Erwin Kessels, Eindhoven University of Technology, the Netherlands, Scott Walton, Naval Research Laboratory*

10:45am PS3+TF-FrM-11 Self-Regulating Electron Temperature in High-Power Impulse Magnetron Sputtering Discharges and Its Effect on the Metal Ion Escape, *Kateryna Barynova, University of Iceland; Nils Brenning, KTH Royal Institute of Technology, Sweden; Swetha Suresh Babu, University of Iceland; Joel Fischer, Daniel Lundin, Linköping University, Sweden; Michael A. Raadu, KTH Royal Institute of Technology, Sweden; Jon Tomas Gudmundsson, University of Iceland; Martin Rudolph, Leibniz Institute of Surface Engineering (IOM), Germany*

We analyze how the primary electron temperature in high-power impulse magnetron sputtering (HiPIMS) depends on the sputtered target. The analysis is based on the experimental discharge data for 7 different target materials, which were modeled using the Ionization Region Model (IRM), a semi-empirical global model for HiPIMS discharges. We observe that the electron heating and collisional cooling processes stabilize after some time into the pulse (20 - 40 μs) reaching a steady state and leading to an almost constant electron temperature; the initial transients in the electron temperature are caused by only small discrepancies in these terms. The underlying mechanism that causes this self-regulation are the rate coefficients for electron impact ionization, which increase monotonically with electron temperature. This leads to a self-balancing mechanism in which an increase in the electron temperature increases the collisional losses of the kinetic energy of electrons because of the higher collisions rate with species in the ionization region. The opposite is true for the decreasing electron temperature. In addition, the steady-state electron temperature depends on the target material and inversely correlates with the self-sputter yield of the target. The species composition in the ionization region shifts from being composed of argon species to target species; and argon has a much higher ionization potential compared to all the studied target materials, so both the ionization and cooling rates substantially increase only at the higher electron temperatures compared to the ionization region composed of target species. This explains the experimentally observed low electron temperature in high self-sputter yield target discharges. Since the mean free path of the sputtered atoms, before being ionized, depends on the electron temperature, we can explain with the IRM results why in metal-rich discharges ionization occurs further away from the target, leading to higher chances of ionized sputtered species to escape to the substrate because the electric field is weaker there. The dominating species in the ionization region, which define the main collisional loss process and the electron temperature, are not identified only by the sputter yield of the target, but by a more complex recycling loop

of argon and target species in the ionization region and the rarefaction of argon in front of the target.

11:00am PS3+TF-FrM-12 Comparison of Particle Size and Morphology of Graphene-Like Carbon Grown with and Without Substrate in Atmospheric Pressure Microwave Plasma, *Parker Hays, Dhruval Patel, Dren Qerimi, University of Illinois at Urbana-Champaign; Michael Stowell, Lyten; David Ruzic, University of Illinois at Urbana-Champaign*

Graphene-like carbon materials were synthesized on a substrate as well as free-standing using an atmospheric pressure microwave plasma (APP) system. Argon and nitrogen were utilized as carrier gases and methane as the carbon precursor. This study compares the morphological and structural differences of the materials formed under each growth condition.

Free-standing carbon material was collected from the APP using quickly inserted TEM grids at various distances from the microwave insertion point. Carbon was also grown on a temperature-controlled aluminum surface using the same APP system by placement of the aluminum substrate at different distances from the microwave insertion point.

Scanning Electron Microscopy (SEM) images were used to find the particle diameter distributions for each case, showing for both the free-standing carbon and the carbon grown on aluminum that mean primary particle size increased as a function of increased methane flow rate and distance from the microwave insertion point, and decreased with an increase in microwave forward power. Furthermore, the particle diameter distributions in the free-standing case showed minimal change past the bulk plasma boundary, meaning most of the free-standing graphene growth occurred in the bulk plasma and at the boundary.

Raman spectroscopy was employed to evaluate the structural order and defect density of the carbon materials. The free-standing material exhibited a higher I_D/I_G intensity ratio, suggesting increased disorder and a more amorphous structure compared to substrate-grown samples, which displayed sharper G and 2D peaks indicative of more crystalline graphene. These findings suggest that while substrate-free growth at atmospheric pressure offers a more scalable and simple synthesis route, growth on substrate may yield higher structural quality in the resulting carbon materials.

11:15am PS3+TF-FrM-13 Mass Spectrometric Study of Ar-Diluted Ammonia Borane Plasma for H-Bn 2d Film Formation, *Takeshi Kitajima, Reiji Kawasaki, Toshiki Nakano, National Defense Academy, Japan*

Ammonia borane is used as a relatively safe source of BN for the rapid synthesis of h-BN, an important insulating material¹ in the field of two-dimensional electronics². Ammonia borane plasma attracts attention when aiming at high-speed film formation, and analysis of active species in the plasma is necessary. In this study, active species generated from ammonia borane powder irradiated with Ar plasma were analyzed by mass spectrometry. Parallel plate type 100MHz driven capacitively coupled plasma generated in a high vacuum chamber is used. After placing 0.1 g of ammonia borane (BH_3NH_3) powder on the RF electrode and evacuating, a 10 W glow discharge was formed with an Ar gas flow rate of 30 sccm. A copper sample heated to 800°C was placed downstream, and when BN radicals were supplied at a pressure of 800 Pa, an h-BN atomic film was formed over 30 minutes as shown in the SEM image and Raman spectrum of Fig. 1(a,b). Radical analysis in the downstream was performed with a mass spectrometer at a pressure of 30 Pa. Figure 1(c) shows the difference in the mass spectrum when the plasma is turned on and off. $\text{BNH}_5(30)$ is increased by plasma lighting. $\text{O}_2(32)$ is produced by plasma irradiation to the chamber wall. Radicals generated from ammonia borane raw material leading to formation of h-BN atomic film are presumed to be BNH_5 generated by decomposition of BH_3NH_3 . Dangling bonds of BNH_5 are thought to generate chemical reaction activity on the substrate. Time dependence of mass signal is shown in Fig. 1(d). The relation of OH and BNH_5 is shown in Fig. 1(e). OH is linearly related to BNH_5 amount and presumed to be the major source of production. Contrarily, O signal is nonlinear to the BNH_5 signal as shown in Fig. 1(f). The consequence of the oxygen related radical exposure will be summarised in the presentation. 1. K.H. Lee, et.al. Nano Letters 12, 714 (2012). 2. L. Song, et.al. Nano Letters 10, 3209 (2010).

11:30am PS3+TF-FrM-14 Automated Deposition Chamber for Functional Dielectrics: Development and Implementation, *Stanislav Udoeneko, Ian Mercer, Susan Trolier-McKinstry, Jon-Paul Maria, Darren Pagan, The Pennsylvania State University*
S. A. Udoeneko¹, I. Mercer¹, S. Trolier-McKinstry¹, J. P. Maria¹ and D. C. Pagan¹

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Automated Deposition Chamber for Functional Dielectrics: Development and Implementation

The dielectric and piezoelectric properties of ferroelectrics make them essential in the fabrication of multilayer ceramic capacitors (MLCCs) and various transducers (such as those used in medical ultrasound, naval sonar, and consumer electronics) [1–3]. Modern devices demand high-quality, reproducible material synthesis, especially in the fabrication of complex multilayer structures where the thickness of individual layers critically affects device performance. In this context, automating the material synthesis process becomes highly beneficial, as it reduces human error, increases repeatability, and improves overall efficiency. However, there is currently a disconnect between university-based materials design and synthesis which is primarily an analog process and large-scale automated manufacturing found in industry.

This project focuses on developing a framework for digitizing and automating functional ferroelectric synthesis in a university setting. Our demonstration case is the sputtering of ferroelectric films within a vacuum deposition chamber. In the initial stage, a data acquisition and controller system was designed and installed on deposition chamber automated for doped AlN. Next, LabVIEW-based software was developed to acquire data from all electronic units of the chamber—including sputter cathode power supplies, mass flow controllers, temperature controllers, and vacuum pumps. Following software development, control functionality was implemented, enabling the system to send control commands to all electronic units while simultaneously logging process parameters in real time. Additionally, Python scripts were developed to convert deposition recipes—originally created in Microsoft Excel—into system control routines, easing use by non-experts.

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Surface Science

Room 209 CDE W - Session SS-FrM

Surface Science of Reduced Dimensional Materials

Moderators: Moritz Eder, TU Wien, Naihao Chiang, University of Houston

8:15am SS-FrM-1 On-Surface Synthesis of Planar/Nonplanar Porous Graphene Nanoribbons and Nanosheets, Junfa Zhu, University of Science and Technology of China **INVITED**

The low-dimensional porous graphene nanomaterials might have intriguing electronic properties and open exciting possibilities in the field of functional materials. By using rationally designed precursor molecules, on-surface synthesis (OSS) approach has emerged as a powerful platform for the synthesis of porous low-dimensional graphene-based nanostructures with atomic precision. In this presentation, we report our recent works on the synthesis of planar/nonplanar porous graphene nanoribbons and nanosheets on different metal surfaces. We have successfully synthesized the one-dimensional planar graphene nanoribbons (GNRs) containing periodic [14]annulene pores on Ag(111) and the two-dimensional non-planar graphene nanosheets containing periodic [30]annulene pores on Au(111), originating from a same precursor [1]. Two distinct reaction pathways on the two surfaces were regulated by different thermodynamic and kinetic mechanisms. In addition, a novel nonplanar porous [32]annulene graphene nanosheet that contains the narrowest periodic nanopores up to date was also successfully synthesized by the dissymmetrical debromination and regioselective coupling reactions of precursor molecules on an Au(111) surface [2]. With the combination of the scanning tunneling microscopy (STM), synchrotron radiation photoemission spectroscopy (SRPES) and density functional theory (DFT) calculations, we identified the reaction products, intermediates precisely, and obtained insights into the reaction mechanism. Moreover, the electronic properties of these porous graphene nanoribbons were also precisely characterized.

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[2] Qin T.; Gao F.; Wu Y.; Liang B.; Hu L.; Yang W.; Ding H.; Hu J.; Xu Q.; Garcia-Lekue A.; Guo D.; Wang T.; Zhu J., Synthesis of Graphene Nanosheets Containing Ultra-Narrow Nonplanar Nanopores on Surfaces. *Submitted*.

8:45am SS-FrM-3 Deuterium Adsorption on N-Doped Carbon Materials, Buddhika Alupothe Gedara, Mi Yeon Byun, Zdenek Dohnalek, Zbynek Novotny, Tom Autrey, Pacific Northwest National Laboratory

Nitrogen-doped carbon materials have been identified as promising candidates for hydrogen activation and storage, however, there is little experimental insight into the nature of the hydrogen interaction in response to the changes in the physical behavior of these materials. In this study, we investigated deuterium adsorption on N-doped highly oriented pyrolytic graphite (N-HOPG) and porous, layered N-doped carbon (NC) materials using x-ray photoelectron spectroscopy (XPS) and scanning tunneling microscopy. N-dopants were introduced to HOPG through low-energy N₂+ irradiation, while NC was obtained by pyrolysis of glucose and graphitic carbon nitride (g-C₃N₄). Nitrogen is embedded in the carbon materials in two predominant configurations: as graphitic N (N substituted in the hexagonal C lattice) and pyridinic N (substitutional N adjacent to a C vacancy). In both N-doped carbon materials the amount of graphitic N exceeds the amount of pyridinic N, at 6.9 and 4.2 atomic percent (at.%), and 4.3 and 2.7 at.%, in N-HOPG and NC respectively. Atomic deuterium (D) was generated by D₂ cracking over a hot tungsten (W) filament. XPS data showed that upon D exposure at 220 K, the pyridinic N peak (398.0 eV) shifted to a higher binding energy by +1.2 eV for HOPG and +1.1 eV for NC, while the graphitic N peak (400.7 eV) remained unchanged, indicating that the D atoms bound solely to pyridinic N. All the pyridinic N on HOPG could be saturated with D atoms, whereas only approximately 30% of the pyridinic N could bind D atoms in NC. This is attributed to the porosity of NC, which prevents atomic D from reaching some pyridinic N located within the pores. Deuterium fully desorbed from HOPG at 773 K, while complete desorption from NC was observed above 873 K. This study demonstrates a strong correlation between D adsorption on freestanding graphene and layered porous carbon materials, providing a comparative analysis of the N-doping effects on the surfaces and interfaces of carbon materials in both idealized planar model systems (N-HOPG) and high surface area materials such as NC. The authors gratefully acknowledge the support of U.S. Department of Energy, Office of Science, Basic Energy Sciences, Physical Behavior of Materials under Award No. 80110.

9:00am SS-FrM-4 Ion Beam-induced MoS₂ Surface Modification: An XPS Study of Ar+ and Ar Gas Cluster Ion Beam Treatments, Francesco Laudani, Markus Sauer, Dmitry Polyushkin, Technische Universität Wien, Austria; Lorenzo Petrorosso, Technische Universität Wien, Austria; Jakob Rath, Jakob Hemetsberger, Annette Foelske, Technische Universität Wien, Austria

Two-dimensional (2D) materials are a class of crystals structured as subnanometer sheets with no dangling bonds on the basal plane. Molybdenum Disulfide MoS₂ is the second most studied 2D material after graphene [1]. The material's electrical and chemical properties can be tuned by creating defects. The most studied type of defect due to its ease of formation is the sulfur vacancy, usually found to be a p-dopant [2] and to increase of chemical reactivity of the surface as the defect presents increased chemical reactivity [3]. One way of creating such vacancies is ion beam exposure. It provides a precise and spatially resolved possibility of creating defects on the material's surface due to preferential sputtering of sulfur [4]. XPS studies of ion beam exposure effects on MoS₂ have previously been featured in several publications which showed molybdenum (IV) to reduce to an oxidation state whose nature is not yet precisely defined [5,6,7]. As the nature of the treated surface is still not fully understood our study aims to gain further understanding through a more in-depth investigation of ion beam treatment. We compare freshly cleaved surfaces of MoS₂ crystals (molybdenite) and CVD-deposited MoS₂ monolayers using Ar⁺ ion beam at 500 eV and 1 keV to induce preferential sputtering of sulfur and follow the evolution of molybdenum's chemical environment by recording the Mo 3d region using XPS. In addition, we investigate the effects of Gas Cluster Ion Beams with clusters Ar⁺₂₅₀₀ at 20 keV energy and Ar⁺₁₀₀₀ at 2.5 keV energy, respectively, to understand how a different energy transfer may affect the surface transformation for monomer compared to gas cluster ion beams [8]. The surface properties are then investigated further by monitoring the reactivity by exposing the sample to ambient conditions and following the re-oxidation process in air. The results allow for a better understanding of

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the surface modifications and a preliminary model for the effects of Ar ions on MoS₂ is proposed which might contribute to a more precise tailoring of MoS₂ (electronic) properties in the future.

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9:15am SS-FrM-5 Model Studies of the Surface Structure and Stability of Metal Nanoparticles on Oxide Surfaces Under Catalytic Conditions, *Ravi Ranjan, Francisco Zaera*, University of California - Riverside

The surface structure and properties of copper (Cu) and platinum (Pt) nanoparticles (NPs) supported on tantalum oxide films (Cu/TaO_x/Ta and Pt/TaO_x/Ta) have been investigated under ultrahigh vacuum (UHV) and high-pressure conditions using reflection absorption infrared spectroscopy (RAIRS) and temperature-programmed desorption (TPD), together with carbon monoxide (CO) as a probe molecule. After oxidizing the surface of the tantalum disc *in situ* under UHV, both metals were vapor-deposited onto tantalum at room temperature, and the resulting surface sites were titrated with CO at 77 K for the Cu-deposited surface and 300 K for the Pt-deposited surface. Sequential growth of Cu led to the formation of distinct adsorption sites, including atoms at the metal–oxide interface and on (100) and (111) facets. These Cu NPs remained stable under UHV up to at least 500 K. However, under atmospheric CO pressures, they exhibited reduced thermal stability, remaining intact only between 300 and 450 K. Furthermore, CO adsorption was found to be significantly more exothermic under UHV conditions compared to ambient CO environments, indicating a notable pressure dependence in adsorption energetics.

In contrast, Pt deposition at room temperature resulted in a less dramatic development, manifested by a slight shift in the a-top CO adsorption frequency, the only feature observed in the RAIRS data, to higher wavenumbers with increasing deposition time. No bridging CO features were detected, suggesting the formation of relatively small and isolated NPs. Pt NPs were observed to diffuse into the subsurface upon heating above around 600 K, suggesting limited thermal stability on the TaO_x support. These studies provide insights into the structural evolution and dynamic behavior of metal NPs on oxide supports under conditions relevant to catalysis.

9:30am SS-FrM-6 Exploring the Catalytic Potential of Supported MgO Nanostructures for CH₄ Conversion, *Arephin Islam*¹, Brookhaven National Laboratory; *Jose Rodriguez*, Brookhaven National Laboratory and State University of New York at Stony Brook

Natural gas, primarily composed of methane, is a versatile energy vector with significant potential for efficient energy utilization. Converting methane into valuable hydrocarbons, such as ethane and ethylene, at low temperatures without deactivation challenges remains a critical objective. MgO nanostructures have emerged as promising candidates for methane activation due to their unique surface properties, while Cu-based catalysts demonstrate potential for selective methane oxidation at reduced temperatures. This study examines the growth and reactivity of MgO nanostructures on Cu₂O/Cu(111) and Au(111) substrate using scanning tunneling microscopy (STM) and synchrotron-based ambient-pressure X-ray photoelectron spectroscopy (AP-XPS). Mg deposition onto the "29" structured copper oxide film promotes oxygen transfer from the Cu₂O/Cu(111) substrate to Mg, forming MgO and CuO_x phases. The resulting structures exhibit diverse morphologies, including embedded MgO nanostructures (1–3 Mg atoms) and randomly dispersed MgO nanoparticles. AP-XPS and STM analyses reveal that MgO nanostructures (0.2–0.5 nm wide, 0.4–0.6 Å high) embedded in Cu₂O/Cu(111) substrates activate methane at room temperature, dissociating it primarily into CH_x (x = 2 or 3) and H adatoms with minimal C adatom formation. At 500 K, these structures facilitate C–C coupling into ethane and ethylene with negligible

carbon deposition and no catalyst deactivation, significantly outperforming bulk MgO catalysts, which require temperatures exceeding 700 K. Density functional theory (DFT) calculations support these experimental findings, showing that methane activation is a downhill process on MgO/Cu₂O/Cu(111) surfaces. Methane dissociation is driven by electron transfer from copper to MgO and the presence of under-coordinated Mg and O atoms. The formation of O–CH₃ and O–H bonds lowers the energy barrier for C–H bond cleavage in methane. Furthermore, DFT studies indicate that smaller MgO₂ clusters exhibit stronger binding and lower activation barriers for C–H dissociation, while larger MgO₃ clusters enhance C–C coupling due to weaker *CH₃ binding. To understand the role of Cu, MgO was also deposited on inert Au(111) surface followed by similar XPS and STM experiments. These results highlight the critical role of size in optimizing the catalytic performance of MgO nanostructures for selective methane conversion.

9:45am SS-FrM-7 Automated Matter Manipulation to Create Artificial Lattice Structures, *Ganesh Narasimha*², *Mykola Telychko*, *Woojin Yang*, *Arthur Baddorf*, *An-Ping Li*, *Rama Vasudevan*, Oak Ridge National Laboratory

The precise arrangement of matter using scanning tunneling microscopy (STM) presents a controlled route for engineering structures that exhibits designer quantum states. Nonetheless, the sensitive nature of STM tip poses significant operational challenges in assembling diverse lattice geometries with tailored functionalities. In this work, we introduce a reinforcement learning (RL) driven experimental framework to construct artificial nanostructures via spatial manipulation carbon monoxide (CO) molecules on a copper substrate. The pipeline integrates deep learning-based image analysis for molecule recognition that is coupled with an RL agent that predicts optimized parameters for molecule manipulation. Initial manipulation strategies are generated through stochastic sampling of tip parameters—bias voltage, current setpoint, and tip speed—which are compiled into action sequences serving as training data for the RL agent. Upon training, the agent is deployed on the STM for construction of artificial structures. The workflow uses additional techniques such as data augmentation, active drift correction, and high-precision controls, thereby facilitating the creation of artificial lattice structures. Acknowledgement: Research was supported by the U.S. Department of Energy, Office of Basic Energy Sciences, Scientific User Facilities Division as part of the QIS Infrastructure Project, "Precision Atomic Assembly for Quantum Information Science" and performed at the Center for Nanophase Materials Sciences (CNMS), which is a US Department of Energy, Office of Science User Facility at Oak Ridge National Laboratory.

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10:00am SS-FrM-8 Morton Traum Student Award Announcement,

10:30am SS-FrM-10 Atomic-Scale Exploration of Low-Dimensional Materials, *Nathan Guisinger*, Argonne National Laboratory, USA INVITED

Low-dimensional materials functioning at the nanoscale are a critical component for a variety of current and future technologies. From the optimization of light harvesting solar technologies to novel electronic and magnetic device architectures, key physical phenomena are occurring at the nanometer and atomic length-scales and predominately at interfaces. This talk will cover research and review capabilities within the Center for Nanoscale Materials (CNM) at Argonne National Laboratory, which is one of the five Department of Energy Nanoscale Research Centers. In this presentation, I will discuss low-dimensional material research occurring in the Nanoscale Synthesis and Characterization (NSC) Group at the (CNM). I will discuss the synthesis and characterization of advanced material platforms, such as graphene and borophene, and a more recent focus on artificial lattices. Specifically, the synthesis of artificial graphene nanoribbons by positioning carbon monoxide molecules on a copper surface to confine its surface state electrons into artificial atoms positioned to emulate the low-energy electronic structure of graphene derivatives. We demonstrate that the dimensionality of artificial graphene can be reduced to one dimension with proper "edge" passivation, with the emergence of

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² JVST Highlighted Talk

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an effectively gapped one-dimensional nanoribbon structure. Remarkably, these one-dimensional structures show evidence of topological effects analogous to graphene nanoribbons. Guided by first-principles calculations, we spatially explore robust, zero-dimensional topological states by altering the topological invariants of quasi-one-dimensional artificial graphene nanostructures. The robustness and flexibility of our platform allows us to toggle the topological invariants between trivial and non-trivial on the same nanostructure. Our atomic synthesis gives access to nanoribbon geometries beyond the current reach of synthetic chemistry and thus provides an ideal platform for the design and study of novel topological and quantum states of matter.

11:00am SS-FrM-12 Using Two-Dimensional Covalent Organic Frameworks to Stabilize Single-Atom Catalysts on Model Surfaces, *Yufei Bai*, Indiana University Bloomington; *David Wisman*, NAVSEA Crane; *Steven Tait*, Indiana University Bloomington

Single-atom catalysts (SACs) combine the advantages of homogeneous and heterogeneous catalysts by limiting the reaction sites to isolated single metal atoms with well-defined chemical properties. A metal-ligand coordination method to stabilize SACs has been previously developed by our group, in which 1,10-phenanthroline-5,6-dione (PDO) was used as the ligand to coordinate with metals such as Pt, Fe, and Cr to form stable metal single sites on the gold surface.¹ To further enhance the metal loading per unit surface area while preserving catalyst stability, we explored utilizing the uniform pores of single-layered two-dimensional covalent organic frameworks (2D COFs) for the stabilization of these SACs. Highly stable on-surface 2D COFs with well-defined pore sizes were synthesized on model surfaces under ultra-high vacuum (UHV) or ambient conditions, subsequently serving as templates to host ligand-coordinated Pt SACs. Under UHV conditions, the formation of 2D COF with hexagonal symmetry on the Au(111) surface was achieved by surface-mediated Ullmann-type radical coupling of COF precursor 1,3,5-tris-(4-bromophenyl)benzene (TBB).² Subsequent deposition of PDO and Pt on the COF surface allowed the formation of single-site Pt catalysts via coordination interaction. Surface characterization, including scanning tunneling microscopy (STM) and X-ray photoelectron spectroscopy (XPS), demonstrated the confinement of PDO in the COF pores and the existence of oxidized Pt, indicating its single-atom nature. Under ambient conditions, an imine-linked 2D COF was formed on the highly oriented pyrolytic graphite (HOPG) surface via a solid-vapor interface mechanism, resulting in a high-quality network with long-range order.³ Subsequently, PDO and PDO-coordinated Pt were deposited onto the COF surface, and their surface distribution and interactions with the COF network at the liquid/solid interface were characterized by STM. Those results were compared to the self-assembly behavior of PDO and PDO-coordinated Pt complexes on graphite without 2D COF. STM analysis provides insights into the intermolecular interactions that determine the supramolecular structure and patterning on the surface. In both systems studied, the 2D COF has a significant impact on the distribution of Pt-PDO complexes. These systems which combine COF confinement and metal-ligand coordination strategy to stabilize SACs offer the possibility to achieve higher stability and greater metal loading.

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- (3) *J. Am. Chem. Soc.* **2013**, *135*, 10470-10474.

11:15am SS-FrM-13 Probing the Promotion or Inhibition of TiO₂ Atomic Layer Deposition on Si(111) Surfaces Modified by Basic Amines, *Tyler Parke*, Andrew Teplyakov, University of Delaware

The use of small molecule inhibitors (SMI) in area selective atomic layer deposition (AS-ALD) processes has gained widespread attention for their capability to confer selectivity onto ALD substrates with near-atomic scale resolution. In TiO₂ AS-ALD processes using hydrogen-terminated silicon (H-Si) and oxidized silicon (HO-Si), some nitrogen-containing compounds have been shown to selectively block titanium precursors from the H-Si non-growth surface and prevent selectivity loss.

In this study, an array of basic amines, such as aniline, parafluoroaniline (pFA), pyridine, and trifluoroethylamine (TFEA) were investigated for their use as inhibitors or promoters of TiO₂ thermal ALD processes on the (111) single-crystal surface of H-Si and HO-Si. While some compounds act as a small molecule inhibitor (SMI) on these surfaces during the TiO₂ ALD processes, blocking precursor adsorption, some, such as para-fluoroaniline (pFA), act as a promoter of TiO₂ deposition, enhancing growth rate well beyond what is expected for the unmodified HO-Si growth surface.

Nucleation patterns during the first few cycles of ALD on amine-modified silicon surfaces were probed by atomic force microscopy (AFM) to determine the cause of inhibition or promotion. To further understand these patterns, surface topography was compared between surfaces reacted with basic amines -in vapor-phase and in solution. The bonding of the amines to each surface was confirmed with X-ray photoelectron spectroscopy (XPS) and Fourier transform infrared spectroscopy (FT-IR), which were correlated with density functional theory (DFT) simulations to model the resulting surface structures. Understanding the amine-modified surface structures and what drives them to promote or inhibit ALD processes will allow for a greater capability to tune surface selectivity, and thus a wider scope of 3D architectures to be formed and integrated into nanoelectronic devices.

11:30am SS-FrM-14 Oxides Formed on Multi-Phase Complex Concentrated Alloys: Nanoscale Spectroscopic Imaging with XPEEM and ToF-SIMS, *Keithen Orson*, Samuel Inman, University of Virginia; Jerzy Sadowski, Brookhaven National Laboratory; Derk Rading, Julia Zabel, ION-TOF USA, Inc.; John Scully, Petra Reinke, University of Virginia

Complex concentrated alloys (CCAs) present an opportunity to design new alloys with tunable mechanical and corrosion properties. The inclusion of second phases for strengthening is desirable, but second phases can be detrimental to localized corrosion resistance even if both phases individually have good corrosion resistance. The chemistry and structure of the corrosion-protectant passive layer is not well understood for these complex alloys. The air-formed native oxide of a two-phase CCA with the composition Al_{0.3}Cr_{0.5}Fe₂Mn_{0.25}Mo_{0.15}Ni_{1.5}Ti_{0.3} is characterized with X-ray photoemission electron microscopy (XPEEM) and time-of-flight secondary ion mass spectroscopy (ToF-SIMS). These hyperspectral imaging techniques combine nanoscale spatial resolution with spectroscopic information and produce $>10^6$ spectra. There are sharp differences in oxide character between the FCC and L₂1 phases of this nominally two-phase alloy. Clustering analysis of the XPEEM and ToF-SIMS images reveals that there are at least two additional phases present in the alloy which are identified by their distinct oxide contributions: nanoscale Ti-rich and Al-rich inclusions that comprise <1% of the total alloy, making them difficult to study without these techniques. Minor inclusions may nevertheless have large implications for local breakdown of corrosion resistance. XPEEM and complementary X-ray photoelectron spectroscopy (XPS) show that the primary elements in the passive film are Al, Cr, Fe, and Ti. Mo is present in the 4+, 5+, and 6+ oxidation states, acting as an aliovalent cation. Spectral features observed in Cr spectra with XPEEM indicate that the Cr chemical environment varies between the passive film formed on the FCC matrix and the L₂1 second phase, and the minor inclusions have distinct passive films than the surrounding alloy. To further understand what oxide species form in the passive film, a controlled oxidation of the clean alloy surface was done in UHV conditions and combined with XPEEM and XPS to understand what oxides form during early oxidation. This controlled oxidation reveals that Cr, Al, and Ti oxidize in the first few monolayers of Oxygen exposure. Mo, Fe, and Mn oxidize to a smaller degree, and Ni does not contribute at all during the first 100 Langmuir of oxygen exposure. The composition and rate of oxide formation also varies based on the underlying phase. Direct observations of the passive film over the different phases provide insight into the local corrosion resistance CCAs at phase boundaries, aiding in the future design of corrosion resistant multi-phase CCAs.

Thin Films

Room 206 B W - Session TF-FrM

Fundamentals of Thin Films III

Moderators: *Mark Losego*, Georgia Institute of Technology, *Junjie Zhao*, Zhejiang University

8:30am TF-FrM-2 Themally-Managed QCM in ALD for Rapid Saturation Curves, *David Kane*, Arradiance LLC

Optimizing atomic layer deposition (ALD) processes can require many saturation curves and days of time. In any process, the deposition temperature, precursor doses, and often at least one precursor temperature need to be selected, often by preparing saturation curves. A quartz crystal microbalance (QCM) can significantly accelerate this process by enabling saturation curves to be collected quickly, but QCM is very temperature-sensitive and can produce incorrect results. Indeed, many researchers reject QCM for this reason.

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This work demonstrates several strategies for using QCM, overcoming the challenges of its thermal sensitivity. The frequency vs temperature profiles of commercially available quartz crystals are compared. Thermal isolation and gas load impacts are explored to minimize variations in the QCM temperature. With good thermal stability, it was possible to produce multi-parameter 3D saturation curves to rapidly optimize ALD process parameters.

8:45am TF-FrM-3 Conductive Transparent Porous Al-Doped ZnO Conformal Coatings Synthesized Using Sequential Infiltration Synthesis Method, **Vasanta Gurung**, Diana Berman, University of North Texas

In this study we demonstrated a simple approach for the fabrication of conductive, transparent, nanoporous, and conformal aluminum-doped zinc oxide (AZO) coating using sequential infiltration synthesis (SIS) method. Block copolymer (BCP) polystyrene-block-polyvinyl pyridine (PS-b-P4VP) was employed as a polymer template for infiltrating metal-oxide precursors, leading to the synthesis of nanoporous AZO coatings. We show that both the porosity and electrical conductivity of the AZO coatings could be precisely tuned by swelling the polymer template in a suitable solvent and adjusting the number of SIS cycles. We achieved up to 80% porosity, with a low aluminum-to-zinc doping ratio of 1:17, resulting in a resistivity of approximately 7.83 Ω cm, as measured using conductive atomic force microscopy (C-AFM) and Hall effect measurements. Additionally, the AZO coating exhibited average transmittance of over 80%, confirming its high transparency. These results highlight a highly effective and reliable method for synthesizing conductive, transparent, nanoporous, and conformal AZO coatings, which exhibits a promising potential for a wide range of optoelectronic applications.

KEYWORDS: sequential infiltration synthesis, block copolymer, aluminum-doped zinc oxide, conductivity

9:00am TF-FrM-4 Effect of Aminosilane Precursor and Initial Surface Silanol Density on O₂ Plasma-Assisted ALD of SiO₂, **Andrew Kaye**, Colorado School of Mines; **Bhushan Zopé**, Intermolecular, Inc.; **Xinjian Lei**, **Agnes Derecskei**, **Haripin Chandra**, EMD Electronics, USA; **Sumit Agarwal**, Colorado School of Mines

SiO₂ is a commonly used dielectric material in semiconductor manufacturing, and aminosilanes are typically used as the Si precursor during radical-assisted atomic layer deposition (ALD) of SiO₂. This work explores the role of the initial surface Si-OH density, the substrate temperature, and the structure of the aminosilane precursor on the growth per cycle (GPC) for ALD on plasma-deposited SiO₂ substrates. Specifically, we studied O₂-plasma-assisted ALD of SiO₂ using two aminosilanes, di-sec-butylaminosilane (DSBAS) and dimethylamino trimethylsilane (DMATMS). The surface reactions during ALD were monitored using *in situ* attenuated total reflection Fourier transform infrared (ATR-FTIR) spectroscopy, and the GPC was monitored using *in situ* four-wavelength ellipsometry. On an SiO₂ surface with a high initial Si-OH group density, *in situ* ATR-FTIR spectroscopy shows that ~30% more Si-OH groups are consumed by DMATMS than DSBAS because DSBAS contains a bulkier amino leaving group than DMATMS. *In situ* ellipsometry shows that at an ALD temperature of 100 °C, the GPC using DSBAS and DMATMS are ~1.8 and ~1.2 Å, respectively. The higher GPC for DSBAS shows that the initial aminosilane coverage does not influence the GPC. We speculate that during the O₂ plasma step, O radicals can easily insert into Si-H bonds in adsorbed DSBAS. However, for adsorbed DMATMS, surface Si-(CH₃)₃ groups must be combusted, and then converted to Si-OH groups from species generated in the O₂ plasma.

On an SiO₂ surface with a low initial Si-OH group density, approximately the same number of Si-OH groups react with DMATMS and DSBAS. Therefore, we conclude that once the initial surface Si-OH density is sufficiently low, steric effects do not play a role in initial aminosilane adsorption on SiO₂. For both DMATMS and DSBAS, at a constant ALD temperature, the initial SiO₂ surface Si-OH group density has no effect on the GPC of SiO₂ ALD. *In situ* ellipsometry shows that on an SiO₂ surface with a low initial Si-OH group density, no nucleation delay is observed compared to a film with a high initial Si-OH group density. This implies that more Si-OH groups are produced during the first few O₂-plasma half-cycles compared to the initial density of adsorbed aminosilanes on the surface, allowing steady-state ALD to be reached within 5 ALD cycles. As ALD temperature for DSBAS increases, the GPC decreases. This is due to the thermal instability of reactive surface groups such as Si-OH and Si-H, and the areal density of these sites decreases with increasing temperature.

9:15am TF-FrM-5 Low-Temperature Growth of Epitaxial III-Nitride Films via Hollow Cathode Plasma Atomic Layer Deposition, **Steven Allaby**, **Habib Mousa**, **Fatih Bayansal**, **Abiodun Aderibigbe**, **Mustafa Yavuz**, **Steven Suib**, **Helena Silva**, **Necmi Biyikli**, University of Connecticut

The III-nitride compound semiconductor family plays a critical role in optoelectronic devices and transistor channel materials, particularly for high-power and high-frequency applications. In this study, AlN, GaN, and InN thin films were deposited on c-plane sapphire and n-Si(111) substrates via hollow cathode plasma atomic layer deposition (HCP-ALD). Trimethylaluminum (TMA) was used as the aluminum precursor; triethylgallium (TEG) for gallium; and trimethylindium (TMI) for indium. N₂ and H₂ plasma were included for AlN and GaN, while N₂ was included for InN. For each III-nitride film, the effect of adding argon to the plasma gas composition was investigated. All film depositions took place under 100W rf-power and at a substrate temperature of 200°C.

The resulting films were characterized using ellipsometry, x-ray diffraction (XRD), ultraviolet-visible spectroscopy (UV-Vis), and scanning transmission electron microscopy (STEM) imaging. *In situ* ellipsometry showed linear growth in AlN; accelerated growth in GaN; and delayed growth in InN. The growth per cycle (GPC) values were obtained as 1.21, 0.45, and 1.10 Å for AlN, GaN, and InN, respectively. Spectroscopic ellipsometry showed an increase in refractive index when Ar was included for AlN and InN, while refractive index decreased when Ar was included for GaN. XRD patterns showed highly crystalline films oriented along the (002) plane. Ar inclusion resulted in an increase in the (002) peak for GaN and InN films, while it reduced the (002) peak for AlN. From UV-Vis and Tauc analysis, the optical bandgaps were obtained as 5.80, 3.22, and 1.96 eV for AlN, GaN, and InN, respectively. High-angle annular dark-field (HAADF) STEM images showed monocrystalline films for AlN and GaN, forming smooth interfaces with sapphire. InN appeared polycrystalline with distinct grain boundaries.

Future work involves characterizing the electrical properties of III-nitride films, performing Hall effect measurements to obtain conductivity type, carrier concentration, and mobility. X-ray photoelectron spectroscopy will be performed to determine the amount of carbon and oxygen impurities in the films. After optimizing InN and GaN, InGaN will be alloyed under similar conditions to enable bandgap engineering.

This work contributes to the development of stable and reliable n-type nitride semiconductors for back-end-of-line (BEOL) transistor channel materials.

9:30am TF-FrM-6 Understanding Oxygen Evolution Reaction and Charge Transfer Behavior at the Electrode-Electrolyte Interface Using Pulsed Laser-Deposited Ruthenium Oxide Thin Films, **Mengxin Liu**, North Carolina A&T State University

Ruthenium oxide (RuO₂), regarded as one of the benchmarks for oxygen evolution reaction electrocatalyst materials during water splitting, has been grown in epitaxial thin film form using a pulsed laser deposition method. The precision in the RuO₂ thin films structure, surface orientation, and oxygen stoichiometry have been investigated using high-resolution structural characterization techniques that include x-ray diffraction, x-ray reflectometry, Raman Spectroscopy, and x-ray photoelectron spectroscopy. Following the structural characterization, the films were subjected to four-probe resistivity and Hall measurements via the Van der Pauw method and electrochemical measurements via a three-electrode system. The control in the RuO₂ thin film surface orientation was realized using high-quality single crystal rutile Titanium oxide (TiO₂) substrates with (100), (101), and (110) orientations. Due to different atomic arrangements of Ru and O atoms and interatomic orbital positions in these planes, these films profoundly differ in electrical resistivity, charge carrier density, and dominance in the nature of charge carriers, hence, in the net electrochemical properties. The electrochemical measurements and analysis carried out on the RuO₂ thin film with (101) orientation displays the highest electrochemical current density and the lowest onset potential among the RuO₂ films with other orientations. The next part of our study has focused on understanding the role of oxygen defects in RuO₂ thin films in their electrochemical properties. For this purpose, RuO₂ thin films were on TiO₂ substrates with (110) orientation at substrate temperatures of 500, 600, and 700 °C. After the deposition was over, all the films were cooled to room temperature from the deposition temperature in two hours under the high vacuum conditions of $2\text{-}3 \times 10^{-6}$ Torr. The x-ray photoelectron spectroscopy results carried out on these films have shown that the binding energy center of the corresponding Ru3d doublet peaks for the 700 °C sample is 0.5 eV lower than for the 500 and 600 °C samples. These results indicate the formation of oxygen vacancies with the variation of Ru oxidation states near the top

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surface of the thin film. According to the electrochemical measurement, the 700 °C sample displays the lowest overpotential (500 mV) at the current density of 10 mA/cm² and also the lowest Tafel slope (101.6 mV/dec) than others. Additionally, the electrochemical double larger capacitance of the deposited thin films, measured by different methods, indicates that the 700 °C has the highest value of 61.20 μF, compared with the 26.87 and 28.35 μF for 500 and 600 ° samples, respectively.

9:45am TF-FrM-7 Growth of Ag Nanomorphologies by High-Temperature Glancing Angle Deposition — from Initial Growth Stage to Whisker/Plate Formation, Motofumi Suzuki, Kyoto University, Japan; Khushi Aggarwal, Indian Institute of Technology Delhi, India; Ayako Miki, Taisei Morita, Kota Saeki, Taichi Banno, Kyoko Namura, Kyoto University, Japan

It is known that high-temperature glancing angle deposition (HT-GLAD), where vapor is deposited at an angle greater than 80° from the substrate normal onto a substrate heated to a temperature exceeding one-third of the melting point of the evaporated material, can induce whisker growth in metals such as Al, Cu, Ag, Au, Mn, Fe, Co, Ni, Ti, and Zn. These whiskers can have diameters ranging from several tens to several hundreds of nanometers and lengths of several micrometers or more [1]. Among these metals, the morphologies of Al [2] and Fe [3] have been studied in detail concerning substrate temperature and deposition amount. However, the mechanisms of nucleation and the development of complex morphologies remain unclear.

In this presentation, we will report on the results of investigating the HT-GLAD of Ag at higher substrate temperatures than previously reported.

The Si substrate was introduced into the vacuum chamber, evacuated to the 10⁻⁵ Pa range, and then heated to a temperature between 500 °C and 625 °C. A tungsten (W) basket, serving as the evaporation source, was positioned at an angle of 83° from the substrate normal. Approximately 1 g of Ag grains were loaded into the W basket, and evaporation commenced after the substrate temperature had stabilized. The deposition amount was monitored using a quartz crystal thickness monitor, and was converted to a average thickness of 10-60 nm.

At a substrate temperature of 500 °C, no significant structures were observed at a deposition amount of 10 nm. However, when the deposition amount exceeded 20 nm, numerous particles and whiskers with diameters of less than 100 nm grew on the surface. Additionally, platelets, which had not been observed in conventional HT-GLAD, were found to grow with their wide surfaces facing the incident direction of the Ag vapor.

In the presentation, we will discuss the effects of substrate temperature and materials on the growth mechanism of Ag nanomorphology.

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10:00am TF-FrM-8 Controlled Growth of Tellurium Network Structures for Multi-Spectral Photodetector Applications, Ahmed Adel A. Abdelazez, Wanseok Oh, Yizhou Wang, Tom Schmedake, Yong Zhang, Haitao Zhang, University of North Carolina at Charlotte

Recently, tellurium (Te) has gained significant interest for its unique helical atomic chain structure bonded by van der Waals (vdW) forces. It exhibits thickness-dependent electronic properties similarly to two-dimensional (2D) materials, along with strong spin-orbital coupling from its chiral structure and enhanced environmental stability. As a p-type semiconductor, Te has a narrow band gap (1.2 to 0.3 eV), large responsivity, high detectivity, high on/off ratios, and high carrier mobility, making it a promising material for short-wavelength infrared (SWIR) photodetection. Although a convenient physical vapor deposition (PVD) has been widely applied as a tailored growth technique for the Te growth, the critical parameters controlling the synthesis of 2D and 1D Te structures remain unclear. Herein, this research focuses on understanding the growth mechanism of Te nano- and microstructures. Key parameters, such as pressure, temperature, and growth time, have been systematically explored to study their effects on growth evolution. Various Te structures, including microspheres, microrods, microplates, nanowires, etc., have been synthesized at different growth zones. This study makes it possible to realize controlled growth of different Te structures and a research focus is centered on a unique Te network structure of microrods (Te-Net). This innovative structure is the first of its kind to be reported, as previous reports have mostly been focused on individual micro- or nanostructure. The network structure enables low-cost device fabrication without sophisticated lithography.

The Te-Net based photodetectors demonstrate excellent responsivity (R) and detectivity (D*) under different illumination conditions, with typical values as high as R = 0.43 A/W and D* = 3.98 × 10⁷ Jones at 405 nm. At 532 nm and 808 nm, the device exhibits responsivity of 8.6 × 10³ A/W and 7.3 × 10³ A/W, and detectivity of 9.6 × 10⁵ Jones and 7.4 × 10⁵ Jones, respectively. We are investigating the photoresponse mechanisms including direct carrier photogeneration and local heating for further performance improvement. One important phenomenon we discovered is that the devices are extremely sensitive to the dark environment with the room lights off. No significant visible/near-infrared light was detected from the dark environment using a commercial spectrometer and no existing theory explains this phenomenon. Therefore, future research will focus on investigating the source of the light signals and the mechanism of this extreme sensitivity. We are looking into the device performance under illumination of other light sources, especially those in the SWIR to mid-wavelength infrared ranges

10:30am TF-FrM-10 A Comparative Study of Effects of Ultraviolet Irradiation and Laser Curing on Hydrogenated Amorphous Carbon Thin Films, Md. Mahfujur Rahman, Rajib Chowdhury, Seonhee Jang, University of Louisiana

Hydrogenated amorphous carbon (a-C:H) materials can be utilized in a variety of applications, mainly as protective, wear-resistant, or anti-reflective coatings for optical windows. The a-C:H materials show distinct material properties, such as high density, hardness, chemical inertness, and electrical resistivity. The fabricated a-C:H materials are often subjected to a post-processing to enhance optical and physical properties such as refractive index, extinction coefficient, optical bandgap, and surface roughness. For the post-processing of the a-C:H materials, ultraviolet (UV) irradiation and laser curing are considered. In this study, the a-C:H films deposited by plasma-enhanced chemical vapor deposition (PECVD) method underwent the UV irradiation or laser curing, and the effects of these post-processing treatments on the a-C:H thin films were investigated and compared. First, the a-C:H films were deposited on Si (100) substrates by PECVD using cyclohexane (C₆H₁₂) precursor at room temperature with a plasma power of 80 W. The pristine films exhibited characteristics of being optically transparent, hydrophobic, and topologically smooth.

For UV irradiation, the a-C:H thin films were exposed to a 255 nm light source in air. The UV irradiances were 2.2 and 16.5 mW/cm², respectively, and irradiation times were 1 and 4 hours. For laser curing, the a-C:H films were exposed to Nd:YAG laser source. The Nd:YAG laser had a wavelength of 1064 nm, a pulse duration of 4 ns, and a pulse rate of 3.75 Hz. The laser fluences were 100 and 400 mJ/cm², respectively. The a-C:H films were characterized using Fourier-transform infrared spectroscopy (FTIR), ellipsometry, contact angle geometry, and atomic force microscopy (AFM) to identify chemical bonding structure, optical properties, wettability, and surface morphology, respectively.

UV irradiation reduced the film thickness due to surface ablation. Despite the changes in thickness, the films were optically transparent with a smooth surface topology. Additionally, while the optical bandgap decreased, the wettability of the films increased substantially. Hydrogen depletion and oxygen incorporation were confirmed by characterizing the films with FTIR. On the contrary, the post-processing laser cured films did not show a significant change in thickness but exhibited an even smoother surface compared to pristine films. FTIR analysis showed an improved sp³ bonding network and a reduced graphitic sp² content. In conclusion, this comparative study highlights the significance of selecting an appropriate curing method based on specific application requirements.

10:45am TF-FrM-11 Synthesis, Characterization, and Classification of Polymer-Like Hydrogenated Amorphous Carbon, Seonhee Jang, Rajib Chowdhury, Thomas Poché, University of Louisiana at Lafayette

Hydrogenated amorphous carbon (a-C:H) films exhibit a wide range of properties that depend on the hydrogen (H) content and the hybridization of their carbon (C) atoms as sp³, sp², or sp bonded. The a-C:H films with high sp³ content offer high hardness, chemical inertness, and electrical resistivity. These properties enable the a-C:H films to apply for hardmask, diffusion barrier, sensors, protective coatings, and biocompatible films. Graphite-like a-C:H films with high sp² content show increased conductivity and a reduced optical bandgap. This study focuses on polymer-like a-C:H films with a varying H content of 40–50%, leading to a low-density, soft matrix with reduced cross-linking. Additionally, their friction coefficient is also influenced by H, promoting a lubricating transfer layer. This study explores their structural characteristics, emphasizing their potential applications and differences from other a-C:H subclasses.

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The a-C:H thin films were deposited by plasma-enhanced chemical vapor deposition (PECVD) of a cyclohexane (C_6H_{12}) precursor. The effects of deposition parameters such as reactor pressure and plasma power on the characteristics of the polymer-like a-C:H films were investigated. For the first set of the a-C:H films, the deposition plasma power of 80W supplied from the RF power generator was fixed, and the deposition pressure varied from 19.73 to 38.00 Pa. For the second set of the a-C:H films, the pressure was maintained between 19.73 and 20.93 Pa, and the deposition plasma powers were 20, 40, 60, and 80 W. The optical, and chemical properties of the a-C:H materials were analyzed using various characterization tools such as spectroscopic ellipsometry, atomic force microscopy, Fourier transform infrared (FTIR) spectroscopy

Through these analyses, the a-C:H materials were determined to be optically transparent, topologically smooth, and hydrophobic in nature. The refractive index and FTIR spectra of the films were consistent with those of polymer-like a-C:H. The a-C:H films had optical bandgaps ranging from 3.09 to 3.69 eV, classifying them as wide-bandgap semiconductors. The materials deposited at higher plasma powers and lower pressures were found to have an increased refractive index, which is known to correlate with density. The relative H content of the a-C:H films displayed an inverse relationship with the refractive index, suggesting that H within the films inhibits cross-linking and reduces the density. These results indicate that the formation of more energetic plasma at higher plasma powers and lower pressures results in a-C:H films with a reduced H content and increased density.

11:15am TF-FrM-13 Evaluating Repeatability of Structural and Electrical Properties of PLZT Films Prepared Using Three Distinct Sol-Gel Routes, *Sneha Kothapally, Sushma Kotru, The University of Alabama*

The sol-gel method, a widely used chemical solution deposition technique, offers precise control over stoichiometry and chemical composition, low processing temperatures and low fabrication cost without the need for high vacuum environment. Owing to these advantages, sol-gel method has become a preferred route for fabricating ferroelectric materials such as Lead Lanthanum Zirconate Titanate (PLZT) thin films. However, the film properties are highly influenced by the method of preparation of solution (Sol) and achieving repeatable results remains a major challenge limiting their use in practical applications. In this study, three different sol-gel preparation methods adopted from literature were employed to prepare PLZT sols. Each sol was used to fabricate films resulting in a total of three sets of samples. These films were systematically analyzed for their structural and ferroelectric properties to evaluate the impact of solution preparation method on the film performance. One representative sample from each set was further subjected to detailed surface and compositional analysis using scanning electron microscopy (SEM), energy-dispersive X-ray spectroscopy (EDX), and X-ray photoelectron spectroscopy (XPS). The primary objective of this work was to assess the repeatability of properties within each set and identify the sol preparation method that yields the most consistent and optimal properties. Comparative findings from all three solution methodologies will be presented and discussed.

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